# 8-bit MCU Applications Manual 

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## Preface

This compilation of Application Notes, Engineering Bulletins, Design Concepts, etc. was originally published by the European Literature Centre of Motorola Ltd. in Milton Keynes, England, and has subsequently gained worldwide acceptance.

Because of the worldwide popularity of the Application Manuals Series it is important for the reader to take note of the following:

The various Application Notes, Engineering Bulletins, Design Concepts, etc. which are included were developed at Design Centres strategically located throughout the global community and many were originally written to support a local need. Whilst the basic concepts of each of the publications included may have broad global applicability, specific Motorola semiconductor parts may be referred to that are currently available for limited distribution in a specific region and may only be supported by the country of origin of the document in which it is referenced.

Also included in the series for completeness and historical significance are documents that may no longer be available individually because obsolete devices are referenced or perhaps, simply, the original document is out of print. Such items are marked in the Table of Contents, Cross Reference, Abstracts and on the first page of the document with the letters 'HI' to indicate that these documents are included for Historical Information only.

All the Application Notes, Engineering Bulletins, Design Concepts, etc. are included to enhance the user's knowledge and understanding of Motorola's products. However, before attempting to design-in a device referenced in this Series, the user should contact the local Motorola supplier or sales office to confirm product availability and if application support is available.

Thank you.

Other books in this series include:
DL409/D Rev. 1 16/32-bit Applications Manual
DL410/D Power Applications Manual
DL411/D Communications Application Manual
DL412/D Industrial Control Applications Manual
DL413/D Radio, RF and Video Applications Manual
DL414/D FET Applications Manual

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## Device Cross Reference

## Device Cross Reference

This quick-reference list indicates where specific components are featured in applications documents reproduced in this Manual.


# Abstracts of Applications Documents 

## Abstracts

## AN427 MC68HC11 EEPROM Error Correction Algorithms in C

A modified Hamming code is used to correct one-bit errors and detect two-bit errors in data blocks of up to 11 bits - avoiding the problem of erroneous correction of two-bit errors. The technique is implemented entirely in ' C ', and additional functions are provided to program and read MC68HC11 EEPROM using the encoding/ decoding algorithms.

## AN431 Temperature Measurement and Display Using the MC68HC05B4 and the MC14489

Shows the basic building blocks of a temperature control system based on the M68HC05B-series MCUs. Software routines provided include Look-Up Table Interpolation, Binary to BCD Conversion, Degrees $C$ to Degrees $F$ Conversion, and the basis of a real-time counter/clock. Uses a thermistor as the sensing element to allow easy interfacing to the A/D converter of the MC68HC05B4, but the software principles are easily adapted to other sensors.

## AN432 128K byte Addressing with the M68HC11

The 64K byte direct addressing capability of the M68HC11 family is insufficient for some applications. This note describes two methods of memory paging - one software only, the other hardware plus software - that allow the MCU to address a 1 Mbit EPROM (128K bytes) by manipulation of the address lines. The two methods illustrate the concept of paging and the inherent compromises; the technique may be expanded to other memory combinations. Includes full software listings.

## AN433 TV On-Screen Display Using the MC68HC05T1

The T-series devices in the M68HC05 MCU Family provide a convenient and cost-effective means of adding On Screen Display capability (OSD) to TVs and VCRs. The MC68HC05T1 is at the centre of the T-series price/performance range, and is used in this example. Full software listings are provided for a ROM-efficient implementation of an 8 -row by 16 -character display, including Programme Change, Channel Mode, Automatic Search, Analogues and Channel Name.

## AN434 Serial Bootstrap for the RAM and EEPROM1 of the MC68HC05B6

The MC68HC05B6 has 256 bytes of on-chip EEPROM, called EEPROM1, which can be used for non-volatile data storage. In many applications EEPROM1 stores a look-up table or system set-up variables-in these cases it is necessary to initialise the memory during system manufacture. The RAM bootstrap program in the 'B6 mask ROM uses a simple protocol in order to save ROM space, and cannot accept the S-records that are the normal assembler output. This note explains how to convert assembler output to the 'B6 bootstrap format, and how to bootstrap data into EEPROM1.

## AN436 Error Detection and Correction Routines for M68HC05 Devices Containing EEPROM

Applications based on M68HC05 MCUs increasingly require large amounts of critical data to be stored in the on-chip EEPROM. This note describes 'HC05 software routines which allow stored data to be encoded so that single bit errors in retreived data may be corrected, and two bit errors detected. The routines use a simple Linear Block Code (Hamming Code) for encoding the stored data. They were written originally for the MC68HC05SC21 Smart Card MPU, but can be modified easily to run on any 'HCO5 MCU with EEPROM.

## AN440 MC68HC805B6 and MC68HC705B5 Serial/Parallel Programming Module

The MC68HC05B serial/parallel programmer module allows the user to program MC68HC805B6 and MC68HC705B5 MCUs. This note describes its various operating modes, and gives details of its construction and use. Includes circuit diagram and parts list.

## AN441 MC68HC05EO EPROM Emulator

Unlike other members of the M6805 family, the MC68HC05E0 has no on-chip ROM but can address a full 64 K bytes of external memory; the external memory may be ROM, EPROM, RAM and/or additional hardware. This EPROM emulator illustrates a typical use of this type of MCU; it includes a keyboard, LCD, serial communication and 64 K of paged RAM. It can replace with RAM the program ROM or EPROM in a target system through a cable connection to the system's EPROM socket, and can be used to debug and modify the target system software. Includes an assembled listing of the emulator control program.

## AN442 Driving LCDs with M6805 Microprocessors

The MC68HC05L series of MCUs include circuitry for direct LCD drive. Other MCUs in the M6805 and M 68 HC 05 families have a variety of I/O and display drive capabilities. This comprehensive note describes alternative LCD drive arrangements for applications with different numbers of backplanes and display drive capabilities, including software-based and display driver chip solutions. Circuits and software listings are provided. The techniques apply equally to other MCU families such as the M6801 and M68HC11.

## AN446 MCM2814 Gang-Programmer Using an MC68HC805B6

Non-volatile memories (NVM) such as the MCM2814 are widely used in consumer equipment such as television receivers to store semi-permanent, user-defined information. They may also contain data such as optimum sound and picture settings. In a production environment, the initial loading of this data can be achieved quickly by copying an existing NVM. This note describes a programmer based on an MC68HC805B6 which in four

## Abstracts (continued)

seconds can fully program eight MCM2814s in parallel and verify them individually.

## AN448 "FLOF" Teletext using M6805 Microcontrollers

The "-T" members of Motorola's M68HC05 MCU family provide a cost-effective method of adding On Screen Display (OSD) to TVs and VCRs. This note describes an example of Full Level One Feature (FLOF) Teletext control software written for the MC68HC05T7 to control type 5243 Teletext chips. Around 3K bytes of ROM are used, allowing the code to fit with tuning, OSD and stereofunctions into the 7.9 K bytes of the MC68HC05T7. The example software includes the Spanish implementation of Packet 26; Packet 26 allows for the substitution of specific characters for a particular country.

## AN452 Using the MC68HC11K4 Memory Mapping Logic

The MC68HC11K4 includes memory expansion logic which allows the 64 KByte addressing range of the M68HC11 CPU to be extended to more than 1 MByte. This note discusses the operation of this logic and provides examples of memory maps and possible hardware configurations.

## AN459 A Monitor for the MC68HC05E0

Development systems for single-chip MCUs can be complex and relatively expensive. This can dissuade potential users from designing them into new applications. This note describes a simple "entry level" development system suitable for debugging hardware and software for the M6805 family of microprocessors. Includes full descriptions, circuit diagram and a listing of the monitor software.

## AN890 Low Voltage Inhibit (LVI) Capability of the M6805 HMOS Microcomputer (MCU) Family

The LVI option provides a cost effective means for the MCU to sense a drop in supply voltage and then shut itself down in well-defined manner. Because the option does not require any additional external parts it provides an overall product cost reduction. The LVI option is provided at the time of manufacture by on-chip circuitry contained in part of the user's ROM pattern. This application note includes an LVI schematic diagram as well as a listing of the monitor and self-check programs.

## AN900 Using the M6805 Family On-Chip 8-Bit A D Converter

Factor's which should be considered when using on-chip analog-to-digital (A/D) converters are covered. The pertinent circuit elements and terminology are defined and a self-test hardware/software technique is illustrated. An example on how to manipulate the converted analog data from a temperature sensor is given. It is intended for the digital designer with little or no programming experience.

## AN940 Telephone Dialling Techniques Using the

 MC6805Intelligent telephones are increasing in popularity MCUs from the versatile M6805 family make ideal controllers. This demonstration board, based on an MC68705P3 single-chip MCU, shows two cost-effective methods of DTMF and pulse-type dialling. Full hardware schematic and software listings included.

## AN974 MC68HC11 Floating-Point Package

While most MC68HC11 applications can be implemented using 16 -bit integer precision, certain algorithms may be difficult or impossible without floating-point. This application note details an efficient floating-point package that includes basic trig functions and square root in addition to add, subtract, multiply and divide. It requires just over $2 k$ bytes of memory, with only 10 bytes of page zero RAM in addition to stack RAM.

## AN991 Using the Serial Peripheral Interface to Communicate Between Multiple Microcomputers

Communication between multiple processors can be difficult when different types are used. One solution is the SPI, an interface intended for communication between ICs on the same board. It can be implemented in software, allowing communication between two MCUs where one has SPI hardware and the other does not. Costly expansion buses and UARTs are eliminated. The scheme is illustrated with a temperature/time display circuit using an MC68HC05C4 and an MC68705R3.

## AN1010 MC68HC11 EEPROM Programming from a Personal Computer

Describes a simple and reliable method of programming the MC68HC11's internal EEPROM (or EEPROM connected to its external bus) by downloading data in Motorola S-record format from a standard personal computer (PC) fitted with a serial communications port. Includes BASIC program for the PC (to Program External EEPROM/RAM, Program Internal EEPROM, or Verity internal or External EEPROM/RAM) and the source listing of MC68HC11 code for downloading to RAM to receive S records.

## AN1050 Designing for Electromagnetic Compatibility (EMC) with HCMOS Microcontrollers

As the operating speeds of the latest HCMOS devices increase, the MCU system designer must take more account of the electromagnetic compatibility (EMC) of the finished product. This discussion relates mainly to emission control, but most of the techniques also reduce electromagnetic susceptibility. Subjects include Legal Requirements, RFI Problems, types of radiation, Supply Decoupling, Grounding Techniques and PCB Layouts. Incorporates an article reprint from EMC Technology describing an EMI/RFI diagnostic probe.

## Abstracts (continued)

## AN1055 M6805 16-bit Support Macros

MCUs from the M6805 family are usually chosen for applications requiring small program memory and low computing power, where their low cost is an important benefit. However they may also be used in more advanced applications by employing the advanced software techniques described here. The examples are suitable for 'black box' operation (they may be used without knowing how they work) and consist of macros and subroutines that support pseudo registers on the '6805, simulating registers and addressing modes available on the M68HC11.

## AN1057 Selecting the Right Microcontroller Unit

Selecting the proper MCU for an application is one of the critical decisions which can control the success or failure of the project. There are numerous criteria to consider; many of them are presented here along with the thought processes guiding their selection. The reader should attach an appropriate grading scale before evaluating the total and making the correct decision.

## AN1058 Reducing A/D Errors in Microcontroller Applications

The MCU with integrated Analogue to Digital Converter provides a highly cost-effective solution for many mixed analogue/digital applications. However, combining a wide bandwidth ADC system on the same die as a highspeed CPU can lead to noise problems in the analogue measurements. This comprehensive note lays down basic system guidelines for the design phase of an MCU-based product, to avoid ADC problems. Includes an examination of a real-world system.

## AN1060 MC68HC11 Bootstrap Mode

The M68HC11 Bootstrap Mode allows a user program to be loaded into internal RAM through the Serial Communications interface (SCI). In addition to operating normally, this program can do anything a factory test program can do since the protected control bits become accessible; Expanded Mode resources are available because the control bits can be changed by the bootstrap program. Although the basic concepts are simple, some subtle implications of this mode need careful consideration, both to avoid problems and to find useful applications. Includes commented listings for selected M68HC11 bootstrap ROMs.

## AN1064 Use of Stack Simplifies M68HC11 Programming

Architectural extensions to the M6800 family built in to the MC68HC11 allow easy manipulation of data on the stack. The CPU uses the stack for subroutine and interrupt return addresses. This note discusses two additional uses - the storage of local variables and subroutine parameter passing - that can simplify programming and debugging. It describes the basic operation of the MC68HC11 stack, the concept of local and
global variables, subroutine parameter passing, and the use of the instruction set to achieve the additional uses. Includes example listings illustrating the techniques.

## AN1065 Use of the MC68HC68T1 Real-Time Clock with Multiple Time Bases

The MC68HC68T1 Real Time Clock plus RAM can use a crystal or the $50 / 60 \mathrm{~Hz}$ line frequency as its timebase; a Serial Peripheral Interface is provided for communication with a microcomputer. Applications are often line powered during normal operation, using the line frequency as timebase, but must continue to maintain the correct time of day froma crystal source when mains power is lost. The MC68HC68T1 is not capable of switching between the two frequency sources directly and additional support by the MCU is necessary. This note describes the necessary hardware and software, based on an MC68HC11A8P1 MCU.

## AN1066 Interfacing the MC68HC05C5 SIOP to an $I^{2} \mathrm{C}$ Peripheral

A standard MCU may not have all the peripherals required in a system on chip. The problem can be solved by interfacing the MCU to off-chip peripherals, ideally using a synchronous serial communication port. Unfortunately these peripherals may not have an interface that is compatible with Motorola's simple synchronous Serial I/O Port (SIOP). This note describes how the SIOP on the MC68HC05C5 can be interfaced to an $1^{2} \mathrm{C}$ peripheral, in this case the PCF8573 Clock/Timer. Includes circuit and software listings for a timer/calendar application that can interface with a terminal.

## AN1067 Pulse Generation and Detection with Microcontroller Units

MCUs are often required to generate timed output pulses, and to detect and measure input pulses. Output pulses might strobe a display latch, transmit a code or meter an action in a process control system. Input pulses can range from microseconds to hours, and include detecting pushbutton closures, receiving codes or measuring engine rotation. This note describes various methods of generation and detection using several families of Motorola MCUs with differing timer structures. Includes program listings.

## AN1091 Low Skew Clock Drivers and their System Design Considerations

With microprocessor-based systems now running at 33 MHz and beyond, low-skew clock drivers have become essential - Motorola produces several devices with less than 1 ns skew between outputs. Unfortunately, simply plugging one of these high performance clock drivers into a board does not guarantee troublefree operation. Careful board layout and system noise considerations must also be taken into account.

## Abstracts (continued)

## AN1097 Callbration-Free Pressure Sensor System

The MPX2000 Series of pressure transducers give an output signal proportional to applied pressure. They are available as both ported and unported assemblies for pressure, vacuum and differential measurement. By using the on-chip A/D converter of the MC68HC05B6 MCU, an accurate, reliable and versatile pressure measurement system can be designed which needs no external calibration.

## AN1102 Interfacing Power MOSFETs to Logic Devices

Most popular power MOSFETs need 10 volts of gate drive to support their maximum drain current. This creates problems when attempting to drive from 5 volt logic. The new Logic Level power MOSFETs solve some but not all of the problems. This note discusses easy methods of directly interfacing both types of MOSFET to TTL and CMOS logic, and to microprocessors such as the M68HC11. Discusses a method of calculating switching times, to minimise switching losses, and stresses the significance of logic power supply variations.

## AN1120 Basic Servo Loop Motor Control Using the MC68HC05B6 MCU

A Proportional Derivative (PD) closed-loop speed control for a brush motor can be created using four integrated circuits, two opto discretes and less than 200 bytes of code. The use of an MCU in feedback control systems is increasingly commonplace. It is justified when system flexibility is needed, for example to accommodate varying drive motors or to allow wear parameters to be stored in EEPROM. This design is based on an MC68HC05B6 MCU and an MPM3004 power MOSFET H-bridge.

## AN1203 A Software Method for Decoding the Output from the MC14497/MC3373 Combination

Infrared communication is now widely used as a simple and effective means of remote control over short distances. A variety of encoding methods is used, including the biphase scheme implemented by the MC14497, a complete building block for IR data transmission. The MC3373 is a companion receiver chip to the MC14497, providing front-end processing to interface a photo detector to a TTL level. This note describes, with software listings for the MC68HC11 and the MC68HC05, the decoding of the data at the output of the MC3373.

## ANE405 BI-Directional Data Transfer Between MC68HC11 and MC6805L3 Using SPI

The powerful Serial Peripheral Interface available on many Motorola MCUs is implemented in 2 forms (the HCMOS families support only Level 1, Level 2 is implemented only on HMOS processors). Both levels communicate easily with each other, but Level 2 has additional
capabilities including asynchronous communication. This note describes a method of achieving synchronous communication between levels 1 and 2, and explains the on-chip differences in SPI implementation.

## ANE418 MC68HC805B6 Low-Cost EEPROM Microcomputer Programming Module HI

The EEPROM feature of the MC68HC805B6 microcomputer enables the user to emulate the MC68HC05B6 and the MC68HC05B4. This note describes one programming technique for the MC68HC805B6 internal EEPROM, and describes the design of the simple programming module required.

## ANE420 Monitor Program for the

 MC68HC05B6 Microcomputer UnitA monitor program is available in the mask ROM of a 68HC05B6 MCU (XC68HC05B6FN MONITOR) which allows the user to write and debug small portions of $68 \mathrm{HC05B6}$ code. It is used in conjuction with a monitor circuit module, +5 V power supply and RS-232 terminal. This note includes a description of the facilities available from the software, a circuit diagram of the module and a listing of the monitor code.

## EB400 Secure Single Chip Microcomputer Manufacture

Security is the fundamental requirement in designing and manufacturing Smart Card MCUs. This Bulletin summarises the purpose and history of Smart Cards, and explains some of the problems of testing devices after manufacture without prejudicing security. The manufacturing process is necessarily different to that of 'normal' MCUs.

## EB401 SCAM Modules for Smart Cards

Motorola's SCAM range of assembly modules consists of the Smart Card product family packaged for insertion in ISO standard plastic cards. This Bulletin lists the planned devices and shows the IS7816/2 contact dimensions, locations and connections. All devices conform to all relevant ISO standards.

## EB404 "Memories Are Made of This"... a Look at Memory Considerations for Smart Card Applications

A Smart Card application typically uses many millions of units per year, so unit cost is crucial to its success. This paper discusses some of the issues concerning memory size and type - and their effect on the specification and cost of secure microcomputers - with particular reference to physical size. (11pp)

## EB405 Smart Cards: How to Deal Yourself a Winning Hand

An overview of the current Smart Card market and the various types of product on offer. It looks at ways of determining what features must be provided by a suc-

## Abstracts (continued)

cessful Smart Card implementation in a given application. Because of the high production volumes, it is essential to choose the optimum product, and to ask the right questions at the start.

## EB408 MC68HC705T3 Bootloader

This bootloader for the MC68HC705T3 has four switchselected modes of operation. In addition to programming and verifying the internal EPROM from an external EPROM, it is also possible to load and execute a program in RAM locations $\$ 0100-\$ 01 \mathrm{FF}$. A handshake facility is included to allow the external EPROM to be replaced by an intelligent data source and to provide a limited debug capability. Includes circuit diagram and software listing.

Applications
Documents

# MC68HC11 EEPROM Error Correction Algorithms in C 

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## INTRODUCTION

This application note describes a technique for correcting one bit errors, and detecting two bit errors, in a block of data ranging from 1 to 11 bits in length. The technique applied is a modified version of a Hamming code, and has been implemented entirely in C. Additional functions have been provided to program and read the EEPROM on an MC 68 HC 11 microcontroller unit using the error encoding and decoding algorithms.

## ENCODING AND DECODING ALGORITHMS

Some texts [1], [2] describe the use of simultaneous equations to calculate check bits in Hamming distance-3 error correcting codes. These codes are so named because there are at least 3 bit differences between each valid code in the set of available codes. The codes are relatively easy to generate and can be used to correct one bit errors. However, their main drawback is that if two bit errors occur, then the correction will be made erroneously. This is because the condition of two bit errors corresponds exactly with a one bit error from another valid code.

The technique described here is based on an algorithmic strategy which produces Hamming distance-4 codes over the range of 1 to 11 data bits. This type of code is capable of correcting single bit errors and detecting 2 bit errors.

Alternatively, if the errors are only to be detected, without correction, then up to 3 bit errors can be detected. The reason for this is that the condition of a 3 bit error in one code corresponds to a one bit error from an adjacent valid code. The implication of this is that, if the algorithms are used to correct errors, then a 3 bit error will be corrected erroneously, and flagged as a 1 bit error.

The $C$ program is divided into 3 modules, plus one header file:

1. EECOR1.C

This is the main program segment, and serves only to illustrate the method of calling and checking the algorithms.
2. HAMMING.C

This module contains the functions which encode and decode the data.
3. EEPROG.C

This module contains the EEPROM programming functions tailored for an MC68HC11 MCU.

## 4. HC11REG.H

This is the header file which contains the MC68HC11 I/O register names, defined as a C structure.

## IMPLEMENTATION OF ERROR CORRECTION STRATEGY

The basic principle of decoding the error correcting codes is to use a Parity check matrix, $H$, to generate a syndrome word which identifies the error. The H matrix can be generated as follows:

1. Identify how many data bits are needed. For example: 8 data bits
2. Use the standard equation to derive the number of check bits required: If $k$ is the number of check bits, and $m$ the number of data bits, then for the Hamming bound to be satisfied:

$$
2^{k} \geq m+k+1
$$

A simple way to understand why this equation holds true is as follows: If one can generate a check code which is able to identify where a single error occurs in a bit stream, then the check code must have at least the same number of unique combinations as there are bits in the bit stream, plus 1 extra combination to indicate that no error has occurred. e.g. if the total number of data plus check bits were 7 , then the check code must consist of 3 bits, to cover the range 1 to 7 plus one extra (0) to indicate no error at all.

In this example, if $m=8$ then, by rearranging the above equation:

$$
2^{k}-k-1>=8
$$

One way to solve for $k$ is to just select values of $k$ starting at say, 1 and evaluating until the bound is reached. This method is implemented algorithmically in function InitEncode() in module HAMMING.C

For $m=8$, the solution is $k=4$. Note that this value exceeds the Hamming bound, which means that additional data bits can be added to the bit stream, thus increasing the efficiency of the code. In fact, the maximum number of data bits is 11 in this case.
3. A Parity matrix, H is created from a 'horizontally orientated' binary table. The number of columns (b1 to b12) in the matrix correspond to the total number of data and check bits, and the number of rows ( $r 1$ to r 4 ) to the number of check bits.

| i.e. b1 | b2 | b3 | b4 | b5 | b6 | b7 | b8 | b9 | b10 | b11 | b12 |  |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| r1 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |
| r2 | 0 | 1 | 1 | 0 | 0 | 1 | 1 | 0 | 0 | 1 | 1 | 0 |
| r3 | 0 | 0 | 0 | 1 | 1 | 1 | 1 | 0 | 0 | 0 | 0 | 1 |
| r4 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 | 1 | 1 | 1 |

Because the $H$ matrix in this form, is simply a truncated 4 bit binary table, it can easily be generated algorithmically.
4. The position of all the check bits ( C 1 to C 4 ) within the encoded word is the position of the single 1 s in the columns of H . The remaining bits correspond to the data bits (D1 to D8).

| i.e. | C1 | C2 | D1 | C3 | D2 | D3 | D4 | C4 | D5 | D6 | D7 | D8 |
| ---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | 1 | 0 |  |
| 0 | 1 | 1 | 0 | 0 | 1 | 1 | 0 | 0 | 1 | 1 | 0 |  |
| 0 | 0 | 0 | 1 | 1 | 1 | 1 | 0 | 0 | 0 | 0 | 1 |  |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 | 1 | 1 | 1 |  |

5. Each check bit is generated by taking each row of $H$ in turn, and modulo-2 adding all bits with a 1 in them except the check bit positions.

## i.e. $\quad C 1=D 1+D 2+D 4+D 5+D 7$ <br> $C 2=D 1+D 3+D 4+D 6+D 7$ <br> $\mathrm{C} 3=\mathrm{D} 2+\mathrm{D} 3+\mathrm{D} 4+\mathrm{D} 8$ <br> $C 4=D 5+D 6+D 7+D 8$

6. The syndrome, $s$, is the binary weighted value of all check bits.
i.e. $s=1 * C 1+2 * C 2+4 * C 3+8 * C 4$
7. The error position (i.e. column) is determined by the value of the syndrome word, provided it is not zero. A zero syndrome means no error has occurred. Note that this error correction technique can correct errors in either data or check bits - which is not necessarily the case with certain other error correction strategies.

The advantage of this method, where the check bits are interspersed in a binary manner tbroughout the code word, is that the error position can be calculated algorithmically.

An important point to note is that the parity check matrix described above generates Hamming distance-3 codes, which means that 2 errors will cause erroneous correction. This can be fixed by adding an extra parity check bit, C 5 , which is the modulo-2 addition of all data and check bits together.
i.e. $C 5=C 1+C 2+D 1+C 3+D 2+D 3+D 4+C 4+D 5+D 6+D 7+D 8$

The code word then becomes:

C1 C2 D1 C3 D2 D3 D4 C4 D5 D6 D7 D8 C5
To determine if an uncorrectable error has occurred (i.e. 2 errors) in the received word, the extra parity bit is tested. If the syndrome is non-zero and the parity bit is wrong, then a correctable error has occurred. If the syndrome is non-zero and the parity bit is correct, then an uncorrectable error has occurred.

## EFFICIENCY

The following table lists the relative efficiencies of this algorithm, against data size.

Data bits Encoded bits Efficiency \%

| 1 | 4 | 25 |
| ---: | ---: | ---: |
| 2 | 6 | 33 |
| 3 | 7 | 43 |
| 4 | 8 | 50 |
| 5 | 10 | 50 |
| 6 | 11 | 55 |
| 7 | 12 | 58 |
| 8 | 13 | 62 |
| 9 | 14 | 64 |
| 10 | 15 | 67 |
| 11 | 16 | 69 |

The implementation of the above techniques are given in the module HAMMING.C.

In order to maintain orthogonality in the EEPROM algorithms, the encoded data used by the functions in module EEPROG.C are forced to either 1 byte or 2 byte (word) sizes. This also eliminates the complexities of packing and unpacking data in partially filled bytes.

## CONCLUSIONS

In this application note, the encoding algorithm's generator matrix is the same as the parity check matrix.

The C functions <read> and <write> in the module HAMMING.C return a status value $-0,1$ or 2 -which indicates whether the data has no errors, 1 corrected error, or 2 erroneously corrected errors. This means that if the status value is 0 or 1 , then the data can be assumed good. If the status value is 2 , then the data will be bad.

Alternatively the functions can be used for error detection only, without correction. In this case, a status value of 1 corresponds to either 1 or 3 bit errors, while a status value of 2 indicates that $\mathbf{2}$ bit errors have occurred.

By using the C functions listed in this application note, the encoded data size can easily be changed dynamically. To do this, the function <InitEncode> must be called with
the required new data size. The global variables used by all the encoding, decoding and EEPROM programming and reading functions are automatically updated. This allows the encoding and error correction process to be virtually transparent to the user. In addition, the functions <write> and <read> will automatically increment the address pointer by the correct encoded data size set up by <InitEncode>. This simplifies the structure of loops to program and read back data. Example code is provided in module EECOR1.C.

The encoding and decoding algorithms listed here may be applied to other forms of data, such as that used in serial communications, or for parallel data transfers.

By incorporating the error correction or detection-only schemes described in this application note, the integrity of data storage and transfer can be greatly improved. The impact on EEPROM usage is to increase its effective reliability and extend its useful life beyond the manufacturers' guaranteed specifications.

## REFERENCES

[1] Carlson, 'Communication Systems', Chapter 9, McGraw-Hill.
[2] Harman, 'Principles of the Statistical Theory of Communication', Chapter 5, McGraw-Hill

## MODULE EECOR1.C

```
Tests EEPROM error detection using a modified hamming encoding scheme.
typedef unsigned char byte;
typedef unsigned int word;
/* Global variables used by main() */
    byte *ee_addr,*start_addr,*end_addr,i,Error;
    word data;
/**********************************************************************************
/* External global variables */
    extern byte CodeSize; }/*=\mathrm{ number of bits in encoded data */
/* External Functions */
    extern byte read(word *data,byte **addr); /* Function returns error status */
    extern byte write (word data,byte **addr); /* "
/* Table of Status returned by read and write functions
                Returned Status Condition
            0 , No errors detected or corrected.
            1 One error detected and corrected.
            2 Two errors detected, but correction is erroneous.
```

Notes:
1/ When the returned value is 2 , the function <read> will returned a bad value in variable
<data> due to the inability to correctly correct two errors. <read> also automatically increments
the address pointer passed to it, to the next memory space. The incremented value takes into
account the actual size of the encoded data. i.e. either 1 or 2 byte increment.
2/ Function <write> also performs a read to update and return an error status. This gives an
immediate indication of whether the write was successful. <write> also automatically increments
the address pointer passed to it, to the next free memory space. The incremented value takes into
account the actual size of the encoded data. i.e. either 1 or 2 byte increment.
*/

int main()
i
CodeSize=InitEncode (11); /* Get code size (less 1) needed */
/* by 11 data bits */
ee addr=(byte *) $0 x b 600$ /* Initialise EEPROM start address $\quad$ /
e-adr (byce *) 0xb600
/* and 'erase' EEPROM*/
for $(i=1 ; i<=0 \times 10 ; i++)$
Error=write ( $0 \times 7$ ff, \&ee addr);
ee_addr=(byte *) $0 \times \mathrm{xb} 600$;
Error=write (0x5aa, \&ee_addr);
Error=write (0x255, \&ee_addr);
CodeSize=InitEncode (4);
start_addr=ee_addr;
for ( $i=1 ; i<0 \times 10 ; i \ll=1$ )
Error=write (i, \&ee_addr) ;
end_addr=ee_addr;
ee_addr=start_addr;
while (ee addr$<$ end addr)
Error=read (\&dā̄a, \&ee_addr) ;
/* Read back all the 4 bit data

* Read back all the 4 bit data
/* <data> good if Error=0 or 1
\} /* main */


## MODULE HAMMING.C

```
/*Modules to Generate hamming codes of distance 4, for data sizes in the range 1 bit to 11 bits.
The upper bound is limited by the encoded word type bit range (16 bits).
Corrects 1 bit error in any position (check or data), and detects 2 bit errors in any position.
After execution of the <Decode> function, the global variable <ErrFlag> is updated to indicate
level of error correction.
i.e. ErrFlag Condition
    0 No errors detected or corrected.
    1 One error detected and corrected.
    2 Two errors detected, but correction is erroneous.
Note that when ErrFlag is 2, function <Decode> will return a bad value, due to its inability to
correctly correct two errors.
*/
*define TRUE 1
#define FALSE 0
typedef unsigned char byte;
typedef unsigned int word;
    byte DataSize,CodeSize,EncodedWord,ErrFlag;
/* Function prototypes */
    byte OddParity(word Code);
    word Power2 (byte e);
    byte InitEncode (byte DataLength);
    word MakeCheck (word Data) ;
    word Encode (word Data);
    word Decode (word Code);
byte OddParity (Code)
word Code;
/*
Returns TRUE if Code is odd parity, otherwise returns FALSE
*/
1
        byte p;
        p=TRUE;
        while (Code!=0)
    l
        if (Code & 1) p=!p;
        Code>>=1;
    }
    return(p);
}
word Power2 (e)
byte e;
/*
    Returns 2^e
*/
{
word P2;
    signed char i;
    P2=1;
    if ((signed char) (e)<0)
        return(0);
    else
```

```
{
    for (i=1;i<=(signed char) (e);i++)
        P2<<=1;
        return (P2);
    }
}
byte InitEncode (DataLength)
byte DataLength;
/*
    Returns the minimum number of total bits needed to provide
    Hamming distance }3\mathrm{ codes from a data size defined by passed
    variable <DataLength>. This value also updates global variable <DataSize>.
    i.e. finds the minimum solution of (k+m) for the inequality:
        2^k}\geqk+m+
    In addition, updates global variable <EncodedSize> to reflect number of bytes
per encoded data. <EncodedSize> will be either 0 or 1.
*/
{
    byte CheckLength,i;
    DataSize=DataLength; /* DataSize used by other functions in this module */
    CheckLength=1;
    while ((Power2 (CheckLength)-CheckLength-1)<DataLength)
        CheckLength++;
    i=CheckLength+DataLength;
    EncodedWord=i / 8; /* =0 if byte sized, =1 if word sized
    return (CheckLength+DataLength);
}
word MakeCheck (Data)
word Data;
/*
    Returns a check word for Data, based on global variables <DataSize>
    and <CheckSize>. The H parity matrix is generated by a simple for loop.
*/
{
    byte i,H,CheckSize,CheckValue,Check,CheckMask;
    word DataMask;
    Check=0;
    CheckMask=1;
    CheckSize=CodeSize-DataSize;
    for (i=1;i<=CheckSize;i++)
    {
        CheckValue=FALSE;
        DataMask=1;
        for (H=1;H<=CodeSize;H++)
        {
            if ((0x8000 % H)!=0) /* Column with single bit set .......*/
            {
                        if ((H& CheckMask)!=0)
                                CheckValue^=((DataMask & Data) !=0);
                            DataMask<<=1;
            }
        }
        if (CheckValue) Check|=CheckMask;
        CheckMask<<=1;
    }
    return (Check);
}
```

```
word Encode (Data)
word Data;
/*
    Returns an encoded word, consisting of the check bits
    concatenated on to the most significant bit of <Data>.
    A single odd parity bit is concatenated on to the Encoded word to
    increase the hamming bound from 3 to 4, and provide 2 bit error
    detection as well as 1 bit correction.
    Uses global variables <Datasize> and <CodeSize> to determine the
    concatenating positions.
*/
{
    word Code;
    Code=Data | (MakeCheck (Data)<<DataSize);
    if (OddParity (Code))
        Codel=Power2 (CodeSize);
    return(Code);
}
word Decode (Code)
word Code;
/*
    Returns the error corrected data word, decoded from <Code>.
    Uses global variable <DataSize> to determine position of the
    check bits in <Code>.
    Updates global variable <ErrFlag> to indicate error status i.e.:
                ErrFlag Status
            0 No errors found
            1 Single error corrected
            2 Double error - invalid correction
*/
{
    word ParityBit,Data,Check,ErrorCheck,Syndrome,DataMask;
    byte DataPos,CheckSize,CheckPos,H,DataBit;
    ErrFlag=0;
    ParityBit=Code & Power2(CodeSize); /* Extract parity bit. */
    DataMask=Power2 (DataSize)-1; /* Make data mask */
    Data=Code & DataMask; /* Extract data bits. */
    CheckSize=CodeSize-DataSize; /* Extract check bits, */
    Check=(Code>>DataSize) & (Power2(CheckSize)-1); /* ignoring parity. */
    ErrorCheck=MakeCheck (Data);
    Syndrome=Check ^ ErrorCheck;
    if (Syndrome>0) ErrFlag++;
    H=0;
    DataPos=0;
    CheckPos=DataSize,
    DataBit=TRUE;
    while ((H!=Syndrome) & (DataPos<DataSize)) /* Identify which data or */
    {
        H++;
        DataBit=(0\times8000 % H);
        if (DataBit) DataPos++;
        else CheckPos++;
    }
    if (DataBit) Code^=Power2 (DataPos-1);
    else Code^=Power2 (CheckPos-1);
    Codel=ParityBit;
    if (OddParity(Code)) ErrFlag++;
    return(Code & DataMask);
}
```


## MODULE EEPROG.C

/*Module to program MC68HC11 EEPROM.

```
    Contains <read> and <write> functions to encode and decode data
    formatted by modified hamming scheme.
*/
#include <HC11REG.H>
#define regbase (*(struct HC11IO *) 0x1000)
#define eras 0x16
#define writ 0x02
typedef unsigned char byte;
typedef unsigned int word;
    union twobytes
    {
        word w;
        byte b[2]; /* Word stored as MSB,LSB */
    } udata;
    extern byte EncodedWord,ErrFlag;
/* Function prototypes */
    extern word Encode (word Data);
    extern word Decode (word Code);
    void delay(word count);
    void eeprog (byte val,byte byt,byte *addr,word count);
    void program(byte byt,byte *addr);
    byte read(word *data,byte **addr);
    byte write(word data,byte **addr);
void delay (count)
word count;
1
    regbase.TOC1=regbase.TCNT+count; /* Set timeout period on OC1 and */
    regbase.TFLG1=0x80; /* clear any pending OCl flag.
/* Wait for timeout flag. */
}
void eeprog (val, byt, addr, count)
byte val; /* val determines Erase or Write operation */
byte byt;
byte *addr;
word count;
i
    regbase.PPROG=val;
    *addr=byt;
    ++regbase.PPROG;
    if (count<100) count=100;
    delay (count);
    -regbase.PPROG;
    regbase.PPROG=0;
}
```

```
void program(byt, addr)
byte byt;
byte *addr;
l
    eeprog (eras, byt, addr, 20000);
    eeprog (writ, byt, addr, 20000);
}
byte read(data, addr)
word *data;
byte **addr;
{
    udata.b[1] =* (*addr) ++;
    if (EncodedWord)
        udata.b[0] =* (*addr) ++;
    else
        udata.b[0] =0;
    *data=Decode (udata.w);
    return (ErrFlag);
}
byte write(data, addr)
word data;
byte **addr;
{
    byte *oldaddr;
    udata.w=Encode (data) ;
    oldaddr=*addr;
    program(udata.b[1], (*addr) ++);
    if (EncodedWord)
            program(udata.b[0],(*addr)++) ;
    return (read (&udata.w, &oldaddr));
}
```

```
/* First erase byte */
```

/* First erase byte */
/* Then write value
/* Then write value
*/
*/
/* Read back data LSB first, and inc address */
/* If word stored then read MSB */
/* Inc address for next call to this function*/
/* else only byte stored, so clear MSB */
/* Decode data, which updates <ErrFlag>, */
/* and return ErrFlag */
/* Encode data. */
/* Save initial address for verification. */
/* Program LSB first to allow for either */
/* 1 or 2 byte encoded data */
/* MSB of word sized data,\& inc address */
/* Return <ErrFlag> to calling segment */

```

\section*{HC11REG.H}



\title{
Temperature measurement and display using the MC68HC05B4 and the MC14489
}

\author{
By Jeff Wright, \\ Motorola Ltd., East Kilbride
}

\section*{INTRODUCTION}

This application note is intended to show the basic building blocks of a temperature control system based on the MC68HC05Bx family of MCUs. Software routines in the application include look-up table interpolation, binary to BCD conversion, DegC to DegF conversion and the basis of a real time counter/clock. For temperature display the Multi-character LED display driver MC14489 is used, driven from the B4's SCI, resulting in simple hardware with a low component count. The temperature sensing element used here is a thermistor to allow easy interfacing to the A/D converter of the HC05B4, but the software principles shown would be the same for many other types of sensors. A software listing is included at the end of this application note.

\section*{TEMPERATURE MEASUREMENT}

A pre-calibrated thermistor was chosen as the temperature sensing element. Its characteristic curve over the temperature range of -40 to \(80^{\circ} \mathrm{C}\) is shown in Figure 1. To get the best accuracy from the HC05B4's on-board A/D, the input signal shbuld be scaled to use as much of the available VRH-VRL range as possible. Here VRH is connected to Vdd and VRL is tied to Vss. In this case, using the thermistor as potential divider with a \(20 \mathrm{k} \Omega\) resistor results in a signal range of approximately 0.3 V to 4.7 V over the -40 to \(80^{\circ} \mathrm{C}\) temperature range The voltage across the thermistor (input to the A/D), plotted against temperature, is shown in Figure 2.


Figure 1. Thermistor resistance vs Temperature


Figure 2. \(A / D\) input voltage vs Temperature (inset: circuit used)

As can be seen from Figure 2, the response is non-linear and so a look-up table approach is the simplest way of obtaining the required accuracy. The thermistor characteristics are stored as a series of points in a table in ROM and a linear interpolation between adjacent points is used to obtain the temperature that corresponds to a given A/D reading. The number of points that must be stored depends on how non-linear the response is and the required accuracy of the result. In this case 16 points were chosen: in order to keep the software simple (and
therefore fast), they are spread at intervals of 16 through the A/D result range of \(0-255\). For each point ( \(16,32,48\) etc.), the voltage on the A/D input was calculated and the corresponding temperature was obtained from the graph of Figure 2. These points were then used to form the look-up table shown in Figure 3, resulting in a temperature range of -40 to \(79^{\circ} \mathrm{C}\). Figure 4 shows the reconstructed response of the thermistor obtained by linear interpolation of the points in the look-up table.
\begin{tabular}{|c|c|c|c|}
\hline A/D RESULT & ADD (volts) & TEMP \(\left({ }^{\circ} \mathrm{C}\right)\) & TEMP \(\left({ }^{\circ} \mathrm{C}\right.\) 2s Compl \()\) \\
\hline 0 & 0 & - & - \\
\hline 16 & 0.31 & 79 & 4 F \\
\hline 32 & 0.63 & 56 & 38 \\
\hline 48 & 0.94 & 43 & 2 B \\
\hline 64 & 1.26 & 34 & 22 \\
\hline 80 & 1.57 & 27 & 1 B \\
\hline 96 & 1.88 & 21 & 15 \\
\hline 112 & 2.20 & 15 & 0 F \\
\hline 128 & 2.51 & 10 & 0 A \\
\hline 144 & 2.82 & 5 & 05 \\
\hline 160 & 3.14 & -1 & FF \\
\hline 176 & 3.45 & -6 & FA \\
\hline 192 & 3.77 & -11 & F5 \\
\hline 208 & 4.08 & -18 & EE \\
\hline 224 & 4.39 & -26 & E6 \\
\hline 240 & 4.71 & -40 & D8 \\
\hline 255 & 5.0 & - & - \\
\hline
\end{tabular}

Figure 3. Interpolated A/D input voltage vs Temperature


Figure 4. Interpolated A/D input voltage vs Temperature

The temperature reading is updated every second; the software to accomplish this is relatively simple:

The timer is set to overflow every 125 mS with a 4.1934 MHz crystal. The timer overflow interrupt routine updates the real time counters TICKS, SECS, MINS \& HRS and sets the flag bit SEC every time a second has elapsed.

The main program loop is executed every second (via the SEC flag bit) and after checking the metric/imperial selector switch the temperature is measured by the subroutine ADCONV. This routine starts by reading the thermistor selector switch and setting up the A/D control register accordingly. An A/D conversion is then carried out four times on the selected channel and the results accumulated in the accumulator and the temporary register TEMP. This result is then divided by 4 by rotating, to obtain the average \(A / D\) result. The averaging technique is employed to try and reduce the effect of noise on the A/D input. The number of conversions to average is determined by time constraints and the noise levels in the surrounding environment. The upper nibble of the result is then used to access the look-up table to obtain the 'base' temperature value. If the temperature limit is exceeded then the TLIMIT flag is set before exiting from the routine.

Temperature table entries are stored in 2's complement form so that the interpolation between positive and negative values will work successfully. The interpolation is carried out by obtaining the difference between the base value and the next in the table, multiplying this by the lower nibble of the \(A / D\) result and then dividing by 16. This result is then subtracted from the base value to obtain the real temperature in 2 's complement \({ }^{\circ} \mathrm{C}\) which is stored in the register NEWTMP before exiting from the routine. The difference information is subtracted from the base value rather than added because the thermistor has a negative temperature co-efficient (NTC) so that an increase in the A/D result corresponds to a drop in temperature.

If the imperial mode is selected \(\left({ }^{\circ} \mathrm{F}\right)\) then the next stage before updating the display is to convert from \({ }^{\circ} \mathrm{C}\) to \({ }^{\circ} \mathrm{F}\) and this is carried out in the subroutine CTOF.

Converting from \({ }^{\circ} \mathrm{C}\) to \({ }^{\circ} \mathrm{F}\) is accomplished by multiplying by 1.8 and adding 32 . First the sign of the temperature in \({ }^{\circ} \mathrm{C}\) is stored via the flag bit NEGNUM, then the maximum \({ }^{\circ} \mathrm{F}\) limit \(\left(53^{\circ} \mathrm{C}\right)\) is checked before the magnitude is multiplied by 1.8 (multiply by 115 and divide by 64). Again, use is made of rotating to do the dividing, in order to increase execution speed. The sign of the result is then restored and 32 added to obtain the temperature in 2 's complement \({ }^{\circ} F\).

\section*{TEMPERATURE DISPLAY}

An MC14489 multi-character display driver was chosen for this purpose as it can be easily interfaced to a wide range of Motorola MCUs, requires almost no external components and has a character set that includes the degree symbol ( \({ }^{\circ}\) ). The MC14489 can also be cascadedif the application was expanded to require a larger display. The MC14489 would normally be driven from an SPI on the MCU but here, since the the 68 HC 05 B family does not have an SPI, use is made of the SCI clock output feature that is available on this family.

Before the temperature can be written to the display driver it has to be converted into the correct data format.

The first stage of this is to convert from 2's complement binary to \(B C D\). This is carried out in the routine CONBCD which is called from SETDISP. The sign of the temperature is stored in the flag bit NEGNUM before SETDISP is called; then, after first checking if the TLIMIT flag is set, the temperature is converted to BCD in DECO-2-by CONBCD. This is accomplished by rotating left the binary number followed immediately by a rotate left of the BCD result; this has the effect of multiplying the current \(B C D\) result by 2 and adding in the new binary bit at the same time. After each rotate the \(B C D\) registers are checked and adjusted for overflow ( \(\mathbf{~} \$ 09\) ) before the bit counter contained in the index register is decremented. This process of rotate then adjust is continued until all the binary bits have been used; the \(B C D\) result will then be resident in the registers DECO, 1 \& 2.

The rest of the routine SETDISP is concerned with setting up the display registers DISP1, 2, 3 and the display control register DISPC. The MC14489 data format is msb first whereas the 68HC05B4 SCI transmits Isb first; this means that the bit order of the data stream has to be stored in reverse in the display registers. This can be confusing when trying to work out the codes that have to be stored in the B4 to generate a specific character.

Figures 5 a and 5 b show the 14489 data format and the corresponding bit positions in the B4 registers DISP1. \(2,3 \& C\). The sign of the temperature is restored and the numeric display registers are configured to display '-' if the temperature limit has been exceeded before exiting from the SETDISP routine.

The main program loop then calls the subroutine DISPL which actually transmits the contents of the display registers to the MC14489 via the SCI. The MC14489 contains special Bit Grabber circuitry that allows either the internal display registers or the configuration register to be updated without address or steering bits so that updating the display involves a simple transmission of either 3 bytes for the display registers or 1 byte for the configuration register. Even for cascaded 14489s there is no need for address bits - see the MC14489 data sheet for more details.

The MC14489 can be clocked at up to 4 MHz at 5 volts so here the maximum transmit baud rate of the SCl is used - 131.072 KHz with a 4.19304 MHz crystal. The transmission of the display data only takes place if there has been a change in the data since the last time. If there has been a change, the 3 data registers are transmitted in turn starting with DISP3 and the OLD registers are updated ready for the change check next time round. After the last byte has gone, the SCl and 14489 are disabled before returning to the main loop.

The last subroutine called from the main program is the 14489 configuration update routine DISCON. This routine operates in a similar manner to DISPL, checking to see if there has been a change to the config. data before transmitting it.

This completes the operation of the program which now jumps back to the start of the main loop and waits for the SEC bit to be set again before repeating the temperature measurement and display sequence.


MC14489 configuration data

MC68HC05B4 display register DISPC

Figure 5a. MC14489 to MC68HC05B4 display register mapping


Figure 5b. MC14489 to MC68HC05B4 display register mapping

\begin{abstract}
HARDWARE

As already mentioned, the use of the MC14489 results in a very low component count for the application; the hardware schematic can be seen in Figure 6. The only I/O pins required are for reading the option switches and for controlling the enable of the MC14489. Pulldowns are required on the clock and data pins as these become high impedance when the SCl is disabled. The LED displays are common cathode; a single external resistor is all that is required to set the brightness
level of the displays. In this case though, a light dependent resistor, R12 (ORP12), has been used to control the display brightness for a variety of background lighting conditions. The resistance of R12 decreases with increasing light and so R11 must be incorporated to ensure that the maximum source current spec. of the MC14489 is not exceeded in very bright lighting conditions. R13 ensures there is still enough drive current for the LEDs in dark conditions.
\end{abstract}

\section*{APPLICATION AREAS}

As mentioned in the introduction, this application note is designed only to show some fundamental building blocks of a temperature control system based on the \(68 \mathrm{HC05Bx}\) family of MCUs. Where possible, the software has been written in a modular fashion, so that the routines can easily be transported to another application and the binary to BCD routine could be expanded to handle larger numbers. The large number of \(1 / O\),

PWMs and timer functions unused show that the \(68 \mathrm{HC05B}\) family has plenty of functionality left to perform other control functions. For example, in process control, fluid flow or speed sensors could be connected to the timer input capture pins, pressure sensors to the other A/D pins, a keypad to the I/O lines and the other I/O \& PWMs used to perform output control functions.


Figure 6. Hardware schematic




\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 253 & 00000 f 98 & ae08 & & LDX & \# 8 & \\
\hline 254 & 00000f9a & 4 f & & CLRA & & \\
\hline 255 & 00000f9b & 3459 & LUPDIS2 & LSR & DECO & \\
\hline 256 & 00000f9d & 49 & & ROLA & & \\
\hline 257 & 00000f9e & 5a & & DECX & & Shuffle bit order of digits as above. \\
\hline 258 & 00000f9f & 26fa & & BNE & LUPDIS2 & \\
\hline 259 & 00000 fa 1 & ab0f & & ORA & \# \({ }^{\text {S }}\) ( \({ }^{\text {F }}\) & add code for the deg symbol. \\
\hline 260 & 00000 fa 3 & b75f & & STA & DISP2 & Store in second display register. \\
\hline 261 & 00000 fa5 & a631 & & LDA & \#\$31 & Big C, all d.ps off. \\
\hline 262 & \(00000 \mathrm{fa7}\) & 015502 & & BRCLR & IMP, MODE, STDIS3 & \\
\hline 263 & 00000 fa & a6f1 & & LDA & \# \(\$\) F1 & Big \(F\), all d.ps off. \\
\hline 264 & 00000 fac & b760 & STDIS 3 & STA & DISP 3 & \\
\hline 265 & 00000fae & a 6 cb & & LDA & \# \$CB & \\
\hline 266 & \(00000 \mathrm{fb0}\) & be57 & & LDX & DEC2 & \\
\hline 267 & 00000 fb 2 & 2702 & & BEQ & STDISC & \\
\hline 268 & 00000 fb 4 & a68b & & LDA & \# \$8B & \\
\hline 269 & 00000 fb 6 & b761 & STDISC & STA & DISPC & \\
\hline 270 & 00000 fb 8 & 81 & & RTS & & \\
\hline 271 & 00000 fb 9 & a 6 bb & FORCE & LDA & \# \({ }^{\text {B }}\) B & FORCE DISPLAY TO -^C \\
\hline 272 & 00000 fbb & b75e. & & STA & DISP1 & \\
\hline 273 & 00000 fbd & a 6 bf & & LDA & \# \({ }^{\text {BF }}\) & or \(-^{\wedge} \mathrm{E}\) \\
\hline 274 & 00000 fbf & b75f & & STA & DISP2 & \\
\hline 275 & 00000 fcl & a631 & & LDA & \#\$31 & \\
\hline 276 & 00000 fc 3 & 015502 & & BRCLR & IMP, MODE, STDI3 & \\
\hline 277 & 00000 fc 6 & a 6 f1 & & LDA & \# SF1 & \\
\hline 278 & 00000 fc 8 & b760 & STDI3 & STA & DISP3 & \\
\hline 279 & 00000 fca & a 6 fb & & LDA & \# \$FB & \\
\hline 280 & 00000 fcc & b761 & & STA & DISPC & \\
\hline 281 & 00000 fce & 81 & & RTS & & \\
\hline \multicolumn{7}{|l|}{282} \\
\hline \multicolumn{7}{|l|}{283} \\
\hline \multicolumn{7}{|l|}{284} \\
\hline 285 & & & *0000000 & 00000000 & 00000000000000000 & 00000000000000000000000000000000000 * \\
\hline 286 & & & *0 & & & 0* \\
\hline 287 & & & *0 & TOVINT & - Timer & Overflow IRQ routine 0 * \\
\hline 288 & & & *0 & & & 0 * \\
\hline 289 & & & *00000000 & 00000000 & 00000000000000000 & 0000000000000000000000000000000000000 * \\
\hline \multicolumn{7}{|l|}{290} \\
\hline 291 & 00000 fcf & Ob132a & TOVINT & BRCLR & TOF, TSR, NOOVF & Check Tim overflow has really happened. \\
\hline 292 & 00000 fd 2 & 3c50 & & INC & TICKS & \\
\hline 293 & 00000 fd 4 & b650 & & LDA & TICKS & UPDATE REAL TIME CLOCK COUNTERS \\
\hline 294 & 00000 fd 6 & a 108 & & CMP & \#8 & \\
\hline 295 & \(00000 \mathrm{fd8}\) & 2520 & & BLO & NOINC & \\
\hline 296 & 00000 fda & 3 f 50 & & CLR & TICKS & \\
\hline 297 & 00000 fdc & 3 c 51 & & INC & SECS & \\
\hline 298 & 00000 fde & 1654 & & BSET & SEC, FLAG & \\
\hline 299 & 00000 fe 0 & b651 & & LDA & SECS & \\
\hline 300 & 00000 fe 2 & al3c & & CMP & \#60 & \\
\hline 301 & 00000 fe 4 & 2514 & & BLO & NOINC & \\
\hline 302 & 00000 fe 6 & \(3 \mathrm{f51}\) & & CLR & SECS & \\
\hline 303 & 00000 fe 8 & 3c52 & & INC & MINS & \\
\hline 304 & 00000 fea & b652 & & LDA & MINS & \\
\hline 305 & 00000 fec & a13c & & CMP & \# 60 & \\
\hline 306 & 00000 fee & 250a & & BLO & NOINC & \\
\hline 307 & \(00000 \mathrm{ff0}\) & 3f52 & & CLR & MINS & \\
\hline 308 & 00000 ff 2 & b653 & & LDA & HRS & \\
\hline 309 & \(00000 f f 4\) & alff & & CMP & \# \(\$ \mathrm{FF}\) & \\
\hline 310 & 00000 ff 6 & 2702 & & BEQ & NOINC & \\
\hline 311 & 00000 ff 8 & 3 c 53 & & INC & HRS & \\
\hline \multicolumn{7}{|l|}{312} \\
\hline 313 & 00000ffa & b619 & NOINC & LDA & TIMLO & Clear TOF flag. \\
\hline 314 & 00000 ffc & 80 & NOOVF & RTI & & \\
\hline 315 & & & & & & \\
\hline
\end{tabular}




Section synopsis
\begin{tabular}{llll}
1000000016 & \((\) & \(22)\) & .RAM \\
200000010 & \((\) & \(16)\) & .PAGE0 \\
30000001 f 4 & \((\) & \(500)\) & .USROM \\
400000000 e & \((\) & \(14)\) & .VECT
\end{tabular}

Symbol table
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|}
\hline PAGE0 & 2 & 00000000 & I & DISPC & 1 & 00000061 & I & LUPBCD & 3 & 00001059 & I & OLDD3 & 1 & 00000064 & I & TEMP & 1 & 0000005b \\
\hline . RAM & 1 & 00000000 & 1 & DOCONF & 3 & 000010df & 1 & LUPDIS1 & 3 & 00000 f 83 & 1 & OLDDC & 1 & 00000065 & & TEMP 1 & 1 & 0000005c \\
\hline . USROM & 3 & 00000000 & 1 & DWAIT1 & 3 & 000010ae & 1 & LUPDIS2 & 3 & 00000 f9 & 1 & POR & 4 & 00001 ffe & & TEMP 2 & 1 & 0000005d \\
\hline . VECT & 4 & 00000000 & 1 & DWAIT2 & 3 & 000010b7 & 1 & MINS & 1 & 00000052 & 1 & PREAM & 3 & 000010a3 & & TICAP & 4 & 00001 ff 8 \\
\hline ADLUP 1 & 3 & 0000100 f & 1 & DWAIT3 & 3 & 000010c0 & 1 & MODE & 1 & 00000055 & 1 & PREAM1 & 3 & 000010dc & & TICKS & 1 & 00000050 \\
\hline ADTAB & 2 & 00000020 & 1 & DWAIT4 & 3 & 000010e7 & 1 & MUL1P8 & 3 & 00000f5e & 1 & SCIIN & 4 & 00001 ff 2 & 1 & TIMINT & 3 & 00000 f1a \\
\hline BIN0 & 1 & 00000056 & 1 & DWAIT5 & 3 & 000010ee & 1 & NEWTMP & 1 & 0000005a & 1 & SECS & 1 & 00000051 & 1 & TOCMP & 4 & 00001 ff 6 \\
\hline CONT1 & 3 & 00001008 & 1 & EXTINT & 4 & 00001 ffa & 1 & NOIMP & 3 & 00000f2f & 1 & SETAD & 3 & 0000100a & 1 & TOVFLW & 4 & 00001 ff 4 \\
\hline DEC0 & 1 & 00000059 & 1 & FLAG & 1 & 00000054 & I & NOINC & 3 & 00000 ffa & 1 & SOETI & 4 & 00001 ffc & 1 & TOVINT & 3 & 00000 fcf \\
\hline DEC1 & 1 & 00000058 & 1 & FORCE & 3 & 00000 fb 9 & 1 & NONEG & 3 & \(00000 \mathrm{f57}\) & 1 & STD1 & 3 & 00000 f 96 & 1 & TRANGE & 3 & 0000104 f \\
\hline DEC2 & 1 & 00000057 & 1 & GODISP & 3 & 00000f43 & 1 & NONEG1 & 3 & 00000 f 71 & 1 & STDI3 & 3 & 00000 fc 8 & 1 & TSTD1 & 3 & 0000106b \\
\hline DECCX & 3 & 00001018 & 1 & GOMETR & 3 & 00000 f 3 a & 1 & Noove & 3 & 00000 ffc & 1 & STDIS3 & 3 & 00000 fac & , & TSTD2 & 3 & 00001075 \\
\hline DISP 1 & 1 & 0000005e & 1 & GOMORE & 3 & 00000f41 & 1 & NOOVR & 3 & 00001081 & 1 & STDISC & 3 & 00000 fb 6 & 1 & TSTNEG & 3 & \(00000 £ 91\) \\
\hline DISP2 & 1 & 0000005 f & 1 & HRS & 1 & 00000053 & 1 & OLDD1 & 1 & 00000062 & 1 & TABL & 3 & 00001023 & \(I^{\prime}\) & UPDATE & 3 & 00001098 \\
\hline DISP 3 & 1 & 00000060 & & INIRAM & 3 & 00000f0c & & OLDD2 & 1 & 00000063 & 1 & TEMP & 1 & 0000005b & & & & \\
\hline
\end{tabular}

Symbol cross-reference
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|}
\hline . PAGEO & *131 & & & & & & & & & & & & & & \\
\hline . RAM & * 94 & & & & & & & & & & & & & & \\
\hline . USROM & *142 & & & & & & & & & & & & & & \\
\hline . VECT & * 498 & & & & & & & & & & & & & & \\
\hline ADLUP 1 & *334 & 334 & 339 & & & & & & & & & & & & \\
\hline ADTAB & *133 & 351 & 357 & & & & & & & & & & & & \\
\hline BINO & *111 & 183 & 392 & & & & & & & & & & & & \\
\hline CONT1 & 327 & *330 & & & & & & & & & & & & & \\
\hline DECO & *114 & 255 & 387 & 393 & 396 & 399 & & & & & & & & & \\
\hline DEC1 & *113 & 242 & 388 & 394 & 400 & 401 & 404 & & & & & & & & \\
\hline DEC2 & *112 & 246 & 266 & 389 & 395 & 405 & 406 & 410 & & & & & & & \\
\hline DECCX & 336 & *338 & & & & & & & & & & & & & \\
\hline DISP1 & *121 & 252 & 272 & 424 & 451 & & & & & & & & & & \\
\hline DISP2 & *122 & 260 & 274 & 427 & 447 & & & & & & & & & & \\
\hline DISP3 & *123 & 264 & 278 & 430 & 443 & & & & & & & & & & \\
\hline DISPC & *124 & 269 & 280 & 469 & 482 & & & & & & & & & & \\
\hline DOCONF & * 481 & & & & & & & & & & & & & & \\
\hline DWAIT1 & *446 & 446 & & & & & & & & & & & & & \\
\hline DWAIT2 & * 450 & 450 & & & & & & & & & & & & & \\
\hline DWAIT3 & * 454 & 454 & & & & & & & & & & & & & \\
\hline DWAIT4 & *485 & 485 & & & & & & & & & & & & & \\
\hline DWAIT5 & *488 & 488 & & & & & & & & & & & & & \\
\hline EXTINT & *504 & & & & & & & & & & & & & & \\
\hline FLAG & *102 & 170 & 171 & 175 & 182 & 199 & 204 & 222 & 224 & 237 & 250 & 298 & 325 & 376 & 411 \\
\hline FORCE & 237 & *271 & & & & & & & & & & & & & \\
\hline GODISP & *184 & & & & & & & & & & & & & & \\
\hline GOMETR & 177 & *179 & & & & & & & & & & & & & \\
\hline GOMORE & 180 & *183 & & & & & & & & & & & & & \\
\hline HRS & * 100 & 308 & 311 & & & & & & & & & & & & \\
\hline INIRAM & *151 & 154 & & & & & & & & & & & & & \\
\hline LUPBCD & * 392 & 413 & & & & & & & & & & & & & \\
\hline LUPDIS 1 & *242 & 245 & & & & & & & & & & & & & \\
\hline LUPDIS2 & *255 & 258 & & & & & & & & & & & & & \\
\hline MINS & *99 & 303 & 304 & 307 & & & & & & & & & & & \\
\hline MODE & *108 & 172 & 174 & 177 & 262 & 276 & & & & & & & & & \\
\hline
\end{tabular}
\begin{tabular}{lrrrrr} 
MUL1P8 & 201 & 203 & \(* 207\) & & \\
NEWTMP & \(* 116\) & 179 & 197 & 226 & 374 \\
NOIMP & 173 & \(* 175\) & & & \\
NOINC & 295 & 301 & 306 & 310 & \(* 313\) \\
NONEG & 198 & \(* 202\) & & & \\
NONEG1 & 222 & \(* 224\) & & & \\
NOOVF & 291 & \(* 314\) & & & \\
NOOVR & 408 & \(* 412\) & & & \\
OLDD1 & \(* 125\) & 425 & 452 & & \\
OLDD2 & \(* 126\) & 428 & 448 & & \\
OLDD3 & \(* 127\) & 431 & 444 & & \\
OLDDC & \(* 128\) & 150 & 470 & 483 & \\
POR & \(* 506\) & & & & \\
PREAM & \(* 441\) & 441 & & & \\
PREAM1 & \(* 480\) & 480 & & & \\
SCIINT & \(* 500\) & & & & \\
SECS & \(* 98\) & 297 & 299 & 302 & \\
SETAD & 329 & \(* 331\) & & & \\
SOFTI & \(* 505\) & & & & \\
STD1 & 249 & 250 & \(* 252\) & & \\
STDI3 & 276 & \(* 278\) & & & \\
STDIS3 & 262 & \(* 264\) & & & \\
STDISC & 267 & \(* 269\) & & & \\
TABL & \(* 346\) & & & &
\end{tabular}
\begin{tabular}{|c|c|c|c|c|c|c|c|}
\hline TEMP & *117 & 326 & 337 & 340 & 342 & 344 & 359 \\
\hline TEMP 1 & *118 & 355 & 372 & & & & \\
\hline TEMP 2 & *119 & 358 & 361 & 371 & 373 & & \\
\hline TICAP & *503 & & & & & & \\
\hline TICKS & * 97 & 292 & 293 & 296 & & & \\
\hline TIMINT & *161 & & & & & & \\
\hline TOCMP & * 502 & & & & & & \\
\hline TOVFLW & *501 & & & & & & \\
\hline TOVINT* & *291 & 501 & & & & & \\
\hline TRANGE & 352 & 354 & * 376 & & & & \\
\hline TSTD1 & 398 & *401 & & & & & \\
\hline TSTD2 & 403 & *406 & & & & & \\
\hline TSTNEG & 247 & *250 & & & & & \\
\hline UPDATE & 426 & 429 & 432 & * 435 & & & \\
\hline UPDCON & 471 & *474 & & & & & \\
\hline
\end{tabular}

\title{
128K byte addressing with the M68HC11
}

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}

\section*{OVERVIEW}

\begin{abstract}
The maximum direct addressing capability of the M68HC11 device is 64 K bytes, but this can be insufficient for some applications. This application note describes two methods of memory paging that allow the MCU to fully address a single 1 megabit EPROM (128K bytes) by manipulation of the address lines.
\end{abstract}

The two methods illustrate the concept of paging and the inherent compromises. The technique may be expanded to allow addressing of several EPROM, RAM or EEPROM memories or several smaller memories by using both address lines and chip enables.

\section*{PAGING SCHEME}

The M68HC11 8-bit MCU is capable of addressing up to 64 K bytes of contiguous address space. Addressing greater than 64 K bytes requires that a section of the memory be replaced with another block of memory at the same address range. This technique of swapping memory is known as paging and is simply a method of overlaying blocks of data over each other such that only one of the blocks or pages is visible to the CPU at a given time.

In a system requiring more than 64 K bytes of user code and tables, it is possible to use the port lines to extend the memory addressing range of the M 68 HC 11 device. This has certain restrictions but these can be minimised by careful consideration of the user code implementation.

There are two basic configurations; method A uses only software plus a single port line to control the high address bit A16; method \(B\) is a combination of a small amount of hardware and software controlling the top 3 address bits A14, A15 and A16.

In the examples below, the MC68HC11G5 device is used to demonstrate the paging techniques since this device has a non-multiplexed data and address bus; any M 68 HC 11 device may be used in a similar way.

Method A has the advantage of no additional hardware and very fewlimitations in the software. The user code main loop can be up to 64 K bytes long and remain in the same page but this is at the expense of longer interrupt latency. The vector table and a small amount of code must be present in both pages of memory to allow correct swapping of the pages.

Method \(B\) has the advantage of not affecting the interrupt latency and has just one copy of the vector table. The maximum length of the user code main loop in this example is 48 K bytes with a further 5 paged areas of 16 K bytes for subroutines and tables.

\section*{METHOD A - SOFTWARE TECHNIQUE}

Address A16 of the EPROM is directly controlled by port D(5) of the M 68 HC 11 as shown in figure 1 . This port is automatically configured to be in the input state following reset. It is vital that the state of the port line controlling address A16 is known following reset and so there is a \(10 \mathrm{~K} \Omega\) pull-up resistor on this port line to force the A16 address bit to a logic high state following reset. This port bit is then made an output during the set-up code execution but care must be taken in ensuring that the data register is written to a logic one before the data direction register is written with a one to make the port line output a high state.

This port bit allows the M 68 HC 11 to access the 128 K byte EPROM as two memories of 64 K bytes each which are paged by changing the state of the address A16 line on the EPROM. It important to make sure that the port timing enables the port line to change state at least the setup and hold time before the address strobe ( E clock rising edge on the MC68HC11G5), otherwise there could be problems with address timing.

Figure 2 shows a schematic representation of the paging technique for this method where there are two separate 64 K byte pages of memory which may only be addressed individually.

This paging scheme means that code cannot directly jump from one 64 K page to another without running some common area of code during the page switch. This may be accomplished in 2 basic ways. The user code could build a routine in RAM (which is common to both pages since it is internal and therefore unaffected by the port \(D(5)\) line) or have the same location in both pages devoted to a page change routine. The example software listing in appendix \(A\) uses the latter approach.

\section*{Interrupt routines}

The change of page routine stores the current page before setting or clearing the port \(D(5)\) line and then has a jump command which must be at exactly the same address in both pages of memory. This is because the setting or clearing of the port \(D(5)\) line will immediately change the page of memory but the program counter will increment normally. Thus a change from page 0 to page 1 will result in the BSETPORTD command from page 0 followed by the JMP \(0, X\) instruction from page 1 (the new page). To enable a jump to work, the \(X\) index register has been loaded with the acdress of the routine to be run in the new page. Figure 3 shows the execution of code to perform a change of page from page 1 to page 0 .

Returning from the interrupt routine requires the RTI command to be replaced with a return from interrupt routine that checks the RAM location containing the memory page number prior to the interrupt routine execution. The routine then either performs an RTI command immediately if it is to remain in the same page or otherwise changes the state of the port \(D(5)\) line and then performs an RTI command in the correct page. Note that as with the JMP \(0, X\) command, the RTI must be at the same address in both pages. It is important that the

I-bit in the CCR (interrupt inhibit) is set during this time for the example code to run correctly, otherwise the return page may be altered. This limitation can be overcome by using the stack to maintain a copy of the last page prior to the current interrupt.

The latency for an interrupt routine in a different page from the currently running user code is increased by 21 cycles on entering the interrupt routine and 18 cycles on leaving the interrupt routine. Any interrupt code that could not tolerate any such latency could be repeated in both pages of memory.

\section*{Other routines}

Jumping from one page to another may be done at any time by using the same change of page routine but there is no need to store the current page in RAM and so these two lines of code become redundant. In the example, the change page routine could be started at the BCLR or BSET command and save 4 cycles. This would therefore reduce the page change delay to 17 cycles. Note that it is not possible to perform a JSR command to move into the other page with the method shown in the example since the RTS would not return to the original page, however, a modification to the return from interrupt routine would allow an equivalent function for a return from subroutine. In this case the stack should be used to maintain the correct return page or the 1 -bit in the CCR should be set to prevent interrupts.

\section*{Important conditions}

The state of the port line controlling address A16 after reset is very important. In the example, port \(D(5)\) is used which is an input after reset and has a pull-up resistor to force a logic high on A16. If an output only port line was used then it could be reset such that A 16 is a logic zero (no pull-up resistor required) which has an important consequence. The initialisation routine which sets up the ports must be in the default page dictated by the state of address A16 following reset otherwise the user code may not be able to correctly configure the ports and hence be unable to manipulate address A16. Similarly, a bidirectional port line could have a pull-down resistor to determine the address A 16 line after reset with the same implications.

The assembler generates two blocks of code with identical address ranges used by the user code. This could not be programmed directly into an EPROM since the second page would simply attempt to overwrite the first page. The code must therefore be split into two blocks and programmed into the correct half of the EPROM. Some linkers may be capable of performing this function automatically. Figure 2 illustrates the expansion of the pages into the 128 K byte EPROM memory.

The RAM and registers, and internal EEPROM if available and enabled, will all appear in the memory map in preference to external memory so care must be taken to avoid these addresses or move the RAM or registers away to different addresses by writing to the INIT register.


Figure 1. Software Paging Schematic Diagram


Figure 2. Software Paging Representation


1 - Jump to change page routine
2 - Page changes to page 0
3 - Jump to address in X register (in page 0 )

Figure 3. Flow of program changing from Page 1 to Page 0


Figure 4. Hardware and Software Paging Schematic Diagram

\section*{METHOD B - COMBINED HARDWARE AND SOFTWARE TECHNIQUE}

The basic approach to this method is the same as above except that hardware replaces some of the software. A port line together with M68HC11 addresses A14 and A15 are NOR'd to control the address A16 line of the EPROM. This signal is also used to select between the port line and address line for A14 and A15 (see figure 4). The hardware between the port lines controlling the A14 and A15 addresses enables 64 K bytes of user code to be addressed at all times with 48 K bytes common to all the pages and then selecting one of five 16 K byte pages of EPROM memory.

In the example, port \(\mathrm{D}(3)\) and address A 14 are connected to the input of a 2 channel multiplexer such that port \(D(5)\), address A14 and address A15 control which of these two signals reaches the A14 pin of the EPROM. If addresses A14 or A15 are logic 1, the NOR gate outputs a logic 0 state, ensuring the A16 pin of the EPROM is a logic 0 . In this case address A14 controls the A14 pin of the EPROM and similarly A15 and port \(D(4)\) are selected such that address A15 controls the A15 pin of the EPROM. Thus the main 48 K byte portion of the EPROM memory may be addressed at all times at addresses \(\$ 4000\) up to \$FFFF. With Port D(5) and address A14 and A15 all at logic 0 (address range \(\$ 0000\) to \(\$ 3 F F F\) ), the port lines Port \(D(3)\) and Port \(D(4)\) are selected in place of address lines A14 and A15. Page 0 is always selected whenever Port \(D(5)\) is a logic 1 . This makes it possible to have one of the five pages of 16 K bytes paged into the 64 K addressing range of the HC 11 while always maintaining the main 48K bytes of user code in the memory map.

There are few restrictions on the user code since the hardware provides the switching logic. Code can be made to run from one paged area to another by jumping to an intermediate routine in the main page. Port D is configured to be in the input state following reset which results in the main page plus page 0 of the paged memory in the 64 K byte address map since the port \(D\) lines each have a pull-up resistor to maintain a logic high state after reset. A simple change memory map routine can then bring in the desired page at any time. Appendix \(B\) shows the assembly code for a program that toggles different port pins in each of the 5 pages controlled from a main routine in the main page. Figure 5 shows the 5 overlaid pages expanded to a 128 K map with the flow of the program demonstrating a change from page 0 to page 1 by running the change page subroutine shown in bold type.

\section*{Implementation in ' \(C\) ' language}

The demonstration code was originally written in assembly language but it may also be implemented in ' C ' as shown in appendix \(C\). The change of page routines were written in ' \(C\) '
with the first part an example of using in-line code and the second part calling a function. The short example shows the assembly code on the left, generated by the ' C ' code on the right. This is very similar to the assembly code example in appendix B and so it is possible to extend the memory addressing beyond 64 K bytes with the ' C ' language just as with assembly language.

\section*{Interrupt conditions}

The interrupt routines have normal latency when they reside in the main 48 K bytes page since this is always visible to the CPU. The 25 cycle delay for changing pages may cause problems for interrupt routines in a paged area of memory.

\section*{Important conditions}

There are few special conditions for this method. The vectors must point to the main page of memory where the page changing routine must also reside. Routines in a paged area can only move to another page via the main 48 K page unless the technique in method Ais utilised (i.e. page change routine duplicated at identical addresses in both pages).

As with method A, the RAM and registers, and internal EEPROM if available and enabled, will all appear in the memory map in preference to external memory so care must be taken to avoid these addresses or move the RAM or registers away to different addresses.

The assembler generates 5 blocks of code with identical address ranges used by the user code plus the main 48 K byte section. This could not be programmed directly into an EPROM since the second and subsequent pages would simply attempt to overwrite the first page. The code must therefore be splitinto blocks and programmed into the correct part of the EPROM. Some linkers may be capable of performing this function automatically.

Figure 6 illustrates the expansion of the pages into a single 128 K byte EPROM memory.

\section*{Customisation}

Clearly the size of the paged areas may be made to suit the application with for example a 32 K byte main page and three 32 K bytes of paged memory simply by not implementing control over the A14 address of the EPROM and not including Port \(D(3)\) control. Similarly by adding another port line to control address A13, the main program can be 56 K bytes with 9 pages of 8 K bytes each.


Figure 5. Illustration of changing from Page 0 to Page 1


Figure 6. Hardware and software paging representation


Figure 7. Comparison of paging schemes

\section*{IN GENERAL}

In both methods, the registers may be moved to more appropriate addresses. If the usage of RAM is not critical the registers may be moved to address \(\$ 0000\) by writing \(\$ 00\) to the INIT register immediately after reset. For the MC68HC11G5 this means losing 128 bytes of RAM but results in a clean memory map above \(\$ 1 \mathrm{FF}\). In the examples, the registers and RAM remain at the default addresses and so care must be taken not to have user code from address \(\$ 0000\) to \(\$ 01 \mathrm{FF}\) and \(\$ 1000\) to \(\$ 107 \mathrm{~F}\) for the MC68HC11G5. Note that the MC68HC11E9 and MC68HC11A8 have slightly different RAM and register address ranges plus the internal EEPROM which should be disabled if not used.

Figure 7 demonstrates the differences between the paging techniques by showing the overlap of the pages. The number and size of the pages can easily be modified by small changes to the page change routines and hardware.

\section*{Beyond 128K bytes}

Both techniques may be scaled up with several port lines controlling address lines beyond address 115 with the addition of further change page routines and enhancing the return from interrupt routine to allow a return to a specific page in method \(A\) or the addition of further multiplexing logic in method B.

\section*{IN CONCLUSION}

The two methods described in detail are the basis for many other ways of controlling paging on a single large EPROM memory device or several smaller EPROMs. It is a simple matter to scale up or modify the techniques to suit a particular application or EPROM. The software approach is the cheapest and allows for a main program of up to the full size of the EPROM while the combined hardware and software approach has a maximum main program size of 48 K bytes (in this example) and no additional interrupt latency.

\section*{APPENDIX A - SOFTWARE PAGING SCHEME}




\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 260 & & & * & & \multicolumn{2}{|l|}{cycles} \\
\hline 261 & 0000f80a & & \multicolumn{4}{|l|}{RETRTI1} \\
\hline 262 & 0000f80a & 9600 & LDAA & PAGE & 2 & get page the interrupt occured in \\
\hline 263 & 0000f80c & 8100 & CMPA & * 0 & 2 & is it page 0 \\
\hline 264 & 0000f80e & 2701 & BEQ & RTIPAGE 1 & 3 & if yes then change page \\
\hline 265 & 0000 f 810 & 3b & RTI & & 12 & otherwise, return from interrupt \\
\hline 266 & \(0000 \mathrm{f811}\) & & \multicolumn{4}{|l|}{RTIPAGE1 1} \\
\hline 267 & \(0000 \mathrm{f811}\) & 181d0820 & BCLR & PORTD, Y, \#NPAGE & 8 & change page and return from interrupt \\
\hline 268 & 0000 f 815 & 3b & RTI & & 12 & This codes is the same in both pages \\
\hline 269 & & & * & & & \\
\hline 270 & & & & & & \\
\hline 271 & & & \multicolumn{4}{|l|}{} \\
\hline 272 & & & \multicolumn{4}{|l|}{* VECTORS} \\
\hline 273 & & & \multicolumn{4}{|r|}{***********************************************************} \\
\hline 274 & & & \multicolumn{4}{|l|}{*} \\
\hline 275 & & & ORG & VECTORS & & \\
\hline 276 & 0000ffcc & 0200 & FDB & RESET & & EVENT 2 \\
\hline 277 & 0000ffce & 0200 & FDB & RESET & & EVENT 1 \\
\hline 278 & 0000 ffdo & 0200 & FDB & RESET & & TIMER OVERELOW 2 \\
\hline 279 & 0000 ffd 2 & 0200 & FDB & RESET & & INPUT CAPTURE \(6 /\) OUTPUT COMPARE 7 \\
\hline 280 & 0000 ffd 4 & 0200 & FDB & RESET & & INPUT CAPTURE \(5 /\) OUTPUT COMPARE 6 \\
\hline 281 & 0000ffd 6 & 0200 & FDB & RESET & & SCI \\
\hline 282 & \(0000 \mathrm{ffd8}\) & 0200 & FDB & RESET & & SPI \\
\hline 283 & 0000 ffda & 0200 & FDB & RESET & & PULSE ACC INPUT \\
\hline 284 & 0000 ffdc & 0200 & FDB & RESET & & PULSE ACC OVERFLOW \\
\hline 285 & 0000ffde & 0200 & FDB & RESET & & TIMER OVERFLOW 1 \\
\hline 286 & \(0000 f f e 0\) & 0200 & FDB & RESET & & INPUT CAPTURE \(4 /\) OUTPUT COMPARE 5 \\
\hline 287 & 0000 ffe 2 & 0200 & FDB & RESET & & OUTPUT COMPARE 4 \\
\hline 288 & \(0000 f f e 4\) & 0200 & FDB & RESET & & OUTPUT COMPARE 3 \\
\hline 289 & 0000ffe 6 & 0200 & FDB & RESET & & OUTPUT COMPARE 2 \\
\hline 290 & 0000ffe8 & 0200 & FDB & RESET & & OUTPUT COMPARE 1 \\
\hline 291 & 0000ffea & 0200 & FDB & RESET & & INPUT CAPTURE 3 \\
\hline 292 & 0000 ffec & 0200 & FDB & RESET & & INPUT CAPTURE 2 \\
\hline 293 & 0000ffee & 0200 & FDB & RESET & & INPUT CAPTURE 1 \\
\hline 294 & \(0000 f f f 0\) & 0235 & FDB & INTRTI & & REAL TIME INTRRUPT \\
\hline 295 & 0000 fff 2 & 0200 & FDB & RESET & & IRQ \\
\hline 296 & 0000 fff 4 & 0200 & FDB & RESET & & XIRQ \\
\hline 297 & 0000 fff 6 & 0200 & FDB & RESET & & SWI \\
\hline 298 & \(0000 \mathrm{fff8}\) & 0200 & FDB & RESET & & ILLEGAL OPCODE \\
\hline 299 & 0000 fffa & 0200 & FDB & RESET & & COP \\
\hline 300 & 0000 fffc & 0200 & FDB & RESET & & CLOCK MONITOR \\
\hline 301 & 0000 fffe & 0200 & FDB & RESET & & RESET \\
\hline 302 & & & ******** & *********** & ** & ************************************ \\
\hline 303 & & & END & & & \\
\hline
\end{tabular}


\section*{(Continued overleaf)}

\begin{tabular}{|c|c|c|c|c|c|}
\hline 81 & & \multicolumn{4}{|l|}{*} \\
\hline 82 & 00000000 & PORTA & EQU & \$00 & \\
\hline 83 & 00000001 & DDRA & EQU & \$01 & 68HC11GS only \\
\hline 84 & 00000004 & PORTB & EQU & \$04 & \\
\hline 85 & 00000006 & PORTC & EQU & \$06 & \\
\hline 86 & 00000007 & DDRC & EQU & \$07 & \\
\hline 87 & 00000008 & PORTD & EQU & \$08 & \\
\hline 88 & 00000009 & DDRD & EQU & \$09 & \\
\hline 89 & 00000024 & TMSK2 & EQU & \$24 & \\
\hline 90 & 00000025 & TFLG2 & EQU & \$25 & \\
\hline 91 & 00000040 & RTII & EQU & \$40 & \\
\hline 92 & 00000040 & RTIF & EQU & \$40 & \\
\hline 93 & 00000026 & PACTL & EQU & \$26 & \\
\hline 94 & 00000080 & DDRA 7 & EQU & \$80 & 68HC11E9 only \\
\hline 95 & 00001000 & REGS & EQU & \$1000 & \\
\hline 96 & & \multicolumn{4}{|l|}{*} \\
\hline 97 & & \multicolumn{4}{|l|}{*************************************************************************} \\
\hline 98 & & \multicolumn{4}{|l|}{*} \\
\hline 99 & & \multicolumn{4}{|l|}{RAM definitions} \\
\hline 100 & & \multicolumn{4}{|l|}{} \\
\hline 101 & & \multicolumn{3}{|l|}{*******************************} & **************************************** \\
\hline 102 & & \[
\mathrm{OF}
\] & \[
\$ 000
\] & & \\
\hline 103 & 00000000 & \multirow[t]{2}{*}{* IME} & RMB & 2 & Real time intersup routine counter \\
\hline 104 & & & & & \\
\hline 105 & 00000200 & ROMBASEO & EQU & \$0200 & Avoid RAM (from S\% to \$1FF) \\
\hline 106 & 00004000 & ROMBASE 1 & EQU & \$4000 & \\
\hline 107 & 0000 ffcc & VECTORS & EQU & \$FFCC & \\
\hline 108 & & \multicolumn{4}{|l|}{*} \\
\hline 109 & & \multicolumn{4}{|l|}{***************************************************************************} \\
\hline 110 & & * & \multicolumn{2}{|l|}{PAGE \(0=\$ 00000-\$ 03 \mathrm{FFF}\)} & ( \(\mathrm{A} 16=0, \mathrm{~A} 15=0, \mathrm{~A} 14=0\) ) \(\Rightarrow\) PACEC \(=800100000\) \\
\hline 111 & & \multirow[b]{2}{*}{*} & MAIN & \$04000 - \$ OFFFF & \((\mathrm{A} 16=0) \quad \Rightarrow\) START \(=8001 \times \times 000\) \\
\hline 112 & & & PAGE 1 & \$10000 - \$13FFF & \((\mathrm{Al} 6=1, \mathrm{Al5}=0, \mathrm{Al} 4=0) \Rightarrow\) PAGE1 \(=800000000\) \\
\hline 113 & & * & PAGE 2 & \$14000 - \$17FFF & \((\mathrm{A} 16=1, \mathrm{~A} 15=0, \mathrm{~A} 14=-\quad \Rightarrow\) PAGE \(2=\% 00001000\) \\
\hline 114 & & * & \multicolumn{2}{|l|}{* PAGE \(3=\$ 18000-\$ 1 \mathrm{BFFF}\)} & \((\mathrm{A} 16=1, \mathrm{~A} 15=1, \mathrm{~A} 14=0\) ) \(\Rightarrow\) PAGE \(3=\% 00010000\) \\
\hline 115 & & \multicolumn{3}{|l|}{* PAGE \(4=\$ 1 \mathrm{C} 000-\$ 1 \mathrm{FFFF}\)} & \((\mathrm{A} 16=1, \mathrm{~A} 15=1, \mathrm{Al4}=2\) ? \(\Rightarrow\) PAGE \(4=800011000\) \\
\hline 116 & & \multicolumn{4}{|l|}{*} \\
\hline 117 & & * & \multicolumn{3}{|l|}{PAGEn is added to \(\% \times \times 000 \times \times x\) to give the state of port} \\
\hline 118 & & * & \multicolumn{2}{|l|}{\(D(3), D(4)\) and \(D(5)\).} & \\
\hline 119 & & \multicolumn{4}{|l|}{*} \\
\hline 120 & 00000000 & \multicolumn{2}{|l|}{START EQU} & \multicolumn{2}{|l|}{\$00} \\
\hline 121 & 00000020 & \multicolumn{2}{|l|}{PAGEO EQU} & \multicolumn{2}{|l|}{\$20} \\
\hline 122 & 00000000 & \multicolumn{2}{|l|}{PAGE1 EQU} & \multicolumn{2}{|l|}{\$00} \\
\hline 123 & 00000008 & \multicolumn{2}{|l|}{PAGE2 EQU} & \multicolumn{2}{|l|}{\$08} \\
\hline 124 & 00000010 & \multicolumn{2}{|l|}{PAGE3 EQU} & \multicolumn{2}{|l|}{\$10} \\
\hline 125 & 00000018 & \multicolumn{2}{|l|}{PAGE4 EQU} & \multicolumn{2}{|l|}{\$18} \\
\hline 126 & & \multicolumn{4}{|l|}{*} \\
\hline 127 & & ******* & & *************** & **************************************** \\
\hline
\end{tabular}



\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 284 & 0000ffe8 & 4000 & & FDB & RESET & OUTPUT COMPARE 1 \\
\hline 285 & 0000ffea & 4000 & & FDB & RESET & INPUT CAPTURE 3 \\
\hline 286 & 0000 ffec & 4000 & & FDB & RESET & INPUT CAPTURE 2 \\
\hline 287 & 0000ffee & 4000 & & FDB & RESET & INPUT CAPTURE 1 \\
\hline 288 & \(0000 \mathrm{fff0}\) & 4052 & & FDB & RTISRV & REAL TIME INTRRUPT \\
\hline 289 & 0000fff 2 & 4000 & & FDB & RESET & IRQ \\
\hline 290 & 0000fff 4 & 4000 & & FDB & RESET & XIRQ \\
\hline 291 & 0000fff6 & 4000 & & FDB & RESET & SWI \\
\hline 292 & 0000fff8 & 4000 & & FDB & RESET & ILLEGAL OPCODE \\
\hline 293 & 0000fffa & 4000 & & FDB & RESET & COP \\
\hline 294 & 0000fffc & 4000 & & FDB & RESET & CLOCK MONITOR \\
\hline 295 & 0000 fffe & 4000 & & FDB & RESET & RESET \\
\hline 296 & & & * & & & \\
\hline 297 & & & \multicolumn{4}{|l|}{} \\
\hline 298 & & & \multicolumn{4}{|l|}{* +++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++} \\
\hline 299 & & & * & & & \\
\hline 300 & & & \multicolumn{4}{|l|}{* page 1 (2nd half of EPROM)} \\
\hline 301 & & & \multicolumn{4}{|l|}{*} \\
\hline 302 & & & \multicolumn{4}{|l|}{*} \\
\hline 303 & & & \multicolumn{4}{|l|}{} \\
\hline 304 & & & & org & ROMBASE0 & \\
\hline 305 & 00000200 & 181c0010 & \multirow[t]{2}{*}{LOOPP 1} & BSET & \multicolumn{2}{|l|}{PORTA, Y, \#\$10} \\
\hline 306 & 00000204 & 181d0010 & & BCLR & PORTA, Y, \#\$10 & Toggle Port A-4 \\
\hline 307 & 00000208 & 39 & & RTS & & \\
\hline 308 & & & \multicolumn{4}{|l|}{* +++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++} \\
\hline 309 & & & * & & & \\
\hline 310 & & & & \multicolumn{3}{|l|}{page 2 (2nd half of EPROM)} \\
\hline 311 & & & \multicolumn{4}{|l|}{*} \\
\hline 312 & & & \multicolumn{4}{|l|}{*} \\
\hline 313 & & & \multicolumn{4}{|l|}{} \\
\hline 314 & & & & org & ROMBASE0 & \\
\hline 315 & 00000200 & 181c0020 & \multirow[t]{2}{*}{LOOPP 2} & BSET & \multicolumn{2}{|l|}{PORTA, Y, \#\$20} \\
\hline 316 & 00000204 & 181 d 0020 & & BCLR & PORTA, Y, \#\$20 & Toggle Port A-5 \\
\hline 317 & 00000208 & 39 & & RTS & & \\
\hline 318 & & & \multicolumn{4}{|l|}{*+++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++} \\
\hline 319 & & & \multicolumn{4}{|l|}{*} \\
\hline 320 & & & \multicolumn{4}{|l|}{* page 3 (2nd half of EPROM)} \\
\hline 321 & & & \multicolumn{4}{|l|}{*} \\
\hline 322 & & & \multicolumn{4}{|l|}{*} \\
\hline 323 & & & \multicolumn{4}{|l|}{* +++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++} \\
\hline 324 & & & & org & \multicolumn{2}{|l|}{ROMBASEO} \\
\hline 325 & 00000200 & 181c0040 & \multirow[t]{3}{*}{LOOPP 3} & BSET & PORTA, Y, \#\$40 & \\
\hline 326 & 00000204 & 181d0040 & & BCLR & PORTA, Y, \#\$40 & Toggle Port A-6 \\
\hline 327 & 00000208 & 7 e 4026 & & JMP & MAIN3 & return to main page \\
\hline 328 & & & \multicolumn{4}{|l|}{* +++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++++} \\
\hline 329 & & & \multicolumn{4}{|l|}{* \({ }^{\text {a }}\)} \\
\hline 330 & & & \multicolumn{4}{|l|}{* page 4 (2nd half of EPROM)} \\
\hline 331 & & & \multicolumn{4}{|l|}{*} \\
\hline 332 & & & \multicolumn{4}{|l|}{*} \\
\hline 333 & & & \multicolumn{4}{|l|}{} \\
\hline 334 & & & & org & \multicolumn{2}{|l|}{ROMBASEO} \\
\hline 335 & 00000200 & 181c0080 & \multirow[t]{2}{*}{LOOPP 4} & BSET & PORTA, Y, \#\$80 & \\
\hline 336 & 00000204 & 181 d 0080 & & BCLR & PORTA, Y, \#\$80 & Toggle Port A-7 \\
\hline 337 & 00000208 & 7e402c & & JMP & MAIN4 & return to main page \\
\hline 338 & & & ******* & ***** & *************** & ************************************* \\
\hline 339 & & & & END & & \\
\hline
\end{tabular}

\section*{APPENDIX C - 'C' LANGUAGE ROUTINES FOR METHOD B}
```

* /* CHGPAGE.C
* C coded extended memory control for 68HCll
* 
* */
* 

*********************************************************************************
/* HC1l structure - I/O registers for MC68HC11 */
struct HC11IO {
unsigned char PORTA; /* Port A - 3 input only, 5 output only */
unsigned char Reserved; /* Motorola's unknown register */
unsigned char PIOC: /* Parallel I/O control */
unsigned char PORTC; /* Port C */
unsigned char PORTB; /* Port B - Output only */
unsigned char PORTCL; /* Alternate port C latch */
unsigned char Reservedl; /* Motorola's unknown register 2 */
unsigned char DDRC; /* Data direction for port C */
unsigned char PORTD; /* Port D */
unsigned char DDRD; /* Data direction for port D */
unsigned char PORTE; /* Port E */
};
/* End of structure HCllIO */
*******************************************************************************
*

* \#define regbase (*(struct HC11IO *) 0x1000)
* typedef unsigned char byte;
* 
* /* Some arbitrary user defined values */
* \#define page0 0x20
* \#define pagel 0x00
* \#define page2 0x08
* \#define pagemask 0xc7
* /* Macro to generate in line code */
* \#define chgpage(a) regbase.PORTD = (regbase.PORTD \& pagemask) + a
* 
* /* Function prototype */
* void func_chgpage (byte p);
* 

**

* /* Externally defined functions in separate pages */
* extern void func_in_page0(); /* Dummy function in page 0 */
* extern void func_in_page2(): /* Dummy function in page 2 */

```
**
\begin{tabular}{|c|c|c|c|c|c|}
\hline 6 & 0000 & & main: fbegin & & main() \\
\hline \multicolumn{5}{|l|}{*} & \[
\mathfrak{i}
\] \\
\hline \multicolumn{5}{|l|}{*} & \multirow[t]{2}{*}{/* Change page using inline code */} \\
\hline & & & & & \\
\hline 8 & 0000 & f61008 & ldab & \$1008 & \\
\hline 9 & 0003 & c4c7 & andb & \#199 & \\
\hline 10 & 0005 & cb08 & addb & \#8 & \\
\hline 11 & 0007 & f71008 & stab & \$1008 & \\
\hline \multirow[t]{2}{*}{*} & & & & & func_in_page 2 (); \\
\hline & & & & & /* Call function in page 2 */ \\
\hline 13 & 000a & >bd0000 & jsr & func_in_page2 & \\
\hline \multicolumn{6}{|l|}{*} \\
\hline \multirow[t]{2}{*}{*} & & & & & func_chgpage (page 0 ) : \\
\hline & & & & & /* Change page using function call */ \\
\hline 15 & 000d & cc0020 & ldd & \#32 & \\
\hline 16 & 0010 & 8 d 04 & bsr & func_chgpage & \\
\hline \multirow[t]{2}{*}{*} & & & & & func_in_page0 (); \\
\hline & & & & & /* Call function in page 0 */ \\
\hline 18 & 0012 & >bd0000 & jsr & func_in_page 0 & \\
\hline * & & & & & ) \\
\hline 20 & 0015 & 39 & rts & & \\
\hline 21 & 0016 & & fend & & \\
\hline \multicolumn{6}{|l|}{*} \\
\hline & & & & & void func_chgpage (p) \\
\hline \multicolumn{5}{|l|}{*} & byte p ; \\
\hline 24 & 0016 & & \multicolumn{2}{|l|}{func_chgpage: fbegin} & \\
\hline 25 & 0016 & 37 & pstb & & \\
\hline \multicolumn{5}{|l|}{*} & \{ \\
\hline \multicolumn{5}{|l|}{*} & chgpage (p) ; \\
\hline 27 & 0017 & f61008 & ldab & \$1008 & \\
\hline 28 & 001a & c4c7 & andb & \#199 & \\
\hline 29 & 001c & 30 & tsx & & \\
\hline 30 & 001d & eb00 & addb & \(0, \mathrm{x}\) & \\
\hline 31 & 001 f & f71008 & stab & \$1008 & \\
\hline \multicolumn{5}{|l|}{*} & \} \\
\hline 33 & 0022 & 31 & ins & & \\
\hline 34 & 0023 & 39 & rts & & \\
\hline 35 & 0024 & & fend & & \\
\hline 36 & & & import func & _page2 & \\
\hline 37 & & & import func_ & _page0 & \\
\hline 38 & & & end & & \\
\hline
\end{tabular}

\title{
TV on-screen display using the MC68HC05T1
}

\author{
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}

\section*{INTRODUCTION}

The " \(T\) " members of the MC68HC05 family of MCUs provide a convenient and cost effective method of adding on-screendisplay (OSD) to TVs andVCRs. As well as the OSD capability, they include 8 Kbytes of ROM (adequate for Teletext, frequency-synthesis, stereo and OSD), 320 bytes of RAM, a 16 -bit timer and 8 pulse-width-modulated D/A converters. The MC68HC(7)05T7/8 also includes IIC hardware and, by using a 56/64 pin package, 4 ports of I/O independent of the OSD, serial and D/A outputs. It is thus suitable for large full-
feature chassis. The MC68HC05T1 is in the middle of the price/performance range and includes most of the features of the MC68HC05T8 but in a 40-pin package. This is achieved by sharing \(/ / O\) with the other pin functions (SPI, OSD, D/A) Even if all these features are used there is sufficient I/O for most applications. The low cost MC68HC05T4 has 5 Kbytes of ROM and 96 bytes of RAM making it suitable for simpler (mono, non-Teletext) applications.

\section*{68HC05T1 OSD FEATURES}
- Programmable display of 10 rows of 18 characters
- 24 byte ( 18 data +6 control) single row architecture
- Settable in software to any one of four standards
- Zero inter-row and inter-column spacing
- 64 user-defined mask-programmable \(8 \times 13\) characters
- Programmable horizontal position
- Character colour selectable from 4 colours/row
- Software programmable (start, stop and colour) wirdow
- 4 character sizes (normal, double height and/or width)
- Half-dot character rounding
- Selectable half-dot black outline.

\section*{OSD CHARACTERISTICS}

The HC05TX series have an OSD capability of 10 rows of 18 characters. Each row can contain characters of four colours selected from the eight available colours (black, blue, green, cyan, red, magenta, yellow and white). The rows can independently select double height and/or double width and the start and stop positions of a background window of any colour. The signals sent to the TV are Red, Green, Blue, fastblanking and half-tone. Separate horizontal and vertical synchronisation inputs are required.

The OSD architecture employed includes only a single line of display RAM. This makes the software more complicated but reduces the silicon area required to implement the OSD function. The software is required to update the display RAM on a regular basis. When operating in the 625 -line PAL standard the updates must occur at 1.66 ms ( 26 lines) intervals in order to display adjacent lines. The OSD hardware can generate an interrupt when an update is required. There
are 18 data registers (one for each character) and 6 control registers arranged as shown below. The table is for the T1. some of the control bits are different in the T4/7/8.

\section*{\$20-\$31 OSD Data registers.}
\(\$ 32\) CAS Read: status, Write: colours \(1 \& 2\) and outline enable.
\(\$ 33\) C34 Colours 3 \& 4
\$34 RAD Row address, character size, int. enable, RGB invert.
\(\$ 35\) WCR OSD \& PLL enable, Window enable and start column.
\$36 CCP Window colour and end column
\(\$ 37\) HPD Horizontal position, standard selection.

The OSD display is timed from an on-chip 14 MHz oscillator which is phase locked to the TV's line synchronisation pulses. The vertical synchronisation depends on the standard in use. Four standards are available \((15.75 \mathrm{kHz} / 60 \mathrm{~Hz}, 31.5 \mathrm{kHz} / 120\) \(\mathrm{Hz}, 15.625 \mathrm{kHz} / 50 \mathrm{~Hz}\) and \(31.25 \mathrm{kHz} / 100 \mathrm{~Hz}\) ). The standard is selected by control bits in the \(\mathrm{T} 1 / 2\) but is automatic in the T 4 and the \(77 / 8\).

64 OSD characters are mask programmed along with the user ROM. The spacing and full size of the characters is the same at
\(8 \times 13\) (for 625 -line standard). This allows continuous graphics Half-dot interpolation hardware doubles the apparent resolution to produce smoother characters. A software selectable black outline (a half-dot wide) is also implemented in the hardware. Because the half-dot circuitry has to know the information for the next line of pixels, a 14 th line is available in the character generator ROM to facilitate look ahead. The vertical height of a character is 26 lines ( 52 including interlace) and the horizontal width is \(22 / 7 \mu \mathrm{~s}(1 / 7 \mu\) s per half pixel).

\section*{SOFTWARE}

There are several approaches to writing OSD software to operate with the single line architecture. The choice will affect the amount of ROM and RAM used. One principle is to have a separate interrupt routine for each type of row to be displayed. This method will use little RAM but will be inefficient in its use of ROM. The other approach is to write a single interrupt routine which transfers display information from a block of normal RAM to the display RAM as it is required for each new line. This method will be more ROM efficient but requires a RAM location for every display character. The amount of RAM used depends on the maximumamount of data which has to be displayed at any one time. The choice between these two methods will depend on the type of data to be displayed. The first method may be better if much of the displayed data is fixed. This could be, for example, a series of menus. The second method will however be more appropriate if the data is mostly variable. This will usually be the case in conventional TV applications.

This application note describes an implementation of the second of the above approaches. A block of RAM is used to contain a copy of all the data to be displayed. The size of this block can be changed to reflect the number of rows and the number of characters per row. The choice made in the example described here is 8 rows of 16 characters. This is slightly less
than the maximum available and was chosen because the total number of characters (128) corresponds to the available page 1 RAM in the MC68HC05T1. The choice of 16 characters per row also slightly simplifies the software. The software allows any eight of the ten available rows to be used but only the first 16 of the 18 available characters. This choice does not prevent access to the right-hand-side of the screen as the display can be moved to the right under software control. The use of page 1 for the RAM does not incur any significant compromise in execution time. It also leaves free the page 0 RAM for the rest of the TV control software, which would be made less efficient if it had to use page 1 RAM, where direct addressing and bit manipulation instructions cannot be used. This choice slightly increases the ROM used by the OSD code, as 3-byte extended store instructions sometimes need to be used to write data to the RAM used for OSD characters.

The 1-byte indexed addressing mode can however be used in page 1 . This addressing mode can access up to address \$1FE and is made use of in the example software. For example the OSDCLR routine used to initialise RAM locations used for OSD employs a CLR DRAM-1, X instruction. DRAM is the start of page 1 RAM at \(\$ 100\) so DRAM-1 evaluates as \$FF a 1-byte offset.

\section*{INTERRUPT ROUTINE}

The OSD update interrupt routine (NLINE) shown in the programlisting transfers data frompage 1 RAM to display RAM each time an interrupt occurs. The first operation is to increment the pointer which selects the next row number. This pointer (OSDL) is subsequently used to transfer the appropriate data from page 1 RAM to the OSD RAM. So that any row number can be used the pointer selects the number from a table unique to each type of display. The appropriate table is determined by the value of LIND. The pointer is incremented until the corresponding row number is zero when the pointer is reset to zero. This allows any sub-set of up to 8 of the 10 available rows to be used. The next row number (ORed with the character size information contained in RAM) is written into the appropriate register ( \(\$ 34\) ). The row number in this register is compared by the OSD hardware with the current position of the raster. When they match, an interrupt is generated and the next interrupt routine is performed. The other control registers are then updated from the page 0 RAM locations, which are used for this purpose.

To save RAM only three (RAD, CAS _\& CCR) of the six control registers are loaded in this way. The pointer OSDL is multiplied by 3 using the table M3, as this is quicker than shifting and adding. In this example the other registers are loaded by the main program and therefore have fixed values for each display. The fixed registers are Colour \(3 / 4(\$ 33)\), Window enable/start column \((\$ 35)\) and Horizontal position delay \((\$ 37)\). As this choice would not allow windows to be enabled on individual rows, window enable is controlled by the un-used bit (6) in the RAM byte used to update the Colour \(1 / 2\) register (CAS). This choice of fixed registers limits the flexibility of the display but clearly all registers can be updated on a line-by-line basis if more RAM is used. The limitations imposed by this choice are that colours 3 \& 4, the window start column and the horizontal position apply to a whole display rather than to individual lines. In practice these constraints were not found to be significant restrictions for the displays required for TV use.

The interrupt routine then transfers the relevant OSD data from page 1 RAM into the OSD data registers. This is done using linear, repetitive code in order to minimise the time taken by the interrupt routine. The code used uses 8 cycles ( \(4 \mu \mathrm{~s}\) ) for each byte transferred. Less ROM space would be utilised if a loop was employed but this would use 28 cycles per byte. The best choice depends on whether time or ROM use is more critical. The example code includes a cycle count to calculate the length of the interrupt routine. The time taken is \(121 \pm 4 \mu \mathrm{~s}\). This includes the time taken by the interrupt itself. An alternative method of OSD data transfer (TOSD2) using a loop is
included as comments in the listing. It would take an additional \(165 \mu \mathrm{~s}\).

The last task performed by the interrupt routine is to control any character or window flashing. The software allows one or two characters (ona selected row) and one vindow (on the same or a different row) to be flashed at a rate determined by the MCU's timer. This function could be performed outwith the interrupt routine in the main program and the time taken to perform it is not included in the figure given above

\section*{MAIN OSD PROGRAM}

The remainder of the OSD control program does not write directly to most of the display registers. It simply puts the required display and control information into the blocks of RAM allocated for this purpose, together with supplying the coordinates of any required flashing characters or windows. It must, however, write to the display control registers not updated by the interrupt routine; in this example these are \(\$ 33\), \(\$ 35\) and \(\$ 37\). The program has 4 main parts. These are the idle, channel name table, program/channel number and analogue displays. The idle display applies when no transient display (eg program number and channel number or name) is on. The OSD idle condition is selectable between blank and a small program number at the bottom right hand corner of the screen.

The OSD example program (assembler listing included) is just part of the code required to control a TV set. This program was incorporated in HC05T1 software along with four other modules. These were the base module (idle loop, transient control, local keyboard, IR, IIC and reset), the tuning module (PLL, analogue and NVM control), the stereo module (stereoton and Nicam) and the Teletext module (FLOF level 1.5).

The microprocessor in a TV application will usually need to handle the reception of IR commands. Polled methods of IR reception are most effective if the time made unavailable to them by interrupts is minimised. It is for this reason that the illustrated OSD interrupt routine was written to execute as fast as possible. This is, however, not so much of a problem if the TCAP facility is used for \(\mathbb{R}\) reception. When a falling edge occurs, the timer value is saved and it does not matter if the interrupt which processes this information is not serviced until several hundred microseconds later. The allowable size of this delay will of course depend on the IR protocol in use. The biphase protocol used with the example OSD software transmitter chip: MC144105) has a minimum spacing of 1 ms between consecutive edges.

The next section describes the OSD features of this software. Some of the data used in the OSD is passed from other modules (particularly the tuning module) The same RAM allocation file was used in all modules so this part of the listing shows the locations used to pass data between them.

\section*{OSD FEATURES PROVIDED IN THE EXAMPLE PROGRAM}

\section*{Program change}

When keys 0-9, PC- or PC+ are pressed, the new program number appears (in cyan) at the bottom-right-hand corner of the screen in double height/double width characters and stays for 5 seconds after the last change. Above this display either the channel name (if one has been defined) or the channel number is shown (normal size). After 5 seconds this display times out and there is either no display or a permanent normal size program number display. This is selectable using the Teletext MIX key.

For program numbers of 10 and over, three keys are required. They are selected by first pressing "-". Two flashing dashes are displayed, the first \(0-9\) key (only \(0-4\) valid) will be taken as the tens digit and the second as the units digit. If a newprogram number has not been selected within 30 seconds, the TV returns to the previous display (nothing or the old program number).

\section*{Channel mode}

When the P/Ckey is pressed, the program number and channel name (or number) is displayed for 5 seconds as an indication of the current status. If it is pressed again during this period, the TV changes to channel mode. This will remain for 30 seconds after the last key-press. The display (in yellow) shows the program number as in program mode along with the channel number. The channel number flashes to show that it will be changed if a number or PC- or PC+ key is pressed. New channels can be selected. If the STORE key is pressed then the current channel is stored against the current program number. If no key is pressed for 30 seconds, the TV returns to program mode. If the channel has been changed but STORE not pressed then the TV will retune back to the channel stored against the current program number.

\section*{Automatic search}

When SEARCH is pressed the TV goes into the channel mode and the on screen display is as described above. The channel number is incremented at a rate of 2 per second until a signal is found. The search then stops. A press of STORE returns the TV to program mode, storing the new channel against the current program number.

\section*{Analogues}

When any of the analogues are selected the appropriate logo is displayed along with a horizontal bar indicating the current value in the D/A convertor (full-scale 63). Display returns to default (nothing or program number) 5 seconds after the last change. If no analogue is selected the volume is shown (and adjusted) when the ANALOGUE +/-keys are used.

\section*{Channel name table}

Up to 24 channels can have a 4 character name and standard bit associated with them. If the channel number and standard of one of these entries in the table correspond to those selected by the current program number then the name is displayed along with the program number when the program is selected or when P/C is pressed. Entry of names is done using the Teletext INDEXkey When itis pressed a table of six
lines is displayed. Each line (identified by a "station" number in the leftmost column) contains a channel number, standard and the associated name. All of this data is user definable.

One character on the screen flashes to indicate the current position of the cursor. The character at the cursor position can be changed through 0-9, A-Z and space by pressing PC+ or PC- (0-9 for channel number digits and PAL/SECAM for standard). When a character (or the standard) is changed, its colour changes fromyellow to red. The cursoris moved to the leftand right by the Teletext RED and GREEN keys and up and down by the BLUE and YELLOW keys. The current line appears in a light blue (cyan) window as opposed to the dark blue window used for the other lines. The whole table scrolls when the cursor is required to go beyond the bottom (or top) of the current display.

To save a name the STORE key is pressed. This will save the name and standard on the current line against its channel number. This is indicated by the colour of any changed characters returning to yellow. Any changes which have been made to lines other than the one being stored are lost. Channel 00 cannot have a name. The procedure for removing a name from the table is to set the channel number to zero and then to save the line. Any name left on the line will not be used. The table display is exited by pressing the Teletext INDEX key. The function of each key is shown at the bottom of the display.

2300000000
230000001
2300000002
2300000003
2300000004
2300000005
2300000005
2300000006
2300000007
2300000008
2300000009
23 0000000a
0000000 b
0000000c
0000000d
0000000 e
\(0000000 f\)
00000010
00000011
00000012
00000013
00000014
00000015
00000016
00000017
00000020
00000027
0000002a
0000002d
00000030
00000033
00000036
00000039
0000003a
0000003 e
\(0000003 f\)
00000040
00000041
00000042
00000046
23
3
23
23
23
23
23
00000047 00000048


IMPORT CHEX, CBCD, READ, WRITE, CDISP2
EXPORT NLINE, PCOSD, DRAM, ANOSD, PRDSP, CHST
EXPORT CUP, CDWN, CLFT, CRGT, PLUS, MINUS, SAVE, OSDLE, OSDEF
LIB RAMTI.SO5
SECTION.S .RAM, COMM

\begin{tabular}{|c|c|c|c|}
\hline SUB1 & RMB & 1 & \\
\hline R1 & RMB & 1 & mode register \\
\hline R2 & RMB & 1 & page request address register \\
\hline R3 & RMB & 1 & page req. data reg. col. 0 : mag. \\
\hline C1 & RMB & 1 & " " " " 1 : pgt. \\
\hline C2 & RMB & 1 & 2 : pgu. \\
\hline C3 & RMB & 1 & 3 : ht. \\
\hline C4 & RMB & 1 & hu. \\
\hline C5 & RMB & 1 & 5 : mt. \\
\hline C6 & RMB & 1 & 6 : mu. \\
\hline SUB2 & RMB & 1 & \\
\hline R4 & RMB & 1 & \multirow[t]{4}{*}{display chapter register display control register (normal) display control register (news/sub) display mode register} \\
\hline R5 & RMB & 1 & \\
\hline R6 & RMB & 1 & \\
\hline R7 & RMB & 1 & \\
\hline SUB3 & RMB & 1 & \\
\hline R8 & RMB & 1 & \\
\hline R9 & RMB & 1 & active row register \\
\hline R10 & RMB & 1 & active column register \\
\hline R11 & RMB & 1 & active data register \\
\hline PH & RMB & 1 & 2nd \({ }^{\text {nd }}\) \\
\hline PT & RMB & 1 & 3rd \\
\hline PU & RMB & 1 & 4 th \\
\hline LIFO & RMB & 9 & LINKED PAGE No. LIFO BUFFER \\
\hline PAGE & RMB & 7 & PAGE NO. INPUT BUFFER \\
\hline PAGO & RMB & 3 & ACO PAGE No. \\
\hline PAG1 & RMB & 3 & AC1 PAGE No. \\
\hline PAG2 & RMB & 3 & AC2 PAGE No. \\
\hline PAG3 & RMB & 3 & AC3 PAGE No. \\
\hline PAGC & RMB & 3 & CYAN PAGE NO. \\
\hline PAGI & RMB & 3 & INDEX PAGE No. \\
\hline PDP & RMB & 1 & PAGE DIGIT POINTER \\
\hline ACC & RMB & 4 & \multirow[t]{2}{*}{DISP, RED, GREEN, YELLOW AC. CIR. WORKING ACC No.} \\
\hline WACC & RMB & 1 & \\
\hline ADDR & RMB & 1 & WORKING ACC No. IIC ADDRESS \\
\hline DPNT & RMB & 1 & IIC DATA POINTER FOR WRITE \\
\hline SUBADR & RMB & 1 & IIC SUB-ADDRESS \\
\hline IOBUF & RMB & 4 & IIC BUFFER, +2 \& +3 RSRVD FOR PLL \\
\hline Stat2 & RMB & 1 & 0: ROW24 FETCH FLAG \\
\hline * & & & 1: REMOTE REPEATING \\
\hline * & & & 2: SEARCH/STANDBY IIC LOCK \\
\hline * & & & 3: STANDBY Status \\
\hline * & & & 4: UPDATE PENDING \\
\hline * & & & 5: DIFFERENCE FOUND \\
\hline * & & & 6: NO TELETEXT TRANSMISSION \\
\hline * & & & 7: MIXED \\
\hline LINKC & RMB & 1 & LINK OPTIONS \\
\hline STAT3 & RMB & 1 & 0: CYAN LINK ON \\
\hline & & & 1: YELLOW LINK ON \\
\hline * & & & 2: GREEN LINK ON \\
\hline & & & 3: LINKS/ROW24 ON \\
\hline
\end{tabular}

\begin{tabular}{|c|c|}
\hline 23 & \\
\hline 23 & 00000083 \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & 00000084 \\
\hline 23 & \\
\hline 23 & 00000085 \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & 00000086 \\
\hline 23 & 00000087 \\
\hline 23 & 00000088 \\
\hline 23 & 00000089 \\
\hline 23 & 0000008a \\
\hline 23 & 0000008b \\
\hline 23 & 0000008c \\
\hline 23 & 0000008d \\
\hline 23 & 0000008e \\
\hline 23 & 0000008f \\
\hline 23 & 00000090 \\
\hline 23 & 00000091 \\
\hline 23 & 00000092 \\
\hline 23 & 00000093 \\
\hline 23 & 00000094 \\
\hline 23 & 00000095 \\
\hline 23 & 00000096 \\
\hline 23 & 00000097 \\
\hline 23 & 00000098 \\
\hline 23 & 00000099 \\
\hline 23 & 0000009a \\
\hline 23 & 0000009b \\
\hline 23 & 0000009c \\
\hline 23 & 0000009d \\
\hline 23 & \\
\hline 23 & 0000009e \\
\hline 23 & \(0000009 f\) \\
\hline 23 & 000000a0 \\
\hline 23 & 000000al \\
\hline 23 & 000000a2 \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & 000000a3 \\
\hline 23 & 000000a4 \\
\hline 23 & \\
\hline 23 & 000000a5 \\
\hline 23 & \\
\hline 23 & 000000a6 \\
\hline 23 & \\
\hline 23 & 000000a9 \\
\hline 23 & 000000bf \\
\hline 23 & \\
\hline 23 & \\
\hline 23 & 00000000 \\
\hline 23 & 00000000 \\
\hline 23 & 00000000 \\
\hline 23 & 00000003 \\
\hline 23 & \\
\hline 23 & 0000000a \\
\hline 23 & 0000000b \\
\hline 23 & 0000000c \\
\hline 23 & 0000000d \\
\hline 23 & \\
\hline 23 & 00000005 \\
\hline 23 & 00000006 \\
\hline 23 & 00000004 \\
\hline 23 & 00000005 \\
\hline 23 & 00000006 \\
\hline 23 & 00000005 \\
\hline 23 & 00000003 \\
\hline 23 & \\
\hline 23 & 00000080 \\
\hline 23
23 & 00000019 \\
\hline
\end{tabular}



\begin{tabular}{|c|c|c|c|c|c|c|c|c|}
\hline 165 & & & \multicolumn{6}{|l|}{********************************************************} \\
\hline 166 & & & * & & & & * & \\
\hline 167 & & & & OSD id & condition. & & * & \\
\hline 168 & & & * & & & & * & \\
\hline 169 & & & \multicolumn{6}{|l|}{********************************************************} \\
\hline \multicolumn{9}{|l|}{170} \\
\hline 171 & 000000ae & \(>060004\) & OSDEF & BRSET & 3, STAT5, DOFF & & & \\
\hline 172 & 000000b1 & \(>1600\) & & BSET & 3,STAT5 & & & \\
\hline 173 & 000000b3 & 2002 & & BRA & OSDLE & & & \\
\hline \multicolumn{9}{|l|}{174} \\
\hline 175 & 000000b5 & >1700 & DOFF & BCLR & 3, STAT5 & & & \\
\hline \multicolumn{9}{|l|}{176} \\
\hline 177 & 000000b 7 & 9 b & OSDLE & SEI & & & & \\
\hline 178 & 000000b8 & >1900 & & BCLR & 4, STAT5 & NOT ANALOGS & & \\
\hline 179 & 000000ba & >1500 & & BCLR & 2,STAT5 & NOT NAME TABLE & & \\
\hline \multicolumn{9}{|l|}{180} \\
\hline 181 & 000000bc & aeld & & LDX & *29 & CLEAR PAGE 0 & & \\
\hline 182 & 000000be & >6fff & DOOP & CLR & CAS \(1-1, \mathrm{X}\) & OSD CONTROL & & \\
\hline 183 & 000000c0 & 5 a & & DECX & & BYTES & & \\
\hline 184 & 000000c1 & 26 fb & & BNE & DOOP & & & \\
\hline \multicolumn{9}{|l|}{185 .} \\
\hline 186 & 000000c3 & \(>\mathrm{cd} 0000\) & & JSR & CDISP2 & & & \\
\hline 187 & 000000c6 & 3 f 30 & & CLR & \$30 & & & \\
\hline 188 & 000000c8 & 3f31 & & CLR & \$31 & & & \\
\hline 189 & 000000ca & >06000a & & BRSET & 3,STAT5, SKPDEF & & & \\
\hline 190 & 000000cd & >c6000c & & LDA & DRAM+12 & PROGRAM NUMBER & & \\
\hline 191 & 000000d0 & b730 & & STA & \$30 & & & \\
\hline 192 & 000000d2 & >c6000e & & LDA & DRAM+14 & & & \\
\hline 193 & 000000d5 & b731 & & STA & \$31 & & & \\
\hline 194 & 000000d7 & 5 f & SKPDEF & CLRX & & & & \\
\hline 195 & 000000d8 & a67f & & LDA & *127 & & & \\
\hline 196 & 000000da & adlb & & BSR & OSDCLR & & & \\
\hline \multicolumn{9}{|l|}{197} \\
\hline 198 & 000000dc & a 620 & & LDA & \%\%00100000 & HORIZONTAL POSITION : & ZERO & \\
\hline 199 & 000000de & b737 & & STA & HPD & & & \\
\hline 200 & 000000e0 & a6a3 & & LDA & \%10100011 & COLOR 1,0 \(=\) RED, CYAN & EDGE & ON \\
\hline 201 & 000000e2 & >050002 & & BRCLR & 2, STAT4, PMD & PROGRAM MODE ? & & \\
\hline 202 & 000000e5 & a6a6 & & LDA & \%\%10100110 & NO, COLOR \(0=\) YELLOW & & \\
\hline 203 & 000000e7 & >b700 & PMD & STA & CAS1 & & & \\
\hline 204 & 000000e9 & a610 & & LDA & \%\%00010000 & SINGLE WIDTH/HIGHT & & \\
\hline 205 & 000000 eb & >b700 & & STA & RAD1 & & & \\
\hline \multicolumn{9}{|l|}{206} \\
\hline 207 & 000000ed & a60c & & LDA & \$ 50 C & DEFAULT TO VOLUME & & \\
\hline 208 & 000000ef & >b700 & & STA & ANAL & & & \\
\hline 209 & 000000 fl & >a600 & & LDA & AVOL & & & \\
\hline 210 & 000000f3 & >b700 & & STA & ANAF & & & \\
\hline 211 & 000000f5 & 9 a & & CLI & & & & \\
\hline 212 & 000000f6 & 81 & & RTS & & & & \\
\hline 213 & & & & & & & & \\
\hline 214 & 000000£7 & 4 c & OSDCLR & INCA & & & & \\
\hline 215 & 000000f8 & >b700 & & STA & W1 & & & \\
\hline 216 & 000000fa & 5 c & DCLR & INCX & & & & \\
\hline 217 & 000000 fb & >6fff & & CLR & DRAM-1, X & & & \\
\hline 218 & 000000fd & >b300 & & CPX & W1 & & & \\
\hline 219 & 000000ff & \(26 \pm 9\) & & BNE & DCLR & & & \\
\hline 220 & 00000101 & 81 & & RTS & & & & \\
\hline
\end{tabular}





\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 639 & 000003bc & a 121 & & CMP & \# \({ }^{\text {2 }}\) & A \\
\hline 640 & 000003be & 2508 & & BLO & LTA & \\
\hline 641 & 000003c0 & al3a & GTEA & CMP & - \({ }^{\text {3 }}\) A & 2 \\
\hline 642 & 000003c2 & 23 eb & & BLS & NLTO & \\
\hline 643 & 000003c4 & a63a & & LDA & \#\$3A & z \\
\hline 644 & 000003c6 & 20e7 & & BRA & NLTO & \\
\hline 645 & 000003c8 & a119 & LTA & CMP & \$\$19 & 9 \\
\hline 646 & 000003ca & 2302 & & BLS & LT9 & \\
\hline 647 & 000003cc & a 619 & & LDA & *\$19 & 9 \\
\hline 648 & 000003ce & a 110 & LT9 & CMP & - \(\$ 10\) & 0 \\
\hline 649 & 000003d0 & 24 dd & & BHS & NLTO & \\
\hline 650 & 000003d2 & 20d9 & & BRA & SPACE & \\
\hline 651 & & & & & & \\
\hline 652 & 000003d4 & >b600 & GETIT & LDA & BROW & \\
\hline 653 & 000003d6 & a002 & & SUB & \#2 & \\
\hline 654 & 000003d8 & 48 & & LSLA & & \(\times 2\) \\
\hline 655 & 000003d9 & 48 & & LSLA & & \(\times 4\) \\
\hline 656 & 000003da & 48 & & LSLA & & \(\times 8\) \\
\hline 657 & 000003 db & 48 & & LSLA & & \(\times 16\) \\
\hline 658 & 000003dc & >bb00 & & ADD & BCOL & \\
\hline 659 & 000003de & 97 & & tax & & \\
\hline 660 & 000003df & >d60000 & & LDA & DRAM, X & \\
\hline 661 & 000003e2 & 81 & & RTS & & \\
\hline 663 & & & ***** & ** & & \\
\hline 664 & & & * & & & \\
\hline 665 & & & * & Name & re. & \\
\hline 666 & & & * & & & \\
\hline 667 & & & ****** & ** & ******* & ** \\
\hline 668 & & & & & & \\
\hline 669 & 000003e3 & a6a0 & SAVE & LDA & \# \$ \(\mathbf{A O}_{0}\) & \\
\hline 670 & 000003e5 & >b700 & & STA & ADDR & \\
\hline 671 & 000003e7 & >b600 & & LDA & COUNT & \\
\hline 672 & 000003e9, & >bb00 & & ADD & BROW & \\
\hline 673 & 000003eb & 48 & & LSLA & & \\
\hline 674 & 000003ec & 48 & & LSLA & & \\
\hline 675 & 000003ed & ab 70 & & ADD & \# \(\$ 70\) & \\
\hline 676 & 000003ef & >b700 & & STA & SUBADR & \\
\hline 677 & 000003f1 & a603 & & LDA & 13 & \\
\hline 678 & 000003f3 & >b700 & & STA & W1 & \\
\hline 679 & 000003f5 & >b700 & & STA & W2 & \\
\hline 680 & \(000003 f 7\) & >be00 & & LDX & BROW & \\
\hline 681 & 000003f9 & 5 a & & DECX & & \\
\hline 682 & 000003fa & 5 a & & DECX & & \\
\hline 683 & 000003 fb & 58 & & LSLX & & \\
\hline 684 & 000003 fc & 58 & & LSLX & & \\
\hline 685 & 000003fd & 58 & & LSLX & & \\
\hline 686 & 000003 fe & 58 & & LSLX & & \\
\hline 687 & 000003 ff & >bf00 & & STX & W3 & \\
\hline 688 & 00000401 & >d6000c & & LDA & DRAM +12 , X & \\
\hline 689 & 00000404 & a43f & & AND & \#\$3F & \\
\hline 690 & 00000406 & >b700 & & STA & IOBUF & \\
\hline 691 & 00000408 & >d6000d & & LDA & DRAM+13, X & \\
\hline 692 & 0000040b & a43f & & AND & \# \({ }^{\text {3 }}\) 3F & \\
\hline 693 & 0000040d & >b701 & & STA & IOBUF+1. & \\
\hline 694 & 0000040 f & >ae00 & & LDX & \#SUBADR & \\
\hline 695 & 00000411 & >cd0000 & & JSR & WRITE & \\
\hline 696 & & & & & & \\
\hline 697 & 00000414 & >3c00 & & INC & SUBADR & \\
\hline 698 & 00000416 & >3c00 & & INC & SUBADR & \\
\hline 699 & 00000418 & >be00 & & LDX & W3 & \\
\hline 700 & 0000041a & a603 & & LDA & \# 3 & \\
\hline 701 & 0000041c & >b700 & & STA & W1 & \\
\hline 702 & 0000041e & >b700 & & STA & W2 & \\
\hline 703 & 00000420 & >d6000e & & LDA & DRAM +14 , X & \\
\hline 704 & 00000423 & a43f & & AND & \# \({ }^{\text {3 }}\) F & \\
\hline 705 & 00000425 & >b700 & & STA & IOBUF & \\
\hline 706 & 00000427 & >d6000f & & LDA & DRAM +15 , X & \\
\hline 707 & 0000042a & a43f & & AND & \#\$3F & \\
\hline 708 & 0000042c & >b701 & & STA & IOBUF+1 & \\
\hline 709 & 0000042e & >ae00 & & LDX & \#SUBADF & \\
\hline 710 & 00000430 & >cd0000 & & JSR & WRITE & \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{712} \\
\hline 713 & & \\
\hline \multicolumn{3}{|l|}{714} \\
\hline \multicolumn{3}{|l|}{715} \\
\hline \multicolumn{3}{|l|}{716} \\
\hline \multicolumn{3}{|l|}{717} \\
\hline 718 & 00000433 & >be00 \\
\hline 719 & 00000435 & >d60003 \\
\hline 720 & 00000438 & 48 \\
\hline 721 & 00000439 & 48 \\
\hline 722 & 0000043a & 48 \\
\hline 723 & 0000043 b & 48 \\
\hline 724 & 0000043 c & >b700 \\
\hline 725 & 0000043 e & >d60004 \\
\hline 726 & 00000441 & a40f \\
\hline 727 & 00000443 & >bb00 \\
\hline 728 & 00000445 & >cd0000 \\
\hline 729 & 00000448 & >b700 \\
\hline \multicolumn{3}{|l|}{730} \\
\hline 731 & 0000044a & >be00 \\
\hline 732 & 0000044c & >d60006 \\
\hline 733 & 0000044f & a43f \\
\hline 734 & 00000451 & al33 \\
\hline 735 & 00000453 & 2702 \\
\hline 736 & 00000455 & \(>1 e 00\) \\
\hline \multicolumn{3}{|l|}{737} \\
\hline 738 & 00000457 & >b600 \\
\hline 739 & 00000459 & >bbOO \\
\hline 740 & 0000045 b & abdc \\
\hline 741 & 0000045d & >b700 \\
\hline 742 & 0000045 f & a 602 \\
\hline 743 & 00000461 & >b700 \\
\hline 744 & 00000463 & >b700 \\
\hline 745 & 00000465 & >ae00 \\
\hline 746 & 00000467 & >cd0000 \\
\hline \multicolumn{3}{|l|}{747} \\
\hline 748 & 0000046 a & >cd0000 \\
\hline 749 & 0000046d & >cc0000 \\
\hline \multicolumn{3}{|l|}{750} \\
\hline \multicolumn{3}{|l|}{751} \\
\hline \multicolumn{3}{|l|}{752} \\
\hline \multicolumn{3}{|l|}{753} \\
\hline \multicolumn{3}{|l|}{754} \\
\hline \multicolumn{3}{|l|}{755} \\
\hline \multicolumn{3}{|l|}{756} \\
\hline 757 & 00000470 & 0 a 00 \\
\hline 758 & 00000472 & 090800 \\
\hline 759 & 00000475 & 07080a00 \\
\hline 760 & 00000479 & 0203040506070809 \\
\hline 761 & & \\
\hline 762 & 00000482 & 1020304050607080 \\
\hline 763 & 0000048 a & \(000306090 c 0 f 1215\) \\
\hline
\end{tabular}

\begin{tabular}{|c|c|c|}
\hline & LDX & W3 \\
\hline & LDA & DRAM \(+3, \mathrm{X}\) \\
\hline & LSLA & \\
\hline & LSLA & \\
\hline & LSLA & \\
\hline & LSLA & \\
\hline & STA & W1 \\
\hline & LDA & DRAM \(+4, \mathrm{X}\) \\
\hline & AND & *\$0F \\
\hline & ADD & W1 \\
\hline & JSR & CHEX \\
\hline & STA & IOBUF \\
\hline & LDX & W3 \\
\hline & LDA & DRAM \(+6, \mathrm{X}\) \\
\hline & AND & *\$3F \\
\hline & CMP & *\$33 \\
\hline & BEQ & STSEC \\
\hline & BSET & 7, IOBUF \\
\hline STSEC & LDA & COUNT \\
\hline & ADD & BROW \\
\hline & ADD & \#SDC \\
\hline & STA & SUBADR \\
\hline & LDA & \# 2 \\
\hline & STA & W1 \\
\hline & STA & W2- \\
\hline & LDX & *SUBADR \\
\hline & JSR & WRITE \\
\hline & JSR & SEC30 \\
\hline & JMP & FINBN \\
\hline
\end{tabular}

\begin{tabular}{llll} 
LTAB0 & FCB & 10,0 & IDLE DISPIAY \\
LTAB1 & FCB & \(9,8,0\) & PR/CH DISPLAY \\
LTAB2 & FCB & \(7,8,10,0\) & ANALOGUE DISPLAY \\
LTAB3 & FCB & \(2,3,4,5,6,7,8,9,0\) & PR/CH/STD/NAME TABLE \\
& & & \\
M16 & FCB & \(\$ 10, \$ 20, \$ 30, \$ 40, \$ 50, \$ 60, \$ 70, \$ 80\) & MULT X 16 \\
M3 & FCB & \(0,3,6,9,12,15,18,21\) & MULT \(\times 13\)
\end{tabular}
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{\multirow[t]{2}{*}{\[
\begin{aligned}
& 765 \\
& 766
\end{aligned}
\]}} \\
\hline & & \\
\hline \multicolumn{3}{|l|}{767} \\
\hline \multicolumn{3}{|l|}{768} \\
\hline \multicolumn{3}{|l|}{769} \\
\hline \multicolumn{3}{|l|}{770} \\
\hline 771 & 00000492 & a60c \\
\hline 772 & 00000494 & >b700 \\
\hline 773 & 00000496 & >a600 \\
\hline 774 & 00000498 & >b700 \\
\hline 775 & 0000049a & \(>1900\) \\
\hline 776 & 0000049c & a60a \\
\hline 777 & 0000049e & b733 \\
\hline 778 & 000004 a & a670 \\
\hline 779 & 000004 a 2 & b735 \\
\hline 780 & 000004a4 & a622 \\
\hline 781 & 000004a6 & b737 \\
\hline 782 & 000004 a & 3 f 30 \\
\hline 783 & 000004 a & 3f31 \\
\hline 784 & 000004 ac & 5 f \\
\hline 785 & 000004ad & a 609 \\
\hline 786 & 000004af & \(>\mathrm{cd} 0000\) \\
\hline 787 & 000004b2 & ael0 \\
\hline 788 & 000004b4 & a61f \\
\hline 789 & 000004b6 & >cd0000 \\
\hline 790 & 000004b9 & a 610 \\
\hline 791 & 000004 bb & >b700 \\
\hline 792 & 000004bd & >b600 \\
\hline 793 & 000004bf & 2703 \\
\hline 794 & 000004c1 & \(>\mathrm{cd} 0000\) \\
\hline 795 & 000004c4 & a 601 \\
\hline 796 & 000004c6 & >b700 \\
\hline 797 & 000004c8 & a602 \\
\hline 798 & 000004ca & >b700 \\
\hline 799 & 000004cc & a6a3 \\
\hline 800 & 000004ce & >050002 \\
\hline 801 & 000004d1 & a6a6 \\
\hline 802 & 000004d3 & >b700 \\
\hline 803 & 000004d5 & >b700 \\
\hline 804 & 000004d7 & a6d0 \\
\hline 805 & 000004d9 & >b700 \\
\hline 806 & 000004 db & a 610 \\
\hline 807 & 000004 dd & >b700 \\
\hline 808 & 000004 df & a 612 \\
\hline 809 & 000004e1 & >b 700 \\
\hline 810 & \(000004{ }^{\text {e }}\) & >b700 \\
\hline \multicolumn{3}{|l|}{811} \\
\hline 812 & 000004e5 & >1800 \\
\hline 813 & 000004e7 & a61e \\
\hline 814 & 000004e9 & \(>040005\) \\
\hline 815 & 000004ec & >000002 \\
\hline 816 & 000004ef & a 606 \\
\hline 817 & 000004 fl & >b700 \\
\hline 818 & 000004f3 & 81 \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|c|}
\hline  & \multicolumn{3}{|l|}{Bottom corner Program/Channel no. display. *} \\
\hline \multicolumn{4}{|l|}{********************************************************} \\
\hline \multirow[t]{19}{*}{PCOSD} & LDA & \# \$0C & \\
\hline & STA & ANAL & \\
\hline & LDA & *AVOL & \\
\hline & STA & ANAF & \\
\hline & BCLR & 4, STAT5 & NOT ANALOGS \\
\hline & LDA & \%00001010 & COLOR \(2=\) GREEN \\
\hline & STA & C34 & COLOR 3 = BLUE \\
\hline & LDA & * \(\% 01110000\) & OSD \& PLL ON, \\
\hline & STA & WCR & WINDOW OFF (COLUMN 16) \\
\hline & LDA & \#\%00100010 & HORIZONTAL POSITION : TWO \\
\hline & STA & HPD & \\
\hline & CLR & \$30 & PUT A SPACE AT 17th AND 18th \\
\hline & CLR & \$31 & CHARACTERS \\
\hline & CLRX & & \\
\hline & LDA & \% 9 & \\
\hline & JSR & OSDCLR & CLEAR UNUSED CHARACTERS \\
\hline & LDX & \({ }^{\text {¢ }} 16\) & \\
\hline & LDA & *31 & \\
\hline & JSR & OSDCLR & CLEAR UNUSED CHARACTERS \\
\hline \multirow[t]{5}{*}{PNAME} & LDA & +16 & \\
\hline & STA & W3 & \\
\hline & LDA & PROG & \\
\hline & BEQ & SKPGN & \\
\hline & JSR & FNAME & \\
\hline \multirow[t]{7}{*}{SKPGN} & LDA & \(\stackrel{*}{*}\) & START AT 1 TO PREVENT \\
\hline & STA & OSDL & DOUBLE-HIGHT-LINE-SHIFT FIASH \\
\hline & LDA & *LTAB1-LTAB0 & \\
\hline & STA & LIND & FIRST TABLE \\
\hline & LDA & \% 210100011 & COLOR 1,0 = RED, CYAN, EDGE ON \\
\hline & BRCLR & 2, STAT4, PMD2 & PROGRAM MODE ? \\
\hline & LDA & \% \%10100110 & NO, COLOR \(0=\) YELLOW \\
\hline \multirow[t]{9}{*}{PMD2} & STA & CAS 1 & \\
\hline & STA & CAS2 & \\
\hline & LDA & \% \%11010000 & DOUBLE WIDTH/日IGHT \\
\hline & STA & RAD1 & \\
\hline & LDA & \% \%00010000 & SINGLE WIDTH/HIGHT \\
\hline & STA & RAD2 & \\
\hline & LDA & \%00010010 & WINDOW CYAN \\
\hline & STA & CCR1 & \\
\hline & STA & CCR2 & \\
\hline \multirow[t]{5}{*}{SEC5} & BSET & 4, STAT & \\
\hline & LDA & +30 & \\
\hline & BRSET & 2, STAT4, S30 & CHANNEL MODE ? \\
\hline & BRSET & 0, stat 6, s30 & NO, 2-DIGIT PROG No. ENTRY ? \\
\hline & LDA & \# 6 & NO, SO 6 SECONDS ONLY \\
\hline S30 & STA & TMR & \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{820} \\
\hline \multicolumn{3}{|l|}{821} \\
\hline \multicolumn{3}{|l|}{822} \\
\hline \multicolumn{3}{|l|}{823} \\
\hline \multicolumn{3}{|l|}{824} \\
\hline \multicolumn{3}{|l|}{825} \\
\hline 826 & 000004£4 & 0 e 121113 \\
\hline 827 & & \\
\hline 828 & \(000004 \mathrm{f8}\) & 636 f 6 e 74 a 2 b 2 a 9 ac \\
\hline 829 & 00000500 & 63b321f4f6efecf5 \\
\hline \multicolumn{3}{|l|}{830} \\
\hline 831 & 00000508 & >b700 \\
\hline 832 & 0000050a & >080041 \\
\hline 833 & 0000050d & \(>1800\) \\
\hline 834 & 0000050 f & \(5 f\) \\
\hline 835 & 00000510 & a67f \\
\hline 836 & 00000512 & >cd0000 \\
\hline 837 & 00000515 & aeld \\
\hline 838 & 00000517 & \(>6 \mathrm{fff}\) \\
\hline 839 & 00000519 & 5 a \\
\hline 840 & 0000051 a & 26 fb \\
\hline \multicolumn{3}{|l|}{841} \\
\hline 842 & \(0000051 c\) & a60a \\
\hline 843 & 0000051e & b733 \\
\hline 844 & 00000520 & a6el \\
\hline 845 & 00000522 & b735 \\
\hline 846 & 00000524 & a622 \\
\hline 847 & 00000526 & b737 \\
\hline 848 & 00000528 & 3 f 30 \\
\hline 849 & 0000052a & 3 f 31 \\
\hline 850 & 0000052c & a6e6 \\
\hline 851 & 0000052 e & >b700 \\
\hline 852 & 00000530 & >b700 \\
\hline 853 & 00000532 & a6a6 \\
\hline 854 & 00000534 & >b700 \\
\hline 855 & 00000536 & a610 \\
\hline 856 & 00000538 & >b700 \\
\hline 857 & 0000053a & >b700 \\
\hline 858 & 0000053c & >b700 \\
\hline 859 & 0000053 e & a6e3 \\
\hline 860 & 00000540 & >b700 \\
\hline 861 & 00000542 & >b700 \\
\hline 862 & 00000544 & a611 \\
\hline 863 & 00000546 & >b700 \\
\hline 864 & & \\
\hline 865 & 00000548 & \(>3 \mathrm{f00}\) \\
\hline 866 & 0000054a & a605 \\
\hline 867 & 0000054c & >b700 \\
\hline \multicolumn{3}{|l|}{869} \\
\hline \multicolumn{3}{|l|}{870} \\
\hline \multicolumn{3}{|l|}{871} \\
\hline \multicolumn{3}{|l|}{872} \\
\hline \multicolumn{3}{|l|}{873} \\
\hline \multicolumn{3}{|l|}{874} \\
\hline 875 & 0000054 e & >be00 \\
\hline 876 & 00000550 & \(>\mathrm{d} 60000\) \\
\hline 877 & 00000553 & >c70000 \\
\hline 878 & 00000556 & 5 c \\
\hline 879 & 00000557 & >d60000 \\
\hline 880 & 0000055a & >c 70001 \\
\hline 881 & 0000055d & 5 c \\
\hline 882 & 0000055e & >d60000 \\
\hline 883 & 00000561 & >c70010 \\
\hline 884 & 00000564 & 5 c \\
\hline 885 & 00000565 & >d60000 \\
\hline 886 & 00000568 & >c70011 \\
\hline 887 & & \\
\hline
\end{tabular}



\title{
Serial bootstrap for the RAM and EEPROM1 of the MC68HC05B6
}

\author{
By Jeff Wright, Motorola Ltd., East Kilbride
}

\section*{INTRODUCTION}

The MC68HC05B6 has 256 bytes of on chip EEPROM, called EEPROM1, which can be used to store variable data in a non-volatile manner. In many applications this EEPROM1 will be used to hold a look-up table or system set up variables. In these cases it is usually a requirement that the EEPROM1 be initialised during
the manufacture of the application. In addition, loading small programs into RAM and executing them is an easy way of trying out new software routines. This application note describes one method for serially loading (bootstrapping) the EEPROM1 via a program executing in the RAM of the MC68HC05B6.

\section*{BUILT IN BOOTSTRAP}

The MC68HC05B6 has a built in RAM serial bootstrap program contained in the mask ROM of the device that uses the SCI. It would therefore seem a simple task to load programs into RAM; however, as ROM space on the device is obviously critical, a very simple protocol has been implemented. This means that the bootloader on the 'B6' does not accept S-records which are the normal output from an assembler; instead, the protocol expects pure binary data preceded by a count byte that holds the size of the program to be downloaded. No address information is contained in the download; instead, the bootloader always starts the program load at address \(\$ 50\) in RAM. The first byte (the count byte) is stored here and then as the subsequent bytes are received via the SCl they are stored at incrementing RAM locations and the count byte is
decremented for each byte received. When the count byte reaches zero the bootstrap program jumps to address \(\$ 51\) and starts to execute the program that has just been loaded. No built in bootstrap routine is provided for the EEPROM1 array.

These restrictions present two problems:
i) How to convert assembler output to the format accepted by the 68HC05B6 RAM bootstrap routine?
ii) How to bootstrap the EEPROMi of the 68HC05B6?

This application note provides a solution for each of these problems.

\section*{1) CONVERTING S-RECORDS FOR RAM BOOTSTRAP}

To use the built in RAM bootstrap program on the MC68HC05B6 the device must be configured as shown in Figure 1. If these conditions are met when the reset pin is released, then the serial bootstrap program described above will start to execute and a program can be downloaded via a 9600 baud RS-232 source. Personal computers usually have one or more RS-232 ports referred to as COM ports. To overcome the format difference between S-records and that accepted by the bootloader, a conversion program is required. There is also an additional problem when using a PC - when a file is copied to a COM port to transfer it, it is the ascii characters that are transmitted, not the binary data. This means for example that if a file containing the typed data byte \$A5 was copied via the COM port to the B6, the B6 would in fact receive two bytes: \(\$ 41\) and \(\$ 35\), which represent the ascii characters \(A\) and 5 respectively.

This means that the conversion program has to strip out the S -record format and convert the resultant data to binary format for transfer to the HC05B6. It must also insert the count byte at the beginning of the output file.

The pascal program BINCONV performs these three tasks; a listing of the source code is given at the end of this application note. A flow diagram of BINCONV can be seen in Figure 2. The inclusion of the count byte has been left as an option to increase the flexibility of the program, but it could easily be standardised to include the count byte for the B6 RAM bootloader. When BINCONV is invoked it prompts for the name of the Srecord input file and the name required for the binary
output file. After this each S-record in the input file is read and converted to binary data and stored in a temporary file. As each S-record is read it is echoed to the screen; when they have all been processed a message prompts the user and asks if a count byte is required. When used with the 68HC05B6 RAM bootloader the answer will always be yes, in which case the count value is written to the output file before the rest of the data is copied from the temporary file to the output file. Finally the value of the count byte is displayed for user confirmation - remember that the count byte is equal to the number of bytes in the program being converted plus 1 for the count byte itself. The program will only accept standard S-record format and will trap and abort if any non-valid character or format is detected.

With the PC COM port set for 9600 baud and the 68HC05B6 configured as in Figure 1 the binary file can be transferred and executed as follows:

\section*{i) Release Reset on the HCO5B6}
ii) Enter the command "COPY XXXX. YYY COM1\B" on the PC.

The program will then be transferred to the B 6 and execution started automatically. Note that the \B option is used to denote a binary file transfer so that the copy procedure does not abort if it finds an end of file (EOF) character in the middle of the file.


Figure 1. RAM bootstrap schematic

\section*{2) BOOTSTRAPPING THE EEPROM1}

To bootstrap the EEPROM1 on the MC68HC05B6 in the absence of a built in loader program, use must be made of the RAM bootloader described above. The idea is that an EEPROM1 loader can be written to the users exact requirements then assembled and downloaded into the RAM of the HC05B6 where it will execute and in turn download data and program it into the EEPROM1.

The 6K EEPROM emulation part, the MC68HC805B6, does have a built in EEPROM bootloader in place of the RAM bootloader and there is an accompanying PC program available from Motorola called E2B6 that downloads S -records to the device for programming.

The following is an explanation of an example EEPROM1 bootstrap program for the \(B 6\) that has been written to be compatible with the 805B6 PC program \(E 2 B 6\) thus eliminating the need to develop another PC program.

A listing of this program (EE1BOOT) is given at the end of this application note. The MC68HC05B6 has 176 bytes of RAM that can be used for the EEPROM1 bootstrap program, so the protocol must be kept simple and the code written efficiently. The format of the E2B6 program is a transfer of 2 address bytes followed by the data byte that is to be programmed at that location. At the same time the B 6 returns the data from the previously programmed location for verification by E2B6. The program EE1BOOT has 4 main sections: a main loop, an erase routine, a program routine and an SCl service routine. The core of both the erase and program subroutines is the extended addressing subroutine EXTSUB which is used to access the EEPROM1 array. This subroutine is built in RAM by the main loop as the address information for the next byte to be programmed is received from the SCI. E2B6 always sends a null character during initialisation which could throw the EE1BOOT program out of synchronisation, as it is already executing before E2B6 is invoked. For this reason EE1BOOT ignores the first character received and treats the second as the first address byte.

The EXTSUB routine is first called as an "LDA \$aaaa" to retrieve the last byte programmed for verification.

Then the address in the routine is modified as the next address to be programmed is received. When the data byte is received the opcode of EXTSUB is incremented so that it becomes "STA bbbb" before the erase and program routines are called. After programming the opcode is decremented back to LDA before the main loop is repeated.

Note that the EEPROM1 location is always erased before programming. The timer output compare function is used to provide a 10 ms delay for erasing and programming and the programming step is skipped to save time if the data presented to that location is \$FF. The sequence of events to bootstrap the EEPROM1 of the \(68 \mathrm{HC05B6}\) is therefore as follows:
1) Configure the 68 HCO B 6 as in Figure 1.
2) Assemble the program EE1BOOT and convert it to binary using BINCONV as described in section 1.
3) Set up PC COM port to 9600 baud then release Reset on the HC05B6.
4) Use the command "COPY EE1BOOT.BIN COM1/ \(B\) " to download EE1BOOT into the RAM of the HC05B6. EE1BOOT will now start to execute.
5) Start the program E2B6 on the PC and follow the instructions to download the desired S-records to the EEPROM1 of the 68 HCO 5 B 6 .

Note:
i) Only the download procedure of E2B6 will work in conjunction with EE1BOOT.
ii) Once the EEPROM1 security bit has been set, the RAM bootloader on the 68HC05B6 will no longer operate. This means that after the device has been reset it will be impossible to download any more data into the EEPROM1 until selfcheck has been executed selfcheck performs an erase of the entire EEPROM1 array. This means that if the EEPROM1 is to be programmed in several steps, the one that will set the security bit should be done last.

\section*{FURTHER POSSIBILITIES}

This application note has shown a method for initialising the EEPROM1 on the 68HC05B6 by using the RAM bootloader. It would of course be much simpler to incorporate a EEPROM1 bootloader in the ROM space of the user program, but often there is not
enough space. If enough space is available (117 bytes), then EE1BOOT could be incorporated in the application software, thus saving steps \(2,3 \& 4\) in the procedure above.


Figure 2. Flow diagram of BINCONV

0001
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0003
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0024
00250000
00260001
00270002
00280003
00290004
00300005
00310006
0032
00330007
00340002
00350001
00360000
0037
0038 000d
0039000 e
00400004
\(0041000 f\)
00420010
00430005
00440011
0045
0046
0047
00480012
00490005
00500006
00510007
0052


********** I/O and INTERNAL registers definition \(\quad * * * * * * * * * * * * * * * * * * * * *\)
* I/O registers
-
\begin{tabular}{|c|c|c|c|}
\hline PORTA & EQU & \$00 & port A. \\
\hline PORTB & EQU & \$01 & port B . \\
\hline PORTC & EQU & \$02 & port \(C\). \\
\hline PORTD & EQU & \$03 & port D . \\
\hline DDRA & EQU & \$04 & port A DDR. \\
\hline DDRB & EQU & \$05 & port B DDR. \\
\hline DDRC & EQU & \$06 & port \(C\) DDR. \\
\hline EECONT & EQU & \$07 & \\
\hline E1ERA & EQU & 2 & * . \\
\hline ElLAT & EQU & 1 & - . \({ }^{\text {a }}\) \\
\hline E1PGM & EQU & 0 & \\
\hline BAUD & EQU & \$0D & \\
\hline SCCR1 & EQU & \$0E & \\
\hline MBIT & EQU & 4 & \\
\hline SCER2 & EQU & \$0F & \\
\hline SCSR & EQU & \$10 & \(\because \quad\) \\
\hline RDRF & EQU & 5 & " \\
\hline SCDAT & EQU & \$11 & \\
\hline * & & & \\
\hline \multicolumn{4}{|c|}{TIMER registers} \\
\hline * & & & \\
\hline TCR & EQU & \$12 & Timer control register. \\
\hline TCIE & EQU & 5 & Timer overflow interrupt enable. \\
\hline OCIE & EQU & 6 & Timer output compares interrupt enable. \\
\hline ICIE & EQU & 7 & Timer input captures interrupt enable. \\
\hline
\end{tabular}


```

program BINCONV: { Program to convert Motorola S-record files to
binary format. Optional inclusion of a count byte for
HC05B6 RAM bootloader etc}
{ Programmer - Jeff Wright, MCU applications
Motorola
East Kilbride}
{
Last Updated 10/5/90}
{***************************************************************************)
var
SrecFile : text;
BinFile : file;
Tempf : file;
srec : string[100];
Transfer : array[1..20000] of char;
numread, numwritten : word;
answer : char;
fnamei : string[15];
fnameo : string[15];
bytout : char;
countbyt : integer;
datcnt : integer;
datval : integer;
point : integer;
cnt1 : integer;
cnt2 : integer;
quit : boolean;
Count : boolean;
{\longrightarrow_}
Procedure Calc hex(chr1,chr2 : integer);
{Combines 2 characters into a single byte value i.e A5->165, error
signaled if non hex character detected}
Begin
Case chrl of
48..57 : chr1 := chr1 - 48;
65..70 : chr1 := chrl - 55; { Is this a valid hex character?}
else
begin
writeln ('invalid data - conversion aborted');
quit := true
end
end;
Case chr2 of
48..57 : chr2 := chr2 - 48;
65..70 : chr2 := chr2 - 55;
else
begin
writeln ('invalid data - conversion aborted');
quit := true
end

```
```

    end;
    datval := chr1*16 + chr2; {Convert to single byte}
    end;
    \
Procedure Binwrite(length,dpoint : integer);
{Converts an S-record line to hex and stores it in a temporary file}
begin
length := length-3; {Allow for address and checksum bytes}
countbyt := countbyt+length; {Update running byte total}
length := length*2; {Twice as many characters as bytes}
while length > 0 do
begin
cnt1 := Ord(srec[dpoint]); {Get the next two characters}
cnt2 := Ord(srec[dpoint+1]);
dpoint := dpoint+2; {Update pointer and length}
length := length-2;
Calc_hex(cnt1,ont2); {Convert two characters into single byte}
bytout := Chr(datval); {- now convert that single byte into a }
blockwrite (tempf,bytout,1) {character and save it in temporary file}
end
end;
{****************** MAIN PROGRAM STARTS BELOW *************************** }
begin
writeln ('S-record to Binary conversion utility');
writeln;
writeln;
write('Input S-record file name? -> ');
readln(fnamei);
assign(SrecFile, fnamei);
write(` Binary output file name? -> ');
readln(fnameo);
assign(BinFile, fnameo);
assign(tempf, 'temp.tmp');
quit := false;
countbyt := 1;
Reset(SrecFile);
Rewrite(BinFile,1);
Rewrite(tempf,1); { + a temporary file}

```
```

    while not Eof(SrecFile) and not quit do
    begin
        readln(SrecFile, srec); {read S-rec into char string srec}
        writeln(srec);
        If srec[1]='S'then {If string does not start with S then quit}
        begin
            CASE srec[2] of
                '1' : {If not S1 record then loop back}
                    begin
                                cnt1 := Ord(srec[3]); {get the 2 record length}
                                cnt2 := Ord(srec[4]); {characters}
                                calc_hex(cnt1, cnt2); {func to produce hex in
                                datcnt from cntl & 2)
                                datent := datval;
                                point := 9; {point to first data character}
                                    binwrite(datcnt,point) { convert the data in this s-rec
                                    line to binary and store in temp file}
                end;
            '0' : writeln ('Conversion started');
            '9'. : writeln ('last S-record done');
            else
            begin {If not S0,SlorS9 record then abort}
                        quit := true;
                        writeln ('Non standard S-record detected - Conversion aborted')
                end
            end
        end
        else
            begin {If lst char not an S then abort}
                quit := true;
                writeln ('Non standard S-record detected - Conversion aborted')
            end
    end;
    If quit = false then
    {If no errors then copy the temporary file to the output file and add in
a count byte if required}
begin
Reset (tempf,1);
writeln;
write ('Do you want a count byte added to start of output file? -> ');
readln (answer);
If upcase(answer) = 'Y' then
Begin
writeln (`Total size including count byte = ',countbyt);
bytout := chr(countbyt);
blockwrite (binfile,bytout,1)
end;
repeat
blockread (tempf,transfer,sizeof(transfer), numread);
blockwrite (binfile,transfer, numread, numwritten);
until (numread=0) or (numwritten <> numread)
end;
close (tempf);
erase(tempf); {Finished with temporary file so erase it}
close(SrecFile);
close'(BinFile) {Close files before quiting}
end.

```

\title{
AN436
}

\title{
Error Detection and Correction Routines for M68HC05 devices containing EEPROM
}

\author{
By Ken Terry
}

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\section*{INTRODUCTION}

An increasing number of applications involving MC68HC05 MCUs require large amounts of critical data to be stored in EEPROM memory. This application note describes software routines, generated for the HCO5, which allow stored data to be encoded so that single bit errors existing in retrieved data may be corrected and two bit errors detected. The routines use a simple Linear Block Code for the encoding of stored data.

\section*{SINGLE BIT ERROR CORRECTION}

All methods of error detection/correction involve the use of extra check bits added to the data bits to produce some form of codeword. To allow the detection of a single bit error in a specific codeword it is necessary that each word differs from any other word by at least two digits. A one bit error will then produce an invalid word. The number of digits by which two words, of the same length, differ is defined as the Hamming Distance. For the correction of up to \(t\) errors a minimum Hamming Distance of \(2 t+1\) is required between each codeword. Single bit error correction and double bit error detection requires a minimum distance of 3 . The problem is to decide what an original codeword was if an invalid codeword has been detected. One means of doing this is to use a Linear Block Code, as described below. Linear Block Codes for the correction of single biterrors are referred to as Hamming Codes. The following describes a systematic method for single bit error correction.

A codeword consists of \(k\) data digits to which are added \(r\) check digits to produce an \(n\) digit codeword ( \(n=k+r\) ). The \(r\) data digits are redundant, in that they carry no additional data, and the code efficiency is defined as \(\mathrm{k} / \mathrm{n}\). This is an indication of the amount of information transferred, relative to the total number of bits.

For a linear block code the general codeword can be written in the form:
\(a_{1} a_{2} a_{3} \ldots . . . a_{k} c_{1} c_{2} \ldots . . c_{r}\)
where \(a_{1}\) to \(a_{k}\) are the \(k\) data digits and \(c_{1}\) to \(c_{r}\) are the \(r\) check digits.

The check digits are chosen to satisfy the \(r\) linear equations:
\[
\begin{aligned}
& 0=h_{11} a_{1} \oplus h_{12} a_{2} \oplus \ldots \ldots . . \oplus h_{1 k} a_{k} \oplus c_{1} \\
& 0=h_{21} a_{1} \oplus h_{22} a_{2} \oplus \ldots \ldots . . . \oplus h_{2 k} a_{k} \oplus c_{2} \\
& 0 \\
& 0=h_{r 1} a_{1} \oplus h_{r 2} a_{2} \oplus \ldots \ldots \ldots . \oplus h_{r k} a_{k} \oplus c_{r}
\end{aligned}
\]

Each element in the above equations is either a one or a zero and all addition is modulo 2.

These equations can be more conveniently expressed in terms of the matrix equation:
\([H][T]=0\)
where \([T]\) is an \(n \times 1\) column vector representing the stored codeword:
\([T]=\left[\begin{array}{l}a_{1} \\ a_{2} \\ a_{3} \\ \cdot \\ \cdot \\ a_{k} \\ c_{1} \\ c_{2} \\ \cdot \\ \cdot \\ c_{r}\end{array}\right]\)
and \([H]\) is an \(r \times n\) matrix, referred to as the parity check matrix.


A second column vector \([\mathrm{R}]\), with same dimensions as [T], is used to represent the retrieved codeword. This may or may not be equal to the original stored codeword [T], depending on whether or not an error exists. If [H] \([R]=0\), then \([R]\) is most likely to be the original stored codeword. If \([H][R]\) gives a non zero value thenat least one error has occurred. If an \(n \times 1\) error matrix \([E]\) is introduced, then the retrieved codeword [R] can be written as:
\([R]=[T]+[E]\)
If [E] consists totally of zeros then no error has occurred. For any error that does occur in [R], [E] will containa ' 1 ' in the corresponding position. The problem is then to determine where in \([E]\) the non zero elements are, once the codeword [R] has been retrieved. A matrix [S], referred to as the syndrome, is defined such that:
\([\mathrm{S}]=[\mathrm{H}][\mathrm{R}]\)
This can be expanded to
\([S]=[H][T]+[H][E]\)
giving
\([S]=[H][E]\)
[S] is an \(r \times 1\) column matrix and can consists of any one of \(2^{r}\) sequences. [E] is an \(n \times 1\) matrix and can consist of any one of \(2^{n}\) sequences. As \(n>r\) there is no unique solution to the above equation. However, in this case it is assumed that only one error has occurred and therefore \([E]\) contains only one non zero element. Multiplying [E] by \([H]\) yields a syndrome which will be equal to one column within \([H]\). The position of this column will indicate where the non zero element exists in \([\mathrm{E}]\) and hence the position of the single bit error in [R]. In the case of two or more non-zero elements in [E] error correction is not possible.

\section*{HAMMING BOUND AND CODE EFFICIENCY}

The Hamming Bound is defined as: \(2^{r} \geq k+r+1\)
where \(k\) is the number of data bits and \(r\) is the number of check bits.

This must be satisfied for single bit error correction. To allow double bit error detection a further check bit must be added. Table 1 shows the number of check bits required, along with the corresponding code rate, for single bit error correction and double bit error detection in different numbers of data bits.

It can be seen from the table that, in general, the greater the number of data bits the greater the code efficiency. However as the size of the codeword increases the calculations involved in detecting an error become increasingly more cumbersome. It can also be seen that for both 8 and 11 data bits, the number of check bits required is 5 . By using 11 data bits and 5 check bits the Hamming bound can be satisfied exactly. There is no exact solution when 8 data bits are used. However, this is a more convenient data size for an 8-bit MCU and is therefore used in this application, despite the lower code efficiency.
\begin{tabular}{ccc}
\hline \begin{tabular}{c} 
No. of \\
Data Bits (k)
\end{tabular} & \begin{tabular}{c} 
No. of \\
Check Bits
\end{tabular} & \begin{tabular}{c} 
Code \\
Efficiency
\end{tabular} \\
\hline 4 & 4 & \(50 \%\) \\
8 & 5 & \(61.5 \%\) \\
11 & 5 & \(68.7 \%\) \\
26 & 6 & \(83.9 \%\) \\
\hline
\end{tabular}

\footnotetext{
Table 1. Check Bit Requirements and Code Efficiency for Single Error Correction
}

\section*{CODEWORD GENERATION AND STORAGE}

For one byte of data, 4 check bits are required for single bit error correction. The parity check matrix will consist of 12 columns of 4 bits and can be simply generated by taking the binary values \$1 to \$C (represented as binary column vectors) to generate 12 columns as shown. The check bits, c1 to c4, are assigned to the columns containing a single non zero entry and the data bits , b7 to b0, are assigned to the remaining columns. The order of assignment is completely arbitrary.
\([H]=\left[\begin{array}{cccccccccccc}c 1 & c 2 & b 7 & c 3 & b 6 & b 5 & b 4 & c 4 & b 3 & b 2 & b 1 & b 0 \\ 1 & 0 & 1 & 0 & 1 & 0 & 1 & 0 & 1 & 0 & 1 & 0 \\ 0 & 1 & 1 & 0 & 0 & 1 & 1 & 0 & 0 & 1 & 1 & 0 \\ 0 & 0 & 0 & 1 & 1 & 1 & 1 & 0 & 0 & 0 & 0 & 1 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 1 & 1 & 1 & 1 & 1\end{array}\right]\)

The following equations can then be derived from the parity check matrix and used to calculate c1 to c4.
```

c1 = b7 \oplus b6 }\oplus\textrm{b}4\oplus\textrm{b}3\oplus\textrm{b}
c2 = b7 }\oplus\textrm{b}5\oplus\textrm{b}4\oplus\textrm{b}2\oplus\textrm{b}
c3 = b6 \oplus b5 \oplusb4 \oplus b0
c4 = b3 }\oplus\textrm{b}2\oplus\textrm{b}1\oplus\textrm{b}

```

At no time is the application software required to carry out any mat;ix multiplication. This is done implicitly by the use of the above equations. A fifth check digit, c5, is used to detect the occurence of a double bit error and is a simple parity check (even parity) for the 12 bit codeword formed by concatenating b7-b0 and c1-c4.

Figure 1 shows the data organisation in memory. The data bytes (b0-b7) and the corresponding check bits ( \(c 1-c 5\) ) are stored separately in adjoining blocks of EEPROM. This allows executable code to be stored in the EEPROM and protected using error checking. The data EEPROM block is 256 bytes long. It is immediately followed by the check EEPROM block. The minimum size possible for the check EEPROM is 160 bytes ( 256 \(x 5\) bits). In order that all check bits can be accommodated within this, software routines are required for the 'packing' and 'unpacking' of check bits.

DATA

DATA + \$100

DATA + \$190


Figure 1. Data Organisation in Memory

\section*{DATA RETRIEVAL AND CORRECTION}

To allow a retrieved codeword to be checked it is necessary to generate the syndrome [S]. To do this the retrieved data byte is used to generate a new set of check bits, \(c 1^{\prime /-c 4} 4^{\prime}\), using the same set of equations as above. The syndrome is then generated by exclusive ORing c1/ to c4' with c 1 to c 4 . An non zero result will indicate the presence of an error. The parity check c5/ is calculated from the retrieved data and check bits and compared with c5. If they are the same, and the syndrome indicates the presence of an error, then it is assumed that a double error has occurred and can therefore not be corrected. If the error is correctable then the syndrome can be compared with values corresponding to the columns of \([\mathrm{H}]\) (in this case, a simple lookup table in ROM) to determine the error position.

\section*{SOFTWARE}

An assembled listing of the software is included at the end of this application note.

The software has been written to run on the MC68HC05SC21 but can be easily modified to run on any HC05 MCU with EEPROM. It comprises 2 main routines. The first routine is CHECKPROG and this generates the codeword from the data and programs the data and the appropriate check bits into EEPROM.

The second routine, GETCHECK, retrieves the data and check bits from the EEPROM, calculates the syndrome and, if any error is detected, returns with the error position indicated in the accumulator. The detection of a double bit error by GETCHECK is indicated by the carry bit being set on return from the routine. The data and check EEPROM blocks can be placed anywhere within the device EEPROM memory, the start address of the data EEPROM being determined by an address held in RAM registers EPSTHI and EPSTLO.

Four further subroutines are called by the the main routines. PAKCHK and UNPAKCHK are used for the packing and unpacking of the check bits in the check EEPROM block. CHECKBIT is used to calculate the check bits c 1 to c 4 and \(\mathrm{c} 1 /\) to c 4 . CALC5 calculates the parity checks c 5 and c 5 .

The total ROM requirement for the routines is 301 bytes with a further 56 bytes required for the EEPROM write/erase routines. Execution time for the routine GETCHECK is approximately 0.6 ms (with 2 MHz internal bus frequency). The execution time for CHECKPROG is dependant on the EEPROM programming time. The time required for the calculation and packing of the check bits amounts to approximately 0.6 ms .

\section*{REFERENCES}

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\title{
MC68HC805B6 and MC68HC705B5 Serial/Parallel Programming Module
}

\author{
By Ross A Mitchell and Mark Maiolani Motorola Ltd, East Kilbride
}

\section*{INTRODUCTION}

The MC68HC05B serial/parallel programmer module (Figure 1) enables the user to program MC68HC805B6 and MC68HC705B5 MCU devices. This application note describes the various operating modes of the module and gives details of its use and construction.

\section*{PROGRAMMING MODES}

Two programming modes are available via jumper selection: parallel mode and serial mode.

In parallel programming mode, the user program contained in an external EPROM is copied into the internal EEPROM or EPROM of the MCU device, whereas in the serial programming mode the MCU EEPROM or EPROM can be programmed or read via the serial port on the programmer module.

Note: If the security bit is active on the 68HC705B5 device, no programming operations are possible. On the 68HC805B6 device, the device will be initially erased if programming is attempted with the security bit active.

Table 1 describes the 4 modes of operation for the 68HC805B6 and 68HC705B5 devices. The markings for jumpers J 2 and J 3 are on the programmer board.

\section*{PARALLEL PROGRAMMING MODE}

\begin{abstract}
This mode enables programming of the MCU EEPROM (68HC805B6) or EPROM (68HC705B5) directly from an external 27C64 EPROM device, with the programming module operating as a stand-alone unit. The main functions of erasure ( 68 HC 805 B 6 only), programming, and verification are all implemented in this mode.
\end{abstract}

In this mode, all the internal EEPROM of the 68HC805B6 is automatically erased before being programmed. Any failure of the EEPROM to erase results in illumination of the red LED and a re-attempt of erasure. EEPROM erasure is normally complete within 500 mS . The erased state of the 68 HC 805 B 6 is \(\$ F F\) and \(\$ 00\) for the \(68 \mathrm{HC} 705 \mathrm{B5}\).

The 27 C64 EPROM should contain the data to be programmed with the same addresses as the 6 Kbyte EEPROM of the 68HC805B6 and so the EPROM should only have data between addresses \(\$ 800\) and \(\$ 1\) FFF inclusive. Note: The smaller 256 byte EEPROM array of the 68 HC 805 B 6 is not programmable from external EPROM.

When programming 68 HC 805 B 6 devices, locations of the external EPROM not in the internal EEPROM address range are omitted, as are locations containing the data \$FF, thus speeding up the programming operation. With 68HC705B5 devices, a similar technique is used, with the exception that areas with the data \(\$ 00\) are omitted.
\begin{tabular}{|l|l|l|l|}
\hline Jumper J2 & Jumper J3 & Device 68HC805B6 & Device 68HC705B5 \\
\hline SERIAL & BOOT ONLY & SERIAL LOAD (NO ERASE) & RAM/EPROM SERIAL BOOT \\
SERIAL & ERASE + BOOT & SERIAL LOAD WITH ERASE & EPROM ERASE CHECK \\
PARALLEL & BOOT ONLY & PARALLEL RAM BOOT & PARALLEL RAM BOOT \\
PARALLEL & ERASE + BOOT & PARALLEL EEPROM BOOT & PARALLEL EPROM BOOT \\
\hline
\end{tabular}

Table 1. Programming modes for 68HC805B6 and 68HC705B5 devices


Figure 1. MC68HC805B6 and MC68HC705B5 Serial/Parallel Bootstrap Programmer

\section*{PARTS LIST}

\section*{RESISTORS}
\begin{tabular}{ll} 
R1 & 3 K \\
R2 & 3 K \\
R3-R5 & 100 K \\
R6 & 1 K \\
R7,R8 & 470 \\
R9 & 10 M \\
R10 & \(4 \mathrm{K7}\) \\
R11 & 10 K \\
R12,R13 & 1 K \\
R14 & \(4 \mathrm{K7}\) \\
R15-R37 & 100 K \\
R39 & 10 K \\
R40 & 1 K \\
R41 & 12 K \\
R42 & \(4 \mathrm{K7}\)
\end{tabular}

\section*{CAPACITORS}
\begin{tabular}{ll} 
C1-C4 & \(22 \mu \mathrm{~F}\) \\
C5 & \(0.01 \mu \mathrm{~F}\) \\
C6 & \(1.0 \mu \mathrm{~F}\) \\
C7,C8 & 22 FF \\
C9 & \(100 \mu \mathrm{~F}\) \\
C10,C11 & \(47 \mu \mathrm{~F}\) \\
C12 & 1.0 nF \\
C13 & \(0.1 \mu \mathrm{~F}\) \\
& \\
DIODES & \\
& \\
D1.D2 & 1 N 914 \\
D3 & LR3160 \\
D4 & LG3160 \\
D5,D6 & 1N5822 \\
D7 & 1N914 \\
D8 & 1N5818
\end{tabular}

INTEGRATED CIRCUITS AND SOCKETS
\begin{tabular}{lll} 
IC1 & 68HC805B6 & 52 Pin PLCC ZIF \\
IC2 & INT27C64 & 28 Pin DIL ZIF \\
IC3 & MAX232CPE & 16 Pin DIL LIF
\end{tabular}

CONNECTORS
J1
J2, J3, J4
P1
25 Way AMP Female
3 Way Jumper
4 Way Terminal Connector

\section*{SWITCHES}

S1,S2,S3 2 Way, Toggle Switch (SPDT)
MISC
CR1 MK04000A 4MHz Crystal Package HC-18U

TRANSISTORS (All in T092 Package)
\begin{tabular}{ll}
\(\mathrm{Q} 1, \mathrm{Q} 2\) & \(\mathrm{BC} 337-25\) \\
Q3 & BC 239 C \\
Q4 & BC 309 C
\end{tabular}

During the programming operation the green LED should flash with a period of approximately 1 second to indicate normal programming mode.

After the programming operation has been completed, the programmed contents of the MCU are verified against the external EPROM. Any failure to verify will result in illumination of the red LED. Successful verification will result in illumination of the green LED.

The68HC705B5 device can be checked for the EPROM in the erased state by placing the jumpers in the SERIAL and ERASE+BOOT positions with +5 volts on the Vpp supply for 68HC705B5. In this case follow the instructions below for parallel programming ignoring steps 4 and 5, but there is no need for a 27C64 EPROM in socket IC2. The green LED turned on indicates success, the red LED indicates that the EPROM is not in the erased state.

\section*{PARALLEL PROGRAMMING OPERATION}

To program the MCU from an EPROM using parallel mode, perform the following steps:
1. With power to the module removed install MCU and EPROM devices into the programming module.
2. With the power switches S1 and S2 both off, and switch S3 in the RESET position, connect both the +5 V supply and appropriate Vpp supply \((68 \mathrm{HC} 705 \mathrm{~B} 5\) or 68 HC 805 B 6\()\) to the module.
3. Set jumper J 4 to the appropriate setting for the MCU being programmed (705B5 or 805B6).
4. Set jumper J3 to the 'ERASE + BOOT' position.
5. Set jumper J 2 to the 'PARALLEL' position.
6. Turn the +5 V power supply switch, S1, ON.
7. Turn the Vpp power supply switch, S2, ON.
8. Place switch S 3 in the RUN position.
9. Once the green LED has stopped flashing, and remains continuously illuminated, place switch S3 to the RESET position.
10. Place the Vpp power supply switch, S2, in the OFF position.
11. Place the +5 V power supply switch, S 1 , in the OFF position.

Note: To avoid possible damage to the MCU it is essential that power to the programming module is applied and removed in the sequence specified above.

\section*{SERIAL PROGRAMMING MODE}

This mode allows the user to program and read the MCU EEPROM or EPROM via the serial port on the programmer module. By using a host computer and a control program such as E2B6, data can be downloaded and programmed onto the MCU, or uploaded from the MCU back to the host computer.

Programming in serial mode consists of the MCU reading a byte of data from the serial port, programming it into the internal 6 Kbyte EEPROM or EPROM array, reading the data back from programmed location and sending it to the serial port. The host computer should verify programming by checking the data returned from the programming module for differences from the programmed data, which would indicate incorrect programming or erasure.

As in parallel mode, bytes to be programmed with \$FF for EEPROM devices and \(\$ 00\) for EPROM devices are skipped, reducing the overall programming time and allowing the memory upload feature to be implemented. This involves the host computer reading the data programmed in the MCU by attempting to program these values and examining the returned verification data.

\section*{MC68HC805B6}

A program called E2B6 is available for the IBM PC and similar machines that communicate via RS-232 with the programmer board serial connector. This program allows upload (data transfer from 68HC805B6 to IBM PC ) to read the EEPROM and can also program the EEPROM by downloading S1 record files to the 68HC805B6 device.

As in the parallel programming mode, the internal EEPROM areas can be automatically erased before programming. In serial mode, however, this operation is optional, and is selected by setting jumper J 3 to the ERASE + BOOT position. An exception is if the EEPROM security bit is active, in which case the erase will be carried out regardless of the setting on J3. A 'read' or 'upload' of the EEPROM will also cause the EEPROM to be erased if J 3 is set to 'ERASE + BOOT' or if the security bit is active.

\section*{MC68HC05B6}

The 68HC05B6 (ROM device) 256 byte EEPROM may also be programmed using this board as described in
application note AN434. In this case the jumpers should be set as for the \(68 \mathrm{HC} 805 \mathrm{B6}\), ERASE+BOOT and SERIAL but the Vpp supply for the 805B6 power socket should be connected to +5 volts.

\section*{MC68HC705B5}

A program called EPB5 for the IBM PC communicates viaRS-232 with the programmer board serial connector. This program allows upload (data transfer from \(68 \mathrm{HC} 705 \mathrm{B5}\) to IBM PC) to read the EPROM and can also program the EPROM by downloading S 1 record files to the 68HC705B5 device.

The 68HC705B5 EPROM means that the jumpers J 2 and J 3 have slightly different meaning. See table 1 for details of operating modes.

\section*{SERIAL PROGRAMMING OPERATION}
1. Run the program E2B6 \((68 \mathrm{HC} 805 \mathrm{~B} 6)\) or EPB5 (68HC705B5) on an IBM PC to communicate with the device to be programmed.
2. With power to the module removed install the MCU and connect the serial line between the host computer and the serial port on the module.
3. With the power switches S1 and S2 both off and switch S 3 in the RESET position, connect both the +5 V supply and appropriate Vpp supply (705B5 or 805B6) to the module.
4. Set jumper J 4 to the appropriate setting for the MCU being programmed (705B5 or 805B6).
5. Jumper J3 should be set to the desired setting, e.g., BOOT ONLY if reading data from the MCU or ERASE + BOOT if re-programming a device (68HC805B6 only).
6. Set jumper J2 to the 'SERIAL' position.
7. Turn the +5 V power supply switch, S1, ON.
8. Turn the Vpp power supply switch, S2, ON.
9. Place switchS3 in the RUN position when prompted by the host computer control program.
10. Follow the instructions of the upload/download program to initiate the data transfer.
11. When the operation has been completed, place switch S3 to the RESET position.
12. Place the Vpp power supply switch, S 2 , in the OFF position.
13. Place the +5 V power supply switch, S 1 , in the OFF position.

For programming several devices, leave the IBM PC program running and repeat instructions 2 to 13 inclusive.

Note: The documentation of the host computer control program being used should be consulted for further details on the use of serial programming mode.

\title{
MC68HC05E0 EPROM Emulator
}

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}

\section*{INTRODUCTION}

The MC68HC05EO is a versatile member of the M6805 family of microprocessors. Unlike most other versions it has no on-chip ROM but instead can address a full 64 K of external memory. This memory could simply be a ROM or EPROM containing the required program but can also include RAM and/or additional hardware. In addition to the external busses required to support this capability, the MC68HCO5EO has the usual I/O, timers etc. found on single-chip microprocessors.

The EPROM emulator described here illustrates a typical application of this type of microprocessor. In addition to the program EPROMitemploys a keyboard, LCD, serial communication and 64K of paged RAM. The emulator can replace with RAM the program EPROM or ROM (up to \(64 \mathrm{~K} \times 8\) ) in a microprocessor based target system. This is done by connecting the emulator to the target system via a cable to its EPROM socket.

The object code, which can be loaded serially or from an EPROM, can be inspected and modified with the use of a local keyboard and LCD display. The new or modified code can then be used by the target system without having to go through the procedure of erasing and re-programming an EPROM after each software change. A selectable offset in \(\$ 0100\) steps is available in order to position the code correctly in the target system's memory map.

The emulator facilitates the debugging of hardware and software for any system whose control program is to be contained in a 27 (C) \(16 / 32 / 64 / 128 / 256 / 512\) type EPROM. The control software includes branch offset calculation for 6805 code and is thus particularly suitable for debugging systems using one of the microprocessors from the \(\mathrm{M} 68(\mathrm{HC}) 05 / 01 / 11\) ranges.

Two basic methods of loading a program are available. The first is applicable when the code is available in an existing EPROM. The contents of this EPROM can be transferred by the microprocessor into the RAM. This method requires an existing EPROM but will prove useful in applications where a small change to an existing program has to be checked before committing to an updated EPROM. This can be done without access to the source or object code. An EPROM can be read from the target system interface (through the emulator's buffers) or from a separate socket wired directly to the microprocessor. The former method allows one socket to be used for both EPROM reading and the target cable. The second method saves having to remove the target cable to read an EPROM but requires an additional socket.

Alternatively, data can be serially loaded in the form of Motorola S-records via an RS232 link. This code can come from a "COM" port of a PC (using the COPY command) or by tapping into the link between a computer and its terminal on a system using an RS232 connection between terminal and host. In this case a TYPE or LIST to the terminal should be used. A verify facility which compares the contents of RAM with serial S-records is also available, as is a routine to dump the current contents of the emulation RAM out on the RS232 interface.

\section*{PRINCIPLE OF OPERATION}

Figure 1 shows a block diagram of the emulator in each of its three main modes of operation. The data/ address flow is controlled by MC74HC245 bidirectional tri-statable 8 -bit buffers. They constitute two 18 -bit buffers for address and control signals and two 8 -bit buffers for data. The enabling and direction control signals are supplied by the MC68HCO5EO microprocessor.


Figure 1a. Mode A:
direct access to the target system's interface


Figure 1b. Mode B: access to the emulator's RAM


Figure 1c. Mode C:
gives the target system access to the RAM

There are three modes of operation:
a) Mode A allows the microprocessor to read the contents of an EPROM on the target system interface (this is most easily arranged by connecting the cable to the target system via a zero or low insertion force socket) by enabling buffers B1 and \(B 2\) to drive from left to right to supply addresses to the socket (the RAM also receives these addresses but its data outputs are disabled). Buffers B3 and B4 are enabled from right to left to return the data from the EPROM to the MC68HC05EO. The RAM is disabled via its chip-enable pin and so does not affect the data bus between buffers B3 and B4.
b) Mode B enables the buffers in such a way that the microprocessor can read from and write to the RAM. B1 is enabled to supply addresses to the RAM from the microprocessor (MC74HC245s were used throughout although a bidirectional buffer is not strictly necessary in this position as B1, if enabled, always drives from left to right). B3 is enabled to allow data to be written to or read from the RAM. The direction control for B3 is by the R/ W signal from the MC68HC05EO (gated with the RAM's chip enable). This mode is used during use of the memory modify facilities. Buffer B4 is disabled so that there is not a bus contention on either of its busses even if the target system is still connected. Buffer B2 is also disabled. The routine (L1) which loads RAM from an EPROM on the target system interface switches between modes A and B for each byte transferred.
c) In theemulation mode (C) the targetsystem plugged into the socket is required to have access to the RAM so buffers B2 and B4 are enabled. B2 passes the addresses from right to left and B4 the data from left to right (as the emulation is for an EPROM, the target system is not aliowed to write to the RAM). Buffers B1 and B3 are disabled.
\begin{tabular}{|c|c|c|c|}
\hline \multirow{2}{*}{ Control line } & \multicolumn{3}{|c|}{ MODE } \\
\cline { 2 - 4 } & A & B & C \\
\hline 4,PortB & 1 & 1 & 0 \\
5,PortB & 0 & 0 & 1 \\
6,PortB & 0 & 1 & 0 \\
7,PortB & 1 & 0 & 0 \\
\hline
\end{tabular}

\section*{CIRCUIT}

Figure 2 shows the main circuit. An MC74HC138 is used to provide the chip enables. The emulator hardware is enabled in the address range \(\$ 4000-\) \$7FFF and the EM64K program EPROM (27(C)64) at \(\$ C 000-\$ F F F F\). If the EM64K program is contained in a \(27(\mathrm{C}) 16\) its pin \(21(\mathrm{Vpp})\) should be held high.

An additional socket is shown at address \(\$ 8000-\) \$BFFF. This is for the optional LOAD2 facility which allows code to be loaded from EPROM without having to disconnect the cable to the target system. The emulation RAM occupies the address range \(\$ 4000\) \$7FFF. As this is only a 16 K address space the RAM is paged. The four pages are selected by I/O lines (port B, bits 0 and 1) from the microprocessor. The memory map of the emulator is shown in figure 7.

The control lines (port B, bits 4-7) are biased by resistors. This holds the system in mode B if the MC68HC05EO is held in reset and prevents bus contention resulting from an illegal combination of control signals. During hardware debug of the emulator it is advisable to use a current limited power supply (in the range \(50-100 \mathrm{~mA}\) ) as a bus contention can cause sufficiently high currents to damage the buffers.

The display is a 6 -digit 4 -backplane LCD (eg Hamlin type 4200 or the 8 -digit GE type LXD69D3F09KG) which is driven by an MC145000 display driver. The driver is controlled by a 2 -line serial link from the microprocessor. A single-backplane (or "static") display can be used as an alternative as shown in Figure 3. Three MC144115 driver chips are used. This circuit requires many more connections to the LCD but allows the use of a more readily available display. A third line (port B bit 3 ) from the microprocessor is used to supply the enable pins of the MC144115s. The single-backplane display drivers can be supplied directly from the main 5 volt supply but the multiplexed display requires a lower voltage. Figure 2 shows the MC145000 supplied via a 20 k potentiometer which serves as a contrast control.

The keyboard uses an MC14028 decoder to minimise the number of \(I / O\) pins used. Note that port \(A\) bit 6 is used for both the keyboard and the display driver. The LOAD1 and LOAD2 keys overwrite the contents of emulation RAM and should thus not be pressed accidentally. It may therefore be useful for only those LOAD keys actually required to be fitted (usually LOAD1 and LOAD2 will not both be required) and for
any parallel LOAD keys fitted to be placed away from the front panel or protected by requiring two keys, connected in series, to be pressed. An accidental press of the serial LOAD key can be aborted by pressing RESET.

As the circuit, except for the RS232 interface, is all CMOS the supply current is very low when the microprocessor is in STOP mode. This is a low power mode in which all processing, even the clock, is stopped. In the emulation mode (C) the MC68HC05EO is in stop mode. In this mode and with no bus activity from the target system (or its interface open circuit) the supply current should be less than \(1 \mu \mathrm{~A}\) (this does not include the current taken by the RS232 interface which, if present, can be switched off when not in use, or the 70-80 \(\mu \mathrm{A}\) taken by the LCD driver).

It is worth checking that a low supply current is achieved as any excess can be a useful pointer to a wiring fault, particularly open circuit pins. The supply current may be affected by the choice of RAM but the MCM60L256 selected has a specified standby ICC of \(2 \mu \mathrm{~A}\) and is typically well below this figure. In many applications the full 64 K of RAM will not be required. If this is the case, only the required RAM need be included. 6116 2K RAMs could be used for \(2-4 \mathrm{~K}\) applications and MCM60L64s or equivalents for \(8-16 \mathrm{~K}\). If using 6064s, their second chip enable pin (E2) should be held high. One MCM60L256 provides 32K. The serial load routine includes a read-back check on each byte sent to RAM so an attempt to write to non-existent RAM will generate an error message indicating the first faulty address. If 16 K or less is required then the two 74 HC 245 s handling addresses, A14 and A15, can also be omitted. These buffers have unused pins. The simplest way to ensure that no pins are left open circuit is to wire up the buffers in a manner similar to those actually used. Pins 2-7 of the left-hand buffers are held high while pins 13-18 are connected to the right-hand buffers whose other pins have pull-ups. This arrangement means that there will be no open circuits or bus contentions regardless of the levels of the control lines. If only one memory chip is used, the 74 HCOO can be omitted (connect pin 3 of the 74HC32 directly to the RAM's chip enable).

The optional RS232 interface can most easily be implemented using the single-supply MC145407 driver-receiver chip. If outputting of S-records is not required then a simple transistor inverter with a pullup resistor and a reverse polarity protection diode can be used. This interface is shown in Figure 4.



Figure 3. Alternative static LCD display


Figure 4. Simple input-only RS232 interface

\section*{IDD Monitor}

It is often useful with CMOS circuits to provide a simple IDD monitor which shows via an LED whether or not the IDD is above or below a set value. In this application it shows whether or not the microprocessor is in the STOP mode. The required circuit is shown in Figure 5. The current threshold can be chosen by selecting the value of R1. A value of \(1 \mathrm{k} \Omega\) sets the limit at about \(500 \mu \mathrm{~A}\) which means the LED should be off in the emulation mode but on otherwise. The \(500 \mu \mathrm{~A}\) limit allows the LCD and perhaps an emulator-supplied CMOS target system to be supplied without switching on the LED. When the microprocessor is not in STOP (emulator not in mode C), its IDD is several milliamps and the LED should be lit. In a battery application this circuit would also serve as a useful reminder that the RS232 interface has been left on. If a multiplexed LCD is used it may be preferable not to supply it via this type of monitor circuit as a significant change in contrast may occur when the microprocessor goes into its STOP mode (see Figure 5). The monitor drops about 600 mV when the microprocessor is running so the supply voltage should be chosen accordingly; four zinc-carbon or five Ni-Cad cells were found to be satisfactory.

\section*{Address trap}

The emulator allows memory locations to be examined and changed, but does not provide the breakpoint and trace features normally found in development systems. A limited capability can be made available if address comparators of the type shown in Figure 6 are added. This circuit gives an LED indication if the address selected on the bank of switches is encountered by the program running in the target system. An address coincidence is latched by the 74 HC 74 . To indicate the occurrence of a repetitive event, a one-shot chip could be added.

\section*{SERIAL LOAD}

To load external Motorola S-records the serial load key (LOAD) should be pressed. The LCD will display "LOAd". S-records should then be supplied at 9600 baud (8-bit, no parity) on the RS232 interface. When an S9 termination record is received, the prompt returns. If an error is detected during a serial load, the load routine stops and displays the address at which the error occurred and the error type.


Figure 5. Simple IDD monitor

The following error types are possible:
1: Checksum error, transmitted data or interface faulty.
2: RAM read-back error, RAM faulty or non-existent.
3: ASCII character less than \(\$ 30(0)\) received.
4: ASCII character between \(\$ 39\) (9) and \(\$ 41\) (A) received.

5: ASCll character more than \(\$ 46\) (F) received.
7: Verify error when comparing S-records with emulation RAM.

If, when using the emulator, the target system ceases to function properly, then the verify function can be used to check that the emulation RAM has not been corrupted. The VERIFY function is used exactly like LOAD except that RAM is compared with, rather than loaded by, the S-records.

The address at the start of each S1-record determines the address at which the code will reside in the target system. This address will sometimes be different from that at which the code is required to be loaded into the emulation RAM so an offset may need to be used. The offset byte is entered using the appropriate key and allows an offset of any multiple of \(\$ 0100\). The offset is subtracted from the MSB of the S-record address and this modified address is the physical address at which the data is loaded into the emulation RAM. The S-record output routine adds the offset before transmitting the records. At reset or power-up the offset is initialised to zero.

All addresses entered while using the MEMORYMODIFY, BRAOFF and DUMP routine use the actual address in the target system. These addresses will only be the same as the physical RAM address if the offset is zero.


Figure 6. Address Trap

\section*{PARALLEL LOAD}

When the parallel load functions (LOAD1 and LOAD2) are used, OFFSET has no effect on the transfer of code into RAM. It can, however, still be used to offset the RAM addresses to correspond with the actual address in the target system program when using the memory-modify facilities.

\section*{27(C)64/128/256 EMULATION}

When emulating a 27 (C) 512 EPROM, all the RAM is used. For emulation of smaller EPROMS, less RAM is required. The memory used will be at the beginning of RAM (starting at address zero) only if the unused high-order addresslines are heldlow. It may, however, be more convenient to allow one or more of these addresses to be high. The pull-ups included in Figure 2 will hold any uncommitted lines high. For example, a27(C)64 can be emulated with no hardware change as long as the code is loaded between \$E000 and \$FFFF. This will often be appropriate as it allows the vectors at the top of the target system's memory to be included. It makes little difference if the target microprocessor has an address space smaller than 64 K as the high order addresses will not be present and will be held high. Clearly, the code must still be assembled at the appropriate addresses and the emulator's offset feature used to load the S-records between \$E000 and \$FFFF. Alternatively, the S-records can be loaded lower in the emulator's address space and the relevant high-order addresses held low. When loading from a smaller EPROM, with a VPP or PRG pin, these pins should be configured correctly for reading (high) and not driven by the emulator. See Figure 9 for the industry-standard EPROM pinouts. As the software does not behave differently for smaller EPROMs, a full 64 K transfer will still be made, copying the EPROM several times into the 64K RAM. The actual copy used depends on the levels of the high order addresses as outlined above.

\section*{TARGET SYSTEM INTERFACE}

Vdd can be connected to the interface by the link shown. The simplest method of use is to make this connection and to use a common supply for the emulator and the target system. If, however, separate supplies are used, then pin 28 should not be connected. If separate supplies are used, care should be taken that they do not differ by more than 0.5 V . A delta greater than this may cause a malfunction as a result of the logic level on an input pin being in excess of the chip's Vdd.

In emulation mode the target system has total control of the RAM except for its R/W line. It can thus use the RAM exactly as if it were a ROM or EPROM. Before IRQ (or RESET) is pressed to exit from the emulation mode the target system should be stopped so that it no longer expects the "EPROM" to be there. This will normally be done by holding the target system in reset. If the target system is an \(\mathrm{M} 68(\mathrm{HC}) 05\) (eg MC68HC05EO or MC146805E2) or M68HC11, then it can alternatively be put into its STOP mode. If this is its normal idle condition, then nothing need be done prior to exiting emulation.

\section*{EM64K PROGRAM}

The EM64K control program is less than 2 K bytes long and can thus reside in a 27 C 64 or 27C16. The circuit is shown for a 27C64 and assumes that the program starts at the beginning of the EPROM. This EPROM is enabled at \$C000 (and \$E000 as A13 is not used). An assembled listing of the control program is included at the end of this application note.

\section*{EM64K KEY FUNCTIONS}
\begin{tabular}{|c|c|c|}
\hline Function & KEY & Description of function \\
\hline LOAD1 & L1 & Load RAM from target system interface (\$4000-\$7FFF). \\
\hline LOAD2 & L2 & Load RAM from secondary socket (\$8000-\$BFFF). \\
\hline \[
\begin{aligned}
& \text { SERIAL } \\
& \text { LOAD }
\end{aligned}
\] & LOAD & Load emulation RAM with S-records via the RS232 interface, during loading LCD shows "LOAd". \\
\hline VERIFY & Verf & Compare emulation RAM with S-records via the RS232 interface, LCD displays "UErIFy". \\
\hline EmULATE & EM & Emulator mode. Prompts: "EP ?" for the removal of an EPROM (if present) and connection of the target system (press again if OK) and put micro into EMULATE mode. \\
\hline MEMORY MODIFY & M & \begin{tabular}{l}
Display/change a RAM location. When pressed the last address is displayed. Press ENTER to display the contents of this address or input a new address followed by ENTER. To change, input new data followed by ENTER. \\
ENTER moves to next address, \(M\) moves to previous address, ESCAPE exits.
\end{tabular} \\
\hline ENTER & Ent & Enter keyed-in address or data (and move to next address in MEMORY MODIFY). \\
\hline ESCAPE & Esc & Exit from current function (OFFSET, BRAOFF, DUMP or MEMORY MODIFY). \\
\hline BRAOFF & A & Calculate branch offset. The address of the branch instruction and of the destination are requested. If a valid branch is calculated it is written into memory and displayed. If not valid then "or" for out of range is displayed. A branch of -128 through +127 relative to the start address of the next instruction is allowed. Esc returns to the normal prompt. \\
\hline OFFSET & B & Allows entry of an offset to the emulation RAM address. It is subtracted from the most significant byte of the address specified by the incoming S-records. The offset is added to the address by the DUMP function. \\
\hline DUMP & C & Output emulation RAM contents as S-records via RS232 interface. RAM start and finish addresses are requested. They should be entered followed by ENTER. After the second ENTER, the S-record output starts. \\
\hline IRQ & IRO & Abort emulation and return to emulator monitor. \\
\hline RESET & RESET & Resets emulator, displays prompt ( \(\square\) ). Should be used after power-up or if the emulator malfunctions. Can be used instead of IRQ, with the difference that the OFFSET is reset to zero. RESET provides the only exit from a LOAD or VERIFY which has not been terminated correctly by the reception of an S9 record. \\
\hline
\end{tabular}


Figure 7. Memory Map

\section*{SOFTWARE}

A listing of the control program used in the emulator is included in this application note. Some points specific to the MC68HC05E0 are discussed below.

Port D on the MC68HC05E0 can be used as a normal I/O port or can selectively supply special signals. In this application five of the special function are used. These function are selected using the register at address \$12. The function used are P02, RN, A13, A14 and A15. By default only addresses A0 through A12 are available as this will be sufficient in many applications. In this application, however, all the addresses are required. The clock (P02) is used to qualify the chip selects generated by the MC74 HC138 and R/W for control of the emulation RAM. The other three pins are left as I/O pins but are not used in this application. The initialisation of \(\$ 12\) can be seen on lines 93 and 94 of the software listing.

The only other register used (apart from the I/O data and DDR registers) is the interrupt control register (\$0E). It is written to \(\$ 01\) on lines 82 and 83 of the listing. This operation clears the interrupt flag (bit 3) but keeps the INTMX bit set. This bit enables external interrupts. The registers associated with unused onchip resources are left at their reset conditions. An important bit in the MC68HC05E0 is the XROM bit \((2, \$ 0 C)\). It defaults to a 1 which is appropriate in this application. When it is cleared it constrains the data bus to be input only thus preventing any unnecessary activity in sensitive applications when writing to external memory is not required.

The MC68HC05E0 has the 8-bitindex register common to all M6805 microprocessors. It is thus not able to contain a 16-bit extended address. For this reason, loading and storing in the emulator's RAM is carried out using a small program in the micro's RAM. This program consists of an extended LDA or STA instruction followed by a two byte address which can be built in software and an RTS instruction. The fourbyte program resides in RAM at locationsW2, ADDEH, ADDRL and W3. It allows the full 64 K map to be accessed using addresses generated within the program. Address generation is further complicated by the requirement that the emulation RAM is in four 16 K pages. The two most significant addresses thus have to be transferred to port lines PB0 and PB1.

\section*{SERIAL INTERFACE}

Figure 8 shows a suggested method of wiring up the RS232 sockets in an emulator with both loading and dumping capabilities. This arrangement facilitates use of the serial LOAD and DUMP routines of the emulator either via a PC COM port or between a host and terminal connected by an RS232 link. When using a PC the "host" socket should be used. As only one pin on the MC68HC05E0 is used, switching is required to make the required connections. S 2 can be eliminated (or left at "L") if only loading is required, as will often be the case. To save power in battery applications, the RS232 interface chip can be switched off using S1. The following table shows possible methods of use.
\begin{tabular}{|c|l|l|l|l|}
\hline Set-up & Function & S1 & S2 & Comments \\
\hline \multirow{3}{*}{ Host \& terminal } & Load & On & L & \begin{tabular}{l} 
Terminal and host connected. \\
Micro looks at data sent from host to terminal (pins 3).
\end{tabular} \\
\cline { 2 - 6 } & Dump & On & D & \begin{tabular}{l} 
Connection between terminal and host broken. \\
S-records sent to both host (2) and terminal (3).
\end{tabular} \\
\hline PC "COM" port & Load & On & L & S-records loaded from pin 3. \\
\cline { 2 - 5 } & Dump & On & D & \begin{tabular}{l} 
S-records sent to pin 2 on "host" socket \\
(and pin 3 on "terminal" socket).
\end{tabular} \\
\hline
\end{tabular}


Figure 8. RS232 circuit with LOAD/DUMP switching
\begin{tabular}{|c|c|c|c|c|}
\hline Pin & 27512 & 27256 & 27128 & 2764 \\
\hline 1 & A15 & Vpp & Vpp & Vpp \\
\hline 2 & A12 & . & . & . \\
\hline 3 & A7 & . & . & . \\
\hline 4 & A6 & . & . & . \\
\hline 5 & A5 & . & . & . \\
\hline 6 & A4 & . & . & . \\
\hline 7 & A3 & . & . & . \\
\hline 8 & A2 & . & . & . \\
\hline 9 & A1 & . & . & . \\
\hline 10 & AO & . & . & . \\
\hline 11 & D0 & . & . & . \\
\hline 12 & D1 & . & . & . \\
\hline 13 & D2 & . & . & . \\
\hline 14 & Vss & . & . & . \\
\hline 15 & D3 & . & . & . \\
\hline 16 & D4 & . & . & . \\
\hline 17 & D5 & . & . & . \\
\hline 18 & D6 & . & . & . \\
\hline 19 & D7 & . & . & . \\
\hline 20 & Chip enable & . & . & . \\
\hline 21 & A10 & . & . & . \\
\hline 22 & Output enable & . & . & . \\
\hline 23 & A11 & . & . & . \\
\hline 24 & A9 & . & . & . \\
\hline 25 & A8 & . & . & . \\
\hline 26 & A13 & A13 & A13 & NC \\
\hline 27 & A14 & A14 & PGM & PGM \\
\hline 28 & Vcc & . & . & . \\
\hline
\end{tabular}

Figure 9. 27(C) 512, 256, 128 and 64 pin-outs
(Table shows the standard 28-pin EPROMs.
Blank entries indicate that the pin is the same as for the 27(C) 512.\()\)

\title{
ASSEMBLED LISTING OF THE EM64K CONTROL PROGRAM
}
\begin{tabular}{ll}
1 \\
2 \\
3 & \\
4 \\
5 \\
6 & \\
7 & \\
8 & \\
9 & \\
10 & \\
11 & \\
12 & \\
13 & \\
14 & \\
15 & 00000000 \\
16 & 00000001 \\
17 & 00000002 \\
18 & 00000003 \\
19 & 00000004 \\
20 & 00000005 \\
21 & 00000006 \\
22 & 00000007 \\
23 & 00000008 \\
24 & 00000009 \\
25 & 0000000 e \\
26 & 00000012 \\
27 & \\
28 & \\
29 & 0
\end{tabular}



em64k.as5

\begin{tabular}{|c|c|c|c|c|c|c|c|}
\hline \multicolumn{3}{|l|}{225} & \multicolumn{5}{|l|}{***************************************************} \\
\hline \multicolumn{3}{|l|}{226} & \multicolumn{5}{|l|}{* *} \\
\hline \multicolumn{3}{|l|}{227} & * & \multicolumn{4}{|l|}{Build a beginning and ending address} \\
\hline \multicolumn{3}{|l|}{228} & * & \multicolumn{4}{|l|}{in TEMP.TEMP+1 \& ADDRH.ADDRL resp.} \\
\hline \multicolumn{3}{|l|}{229} & \multicolumn{5}{|l|}{*} \\
\hline \multicolumn{3}{|l|}{230} & \multicolumn{5}{|l|}{*****************************************************} \\
\hline \multicolumn{8}{|l|}{231} \\
\hline 232 & 0000e0db & 1931 & \multirow[t]{2}{*}{BLDRNG} & BCLR & \multicolumn{3}{|l|}{4.STAT} \\
\hline 233 & 0000e0dd & 1531 & & BCLR & 2.STAT & \multicolumn{2}{|l|}{EMULATION ADDRESS} \\
\hline 234 & 0000e0df & cde235 & & JSR & CLRTAB & \multicolumn{2}{|l|}{PRINT} \\
\hline 235 & 0000e0e2 & a6f4 & & LDA & \#SF4 & \multicolumn{2}{|l|}{- BA \({ }^{\text {. }}\)} \\
\hline 236 & 0000e0e4 & b724 & & STA & \multicolumn{3}{|l|}{DTABL+4} \\
\hline 237 & 0000e0e6 & a677 & & LDA & \multicolumn{3}{|l|}{\#\$77} \\
\hline 238 & 0000e0e8 & b725 & & STA & \multicolumn{3}{|l|}{DTABL+5} \\
\hline 239 & 0000e0ea & cdelec & & JSR & \multicolumn{3}{|l|}{DISTAB} \\
\hline 240 & 0000e0ed & cde5be & & JSR & BLDADR & \multicolumn{2}{|l|}{GET SOURCE ADDR.} \\
\hline 241 & 0000e0f0 & 2423 & & BCC & BLDRN1 & \multicolumn{2}{|l|}{VALID?} \\
\hline 242 & 0000e0f2 & b630 & & LDA & ADORH & \multicolumn{2}{|l|}{YES} \\
\hline 243 & 0000e0f4 & b726 & & STA & TEMP & \multicolumn{2}{|l|}{SAVE IT} \\
\hline 244 & 0000e0f6 & b62b & & LDA & \multicolumn{3}{|l|}{ADDRL} \\
\hline 245 & 0000e0f8 & b727 & & STA & \multicolumn{3}{|l|}{TEMP + 1} \\
\hline 246 & 0000e0fa & cde570 & & JSR & LOAD & \multicolumn{2}{|l|}{FETCH OPCODE OF INSTR.} \\
\hline 247 & 0000e0fd & b72f & & STA & W6 & \multicolumn{2}{|l|}{SAVE IT} \\
\hline 248 & 0000e0ff & cde235 & & JSR & CLRTAB & & \\
\hline 249 & 0000e102 & a6f1 & & LDA & \#\$F1 & \multicolumn{2}{|l|}{PRINT 'EA'} \\
\hline 250 & 0000e104 & b724 & & STA & \multicolumn{3}{|l|}{DTABL+4} \\
\hline 251 & 0000e106 & a677 & & LOA & \multicolumn{3}{|l|}{\#\$77} \\
\hline 252 & 0000e108 & b725 & & STA & \multicolumn{3}{|l|}{DTABL+5} \\
\hline 253 & 0000e10a & cdelec & & JSR & \multicolumn{3}{|l|}{DISTAB} \\
\hline 254 & 0000e10d & cde5be & & JSR & BLDADR & \multicolumn{2}{|l|}{GET DESTINATION ADDR} \\
\hline 255 & 0000e110 & 2403 & & BCC & BLDRN1 & \multicolumn{2}{|l|}{VALID?} \\
\hline 256 & 0000e112 & b630 & & LDA & \multirow[t]{2}{*}{ADDRH} & \multicolumn{2}{|l|}{YES} \\
\hline 257 & 0000e114 & 81 & & RTS & & \multicolumn{2}{|l|}{InYalid} \\
\hline 258 & 0000el15 & 1831 & BLDRN1 & BSET & 4. STAT & \multicolumn{2}{|l|}{INVALID} \\
\hline 259 & 0000e117 & 81 & & \multicolumn{4}{|l|}{RTS} \\
\hline \multicolumn{8}{|l|}{260 ( 26} \\
\hline 261 & & & \multicolumn{5}{|l|}{***************************************************} \\
\hline 262 & & & \multicolumn{5}{|l|}{* *} \\
\hline 263 & & & * & \multicolumn{4}{|l|}{Display message.} \\
\hline 264 & & & \multicolumn{5}{|l|}{*} \\
\hline 265 & & & \multicolumn{5}{|l|}{} \\
\hline \multicolumn{8}{|l|}{266} \\
\hline 267 & 0000e118 & bf2f & \multirow[t]{2}{*}{DISP} & STX & \multicolumn{3}{|l|}{W6} \\
\hline 268 & 0000el1a & \(3 f 33\) & & CLR & \multicolumn{3}{|l|}{COUNT} \\
\hline 269 & 0000el1c & be2f & DISLP & LDX & \multicolumn{3}{|l|}{W6} \\
\hline 270 & 0000elle & d6el32 & & LDA & \multicolumn{3}{|l|}{DLOAD.X} \\
\hline 271 & 0000el21 & be33 & & LDX & \multicolumn{3}{|l|}{COUNT} \\
\hline 272 & 0000el23 & e720 & & STA & \multicolumn{3}{|l|}{DTABL. X} \\
\hline 273 & 0000el25 & 3 c 2 f & & INC & \multicolumn{3}{|l|}{W6} \\
\hline 274 & 0000e127 & 3c33 & & INC & \multicolumn{3}{|l|}{COUNT} \\
\hline 275 & 0000e129 & b633 & & LDA & \multicolumn{3}{|l|}{COUNT} \\
\hline 276 & 0000e12b & a106 & & CMP & \multicolumn{3}{|l|}{\#6} \\
\hline 277 & 0000e12d & 25ed & & BLO & \multicolumn{3}{|l|}{DISLP} \\
\hline 278 & 0000e12f & ccelec & & JMP & \multicolumn{3}{|l|}{DISTAB} \\
\hline \multicolumn{8}{|l|}{279} \\
\hline 280 & 0000el32 & 0000d0d777e6 & DLOAD & FCB & \multicolumn{3}{|l|}{0.0.5D0.\$D7.577.5E6} \\
\hline 281 & 0000e138 & d6f1600671b6 & VERF & FCB & \multicolumn{3}{|l|}{\$06.\$F1.\$60.506.\$71.\$B6} \\
\hline
\end{tabular}
em64k.as5
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{283} \\
\hline 284 & & \\
\hline \multicolumn{3}{|l|}{285} \\
\hline \multicolumn{3}{|l|}{286} \\
\hline \multicolumn{3}{|l|}{287} \\
\hline \multicolumn{3}{|l|}{288} \\
\hline 289 & 0000e13e & ad9b \\
\hline 290 & 0000e140 & 08313e \\
\hline 291 & 0000e143 & b62b \\
\hline 292 & 0000e145 & a002 \\
\hline 293 & 000 Cel 147 & b72b \\
\hline 294 & 0000e149 & D630 \\
\hline 295 & 0000 e 14 b & a 200 \\
\hline 296 & 0000e14d & b730 \\
\hline 297 & 0000e14f & b62b \\
\hline 298 & 0000el51 & b027 \\
\hline 299 & 0000e153 & b72b \\
\hline 300 & 0000e155 & b630 \\
\hline 301 & 0000e157 & b226 \\
\hline 302 & 0000e159 & b730 \\
\hline 303 & 0000e15b & b62f \\
\hline 304 & 0000e15d & allf \\
\hline 305 & 0000el5f & 234e \\
\hline 306 & 0000e161 & b630 \\
\hline 307 & 0000e163 & alff \\
\hline 308 & 0000e165 & 270b \\
\hline 309 & 0000e167 & 4d \\
\hline 310 & 0000e168 & 2674 \\
\hline 311 & 0000el6a & b62b \\
\hline 312 & 0000e16c & a17f \\
\hline 313 & 0000el6e & 226e \\
\hline 314 & 0000e170 & 200a \\
\hline \multicolumn{3}{|l|}{315} \\
\hline 316 & 000vel72 & b62b \\
\hline 317 & & \\
\hline 318 & 0000el74 & alff \\
\hline 319 & 0000e176 & 2766 \\
\hline \multicolumn{3}{|l|}{320} \\
\hline 321 & 0000e178 & al80 \\
\hline 322 & 0000e17a & 2562 \\
\hline 323 & 0000e17c & ad06 \\
\hline 324 & 0000e17e & cce000 \\
\hline \multicolumn{3}{|l|}{325} \\
\hline 326 & 0000e181 & cce04e \\
\hline
\end{tabular}
em64k.as5
\begin{tabular}{|c|c|c|}
\hline 328 & & \\
\hline 329 & 0000e184 & cde235 \\
\hline 330 & 0000e187 & a6d6 \\
\hline 331 & 0000el89 & b720 \\
\hline 332 & 0000e18b & a6b5 \\
\hline 333 & 0000e18d & b721 \\
\hline 334 & 0000e18f & a6f1 \\
\hline 335 & 0000e191 & b722 \\
\hline 336 & 0000e193 & a6e6 \\
\hline 337 & 0000e195 & b723 \\
\hline 338 & 0000e197 & b62b \\
\hline 339 & 0000e199 & cde5f2 \\
\hline 340 & 0000e19c & 97 \\
\hline 341 & 0000e19d & b627 \\
\hline 342 & 0000e19f & ab01 \\
\hline 343 & 0000elal & b72b \\
\hline 344 & 0000ela3 & b626 \\
\hline 345 & 0000ela5 & a900. \\
\hline 346 & 0000ela7 & b730 \\
\hline 347 & 0000ela9 & 9 f \\
\hline 348 & 0000elaa & 1531 \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|c|c|c|c|}
\hline & 0000elac & \multirow[t]{2}{*}{cce562} & & JMP & STORE & \\
\hline \multicolumn{6}{|l|}{350} & \\
\hline 351 & 0000elaf & b62b & OFFST1 & LDA & ADORL & ADJUST FOR \\
\hline 352 & 0000elbl & a001 & & SUB & \#1 & BIT BRANCH \\
\hline 353 & 0000elb3 & b72b & & STA & ADDRL & \\
\hline 354 & 0000elb5 & b630 & & LDA & ADDRH & \\
\hline 355 & 0000elb7 & a200 & & SBC & \#0 & \\
\hline 356 & 0000elb9 & b730 & & STA & ADORH & \\
\hline 357 & 0000elbb & alff & & CMP & \#SFF & NEG OFFSET? \\
\hline 358 & 0000 elbd & 270b & & BEO & OFFST3 & YES \\
\hline 359 & 0000elbf & 4d & & TSTA & CHECK FOR & \\
\hline 360 & 0000elc0 & 261 c & & BNE & OVRERR & +/- 0 AND -1 \\
\hline 361 & 0000elc2 & b62b & & LDA & ADORL & \\
\hline 362 & 0000elc4 & al7f & & CMP & \#\$7F & \\
\hline 363 & 0000elc6 & 2216 & & BHI & OVRERR & \\
\hline 364 & 0000elc8 & 200a & & BRA & OK2 & \\
\hline \multicolumn{7}{|l|}{365} \\
\hline 366 & 0000elca & b62b & OFFST3 & LDA & ADORL & \\
\hline 367 & 0000elcc & alfe & & CMP & \#\$FE & \\
\hline 368 & 0000elce & 240e & & BHS & OVRERR & \\
\hline 369 & 0000eldo & a 180 & & CMP & \#\$80 & \\
\hline 370 & 0000eld2 & 250a & & BLO & OVRERR & \\
\hline \multicolumn{7}{|l|}{371} \\
\hline 372 & 0000eld4 & 3 c 27 & OK2 & INC & TEMP+1 & \\
\hline 373 & 0000eld6 & 2602 & & BNE & OFFITS & \\
\hline 374 & 0000eld8 & 3c26 & & INC & TEMP & \\
\hline 375 & 0000elda & ada 8 & OFFITS & BSR & USE & PRINT IF VALID \\
\hline 376 & 0000eldc & 200b & & BRA & SCJMP & \\
\hline \multicolumn{7}{|l|}{377} \\
\hline 378 & 0000elde & a6d7 & OVRERR & LDA & \#\$07 & PRINT "OR" \\
\hline 379 & 0000ele0 & b724 & & STA & DTABL+4 & \\
\hline 380 & 0000ele2 & a660 & & LDA & \#\$60 & \\
\hline 381 & 0000ele4 & b725 & & STA & DTABL+5 & \\
\hline 382 & 0000ele6 & cde616 & & JSR & PRTADR & \\
\hline 383 & 0000ele9 & cce000 & SCJMP & JMP & SCAN & \\
\hline \multicolumn{7}{|l|}{em64k.as5} \\
\hline \multicolumn{3}{|l|}{385} & \multicolumn{4}{|l|}{***************************************************} \\
\hline \multicolumn{3}{|l|}{386} & * & & & \\
\hline \multicolumn{3}{|l|}{387} & * & Display & table con & \\
\hline \multicolumn{3}{|l|}{388} & * & & & \\
\hline \multicolumn{3}{|l|}{389} & \multicolumn{4}{|l|}{} \\
\hline \multicolumn{7}{|l|}{390} \\
\hline 391 & 0000elec & 1701 & DISTAB & BCLR & 3. PORTB & ENABLE (144115) LOW \\
\hline 392 & 0000elee & ae05 & & LDX & \#5 & \\
\hline 393 & 0000elfo & e620 & DISCHR & LDA & DTABL.X & LOAD DISPLAY \\
\hline \multicolumn{7}{|c|}{394} \\
\hline 395 & 0000elf2 & bf28 & NT1 & STX & W1 & SAVE INDEX \\
\hline 396 & 0000elf4 & 1 d 00 & & BCLR & 6. PORTA & CLEAR DATA \\
\hline 397 & 0000elf6 & ae08 & & LDX & \#8 & \\
\hline 398 & 0000elf8 & 48 & OIS1 & LSLA & & SET UP \\
\hline 399 & 0000elf9 & 2402 & & BCC & DIS2 & BIT OF \\
\hline 400 & 0000 elfb & 1 c 00 & & BSET & 6.PORTA & ACCUMULATOR \\
\hline 401 & 0000elfd & 1 e 00 & DIS2 & BSET & 7.PORTA & CLOCK \\
\hline 402 & 0000elff & \(1 \mathrm{f00}\) & & BCLR & 7.PORTA & IT \\
\hline 403 & 0000e201 & 1 d 00 & & BCLR & 6.PORTA & CLEAR DaTA \\
\hline 404 & 0000e203 & 5a & & DECX & & COMPLETE? \\
\hline 405 & 0000e204 & 26f2 & & BNE & DIS1 & NO \\
\hline 406 & 0000e206 & be28 & & LDX & W1 & RESTORE INDEX \\
\hline 407 & 0000e208 & 5a & & DECX & & \\
\hline 408 & 0000e209 & \(2 \mathrm{ae5}\) & & BPL & DISCHR & \\
\hline 409 & 0000e20b & 1601 & & BSET & 3.PORTB & ENABLE (144115) HIGH \\
\hline 410 & 0000e20d & 81 & & RTS & & \\
\hline \multicolumn{7}{|l|}{411} \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{412} \\
\hline 413 & & \\
\hline \multicolumn{3}{|l|}{414} \\
\hline \multicolumn{3}{|l|}{415} \\
\hline \multicolumn{3}{|l|}{416} \\
\hline \multicolumn{3}{|l|}{417} \\
\hline 418 & 0000e20e & 1201 \\
\hline 419 & 0000 e 210 & 0e3002 \\
\hline 420 & 0000 e 213 & 1301 \\
\hline 421 & 0000e215 & 1001 \\
\hline 422 & 0000e217 & 0c3002 \\
\hline 423 & 0000e21a & 1101 \\
\hline 424 & 0000e21c & be30 \\
\hline 425 & 0000e21e & bf2a \\
\hline 426 & 0000 e 220 & 1c2a \\
\hline 427 & 0000e222 & 1f2a \\
\hline \multicolumn{3}{|l|}{428} \\
\hline 429 & 0000e224 & 0a3108 \\
\hline 430 & 0000 e 227 & aec 7 \\
\hline 431 & 0000e229 & bf29 \\
\hline 432 & 0000e22b & bd29 \\
\hline 433 & 0000e22d & b72d \\
\hline 434 & 0000e22f & aec 6 \\
\hline 435 & 0000e231 & bf29 \\
\hline \multicolumn{3}{|l|}{436} \\
\hline 437 & 0000e233 & bc29 \\
\hline
\end{tabular}
em64k.as5
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{439} \\
\hline 440 & & \\
\hline \multicolumn{3}{|l|}{441} \\
\hline \multicolumn{3}{|l|}{442} \\
\hline \multicolumn{3}{|l|}{443} \\
\hline \multicolumn{3}{|l|}{444} \\
\hline 445 & 0000e235 & ae05 \\
\hline 446 & 0000e237 & \(6 f 20\) \\
\hline 447 & 0000e239 & 5a \\
\hline 448 & 0000e23a & 2 afb \\
\hline 449 & 0000e23c & 81 \\
\hline \multicolumn{3}{|l|}{450} \\
\hline \multicolumn{3}{|l|}{451} \\
\hline \multicolumn{3}{|l|}{452} \\
\hline \multicolumn{3}{|l|}{453} \\
\hline \multicolumn{3}{|l|}{454} \\
\hline \multicolumn{3}{|l|}{455} \\
\hline \multicolumn{3}{|l|}{456} \\
\hline 457 & 0000e23d & cde235 \\
\hline 458 & 0000e240 & a6f1 \\
\hline 459 & 0000e242 & b720 \\
\hline 460 & 0000e244 & a673 \\
\hline 461 & 0000e246 & b721 \\
\hline 462 & 0000e248 & a663 \\
\hline 463 & 0000e24a & b723 \\
\hline 464 & 0000e24c & cdelec \\
\hline 465 & 0000e24f & cde05f \\
\hline 466 & 0000e252 & 24fb \\
\hline 467 & 0000e254 & al62 \\
\hline 468 & 0000e256 & 2703 \\
\hline 469 & 0000e258 & cce04e \\
\hline \multicolumn{3}{|l|}{470} \\
\hline 471 & 0000e25b & a628 \\
\hline 472 & 0000e25d & b701 \\
\hline 473 & 0000e25f & a6f1 \\
\hline 474 & 0000e261 & b720 \\
\hline 475 & 0000e263 & a6d6 \\
\hline 476 & 0000e265 & b721 \\
\hline 477 & 0000e267 & a6d0 \\
\hline
\end{tabular}

\begin{tabular}{lll}
528 \\
529 & & \\
530 & \\
531 & \\
532 & \\
533 & & \\
534 & \(0000 e 2 c 0\) & \(1 c 31\) \\
535 & \(0000 e 2 c 2\) & 1431 \\
536 & \(0000 e 2 c 4\) & \(a 6 d 7\) \\
537 & \(0000 e 2 c 6\) & \(b 720\) \\
538 & \(0000 e 2 c 8\) & \(a 671\) \\
539 & \(0000 e 2 c a\) & \(b 721\) \\
540 & \(0000 e 2 c c\) & \(b 722\) \\
541 & \(0000 e 2 c e\) & \(3 f 23\) \\
542 & \(0000 e 2 d 0\) & \(3 f 2 a\) \\
543 & \(0000 e 2 d 2\) & \(3 f 30\) \\
544 & \(0000 e 2 d 4\) & \(a 639\) \\
545 & \(0000 e 2 d 6\) & \(b 72 b\) \\
546 & \(0000 e 2 d 8\) & \(c c e 506\)
\end{tabular}
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\begin{tabular}{lll} 
DUMP9 & JSR & CLRTAB \\
& JSR & DISTAB \\
& LDA & \# \(\$ 58\) \\
& STA & MORTB
\end{tabular}

REAL ADDRESS (NO OFFSET)

NEXT PAGE

LAST PAGE ?
YES
GETCMD

ADDRL
ADDRH
LLPG LDX ADDRH
YES

Al5 HIGH
Al4 LOW
READ FROM AUXILIARY SOCKET
Al5 LOW
Al4 HIGH
WRITE TO EMULATION RAM
JSR STORE
INC ADDRL
BNE SKPH9
INC ADDRH
SKPH9 LDA AODRH
\#\$40 LAST ADDRESS \$3FFF
LLPG FINISHED ?
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{590} \\
\hline \multicolumn{3}{|l|}{591} \\
\hline \multicolumn{3}{|l|}{592} \\
\hline \multicolumn{3}{|l|}{593} \\
\hline \multicolumn{3}{|l|}{594} \\
\hline \multicolumn{3}{|l|}{595} \\
\hline 596 & 0000e31b & 1 a 31 \\
\hline 597 & 0000e31d & ae06 \\
\hline 598 & 0000e31f & 2003 \\
\hline 599 & 0000e321 & 1b31 \\
\hline 600 & 0000e323 & \(5 f\) \\
\hline 601 & 0000e324 & a681 \\
\hline 602 & 0000e326 & b72c \\
\hline 603 & 0000e328 & cdell8 \\
\hline \multicolumn{3}{|l|}{604} \\
\hline 605 & 0000e32b & ad5f \\
\hline 606 & 0000e32d & al53 \\
\hline 607 & 0000e32f & 26fa \\
\hline 608 & 0000e331 & ad59 \\
\hline 609 & 0000e333 & al39 \\
\hline 610 & 0000e335 & 276 f \\
\hline 611 & 0000e337 & al31 \\
\hline 612 & 0000e339 & \(26 f 0\) \\
\hline \multicolumn{3}{|l|}{613} \\
\hline 614 & 0000e33b & \(3 f 32\) \\
\hline 615 & 0000e33d & \(3 f 35\) \\
\hline 616 & 0000e33f & cde3bd \\
\hline 617 & 0000e342 & b736 \\
\hline \multicolumn{3}{|l|}{618} \\
\hline 619 & 0000e344 & cde3bd \\
\hline 620 & 0000e347 & b039 \\
\hline 621 & 0000e349 & b730 \\
\hline 622 & 0000e34b & cde3bd \\
\hline 623 & 0000e34e & b72b \\
\hline \multicolumn{3}{|l|}{624} \\
\hline 625 & 0000e350 & cde3bd \\
\hline 626 & 0000e353 & 271d \\
\hline 627 & 0000e355 & Ob310b \\
\hline 628 & 0000e358 & b72f \\
\hline 629 & 0000e35a & cde20e \\
\hline 630 & 0000e35d & b12f \\
\hline 631 & 0000e35f & 2658 \\
\hline 632 & 0000e361 & 2007 \\
\hline 633 & 0000e363 & cde20e \\
\hline 634 & 0000e366 & bl2d \\
\hline 635 & 0000e368 & 263 f \\
\hline 636 & 0000e36a & 3c2b \\
\hline 637 & 0000e36c & 2602 \\
\hline 638 & 0000e36e & 3 c 30 \\
\hline 639 & 0000e370 & 20de \\
\hline
\end{tabular}
em64k.as5
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|}
\hline 641 & & & \multicolumn{8}{|l|}{} \\
\hline 642 & & & \multicolumn{8}{|l|}{* *} \\
\hline 643 & & & & \multicolumn{4}{|l|}{Checksum byte \& error routine.} & & & * \\
\hline 644 & & & * & & & & & & & * \\
\hline 645 & & & \multicolumn{8}{|l|}{*******************************************************} \\
\hline \multicolumn{11}{|l|}{646} \\
\hline 647 & 0000e372 & bb32 & \multirow[t]{4}{*}{CHCK} & ADD & \multicolumn{6}{|l|}{CHKSUM} \\
\hline 648 & 0000e374 & b732 & & STA & CHKSUM & \multicolumn{5}{|c|}{DEBUG} \\
\hline 649 & 0000e376 & alff & & CMP & \#\$FF & \multicolumn{5}{|c|}{IS CHECKSUM BYTE OK ?} \\
\hline 650 & 0000e378 & 27b1 & & BEQ & INPUT & \multicolumn{5}{|c|}{YES. AND AGAIN} \\
\hline \multicolumn{11}{|l|}{651} \\
\hline 652 & 0000e37a & ae01 & & LDX & \#1 & & & & & \\
\hline 653 & 0000e37c & b738 & \multirow[t]{2}{*}{ERR} & STA & ERDAT & \multicolumn{5}{|c|}{DEBUG} \\
\hline 654 & 0000e37e & bf37 & & STX & ERTYP & \multicolumn{5}{|c|}{DEBUG} \\
\hline 655 & 0000e380 & 9 f & \multicolumn{3}{|c|}{TXA} & & & & & \\
\hline 656 & 0000e381 & cde5f2 & & JSR & PRTDAT & & & & & \\
\hline 657 & 0000e384 & 3 f 24 & & CLR & DTABL+4 & & & & & \\
\hline 658 & 0000e386 & cde616 & & JSR & PRTADR & & & & & \\
\hline 659 & 0000e389 & cce000 & & JMP & SCAN & & & & & \\
\hline \multicolumn{11}{|l|}{660} \\
\hline 661 & & & \multicolumn{8}{|l|}{} \\
\hline 662 & & & \multicolumn{7}{|l|}{*} & \\
\hline 663 & & & * & \multicolumn{6}{|l|}{Input routine, MC68HCO5E0 : 0.5 uS.} & * \\
\hline 664 & & & * & \multicolumn{6}{|l|}{Cycles per bit at 9600 baud : 208} & * \\
\hline 665 & & & * & & & & & & & \\
\hline 666 & & & \multicolumn{8}{|l|}{} \\
\hline \multicolumn{11}{|l|}{667} \\
\hline 668 & 0000e38c & ad60 & I NCHD & BSR & DEL191 & 191 & & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{IS LINE HIGH?}} \\
\hline 669 & 0000e38e & 0501 fd & \multirow[t]{2}{*}{INCH} & BRCLR & 2.PORTB.* & 5 & & & & \\
\hline 670 & 0000e391 & 0401fd & & BRSET & 2.PORTB.* & 5 & & \multicolumn{3}{|l|}{YES. WAIT FOR START} \\
\hline 671 & 0000e394 & ae07 & & LDX & \#7 & 2 & 6 & \multicolumn{3}{|l|}{7 data bits to read} \\
\hline 672 & 0000e396 & bf33 & & STX & COUNT & 4 & 10 & & & \\
\hline 673 & 0000e398 & ad58 & & BSR & DEL110 & 110 & 120 & \multicolumn{3}{|l|}{+/-3 OF 1st BI} \\
\hline \multicolumn{11}{|l|}{674} \\
\hline 675 & 0000e39a & ad52 & \multirow[t]{2}{*}{I NBT} & BSR & OEL191 & \multicolumn{2}{|l|}{191} & \multicolumn{3}{|l|}{+120-208=103} \\
\hline 676 & 0000e39c & 050100 & & BRCLR & 2.PORTB.ZER & 5 & 196 & CYC 2 & (105) & REA \\
\hline 677 & 0000e39f & 46 & \multirow[t]{3}{*}{ZER} & RORA & & 3 & 199 & \multicolumn{3}{|l|}{\multirow[t]{3}{*}{SAVE BIT}} \\
\hline 678 & 0000e3a0 & 3a33 & & DEC & COUNT & 5 & 204 & & & \\
\hline 679 & 0000e3a2 & \(26 \mathrm{f6}\) & & BNE & INBT & \multicolumn{2}{|r|}{\(3 \quad 207\)} & & & \\
\hline \multicolumn{11}{|l|}{680} \\
\hline 681 & 0000e3a4 & 44 & & & & 3 & 16 & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{MSB A ZERO}} \\
\hline 682 & 0000e3a5 & 81 & \multicolumn{3}{|c|}{RTS} & \multicolumn{2}{|r|}{\(6 \quad 22\)} & & & \\
\hline 683 & & & \multicolumn{2}{|l|}{} & & & & & & \\
\hline 684 & 0000e3a6 & cce04e & NINE & JMP & \multicolumn{6}{|l|}{GETCMD} \\
\hline 685 & & & & & & & & & & \\
\hline 686 & 0000e3a9 & ae02 & \multirow[t]{2}{*}{ERR2} & LDX & \#2 & \multicolumn{5}{|c|}{READBACK FROM RAM} \\
\hline 687 & 0000e3ab & 20cf & & BRA & ERR & & & & & \\
\hline 688 & 0000e3ad & ae03 & \multirow[t]{2}{*}{ERR3} & LDX & \#3 & \multicolumn{5}{|c|}{LESS THAN ASCII 0} \\
\hline 689 & 0000e3af & 20cb & & BRA & ERR & & & & & \\
\hline 690 & 0000e3b1 & ae04 & \multirow[t]{2}{*}{ERR4} & LDX & \#4 & \multicolumn{5}{|c|}{BETWEEN ASCII 9 \& \(A\)} \\
\hline 691 & 0000e3b3 & 20c7 & & BRA & ERR & & & & & \\
\hline 692 & 0000e3b5 & ae05 & \multirow[t]{2}{*}{ERR5} & LDX & \#5 & \multicolumn{5}{|c|}{MORE THAN ASCII F} \\
\hline 693 & 0000e3b7 & 20c3 & & BRA & ERR & & & & & \\
\hline 694 & 0000e3b9 & ae07 & \multirow[t]{2}{*}{ERR7} & LDX & \#7 & \multicolumn{5}{|c|}{\multirow[t]{2}{*}{VERIFY ERROR}} \\
\hline 695 & 0000e3bb & 20bf & & BRA & ERR & & & & & \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{697} \\
\hline 698 & & \\
\hline \multicolumn{3}{|l|}{699} \\
\hline \multicolumn{3}{|l|}{700} \\
\hline \multicolumn{3}{|l|}{701} \\
\hline \multicolumn{3}{|l|}{702} \\
\hline 703 & 0000e3bd & adcd \\
\hline 704 & 0000e3bf & ad17 \\
\hline 705 & 0000 e 3 cl & 48 \\
\hline 706 & 0000 e 3 c 2 & 48 \\
\hline 707 & 0000e3c3 & 48 \\
\hline 708 & 0000 e 3 c 4 & 48 \\
\hline 709 & 0000 e 3 c 5 & b734 \\
\hline 710 & 0000 e 3 c 7 & b635 \\
\hline 711 & 0000 e 3 c 9 & bb32 \\
\hline 712 & 0000 e3cb & b732 \\
\hline 713 & 0000e3cd & adbd \\
\hline 714 & 0000e3cf & ad07 \\
\hline 715 & 0000e3d1 & bb34 \\
\hline 716 & 0000 e 3 d 3 & b735 \\
\hline 717 & 0000e3d5 & 3a36 \\
\hline 718 & 0000e3d7 & 81 \\
\hline \multicolumn{3}{|l|}{719} \\
\hline 720 & 0000e3d8 & a 130 \\
\hline 721 & 0000e3da & 25d1 \\
\hline 722 & 0000e3dc & a 139 \\
\hline 723 & 0000e3de & 2203 \\
\hline 724 & 0000 e3e0 & a030 \\
\hline 725 & 0000 e 3 e 2 & 81 \\
\hline \multicolumn{3}{|l|}{726} \\
\hline 727 & 0000e3e3 & a 141 \\
\hline 728 & 0000 e3e5 & 25ca \\
\hline 729 & 0000e3e7 & a 146 \\
\hline 730 & 0000 e3e9 & 22ca \\
\hline 731 & 0000 e3eb & a037 \\
\hline 732 & 0000e3ed & 81 \\
\hline \multicolumn{3}{|l|}{733} \\
\hline 734 & 0000 3ee & aeld \\
\hline 735 & 0000e3f0 & 2002 \\
\hline 736 & 0000 e ff 2 & aelo \\
\hline 737 & 0000 e 3 f 4 & 5a \\
\hline 738 & 0000 e 3 f5 & 26fd \\
\hline 739 & 0000 e 3 f 7 & 81 \\
\hline
\end{tabular}
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\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{741} \\
\hline \multicolumn{3}{|l|}{742} \\
\hline \multicolumn{3}{|l|}{743} \\
\hline \multicolumn{3}{|l|}{744} \\
\hline \multicolumn{3}{|l|}{745} \\
\hline \multicolumn{3}{|l|}{746} \\
\hline 747 & 0000e3f8 & 1406 \\
\hline 748 & 0000e3fa & cde0db \\
\hline 749 & 0000e3fd & 0831a6 \\
\hline 750 & 0000e400 & be26 \\
\hline 751 & 0000e402 & b726 \\
\hline 752 & 0000e404 & bf30 \\
\hline 753 & 0000e406 & b62b \\
\hline 754 & 0000e408 & be27 \\
\hline 755 & 0000e40a & bf2b \\
\hline 756 & 0000e40c & b727 \\
\hline 757 & 0000e40e & 1 f 31 \\
\hline 758 & 0000e410 & 1531 \\
\hline \multicolumn{3}{|l|}{759} \\
\hline 760 & 0000e412 & b627 \\
\hline 761 & 0000e414 & b02b \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|c|c|c|}
\hline \multicolumn{6}{|l|}{* *} \\
\hline * & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{Byte input sub-routines.}} & \multicolumn{2}{|r|}{\multirow[t]{2}{*}{*}} \\
\hline * & & & & & \\
\hline \multicolumn{6}{|l|}{********************************************************} \\
\hline \multirow[t]{16}{*}{BYTEI} & BSR & INCHD & 22 & & MS NIBBLE \\
\hline & BSR & ASCII & 35 & 57 & WHAT WAS IT \\
\hline & LSLA & & 3 & & YES \\
\hline & LSLA & & 3 & & SHIFT \\
\hline & LSLA & & 3 & & IT \\
\hline & LSLA & & 3 & 69 & UP \\
\hline & STA & TMP1 & 4 & 71 & AND SAVE IT \\
\hline & LDA & TMP2 & 3 & 74 & RESTORE BYTE \\
\hline & ADD & CHKSUM & 3 & 79 & accumulate \\
\hline & STA & CHKSUM & 4 & 83 & IN CHECKSUM byte \\
\hline & BSR & INCHD & 22 & & LS NIBBLE \\
\hline & BSR & ASCII & 35 & 57 & WHAT WAS IT \\
\hline & ADD & TMP1 & 3 & 60 & ADD TO MS NIBBLE \\
\hline & STA & TMP2 & 4 & 64 & SAVE BYTE \\
\hline & DEC & BCNT & 5 & 69 & \multirow[t]{2}{*}{DECREMENT BYTE COUNT} \\
\hline & RTS & & 6 & 75 & \\
\hline \multirow[t]{6}{*}{ASCII} & CMP & \#\$30 & 2 & & BEFORE ZERO ? \\
\hline & BLO & ERR3 & 3 & 5 & YES. NOT LEGAL \\
\hline & CMP & \#\$39 & 2 & 7 & AFTER NINE \\
\hline & BHI & MT9 & 3 & 10 & YES TRY A-F \\
\hline & SUB & \#\$30 & 3 & 13 & \multirow[t]{2}{*}{0-9. CONVERT TO HEX} \\
\hline & RTS & & 6 & 19 & \\
\hline \multirow[t]{5}{*}{MT9} & CMP & \#\$41 & 2 & 12 & \multirow[t]{5}{*}{\begin{tabular}{l}
BEFORE A ? \\
YES. NOT LEGAL \\
AFTER F ? \\
YES. NOT LEGAL \\
A-F. CONVERT TO HEX
\end{tabular}} \\
\hline & BLO & ERR4 & 3 & 15 & \\
\hline & CMP & \#\$46 & 2 & 17 & \\
\hline & BHI & ERR5 & 3 & 20 & \\
\hline & SUB & \#\$37 & 3 & 23 & \\
\hline NFND & RTS & & 6 & 29 & \\
\hline DEL191 & LDX & \#29 & 2 & & \\
\hline & BRA & delay & 3 & 5 & \\
\hline DELI10 & LDX & \#16 & 2 & & \\
\hline delay & DECX & & 3 & & \\
\hline & BNE & DELAY & 3 & & \(6 \times X\) \\
\hline & RTS & & 6 & & 12+6X (INC BSR) \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 762 & 0000e416 & b72f & & STA & W6 & DIFFERENCE LSB \\
\hline 763 & 0000e418 & D626 & & LDA & TEMP & END MSB \\
\hline 764 & 0000e41a & b230 & & SBC & ADDR & CURRENT MSB \\
\hline 765 & 0000e41c & 260d & & BNE & LOTS & MSB ZERO ? \\
\hline 766 & 0000e41e & D62f & & LDA & W6 & YES. LOOK AT LSB \\
\hline 767 & 0000e420 & 4 c & & INCA & & ADJUST \\
\hline 768 & 0000e421 & 2708 & & BEQ & LOTS & WAS \$FF ? \\
\hline 769 & 0000e423 & a 120 & & CMP & \#\$20 & MORE THAN 23 ? \\
\hline 770 & 0000e425 & 2204 & & BHI & LOTS & IF SO USE 23 \\
\hline 771 & 0000e427 & 1 e 31 & & BSET & 7.STAT & NO. LAST S1 RECORD \\
\hline 772 & 0000e429 & 2002 & & BRA & LTE20 & LESS THAN OR EQUAL TO 20 \\
\hline 773 & & & & & & \\
\hline 774 & 0000e42b & a620 & LOTS & LDA & \#\$20 & \\
\hline 775 & 0000e42d & ab03 & LTE20 & ADD & \#\$03 & ADD BYTE CNUNT \& ADDRESS \\
\hline 776 & 0000e42f & b736 & & STA & BCNT & No. BYTES THIS S1 RECORD \\
\hline 777 & 0000e431 & a653 & & LDA & \#'S' & S \\
\hline 778 & 0000e433 & cde484 & & JSR & OUCH & \\
\hline 779 & 0000e436 & a631 & & LDA & \#'1' & 1 \\
\hline 780 & 0000e438 & ad4a & & BSR & OUCH & \\
\hline 781 & 0000e43a & 3 f 32 & & CLR & CHKSUM & \\
\hline 782 & 0000e43c & D636 & & LDA & BCNT & BYTE COUNT \\
\hline 783 & 0000e43e & ad72 & & BSR & BYTEO & \\
\hline 784 & 0000e440 & b630 & & LDA & ADDRH & ADDRESS HIGH \\
\hline 785 & 0000e442 & ad6e & & BSR & BYTEO & \\
\hline 786 & 0000 e444 & b62b & & LDA & ADDRL & \\
\hline 787 & 0000e446 & ad6a & & BSR & BYTEO & ADDRESS LOW \\
\hline 788 & & & & & & \\
\hline 789 & 0000e448 & cde570 & L00P2 & JSR & LOAD & GET BYfE \\
\hline 790 & 0000e44b & 3c2b & & INC & ADDRL & INCREMENT AMDRESS \\
\hline 791 & 0000e44d & 2602 & & BNE & NOVR & OVERFLOW? \\
\hline 792 & 0000e44f & 3 c 30 & & INC & AODRH & YES. INC. HIGH BYTE \\
\hline 793 & 0000e451 & ad5f & NOVR & BSR & BYTEO & SEND BYTE \\
\hline 794 & 0000453 & 26f3 & & BNE & L00P2 & LAST BYTE ? \\
\hline \multicolumn{7}{|l|}{em64k.as5} \\
\hline 796 & & & \multicolumn{4}{|l|}{} \\
\hline 797 & & & * & & & * \\
\hline 798 & & & * & \multicolumn{2}{|l|}{Checksum byte.} & * \\
\hline 799 & & & * & & & * \\
\hline 800 & & & \multicolumn{4}{|l|}{} \\
\hline \multicolumn{7}{|r|}{801} \\
\hline 802 & 0000e455 & b632 & & LDA & CHKSUM & CHECKSUM \\
\hline 803 & 0000e457 & 43 & & COMA & & REQUIRED CHECKSUM BYTE \\
\hline 804 & 00004458 & ad58 & & BSR & BYTEO & SEND IT \\
\hline 805 & 0000e45a & ad22 & & BSR & CRLF & CRLF \\
\hline 806 & 0000e45c & 0f31b3 & & BRCLR & 7.STAT.LOOP1 & FINISHED ? \\
\hline \multicolumn{7}{|l|}{807} \\
\hline 808 & & & \multicolumn{4}{|l|}{} \\
\hline 809 & & & * & & & * \\
\hline 810 & & & \multicolumn{3}{|c|}{S9 record.} & * \\
\hline 811 & & & * & & & ** \\
\hline 812 & & & \multicolumn{4}{|l|}{*******************************************************} \\
\hline \multicolumn{7}{|l|}{813} \\
\hline 814 & 0000e45f & a653 & & LDA & \#'5* & S \\
\hline 815 & 0000e461 & ad21 & & BSR & OUCH & \\
\hline 816 & 0000e463 & a639 & & LDA & \#'9 \({ }^{\circ}\) & 9 \\
\hline 817 & 0000e465 & adld & & BSR & OUCH & \\
\hline 818 & 0000 e467 & a603 & & LDA & \#\$03 & 3 BYTES \\
\hline 819 & 0000e469 & ad47 & & BSR & BYTEO & \\
\hline 820 & 0000e46b & a600 & & LDA & \#500 & \\
\hline 821 & 0000e46d & ad43 & & BSR & BYFEO & DUMMY (0) \\
\hline 822 & 0000e46f & a600 & & LDA & \#500 & \\
\hline 823 & 0000e471 & ad3f & & BSR & BYTEO & ADDRESS \\
\hline 824 & 0000 e473 & a6fc & & LDA & \#\$FC & \\
\hline 825 & 0000e475 & ad3b & & BSR & BYTEO & CHECKSUM \\
\hline 826 & 0000e477 & ad05 & & BSR & CRLF & \\
\hline 827 & 0000e479 & 1506 & & BCLR & 2.PORTBD & BIT 2 INPUT \\
\hline
\end{tabular}


\begin{tabular}{|c|c|c|c|c|c|c|c|c|}
\hline & 0000e514 & 271a & & BEQ & ADRINC & \multicolumn{3}{|l|}{\multirow[b]{2}{*}{MEMORY ?}} \\
\hline 959 & 0000e516 & al13 & & CMP & \#\$13 & & & \\
\hline 960 & 0000e518 & 272e & & BEQ & ADRDEC & & & \\
\hline 961 & & & & & & & & \\
\hline & 0000e51a & al0f & & CMP & \#SOF & & & \\
\hline 963 & 0000e51c & 2208 & & BHI & CMDMDL & VALID HEX ? & & \\
\hline 964 & & & & & & & & \\
\hline 965 & 0000e51e & cde5f2 & MEMEX 1 & JSR & PRTDAT & PRINT IT & & \\
\hline 966 & 0000e521 & cde59d & & JSR & GETBY2 & SHIFT IN NEXT & & \\
\hline 967 & 0000e524 & 25f8 & & BCS & MEMEX1 & IF Valid try again & & \\
\hline 968 & 0000e526 & al11 & CMDMDL & CMP & \#\$11 & ENTER ? & & \\
\hline 969 & 0000e528 & 2614 & & BNE & MEMEX2 & NO & & \\
\hline 970 & 0000e52a & D629 & & LDA & W2 & RESTORE ACCA & & \\
\hline 971 & 0000e52c & ad34 & & BSR & STORE & YES STORE IT & & \\
\hline 972 & 0000e52e & 25d6 & & BCS & MEMEX3 & STORE VALID ? & & \\
\hline 973 & 0000e530 & 0c3125 & ADRINC & BRSET & 6.STAT.MEMEX4 & & & \\
\hline 974 & 0000e533 & 3c2b & & INC & ADDRL & YES GOTO & & \\
\hline 975 & 0000e535 & 2602 & & BNE & MEMEX5 & NEXT & & \\
\hline 976 & 0000e537 & 3 c 30 & & INC & ADDRH & & & \\
\hline 977 & 0000e539 & cde616 & MEMEX 5 & JSR & PRTADR & PRINT IT & & \\
\hline 978 & 0000e53c & 20c8 & & BRA & MEMEX3 & REPEAT & & \\
\hline 979 & 0000e53e & a113 & MEMEX2 & CMP & \#\$13 & \(M\) ? & & \\
\hline 980 & 0000e540 & 2616 & & BNE & MEMEX4 & NO & & \\
\hline 981 & 0000e542 & b629 & & LDA & W2 & & & \\
\hline 982 & 0000e544 & adic & & BSR & STORE & & & \\
\hline 983 & 0000e546 & 25be & & BCS & MEMEX3 & & & \\
\hline 984 & 0000e548 & 0c310d & ADRDEC & BRSET & 6.STAT.MEMEX4 & & & \\
\hline 985 & 0000e54b & 3d2b & & TST & ADDRL & YES THEN & & \\
\hline 986 & 0000e54d & 2602 & & BNE & CMDMB2 & GET PREVIOUS & & \\
\hline 987 & 0000e54f & 3a30 & & DEC & ADDRH & ADDRESS & & \\
\hline 988 & 0000e551 & 3a2b & CMDMB2 & DEC & ADDRL & & & \\
\hline 989 & 0000e553 & cde616 & & JSR & PRTADR & PRINT IT & & \\
\hline 990 & 0000e556 & 20ae & & BRA & MEMEX3 & REPEAT & & \\
\hline 991 & 0000e558 & 0d3102 & MEMEX4 & BRCLR & 6. STAT. NORM2 & & & \\
\hline 992 & 0000e55b & 3f2b & & CLR & ADDRL & & & \\
\hline 993 & 0000e55d & 1 d 31 & NORM2 & BCLR & 6. STAT & & & \\
\hline 994 & 0000e55f & cce04e & & JMP & GETCMD & & & \\
\hline \multicolumn{9}{|l|}{em64k.as5} \\
\hline 996 & & & \multicolumn{6}{|l|}{*********************************************} \\
\hline 997 & & & * & & & * & & \\
\hline 998 & & & * & LOAD/S & ORE AT ADDRH(EH) & - ADORL & & \\
\hline 999 & & & * & & & * & & \\
\hline 1000 & & & \multicolumn{6}{|l|}{*********************************************} \\
\hline \multicolumn{9}{|l|}{1001} \\
\hline 1002 & 0000e562 & aec 7 & \multirow[t]{2}{*}{STORE} & LDX & \#SC7 & SET-UP & & \\
\hline 1003 & 0000e564 & ad0c & & BSR & LDSTCM & ROUTINE & & \\
\hline 1004 & 0000e566 & b72d & & STA & W4 & TO 00 & & \\
\hline 1005 & 0000e568 & ad06 & & BSR & LOAD & TWO BYTE & & \\
\hline 1006 & 0000e56a & b12d & & CMP & W4 & \multicolumn{3}{|l|}{STORE} \\
\hline 1007 & 0000e56c & 2701 & & BEO & \multicolumn{4}{|l|}{STRTS} \\
\hline 1008 & 0000e56e & 99 & & SEC & & & & \\
\hline 1009 & 0000e56f & 81 & \multirow[t]{2}{*}{STRTS} & \multicolumn{5}{|l|}{RTS} \\
\hline 1010 & & & & & & & & \\
\hline 1011 & 0000e570 & aec 6 & LOAD & LDX & \#\$C6 & \multicolumn{3}{|l|}{SET-UP ROUTINE} \\
\hline 1012 & 0000e572 & bf29 & LDSTCM & STX & W2 & \multicolumn{3}{|l|}{TO DO} \\
\hline 1013 & 0000e574 & ae81 & & LDX & \#\$81 & \multicolumn{3}{|l|}{TWO BYTE} \\
\hline 1014 & 0000e576 & bf2c & & STX & W3 & \multicolumn{3}{|l|}{LOAD} \\
\hline 1015 & 0000e578 & 043120 & & BRSET & 2.STAT. NORM & \multicolumn{3}{|l|}{REAL ADDRESS ?} \\
\hline \multicolumn{9}{|l|}{1016} \\
\hline 1017 & 0000e57b & b72d & & STA & \multicolumn{4}{|l|}{W4} \\
\hline 1018 & 0000e57d & b630 & & LDA & \multicolumn{4}{|l|}{ADDRH} \\
\hline 1019 & 0000e57f & b039 & & SUB & \multicolumn{4}{|l|}{OFF} \\
\hline 1020 & 0000e581 & b72e & & STA & \multicolumn{4}{|l|}{W5} \\
\hline 1021 & 0000e583 & b62d & & LDA & \multicolumn{4}{|l|}{W4} \\
\hline 1022 & & & & & & & & \\
\hline 1023 & 0000e585 & 1201 & RMCC & BSET & 1. PORTB & 55 XFER A14 & A15 TO & O PORTB \\
\hline
\end{tabular}
\begin{tabular}{lll}
1024 & \(0000 e 587\) & \(0 e 2 e 02\) \\
1025 & \(0000 e 58 a\) & 1301 \\
1026 & \(0000 e 58 c\) & 1001 \\
1027 & \(0000 e 58 e\) & \(0 c 2 e 02\) \\
1028 & \(0000 e 591\) & 1101 \\
1029 & \(0000 e 593\) & be2e \\
1030 & \(0000 e 595\) & \(b f 2 a\) \\
1031 & \(0000 e 597\) & \(1 c 2 a\) \\
1032 & \(0000 e 599\) & \(1 f 2 a\) \\
1033 & \(0.000 e 59 b\) & \(b c 29\) \\
1034 & & \\
1035 & & \\
1036 & & \\
1037 & & \\
1038 & & \\
1039 & & \\
1040 & \(0000 e 59 d\) & \(b 729\) \\
1041 & 0000 \\
1042 & \(0000 e 59 f\) & \(a d 0 e\) \\
1043 & \(0000 e 5 a l\) & \(240 b\) \\
1044 & \(0000 e 5 a 3\) & 3829 \\
1045 & \(0000 e 5 a 5\) & 3829 \\
1046 & \(0000 e 5 a 7\) & 3829 \\
1047 & \(0000 e 5 a 9\) & 3829 \\
1048 & \(0000 e 5 a b\) & \(b a 29\) \\
1049 & \(0000 e 5 a d\) & 99 \\
1050 & \(0000 e 5 a e\) & 81
\end{tabular}
\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{em64k.as5} \\
\hline \multicolumn{3}{|l|}{1052} \\
\hline \multicolumn{3}{|l|}{1053} \\
\hline \multicolumn{3}{|l|}{1054} \\
\hline \multicolumn{3}{|l|}{1055} \\
\hline \multicolumn{3}{|l|}{1056} \\
\hline \multicolumn{3}{|l|}{1057} \\
\hline \multicolumn{3}{|l|}{1058} \\
\hline 1059 & 0000e5af & cde4ed \\
\hline 1060 & 0000e5b2 & 98 \\
\hline 1061 & 0000e5b3 & a 10 f \\
\hline 1062 & 0000e5b5 & 2201 \\
\hline 1063 & 0000e5b7 & 99 \\
\hline 1064 & 0000e5b8 & 81 \\
\hline \multicolumn{3}{|l|}{1065} \\
\hline \multicolumn{3}{|l|}{1066} \\
\hline \multicolumn{3}{|l|}{1067} \\
\hline \multicolumn{3}{|l|}{1068} \\
\hline \multicolumn{3}{|l|}{1069} \\
\hline \multicolumn{3}{|l|}{1070} \\
\hline \multicolumn{3}{|l|}{1071} \\
\hline \multicolumn{3}{|l|}{1072} \\
\hline 1073 & 0000e5b9 & cde235 \\
\hline 1074 & 0000e5bc & ad58 \\
\hline 1075 & 0000e5be & adef \\
\hline 1076 & 0000e5c0 & 250a \\
\hline 1077 & 0000e5c2 & al10 \\
\hline 1078 & 0000e5c4 & 272b \\
\hline 1079 & 0000e5c6 & al11 \\
\hline 1080 & 0000e5c8 & 2727 \\
\hline 1081 & 0000e5ca & 20ed \\
\hline 1082 & 0000e5cc & \(3 f 30\) \\
\hline 1083 & 0000e5ce & b72b \\
\hline 1084 & 0000e5d0 & ad44 \\
\hline
\end{tabular}


\begin{tabular}{llll} 
GETNYB & JSR & CHRIN & GET CHARACTER \\
& CLC & & \\
CMP & \#SOF & VALID HEX? \\
BHI & GETRET & NO \\
SEC & & YES
\end{tabular}

GETRET RT

\begin{tabular}{|c|c|c|}
\hline 1085 & 0000e5d2 & addb \\
\hline 1086 & 0000e5d4 & 2412 \\
\hline 1087 & 0000e5d6 & 48 \\
\hline 1088 & 0000e5d7 & 48 \\
\hline 1089 & 0000e5d8 & 48 \\
\hline 1090 & 0000e5d9 & 48 \\
\hline 1091 & 0000e5da & ae04 \\
\hline 1092 & 0000e5dc & 48 \\
\hline 1093 & 0000e5dd & 392b \\
\hline 1094 & 0000e5df & 3930 \\
\hline 1095 & 0000e5e1 & 5a \\
\hline 1096 & 0000 e 5 e 2 & 26f8 \\
\hline 1097 & 0000 e 5 e 4 & ad30 \\
\hline 1098 & 0000e5e6 & 20ea \\
\hline 1099 & 0000e5e8 & al10 \\
\hline 1100 & 0000e5ea & 2705 \\
\hline 1101 & 0000e5ec & al11 \\
\hline 1102 & 0000e5ee & 26e2 \\
\hline 1103 & 0000e5f0 & 99 \\
\hline 1104 & 0000e5f1 & 81 \\
\hline
\end{tabular}
em64k.as5
\begin{tabular}{lll}
1106 \\
1107 & \\
1108 & \\
1109 & \\
1110 & \\
1111 & \\
1112 & \\
1113 & & \\
1114 & \(0000 e 5 f 2\) & ae04 \\
1115 & \(0000 e 5 f 4\) & \(b f 28\) \\
1116 & \(0000 e 5 f 6\) & \(b 72 d\) \\
1117 & \(0000 e 5 f 8\) & 44 \\
1118 & \(0000 e 5 f 9\) & 44 \\
1119 & \(0000 e 5 f a\) & 44 \\
1120 & \(0000 e 5 f b\) & 44 \\
1121 & \(0000 e 5 f c\) & 97 \\
1122 & \(0000 e 5 f d\) & \(d 6 e 4 c d\) \\
1123 & \(0000 e 600\) & \(b e 28\) \\
1124 & \(0000 e 602\) & \(e 720\) \\
1125 & \(0000 e 604\) & \(b 62 d\) \\
1126 & \(0000 e 606\) & \(a 40 f\) \\
1127 & \(0000 e 608\) & 97 \\
1128 & \(0000 e 609\) & \(d 6 e 4 c d\) \\
1129 & \(0000 e 60 c\) & \(b e 28\) \\
1130 & \(0000 e 60 e\) & \(e 721\) \\
1131 & \(0000 e 610\) & \(c d e l e c\) \\
1132 & \(0000 e 613\) & \(b 62 d\) \\
1133 & \(0000 e 615\) & 81 \\
1134 & & \\
1135 & \(0000 e 616\) & b72e \\
1136 & \(0000 e 618\) & \(b f 2 c\) \\
1137 & \(0000 e 61 a\) & \(b 630\) \\
1138 & \(0000 e 61 c\) & \(5 f\) \\
1139 & \(0000 e 61 d\) & add5 \\
1140 & \(0000 e 61 f\) & \(b 62 b\) \\
1141 & \(0000 e 621\) & \(a e 02\) \\
1142 & \(0000 e 623\) & \(a d c f\) \\
1143 & \(0000 e 625\) & \(b 62 e\) \\
1144 & \(0000 e 627\) & \(b e 2 c\) \\
1145 & \(0000 e 629\) & 81 \\
1146 & & \\
10
\end{tabular}
\begin{tabular}{|c|c|c|c|}
\hline \multirow[t]{7}{*}{getal \({ }^{*}\)} & BSR & GETNYB & GET ANOTHER CHAR \\
\hline & BCC & GETARG & VALID? \\
\hline & ASLA & & YES \\
\hline & ASLA & & SHIFT IT IN \\
\hline & ASLA & & \\
\hline & ASLA & & \\
\hline & LDX & \#4 & \\
\hline \multirow[t]{7}{*}{GETASF} & ASLA & & \\
\hline & ROL & ADDRL & \\
\hline & ROL & ADDRH & \\
\hline & DECX & & \\
\hline & BNE & GETASF & \\
\hline & BSR & PRTADR & PRINT NEW ADDR \\
\hline & BRA & GETALP & GET ANOTHER CHAR \\
\hline \multirow[t]{5}{*}{GETARG} & CMP & \#\$10 & ESCAPE ? \\
\hline & BEQ & GETRTS & \\
\hline & CMP & \#\$11 & ENTER ? \\
\hline & BNE & GETALP & NO TRY AGAIN \\
\hline & SEC & & YES SET FLAG \\
\hline GETRTS & RTS & & \\
\hline
\end{tabular}

PRTDAT LDX \#R \# PRINT IN LAST TWO LCD DIGITS

PRTBYT STX W1
STA W4
LSRA
LSRA
LSRA
LSRA
TAX
LDA
LDX
STA
W1
DTABL.X
W4
\#\$0F

CTABL.X
W1
DTABL+1,X
DISTAB
W4

PRTADR STA W5 PRINT ADDRESS (FIRST 4 DIGITS)
11360000 e 618 bf2c
1137 0000e61a b630
1138 0000e61c \(5 f\)
11390000 e 61 d add5
11400000 e 61 f b62b
1141 0000e621 ae02
11420000 e 623 adcf
11430000 e 625 b62e
0000e627 be2c

1146
\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 1147 & & & *********** & ******* & ******* & ************ \\
\hline 1148 & & & * & & & * \\
\hline 1149 & & & MC68 & 5EO Vect & & \\
\hline 1150 & & & * & & & * \\
\hline 1151 & & & ************ & ******** & ******** & ************* \\
\hline 1152 & & & & & & \\
\hline 1153 & & & ORG & SFFF4 & & \\
\hline 1154 & & & & & & \\
\hline 1155 & 0000fff 4 & e022 & FDB & Start & SERIAL & \\
\hline 1156 & 0000fff6 & e022 & FDB & Start & TIMER B & \\
\hline 1157 & 0000fff 8 & e022 & FDB & Start & TIMER A & \\
\hline 1158 & 0000fffa & e04e & FDB & GETCMD & EXTERNA & Interrupt \\
\hline 1159 & 0000 fffc & e022 & FDB & Start & SWI & \\
\hline 1160 & 0000ffe & e022 & FDB & START & RESET & \\
\hline 1161 & & & END & & & \\
\hline
\end{tabular}

\title{
Driving LCDs with M6805 Microprocessors
}

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}

\section*{INTRODUCTION}

M6805 microprocessors include a wide range of parts with a large diversity of on-chip features. These include A/D and D/A convertors, serial interfaces, timers and display drivers. The display drive capability of the microprocessors range from none beyond I/O pins, through high current ports, to specialised display drivers for LCDs and vacuum fluorescent displays.

The MC68HC05M series have vacuum fluorescent drive capabilities up to 40 V . The MC68HC05L series include LCD drivers with capabilities ranging from the MC68HC05L6 (3 or 4 backplanes and 24 frontplanes) through the MC68HC05L7/9 with 8 or 16 backplanes and 60/40 frontplanes. The L9's 40 frontplanes can be expanded to 205 with three MC68HC68L9 expanders.

Microprocessors without special LCD circuitry can be used to drive single backplane LCDs directly but require regular software intervention if the requirement that the display receives only \(A C\) drive is to be met. Alternatively display driver chips can be used to interface microprocessors with single and multiple backplane displays.

This application note gives hardware and software examples for these different arrangements. The same methods also apply to other families of microprocessors, eg M6801 and M68HC11. The examples are arranged in the order of the number of backplanes.

\section*{SINGLE-BACKPLANE DISPLAYS}

Single-backplane displays are commonly used where the number of segments required is limited, usually using the 7 -segment format. They have the advantages over multiplexed displays of superior contrast and viewing angle and a wider range of operating voltage and temperature. They can be driven directly by microprocessors with the number of segments limited simply by the number of available pins which are (or can be configured as) autputs. An output pin is required for the backplane together with one for each segment. The ports are loaded with the segment data corresponding to the required display, as with any other peripheral being directly driven by \(1 / O\) lines. In this case, however, the microprocessor must complement the signals (backplane and frontplanes) at regular intervals, thus satisfying the requirement that the display receives an AC waveform with only a small DC component. It is possible for interrupts to alter the timing of these voltage reversals and the programmer must ensure that the resultant DC component does not exceed that above which the life of the display is reduced.

An alternative method of driving single-backplane displays from microprocessors is to use an LCD driver. Figure 1 shows a 6-digit 7-segment circuit using 3 MC144115P LCD drivers. These chips are driven serially and constitute a simple shift register giving the programmer full control over the display.

They can also be simply cascaded to drive a display of any required size. Clearly, the number of chips and interconnections increases directly as the number of segments. This limits the practical size of a display using this arrangement. The output pin to segment connections can be chosen to suit the application. The arrangement used here has been chosen to be compatible with the 4 -backplane MC145000 driver used in a later example.

The MC144115 has a three-line serial interface consisting of clock, data, and chip enable. The clock and data lines can be shared with other peripherals, provided that each peripheral has a separate enable line. The enable line can, however, be derived from the clock if no other chips share the clock and data. This method of saving an I/O line is used in application note ANE416. The MC144115 software example (listing 1) has been modified from the routine used in ANE416.


Figure 1. Single-backplane LCD display with MC144115P display drivers

\section*{LISTING 1}

\(\left.\begin{array}{ll}60 & \\ 61 & \\ 62 & \\ 63 & \\ 64 & \\ 65 & \\ 66 & \\ 67 & \\ 68 & 0000101 a\end{array}\right] 1701\)
\(* * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * ~\)

\section*{THREE-BACKPLANE DISPLAYS}

The MC68HC05L6 can drive 24 frontplanes and either 3 or 4 backplanes, the number of backplanes being selectable in software. The data to be displayed is arranged in the display RAM as shown in figure 2. Note that data sheet for the MC68HC05L6 (ADI1254) shows this relationship wrongly.

It can be seen that each frontplane occupies a nibble in the 12-byte RAM. There is thus a simple relationship between RAM location and displayed digit on a 4-backplane 7 -segment display (each 2 frontplane digit corresponds to one byte). With a 3-backplane display, however, each digit corresponds to 3 nibbles ( 1.5 bytes) so the software required to translate the required segments into display RAM data is more complex. Listing 2 shows a suggested method of doing this.
\begin{tabular}{|c|c|c|c|c|c|c|c|c|}
\hline LCD data latch 00 & 7 & 6 & 5 & 4 & 3 & 2 & 1 & 0 \\
\hline \multirow[t]{2}{*}{(\$00)} & Bp1 & Bp2 & Bp3 & Bp4 & Bp1 & Bp2 & Bp3 & Bp4 \\
\hline & \multicolumn{4}{|c|}{Fp 01} & \multicolumn{4}{|c|}{Fp 02} \\
\hline
\end{tabular}

Figure 2. MC68HC05L6 back/frontplane pin to LCD data latch bit relationship

The table which translates the required character into segments contains 2 bytes per character, the middle nibble of the 3 required being repeated. This simplifies the code required to write to the display RAM by using one nibble if the character is intended for an even position in the display and the other for an odd position. Figure 3 shows the L6-LCD segment arrangement used in this example.

When using a microprocessor without an LCD drive capability a separate display driver can be used to drive a multiplexed display. The example shown in figure 4 and listing 3 uses the ICM7231B 3-backplane driver. The ICM7231B requires each character to beaddressed through pins A0, A1 and A2 and the appropriate data written to pins D0, D1, D2 and D3. This parallel control uses more I/O lines than the serial arrangement employed in MC145000/1 and MC144115 drivers.

The fact that data is accepted in HEX and encoded into segments by the driver simplifies the software but reduces the versatility of the display as only the driver's 16 characters are available. The ICM7231B driver displays \(0-9,-, E, H, L, P\) and blank while the ICM7231A displays 0-9, A, B, C, D, E and F.

As with any multiplexed LCD drive, the contrast is dependent on the supply voltage to the driver's multiplexer circuitry. In the case of the ICM7231, contrast can be adjusted using the potentiometer on pin 2 (figure 4).


Figure 3. MC68HC05L6 with a 3-backplane LCD

\section*{LISTING 2}
\begin{tabular}{|c|c|c|c|c|c|c|c|}
\hline & & & & & & & \\
\hline 2 & & & \multicolumn{5}{|l|}{****************************************************} \\
\hline 3 & & & * & & & & * \\
\hline 4 & & & * & \multicolumn{4}{|l|}{Example program using the MC6BHCOLL6} \\
\hline 5 & & & * & \multicolumn{4}{|l|}{to directly drive a 3 -backplane display. *} \\
\hline 6 & & & * & & & & * \\
\hline 7 & & & \multicolumn{5}{|l|}{****************************************************} \\
\hline 8 & & & \multicolumn{5}{|l|}{\multirow[t]{2}{*}{}} \\
\hline 9 & & & & & & & \\
\hline 10 & \multicolumn{2}{|l|}{00000009} & LADD & EQU & \$0009 & \multicolumn{2}{|r|}{LCD address register} \\
\hline 11 & \multicolumn{2}{|l|}{00000008} & ldat & EQu & \$0008 & \multicolumn{2}{|r|}{lcd data register} \\
\hline \multicolumn{8}{|l|}{12 le} \\
\hline \multicolumn{8}{|l|}{13} \\
\hline 14 & & & \multicolumn{2}{|r|}{ORG} & \$0050 & \multirow{5}{*}{DISPLAY R} & \multirow[t]{2}{*}{} \\
\hline \multicolumn{3}{|l|}{15} & & & & & \\
\hline 16 & \multicolumn{2}{|l|}{00000050} & 0 & RMB & 8 & & \multirow[t]{3}{*}{REGISTER} \\
\hline 17 & 00000058 & & W1 & RMB & 1 & & \\
\hline \multicolumn{3}{|l|}{\multirow[b]{2}{*}{19}} & W2 & RMB & 1 & & \\
\hline & & & \multicolumn{3}{|l|}{} & & \\
\hline \multicolumn{3}{|l|}{20} & \multicolumn{3}{|r|}{\multirow[b]{2}{*}{ORG \(\quad \mathbf{0 1 0 0}\)}} & & \\
\hline \multicolumn{3}{|l|}{21} & & & & & \\
\hline \multicolumn{3}{|l|}{22} & \multicolumn{5}{|l|}{} \\
\hline \multicolumn{3}{|l|}{23} & \multicolumn{5}{|l|}{****************************************************} \\
\hline \multicolumn{3}{|l|}{24} & \multicolumn{4}{|r|}{\multirow[b]{2}{*}{LCD segment look-up table.}} & * \\
\hline \multicolumn{3}{|l|}{25} & & & & & \\
\hline \multicolumn{3}{|l|}{26} & \multicolumn{4}{|l|}{} & * \\
\hline \multicolumn{3}{|l|}{27} & \multicolumn{5}{|l|}{****************************************************} \\
\hline 28 & & & & & & & \\
\hline 29 & 00000100 & acca & L6TAB & FCB & SAC. SCA & 0 & \\
\hline 30 & 00000102 & 00c0 & & FCB & \$00.sCO & 1 & \\
\hline 31 & C0000104 & e48e & & FCB & SE4.S8E & 2 & \\
\hline 32 & 00000106 & e0ce & & FCB & SEO. SCE & 3 & \\
\hline 33 & 00000108 & 48c4 & & FCB & \$48.sc4 & 4 & \\
\hline 34 & 0000010a & e84e & & FCB & SE8.54E & 5 & \\
\hline 35 & 0000010c & ec4e & & FCB & SEC.54E & 6 & \\
\hline 36 & 0000010e & 80c8 & & FCB & \$80.5C8 & 7 & \\
\hline 37 & 00000110 & ecce & & FCB & SEC. SCE & 8 & \\
\hline 38 & 00000112 & e8ce & & FCB & SE8.5CE & 9 & \\
\hline 39 & 00000114 & 4004 & & FCB & \$40.504 & - & ( \(\mathrm{A}: \mathrm{CC}(\mathrm{CC})\) \\
\hline 40 & c0000116 & ecoe & & FCB & SEC. SOE & E & (B: 6C 46) \\
\hline 41 & 00000118 & 4 cc 4 & & FCB & \$4C.5C4 & H & (C: AC OA) \\
\hline 42 & c000011a & 2 c 02 & & FCB & \$2C.s02 & L & ( \(0: 64\) C6) \\
\hline 43 & ccoool?c & cc8c & & FCB & SCC.s8C & P & ( \(\mathrm{E}: ~ \mathrm{EC}\) OE) \\
\hline 44 & 000colle & 0000 & & FCB & \$00. 500 & & ( \(\mathrm{F}: \mathrm{CC} 0 \mathrm{O}\) ) \\
\hline
\end{tabular}



Figure 4. 3-backplane LCD driven by an ICM7321

\section*{LISTING 3}


\section*{FOUR-BACKPLANE DISPLAYS}

As mentioned above, the MC68HC05L6 can drive a 4-backplane display with up to 24 frontplanes directly. The resultant 96 pixels could be used to drive 2 digits of an \(5 \times 8\) dot matrix display, but with this number of segments most applications will use 7 -segment or customised displays. A 7-segment display of up to 12 digits can be used. The software required is similar to, and simpler than, that shown for the L6 with a 3-backplane display. When it is required to drive a 4-backplane display using a microprocessor without an LCD drive capability, the MC145000 offers a versatile solution. Up to 6 digits ( 12 frontplanes) can be driven directly and more can be driven by the addition of one or more of the 18-pin MC145001 expanders, each adding 11 frontplanes. The example shown in figure 5 and listing 4 drives 6 digits, the software being very similar to that shown for the MC144115 single-backplane driver. This is the result of both chips having the same shift-register/latch architecture despite the actual output signals being quite different. The listing also shows a routine using an SCl rather than port lines.

A difference between the MC145000 and the MC144115 is that the MC145000 has no chip-enable input. It can share its data line with other peripherals but must have a dedicated clock so that the controller can supply data independently of other chips.

For applications requiring more than the 12 frontplanes made available by the MC145000, the MC145003/4 may be appropriate. They provide 32 frontplanes for use with a 4-backplane display, allowing up to 128
segments. The MC145003 and MC145004 are identical except for their serial protocol. The MC145004 has an IIC bus interface incorporating the usual acknowledge procedure associated with the IIC standard. The MC145003 is the same, except that there is no acknowledge and hence no associated clock cycle. The incoming data is automatically latched after 128 bits have been received. If, however, it is required that the data be latched at other times, an enable pin is available.

For applications where Vdd and Vlcd are connected together, the LCD contrast is adjusted by adjusting Vdd. If the data is coming from a chip with a higher supply voltage, the input pins may go higher than the supply voltage of the MC145003/4. This is allowed for the clock and data pins, but not recommended for the enable pin as its input protection circuitry may clamp the input voltage. It is therefore not advisable to use the enable pin if the MC145003/4 has a different Vdd from the chip supplying it with data. In applications not using this pin it can be left floating or tied high.

The example shown in figure 6 does not use the enable pin; the example software sends all 128 bits every time it is executed. The latching is thus performed automatically. The circuit shows 26 -digit displays, each with 12 frontplanes. Any display or combination of displays with up to 32 frontplanes can be used with the software shown in listing 6, as all 128 bits are always sent. The 6 lines of code (45-50) are commented out for use with the MC145003; they are required for the MC145004.


Figure 5. MC145000 driving a 4-backplane LCD


Figure 6. MC145003/4 driving 4-backplane LCDs

\section*{LISTING 4}

1
2
3
4
5
6
7
8
900000000
0000000d
0000000 e
\(0000000 f\)
00000010
00000011
15
16
17
1800000050
19
2000000056
00000057
00000058
00000059
0000005a
25
26
27
28
29
30
31
32
33
34
35
3600001000
3700001002 b758
3800001004 be56
3900001006 f6
4000001007 bf59
41000010099
420000100 a d61047
43 0000100d be58
\(440000100 f\) e750
45000010113 a 58
4600001013 be59
4700001015 5a-
4800001016 b35a
4900001018 26ec

\(\qquad\)
\begin{tabular}{|c|c|c|c|}
\hline PORTA & EQU & \$00 & PORT A DATA \\
\hline BAUD & EQU & \$00 & SCI BAUD RATE REGISTER \\
\hline SCR1 & EQU & SOE & * CONTROL REG. No. 1 \\
\hline SCR2 & EQU & \$0F & - 2 \\
\hline SCSR & EQU & \$10 & Status \\
\hline SDAT & EQU & \$11 & data \\
\hline & ORG & \$0050 & \\
\hline R & RMB & 6 & WORKING NUMBER \\
\hline W2 & RMB & 1 & POSITION OF LSB \\
\hline W3 & RMB & 1 & \\
\hline W4 & RMB & 1 & \\
\hline W5 & RMB & 1 & \\
\hline W6 & RMB & 1 & POSITION OF MSB \\
\hline
\end{tabular}

ORG \(\$ 1000\)


DISP LDA \#\$05
STA W4
LDX W2 LSB
03 LDA \(0 . X\)
STX W5
TAX
LDA STABL.X FIND 7 SEGMENT CODE
LDX W4
STA R.X PUT IN DISPLAY TABLE
DEC W4
LDX W5
DECX
CPX W6 FINISHED ?
BNE D3
\(\left.\begin{array}{ll}60 & \\ 61 & \\ 62 & \\ 63 & \\ 64 & \\ 65 & \\ 66 & \\ 67 & \\ 68 & \\ 69 & \\ 70 & 0000101 a\end{array}\right)\) ae05
\begin{tabular}{|c|c|c|c|c|}
\hline \multicolumn{5}{|l|}{} \\
\hline * & \multicolumn{3}{|l|}{The second part of the display routine} & e \\
\hline * & \multicolumn{2}{|l|}{sends the 48} & bits required by the & e \\
\hline * & \multicolumn{2}{|l|}{display driver.} & . For comparison two & * * \\
\hline * & \multicolumn{3}{|l|}{routines are included. one using port \(A\)} & A \\
\hline * & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{lines and a second using the SCI.}} & * \\
\hline * & & & & * \\
\hline \multicolumn{5}{|l|}{} \\
\hline OUTT & LDX & \#5 & \multicolumn{2}{|l|}{SEND DISPLAY TABLE TO 144115/145000} \\
\hline DISCHR & LDA & R, X & & \\
\hline \multirow[t]{3}{*}{DISPLY} & STX & W3 & \multicolumn{2}{|l|}{SAVE INDEX} \\
\hline & BCLR & 6. P.ORTA & \multicolumn{2}{|l|}{Clear data} \\
\hline & LDX & \#8 & & \\
\hline \multirow[t]{3}{*}{DIS1} & \multicolumn{2}{|l|}{LSRA} & SET UP & \\
\hline & BCC & DIS2 & BIT OF & \\
\hline & BSET & 6.PORTA & ACCUMULATOR & \\
\hline \multirow[t]{8}{*}{DIS2} & BSET & 7. PORTA & CLOCK & \\
\hline & BCLR & 7. PORTA & IT & \\
\hline & BCLR & 6.PORTA & CLEAR data & \\
\hline & DECX & & COMPLETE ? & \\
\hline & BNE & DIS1 & NO & \\
\hline & LDX & W3 & RESTORE INDEX & \\
\hline & \multicolumn{4}{|l|}{DECX} \\
\hline & BPL & \multicolumn{2}{|l|}{DISCHR} & \\
\hline \multicolumn{5}{|l|}{*****************************************************} \\
\hline \multicolumn{4}{|l|}{*} & * \\
\hline * & \multicolumn{3}{|l|}{SCI LCD driver interface.} & * \\
\hline \multicolumn{4}{|l|}{*} & * \\
\hline \multicolumn{5}{|l|}{*****************************************************} \\
\hline & LDX & \#5 & \multicolumn{2}{|l|}{INITIALISE X} \\
\hline \multirow[t]{7}{*}{MORE} & LDA & R. X & \multicolumn{2}{|l|}{FETCH DIGIT} \\
\hline & BRCLR & 7.SCSR.* & WAIT UNTIL TDRE \(=1\) & \\
\hline & STA & SDAT & \multicolumn{2}{|l|}{WRITE IT TO SCI TX REG.} \\
\hline & DECX & & NEXT DIGIT & \\
\hline & BPL & MORE & DONE ? & \\
\hline & BRCLR & 6.SCSR.* & WAIT UNTIL TC=1 & \\
\hline & \multicolumn{3}{|l|}{RTS} & \\
\hline \multirow[t]{10}{*}{STABL} & FCB & \$EB & 0 SEGMENT & \\
\hline & FCB & \$60 & 1 & \\
\hline & FCB & \$C7 & 2 CODES & \\
\hline & FCB & \$E5 & 3 & \\
\hline & FCB & \$6C & 4 FOR THE & \\
\hline & FCB & \$AD & 5 & \\
\hline & FCB & \$AF & 6 MC145000/MC144115 & \\
\hline & FCB & \$EO & 7 & \\
\hline & FCB & \$EF & 8 LCD DRIVER & \\
\hline & FCB & \$ED & 9 & \\
\hline
\end{tabular}

\section*{LISTING 5}


\section*{8/16-BACKPLANE DISPLAYS}

For dot-matrix displays, 8 or 16 backplanes are common. This is the result of the large number of pixels required. A compromise between pin-count and contrast is made to decide the number of backplanes. The minimum pin requirement for a display with N segments would require the number of backplanes to be the square root of \(N\), but with typical requirements of many hundred or thousands of pixels this is not practical as the resultant contrast would not be acceptable. Typical compromises are 8 or 16 backplanes, as this gives acceptable contrast and fits in conveniently with the \(8 \times 5\) dot-matrix format commonly used for this type of display.

The MC68HC05L7 and L9 are designed to directly drive this type of display. The L7 has 16 backplanes and 60 frontplanes allowing it to drive up to 960 pixels or \(248 \times 5\) dot matrix digits ( 12 with \(\times 8\) multiplexing). The L9 has only 40 frontplanes ( \(168 \times 5\) digits) but is
capable of being used with MC68HC68L9 LCD drive expanders. Each MC68HC68L9, up to 3 of which may be added, contributes 55 frontplanes. An L9 and 3 expanders has thus 205 frontplanes allowing then to drive up to 3280 pixels or \(828 \times 5\) dot matrix digits.

The display RAM contains a 5-bit word for each row of dots in the \(8 \times 5\) format; thus, 8 locations are used for each digit, allowing easy addressing. The RAM corresponding to the digits driven by expanders is contained in the expanders, but appears in the L9's memory map as the data and address buses from the L9 to external memory are also used by the MC68HC68L9s.

Application note ANHK10/D shows an application using the L9 and also describes a method of extending the display size beyond that normally available using this device.

\section*{APPLICATION NOTES}

The following application notes give complete applications using the type(s) of display indicated.

ANE404 An extended MC146805E2 CBUG05 system using the MC68HC25.
MC145000-driven 4-backplane, 6-digit and ICM7231B-driven 3-backplane, 8-digit display.

ANE416 MC68HC05B4 Radio Synthesizer.
MC145000-driven 4-backplane, 6-digit and MC144115-driven 1-backplane, 6-digit display.

ANE425 Use of the MC68HC68T1 RTC with M6805 Microprocessors.
ICM7231B-driven 3-backplane, 8-digit display.

ANHK10 The summary of the MC68HC05L9 Micro. App. Demo. Board.
MC68HC05L9/MC68HC68L9-driven dot matrix display.

\section*{DRIVER CHIPS}

The following list shows some LCD driver devices. They are most suitable for 7 -segment, 16 -segment and custom displays. The 7SD column shows how many 7-segment digits each device can drive. With the possible exceptions of the MC145000/1 and the MC145003/4, they are not generally suitable for dot-matrix displays which have \(35-40\) segments per digit.
\begin{tabular}{lccccccc} 
Device & Back & Front & 7SD & Drive & Expan. & Pins & \\
MC14543 & 1 & 7 & 1 & parallel & parallel & 16 & BCD \\
MC14544 & 1 & 7 & 1 & parallel & parallel & 18 & ripple blank \\
MC144115 & 1 & 16 & 2 & 3 -line & yes & 24 & \\
MC144117 & 2 & 16 & 4 & 3-line & no & 24 & \\
MC145000 & 4 & 12 & 6 & 2-line & MC145001 & 24 & \\
MC145001 & \((4)\) & 11 & 5.5 & 2-line & n/a & 18 & expander \\
MC145003 & 4 & 32 & 16 & 2- or 3-line & parallel & 52 & 2- or 3-line \\
MC145004 & 4 & 32 & 16 & 2-line & parallel & 52 & IIC \\
MC145453 & 1 & 33 & 4 & 2-line & parallel & 40 & also 44-pin \\
ICM7231 & 3 & 24 & 8 & parallel & no & 40 & BCD
\end{tabular}

\title{
AN446
}

\title{
MCM2814 Gang-programmer using an MC68HC805B6
}

\author{
By Peter Topping \\ MCU Applications Group \\ Motorola Ltd, East Kilbride
}

\section*{INTRODUCTION}

\section*{PRINCIPLE OF OPERATION}

The programmer has been designed with an emphasis on ease of use and consequently has as few controls as possible. The only control which is used regularly is the "RUN" button S1. When it is pressed, the NVMs are powered-up and programmer operation starts. When it is released, power is disconnected from the NVMs but remains on within the programmer so that the LED indicators remain.

Three different operations are available.
The first requirement is to load data into the programmer. This procedure is selected by pressing and holding button S3, and started by pressing, and holding, the button S1. The contents of a master NVM in socket \#0 will be loaded into the programmer; this takes about 12 seconds. The MC68HC805B6 in the programmer retains this data in its non-volatile EEPROM. Duringloading both LED s at socket \#0 are on and the rest are off. Once the B6's EEPROM is written it is verified against the NVM in socket \#0, a green LED indicating a pass and a red LED a fail. Sockets 1-7 should be empty during this procedure but if they contain an NVM they will also be checked. An attempt to perform this routine without an NVM in socket \#0 will not destroy the data in the programmer as the software checks for an IIC acknowledge before overwriting the contents of the EEPROM within the MCM68HC05B6. If S 3 is pressed, the position of the slide switch S2 (program and verify or verify only) is not relevant. As S1 supplies power to the NVM sockets, it is important that it is held until the procedure is complete. Reliable results will not be obtained if S 1 is released before the verification has finished.


The main programming sequence is selected by putting S2 in position PN (program and verify). The NVMs should be placed in the sockets and button S1 pressed, and held, until programming and verification are complete ( 4 seconds). During programming, both red and green LEDs are on. The procedure clears the write-protect bytes and programs the NVMs in parallel using the data stored within the B6 in the programmer. It then verifies the NVMs individually, the results being shown on the LEDs (green for pass, red for fail and neither for no acknowledge).

Running only the verify routine can be selected by placing S 2 in position." V ". The procedure is otherwise similar to programming. S1 should be held in until verification is finished (up to 1 second depending on results).

\section*{CIRCUIT}

The NVMs are arranged in a matrix using their IIC chip-selects (pins 1 and 2 ). These pins configure the two least significant bits (1 and 2) of the recognised IIC address. Bit 0 determines if the device is receiving or transmitting. The software uses only the address 1010000x and so an NVM will only be addressed if both its chip-select pins are low. The matrix thus allows each NVM to be addressed individually by I/O lines using common software. Six port B I/O lines (0-5) are used for this purpose.

The NVMs (and the IIC pullups) are only powered up when S1 is closed, allowing them to be inserted and removed when they are powered down. When S1 is pressed, 5 volts is also applied to the RC circuit connected to the base of the BC107 NPN transistor. This supplies a base current to the transistor while the \(10 \mu \mathrm{~F}\) capacitor is charging. During this transient the transistor is on and the MC68HC05B6 is in reset. The program starts when the capacitor is charged and the transistor switches off. The MC34064 also connected to the reset pin ensures that the microprocessor is held in reset if the supply is below 4.75 V . This will be the case during power-up and power-down. This is advisable in any system with EEPROM in order to prevent the possibility of it being corrupted during the rise or fall of Vdd.

The 33 ohm resistor in series with the supply to the NVMs limits the current if a device is plugged in the wrong way round. If this happens, the BC327 PNP transistor is turned on and the RED fault LED lit. The actual voltage on the VDD pins of the NVMs is monitored by bit 5 on port D. Thus the microprocessor can tell if there is a short or a device inserted the wrong way round. If this is the case the software aborts any attempt to program or verify NVMs.

Ports \(A\) and \(C\) are used for the pass and fail LEDs respectively, while the input-only port \(D\) has two pins used to read the positions of S2 and S3.

\section*{SOFTWARE}

On reset, the program initialises the ports, IIC addresses and the RAM location (STAT) which is used for status flags. The state of bit 0 on port \(D\) is then checked. This will be low unless the button (S3), which selects the loading of data into the programmer, is pressed. If it is low, either program and verify or verify only is executed according to the level of bit 1 on port \(D\) which is connected to switch S2.

The programming routine (PROG) switches on all the LEDs, enables all the NVMs and clears their writeprotect by writing \(\$ 00\) to address \$FF. A loop which reads a byte from the B 6 within the programmer and writes it to the NVMs is then performed 255 times. Writing to the NVMs is carried out without checking for an acknowledge, so the full procedure will take place even if all the NVM sockets are empty. This is the only routine which does not check for an acknowledge.

Only 255 bytes are transferred, as the last byte in the MCM2814 is reserved for the write-protect status. The B6 also has a reserved byte, but it is the first byte, so the correspondence of the addresses between the B6 and the NVMs is offset by one.

The verify routine (VERF) switches off all the LEDs and compares the data in the B6 with the data in each of the NVMs. It immediately fails a socket which does not return an IIC acknowledge. The RAM location COUNT contains the number of the socket being checked and is used to switch on the appropriate LED once each verify is complete.

The NVM sockets are arranged in a \(2 \times 4\) matrix using their two IIC chip selects. The IIC address used is always \$A1 (\$A0 for writing) and thus an MCM2814 will only respond if both its chip-selects are low. During the programming routine all lines in the matrix are low, but during verification each chip is individually selected by a low on one row and one column. The required value to be sent to port \(B\) to achieve this is derived from the value in COUNT using the table TAB1.

If the LOAD routine is selected it performs a loop which does the opposite of the program loop. It transfers the contents of an MCM2814 into the EEPROM of the MC68HC805B6 within the programmer. It only looks at socket \#0 and checks for an acknowledge before it proceeds to over-write the data in the B6.

The three routines WRT, RDALL and WRTAL were used during de-bug, are self-explanatory, and have been left in the program for interest and for future use if required. They are not used by the MC68HC805B6 but can be used if the program is run on a development system (eg an M68HC05EVM).

The IIC READ, SEND and WRITE routines are self contained and, by using ordinary I/O lines, could be used on any \(68(\mathrm{HCl} 05\) microprocessor. The READ sub-routine reads one byte using the IIC address in ADDR and the sub-address in SUBARD. The commented out lines ( \(382-385\) ) provide a simple method of also reading a second byte. Data is returned in IOBUF (and IOBUF+1 in the case of a 2-byte read). Clearly, the number of bytes can be increased by including more in-line code or by executing a loop.

The SEND sub-routine writes data on the IIC bus at IIC addressADDR startingat the address in RAM contained in the.index register. The number of bytes sent is determined by the value stored the accumulator. If, as in this example, a sub-address has to be sent, then it should be in the RAM location pointed to by the index register with subsequent locations containing the data. SEND is suitable for most IIC peripherals. The WRITE subroutine constitutes a SEND followed by a delay and a READ. This is what is required to write a byte to an MCM2814, EEPROM programming is started by an IIC write and continues until the chip is addressed again by READ.

The IIC routines use simple BCLR and BSET instructions on the data registers so that an active high level is generated. This is not strictly what should be done on an IIC bus but is OK in the case where there are no other possible masters in the system. A passive high can be obtained by keeping the data bit of the I/O lines used for the IIC bus at a zero and using BCLR and BSET instructions on the corresponding data direction bits. If this is done care must be taken to ensure that these zeros are not lost by any other read-modify-write operations carried out on the data register. A BCLR or BSET on another bit on the same port will read the whole port, modify the required bit and then write the whole port. The data bit on an IIC line which was pulled high by the external pull-up would thus become a one. This would cause a malfunction the next time the corresponding DDR bit was set to a one, as the pin would output a high instead of a low. This can be avoided by using other types of instructions (eg STA) or by making sure the relevant data bit is a zero before enabling an output.









\title{
"FLOF" Teletext using M6805 Microcontrollers
}

\author{
By Peter Topping \\ MCU Applications \\ Motorola Ltd, East Kilbride
}

\section*{1. INTRODUCTION}

The " \(T\) " members of the MC68HC05 family of MCUs provide a convenient and cost effective method of adding on-screen-display (OSD) to TVs and VCRs. As well as the 64-character OSD capability, they include 8 Kbytes of ROM (adequate for Teletext, frequency-synthesis, stereo and OSD), 320 bytes of RAM, a 16 -bit timer and 8 pulse-width-modulated D/A converters. The MC68HC05T7 also includes IIC hardware and, by using a 56 -pin package, 4 ports of I/O independent of the OSD, serial and D/A outputs. It is thus suitable for large full-feature chassis. The MC68HC05T1 is in the middle of the price/performance range and includes most of the features of the MC68HC05T7 but in a 40-pin package. This is achieved by sharing I/O with the other pin functions (SPI, OSD, \(D / A)\). Even if all these features are used, there is sufficient I/O for most applications.

The MC68HC05T2 is a 16 K upgrade of the MC68HC05T1 and the MC68HC05T3 a 24 K version with increased RAM ( 512 bytes) and enhanced OSD ( 112 characters and 2 rows of OSD buffer). The low cost MC68HC05T4 has 5 Kbytes of ROM and 96 bytes of RAM making it suitable in simpler (eg mono, non-Teletext) applications. The T4 and T7 also include a 14-bit D/A converter to facilitate voltage synthesis tuning. There are EPROM (and OTP) versions of the T3 (including T1 and T2 emulation), T4 and T7.

This application note describes an example of Teletext control software written for the MC68HC05T7 which directly controls Teletext chips of the type 5243. Spanish FLOF Teletext (level 1.5) is handled using packet X/26. If no CCT teletext chip is present on the IIC bus (as indicated by the lack of an acknowledge), all Teletext functions are disabled in software. About 3Kbytes of ROM are used allowing the code to fit into the 7.9 K bytes available in an MC68HC05T7 along with tuning, OSD and stereo functions.

The software in the included listing has been written for the MC68HC05T7 but could, with a little modification, be implemented on other M 6805 microcontrollers. A microcontroller without IIC hardware can be used as long as additional software is included to facilitate the IIC bus using I/O pins. An example of IIC master I/O driven software can be found in application note AN446.

\section*{2. "FLOF" TELETEXT FEATURES}

Full Level One Feature (FLOF) Teletext utilises "ghost" packets to provide features in addition to those available with the original CCT Teletext. The primary enhancement is the provision of a menu with a choice of four linked pages selectable by the user with a single press of one of four coloured buttons on the remote control. The menu itself is sent in the ghost page using packet 24 while the linked page numbers are contained in packet 27 . In addition to linked pages, packets 26 and 30 are used. Packet 26 allows for the substitution of selected characters in the display by special characters specific to a particular country. This example application includes the Spanish implementation of packet 26 . The broadcast service data packet \((8 / 30)\) is used to get the initial (index) page for each channel and to display station identification information.

\section*{"Ghost" packets handled}

\section*{X24 :}

The FLOF menu information contained in this page extension packet is transferred by the microcomputer to row 24 of the display chapter. When links are disabled because there is no packet 27 (destination code 0 ) or when bit 4 of byte 43 is 0 , row 24 is blank.

\section*{X/26 :}

Optional handling of modes \(1 \times x \times x\), 01111 and 00010 in accordance with the Spanish Teletext specification. All the additional characters which are available in the 5243 CCT chip are handled. The feature can be disabled with a hardware link on an I/O pin (see figure 1) so that the software can be used at level 1.0 in non-Spanish countries also using packet 26.

\section*{X/27 :}

This packet contains the linked page numbers for the red, green yellow, blue and index (black) keys. Bit 4 on the link control byte (byte 43) is used to determine if these links are enabled (1) or disabled ( 0 ). When enabled, the Spanish specification requires that bits 1,2 and 3 be used to enable the green, yellow and blue links respectively. This use of these bits is not defined in the World Teletext Specification. For this reason their use is selectable by a hardware link (see figure 1). If these bits are not used, all links (if enabled by bit 4 ) will be taken from packet 27 but will be automatically disabled if the broadcast links are default (FF3F7F) or invalid.

\section*{8/30:}

The broadcast service packet is used to supply the index page number on exit from standby and fif teletext is not stopped) after a channel change. Bytes 10-30 of this packet are displayed for 5 seconds on exit from standby and (if teletext is not stopped) after a channel change.

\section*{3. IMPLEMENTATION}

The software listing is in two parts. The first part contains the "ide" loop and IIC routines from the main TV control part of the MC68HC05T7 application. The idle loop controls the timing of everything performed by the microprocessor, scans the local keyboard, checks whether or not an IR command has been received, etc. It also monitors the relevant flags in the Teletext chip and performs the tasks (eg fetching linked pages) which have to be performed independently of requests for the user.

The second and main listing is the Teletext module itself. It contains all the subroutines required to carry out automatic and user requested Teletext activity. Both modules use the same RAM allocation file (RAMT8.SO5) which is included in the listing of the Teletext module. This listing also includes a symbol cross-reference table.

Figure 1 shows a simplified circuit diagram of the application. Most of the MC68HC05T7's \(1 / O\) is used for purposes other that Teletext and is not shown in detail. Communication with the 5243 Teletext chip is via an IIC bus in which the T7 is always the master. The function of the three I/O pins used for Teletext is described under "Ghost packets handled" and "Inputs and Outputs".

A version of this Teletext software has been implemented on an MC68HC05C4 for use in a TV where the other control functions were handled by a separate microcontroller. The signal from the IR pre-amp was fed into the C4 which used Teletext commands to control a 5243 via a software IIC bus. Non-Teletext commands were regenerated by the C 4 and sent to the other microcontroller. This arrangement allows Teletext to be added to a chassis which was originally designed without considering Teletext.


Figure 1. MC68HC(7)05T7 - Teletext application circuit

\section*{4. IDLE LOOP}

In the example application the idle loop code is in the main TV control software module rather than in the teletext module. Listing 1 shows the relevant parts of this module. The loop time is 12.8 mS and it is at this rate that the timing counters used by Teletext (CNT1 and CNT4) are incremented. The standby condition is checked first; if the TV set is in standby then there is no IIC activity and hence no reading from, or writing to, the 5243 . If the TV has just exited from standby, as indicated by the flag 3,STAT2, then Teletext is initialised using the sub-routine RESTRT. This sub-routine writes to the 5243's control and mode registers (R5, R6 and R7) and checks that the IIC acknowledge is present. If there was no acknowledge, as indicated by flag 6,STAT7, then no further Teletext activity is attempted.

If an acknowledge is present, Teletext polling goes ahead, although it is suspended if there is a mute or time display. A mute indicates that the channel has just been changed, or no channel is tuned. During time display, all other Teletext activity is suspended. Re-initialisation using sub-routine START2 is performed if flag 7,STAT5 is set by a change of the tuned frequency.

Counter CNT4 is used to delay the transfer of packets 24 (page extension - FLOF menu), 27 (links), 26 (enhanced display characters) and the control bits from row 25 (display page) after the initial arrival of a page. When row 24 is read the 5243 FOUND flag is set to indicate that the arrival has been acted upon. If UPDATE is on then an update indicator appears if the update control bit (C9) is set or if the sub-page has changed or if it is the first arrival of the page. The update display is performed by the sub-routine ARRVD which clears the transient flags and enables the required display, i.e. page no. in normal mode and the whole of row 0 in sub-page mode. Any boxed information (eg sub-titles or newsflash) in the current page is also displayed. The last Teletext function performed by the idle loop is the checking of the FOUND flag in the 5243. This is accessed via the IIC bus; it is on the last (not displayed) row of the display page along with the current page and sup-page numbers and the control bits.

If there is a current Teletext transient (time, row 0 box or packet \(8 / 30\) ), the transient control branch from the idle loop is executed. This routine checks to see if it is time to end the transient. If it is, the subroutine OSDLE is executed. It resets transients for both the OSD generated by the MC68HC05T7 and Teletext. The sub-routine RSTMD2 performs this function for Teletext. It is called from within the sub-routine OSDLE (not listed).

\section*{5. REMOTE CONTROL FUNCTIONS}

TV/TXT
Toggle between TV \& Teletext mode.

\section*{0-9}

Number keys for entry of page and sub-page numbers
Red, Green, Yellow, Blue
Linked page access keys. The decoder stores four pages of text. These are the display page and the three pages corresponding to the red, green and yellow links. The blue linked page is not acquired in advance. In the absence of FLOF data or if the links are disabled by the control bit in packet 27 , the red key is page +1 and the green key page-1. Under these circumstances the requested page and the next three pages are acquired.
\(P C+1-\)
These keys always select page \(+1 /\) page-1 regardless of the availability of FLOF information. As with the red, green and yellow keys, the page is displayed immediately if it is already in RAM.

\section*{INDEX}

This key operates as an additional link with the difference that if the link is invalid the initial page from packet 8/ 30 is selected.

\section*{SUB-PAGE/TIME}

Text mode: Enter sub-page mode, (max. 3979). TV mode: Display time in top-right-hand corner for 5 seconds. Pressing this key during a station identification display (packet \(8 / 30\) bytes \(10-30\) ) can be used to extend this display beyond the five seconds it appears for, after a channel change.

\section*{STOP}

Halt acquisition, "STOP" is displayed instead of page number. Press again to restart. If acquisition has been stopped by partially entering a new page number then this key can be used to return to the original page.

\section*{MIXNOO-MIX}

Toggle between Teletext and mixed display. Use of this key causes the display of the top status row for 5 seconds if it is not being displayed because the current page is a newsflash or a sub-title. 5243 contrast reduction is enabled in mixed mode.

\section*{FULL/TOP/BOT}

Selects one of the three display formats, normal, top half enlarged, bottom half enlarged.
REVEAL
Reveal hidden text, toggle action.
UPDATE
Return to picture until a new version of the requested page arrives. When it arrives, its page no. is displayed in the top-right-hand corner, the key operates in both TV and Teletext mode, set is put into TV mode. Any boxed information (alarm clock, newsflash or sub-title) will be displayed. In sub-page mode the complete header is displayed so that both page \(\&\) sub-page numbers can be seen. Cancel update by entering Teletext mode and then going back to TV mode by pressing the TV/Text key twice.

\section*{6. TELETEXT SUBROUTINES}

\section*{6a. Subroutines: TVTX, UPDATE, DIGITO and GETIT}

The Teletext module (listing 2) comprises various sub-routines which are used both by the idle loop and to perform any Teletext actions initiated by commands from the IR remote control. They are described in the order in which they appear in the listing.

TVTX is executed when the TV/TEXT button is pressed. Its function is to toggle between TV mode and Teletext mode. The flag 0,STAT indicates the current mode. This flag routes the microprocessor to execute either TXTOFF or TXTON according to the current mode. TXTON checks that Teletext hardware is present and does nothing if there has been no IIC acknowledge. If, however, a 5243 is present in the TV, it clears all transients (OSDLE) and sets up the Teletext mode. It initialises the control registers (R5 and R6) to display text and background both in and out of boxes. For newsflashes the set-up is text and background within boxes and picture outside. TXTOFF also resets transients but forces TV mode and sync. Polling and updating continue as a background activity.

When the UPDATE key is pressed the update flag 4,STAT2 is set and TXTOFF executed so the TV is forced to TV mode. If there is a current transient hold (eg time), the hold is cleared before TXTOFF is executed.

The number entry sub-routine DIGITO branches to DIGITS in sub-page mode but otherwise accepts any number key as a page number input. Three digits are required, the pointer PDP holding the current position ( 0,1 or 2 for hundreds, tens or units). During entry the flag 2,STAT is set to stop Teletext activity. The numbers have to be written to the top-left-hand corner of the display page as well as saved in RAM. Once all three digits have been entered the page is requested and page acquisition restarted.

The code at label GETIT makes this request after first checking whether or not the selected page has already been requested (it could be the current display page or an already requested linked page). If it has, then a switch is made to the chapter associated with the appropriate acquisition circuit and no new request is generated. If not, the new request is made and the FOUND flag set.

\section*{6b. Subroutines: Colours, INDEX, NPAGE and PPAGE}

The four colour keys (Red, Green, Yellow and Blue) are primarily intended for selecting Teletext linked pages. When pressed the chapter which corresponds to the apnropriate acquisition circuit is selected for display. If links are disabled (by the link control bit or because there is no packet 27), then the RED and GREEN keys select current page +1 and -1 respectively. This choice is taken according to the state of flag3,STAT3 which reflects the condition of the link control bit in packet 27. The code executed by RED, if links are not in use, is the same as that executed by the " + " function (NPAGE) which always selects the next page. Similarly the alternative GREEN function (PPAGE) is the same as for the "-" key. The YELLOW and BLUE keys do nothing under these circumstances. In Spanish Teletext the GREEN, YELLOW and BLUE links can be individually inhibited, but the RED link is only inhibited if all links are off.

The chapter associated with the selected page is displayed immediately if it has already been requested. This will normally be the case if a linked page (red, green or yellow) has been selected. The code at label LPT is executed if the page has already been requested. If not, a jump to CLRPD is performed. CL.RPD is a label within DIGITO; the code at CLRPD requests a new page just as if the page number had been entered manually. If the required acquisition circuit is the one already current, then the "unstop" code is executed. This causes the green page-being-looked-for header to roll as though the page number had just been entered. This means that something can be seen to happen in the case where the linked page differs only from the current page in its sub-page number. Linked sub-pages are not fully supported in this implementation as they are rarely used by broadcasters and would significantly increase the size of the software. When the chapter is changed the Teletext PBLF (page being looked for) flag is checked. If it is low the FOUND flag is cleared. This forces the fetching of the links associated with the new display page. If the page is not already in, this will automatically happen when it arrives so the FOUND flag does not need to be cleared.

The BLUE (or cyan) key is different in that its page will not normally be immediately available (the four pages: display, red, green and yellow occupy the four acquisition circuits and RAM chapters).

The INDEX (or black link) function is similar to BLUE except that if its link is not valid it defaults to the initial (index) page number supplied by packet \(8 / 30\) (see sub-routine GIP).

\section*{6c. Subroutines: LINK, GLP1, GLP2, SRCH, CHCK1 and NOTOKx}

The sub-routine LINK allocates the three linked pages (RED, YELLOW and GREEN) to the three free acquisition circuits (not in use by the display page). To do this it checks the page numbers in turn to see if they have already been requested. If so they are left in their current acquisition circuit. If they have not already been requested the page number is put into a LIFO. Only 0-9 are regarded as acceptable digits for page numbers; this is consistent with the Spanish specification although the additional HEX numbers (A-F) may be used experimentally or by Teletext page generators. Within this first loop the sub-routine GLP1 is used to get the linked page numbers from packet 27, perform a decode of the Hamming encoded data and calculate the new magazine number (page hundreds) if different from that of the display page. GLP1 uses sub-routine SRCH to check if the page has already been requested. If there are no links, or if links are disabled, then displayed page \(+1,+2\) and +3 are requested.

The second loop in LINK allocates new page numbers to the remaining unused acquisition circuits. It uses GLP2 to clear the relevant chapters in the Teletext memory and make the new requests. Subroutine CHCK1 is used to check whether or not an acquisition circuit is in use before it is loaded with a new page number from the LIFO.

This method of organising new page requests prevents unnecessary requests being made for pages already requested. This is particularly important when links are disabled and pages are being requested using the "+" or "-" functions. Under these circumstances when the page number is incremented (or decremented) only one new page has to be requested (new display page +3 ), while page, page +1 and page +2 do not need to change and can be left in their current acquisition circuits.

NOTOK3 and NOTOK2 handle the RED and GREEN functions when links are disabled. They are disabled if the link control bit (packet 27 bit 3 , byte 43 ) is zero or if there is no packet 27 . These subroutines respectively increment and decrement the current page number (units and tens). The current magazine number (page hundreds) is not affected.

\section*{6d. Subroutines: ROW24, W2B, R2B, GCYI, CLINK and DECODE}

ROW24 is used to transfer ghost row 20 (packet 24) into the display chapter. This has to be done via the IIC bus. The loop reads two bytes via the IIC (sub-routine R2B) bus from the ghost page and writes it to the display page (sub-routine W2B). The FOUND flag is then set to indicate that the arrival of the page has been recognised and acted upon. This sub-routine is only called by the idle loop and is used along with the other sub-routines which get information from the ghost page (CLINK, LINK and GET25).

R2B and W2B use IIC routines READ and SEND which are outwith the Teletext module. These subroutines will differ according to the microprocessor in use. An MC68HC05C8 implementation would need to use I/O lines (see reference for suitable software) while the MC68HC05T7 can use its IIC hardware. The routines used in this example are included in the listing extract from the TV control software module (listing 1).

The sub-routine GCYI is used by LINK to store the data associated with the BLUE an INDEX links. As explained above, these pages will not be acquired in advance, the page number only being sent to an acquisition circuit if requested by an IR command.

CLINK fetches the link control byte from packet 27 if the destination code is OK and, after decoding the Hamming encoded data, transfers the bits to STAT3.

The Hamming decode sub-routine DECODE corrects for single bit errors. This is done with in-line code using the table HAM (at the end of listing 2 ) as this uses less ROM than an algorithmic method.

\section*{6e. Subroutines: MIX, TRANx, TXTx, HOLD, and NOHOLD}

The mixed display capability of the Teletext chip (5243) is toggled using an IR key which calls the sub-routine MIX. When mixed mode is entered, interlaced broadcast sync. \((312 / 313)\) is selected because the non-interlaced sync. used for teletext is not suitable if a TV picture is present on the screen. This is set up via the 5243 mode register R1. The control registers R5 and R6 are updated to provide the mixed display.

When returning to a non-mixed display, the code at NOMIX is used to re-configure the control registers and to set up a Teletext only 312/312 non-interlaced sync. This sync. reduces adjacent line flicker in a pure Teletext display.

The subroutine TRAN2 sets up a transient which retains a black background on the top row so that the page number, time etc. can be seen clearly. This type of transient is also started if the page number or sub-page number is being entered in mixed mode. Sub-routines TRAN1, TRAN2 and TRAN3 are used to initialise the various transient displays. These displays are cancelled as discussed above by actions taken within the idle loop controlled by the free-running timer within the MC68HC05T7.

The TXTx sub-routines are used in conjunction with the IIC SEND routine to write to various sub-sets of the registers within the 5243.

If the Teletext STOP function is requested by an IR command the routine HOLD is executed. This is a toggled function when requested in this way. HOLD displays the word "STOP" in place of the page number and stops the display acquisition circuit by clearing the 5243 HOLD flag accessed via its page request register R3.

NOHOLD is executed to restart the display acquisition circuit. It returns the page number to the top-left-hand corner. If a new page number has been partially entered, a press of STOP (executing an UNHOLD) will allow a return to the most recent page request. This takes only a single press as the start of the entry of a new page number cause a HOLD. The completion of a page number entry ( 3 digits) causes a NOHOLD.

\section*{6f. Subroutines: REVEAL, EXPTB and TIME}

The REVEAL function causes any hidden display information to appear. It is controlled by a bit in the display mode register (R7). The software example leaves any revealed information permanently displayed. If, however, it is required that such information disappear when the page is updated (this may be better for a quiz page), then the two commented out lines (80 and 81) in the idle loop should be enabled.

The display expand facility is controlled by another two bits in R7. The EXPTB sub-routine cycles through normal, top-half double height and bottom-half double height.

The example application uses a single IR key (subroutine TIME) for both the display of the Teletext clock and the entry into sub-page mode. IF the set is in TV mode then the time is displayed for 5 seconds. If the TV is in Text mode then sub-page mode is selected. Sub-page number entry is described in the following section. When the Teletext clock is requested it appears (boxed) at the top-right-hand corner. It is removed by the idle loop 5 seconds after the last press of the time button. When the time is being displayed all other Teletext activity is stopped using UCHOLD.

\section*{6g. Subroutines: DIGITS, SUBPG, GET25 and GET26}

DIGITS is the sub-page version of DIGITO and uses similar code. More checks on the input data are required as the four digits of the sub-page number have different maximum values. These maximums are 3 for thousands, 7 for the tens and 9 for the hundreds and units. These values reflect the sub-page number's original use as a time ( 24 hr format). For tens and thousands a keyed 8 becomes a 0 and a 9 becomes a 1 ; for thousands only 4, 5, 6 and 7 become \(0,1,2\) and 3 respectively.

The code at the label SETIT is the sub-page equivalent of GETIT, described above. It requests the new sub-page and sets the FOUND flag.

The sub-routine SUBPG is called when the TIME (or clock) key is pressed (TV in Teletext mode). It toggles between normal mode and sub-page mode. When sub-page mode is entered the page number display \((\mathrm{P}-)\) is replaced with **** to indicate the mode change and to prompt for the entry of a sub-page number. Once all four digits have been entered the new sub-page is requested by SETIT. The code at the label RSTR is used to exit from this mode back to the normal (page number) mode, restoring the page number display to the top-left-hand corner.

GET25 is used by the idle loop to get the information stored in row 25 of the display chapter. This row is not displayed but contains various information used by the control microprocessor. The current page number, magazine number, sub-page number, Teletext control bits and the FOUND and PBLF flags are available. GET25 gets the required information and stores it in the RAM of the MC68HC05T7.

At the end of this sub-routine the \(1 / O\) line 7, portB is checked. If it is low, packet 26 is handled. If it is high, this packet is disabled. This would be required if this application were to be used in a country other than Spain which used packet 26. It would require to be switched off as the enhanced display feature uses different characters depending on the country. In countries which do not use packet 26 (eg the UK) it does not matter whether or not packet 26 is enabled.

If packet 26 is enabled, GET26 processes all packet 26 data present in the ghost page. The tables G2TAB, G3TAB and CTAB contain the characters used to replace the character at the display location defined by each packet.

\section*{6h. Subroutines: GIP, R24T and SR24T}

The sub-routine GIP gets the initial (index) page from packet \(8 / 30\). It will be doing this as the set is brought out of standby or just after a channel change. It may thus initially get a poor signal for there may be no Teletext) so it tries repeatedly until it finds a valid packet \(8 / 30\) format 1 . If this is not found after 96 tries it gives up and sets the flag 6,STAT2 to indicate that there is no packet \(8 / 30\) (or no Teletext). In this circumstance it defaults to an index page number of 100.

R24T transfers bytes \(10-30\) of the broadcasting service data packet ( \(8 / 30\) ) into the display chapter. It is called once a second for five seconds after power-on or a channel change. The data is transferred to row 0 of the display page which can be displayed either at the bottom or, as in this example, the top of the screen. This transient display is setup using the sub-routine SR24T if Teletext is present. If the flag 6,STAT2 has been set by GIP as described above then SR24T does nothing. The transient display is terminated by code executed at the appropriate time from within the idie loop.

\section*{7. INPUT AND OUTPUTS}

Apart from the IIC bus, only three pins on the controlling microprocessor are relevant to Teletext. Two inputs select the usage of packets 26 and 27 and one output can be used to control any hardware which requires to be changed according to whether or not there is a TV picture currently being displayed. In many applications some or all of these functions will not be required and could be eliminated from the software thus freeing up the pins for other uses.

PB3)

This pin is active (high) during a pure (no-mixed, no-boxed) teletext display, otherwise it is low.
PB6)
When this pin is low, Spanish use of link control bits 1,2 and 3 is enabled. When it is high, these bits are ignored.
PB7)
Packet 26 control. When low, packet 26 is enabled and handles all the Spanish alternate characters which are available in the 5243 . When PB7 is high, packet 26 is ignored.

\section*{8. REFERENCES}

Application note AN446, MCM2814 Gang-programmer using an MC68HC05B6.

\section*{LISTING 1}


\begin{tabular}{|c|c|c|}
\hline \multicolumn{3}{|l|}{23} \\
\hline 231 & & \\
\hline \multicolumn{3}{|l|}{232} \\
\hline 233 & & \\
\hline \multicolumn{3}{|l|}{234} \\
\hline \multicolumn{3}{|l|}{235} \\
\hline 236 & 00000140 & adoc \\
\hline 23. & 0000014 d & ＞8600 \\
\hline 238 & 0000014 f & ＞b701 \\
\hline 239 & 00000151 & ＞b600 \\
\hline 240 & 00000153 & alal \\
\hline 241 & 00000155 & 2602 \\
\hline 242 & 00000157 & ＞3c00 \\
\hline \multicolumn{3}{|l|}{243} \\
\hline 244 & 00000159 & add9 \\
\hline 245 & 00000150 & ＞1100 \\
\hline 246 & 0000015d & ＞6600 \\
\hline 247 & 00000151 & addd \\
\hline 248 & 00000161 & ＞ 6600 \\
\hline 249 & 00000163 & add9 \\
\hline 250 & 00000165 & 1b3b \\
\hline \multicolumn{3}{|l|}{251} \\
\hline 252 & 00000167 & 1a3b \\
\hline 253 & 00000169 & ＞1000 \\
\hline 254 & 0000016b & ＞b600 \\
\hline 255 & 0000016 d & adef \\
\hline 256 & 00000168 & 193b \\
\hline 25 ？ & 00000171 & 163b \\
\hline 258 & 00000173 & b63d \\
\hline \multicolumn{3}{|l|}{259} \\
\hline \multicolumn{3}{|l|}{260} \\
\hline \multicolumn{3}{|l|}{26：} \\
\hline \multicolumn{3}{|l|}{262} \\
\hline \multicolumn{3}{|l|}{263} \\
\hline \multicolumn{3}{|l|}{264} \\
\hline 265 & 00000175 & Of3cfd \\
\hline 266 & 00000178 & 1b3b \\
\hline 267 & 0000017 a & b63d \\
\hline 268 & 0000017 c & ＞b700 \\
\hline 269 & 0000017 e & 9 a \\
\hline 270 & 0000017 f & 81 \\
\hline \multicolumn{3}{|l|}{27.} \\
\hline \multicolumn{3}{|l|}{272} \\
\hline \multicolumn{3}{|l|}{273} \\
\hline \multicolumn{3}{|l|}{274} \\
\hline \multicolumn{3}{|l|}{275} \\
\hline \multicolumn{3}{|l|}{276} \\
\hline \(2 \times\) & & \\
\hline ご8 & こ0こ00：80 & \(3 \mathrm{f3c}\) \\
\hline 2＊9 & ここここ0：82 & 80 \\
\hline
\end{tabular}


\section*{LISTING 2}

\begin{tabular}{|c|}
\hline \multirow[t]{2}{*}{\begin{tabular}{l}
TV/Teletext/OSD/Stereo program (MC68HCOST7). \\
CCT Teletext control module (Spain). \\
Used with RAMTB.SOS, OST.SOS 6 TMTT.SOS \\
This software was developed by Motorola Ltd. for demonstration purposes. \\
No liability can be accepted for its use in any specific application. Original software copyright Motorola - all rights reserved. \\
P. Topping \\
19th October 90
\end{tabular}} \\
\hline \\
\hline
\end{tabular}

EXPORT DIGITO, RED, GREEN, YELLOW, CYAN
EXPORT DIGITO,RED, GREEN, YELLOW, CYAN
EXPORT NPAGE,PPAGE,REVEAL, EXPTB, UPDATE,TVTX, GIP
EXPORT TIME, MIX, INDEX, HOLD, SR24T, START2, INITXT
EXPORT CLINK, LINK, ROW24, GET25,R2B, TXT2
EXPORT R24T, NOTTH, BOXOON, BOXOOF
IMPORT SEND, READ, OSDLE, TPAU2
LIB RAMT8.S05

SECTION.S .RAM, COMM

\begin{tabular}{|c|c|c|c|}
\hline PORTA & EQU & \$00 & Port A address \\
\hline PORTB & EQU & \$01 & Port B \\
\hline PORTC & EQU & \$02 & Port C \\
\hline PORTD & EQU & \$03 & Port D \\
\hline DDRA & EQU & \$04 & Port \(A\) data direction reg. \\
\hline DDRB & EQU & \$05 & Port B " " \\
\hline DDRC & EQU & \$06 & Port C \\
\hline DDRD & EQU & \$07 & Port \({ }^{\text {d }}\) \\
\hline LED1 & EQU & \$08 & D/A 0 Stereo LED \\
\hline LED2 & EQU & \$09 & D/A 1 BILINGUAL LED \\
\hline LED3 & EQU & \$0A & D/A 2 FM -/- NICAM LED \\
\hline *VOLU & EQU & \$0A & D/A 2 JP08 IN T1 EVB \\
\hline CONT & EQU & \$0B & D/A 3 JP09 IN Tl EVB \\
\hline BRILL & EQU & \$0C & D/A \(4 \quad\) JP10 IN Tl EVB \\
\hline SATU & EQU & \$0D & D/A 5 JP11 IN T1 EVB \\
\hline VOLU & EQU & \$0E & D/A 6 \\
\hline TCR & EQU & \$12 & Timer control register. \\
\hline TSR & EQU & \$13 & Timer status register. \\
\hline ICRH & EQU & \$14 & Input capture register, high. \\
\hline ICRL & EQU & \$15 & Input capture register, low. \\
\hline OCRH & EQU & \$16 & Output compare register, high. \\
\hline OCRL & EQU & \$17 & Output compare register, low. \\
\hline TDRH & EQU & \$18 & Timer data register, high. \\
\hline TDRL & EQU & \$19 & Timer data register, low. \\
\hline MISC & EQU & \$10 & misc. register \\
\hline OSD & EQU & \$20 & 18 OSD data registers \\
\hline CAS & EQU & \$32 & Color 6 status register \\
\hline C34 & EQU & \$33 & Color 3/4 register \\
\hline RAD & EQU & \$34 & Row address \({ }^{\text {c character size }}\) \\
\hline WCR & EQU & \$35 & Window/Column register \\
\hline CCR & EQU & \$36 & Column/color register \\
\hline HPD & EQU & \$37 & Horizontal position delay \\
\hline MADR & EQU & \$39 & \\
\hline FDR & EQU & \$3A & \\
\hline MCR & EQU & \$3B & \\
\hline MSR & EQU & \$3C & \\
\hline MDR & EQU & \$3D & \\
\hline TR1 & EQU & \$3E & Test 1, OSD/Timer/PLM \\
\hline TR2 & EQU & \$3F & Test 2, EPROM \\
\hline
\end{tabular}













\begin{tabular}{|c|c|c|c|c|}
\hline \multicolumn{5}{|l|}{\multirow[t]{2}{*}{}} \\
\hline & & & & \\
\hline  & \multicolumn{4}{|l|}{Reveal, top/bottom clock.} \\
\hline \multirow[t]{3}{*}{reveal} & BRSET & 5, R7, REV & & \\
\hline & BSET & 5,R7 & & \\
\hline & BRA & OUT & & \\
\hline \multirow[t]{2}{*}{REV} & BCLR & S, R7 & & \\
\hline & BRA & OUT & & \\
\hline \multirow[t]{4}{*}{EXPTB} & BRCLR & 3,R7, EXP & & \\
\hline & BRCLR & 3, R7, BOT & & \\
\hline & BCLR & 3,R7 & SINGLE HEIGHT & \\
\hline & BRA & OUT & & \\
\hline \multirow[t]{2}{*}{BOT} & bsET & 4, R7 & BOTTOM & \\
\hline & BRA & OUT & & \\
\hline \multirow[t]{2}{*}{EXP} & BSET & 3,R7 & & \\
\hline & BCLR & 4,R7 & TOP & \\
\hline OUT & JMP & TXT2 & & \\
\hline \multirow[t]{3}{*}{TIME} & BRSET & 6, STAT7, HIGH & & \\
\hline & BRCLR & o, stat, clock & TELETEXT MODE ? & \\
\hline & JMP & SUBPG & & \\
\hline \multirow[t]{17}{*}{CLOCK} & BRSET & 5, STAT, TAO & NO, time already on ? & \\
\hline & LDA & Acc & & \\
\hline & STA & R4 & & \\
\hline & JSR
BSET & UCHOLD & & \\
\hline & BSET & S,Stat & & \\
\hline & CLPA & & & \\
\hline & BSR & NOBX & & \\
\hline & LDA & 430 & & \\
\hline & BSR & BOXOON & & \\
\hline & JSR & FRO & & \\
\hline & LDA & \$\$09 & & \\
\hline & STA & R7 & & \\
\hline & JSR & TXT2 & Stor flashes on first & T Press \\
\hline & LDA & \$\$46 & & \\
\hline & STA & R5 & & \\
\hline & STA & R6 & & \\
\hline & JSR & TXT2 & & \\
\hline \multirow[t]{3}{*}{tao} & LDA & 46 & & \\
\hline & STA & TMR & & \\
\hline & RTS & & & \\
\hline \multirow[t]{3}{*}{nobx} & STA & R10 & & \\
\hline & LDA & \$ \(\$ 20\) & & \\
\hline & BRA & B0X & & \\
\hline \multirow[t]{3}{*}{BOXOON} & STA & R10 & & \\
\hline & LDA & 4\$0B & & \\
\hline & BRA & Box & & \\
\hline \multirow[t]{2}{*}{B0x00F} & STA & R10 & & \\
\hline & LDA & \$\$0A & & \\
\hline \multirow[t]{7}{*}{Box} & STA & R11 & & \\
\hline & STA & PH & & \\
\hline & LDA & R4 & & \\
\hline & STA & R8 & & \\
\hline & CLR & R9 & & \\
\hline & LDA & \$6 & & \\
\hline & JMP & TXT32 & & \\
\hline
\end{tabular}











\title{
Using the MC68HC11K4 Memory Mapping Logic
}

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}

\section*{INTRODUCTION}

\begin{abstract}
The MC68HC11K4 is provided with memory expansion logic which allows the 64 K Byte addressing range of the 68 HC 11 CPU to be extended to more than 1 Mbyte . This application note discusses the operation of this logic and provides examples of memory maps and possible hardware configurations.
\end{abstract}

\section*{THE MC68HC11K4 MEMORY EXPANSION LOGIC}

The memory expansion logic extends the addressing range of the 68 HC 11 CPU by providing two new onchip blocks. The first new block implements additional address lines which are only made active when required by the CPU. The second block eases interfacing to external memory chips by providing chip select signals. Both of these blocks are fully user programmable.

\section*{ADDITIONAL ADDRESS CAPABILITY}

If the addressing capability of the 68 HC 11 CPU is to be extended then the first step involved is to provide additional address lines. The CPU itself provides 16 lines ( \(A 0\) to 15 ) which allow up to 64 K Bytes of memory to be accessed. Each new address line provided will double that total.

To maintain compatibility with other members of the 68 HC 11 family the CPU used in the K4 is not functionally changed. The extra addressing capability is provided in
such a way that the CPU itself is unable to distinguish more than 64 K Bytes of memory. The extra capacity is provided by switching banks of the extra memory in and out of the 64 K Byte range provided. To maximise the flexibility of this approach the size and number of the switched banks is user programmable.

To use extended memory, the programmer must first allocate a range (called a window) within the CPU 64 K Byte addressing range which will be used when banks are switchedin and out. The memory expansion logic allows windows of \(8 \mathrm{~K}, 16 \mathrm{~K}\) or 32 K Bytes to be defined and placed at programmable points in the CPU 64K Byte memory. At any time only one bank may be displayed in the defined window and therefore the CPU may only have access to the memory contents of one bank at a time. The bank which is displayed in the window is selected by the additional address lines provided by the memory expansion logic. The process of replacing the active bank with a new bank is called bank-switching.

A usefulanalogy is that of photographic transparencies and a projector. The viewer may have many transparencies but is only able to view one at a time in the projector. If the photographs are numbered then the viewer is able to select precisely which one to view without having to go through all of them. Here the memory banks are akin to the transparencies many are available but only one is accessible at any time. The number on the transparency can be thought of here as an address. Any transparency which is not being displayed at any one time is still accessible but only when the current one is removed and it is put in its place.

To extend the addressing capability of the CPU, six address lines were added. These are termed XA13, XA14, XA15, XA16, XA17 and XA18. To allow flexibility in the size of the windows, the lower three address lines are only used when determined by the size of the window and replace the CPU's equivalent addresses.

To understand the need for the XA13 to XA15 addresses consider the case when an 8 K Byte window is being used. Address lines XA16 to XA18 are only active when the CPU is accessing memory within the window and they provide an extra \(8\left(2^{3}\right)\) times the memory provided by the CPU within that window. If an 8 K Byte window is used then a maximum of \(8 \times 8 \mathrm{~K}\) Bytes is available. However, for the CPU to uniquely distinguish each location in the 8 K Byte window it only requires to use addresses A0 to A12. Changes in address lines A13 to A15 take it outside of the window and are therefore never valid within the window except to identify the starting address of the window. The three new addresses XA13 to XA15 are provided so that a full 512 K Byte ( \(8 \times 8 \times 8 \mathrm{~K}\) Byte) range is realised. For a 16 K Byte window only addresses XA14 and XA15 can be used and for 32 K Byte only XA 15 is usable. Note that the size of the memory window to be used need not necessarily be defined at the hardware design stage since the additional addresses XA13 to XA15 can be programmed to carry the CPU A 13 to \(A 15\) signals. The situation may be complicated by the need to use differently sized windows (see example 2).

The memory expansion logic actually allows the user to define two independent windows and so more than 1 M Byte of memory is accessible.

The hardware required to implement such a large memory range is greatly simplified by the use of the memory expansion's chip select block.

\section*{CHIP SELECTS}

The memory expansion chip selects are provided to help the user interface the \(K 4\) with external memories. Four are provided but only three are of directimportance to the memory expansion logic. These are the two General Purpose Chip Selects and the Program Chip Select. The fourth, I/O Chip Select, is used to simplify the addition of external peripheral chips.

The basic function of a chip select is to provide a logic signal to indicate that the CPU is accessing a certain area of memory. For example, the Program Chip Select is intended to be active in the range of memory where the main program exists. Other chip selects will be active when their respective memory areas are used.

The General Purpose Chip Selects are the most flexible of those provided and their function is closely linked to the memory expansion logic. They can be programmed to be active on an area either within the CPU 64 K Byte memory or within either window's 512K. Byte range. In both cases the size of memory selected is fully programmable from 2 K Bytes to 512 K Bytes.

The above paragraphs outline the method by which the memory expansion logic extends the addressing range of the CPU. A detailed description of the internal registers used to implement the new logic is now required. Finally a series of examples are considered.

\section*{MEMORY EXPANSION AND CHIP SELECT REGISTERS}

This discussion describes the functionality of the internal registers relating to the memory expansion logic and chip selects. Further details on their addresses and specific bit operations may be found in the Technical Summary [1].

The following registers perform the memory expansion function.

The MMWBR register allows the starting address of each of the two windows within the CPU 64K Byte address range to be defined. The windows will normally start on a boundary related to their size, for example an 8 K Byte window may start on any 8 K Byte boundary starting at \(\$ 0000\), that is, \(\$ 2000 \$ 4000\)... \(\$ E 000\). A 16K Byte window can only start on 16K Byte boundaries, \(\$ 0000 \$ 4000 \ldots \$ C 000\). An exception is made for the 32 K Byte window. This would normally start at either \(\$ 0000\) or \(\$ 8000\). However, the window is also allowed to start at \(\$ 4000\).

The MMSIZ register sets the size of the windows in use and selects whether the chip selects are active for only CPU addresses or for extended addresses.

Each General Purpose Chip Select has two registers called GP1CSC, GP1CSA and GP2CSC and GP2CSA.

The control register (GP7CSC) determines the logical output required when an area of memory is selected (with possible logic combinations with other chip selects) and the range of memory over which the chip select is to be active. Each chip select can be programmed to become active whenever the CPU address enters an memory expansion window (regardless of the actual bank selected); this is known as following a window.

The address register (GPTCSA) allows the starting address of the chip select to be programmed. The bits in this register which are active are determined by the size of the chip select range selected by the control register.

The program and I/O chip selects are programmable via the CSCTL register.

Two window registers, MM1CR and MM2CR, are used to indicate which bank is active in a window. Each contains the values of XA13 to XA18 to be output when the CPU selects addresses within the extended memory window. To change banks the user writes the address of the new bank into the appropriate window register.

The actual memory expansion address lines are multiplexed with PORT GI/O pins. Selectingan address line on one of these pins means that a PORT G pin is lost. For this reason the user need only select those address lines which are needed by the expansion logic. This allows unused lines to be used as general purpose 1/O. The register which defines which extended address lines are used is PGAR. If an address line is not required then the appropriate bit in PGAR should be cleared to 0 . A special case exists for two address lines which overlap the CPU address lines (XA13 and XA14). If XA13 or XA14 are selected as address lines in PGAR, but are not used in either window, then the appropriate CPU address line will be output on the port.

\section*{EXTENDED MEMORY EXAMPLES}

The best way to grasp the implications of the K4 extended memory function is to consider some examples. Each example consists of two figures. Figures a are the logical arrangement of the memory and Figures \(b\) are a possible hardware configuration.

Example 1 shows one window in use. This is an 8 K Byte window scheme and provides 8 banks from a single 64 K Byte EPROM chip. Note that the logical address of each bank is derived from address lines \(A 0\) to A12 then XA13 to XA15. Chip select 1 is used.

Example 2 shows two windows in use. The first window is of 8 K Bytes and is organised as in example 1. The second window is of 16 K Bytes and is organised as 16 banks in two 128 K Byte RAM chips. The logical addresses of the Window 2 banks are determined by A0 to A13 then XA14 to XA17 (XA18 determines start address). Chip select 2 is used for window 2.

Example 3 shows the same two windows as in example 2 except that the logical addressing of the windows are changed. Now Window 1's logical address is determined by AO to A12 then XA15 to XA17 (XA13 and XA14 ignored) and Window 2's logical address is determined by A0 to A13 then XA15 to XA18 (XA14 ignored). Note that in both windows every bank will be duplicated due to the lack of decoding on certain address lines. In Window 1 each bank is duplicated four times. In Window 2 each bank is duplicated twice.

Example 4 shows the maximum 1 Mbyte extended memory possibility in use. Window 1 is 16 K Bytes starting at \(\$ 0000\) and Window 2 is 32 K Bytes starting at \(\$ 4000\). Note that the internal RAM and registers of the \(K 4\) are echoed in every page of window 1 , but that the internal EPROM in window 2 only occurs in the first 64 K Bytes of extended memory. That is, for addresses below \$10000, the internal EPROM is present in the memory map at the relevant address. This currently applies to all window sizes and configurations, however, the user should avoid referring to EPROM at any address beyond page 0 to ensure compatibility with any future upgrades.

Logical addresses of both windows are given by A0 to A13 then XA14 to XA18. Window 2 uses XA14 because it does not start on a 32 K Byte boundary and so requires that the XA14 is inverted. Both chip selects are used and follow a window each.

PGAR \$3F - XA13..XA18 MMSIZ \$42-Window 18 K MMWBR \(\$ 04\) - window at \(\$ 4000\) CSCTL \(\$ 00\) - no I/O or program chip select GPCS1A \(\$ 00\) - from \(\$ 00000\) GPCS1C \(\$ 06-64 \mathrm{~K}\) range ( \(8 \times 8 \mathrm{~K}\) ) GPCS2A \(\$ 00\) - not relevant GPCS2C \(\$ 00\)-disabled

Figure 1a. One 8K Byte window





PGAR \$3C - XA15..XA18 MMSIZ \$E2 - Window 18 K , Window 216 K MMWBR \(\$ 84\) - Window 1 at \(\$ 4000\). Window 2 at \(\$ 8000\) CSCTL \(\$ 00-\) no \(1 / O\) or program chip select



PGAR \$3E - XA14..XA18 MMSIZ \$F2 - Window 1 16K, Window 2 32K MMWBR \(\$ 40\) - one window at \(\$ 0000\), one at \(\$ 4000 \quad\) CSCTL \(\$ 00-\) no I/O or program chip select GPCS1A \$00-not relevant GPCS2A \$00-not relevant

\section*{GPCS1C \$0A - follow window 1} GPCS2C \$OB - follow window 2



Figure 4b. One MByte in two windows

\section*{CONCLUSION}

The standard 64 K Byte sddressing range of the M6BHCll family is easily extended using the MC68HC(7)11K4 memory expansion. This logic also provides programmable chip selects to allow easy interfacing with extemal memory chips. A similar extended memory system may be implemented on other NisbHC 11 products by following other systems as described in [2].

\section*{REFERENCES}
(11) MC68HC711K4 Technical Summary, Reference BR751/D
12] "128K byte addressing with the M68HC11", Reference AN432/D

\title{
A Monitor for the MC68HC05E0
}

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}

\section*{INTRODUCTION}

Development systems for single-chip MCUs can be complex and expensive. This can dissuade potential users of this type of microprocessor from designing them into new applications. This application note describes a simple "entry" development system suitable for debugging hardinare and software for the M6805 range of microprocessors. The M6805 range includes both CMOS and NMOS parts, most of which are single-chip devices which include mask-programmable ROM, RAM, I/O and one or more timers. The exceptions are the CMOS MC146805E2 and MC58hCO5EO which have no on-chip ROM but instead have data and address buses which enables them to use external memories and peripherals.

The development system uses the MC68HC05E0 processor and can be used to develop applications intended for any M6805 but is particularly suitable for applications which will use the MC68HC05E0 itself. The MC68HC05E0 has a non-multiplexed bus which requires no additional hardware to interface with RAMs, ROMs and EPROMS. It has 480 bytes of RAM, 3 timers, 3 chip-select lines and 48 -bit ports enabling it to meet many requirements with the addition of only an EPROM containing the application software.

Such a system will be most cost effective in small volume applications not justifying a mask programmed single-chip MCU and also in applications requiring larger programs than can be accommodated in ROMed MCU versions.

For software development, however, RAM and a monitor have to be incorporated so software can be loaded and de-bugged. An MCM6264 8Kbyte (or MCM60L256/MCM6206 32Kbyte) RAM is used. The EBUG05 monitor EPROM, listed at the end of this application note, fulfils the monitor requirement.

In an E0 application the development system can be used as an add-on to the target system hardware, as shown in Figure 1 (components to the left of the dotted line). The application hardware needs very little modification as it already contains the MPU, the interface to the development system being mostly via the socket for the EPROM. Apart from the keyboard and display connections which use port A, only four or five additional connections are required. These can be made available on a small connector on the application PCB. In one of the 8K applications, used to check out the development system (reference 1), a keyboard and display were required, so only four \(1 / O\) lines (see below) were dedicated to the development system. In a 16 K application, A13 (PD5) is also required, so a fifth I/O line would be used. The keyboard provides up to 32 keys using \(7 \mathrm{I} / \mathrm{O}\) lines and an external 3 -line to 8 -line decoder. One additional I/O line is used for the display. If the keyboard and/or display is not required in the final application (e.g., reference 2 ) then the I/O lines, used by them during development, are available for other purposes but their use cannot readily be de-bugged. This is a disadvantage of such a simple development system. There is, however, a major advantage of this system compared with those which use the display and keyboard of a PC. In this system the PC can be used to display the program listing file, obviating the need for printouts during debug.

\section*{CIRCUIT}

Figure 1 shows the circuit used. The 8 K or 16 K (half of an MCM60L256) RAM is placed between \(\$ 0000\) and \(\$ 3 F F F\); this means that the 512 bytes from \(\$ 0000\) to \(\$ 01\) FF are not used, as they are mapped over the EO's I/O and RAM space. Locations \(\$ 0200\) to \(\$ 021 \mathrm{~F}\) are used by the monitor, so use of the RAM should start at \(\$ 0220\) or above. Some RAM may be required to replace E0 page 0 RAM ( 16 bytes), used by the monitor or for other purposes during de-bug; the application used to check out the monitor used RAM from \(\$ 0400\). This provides 7 K (15K using an MCM60L256) of RAM for the code being de-bugged. The start address chosen for the code being developed can be extended down to \(\$ 0220\) if this RAM is not required, providing a program space of nearly \(15^{1 / 2 K}\) Kytes. The 16 K limitation is caused by the split of the memory map into four (see Figure 3), to simplify address decoding and facilitate the ability to load code from an EPROM. If this capability is not required, more complex address decoding would allow up to 60K of RAM to be available for code; the monitor uses less than \(4 K\).

The MC74HC138 provides the chip selects during de-bug as the on-chip chip selects signals are not suitable for the monitor's address map. The final system will usually not require an MC74HC138.

The 28 -pin EPROM socket which will contain the final de-bugged code is used during development as the main interface to the monitor and its RAM. Only four or five other signals are required. These are the two or three most significant address lines, A15, A14 and, optionally, A13 and the clock (P02), which are required by the MC74HC138, the RM line and a port line (PB2) for inputting or outputting code on an RS232 serial link. PB2 can be used in the application as it is only used by the monitor during serial transfers when the application is not running. Care should, however, be taken to avoid contention within the hardware connected to PB2. If only 8 K bytes of external RAM are required, then A13 is not required and its pin, PD5, can be used by the application.

The hardware connected to the EPROM socket can also include a 28 -pin socket to accommodate a 27 (C) 64 or \(27(\mathrm{C}) 128\) EPROM. This is addressed between \(\$ 4000\) and \(\$ 7 \mathrm{FFF}\) and can be used to introduce software from an EPROM which has been programmed with code for de-bug. The monitor contains a routine which transfers the contents of this EPROM into RAM. Alternatively, code can be loaded serially via the RS232 interface.

The EBUG05 monitor EPROM (27C64) included in the external hardware is enabled from \(\$ C 000\) to \(\$\) FFFF, although its actual start address is \(\$ E 000\). Figure 3 shows the memory map of the development system.

The monitor display is a 6 -digit 4-backplane LCD (e.g., Hamlin type 4200 or the 8 -digit GE type LXD69D3F09KG), which is driven by an MC145000P display driver. The driver is controlled by a 2 -line serial link from the microprocessor. A single-backplane display can be used as an alternative, as shown in Figure 2. Three MC144115 driver chips are used along with a transistor inverter to supply the additional latch enable signal required by these drivers. This circuit requires more connections to the LCD but allows the use of a more commonly available display.

The optional RS232 interface can be implemented using the single-supply MC145407 driver-receiver chip. If outputting of S -records is not required, then a simple transistor inverter with a pull-up resistor and a reverse polarity protection diode can be used. This interface is shown in Figure 4.



Figure 2. Alternative static LCD display
\begin{tabular}{|c|c|}
\hline MC68HCO5EO I/O, timers & \multirow[t]{2}{*}{\[
\begin{aligned}
& 001 \mathrm{~F} \\
& 0020
\end{aligned}
\]} \\
\hline MC68HC05EO RAM (16 bytes used by EBUG05) & \\
\hline \begin{tabular}{l}
MC68HC05E0 RAM \\
(464 bytes including stack at 00FF), for use in application
\end{tabular} & \[
\begin{aligned}
& 002 \mathrm{~F} \\
& 0030
\end{aligned}
\] \\
\hline \begin{tabular}{l}
MC68HCO5EO RAM \\
( 32 bytes used by EBUG05)
\end{tabular} & \[
\begin{aligned}
& 01 \mathrm{FF} \\
& 0200
\end{aligned}
\] \\
\hline External RAM, can be used for data and/or program & \[
\begin{aligned}
& 021 \mathrm{~F} \\
& 0220
\end{aligned}
\] \\
\hline Optional EPROM socket & \[
\begin{aligned}
& 3 \text { FFF } \\
& 4000
\end{aligned}
\] \\
\hline not used & \[
\begin{aligned}
& \text { BFFF } \\
& \text { COOO }
\end{aligned}
\] \\
\hline EBUG05 monitor & \[
\begin{aligned}
& \text { COOO } \\
& \text { FFF5 }
\end{aligned}
\] \\
\hline MC68HCO5EO vectors & \[
\begin{aligned}
& \text { FFF6 } \\
& \text { FFFF }
\end{aligned}
\] \\
\hline
\end{tabular}

Figure 3. Memory Map


Figure 4. Simple input-only RS232 interface


Figure 5. IDD Monitor Circuit

\section*{IDD INDICATOR}

It is often useful with CMOS circuits to provide a simple IDD monitor which shows via an LED whether or not the IDD is above or below a specific value. In this application it shows whether or not the microprocessor is in the STOP mode. The required circuit is shown in Figure 5. The current threshold can be chosen by selecting the value of R1. A value of 1 kohm sets the limit at about \(500 \mu \mathrm{~A}\) which means the LED should be off when the EO is in STOP mode and on otherwise. The \(500 \mu \mathrm{~A}\) limit allows the LCD and perhaps a CMOS target application to be supplied without switching on the LED. When the microprocessor is not in STOP mode, its IDD is several milliamps and the LED should be lit. If a multiplexed LCD is used, it may be preferable not to supply it via this type of monitor circuit, as a significant change in contrast may occur as the microprocessor goes into its STOP mode (see Figure 5). The monitor drops about 600 mV when the microprocessor is running, so the supply voltage should be chosen accordingly. While the microprocessor will operate down to 3 V (at an appropriate frequency), the RAM and EPROM chips are specified at \(5 \mathrm{~V} \pm 0.5 \mathrm{~V}\). For battery operation 4 zinc-carbon or 5 Ni -Cad cells can be used.

\section*{EBUG05 KEY FUNCTIONS}

The EBUG05 EPROM comprises a monitor, developed from the MC146805E2 CBUG05 program, specifically written to enter and debug 6805 code. The following functions are available using the 24-key keyboard:
\begin{tabular}{|c|c|c|}
\hline Function & Key & Description of function \\
\hline PC & 0 & Display program counter. \\
\hline BP & 5 & Enable breakpoints. The first breakpoint is displayed if enabled or boff if it isn't. Enter new breakpoint address followed by ENTER to change, or just ENABLE to move to next one, three breakpoints are available. This number can be increased, the only cost being the additional RAM used ( 3 bytes per breakpoint). \\
\hline BPC & 6 & Clear breakpoints. ENTER clears all breakpoints. Entering a number followed by ENTER clears that breakpoint only. \\
\hline OFF & A & Calculate branch offset. The address of the branch instruction and that of the destination are requested. If a valid branch is calculated, it is written into memory and displayed. If not valid, then "or" for out of range is displayed. A branch of -128 through +127 relative to the start address of the next instruction is allowed. \\
\hline TR & B & "Trace" one instruction. This is not a true trace as breakpoints are advanced sequentially through the code and do not follow branches or jumps (see below). \\
\hline STOP & C & Put the EO into STOP mode, clock stops. \\
\hline WAIT & 3 & Put the EO into WAIT mode. \\
\hline CC & D & Display/change Condition Code register, new data is followed by ENTER. ESC returns to "ם" prompt without changing contents. \\
\hline XR & E & Display/change indeX Register, new data is followed by ENTER. ESC returns to " \(\square\) " prompt without changing contents. \\
\hline AR & F & Display/change Accumulator, new data is followed by ENTER. ESC returns to "ロ" prompt without changing contents. \\
\hline P & P & Output S-records. When this key is pressed, "bA" for begin address is displayed; enter first address (and ENTER), then last address when "EA" is displayed. Another ENTER starts the RS232 S-record output. \\
\hline L & L & Load S-records from the RS232 interface. Press L and "LOAd" is displayed. Srecords sent to 2, PORTB, will be loaded until an S9 record is received. The prompt returns if the load was OK. If not, an error message is displayed (see next section). \\
\hline v & v & Verify RAM against S-records. "UErIFy" is displayed, otherwise the same as LOAD including error checks. \\
\hline ENTER & ENT & Enter keyed-in address or data (and move to next address in "M"). \\
\hline ESC & ESC & Escape from current function (except STOP, WAIT, V, L \& P). \\
\hline
\end{tabular}
\begin{tabular}{|l|c|l|}
\hline Function & Key & Description of function \\
\hline GO & GO & \begin{tabular}{l} 
Begin or continue program. When pressed current PC is displayed. To proceed \\
from that location, press ENTER; to proceed from a different address, enter the \\
address followed by ENTER.
\end{tabular} \\
\hline M & M & \begin{tabular}{l} 
Display/change a location in RAM. When pressed, last address is displayed. Press \\
ENTER to display the contents of this address or enter a new address, followed by \\
ENTER. New contents can be entered (followed by ENTER) if required. ENTER \\
moves to next address; M moves to previous address.
\end{tabular} \\
\hline SP & SP & \begin{tabular}{l} 
Display stack pointer; cannot be modified.
\end{tabular} \\
\hline XFER & 7 & \begin{tabular}{l} 
Transfer code from an EPROM between \(\$ 4220\) and \(\$ 7 F F F\) into RAM (\$0220 to \\
\$3FFF). When pressed, default start address (in RAM) is displayed. Press ENTER \\
to start at this address (\$0400), or enter new start address followed by ENTER. End \\
address (in RAM) is displayed. Press ENTER to transfer code up to this end address \\
(\$1FFF), or enter new end address followed by ENTER. The lowest allowable start \\
address is \$0220 and the highest end address is \(\$ 3 F F F\). During the transfer the \\
code is read from the EPROM at the RAM addresses plus \$4000. The code in \\
EPROM should have been assembled with the start address where it will reside \\
during execution (e.g., \$0400).
\end{tabular} \\
\hline
\end{tabular}

\section*{USE OF THE MONITOR}

The MC68HC05EO's vectors are within the address space of the EBUG05 EPROM. They operate via extended jumps in RAM. This gives the user access to the vectors if these jumps are written to, from within the user's program. The vectors' locations are shown in Table 1. The extended jump instruction (\$CC) is written to RAM by the monitor; all the user has to do is to overwrite the destination addresses at the locations indicated in the Table. This must be done at the start of the user code, before interrupts are enabled. Vectoring the jumps through a table at a fixed location in the user code obviates the need to change this initialisation when re-assembling changes the addresses of the interrupt service routines. Lines of code for this purpose are included as comments in reference 2.

Clearly the RESET vector cannot be altered in this way, so during debug user software should be started using the GO facility in EBUG05. Software interrupts (SWIs) are used by the monitor to facilitate breakpoint and should therefore not be used in the application software.

Software for de-bug should be assembled to reside in RAM, starting at address \(\$ 400\) (or down to \(\$ 220\) if more space is required, see above). It can be introduced into the system in an EPROM at \(\$ 4000\) or loaded serially from a PC via the RS232 interface. The monitor includes a routine to move the code from EPROM to RAM, where it can be executed and debugged using EBUG05. This provides an alternative method of loading code for debug if a serial load is not appropriate. When debug is complete, the code should be reassembled at \$E000 (or \$C000 if a 16K EPROM is used). When the code is in EPROM, the vectors should be included. The jumps required during debug are then no longer relevant.

CSROM will normally be suitable for selecting this EPROM, so that the MC74HC138 will not be required once the code has been finalised.

Table 1.
\begin{tabular}{|c|c|c|}
\hline Vector & Address & JMP location in RAM \\
\hline SPI/IIC & \$FFF4-5 & \$0209 (add: \$20AB) \\
\hline Timer B & \$FFF6-7 & \$0206 (add: \$207/8) \\
\hline Timer A & \$FFF8-9 & \$0203 (add: \$204/5) \\
\hline IRQ & \$FFFA-B & \$0200 (add: \$201/2) \\
\hline SWI & \$FFFC-D & used by monitor \\
\hline RESET & \$FFFE-F & use "GO" function \\
\hline
\end{tabular}

\section*{BREAKPOINTS}

Up to three breakpoint addresses can be entered; this number can be easily increased if required by changing the EQU on line 25 of EBUG05 source code. To allow the continuation of execution from a breakpoint, a breakpoint at the start address specified by a GO is ignored. This means that a single breakpoint in a loop will only be encountered once if, after it has occurred, execution is re-commenced with a GO from the current address. If it is required to stop at the breakpoint again, then one of the two procedures described here should be used. Two breakpoints can be entered at different places in the loop. They will be encountered alternately; clearly, two GOs are required for each execution of the loop. A second method is to insert only one breakpoint but to trace one instruction before continuing with a GO. This trace takes the program counter past the breakpoint address and so allows the breakpoint to be re-inserted when GO is executed. This will only work reliably if the breakpoint in not on a branch, jump, or any other instruction that could cause the program to proceed to an address other than the next sequential address (see below).

If a single breakpoint has been entered and encountered and execution re-started with a GO from the same address, then pressing RESET is the only method of returning to the monitor. Normally pressing RESET when the program is running with breakpoints valid is not recommended as the application code will be left corrupted with SWIs replacing the instructions at the breakpoint addresses. If, however, control has been lost because execution was recommenced from the address of a single breakpoint, then corruption will not occur as the breakpoint will not have been re-inserted.

Breakpoints are inserted when TRace or GO are executed but removed when a breakpoint is encountered. The trace facility inserts a breakpoint (SWI) at the address of the instruction sequentially after the current instruction and then executes the current instruction. If the current instruction jumps or branches somewhere else then the SWI will not be encountered. This is thus not a true program-following trace but in many cases is more useful as often subroutines do not need to be traced, variables being required to be checked only after each subroutine has been executed. If it is required to trace the program flow to the other address, then another breakpoint should be inserted at that address.

\section*{SERIAL LOAD}

To load external Motorola S-records, the serial load key ( L ) should be pressed. The LCD will display "LOAd". S-records should then be supplied at 9600 baud (8-bit, no parity) on the RS232 interface. When an S9 termination record is received, the prompt returns. If an error is detected during a serial load, the load routine stops and displays the address at which the error occurred and the error type. The following error types are possible.

1: Checksum error, transmitted data or interface faulty.
2: RAM read-back error, RAM faulty or nonexistent.
3: \(\quad\) ASCII character less than \(\$ 30(0)\) received.
4: \(\quad\) ASCII character between \(\$ 39(9)\) and \(\$ 41(\mathrm{~A})\) received.
5: \(\quad\) ASCII character more than \(\$ 46(F)\) received.
7: Verify error when comparing S-records with RAM.

The verify function can be used to check that the RAM has not been corrupted. The VERIFY function is used exactly like LOAD except that RAM is compared with, rather than loaded by, the S-records.

The S-record format can be seen in the example below. The number following the \(S\) is the record type. The monitor only recognises \(S 1\) (8-bit data) and S9 (termination) records. The next byte ( 23 in most of the records) is the number (in hex) of bytes which follow. This is followed by a 2-byte address (e.g., E000 and FFF4), then the data. The last byte is a checksum byte. The sum of all bytes, including the byte count and the checksum byte, is \(\$ X X F F\). This can be easily checked on the \(S 9\) record \((03+00+00+F C=F F)\).
```

S123E000CDE05F24FB5FB728D6E09FB128270BC1E0BF273A5C5C5C5C20EEA601B70E5CDC50
S123E020E09FA6E3B7123F00A6F0B705A658B701A6FBB7063F02A6FFB7073F03A61CB708FF
S123E5E0305A26F8AD3020EAA1102705A11126E29981AE04BF28B72D4444444497D6E4CD2C S123E600BE28E720B62DA40F97D6E4CDBE28E721CDE1ECB62D81B72EBF2CB6305FADD5B61C S10DE6202BAE02ADCFB62EBE2C8146 S10FFFF4E022E022E022E04EE022E022C5 S9030000FC

```

\section*{SERIAL INTERFACE}

Figure 6 shows a suggested method of wiring up the RS232 sockets in a system with both loading and dumping capabilities. This arrangement facilitates use of the serial LOAD and DUMP routines of the monitor either via a PC COM port or between a host and terminal connected by an RS232 link. When using a PC, the "host" socket should be used. As only one pin on the MC68HCO5EO is used, switching is required to make the required connections. S2 can be eliminated (or left at "L") if only loading is required, as will often be the case. To save power in battery applications, the RS232 interface chip can be switched off using S1. Table 2 shows possible methods of use.


Figure 6. RS232 serial interface with Load/Dump switching
Table 2.
\begin{tabular}{|l|c|c|c|l|}
\hline \multicolumn{1}{|c|}{ Set-up } & Function & S1 & S2 & \multicolumn{1}{|c|}{ Comments } \\
\hline \multirow{2}{*}{\begin{tabular}{l} 
Host \& \\
terminal
\end{tabular}} & Load & On & L & \begin{tabular}{l} 
Terminal and host connected. Micro looks at data \\
sent from host to terminal (pins 3).
\end{tabular} \\
\cline { 2 - 5 } & Dump & On & D & \begin{tabular}{l} 
Connection between terminal and host broken, \\
S-records sent to both host (2) and terminal (3).
\end{tabular} \\
\hline \multirow{2}{*}{\begin{tabular}{l} 
PC "COM" \\
port
\end{tabular}} & Load & On & L & S-records loaded from pin 3. \\
\cline { 2 - 5 } & Dump & On & D & \begin{tabular}{l} 
S-records sent to pin 2 on "host" socket \\
(and pin 3 on "terminal" socket).
\end{tabular} \\
\hline
\end{tabular}

\section*{REFERENCES}
1) \(A N 441 / D\), An EPROM Emulator using the MC68HCO5EO.
2) AN460/D, An RDS Decoder using the MC68HC05EO.

\section*{APPENDIX - EBUG05 E0 monitor listing}


\begin{tabular}{|c|c|c|c|}
\hline \multicolumn{4}{|l|}{*} \\
\hline * & \multicolumn{3}{|l|}{Reset.} \\
\hline * & & & \\
\hline \multicolumn{4}{|l|}{} \\
\hline \multirow[t]{25}{*}{RESET} & \(\cdots\) & SSO & TUP PORT \\
\hline & STA & \(\cdots \cdots\) & - JR KEYPAD \\
\hline & LDA & \(\cdots\) & SETUP PORTD \\
\hline & STA & PORT \(F\) & FOR ADDRESSES ETC. \\
\hline & LDA & \# \({ }^{\text {S }}\) CC & \multirow[t]{21}{*}{VECTORS IN RAM} \\
\hline & STA & IRQ & \\
\hline & STA & TIRQA & \\
\hline & STA & TIRQB & \\
\hline & STA & SIRQ & \\
\hline & LDA & VECTOR & \\
\hline & STA & IRQ +1 & \\
\hline & LDA & VECTOR+1 & \\
\hline & STA & IRQ+2 & \\
\hline & LDA & VECTOR +2 & \\
\hline & STA & TIRQB+1 & \\
\hline & LDA & VECTOR + 3 & \\
\hline & STA & TIRQB+2 & \\
\hline & LDA & VECTOR + 4 & \\
\hline & STA & TIRQA+1 & \\
\hline & LDA & VECTOR +5 & \\
\hline & STA & TIRQA+2 & \\
\hline & LDA & VECTOR+6 & \\
\hline & STA & SIRQ+1 & \\
\hline & LDA & VECTOR +7 & \\
\hline & STA & SIRQ+2 & \\
\hline & LDX & \#STAT & \\
\hline \multirow[t]{6}{*}{INIT} & CLR & \(0, \mathrm{X}\) & CLEAR \\
\hline & INCX & & WORKING \\
\hline & CPX & \#BCNT & \multirow[t]{2}{*}{STORAGE} \\
\hline & BLS & INIT & \\
\hline & JSR & SCNBKP & CLEAR \\
\hline & LDA & \# \({ }^{\text {FFF }}\) & ALL \\
\hline \multirow[t]{7}{*}{REBCLR} & STA & BKPTBL, X & \multirow[t]{7}{*}{BREAKPOINTS} \\
\hline & INCX & & \\
\hline & INCX & & \\
\hline & INCX & & \\
\hline & DEC & PNCNT & \\
\hline & BNE & REBCLR & \\
\hline & SWI & & \\
\hline
\end{tabular}


\begin{tabular}{|c|c|}
\hline \multicolumn{2}{|l|}{0251} \\
\hline \multicolumn{2}{|l|}{0252} \\
\hline 0253 & \\
\hline \multicolumn{2}{|l|}{0254} \\
\hline \multicolumn{2}{|l|}{0255} \\
\hline \multicolumn{2}{|l|}{0256} \\
\hline 0257 & e135 a6 73 \\
\hline 0258 & e137 c7 0210 \\
\hline 0259 & e13a a6 dl \\
\hline 0260 & e13c c7 0211 \\
\hline 0261 & e13f ad e2 \\
\hline 0262 & e141 e6 07 \\
\hline 0263 & e143 b7 22 \\
\hline 0264 & el 145 e6 08 \\
\hline 0265 & e147 b7 23 \\
\hline 0266 & e149 cd e8 \\
\hline 0267 & el4c cc e0 \\
\hline \multicolumn{2}{|l|}{0268} \\
\hline \multicolumn{2}{|l|}{0269} \\
\hline \multicolumn{2}{|l|}{0270} \\
\hline \multicolumn{2}{|l|}{0271} \\
\hline \multicolumn{2}{|l|}{0272} \\
\hline \multicolumn{2}{|l|}{0273} \\
\hline \multicolumn{2}{|l|}{0274} \\
\hline 0275 & e14f a6 77 \\
\hline 0276 & e151 c7 0200 \\
\hline 0277 & e154 c7 02 of \\
\hline 0278 & e157 a6 dl \\
\hline 0279 & e159 c7 02 0d \\
\hline 0280 & e15c c7 020 l \\
\hline 0281 & el5f ad c2 \\
\hline 0282 & el61 9f \\
\hline 0283 & el 162 ab 05 \\
\hline 0284 & el64 3f 22 \\
\hline 0285 & e166 b7 23 \\
\hline 0286 & e168 1c 20 \\
\hline 0287 & e16a cc e6 \\
\hline \multicolumn{2}{|l|}{0288} \\
\hline \multicolumn{2}{|l|}{0289} \\
\hline \multicolumn{2}{|l|}{0290} \\
\hline \multicolumn{2}{|l|}{0291} \\
\hline \multicolumn{2}{|l|}{0292} \\
\hline \multicolumn{2}{|l|}{0293} \\
\hline \multicolumn{2}{|l|}{0294} \\
\hline \multicolumn{2}{|l|}{0295} \\
\hline \multicolumn{2}{|l|}{0296 e16d cd e6 42} \\
\hline \multicolumn{2}{|l|}{0297 e170 a6 06} \\
\hline \multicolumn{2}{|l|}{0298 e172 c7 020 d} \\
\hline \multicolumn{2}{|l|}{0299 e175 a6 e6} \\
\hline 0300 & e177 c7 02 0e \\
\hline \multicolumn{2}{|l|}{0301 el7a a6 60} \\
\hline 0302 & e17c c7 02 of \\
\hline \multicolumn{2}{|l|}{0303 e17f ad a2} \\
\hline \multicolumn{2}{|l|}{0304 e181 9f} \\
\hline \multicolumn{2}{|l|}{0305 e182 ab 06} \\
\hline \multicolumn{2}{|l|}{0306 el84 3f 22} \\
\hline \multicolumn{2}{|l|}{0307 e186 b7 23} \\
\hline \multicolumn{2}{|l|}{0308 e188 1c 20} \\
\hline \multicolumn{2}{|l|}{\multirow[t]{2}{*}{0309
0310 e18a cc e6 ea}} \\
\hline & \\
\hline \multicolumn{2}{|l|}{0311} \\
\hline \multicolumn{2}{|l|}{0312} \\
\hline \multicolumn{2}{|l|}{0313} \\
\hline \multicolumn{2}{|l|}{0314} \\
\hline \multicolumn{2}{|l|}{0315} \\
\hline \multicolumn{2}{|l|}{0316} \\
\hline \multicolumn{2}{|l|}{0317 e18d cd e6 42} \\
\hline \multicolumn{2}{|l|}{0318 e190 a6 d1} \\
\hline 0319 & e192 c7 02 0c \\
\hline 0320 & e195 a6 d7 \\
\hline 0321 & e197 c7 02 od \\
\hline 0322 & e19a a6 e6 \\
\hline 0323 & e19c c7 0200 \\
\hline 0324 & e19f a6 f1 \\
\hline 0325 & elal c7 02 of \\
\hline 0326 & ela4 cd e1 23 \\
\hline 0327 & ela7 9f \\
\hline 0328 & e1a8 ab 04 \\
\hline 0329 & elaa 3f 22 \\
\hline 0330 & elac b7 23 \\
\hline 0331 & elae 1c 20 \\
\hline 0332 & elbo cc e6 ea \\
\hline 0333 & \\
\hline 0334 & \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|c|c|c|}
\hline \multicolumn{6}{|l|}{**************************************************} \\
\hline * & \multicolumn{5}{|l|}{\multirow[t]{2}{*}{Display program counter.}} \\
\hline * & & & & & \\
\hline \multicolumn{6}{|l|}{**************************************************} \\
\hline \multirow[t]{11}{*}{PCOUNT} & LDA & *\$73 & \multicolumn{3}{|l|}{PRINT} \\
\hline & STA & DTABL+4 & \multicolumn{3}{|l|}{\multirow[t]{3}{*}{\({ }^{\prime} \mathrm{PC}{ }^{\prime}\)}} \\
\hline & LDA & \#\$D1 & & & \\
\hline & STA & DTABL+ 5 & & & \\
\hline & BSR & LOCSTK & \multicolumn{3}{|l|}{FIND USER PC} \\
\hline & LDA & 7, x & \multicolumn{3}{|l|}{HIGH BYTE} \\
\hline & STA & ADDRH & & & \\
\hline & LDA & 8, X & \multicolumn{3}{|l|}{LOW BYTE} \\
\hline & STA & ADDRL & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{PRINT IT}} \\
\hline & JSR & PRTADR & & & \\
\hline & JMP & \multicolumn{4}{|l|}{CMDSCN} \\
\hline \multicolumn{6}{|l|}{\multirow[t]{2}{*}{}} \\
\hline & & & & & \\
\hline \multicolumn{6}{|l|}{\multirow[t]{2}{*}{Accumulator examine/change.}} \\
\hline & & & & & \\
\hline \multicolumn{6}{|l|}{*************************************************} \\
\hline \multirow[t]{13}{*}{AREG} & LDA & \#\$77 & \multicolumn{3}{|l|}{PRINT ' \(\mathrm{ACCA}{ }^{\text {¢ }}\)} \\
\hline & STA & \multicolumn{4}{|l|}{DTABL} \\
\hline & STA & \multicolumn{4}{|l|}{DTABL+3} \\
\hline & LDA & \multicolumn{4}{|l|}{\#\$D1} \\
\hline & STA & \multicolumn{4}{|l|}{DTABL+1} \\
\hline & STA & \multicolumn{4}{|l|}{DTABL+2} \\
\hline & BSR & LOCSTK & FIND A & ACCUM. & value \\
\hline & \multicolumn{5}{|l|}{TXA} \\
\hline & ADD & \multicolumn{4}{|l|}{\#5} \\
\hline & CLR & ADDRH & \multicolumn{3}{|l|}{SETUP FOR} \\
\hline & STA & ADDRL & \multicolumn{3}{|l|}{EXAMINE/CHANGE} \\
\hline & BSET & 6, STAT & & & \\
\hline & JMP & MEMEX 3 & \multicolumn{3}{|l|}{USING MEMORY ROUTINE} \\
\hline \multicolumn{6}{|l|}{\multirow[t]{2}{*}{}} \\
\hline & & & & & \\
\hline * & \multicolumn{5}{|l|}{Index reg. examine/change.} \\
\hline \multicolumn{6}{|l|}{************************************************************)} \\
\hline \multirow[t]{14}{*}{XREG} & & & \multicolumn{3}{|l|}{\multirow[b]{2}{*}{PRINT ` Idr`}} \\
\hline & \[
\begin{aligned}
& \text { JSR } \\
& \text { LDA }
\end{aligned}
\] & & & & \\
\hline & STA & \multicolumn{4}{|l|}{DTABL+1 PRINT Idr} \\
\hline & LDA & \multicolumn{4}{|l|}{\#\$E6} \\
\hline & STA & \multicolumn{4}{|l|}{DTABL+2} \\
\hline & LUA & \multicolumn{4}{|l|}{\#\$60} \\
\hline & STA & \multicolumn{4}{|l|}{DTABL+3} \\
\hline & BSR & \multirow[t]{2}{*}{LOCSTK} & \multicolumn{3}{|l|}{FIND INDEX} \\
\hline & TXA & & \multicolumn{3}{|l|}{REGISTER VALUE} \\
\hline & ADD & \multicolumn{4}{|l|}{\#6} \\
\hline & CLR & ADDRH & \multicolumn{3}{|l|}{SETUP FOR} \\
\hline & STA & ADDRL & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{EXAMINE/CHANGE}} \\
\hline & BSET & 6, STAT & & & \\
\hline & JMP & MEMEX 3 & \multicolumn{3}{|l|}{USING MEMORY ROUTINE} \\
\hline \multicolumn{6}{|l|}{\multirow[t]{2}{*}{}} \\
\hline \(\stackrel{*}{*}\) & \multicolumn{5}{|l|}{\multirow[b]{2}{*}{CC reg. examine/change.}} \\
\hline * & & & & & \\
\hline
\end{tabular}
CCODE JSR CLRTAB
LDA \#SD1
\begin{tabular}{ll} 
STA & DTABL \\
LDA & \(\# \$ D 7\)
\end{tabular}
    STA DTABL+1
    LDA \#\$E6
        STA DTABL+2
        LDA \#\$F1
        STA DTABL+3
        \(\begin{array}{lll}\text { STA } & \text { DTABL+3 } & \\ \text { JSR } & \text { LOCSTK } & \text { FIND CONDITION } \\ \text { TXA } & & \text { CODES }\end{array}\)
0327 ela7 9f
0328 ela8 ab 04
0329 elaa 3 f 22
0330 elac b7 23
0331 elae 1c 20
0332 e1b0 cc ef ea
0334








\begin{tabular}{|c|c|}
\hline \multicolumn{2}{|l|}{0726} \\
\hline \multicolumn{2}{|l|}{0727} \\
\hline \multicolumn{2}{|l|}{0728} \\
\hline \multicolumn{2}{|l|}{0729} \\
\hline \multicolumn{2}{|l|}{0730} \\
\hline \multicolumn{2}{|l|}{0731} \\
\hline \multicolumn{2}{|l|}{0732} \\
\hline 0733 & e459 ad 60 \\
\hline 0734 & e45b 0501 fd \\
\hline 0735 & e45e 0401 fd \\
\hline 0736 & e461 ae 07 \\
\hline 0737 & e463 bf 2b \\
\hline 0738 & e465 ad 58 \\
\hline \multicolumn{2}{|l|}{0739} \\
\hline 0740 & e467 ad 52 \\
\hline 0741 & e469 050100 \\
\hline 0742 & e46c 46 \\
\hline 0743 & e46d 3a 2b \\
\hline 0744 & e46f 26 f6 \\
\hline \multicolumn{2}{|l|}{0745} \\
\hline 0746 & e471 44 \\
\hline 0747 & e472 81 \\
\hline \multicolumn{2}{|l|}{0748} \\
\hline 0749 & e473 cc e0 b4 \\
\hline \multicolumn{2}{|l|}{0750} \\
\hline 0751 & e476 ae 02 \\
\hline 0752 & e478 20 d1 \\
\hline 0753 & e47a ae 03 \\
\hline 0754 & e47c 20 cd \\
\hline 0755 & e47e ae 04 \\
\hline 0756 & e480 20 c9 \\
\hline 0757 & e482 ae 05 \\
\hline 0758 & e484 20 c5 \\
\hline 0759 & e486 ae 07 \\
\hline 0760 & e488 20 cl \\
\hline \multicolumn{2}{|l|}{0761} \\
\hline 0762 & \\
\hline
\end{tabular}

\begin{tabular}{|c|c|c|c|c|c|c|c|c|}
\hline 0763 & & \multicolumn{7}{|l|}{***************************************************} \\
\hline 0764 & & \multicolumn{7}{|l|}{* *} \\
\hline 0765 & & * & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{Byte input sub-routines.}} & \multicolumn{3}{|c|}{*} \\
\hline 0766 & & * & & & & \multicolumn{3}{|l|}{} \\
\hline 0767 & & \multicolumn{7}{|l|}{****************************************************} \\
\hline 0768 & 0768 & & & & & & & \\
\hline 0769 & e48a ad cd & \multirow[t]{2}{*}{BYTEI} & BSR & \multirow[t]{2}{*}{\[
\begin{aligned}
& \text { INCHD } \\
& \text { ASCII }
\end{aligned}
\]} & \multicolumn{2}{|l|}{22} & \multicolumn{2}{|l|}{MS NIBBLE} \\
\hline 0770 & e48c ad 17 & & BSR & & 35 & 57 & \multicolumn{2}{|l|}{WHAT WAS IT} \\
\hline 0771 & e48e 48 & \multicolumn{3}{|c|}{LSLA} & 3 & & \multicolumn{2}{|l|}{OK} \\
\hline 0772 & e48f 48 & \multicolumn{3}{|c|}{LSLA} & 3 & & \multicolumn{2}{|l|}{SHIFT} \\
\hline 0773 & e490 48 & \multicolumn{3}{|c|}{LSLA} & 3 & & \multicolumn{2}{|l|}{IT} \\
\hline 0774 & e49148 & \multicolumn{3}{|c|}{LSLA} & 3 & 69 & \multicolumn{2}{|l|}{UP} \\
\hline 0775 & e492 b7 2c & & STA & TMP1 & 4 & 73 & \multicolumn{2}{|l|}{AND SAVE IT} \\
\hline 0776 & e494 b6 2d & & LDA & TMP2 & 3 & 76 & \multicolumn{2}{|l|}{RESTORE BYTE} \\
\hline 0777 & e496 bb 2a & & ADD & CHKSUM & 3 & 79 & \multicolumn{2}{|l|}{ACCUMULATE} \\
\hline 0778 & e498 b7 2a & & STA & CHKSUM & 4 & 83 & \multicolumn{2}{|l|}{IN CHECKSUM BYTE} \\
\hline 0779 & e49a ad bd & & BSR & INCHD & & 22 & \multicolumn{2}{|l|}{LS NIBBLE} \\
\hline 0780 & e49c ad 07 & & BSR & ASCII & 35 & 57 & \multicolumn{2}{|l|}{WHAT WAS IT} \\
\hline 0781 & e49e bb 2c & & ADD & TMP1 & 3 & 60 & \multicolumn{2}{|l|}{\multirow[t]{2}{*}{ADD TO MS NIBBLE SAVE BYTE}} \\
\hline 0782 & e4a0 b7 2d & & STA & TMP2 & 4 & 64 & & \\
\hline 0783 & e4a2 3a 2e & & DEC & BCNT & 5 & 69 & \multicolumn{2}{|l|}{\multirow[t]{2}{*}{DECREMENT BYTE COUNT}} \\
\hline 0784 & e4a4 81 & & \multicolumn{2}{|l|}{RTS} & 6 & 75 & & \\
\hline 0785 & & & & & & & & \\
\hline 0786 & e4a5 al 30 & \multirow[t]{6}{*}{ASCII} & CMP & *\$30 & 2 & & \multicolumn{2}{|l|}{BEFORE ZERO ?} \\
\hline 0787 & e4a7 25 d 1 & & BLO & ERR3 & 3 & 5 & \multicolumn{2}{|l|}{YES, NOT LEGAL} \\
\hline 0788 & e4a9 al 39 & & CMP & *\$39 & 2 & 7 & \multicolumn{2}{|l|}{AFTER NINE} \\
\hline 0789 & e4ab 2203 & & BHI & MT'y & 3 & 10 & \multicolumn{2}{|l|}{YES TRY A-F} \\
\hline 0790 & e4ad a0 30 & & SUB & \#\$30 & 3 & 13 & \multicolumn{2}{|l|}{\multirow[t]{2}{*}{0-9, CONVERT TO HEX}} \\
\hline 0791 & e4af 81 & & \multicolumn{2}{|l|}{RTS} & \(\epsilon\) & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{19}} \\
\hline 0792 & & & & & & & & \\
\hline 0793 & e4b0 al 41 & \multirow[t]{5}{*}{MTG} & CMP & \# 541 & 2 & 12 & \multicolumn{2}{|l|}{BEFORE A ?} \\
\hline 0794 & e4b2 25 ca & & BLO & ERR4 & 3 & 15 & \multicolumn{2}{|l|}{YES, NOT LEGAL} \\
\hline 0795 & e4b4 al 46 & & CMP & \#\$46 & 2 & 17 & \multicolumn{2}{|l|}{\multirow[t]{2}{*}{AFTER F ? YES, NOT LEGAL}} \\
\hline 0796 & e4bs 22 ca & & BHI & ERR5 & 3 & 20 & & \\
\hline 0797 & e4b8 ac 37 & & SUB & \#\$37 & 3 & 23 & \multicolumn{2}{|l|}{A-F, CONVERT TO HEX} \\
\hline 0798 & e4ba 81 & \multirow[t]{2}{*}{NFTND} & \multicolumn{2}{|l|}{RTS} & \multirow[t]{2}{*}{6} & \multicolumn{3}{|l|}{29} \\
\hline 0799 & & & & & & & & \\
\hline 0800 & e4bb ae 1d & \multirow[t]{2}{*}{DEL191} & \multirow[t]{2}{*}{LDX
BRA} & \multirow[t]{3}{*}{\begin{tabular}{l}
\#29 DELAY \\
\#16
\end{tabular}} & \multicolumn{2}{|l|}{2} & \multicolumn{2}{|l|}{} \\
\hline 0801 & e4bd 2002 & & & & 3 & \multicolumn{3}{|l|}{5} \\
\hline 0802 & e4bf ae 10 & \multirow[t]{3}{*}{\begin{tabular}{l}
DEL110 \\
DELAY
\end{tabular}} & LDX & & 2 & & & \\
\hline 0803 & e4c1 5a & & DECX & \multirow[t]{3}{*}{DELAY} & 3 & & & \\
\hline 0804 & e4c2 25 fd & & BNE & & 3 & \multicolumn{3}{|l|}{\(6 \times \mathrm{X}\)} \\
\hline 0805 & e4c4 81 & & \multirow[t]{3}{*}{KTS} & & \(\epsilon\) & \multicolumn{3}{|l|}{\multirow[t]{3}{*}{\(12+6 \mathrm{X}\) (INC BSE)}} \\
\hline 0806 & & & & & & & & \\
\hline 0807 & & & & & & & & \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|c|c|c|}
\hline 0808 & & \multicolumn{4}{|l|}{****************************************************} \\
\hline 0809 & & * & & & * \\
\hline 0810 & & * & RS232 & (9600 \& 4 MHz ) S & S-Record output. \\
\hline 0811 & & * & & & * \\
\hline 0812 & & \multicolumn{4}{|l|}{***************************************************} \\
\hline \multicolumn{6}{|l|}{0813} \\
\hline 0814 & e4c5 1406 & PUNCH & BSET & 2, PORTBD & BIT 2 OUTPUT \\
\hline 0815 & e4c7 cd e1 b3 & & JSR & BLDRNG & BUILD RANGE \\
\hline 0816 & e4ca 0820 a6 & & BRSET & 4, STAT, NINE & NEW ADDRESS ENTERED ? \\
\hline 0817 & e4cd be 27 & & LDX & TEMP & NO, SWAP ADDRESSES \\
\hline 0818 & e4cf b7 27 & & STA & TEMP & \\
\hline 0819 & e4d1 bf 22 & & STX & ADDRH & \\
\hline 0820 & e4d3 b6 23 & & LDA & ADDRL & \\
\hline 0821 & e4d5 be 28 & & LDX & TEMP+1 & \\
\hline 0822 & e4d7 bf 23 & & STX & ADDRL & \\
\hline 0823 & e4d9 b7 28 & & STA & TEMP + 1 & \\
\hline 0824 & e4db if 20 & & BCLR & 7, STAT & CLEAR END FLAG \\
\hline \multicolumn{6}{|l|}{0825} \\
\hline 0826 & e4dd b6 28 & LOOP1 & LDA & TEMP + 1 & END LSB \\
\hline 0827 & e4df bo 23 & & SUB & ADDRL & CURRENT LSB \\
\hline 0828 & e4e1 b7 26 & & STA & WORK6 & DIFFERENCE LSB \\
\hline 0829 & e4e3 b6 27 & & LDA & TEMP & END MSB \\
\hline 0830 & e4e5 b2 22 & & SBC & ADDRH & CURRENT MSB \\
\hline 0831 & e4e7 26 0d & & BNE & LOTS & MSB ZERO ? \\
\hline 0832 & e4e9 b6 26 & & LDA & WORK6 & YES, LOOK AT LSB \\
\hline 0833 & e4eb 4c & & INCA & & ADJUST \\
\hline 0834 & e4ec 2708 & & BEQ & LOTS & WAS \$FF ? \\
\hline 0835 & e4ee al 20 & & CMP & \# \$20 & MORE THAN 23 ? \\
\hline 0836 & e4f0 2204 & & BHI & LOTS & IF SO USE 23 \\
\hline 0837 & e4f2 1e 20 & & BSET & 7, STAT & NO, LAST S1 RECORD \\
\hline 0838 & e4f4 \(20 \quad 02\) & & BRA & LTE20 & LESS THAN OR EQUAL TO 20 \\
\hline \multicolumn{6}{|l|}{0839} \\
\hline 0840 & e4f6 a6 20 & LOTS & LDA & \#\$20 & \\
\hline 0841 & e4f8 ab 03 & LTE20 & ADD & \#\$03 & ADD BYTE COUNT \& ADDRESS \\
\hline 0842 & e4fa b7 2e & & STA & BCNT & No. BYTES THIS Si RECORD \\
\hline 0843 & e4fc a6 53 & & LDA & * 'S' & S \\
\hline 0844 & e4fe cd e5 63 & & JSR & OUCH & \\
\hline 0845 & e501 a6 31 & & LDA & *'1' & 1 \\
\hline 0846 & e503 ad 5 e & & BSR & OUCH & \\
\hline 0847 & e505 3f 2a & & CLR & CHKSUM & \\
\hline 0848 & e507 b6 2e & & LDA & BCNT & BYTE COUNT \\
\hline 0849 & e509 cd e5 8 f & & JSR & BYTEO & \\
\hline 0850 & e50c b6 22 & & LDA & ADDRH & ADDRESS HIGH \\
\hline 0851 & e50e cd e5 8f & & JSR & BYTEO & \\
\hline 0852 & e511 b6 23 & & LDA & ADDRL & \\
\hline 0853 & e513 ad 7a & & BSR & BYTEO & ADDRESS LOW \\
\hline \multicolumn{6}{|l|}{0854 ( 080} \\
\hline 0855 & e515 cd e7 46 & LOOP2 & JSR & LOAD & GET BYTE \\
\hline 0856 & e518 3c 23 & & INC & ADDRL & INCREMENT ADDRESS \\
\hline 0857 & e51a 2602 & & BNE & NOVR & OVERFLOW ? \\
\hline 0858 & e51c 3c 22 & & INC & ADDRH & YES, INC, HIGH BYTE \\
\hline 0859 & e51e ad 6 f & NOVR & BSR & BYTEO & SEND BYTE \\
\hline 0860 & e520 26 f3 & & BNE & LOOP2 & LAST BYTE ? \\
\hline \multicolumn{6}{|l|}{0861} \\
\hline \multicolumn{6}{|l|}{0862} \\
\hline 0863 & & \multicolumn{4}{|l|}{} \\
\hline 0864 & & * & & & * \\
\hline 0865 & & * & \multicolumn{2}{|l|}{Checksum byte.} & * \\
\hline 0866 & & * & & & * \\
\hline 0867 & & \multicolumn{4}{|l|}{****************************************************} \\
\hline \multicolumn{6}{|l|}{0868} \\
\hline 0869 & e522 b6 2a & & LDA & CHKSUM & CHECKSUM \\
\hline 0870 & e524 43 & & COMA & & REQUIRED CHECKSUM BYTE \\
\hline 0871 & e525 ad 68 & & BSR & BYTEO & SEND IT \\
\hline 0872 & e527 ad 34 & & BSR & CRLF & CRLF \\
\hline 0873 & e529 Of 20 b1 & & BRCLR & 7, STAT, LOOP1 & FINISHED ? \\
\hline 0874 & & & & & \\
\hline
\end{tabular}

\begin{tabular}{|c|c|}
\hline 0951 & \\
\hline 0952 & \\
\hline 0953 & \\
\hline 0954 & \\
\hline 0955 & \\
\hline 0956 & \\
\hline 0957 & e58f b7 2 c \\
\hline 0958 & e59144 \\
\hline 0959 & e592 44 \\
\hline 0960 & e593 44 \\
\hline 0961 & e59444 \\
\hline 0962 & e595 ad ef \\
\hline 0963 & e597 ad ca \\
\hline 0964 & e599 b6 2c \\
\hline 0965 & e59b bb 2a \\
\hline 0966 & e59d b7 2a \\
\hline 0967 & e59f b6 2c \\
\hline 0968 & e5al a 4 Of \\
\hline 0969 & e5a3 ad e1 \\
\hline 0970 & e5a5 ad bc \\
\hline 0971 & e5a7 3a 2e \\
\hline 0972 & e5a9 81 \\
\hline 0973 & \\
\hline 0974 & \\
\hline
\end{tabular}










\title{
LOW VOLTAGE INHIBIT (LVI) CAPABILITY OF THE M6805 HMOS MICROCOMPUTER (MCU) FAMILY
}

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}

\section*{INTRODUCTION}

The low voltage inhibit (LVI) option, as used with many of the M6805 HMOS Family Microcomputer (MCU) devices (EPROM MCUs excluded), provides a means for the MCU to sense a drop in supply voltage ( \(\mathrm{V}_{\mathrm{CC}}\) ) and then shut itself down in a well-defined manner. The LVI option may be used in applications which require the correct-output during normal operation and no-output during loss of power. The LVI option is also useful in fail-safe and/or fall-back operating modes for minimum systems operation.

An example of this no-output control scheme is in heightpositioning applications. With correct-output control signals from the MCU, the position of "cherry-picker" platforms could be controlled and maintained. With inadvertant loss of power due to power supply/battery deterioration and/or cable disconnects, the no-output signal would permit locking methods to be initiated within microseconds. This would allow the "cherry-picker" to maintain its "last position" (thus preventing disasterous falls for personnel or on-board equipment) or to start a predetermined (hydraulic selflocking or hydraulic bleed-off valves) controlled descent. This LVI capability of transition from correct-output to nooutput (i.e., high-Z, 3-state) without an intermediate uncontrolled region is defined in the On-Chip Operation paragraph.

Another example of this correct-output usefulness is in starter-controls of multi-horsepower electric motors. During normal power transitions, the controller signals will start up the motor at prescribed voltage and current versus time relationships, and maintain specified shaft RPM and shaft output power afterwards. At low power conditions (i.e., brownout), the electric current required to maintain this same motor-rpm and shaft output power increases proportional to the voltage decrease; e.g., a \(20 \%\) drop in powerline voltage causes an equivalent \(20 \%\) increase in motor current. This \(20 \%\) increase in motor current produces a \(44 \%\) increase in internal \(\mathrm{I}^{2} \mathrm{R}\) loss. The internal \(\mathrm{I}^{2} \mathrm{R}\) loss may cause the motor to overheat or even burn out. The M6805 HMOS

MCU can detect this "brownout" (low voltage) condition and immediately place the MCU output control lines (normally used to turn on the motor controller) in the highimpedance state. Bipolar driver devices with built-in pulldown resistors are usually used in these applications to turn themselves off when the control input is open-circuited. Restart can be then prohibited until normal power conditions return and the original current versus time relationships are reestablished, within the controller.

The LVI option is provided at the time of manufacture by on-chip circuitry, as a mask option, contained in part of the users ROM pattern. When the LVI option is provided, no additional external parts are required for normal operation. The LVI option will usually provide for an overall product cost reduction by eliminating the external components required to implement this feature off-chip.

\section*{ON-CHIP RESET/LVI OPERATION}

A simplified equivalent of the internal reset and LVI circuitry is shown in Figure 1. The circuit consists of three basic sections: (1) internal reset generator, (2) an internal Schmitt trigger which is externally activated, plus bias circuits, clamping diodes and current limiting, and (3) a low voltage detector with gating logic.

\section*{LVI DISABLED}

Without the LVI option (i.e., LVI disabled), the internal reset generator is only actuated by the external \(\overline{\text { RESET }}\) pin via the Schmitt trigger. In this case during power-on reset (POR), external capacitor \(\mathrm{C}_{\mathrm{R}}\) ( 0.1 to 1.0 microfarad) is charged through an on-chip resistor \(\left(R_{C}\right)\) and the current source from \(V_{C C}\). When the \(\overline{R E S E T}\) pin voltage rises to the Schmitt trigger positive threshold (VIRES + ), the on-chip reset generator allows the CPU to begin executing from ROM. The RC delay ( \(\mathrm{t}_{\mathrm{RHL}}\) ) allows the on-chip oscillator to stabilize prior to start of program execution. During normal power turn-off, the on-chip reset generator is actuated by the


FIGURE 1 - M6805 HMOS Family LVI Simplified Schematic Diagram

Schmitt trigger after the decreasing voltage on the \(\overline{\text { RESET }}\) pin falls to the negative threshold voltage ( \(\mathrm{V}_{\text {IRES }}-\) ). The individual M6805 HMOS Family data sheet and Figure 2 (of this application note) contain information concerning the reset and LVI timing waveforms, and \(\mathrm{V}_{\mathrm{CC}}\) voltage spectrum.

\section*{LVI ENABLED}

With the LVI mask option (i.e., LVI enabled), the poweron sequence is exactly the same as described above. However, in the power-down condition (resulting from normal power turn off, brownout, or voltage "dip"), the on-chip reset generator is triggered by the low voltage detector before power falls below the reset level. In this case (as shown in Figure 1), the second input to the reset generator OR gate becomes functional and the low voltage detect circuit causes a reset at a voltage point ( \(\mathrm{V}_{\mathrm{LVI}}\) ) prior to the \(\overline{\operatorname{RESET}}\) pin
reaching the Schmitt trigger VIRES - threshold. The only requirement is that \(V_{\text {LVI }}\) remains at its threshold for one \(t_{\text {cyc }}\) (minimum). In typical applications, the \(\mathrm{V}_{\mathrm{CC}}\) bus filter capacitor will eliminate negative-going voltage glitches of less than one \(t_{\text {cyc }}\). Once the \(V_{\text {LVI }}\) threshold is reached for one \(\mathrm{t}_{\text {cyc }}\), the low voltage detect circuit outputs a logic 1 which is gated to the on-chip reset generator, resetting the CPU within the next \(\mathrm{t}_{\text {cyc }}\) period.
Simultaneous to the activation of the on-chip reset generator, the low voltage detector turns on the internal \(R_{\text {on }}\) device. With the \(\mathrm{R}_{\text {on }}\) device turned on, the external reset capacitor discharges through internal current limiter \(R_{D}\) and continues until the RESET pin voltage falls below the minimum reset voltage, holding the CPU in reset. This condition remains until recovery of \(\mathrm{V}_{\mathrm{CC}}\), at which time normal poweron reset resumes.


FIGURE 2 - M6805 HMOS Family Reset/LVI Timing and
\(V_{\text {CC }}\) Voltage Spectrum Diagrams

\section*{LVI TESTING}

Figure 3 shows an LVI test circuit connection for the MC6805P4L1 (or P1). Similar connections for other M6805 HMOS Family MCUs could be made to corresponding pins for LVI testing. This circuit, together with the software in Figure 4, is used to determine the \(\mathrm{V}_{\mathrm{LVI}}\) and \(\mathrm{V}_{\mathrm{LVR}}\) for the MCU under test.
Figure 4 is the test pattern (TEST P) software routine to be entered into RAM in order to generate a continuous output square wave on the PB0 pin. By utilizing the on-chip monitor capability of the MC6805P4L1 demonstration program, the TEST P program can be loaded into on-chip RAM via an RS-232-C terminal. This connection is shown schematically in Figure 3. In typical lab applications, the 15 k pullup resistor is adequate to provide the required operating frequency. Alternatively, an adjustable resistor may be used to set the frequency at 3.58 MHz .
In order to activate the LVI state, the supply voltage ( \(\mathrm{V}_{\mathrm{CC}}\) ) must drop below \(\mathrm{V}_{\text {LVI }}\) and remain there for one \(\mathrm{t}_{\mathrm{cyc}}\) (internal clock period) plus 250 nanoseconds. The M6805 HMOS Family \(\mathrm{V}_{\mathrm{CC}}\) voltage spectrum is shown in Figure 2b. To determine the \(\mathrm{V}_{\text {LVI }}\) trip point, reduce the \(\mathrm{V}_{\mathrm{CC}}\) from the
normal value ( 5.25 Vdc ) to the point where the TEST \(P\) square wave disappears (i.e., PBO switches to high impedance). This is the \(\mathrm{V}_{\text {LVI }}\) value for this particular device. When \(\mathrm{V}_{\text {LVI }}\) is attained by reducing \(\mathrm{V}_{\mathrm{CC}}\), the three-state leakage current (ITSI) can then be measured to check that all I/O port pins are in the high-impedance state.
Increase \(\mathrm{V}_{\mathrm{CC}}\) in small increments ( \(10-100\) millivolt steps) and reinitiate the test pattern TEST P by keying the Execute address \(\$ 040\) into the RS-232-C terminal. This determines the \(\mathrm{V}_{\text {LVR }}\) value for the device being tested. (Note that the TEST P program will be retained in the on-chip RAM at the \(\mathrm{V}_{\text {LVI }}\) voltage level.)

\section*{TYPICAL APPLICATION}

A circuit that can be used to directly control a Darlington bipolar solenoid driver is shown in Figure 5. The MC6805P4L1 was chosen for the circuit because of its larger RAM area ( 112 bytes versus 64 bytes on other masked ROM devices). As shown in this figure, the port B (PB0) high current drive capability is used for this circuit. When the LVI capability is utilized, the solenoid immediately turns off with loss of power or brownout condition.

* If crystal option is used, delete 15 k resistor and connect crystal per data sheet.

FIGURE 3 - MC6805P4 LVI Test Circuit Schematic Diagram
\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 040 & & & & ORG & \$040 & \\
\hline 040 & A6 & FF & & LDA & \#\$FF & \\
\hline 042 & B7 & 05 & & STA & \$005 & Set Port B As Output \\
\hline 044 & 10 & 01 & TESTP & BSET & 0, PORT B & Set PB0 \\
\hline 046 & 11 & 01 & & BCLR & 0, PORT B & Clear PBO \\
\hline 048 & BC & 44 & & JMP & TEST P & Doit Again \\
\hline
\end{tabular}

FIGURE 4 - Test Pattern Routine (TEST P)


Software to control the solenoid (via port B, PBO) is shown in Figure 6. This software routine may be entered into onchin RAM via the RS-232-C terminal with the MC6805P4L1 in the monitor mode. The on-time of the solenoid (Allied Controls \#306X-32) is set by the value entered (by the RS-232-C terminal) in RAM location \$04F. The on/off times for this particular solenoid and software timing loops are shown below.
\[
\begin{aligned}
\$ 04 \mathrm{~F} & =04 ; 9.6 \mathrm{~ms} / 9.6 \mathrm{~ms} \\
& =0 \mathrm{~F} ; 36 \mathrm{~ms} / 36 \mathrm{~ms} \\
& =4 \mathrm{~F} ; 188 \mathrm{~ms} / 188 \mathrm{~ms} \\
& =\mathrm{FF} ; 620 \mathrm{~ms} / 620 \mathrm{~ms}
\end{aligned}
\]

The minimum on/off time of the solenoid shown in Figure 5 is 13 milliseconds. The 9.6 millisecond value (RAM \(\$ 04 \mathrm{~F}=04\) in Figure 6) only caused the solenoid to chatter; therefore, a higher hexadecimal value may be required in location \(\$ 04 \mathrm{~F}\).

\section*{MONITOR SOFTWARE}

A listing of the monitor (and self-check) program in the MC6805P4L1 (P1) is attached to this application note. This monitor program permits selection (via switch positions) of
four baud rates which allows the user to enter and execute small software programs directly from on-chip RAM, as is done in this application note.

\section*{PORT I/O CHARACTERISTICS WITH LVI OPTION}

The device operates successfully down to the \(\mathrm{V}_{\text {LVI }}\) threshold. During a lowering of \(V_{C C}\) voltage, due to a brownout condition of electrical power or other reason, the LVI option provides the user with reduced drive capability but a stable port configuration. A discussion of these characteristics is provided below.
The LVI threshold range may be between +2.7 V and +4.7 Vdc . The exact level could be determined as described above for the LVI Testing. Between the range of +4.7 Vdc and the actual \(\mathrm{V}_{\text {LVI }}\) voltage, each I/O port configuration remains as programmed. However, the drive capabilities (as a percentage of the specified port dc electrical characteristics) between the 4.7 Vdc and the actual \(\mathrm{V}_{\text {LVI }}\) voltage are as follows:
(1) I LOAD Sink - \(100 \%\) of specified current sinking capability for ports A and C, and \(50 \%\) of specified sinking capability for port B.
(2) ILOAD Source - \(0 \%\) of specified drive current. That is, do not depend upon the M6805 HMOS Family MCU to source current below the lower \(\mathrm{V}_{\mathrm{CC}}\) limit of +4.75 Vdc.
\begin{tabular}{|c|c|c|c|c|c|c|c|c|}
\hline 00001 & & & 0005 & A & DDRB & EQU & \$05 & \\
\hline 00002 & & & 0001 & A & PORT B & EQU & \$01 & \\
\hline 00003A & 0040 & & & & & ORG & \$040 & \\
\hline 00004A & 0040 & AG & FF & A & TEST01 & LDA & \#\$FF & \\
\hline 00005A & 0042 & B7 & 05 & A & & STA & DDRB & \\
\hline 00006A & 0044 & 10 & 01 & A & & BSET & O,PORT B & \\
\hline 00007A & 0046 & AD & 06 & 004E & & BSR & DELAY & \\
\hline 00008A & 0048 & 11 & 01 & A & & BCLR & 0,PORT B & \\
\hline 00009A & 004A & AD & 02 & 004E & & BSR & DELAY & \\
\hline 00010A & 004C & BC & 40 & A & & JMP & TEST01 & \\
\hline 00011A & 004E & AE & 04 & A & DELAY & LDX & \#\$04 & LOAD FROM RS-232 \\
\hline 00012A & 0050 & A6 & FF & A & DELAY1 & LDA & \#SFF & \\
\hline 00013A & 0052 & 4A & & & DELAY2 & DECA & & \\
\hline 00014A & 0053 & 26 & FD & 0052 & & BNE & DELAY2 & \\
\hline 00015A & 0055 & 5A & & & & DEX & & \\
\hline 00016A & 0056 & 26 & F8 & 0050 & & BNE & DELAY1 & \\
\hline 00017A & 0058 & 81 & & & & RTS & & \\
\hline 00018 & & & & & & END & & \\
\hline
\end{tabular}










\begin{tabular}{|c|c|c|c|}
\hline PAGE & 011 MONIT & . P4: 1 & \\
\hline 07A5 & 26 F9 & & BNE RAM3 \\
\hline 07A7 & 5C & & INCX ADVANCE TO NEXT RAM BYTE \\
\hline \multirow[t]{2}{*}{07A8} & 2A F5 & & BPL RAM2 CONTINUE TILL ALL TESTED \\
\hline & & * & EXIT WITH A \(=0, \mathrm{X}=\$ 80\) \\
\hline \multirow[t]{12}{*}{07AA} & 83 & * & SWI PASSED RAM TEST \\
\hline & & * & \\
\hline & & * & ROM TEST \\
\hline & & * & FORCE A RESULT OF \(\$ \mathrm{FF}\) ( 1 'S PARITY). THE CHECKSUM HAS BEEN \\
\hline & & * & CHOSEN TO FORCE THIS RESULT IF THE ROM ITSELF IS GOOD. \\
\hline & & * & ADDRESS AND DATA LINES STUCK HIGH, LOW OR TO EACH OTHER \\
\hline & & * & ARE DETECTED WITH HIGH PROBABILITY. \\
\hline & & * &  \\
\hline & & * & FOR A DISCUSSION OF THE RELIABILITY OF THIS METHOD OF TESTING THE ROM, SEE "MICROPROCESSOR BASED DESIGN" BY DR. \\
\hline & & * & J. B. PEATMAN, PAGES 315-316. \\
\hline & & * & \\
\hline & & * & ENTER WITH \(\mathrm{A}=\$ 00, \mathrm{X}=\$ 80\), RAM \(=00\) \\
\hline 07AB & & ROMTST & \\
\hline 07AB & BF 41 & & STX RAMSUB+2 \\
\hline 07AD & AE C8 & & LDX \#\$C8 =EOR EXTENDED \\
\hline 07AF & BF 3F & & STX RAMSUB \\
\hline 07B1 & AE 81 & & LDX \#\$81 =RTS \\
\hline 07B3 & BF 42 & & STX RAMSUB+3 \\
\hline 07B5 & BD 3F & SUM & JSR RAMSUB \\
\hline 07B7 & 3C 41 & & INC RAMSUB+2 ADVANCE TO NEXT ADDRESS \\
\hline 0789 & 22 FA & & BHI SUM \\
\hline 07 BB & 3 C 40 & & INC RAMSUB+1 \\
\hline 07BD & 0740 F5 & & BRCLR 3,RAMSUB+1, SUM LOOK FOR \$8 IN RAMSUB+1 \\
\hline 07C0 & 43 & & \begin{tabular}{l}
COMA \\
A SHOULD HAVE BEEN \$FF,
\end{tabular} \\
\hline 07C1 & 26 FE & * & BNE * HANG HERE FOR BAD ROM \\
\hline \multirow[t]{19}{*}{07C3} & 83 & & SWI PASSED ROM TEST \\
\hline & & * & INTERRUPTS TEST \\
\hline & & * & \\
\hline & & * & ENTER WITH: \(\mathrm{X}=\) \$81 \\
\hline & & * & \[
A=\$ 00
\] \\
\hline & & * & LOC=\$80 \\
\hline & & * & \\
\hline & & * & INTERRUPT TEST ALLOWS INTERRUPTS LONG ENOUGH TO GET ONE \\
\hline & & * & TIMER INTERRUPT AND ONE INT INTERRUPT. THE INTERRUPT \\
\hline & & * & SERVICE ROUTINES SHIFT A BYTE IN MEMORY TO A KNOWN PATTERN \\
\hline & & * & WHICH IS CHECKED AFTER THE INTERRUPTS SHOULD HAVE OCCURED. \\
\hline & & * & FURTHER, THE A AND X REGISTER ARE COMPARED WITH WHAT WAS \\
\hline & & * & STACKED DURING THE INTERRUPTS. \\
\hline & & * & A TIMER INTERRUPT IS GUARANTEED PENDING BY ALLOWING ENOUGH \\
\hline & & * & TIME TO ELAPSE DURING THE OTHER TESTS TO UNDERFLOW THE \\
\hline & & * & COUNTER (EVEN WITH MAXIMUM PRE-SCALE). THE INT INTERRUPT \\
\hline & & * & IS ALSO GUARANTEED SINCE THE INT LINE IS TIED TO THE PORTA \\
\hline & & * & LINE WHICH WIGGLES UP AND DOWN DURING THE I/O TEST. \\
\hline & & * & \\
\hline 07C4 & & INTTST & \\
\hline
\end{tabular}



\title{
USING THE M6805 FAMILY ON-CHIP 8-BIT A/D CONVERTER
}

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}

\section*{INTRODUCTION}

This application note covers some factors which should be considered when using on-chip analog-to-digital (A/D) converters. It is intended for the digital designer with little or no programming experience.

The task of converting analog signals into digital information is becoming easier using today's technology. The MC6805R3 and MC6805S2 microcomputer (MCUs) have an on-chip 8-bit A/D converter with four user channels to help accomplish this task. These versatile MCU devices are easy to use and serve well in automotive, industrial, medical or environmental systems where analog information is monitored, controlled, or stored.

The merging of analog and digital circuits does present a problem to the designer who is most familiar and comfortable using only one of the two disciplines. The problem arises when the analog designer needs to write a program to process the analog information or the digital designer has to contend with the analog hardware characteristics with which he is not totally familiar.

This application note defines the terminology used when discussing A/D converters, describes the circuit elements pertinent to the user, illustrates a self-test hardware/software technique, and gives an example on how to manipulate the converted analog data from a temperature sensor. Program listings are provided at the end of this application note.

\section*{DEFINITION OF TERMS}

For a better understanding of the characteristics of the M6805 Family 8 -bit A/D converter, the key terms used to describe the capabilities and limitations of an A/D converter, are presented first. Also included in this presentation is a brief interpretation of the specifications in the current MC6805R2 data sheet.

\section*{Conversion Range}

The voltage reference high ( \(\mathrm{V}_{\mathrm{RH}}\) ) and the voltage reference low ( \(\mathrm{V}_{\mathrm{RL}}\) ) pins establish the voltage range that is recognized by the converter. The sum of \(\mathrm{V}_{\mathrm{RH}}\) and \(\mathrm{V}_{\mathrm{RL}}\)
should never exceed the \(V_{C C}\) of the MCU. If \(V_{R H}-V_{R L}\) is below 4.000 volts, the specification accuracy can not be maintained. Operating below the minimum \(\mathrm{V}_{\mathrm{RH}}\) limit of 4,000 volts may cause the converter to miss steps or lose accuracy.

\section*{Conversion Time}

The A/D converter in an M6805 Family MCU is a successive approximation type. A hardware binary-search method is used to determine the unknown input voltage. This method significantly reduces the time (total of 30 machine cycles) needed to analyze the input voltage and generate a hexadecimal value accurately. An M6805 Family MCU with a full-speed, \(4-\mathrm{MHz}\) crystal has a 1 -microsecond machine cycle, and thus a 30 microsecond conversion time.

\section*{Monotonicity/Missing Codes}

Monotonicity is a function of the integral non-linearity of the converter. An A/D converter is monotonic if the output digital value always increases or remains the same when the analog input voltage is increasing. A non-monotonic \(\mathrm{A} / \mathrm{D}\) converter is one that skips steps or decreases in output digital value when the input is increasing.

\section*{Non-Linearity}

Studying the relationship of the analog input voltage with respect to the digital value that is derived after a conversion on an ideal A/D converter, yields a linear graph similar to the one shown in Figure 1. Integral non-linearity is defined as the deviation from an ideal straight-line, transfer function. Differential non-linearity is the amount that a particular step differs from one least significant bit (LSB). An ideal A/D converter has equal steps, and thus no differential nonlinearity. Total non-linearity error is then the sum of the differential and integral errors.

\section*{Quantizing Error}

The converter's inability to recognize voltage changes of less than one quantum step is referred to as the quantizing error. Since one increment or quantum is the smallest voltage


FIGURE 1 - Ideal A/D Conversion Points
value that the \(A / D\) converter recognizes, there is an inherent offset designed into the circuit. The M6805 Family A/D converter minimizes the impact of the offset error by centering it about the ideal conversion point.

Figure 1 shows the quantizing error to be \(\pm 0.5\) LSB. This offset enables the converter to detect input voltage changes \(\pm 0.5 \mathrm{LSB}\) from the center of a step. Thus, the first step occurs at 0.5 LSB and all subsequent steps occur at one LSB increments from this first 0.5 LSB step (that is, \(1.5 \mathrm{LSB}, 2.5\) LSB, etc.). Also, the last step (\$FE to \$FF) is 1.5 LSB long because of this shift in the transfer function.

\section*{Ratiometric Reading/Gain Error}

The gain error of the \(A / D\) comparator is the deviation from the ideal full scale input voltage and the full scale digital output value. The specification limit can be adjusted by trimming the \(V_{\text {RH }}\) reference voltage when the input voltage is at the transfer point between \$FE and \$FF ( 5.090 volts for a nominal \(\mathrm{V}_{\mathrm{RH}}=5.120\) volts system) and looking for an output value of \(\$ F F\).

\section*{Reference Voltage ( \(\mathbf{V R H}_{\mathbf{R}} / \mathbf{V}_{\mathbf{R L}}\) )}

The voltage reference high and voltage reference low pins provide the voltage limits to the digital-to-analog (D/A) converter resistor/capacitor chain in the \(A / D\) circuit. The nominal resistance value between these two pins is approx-
imately 6 kilohms. The reference voltage variation during a conversion should not exceed 0.25 LSB.

\section*{Resolution}

When referring to an analog voltage range, there are an infinite number of steps that can be realized. Since it is unrealistic to try and cover all the possible steps, a method of approximating the unknown value using a digital circuit was developed. If a data converter has 8 -bits, the 8 refers to the number of steps in powers of two. For example, an 8 -bit A/D converter has 256 steps ( \(2^{8}\) ).

The number of steps is used to determine the \(A / D\) resolution. Resolution is defined as the full scale input voltage divided by the total number of steps. This can be represented by the equation:
\[
\text { Resolution }=\left(\mathrm{V}_{\mathrm{RH}}-\mathrm{V}_{\mathrm{RL}}\right) / \text { Number of Steps }
\]

The \(\mathrm{V}_{\mathrm{RH}}\) (voltage reference high) is the highest voltage that can be converted, and \(\mathrm{V}_{\mathrm{RL}}\) (voltage reference low) is the low end of the conversion range.

This means that the converter recognizes input voltage changes no smaller than one incremental value. One increment can be expressed as a fraction of the full scale voltage or one least significant bit (LSB) of the N -bit digital word.

The 8-bit \(\mathrm{A} / \mathrm{D}\) converter implemented in an M6805 Family MCU uses a unipolar binary code. A value of \(\$ 00\) represents an analog input voltage of 0.000 to 0.020 volts and a value of
\$FF represents an analog input voltage of 5.100 to 5.120 volts, provided \(\mathrm{V}_{\mathrm{RH}}=5.120\) volts and \(\mathrm{V}_{\mathrm{RL}}=0.000\) volts. A dollar sign (\$) in front of a symbol identifies it in this document as a hexidecimal number (base 16 number).

\section*{Sample Time/Sample and Hold Capacitance}

The sample time of the M6805 Family A/D converter is the first five machine cycles. This is the actual aperature window during which the selected analog channel coupler connects the sample and hold capacitor to the input voltage. The internal sample and hold capacitor charges for five machine cycles, and then holds that charge on the comparator input during the remaining 25 cycles of the conversion period.

The analog input voltage ideally should stay constant during the sample period. Any variation contributes to the conversion error. It is desirable to hold the input voltage within 0.5 LSB variation during the sample window. Under extreme operating conditions, the first conversion obtained after selecting a new channel may be less accurate than later conversions of the channel. Input channel changes can affect the stored sample and charge.

The input voltage on the channel coupler should not exceed \(\mathrm{V}_{\mathrm{RH}}\) nor be less than \(\mathrm{V}_{\mathrm{RL}}\). A voltage greater than \(\mathrm{V}_{\mathrm{RH}}\) converts to \(\$ \mathrm{FF}\), but no overflow indication is provided. Since the maximum rate of change of the input signal is dependent upon the converter sample time, the maximum frequency of a sine wave input is: \(\mathrm{F}=1(\mathrm{TS} \times \mathrm{pi} \times 2(\mathrm{~N}+1)\) ) where TS is the sample time and N is the number of bits. With this equation, the slew rate of the signal does not exceed 0.5 LSB during a sample of the input voltage.

\section*{Zero Input Reading/Offset Error}

The input offset voltage of the A/D comparator causes a shift in its transfer function. The quantizing error inherent in the design of the converter causes the 0.5 LSB shift in the step function. Since a 0.5 LSB error is also allowed in linearity error, an input of 0.000 volts can convert to \(\$ 00\) or \(\$ 01\).

\section*{THE M6805 FAMILY A/D CONVERTER}

Figure 2 is a block diagram of the successive approximation A/D converter implemented in an M6805 Family MCU. There are two unique registers which are addressed under program control. They are used to select a channel, start a conversion, and read the 8 -bit result after a conversion has been completed.

There are four separate external input channels which can be individually coupled to the comparator input by writing to the three lower order bits in the A/D control register (ACR). There are also four internal input channels which are coupled to the \(\mathrm{V}_{\mathrm{RH}} / \mathrm{V}_{\mathrm{RL}}\) resistor chain and can be used as calibration references. Also shown in Figure 2 are the address locations for the external and internal channels.

The converter operates continuously producing a new result every 30 machine cycles. Bit 7 of the ACR flags the user when a conversion has been completed and the digital value of the analog input can be read from the A/D result register (ARR).

When the aperture window closes, the successive approximation register (SAR) addresses the D/A converter (DAC) with a binary word value of \(\$ 80\). Thus, only the most significant bit (MSB) of the word is set. This value causes the DAC to generate an analog voltage equal to the midway value of the conversion range.

At the comparator, the DAC output is compared with the input voltage stored in the sample and hold capacitor. The comparator then signals the SAR whether the DAC value is greater than the sampled value. If the sampled voltage is greater than the DAC voltage, the SAR binary value is increased to \$CO by setting the bit that is adjacent to the already set MSB. In turn, this increased value increases the DAC output voltage. If the input voltage is less than the DAC voltage, the SAR MSB is cleared and the bit adjacent to the MSB is set, resulting in less DAC voltage to the comparator. This binary-search method continues until all eight SAR bits have been determined.

At the end of the conversion, the SAR value is transferred to the A/D result register (ARR). This binary value is the approximate digital representation of the analog input within one LSB of error. A conversion complete flag is set in the ACR indicating to the user program that a new result may be retrieved.

The equivalent analog input circuit for one channel entering the multiplexer is illustrated in Figure 3. The worst case instantaneous current draw is at the beginning of the sample period. Since the RC time constant of the sample and hold circuit is approximately 500 nanoseconds, the five machinecycle sample time is more than sufficient to charge the sample and hold capacitor.

The average analog channel input current is less than one microampere. Thus, no additional buffering of external transducer signals is required. The analog channel input impedance should not be greater than 1 K ohms to prevent capacitor leakage currents from producing unwanted voltage drops.

\section*{A/D CONVERTER SELF-TEST}

Designing a test capability into a system simplifies maintenance, decreases the need for costly test equipment in the field, and provides an excellent way to learn the system characteristics. Using a minimum amount of hardware an M6805 Family MCU can test its own A/D converter in less than one second for 8 -bit accuracy. The objective of this example is to self-adjust the \(\mathrm{A} / \mathrm{D}\) converter under test for full scale error within two LSB and then to test for a correct conversion at the center of each step. The MCU used in this example is an MC68705R3.

The hardware schematic for the \(A / D\) converter self-test shown in Figure 4 consists of a voltage stimulus, a programmable voltage reference, and a program storage unit. A 12-bit resolution monolithic current output DAC (U2) presents the voltages to the MCU A/D converter input، An operational amplifier converts the DAC current output to a voltage and is fed into the device under test (DUT).

In order to download the test program to the MCU RAM, a 12-bit binary counter (U7) is used to address an EPROM (U3). Another 12 -bit counter (U1) addresses the DAC in order to ramp the test voltages to the DUT. The two 12 -bit counters are used to minimize the MCU pins needed for calibration in user systems. A variable-precision voltage reference (U5) and a quad analog switch (U6) are used to derive the voltage reference to the DUT.

\section*{BOOTSTRAP PROGRAM (BOOT)}

To minimize the amount of ROM occupied by the self-test program, a 28 -byte bootstrap loader routine is suggested. The bootstrap loader is a short program which is executed


FIGURE 2 - A/D Converter Block Diagram and Input Select Code


FIGURE 3 - Analog Channel Input Circuit


FIGURE 4 - On-Chip A/D Converter Self-Test
and Self-Calibration-Schematic Diagram
when a particular condition is met after the MCU comes out of reset. The bootstrap program loads a short test program from an external memory device into on-chip RAM and executes the program.

The condition selected in order to execute the bootstrap loader program is a logic low level on the interrupt pin when coming out of reset. When the interrupt pin has a logic high level, the user main program is entered. The address of the label "load" in the bootstrap program is used in the self-test program to jump back to load new routines. The bootstrap loader approach is not limited to the A/D converter self-test program. It can be used to examine or test other system features.

\section*{SELF-TEST SOFTWARE (A/DTST)}

The self-test software consists of three sequential loads. This requires the bootstrap loader to jump to RAM after downloading, execute a program from RAM, then return to the bootstrap loader to download the next routine. When the MCU comes out of reset, the interrupt pin is held low in order to enter the bootstrap loader routine.

The bootstrap program uses port B bit 1 to clear the counter and port B bit 0 to increment the count on a negative transition. The program is fed into port \(A\) and stored to RAM.

The index register is used as the RAM pointer and is tested for a negative value after each RAM byte load. Since the negative status bit in the condition code register is set when the accumulator holds a value between \(\$ 80\) and \(\$ F F\), the loading routine ends when the index register reaches a value of \(\$ 80\). The Figure 5 flow chart illustrates the interaction between the bootstrap loader routine (BOOT) and the A/D converter self-test routines (A/DTST).

\section*{12-Bit DAC Calibration}

The first routine is used to calibrate the 12 -bit DAC (U2) and the precision voltage reference (U5). The ideal \(\mathrm{V}_{\mathrm{RH}}\) level selected is 5.120 volts for 0.020 -volt steps. Therefore, the first step is to preset US with R5 to 5.160 volts (2 LSB above the ideal \(\mathrm{V}_{\mathrm{RH}}\) ) while the MCU is held in reset.

The next step is to calibrate the 12 -bit DAC zero output for 0.000 volts and the full scale output for 5.100 volts. This routine is executed only if port C bits 4 and 5 are held low. This is done by closing S1 (zero calibrate select) and S2 (full scale calibrate select) before bringing the MCU under test out of reset.

The 12-bit DAC zero offset adjustment is set by varying R6 while monitoring the DAC output for a value of 0.000 volts. Opening the bit 4 switch causes the DAC to be incremented to \$FF0 and held there for the full-scale error adjust provided the bit 5 switch is closed.

The DAC should then be calibrated to 5.100 volts by varying R15. Opening the bit 5 switch causes the calibration routine to terminate, and the second routine is then downloaded. The DAC calibration routine is normally done once after initial power-up and is skipped if the port C switches are open.

\section*{On-Line A/D Calibration}

The second routine in the self-test exercise is the A/D converter automatic full-scale error adjust. The DAC is incremented to \(\$\) FE8 ( 5.090 V ), which is the A/D converter switch point between \$FE and \$FF. All analog switches on U6 are off at this time so the voltage reference to the DUT is 5.160 volts ( \(\mathrm{V}_{\mathrm{RH}}\) ideal + 2 LSB). The A/D converter should
output a value of \$FE since the analog input switch point from \(\$ F E\) to \(\$ F F\) would be 5.140 volts using this reference value. Table 1 represents the voltage inputs that cause a switch in the digital output of the A/D converter when using a \(\mathrm{V}_{\mathrm{RH}}+\mathrm{V}_{\mathrm{RL}}\) of 5.120 V .

The analog switch is controlled by the four lower order bits of port C . As port C is incremented, it causes a decrease of 10 millivolts on the output of the voltage reference, US. An A/D conversion is done after each port \(C\) increment to check for a value of \$FF.

When the \(\mathrm{A} / \mathrm{D}\) converter recognizes the input voltage as an \(\$ F F\), port \(C\) is left constant at that value for the next test. This self-adjusting routine compensates for the variation of full-scale error from one device to another and eliminates having to manually adjust each unit before test.

\section*{A/D Linearity Test}

The third and last routine is the actual A/D converter voltage ramp test. The 12 -bit DAC is cleared then ramped in 20 -millivolt increments to check the center of each A/D step for a correct conversion. At the end of the 256 voltage steps, the program outputs a logic low level on the port B bit 2 to turn on an LED, indicating a good device.

If at any point during the 256 voltage steps a conversion is incorrect, testing is stopped and the program outputs a logic low on port \(B\) bit 3 to signal that the \(A / D\) converter failed the test. The A/D converter linearity is thus confirmed to be within one LSB ( 20 millivolts) of the proper reading.

\section*{TEMPERATURE SENSOR CONVERSION}

Monitoring temperature for display or control is a key factor for energy conservation or process control in closed loop systems. The objective in this portion of the application note is to demonstrate how to manipulate the converted analog signal from a temperature sensor for display.

By monitoring the base-emitter voltage variations on the Motorola MTS-102 silicon temperature sensor, the MCU converts that analog information into an equivalent digital value in degrees fahrenheit and displays it on three 7 -segment displays.

Many tasks can be performed after the conversion is complete. One typical application for this circuit is a ceiling fan control to increase room air flow for a period of time before turning on the main central air conditioning unit. If the temperature does not decrease after a timeout period, then the central air is turned on for a period of time.

The Figure 6 schematic shows how the sensor voltage is amplified to give 20 -millivolt steps per degree fahrenheit. A dual differential amplifier (U2) buffers the sensor voltage and then inverts and amplifies the signal before entering the A/D converter on the MCU. An amplifier gain of eight produces 10 millivolts per degree fahrenheit, and a gain of 4.444 produces 10 millivolts per degree centigrade.

In order for the A/D converter to recognize one degree steps, the gain must be doubled. The maximum output voltage on the differential amplifier is approximately 3.8 volts using a \(\mathrm{V}_{\mathrm{CC}}\) of 5 volts. Therefore, the temperature sensing range is from -40 degrees to +140 degrees fahrenheit.
The Monsanto LED displays have a common anode and are driven directly by the MCU port B. To update the displays, port \(C\) bits 0,1 and 2 enable each display sequentially every 2048 machine cycles. The regulated voltage from U 1 is tied to the MCU \(\mathrm{V}_{\mathrm{CC}}\) as well as to the displays and is used ratiometrically with respect to the \(\mathrm{V}_{\mathrm{RH}}\) pin and the


FIGURE 5 - Boot and A/D TST Program Flow Chart
(Sheet 1 of 2)


FIGURE 5 - Boot and A/D TST Program Flow Chart
(Sheet 2 of 2)


FIGURE 6 - Temperature Sensing A/D
Demonstration-Schematic Diagram
sensor supply. Thus, any variation on the amplifiers also occurs on the \(\mathrm{V}_{\mathrm{RH}}\) pin.
Since the MC68705R3 has an EPROM erasing window, it is necessary to cover it after programming so that the A/D converter will maintain its 8 -bit accuracy. It is also recommended that the MTS 102 sensor leads be moistured-sealed with epoxy. About 12 to 18 inches of twisted, stranded, 22 -gauge wire was used to connect the sensor to the amplifier input.
The Figure 7 flow chart describes the sequence of events in the temperature sensor program (TMPSNS). After port initialization, the timer is enabled to periodically update the 7 -segment displays. An A/D conversion is performed and the result is converted to binary-coded-decimal (BCD) format for the display routine.
Zero degrees fahrenheit is equal to a conversion of \(\$ 30\) so the \(\mathrm{A} / \mathrm{D}\) conversion result must be offset before converting to a BCD number. Since the displays are updated during a timer interrupt, the MCU goes into a wait loop before doing
another A/D conversion. This is a good entrypoint for appending new tasks to the basic program such as time of day or controlling a heater or air conditioner.
Calibration of the temperature sensor is performed by varying the 50 kilohms potentiometer (R1) on the differential amplifier for a reading of 32 degrees after a piece of ice has been placed on the sensor for approximatley one minute. Refer to the MTS-102 specification for further details.

\section*{SUMMARY}

The terminology used to describe an A/D converter characteristics has been discussed and related to the electrical characteristics in the M6805 Family A/D converter specifications. A circuit and program which tests the on-chip A/D converter was also discussed to familiarize the reader with a method of calibrating the \(A / D\) converter. A typical temperature sensor application was covered with the intent of showing the sequence of events that take place when converting the \(\mathrm{A} / \mathrm{D}\) result to a displayable value.
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|c|}
\hline Hi/Lo & 0 & 1 & 2 & 3 & 4 & 5 & 6 & 7 & 8 & 9 & A & B & C & D & E & F \\
\hline \({ }^{\circ}\) & 0.010 & 0.330 & 0.650 & 0.970 & 1.290 & 1.610 & 1.930 & 2.250 & 2.570 & 2.890 & 3.210 & 3.530 & 3.850 & 5.170 & 4.490 & 4.810 \\
\hline 1 & 0.030 & 0.350 & 0.670 & 0.990 & 1.310 & 1.630 & 1.950 & 2.270 & 2.590 & 2.910 & 3.230 & 3.550 & 3.870 & 4.190 & 4.510 & 4.830 \\
\hline 2 & 0.050 & 0.370 & 0.690 & 1.010 & 1.330 & 1.650 & 1.970 & 2.290 & 2.610 & 2.930 & 3.250 & 3.570 & 3.890 & 4.210 & 4.530 & 4.850 \\
\hline 3 & 0.070 & 0.390 & 0.710 & 1.030 & 1.350 & 1.670 & 1.990 & 2.310 & 2.630 & 2.950 & 3.270 & 3.590 & 3.910 & 4.230 & 4.550 & 4.870 \\
\hline 4 & 0.090 & 0.410 & 0.730 & 1.050 & 1.370 & 1.690 & 2.010 & 2.330 & 2.650 & 2.970 & 3.290 & 3.610 & 3.930 & 4.250 & 4.570 & 4.890 \\
\hline 5 & 0.110 & 0.430 & 0.750 & 1.070 & 1.390 & 1.710 & 2.030 & 2.350 & 2.670 & 2.990 & 3.310 & 3.630 & 3.950 & 4.270 & 4.590 & 4.910 \\
\hline 6 & 0.130 & 0.450 & 0.770 & 1.090 & 1.410 & 1.730 & 2.050 & 2.370 & 2.690 & 3.010 & 3.330 & 3.650 & 3.970 & 4.290 & 4.610 & 4.930 \\
\hline 7 & 0.150 & 0.470 & 0.790 & 1.110 & 1.430 & 1.750 & 2.070 & 2.390 & 2.710 & 3.030 & 3.350 & 3.670 & 3.990 & 4.310 & 4.630 & 4.950 \\
\hline 8 & 0.170 & 0.490 & 0.810 & 1.130 & 1.450 & 1.770 & 2.090 & 2.410 & 2.730 & 3.050 & 3.370 & 3.690 & 4.010 & 4.330 & 4.650 & 4.970 \\
\hline 9 & 0.190 & 0.510 & 0.830 & 1.150 & 1.470 & 1.790 & 2.110 & 2.430 & 2.750 & 3.070 & 3.390 & 3.710 & 4.030 & 4.350 & 4.670 & 4.990 \\
\hline A & 0.210 & 0.530 & 0.850 & 1.170 & 1.490 & 1.810 & 2.130 & 2.450 & 2.770 & 3.090 & 3.410 & 3.730 & 4.050 & 4.370 & 4.690 & 5.010 \\
\hline B & 0.230 & 0.550 & 0.870 & 1.190 & 1.510 & 1.830 & 2.150 & 2.470 & 2.790 & 3.110 & 3.430 & 3.750 & 4.070 & 4.390 & 4.710 & 5.030 \\
\hline C & 0.250 & 0.570 & 0.890 & 1.210 & 1.530 & 1.850 & 2.170 & 2.490 & 2.810 & 3.130 & 3.450 & 3.770 & 4.090 & 4.410 & 4.730 & 5.050 \\
\hline D & 0.270 & 0.590 & 0.910 & 1.230 & 1.550 & 1.870 & 2.190 & 2.510 & 2.830 & 3.150 & 3.470 & 3.790 & 4.110 & 4.430 & 4.750 & 5.070 \\
\hline E & 0.290 & 0.610 & 0.930 & 1.250 & 1.570 & 1.890 & 2.210 & 2.530 & 2.850 & 3.170 & 3.490 & 3.810 & 4.130 & 4.450 & 4.770 & 5.090 \\
\hline F & 0.310 & 0.630 & 0.950 & 1.270 & 1.590 & 1.910 & 2.230 & 2.550 & 2.870 & 3.190 & 3.510 & 3.830 & 4.150 & 4.470 & 4.790 & 5.110* \\
\hline
\end{tabular}

NOTES: (1) Voltages in the chart represent the switch point between steps. For example, 0.010 volts is the switch point between \(\$ 00\) and \(\$ 01\).
(2) Due to quantizing error, the center of each step is the chart value minus 10 millivolts. The last step does not overflow.
(3) The first step (*) equals 10 millivolts; the last step (*) equals 30 millivolts.


FIGURE 7 - Temperature Sensor (TEMPSNS) Program Flow Chart
(Sheet 1 of 2)


FIGURE 7 - Temperature Sensor (TEMPSNS) Program Flow Chart
(Sheet 2 of 2)

PAGE 001 BOOT .SA:1 BOOT



\begin{tabular}{|c|c|c|c|c|c|c|c|}
\hline PAGE & 003 & Slftst & . SA : 1 & A/DTS & & & \\
\hline \multicolumn{8}{|l|}{00086} \\
\hline 00087 & & & & \multicolumn{2}{|l|}{*****SEGMENT} & "\$3 A/D & TEST ROUTINE***** \\
\hline \multicolumn{8}{|l|}{00088} \\
\hline 00089A & 0080 & & & & ORG & \$80 & \\
\hline \multicolumn{8}{|l|}{00090} \\
\hline 00091 A & 0080 & AE 01 & A & & LDX & \#S01 & Initialize X-REG AS COUNTER \\
\hline 00092A & 0082 & 1 A 01 & A & & BSET & 5.PORTB & RESET DAC 12-BIT COUNTER \\
\hline 00093A & 0084 & 1 B 01 & A & & BCLR & 5, PORTB & \\
\hline 00094A & 0086 & 3F OE & A & & CLR & ACR & Clear conversion flag \\
\hline 00095A & 0088 & B6 OE & A & & LDA & ACR & \\
\hline 00096A & 008A & 2A FC & 0088 & & BPL & *-2 & WAIT FOR END OF CONVERSION \\
\hline 00097a & 008C & B3 0F & A & & CPX & ARR & \\
\hline 00098A & 008 E & Al 01 & A & & CMP & \#SO1 & TEST FOR zero input reading of \\
\hline 00099A & 0090 & 2514 & OOAC & & BLO & FAIL2 & 00 OR 01 AND STOP IF ARR-REG > X-REG \\
\hline 00100A & 0092 & A6 10 & A & LOOP2 & LDA & \#\$10 & INCREMENT DAC BY 16 STEPS \\
\hline 00101A & 0094 & 1901 & A & & BCLR & 4, PORTB & TO STAY IN CENTER OF 8-bit step \\
\hline 00102A & 0096 & 1801 & A & & BSET & 4, PORTB & \\
\hline 00103A & 0098 & 4 A & & & deca & & \\
\hline 00104A & 0099 & 26 F9 & 0094 & & bNE & *-5 & \\
\hline 00105A & 009B & 3F OE & A & & CLR & ACR & Clear conversion flag and \\
\hline 00106A & 009D & B6 OE & A & & LDA & ACR & WAIT FOR END OF CONVERSION \\
\hline 00107A & 009 F & 2A FC & 009D & & BPL & *-2 & \\
\hline 00108A & OOA1 & B3 OF & A & & CPX & ARR & TEST FOR CORRECT CONVERSION AND \\
\hline 00109A & 00A3 & 2607 & 00AC & & bNE & FAIL2 & Stop if arr-reg. Not Equal to x-reg. \\
\hline DOL10A & 00as & jc & & & INCX & & \\
\hline 00111A & 00a6 & 26 EA & 0092 & & bNE & LOOP2 & CONTINUE TESTING TILL X-REG. \(=00\) \\
\hline 00112A & 00A8 & 1501 & A & & BCLR & 2, PORTB & TURN LED ON FOR TEST PASS \\
\hline 00113A & OOAA & 20 FE & 00AA & & BRA & * & AND STOP \\
\hline 00114 A & OOAC & 1701 & A & fall2 & BCLR & 3, PORTB & TURN LED ON FOR TEST fail \\
\hline 00115 A & OOAE & 20 FE & OOAE & & BRA & * & AND STOP \\
\hline 00116 & & & & & End & & \\
\hline \multicolumn{8}{|l|}{TOTAL ERRORS 00000--00000} \\
\hline
\end{tabular}





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\title{
TELEPHONE DIALING TECHNIQUES USING THE MC6805
}

\author{
Prepared by \\ Robert Fischer \\ Downsview, Ontario, Canada
}

\section*{INTRODUCTION}

Telephones and associated ancillary equipment providing intelligent features are fast becoming commonplace. Often, it is necessary for the microprocessor providing the intelligence to also dial a telephone number.

The M6805 Family microcomputers (MCU), with their proven hardware/software versatility, are ideal candidates for such applications. Illustrated here are two cost-effective methods of telephone dialing. Hardware and software is given for both Dual Tone Multi-Frequence (DTMF) and rotary-pulse type dialing.

\section*{DEMONSTRATION BOARD DESCRIPTION}

Figure 1 shows the schematic of the demonstration board designed around a MC68705P3 single-chip MCU. This board is capable of pulse or DTMF dialing. The type of dialing is selected by switch S1. A 12-contact keyboard is used for input. While this is an extravagant use of \(\mathrm{I} / \mathrm{O}\), it is acceptable for the purposes of a demonstration board.

Pulse dialing requires a direct connection to the telephone line. Interface to the line is made by a 600 -ohm, \(1: 1\) line transformer and a relay that provides on/off hook capability. An indicator light (LED \#1) shows the current hook status.

After a power-on reset, the board is in an on-hook state (LED \#1 off). The pressing of any key will result in an offhook state without the digit being dialed. Subsequent key presses will result in the dialing of the corresponding digit. Pressing of the cancel button (S2) returns the board to the on-hook state.

The hardware and software to accomplish either form of dialing is readily applicable to any number of the M6805 Family.

\section*{ROTARY PULSE DIALING}

From both a hardware and software viewpoint, pulse dialing is by far the simplest form of dialing to implement.

Pulse dialing requires that the telephone line circuit receive a make/break sequence at a 10 -pulse-per-second (PPS) rate (see Figure 2). The dialing of the digit 3, for example, requires three make/break sequences. The 10-PPS rate requires the use of either a transistor or high speed relay for line looping. Note that if a low current reed relay is used, port \(B\) may be capable of driving the relay directly (eliminating the 2 N 3904 driver).

Subroutine PDIAL provides the proper timing sequences for pulse dialing. The routine is called with the digit to be dialed resident in the accumulator. Because the timing is not particularly critical, interrupts that can be quickly serviced are permissible.

\section*{DTMF DIALING}

Dual tone multi-frequency tone dialing is considerably more complex in terms of ROM usage and external hardware. The M6805 MCU is required to generate two simultaneous sine waves of different frequencies. Table 1 shows the key pad digit and the frequencies of the corresponding tone pairs. Note that the tones fall into two groups:
\begin{tabular}{ll} 
Group & \multicolumn{1}{c}{ Frequency (Hz) } \\
\hline Low Tones & 697, 770, 852, 941 \\
High Tones & \(1209,1336,1477,1633\)
\end{tabular}

TABLE 1 - Keypad Digit and Frequencies for Tone Pairs
\begin{tabular}{|c|c|cc|}
\hline Keypad Digit & DTONE Entry & \multicolumn{2}{|c|}{ Tone Pair (Hz) } \\
\hline 0 & \(\$ 0\) & 941 & 1336 \\
1 & \(\$ 1\) & 697 & 1209 \\
2 & \(\$ 2\) & 697 & 1336 \\
3 & \(\$ 3\) & 697 & 1477 \\
4 & \(\$ 4\) & 770 & 1209 \\
5 & \(\$ 5\) & 770 & 1336 \\
6 & \(\$ 6\) & 770 & 1477 \\
7 & \(\$ 7\) & 852 & 1209 \\
8 & \(\$ 8\) & 852 & 1336 \\
9 & \(\$ 9\) & 852 & 1477 \\
A & \(\$ A\) & 697 & 1633 \\
\(B\) & SB & 770 & 1633 \\
C & \(\$ C\) & 852 & 1633 \\
D & SD & 941 & 1633 \\
\(*\) & SE & 941 & 1209 \\
\(\#\) & SF & 941 & 1477 \\
\hline
\end{tabular}

Also note that if the seldom used keys A, B, C, and D are not required, it is not necessary to generate a \(1633-\mathrm{Hz}\) tone.

The method used to generate the tones uses a series-of 3-bit look-up tables. Consider a sine wave that has been sampled


FIGURE 1 - Demonstration Board Schematic
at a constant interval, starting at the positive peak (see Figure 3). Sampling is continued until the next positive peak is encountered. There is, of course, some quantization error associated with this next found peak. If this group of samples were to be continuously cycled, a frequency error would result.


FIGURE 2 - Timing for Rotary Pulse Dialing

To cure this, continue sampling until the next peak is encountered and determine if the resultant frequency error falls within acceptable limits. Figure 3 is actually the output of a program written in BASIC for the EXORciser. This listing is included at the end of this application note. This program is used to design the look-up table for incorporation into the M6805 program according to the error rates acceptable in the end equipment.

This program prompts the user for the sample interval and the frequency of the tone which is to be generated. Sampling of the tone is thus automated and after a peak is encountered, the cumulative frequency error is calculated and displayed along with the sample count. If the user is satisfied with the percentage error, a table of the samples is generated. If the error is still unacceptable, the program continues sampling until the next peak is encountered. Note that the samples have all been "dc shifted".

This program was used to generate the look-up tables for all the tones given in Table 1 with a criteria of \(1 \%\) maximum frequency error.

The subroutine DTONE actually operates on these tables to generate the DTMF tone pairs. The routine is entered with
the DTMF digit (see Table 1) is resident in the accumulator. Note that interrupts cannot be tolerated by this routine.

The first task of this routine is to convert the digit into the table start addresses for the high and low tones. This routine requires that the tables be resident in page 0 ROM to allow use of indexed addressing with 0 offset. The structure chosen for the tables puts the high group tones in the right nibble and the low group tones in the left nibble. Because the tables are all of different lengths, the table end is marked by an entry of \$F. In defiance of Murphy's Law, the DTMF tables fit exactly into page 0 ROM.

Generation of the tones involves cycling around a loop which plucks a 3-bit low tone sample and adds it to the 3-bit high tone sample. The 4 -bit sum is then output to a D/A converter. If the end of the table marker is encountered for either sample, the pointer must be reset to the table start. This loop also keeps track of the duration of the tone burst by counting loops in TIMEH and TIMEL.

Notice that every program path through the loop takes a constant time ( 122 microseconds). The actual sequence of program development was to first write the loop, determine the execution time, and then, with the sample interval defined, generate the tone tables.
The 4-bit D/A converter is economically implemented with standard \(5 \%\) resistors ( 60 kilohms \(=30\) kilohms +30 kilohms). Port B was used because of its slightly superior high output voltage drive. It is still necessary to supplement the high drive with pull-up resistors.

One unfortunate by-product of this tone generation technique is the production of subharmonics (and, of course, harmonics). This necessitates the use of an active bandpass filter. This filter consists of separate high pass and low pass sections. The filter response is shown in Figure 4.
The output level to the telephone line is adjusted with a 470-ohm resistor in series with the line transformer primary. This also provides the RX point, where received audio can be obtained for duplex communication.

Using the BASIC software at the end of this application note, the generation of custom tone groups is readily accomplished. Single tone generation is also possible by using the table entry TNOFF at the end of the given DTMF tables. This allows the muting of either the high or low group tones.


FIGURE 3 - Sine Wave Sampling


FIGURE 4 - Cumulative High-Pass, Low-Pass, and Line Transformer Response


20005
0000E
00007
2000s
00009
00010
00011
00012
02013

00015
0001E
000：7
0001EA 0784
0001940784
5F


20021
00022
ありにこ
\begin{tabular}{|c|c|c|c|c|c|c|c|}
\hline 82025 & & 0000 & A & PORTA & EQU & \(\$ 0\) & PORT A ： 1 O \\
\hline 00025 & & 920 & A & Par： & EQU & \＄ 2 & PORT E I／0 \\
\hline ロめめこ7 & & W6EC & F & PGRTC & \＃0i & \＄ & PORT C \(\because / 0\) \\
\hline \(0 \mathrm{0cze}\) & & 0064 & A & portad & E0U & \＄4 & PORT A DDR \\
\hline 20023 & & 0005 & A & PGR：BD & EQL & \＄5 & FCRT E DDR \\
\hline Ø00．50 & & 000E & A & วบPTED & E0U & あ & ORQ C EDF \\
\hline のロ0ら1 & & 0003 & A & TVizDAT & EDU & ¢ & TIMEA DATA REGISTER \\
\hline 62022 & & 0009 & A & TMRCOM & EQU & \＄ & THER CGTACG REGUS： \\
\hline 22034 & & & & ＊ & & & \\
\hline 00205 & & & & ＊ & RAM & aliocatyon & \\
\hline 0003E & & & & \％． & & & \\
\hline 0001374 & 0042 & & & & 0RG & \＄40 & \\
\hline ODOSEA & －2040 & 20001 & A & \(\cdots \mathrm{raj}\) & ave & － & GUE TME（rs） \\
\hline 2003s9 & 0041 & 900： & A & TMME & RME & ： & TONE TVE（LS） \\
\hline D0040A & 2042 & 000： & 9 & STAR＂－ & Rvie & \(\square\) &  \\
\hline － 60.64 & 204．3 & 0001 & A & START：－ & 7．以 B & \(\therefore\) & －0 TONE TABES START \\
\hline 20042A & 2044 & 0001 & A & Tonet： & RME & 1 & H：TONE CLRREN PGINTER \\
\hline 00043． & 0045 & 002： & A & TONEL & PMB & 1 &  \\
\hline 20044A & 0045 & 0001 & 9 & SERTCH： & Rrib & i & TEMPORARY SCRATC－1 \\
\hline D0045A & 0047 & Dear： & A & LSTKEY & pMe & ： & LAST LIALED DEGT：SED \\
\hline
\end{tabular}

```

FOGE DAS DEMD .GA:1 DEND - NCEETOSPS SOURCE -OR DIALER DENO

```
02094
02005
0209E
00097
00098
\(00: 00\)
00.01
00102
00.02
\(00: 04\)
\(00.05 F, 0132\) AE 70
DD: DEA D13 \(\quad 5 \mathrm{~A}\)
00i.07A 0.35 2E -
00: DSA 0. 274 A


\(001: 2\)
\(001: 3\)
\(201: 4\)
00115
001.5
00117
001.15
00119
20.20
2012.A D13E A4 DF
DE 22F 0.3 D 97
\(00.2 \mathrm{SA} 0: \mathrm{SE} 50\)

D0125A 0:42 E7 42
DOUSEA D1.44 E7 44
00127A D.4E DE R19E
20:296 0.495743
20129A 0.4B B745
ด2: 30
ne:

En: 4 A \(\angle=E 740\)
07. TSF R151 AE EC
20. SEA D:53 E7 41
00157
021.39
0ッ: 3
00.40
00.4:A Di5S SC 41
00.42 A 0.57 2E 0 0
DO1.4 OA 0.55 SC 40
D2. 44f Di5E 2E 0?
A0. 45
\(00.14 E\)
\(0014 \%\)


```

PAGE DOE DEMO .SA:Z DENO - VCESTOSPE SOURCE FOR ITRER DEVD
00.50
* \O KEY = RESSED.
002%1.
0W2E2
D02ESA 0. SG BE 47
OZZELA DIEE AI QA
00255` D18D 27 0D
DCZEE
*:F\#RS"-TVE
OCEEFA O:BF RE \thereforeO
DOZEER DICJ. CE DIC2
DZ2ESA DIC4 AD :D
DDC70F Q:CE, 2S ZE DICE
0271
00272A D1DS AE DA
0%\こA 2,CA B747
20274%: 01CC 90
20こ75% 01CD 01
0227E
0277
* GOT F NEY.
0<27%
0027
0ロこE0A ロ1CE B: 47
\triangle02E:A D1D@ 27 :A
00E2A D:D2 E7 4?
205%A 01D4 99
D2E4A 0:D5 E1

| A |  | －DF9 | －ST K \％ |
| :---: | :---: | :---: | :---: |
| A |  | Cw？ | \％ 1 |
| O1cc |  | 200 | KEYZ |
|  | ＊：F \％RS | $\cdots$ |  |
| A |  | 109 | ＋25 |
| A |  | JSP | WATTE |
| O：DE |  | Esf | C－ECく |
| OICE |  | BCS | EY．．． |
|  | ＊ST＂ | N］ |  |
| c |  | ：EFi | \＄ \＄$^{\text {a }}$ |
| A |  | STA | CSTKEY |
|  | SEY22 | CLC |  |
|  |  | R：S |  |

        *:
        * CHECK THAT IY IS FTOS- TMVE.
    *
    CEYI CMP -STKEY
D:CC
EE0 !EYこ2
STA LSTKEY
SEC
*
\thereforeO
A M, LDG HCE
O:DE ESP C-EC<
* STM-..N0 -\EY
_ST%:Y
*
KEYZ2
EY2% STA SSTKEY
NEv22 CLC
202EE
** cuacs
002CE5

* SCANS MEYEOARD = OF CLOEURE.
02200
025ee
00こe3 (
20290 *
00291
*: VAlUE IN fCC fAD CARZY SET.
* 

DD29こA D1DE 4F
CHECK ClRA
0023SA Q:D7 BE DO A
GDX PORTA GET MEYS
02234A Q:DS 5S
SEY:
DO235A DIDA 24 \7 DIFS
DOESEA OIDC 4C
02-3EA b,D- 4L
D297A 0.DL A1 0e A
002כEA ZiDF 2E FE DIDG
00299
7%5
202SE

```

FWE JQ17 DEAD ．SA：D DEMO－VCESTBSPS SDURCE FOR DMALER DEVD DOSLEA OT： 275
```

20%:8
02%.9
0eS20
00.32:
00.52=
00323F 0:=5 45
\#0.249 DIFE 2E D2
04325
DESEEA DIFE DE DA
D0こ%% a;FE E7 4E
00.25
023294 0.FC :502
ROZOA T1FE PS SD
00SEif R20R CD 0:32
003324 0203 14 02
00SCSA D205 AS 27
00SGSA D205 AS 27
00.S5A ロ20A SA 45
D2SSEA 020E 2E EE
005%7
20.3SA 220E AE CS
00こ39A 02:0 CC 0132
O:G ENE ODIAL:
DDAL STF BNE PDIRLI
A M IDA NE:
DA ※%\$A
A PDAL: 5%9 SEROCH SAVE
*: MAKE A PM_SE
A PDjA.2 BCLF 2, गORTC DK H00*
ESET 2,PORTC DSF HOOK
LDH m3S
*: w
*: ODEA!

* MGSE DIGLS -:E DNGYT GIVEN IN
* C-GMJE"0" OO \#\$\$A
*: ACE. FOLLOWED BY A 20G MSEC. WAIT.
+:
```



| 003454 | 0080 |  |  |  | QRG | \＄80 |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| DOSUEA | 0080 | 77 | A | TNES？ | ＝cs | \＄77 |
| $20.347 A$ | 0081 | 7E | A |  | FCE | \＄7E |
| 00.3489 | 0082 | 53 | A |  | FCE | \＄53 |
| 00.3494 | 0003 | 30 | 9 |  | FCB | ¢ 50 |
| 0 0 350 A | D0E4 | 21 | A |  | FCB | \＄21 |
| 00.551 A | D085 | 0］ | A |  | FCE | \＄0 |
| 06352A | Dace | DE | A |  | FCB | \＄0E |
| 2035： | D0es | 17 | A |  | FEB | क．7 |
| 00.3549 | Dines | 25 | A |  | FCE | \＄25 |
| 70．355A | 0889 | 42 | A |  | FCE | \＄く2 |
| $00 . S 5 E A$ | ロ0ea | E 0 | A |  | FCE | \＄ED |
| $00.357 A$ | 00eb | 71 | A |  | FCE | \＄7： |
| 200558A | ロロご | 74 | 9 |  | ＝ce | \＄74 |
| DロS59A | 006 D | ET | A |  | FCE | ¢も7 |
| DREEQA | D08E | 57 | A |  | FCE | \＄57 |
| DOSE：A | Q08： | 34 | A |  | ：CE | \＄．34 |
| D0SE2A | 0090 | 21 | A |  | FCE | \＄ |
| DDSESA | 0091 | 06 | A |  | FCB | \＄00 |
| 305644 | 0092 | 02 | 9 |  | FCE | \＄02 |
| 22S5EA | 0095 | 15 | A |  | FCB | \＄15 |
| D®SEEA | 0034 | 27 | a |  | FCE | \＄27 |
| 2DJETA | 0095 | 46 | A |  | FCE | \＄4E |
| 20.5634 | 0036 | E4 | A |  | －CB |  |
| 20．0．9A | 0097 | 7． | A |  | FCE | क7： |
| 20－729 | 009 | 70 | A |  | FCE | \＄70 |
| 20371A | 0099 | E2 | A |  | FCE | 中E2 |
| $02572 A$ | 0099 | 45 | A |  | FCE | \＄45 |
| D0373A | 0098 | 3 | A |  | FCB | \＄5 |
| DQ\％74A | 0095 | 17 | 9 | Tnizse | FCB | \＄17 |
| 203375A | ロu9 | 05 | 9 |  | FCE | \＄0．5 |
| DES7EA | 009 E | ロ2 | A |  | FCE | \＄02 |
| 20.3774 | D09：－ | 10 | A |  | FCE | \＄10 |
| D2378A | QEAD | 31 | A |  | FCB | \＄51 |
| $00.579 A$ | OEA1 | 55 | A |  | FCB | \＄55 |
| 003501 | $\triangle \triangle A Z$ | E 7 | A |  | FCE | \＄E7 |
| D0．3S1A | DDAS | Fe | A |  | FCE | 中FE |
| DRSE2A | DOA4 | 72 | A | TN770 | FCE | \＄72 |
| $20.353 A$ | DヌAS | EO | A |  | FCE | \＄ED |
| D0．334A | DRAE | 51 | A |  | FCE | \＄5． |
| －0．3ESA | DOA7 | 34 | A |  | FCB | 9.34 |
| 2038EA | DOAS | 17 | 9 |  | FCE | \＄17 |
| 202387A | DOA | RE | A |  | －CE | \＄0E |
| 003EEA | DDAA | 03 | A |  | FCB | \＄03 |
| Z003E9A | DOAB | 20 | A |  | FCB | \＄20 |
| 00．390A | DDAC | $4:$ | A |  | FCB | \＄4． |
| 20391A | COAD | 54 | A |  | FCB | \＄54 |
| 00.3924 | DEAE | 77 | A |  | FCB | \＄77 |
| DR3934 | DOAF | 76 | A |  | FCE | \＄7E |
| 00.394 A | ロロE』 | ES | A |  | FCE | \＄ES |
| 20．395A | 20B： | 40 | A |  | FCB | \＄40 |
| 20．395A | ロッ52 | 20 | A |  | FCE | \＄20 |




PRGE DII DEMO ．SA： 1 DENC－MCEETOSPS SOLREE FDR DIALER DEMO
 TO＂A＿ERRORS OODOD－－00000

```
0.89 ADDNUM 001.92 02:93%
Q:DE CHECK 002:37 DD2E9 00232*
01.5E CONT DO:.44:+00.52
0.1A DIAL DOCEE ODOTE*
0iz1 DOLEAL DQD7E 000E2*
0.3日 LTCNE 000es 00:2%*
0.O5 TEM," 00.99 00.3E+
01E4 GETLO 00:44 0015E*
AEL GE:VNO DOIED DOIET:
```



```
0.09 トEY: ロ@294:#029E
0.CE KEY:1 0025S 00270 00280%:
01CC KEY22 002ES 00274%002ES:
DIES LCYTM QODES 002S7:+
0047 L_STKEY 00045%002E% 0027% 00200 002E2
DIES NCARZY DQ:42 DO:51*
0.FS P0:A, 0003, 00323+
R1=A D.A-1 ODO24 00327+
```



```
200 PORT% 00025+00055 00295
0004 P0-7a5 0002E:
DNR- PORTE DODEE*ODRSE 002DE ODSOO DOSD2 DOSC4 DOSDE
\005 POFTED DD023+0005S
```



```
ODDE PORTCD OODSD%ODOE:
029 B-5E 02US2 DOEE9*
0.\E SCA. 200E5+0D0ES 00070 00078 000E4 00090 00092
004E SC, C-- 20044*00177 20204 00327 00S35
070 SH-& DO:ES OD:72+
0.00 START 00055%00482 00485 00434 00485
#04こ START-- DOQLD*00:25 00:9E
0043 ST&R: 0004 +0012E D01E7
0040 \becauseMUER D0020+001.34 00:43
004: Tursi 000SG+00ISE D0:41
0209 "M205v 200S2+
20EE "raDA" 000E+t
20E0 N, 2&E DE220 0022E 00252 DO24E 00475%
4QT NS SE 0021E 00222 0022E 002S4 00374**
#0.2 TN:477 00224 00230 00255 D024E 004:2*
#0D9 TN1ES 0023E 00240 02242 00244 004.35*
```

```
PGGE DIZ DEMD .SA:1 DENG - MCESTRSPS SOURCE FQR DIF.ER DENQ
0DE0 NE97 00221 0Z225 0-225 02259 00S4E+0U475
0Q&:4 TN770 00227 00229 00231 00241 に0382%:
00C5 TNS52 00233 00235 00237 00243 004:5%:
00ES TN94: 002.9 00245 00247 00249 00445%:
ODFE NOEF DD472*
DQ44 TONE-: D0042*0012E 001E4 00200
0045 TONEL D0042%00129 00:5E: 00180
0:55 OOVELP 00:4:+:002:3
2.95 \becauseTAE DE:24 00127 00215%:
0.54 NAOT: 0010E%00107
0.22 NA:TTSS 00105*00109 00:49 00こES 00Eこ: 00S54 00ES9
```

```
FAGE DOL TONCAL .SA:I
0.00 DINT T(100)
0101 H=3.
0102 P=122E-E
0.10 C=0
0120 W=P+1EE
0.2! PRINT "PERIOD = ";N;"USECS (Y/N)";
D2Z InPUT A$
0123 "F A$="Y" F-NEN OOTD : S0
0.24 IF A$ \"N" THEN GO'0 121
DIZS MNPUT "OEQEOD (USECES)=",?
OLE, P=P:12-E
0.SD PRINT "TONE FRED=";
0.40 INPL" =
2.50 }x=2+5.1.41595+F:
0.EQ [OR N=1. TO 100
D:70 T(N)=NNT(S.5*COS(N*X)+4)
0.7i GOSJE S000
0190 IF TCN`\7 7HEN GOTD 37D
O200 REV GOT A CREST- CAICULATE CUNULATIVE ERRDZ
0220 0:N%:
ZこO E=(C/F-D)*1DDO/O
0240 GOSUE 7000
Z2E0 PRINT "ERROR =";E:"%"
ØE70 PRINT "SAMDLE COUNT=",N
Q275 决\T "FREDUENCY =";F:"-z"
02\Xi0 PRINT "CONTINUE (Y/N)";
2230 SNPL' A$
3OOD IF Aक="Y" THEN GOTO S70
2E1区 IF A$\)"N" THEN GOTO 2ED
OS2D REN DONE- PRINT GAMPLE LIS'
0330 00548 9000
035 GOT0 ..0
OSTE NEXT v
Z\Omega0 PRIN" "SAVPLE COUNT ; \OO"
0.50 END
7000 REV P_OT SJEROUTINE
7001 כRINT CHRक(27):"口"
7022 FOR : = = TC =0
700S NEXT I
T205 PRINT
7OQE PRENT " :"
7010 F09 I = 1 70 e
702Q - = = i
70.30 PRINT L:":";
7040 REM वRINT TH2S -TNE
7050 FOR J=4 T0 N
7DE| IF \because(J)=L THEN GOTO 7090
707D 3QINT " ";
7080 60"0 7100
7090 PRINT "*:":
7%0 NEXT J
7110 PRNNT
7120 NEXT I
7:ZZ JRINT " ";
7.40 FOR I=: TO 70
7:50 PRENT ":";
71EO NEXT =
71ES W=P*1EE
```

```
PAGE DOZ TDNCAL .SA:I
7:70 PRIN" "ON:ZONTF_=";W;"USEE"
7:OQ PRINT
7:O0 PRINT
7200 RETURN
EQIDO REN CREST COUNT ROUTYN- ZDO< =OR A ZERO CROSSING
EDIQ T= T(N) \ THEN GOTE E040
ODZO F=O
EQSD RETURN
OQ40 IF H=D O-HE\ C=C+%
G050 h=1
EDEQ RET:JPN
GQDD REN PRENOER OUTPU GUBROUTNE
90:1 F[R J=1. TO 4
G0:2 دマN:NT 42
G0% NEXT I
G02D SQIN% 42
GOZQ PZINT &二," :"
9040 -0. I= T0 8
9050 L=E-T
92EO PRJN" #こ,_;":":
SR70 =0& }==1.T0 
9090 \becauseFT(T)=L \becauseHEN GOOO G%:0
GQG0 3QIN-" 杸,"";
9土00 60"0 0120
```



```
9120 NEXT =
```



```
3:40 NEXT ?
G:SR PRINT +2," ";
GIGQ FOR 首=: T0 70
日:70 PRENT ##,":";
G:ER NEXT !
#90 W=0*1EE
90. 5%G%7S=%
9:52 PRIN" 标2
```



```
G2.0 PRTNT *2
92こ0 PR#NT 42
9ご的 PRINT "Z,"FREQUENCY = "#F:" F-z"
G24D PRZNT 杸, "ERROR = ":E;" %"
3250 دRINT %2,"NO. SAMO_ES=":N
GZED PaNN #2,"ND. CYCLES = ";O
Эこ70 PRYNT WZ
G27- DIGITS= 6
9こg0 PqIN- +2
Э2G0 =ПR J=% TO N STES ב
```



```
GID B=J+!
```



```
GS| \RTNT S#," SANP:E ";B;" = ";"(B);
GZ4Q PRIN **
GS00 NEXT J
GEER ORJNT F, CHR&(12)
970 R=TU年
```


## MC68HC11 Floating-Point Package

## INTRODUCTION

The MC68HC11 is a very powerful and capable singlechip microcomputer. Its concise instruction set combined with six powerful addressing modes, true bit manipulation, 16 -bit arithmetic operations and a second 16 -bit index register make it ideal for control applications requiring both high-speed I/O and high-speed calculations.

While most applications can be implemented by using the 16 -bit integer precision of the MC68HC11, certain applications or algorithms may be difficult or impossible to implement without floating-point math. The goal in writing the MC68HC11 floating-point package was to provide a fast, flexible way to do floating-point math for just such applications.

The HC11 floating-point package (HC11FP) implements more than just the four basic math functions (add, subtract, multiply, and divide); it also provides routines to convert from ASCII to floating point and from floating point to ASCII. For those applications that require it, the three basic trig functions SINe, COSine, and TANgent are provided along with some trig utility functions for converting to and from both radians and degrees. The square root function is also included.

For those applications that can benefit by using both integer and floating-point operations, there are routines to convert to and from integer and floating-point format.

The entire floating-point package requires just a little over 2 k bytes of memory and only requires ten bytes of page-zero RAM in addition to stack RAM. All temporary variables needed by the floating-point routines, reside on the stack. This feature makes the routines completely reentrant as long as the ten bytes of page zero RAM are saved before using any of the routines. This will allow both interrupt routines and main line programs to use the floating-point package without interfering with one another.

## FLOATING-POINT FORMAT <br> FLOATING-POINT ACCUMULATOR FORMAT

The ten bytes of page-zero RAM are used for two software floating-point accumulators FPACC1 and FPACC2. Each five-byte accumulator consists of a one-byte exponent, a three-byte mantissa, and one byte that is used to indicate the mantissa sign.

The exponent byte is used to indicate the position of the binary point and is biased by decimal $128(\$ 80)$ to make floating-point comparisons easier. This one-byte exponent gives a dynamic range of about $1 \times 10 \pm 38$.

The mantissa consists of three bytes ( 24 bits) and is used to hold both the integer and fractional portion of the floating-point number. The mantissa is always assumed to be "normalized" (i.e., most-significant bit of the most-significant byte a one). A 24-bit mantissa will provide slightly more than seven decimal digits of precision.
A separate byte is used to indicate the sign of the mantissa rather than keeping it in twos complement form so that unsigned arithmetic operations may be used when manipulating the mantissa. A positive mantissa is indicated by this byte being equal to zero ( $\$ 00$ ). A negative mantissa is indicated by this byte being equal to minus one (\$FF).

$$
\begin{array}{llll}
\text { FPACC1 } & 82 \text { C90FDB 00 } & +3.1415927 \\
\text { FPACC2 } & 82 \text { C90FDB FF } & -3.1415927
\end{array}
$$

## MEMORY FORMAT

The way that floating-point numbers are stored in memory or the "memory format" of a floating-point number is slightly different than its floating-point accumulator format. In order to save memory, floating-point numbers are stored in memory in a format called "hidden bit normalized form".
In this format, the number is stored into four consecutive bytes with the exponent residing at the lowest address. The mantissa is stored in the next three consecutive bytes with the most-significant byte stored in the lowest address. Since the most-significant bit of the mantissa in a normalized floating-point number is always a one, this bit can be used to store the sign of the mantissa. This results in positive numbers having the most-significant bit of the mantissa cleared (zero) and negative numbers having their most-significant bit set (one). An example follows:

$$
\begin{array}{ll}
82 & \text { 490FDB }
\end{array} \quad+3.1415927
$$

There are four routines that can be used to save and load the floating-point accumulators and at the same time convert between the floating-point accumulator and memory format. These routines are discussed in detail in FLOATING-POINT ROUTINES.

## ERRORS

There are seven error conditions that may be returned by the HC11 floating-point package. When an error occurs, the condition is indicated to the calling program by setting the carry bit in the condition code register and returning an error code in the $\mathbf{A}$-accumulator. The error codes and their meanings are explained below.

| Error \# | Meaning |
| :---: | :--- |
| 1 | Format Error in ASCII to Floating-Point Con- <br> version |
| 2 | Floating-Point Overflow |
| 3 | Floating-Point Underflow |
| 4 | Division by Zero (0) |
| 5 | Floating-Point Number too Large or Small to <br> Convert to Integer |
| 6 | Square Root of a Negative Number |
| 7 | TAN of $\pi 2(90)$ |

NOTE
None of the routines check for valid floating-point numbers in either FPACC1 or FPACC2. Having illegal floating-point values in the floating-point accumulators will produce unpredictable results.

## FLOATING-POINT ROUTINES

The following paragraphs provide a description of each routine in the floating-point package. The information provided includes the subroutine name, operation performed, subroutine size, stack space required, other subroutines that are called, input, output, and possible error conditions.
The Stack Space required by the subroutine includes not only that required for the particular routines local variables, but also stack space that is used by any other subroutines that are called including return addresses. Note that the trig functions require a good deal of stack space.

Since some applications may not require all the routines provided in the floating-point package, the description of each routine includes the names of other subroutines that it calls. This makes it easy to determine exactly which subroutines are required for a particular function.

## ASCII-TO-FLOATING-POINT CONVERSION

Subroutine Name: ASCFLT
Operation:
Size:
Stack Space:
Calls:
Input:
Output:
Error Conditions:
Notes:
ASCFLT

14 Bytes

ASCII (X) FPACC1
352 Bytes (includes NUMERIC subroutine)
NUMERIC, FPNORM, FLTMUL, PSHFPAC2, PULFPAC2
$X$ register points to $A S C I I$ string to convert.
FPACC1 contains the floating-point number.
Floating-point format error may be returned.
This routine converts an ASCII floating-point number to the format required by all of the floating-point routines. Conversion stops either when a non-decimal character is encountered before the exponent or after one or two exponent digits have been converted. The input format is very flexible. Some examples are shown below.
20.095
0.125
$7.2984 \mathrm{E}+10$
167.824E5
005.9357E - 7

500

## FLOATING-POINT MULTIPLY

| Subroutine Name: | FLTMUL |
| :--- | :--- |
| Operation: | FPACC1 $\times$ FPACC2 |
| Size: FPACC1 |  |
| Stack Space: | 169 Bytes |
| Calls: | 10 Bytes |
| Input: | PSHFPAC2, PULFPAC2, CHCK0 |
| Output: | FPACC1 and FPACC2 contain the numbers to be multiplied. |
|  | FPACC1 contains the product of the two floating-point accumulators. FPACC2 remains |
| Error Conditions: | unchanged. <br> Overflow, Underflow. |

## FLOATING-POINT ADD

Subroutine Name: FLTADD
Operation: $\quad$ FPACC1 + FPACC2 1 FPACC1

Size:
Stack Space:
Calls:
Input:
Output:
Error Conditions:
Notes:

194 Bytes
6 Bytes
PSHFPAC2, PULFPAC2, CHCK0
FPACC1 and FPACC2 contain the numbers to be added.
FPACC1 contains the sum of the two numbers. FPACC2 remains unchanged.
Overflow, Underflow.
The floating-point add routine performs full signed addition. Both floating-point accumulators may have mantissas with the same or different sign.

FLOATING-POINT SUBTRACT
Subroutine Name: FLTSUB
Operation: FPACC1 - FPACC2 FPACC1
Size: $\quad 12$ Bytes
Stack Space: 8 Bytes
Calls: FLTADD
Input: $\quad$ FPACC1 and FPACC2 contain the numbers to be subtracted.
Output: $\quad$ FPACC1 contains the difference of the two numbers (FPACC1-FPACC2). FPACC2 remains unchanged.
Error Conditions: Overflow, Underflow,
Notes: Since FLTADD performs full signed addition, the floating-point subtract routine inverts the sign byte of FPACC2, calls FLTADD, and then changes the sign of FPACC2 back to what it was originally.

## FLOATING-POINT DIVIDE

Subroutine Name: FLTDIV
Operation: $\quad$ FPACC1 $\div$ FPACC2 FPACC1
Size: 209 Bytes
Stack Space: 11 Bytes
Calls: PSHFPAC2, PULFPAC2
Input: $\quad$ FPACC1 and FPACC2 contain the divisor and dividend respectively.
Output: FPACC1 contains the quotient. FPACC2 remains unchanged.
Error Conditions: Divide by zero, Overflow, Underflow

FLOATING-POINT-TO-ASCII CONVERSION

| Subroutine Name: | FLTASC |
| :---: | :---: |
| Operation: | 'FPACC1 (X) |
| Size: | 370 Bytes |
| Stack Space: | 28 Bytes |
| Calls: | FLTMUL, FLTCMP, PSHFPAC2, PULF!'AC2 |
| Input: | FPACC1 contains the number to be converted to an ASCll string. The index register X points to a 14 byte string buffer. |
| Output: | The buffer pointed to by the $X$ index register contains an ASCII string that represents the number in FPACC1. The string is terminated with a zero (0) byte and the $X$ register points to the start of the string. |
| Error Conditions: | None |

## FLOATING POINT COMPARE

| Subroutine Name: | FLTCMP |
| :--- | :--- |
| Operation: | FPACC1 - FPACC2 |
| Size: | 42 Bytes |
| Stack Space: | None |
| Calls: | None |
| Input: | FPACC1 and FPACC2 contain the numbers to be compared. |
| Output: | Condition codes are properly set so that all branch instructions may be used to alter program |
|  | flow. FPACC1 and FPACC2 remain unchanged. |
| Error Conditions: | None |

## UNSIGNED INTEGER TO FLOATING POINT

Subroutine Name: UINT2FLT
Operation: (16-bit unsigned integer) FPACC1
Size:
Stack Space: 6 Bytes
Calls: FPNORM, CHCKO
Input: $\quad$ The lower 16-bits of the FPACC1 mantissa contain an unsigned 16 -bit integer.
Output: $\quad$ FPACC1 contains the floating-point representation of the 16 -bit unsigned integer.
Error Conditions: None

## SIGNED INTEGER TO FLOATING POINT

Subroutine Name: SINT2FLT
Operation: (16-bit signed integer) FPACC1
Size: 24 Bytes
Stack Space: 7 Bytes
Calls: UINT2FLT
Input: $\quad$ The lower 16 -bits of the FPACC1 mantissa contain a signed 16 -bit integer.
Output: $\quad$ FPACC1 contains the floating-point representation of the 16 -bit signed integer.
Error Conditions: None

## FLOATING POINT TO INTEGER

| Subroutine Name: | FLT2INT |
| :--- | :--- |
| Operation: | FPACC1 (16-bit signed or unsigned integer) |
| Size: | 74 Bytes |
| Stack Space: | 2 Bytes |
| Calls: | CHCKO |
| Input: | FPACC1 may contain a floating-point number in the range $65535 \leqslant$ FPACC1 $\geqslant-32767$. |
| Output: | The lower 16-bits of the FPACC1 mantissa will contain a 16 -bit signed or unsigned number. |
| Error Conditions: | None |
| Notes: | If the floating-point number in FPACC1 is positive, it will be converted to an unsigned <br> integer. If the number is negative it will be converted to a signed twos complement integer. |
|  | This type of conversion will allow 16 -bit addresses to be represented as positive numbers <br> in floating-point format. Any fractional part of the floating-point number is discarded. |

## TRANSFER FPACC1 TO FPACC2

| Subroutine Name: | TFR1TO2 |
| :--- | :--- |
| Operation: | FPACC1 FPACC2 |
| Size: | 13 Bytes |
| Stack Space: | O Bytes |
| Calls: | None |
| Input: | FPACC1 contains a floating-point number. |
| Output: | FPACC2 contains the same number as FPACC1. |
| Error Conditions: | None |

## FLOATING-POINT FUNCTIONS

The following paragraphs describe the supplied float-ing-point functions, returned results. and possible error conditions. Note that even though the Taylor series which is used to calculate the trig functions requires that the input angle be expressed in radians; less precision is lost through angle reduction if the angle being reduced is expressed in degrees. Once the angle is reduced, the DEG2RAD subroutine is called to convert the angle to radians.

To reduce the number of factors in the Taylor expansion series all angles are reduced to fall between $0^{\circ}$ and $45^{\circ}$ by the ANGRED subroutine. This subroutine returns the reduced angle in FPACC1 along with the quad number that the original angle was in, and a flag that tells the calling routine whether it actually needs to calculate the sine or the cosine of the reduced angle to obtain the proper answer

## SQUARE ROOT

| Subroutine Name: | FLTSQR |
| :--- | :--- |
| Operation: | I'FPACC1 FPACC1 |
| Size: | 104 Bytes |
| Stack Space: | 21 Bytes |
| Calls: | TFR1TO2, FLTDIV, FLTADD, PSHFPAC2, PULFPAC2 |
| Input: | FPACC1 contains a valid floating-point number. |
| Output: | FPACC1 contains the square root of the original number. FPACC2 is unchanged. |
| Error Conditions: | NSQRTERR is returned if the number in FPACC1 is negative and FPACC1 remains un- <br> changed. |

## SINE

| Subroutine Name: | FLTSIN |
| :--- | :--- |
| Operation: | SIN (FPACC1) FPACC1 |
| Size: | 380 Bytes (Includes SINCOS subroutine) |
| Stack Space: | 50 Bytes |
| Calls: | ANGRED, SINCOS, DEG2RAD, PSHFPAC2, PULFPAC2 |
| Input: | FPACC1 contains an angle in radians in the range $-2 \pi \leqslant$ FPACC1 $\leqslant+2 \pi$. |
| Output: | FPACC1 contains the sine of FPACC1, and FPACC2 remains unchanged. |
| Error Conditions: | None |
| Notes: | The Taylor Expansion Series is used to calculate the sine of the angle between $0^{\circ}$ and $45^{\circ}$ |
|  | ( $\pi \div 4)$. The subroutine ANGRED is called to reduce the input angle to within this range. |
|  | Spot checks show a maximum error of $+1.5 \times 107$ throughout the input range. |

## COSINE

Subroutine Name: FLTCOS
Operation: COS(FPACC1) FPACC1
Size:
Stack Space:
Calls:
384 Bytes (Includes SINCOS subroutine)
50 Bytes
ANGRED, FLTSIN, DEG2RAD, PSHFPAC2
Input: $\quad$ FPACC1 contains an angle in radians in the range $-2 \pi \leqslant$ FPACC $1 \leqslant+2 \pi$.
Output:
Error Cenditions
FPACC1 contains the cosine of FPACC1, and FPACC2 remains unchanged.
None
Notes: $\quad$ The Taylor Expansion Series is used to calculate the cosine of the angle between $0^{\circ}$ and $45^{\circ}(\pi \div 4)$. The subroutine ANGRED is called to reduce the input angle to within this range. Spot checks show a maximum error of $+1.5 \times 10^{7}$ throughout the input range.

## TANGENT

Subroutine Name: FLTTAN
Operation: TAN (FPACC1) FPACC1
Size: $\quad 35$ Bytes (Also requires FLTSIN and FLTCOS)
Stack Space: $\quad 56$ Bytes
Calls: TFR1TO2, EXG1AND2, FLTSIN, FLTCOS, FLTDIV, PSHFPAC2, PULFPAC2
Input: $\quad$ FPACC1 contains an angle in radians in the range $-2 \pi \leqslant$ FPACC1 $\leqslant+2 \pi$.
Output: $\quad$ FPACC1 contains the tangent of the input angle, and FPACC2 remains unchanged.
Error Conditions: Returns largest legal number if tangent of $\pm \pi \div 2$ is attempted.
Notes: $\quad$ The tangent of the input angle is calculated by first obtaining the sine and cosine of the input angle and then using the following formula: TAN $=\mathrm{SIN} \div \operatorname{COS}$. At $89.9^{\circ}$ the tangent function is only accurate to 5 decimal digits. For angles greater than $89.9^{\circ}$ accuracy decreases rapidly.

## DEGREES TO RADIANS CONVERSION

| Subroutine Name: | DEG2RAD |
| :--- | :--- |
| Operation: | FPACC $1 \times \pi \div 180 \vee$ FPACC1 |
| Size: | 15 Bytes |
| Stack Space: | 16 Bytes |
| Calls: | GETFPAC2, FLTMUL |
| Input: | Any valid floating-point number representing an angle in degrees. |
| Output: | Input angles equivalent in radians. |
| Error Conditions: | None |

## RADIANS TO DEGREES CONVERSION

| Subroutine Name: | RAD2DEG |
| :--- | :--- |
| Operation: | FPACC $1 \times 180 \div \pi$ FPACC1 |
| Size: | 8 Bytes (Also requires DEG2RAD subroutine) |
| Stack Space: | 16 Bytes |
| Calls: | DEG2RAD |
| Input: | Any valid floating-point number representing an angle in radians. |
| Output: | Input angles equivalent in degrees. |
| Error Conditions: | Overflow, Underflow. |

PI

| Subroutine Name: | GETPI |
| :--- | :--- |
| Operation: | $\pi$ FPACC1 |
| Size: | 6 Bytes |
| Stack Space: | None |
| Input: | None |
| Output: | The value of $\pi$ is returned in FPACC1. |
| Error Conditions: | None |
| This routine should be used to obtain the value of $\pi$ | Th it is required in calculations since <br>  <br> it is accurate to the fuli 24 bits of the mantissa. |

## FORMAT CONVERSION ROUTINES

As discussed in FLOATIGNG-POINT ACCUMULATOR FORMAT and MEMORY FORMAT, the format for floatingpoint numbers as they appear in the floating-point accumulators is different than the way numbers are stored in memory. This was done primarily to save memory when a large number of floating-point variables are used in a program. Four routines are provided to convert to and from the different formats while at the same time moving a number into or out of the floating-point accumulators. By always using these routines to move num-
bers into and out of the floating-point accumulators, it would be extremely easy to adapt this floating-point package to work with any other floating-point format.

One example might be to interface this package with code produced by Motorola's 68 HC 11 ' C ' compiler. The Motorola ' $C$ ' compiler generates code for single-precision floating-point numbers whose internal format is that defined by the IEEE Standard for Binary Floating-Point Arithmetic. By rewriting the four routines described below the IEEE format could be easily converted to the format required by this floating-point package.

## Get FPACC( x )

```
Subroutine Name: GETFPAC1 and GETFPAC2
Operation: (X) FPACC1; (X) FPACC2
Size:
Stack Space:
Input:
Output:
Error Conditions:
22 Bytes each
None
The X index register points to the 'memory formatted' number to be moved into the floating-
point accumulator.
The number pointed to by X is in the specified floating-point accumulator.
None
```


## Put FPACC( $x$ )

Subroutine Name:
Operation:
Size:
Stack Space:
Input:
Output:
Error Conditions:
PUTFPAC1 and PUTFPAC2
FPACC1 (X); FPACC2 (X)
22 Bytes each.
None
The $X$ index register points to four consecutive memory locations where the number will be stored.

0001
0002
0003
0004
0005
0006
0007
0008
0009
0010
0011
0012
0013
0014
0015
0016
0017
0018
0019
0020
0021
0022
0023
0024
0025
0026
0027
00280000
0029
00300000
00310001
00320004
00330005 00340006 00350009
0036
0037
00380001
00390002
00400003
00410004
00420005
00430006
00440007
0045
0046




| 0178 | C07C 8128 |  | CMPA | \#'+ | NO. IS It A PLUS SIGN? |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 0179 | COTE 2705 |  | BEQ | ASCFLT16 | yes. just ignore it. |
| 0180 | C080 20 B7 |  | BRA | ASCFLTS | NO. FORMAT ERROR. |
| 0181 | C082 186300 | ASCFLT15 | COM | EXPSIGN, Y | flag a negative exponent. is it ist? |
| 0182 | C085 08 | ASCFLT16 | InX |  | point to next character. |
| 0183 | C086 Ab 00 |  | LDAA | $0, \mathrm{x}$ | get next character. |
| 0184 | C088 BD Cl 55 |  | JSR | NUMERIC | IS IT A number? |
| 0185 | C08B 24 AC |  | BCC | ASCFLTS | NO. Format error. |
| 0186 | CO80 8030 | ASCFLT9 | SUBA | \#530 | make it binary. |
| 0187 | C08F 18 A7 01 |  | STAA | PWR10EXP, Y | BUILD The power 10 EXPONENT. |
| 0188 | C092 08 |  | INX |  | POINT TO NEXT Character. |
| 0189 | C093 A6 00 |  | LDAA | $0, \mathrm{x}$ | GET IT. |
| 0190 | C095 BD C1 55 |  | JSR | NUMERIC | IS IT NUMERIC? |
| 0191 | C098 2413 |  | BCC | ASCFLT14 | NO. GO FINISH UP THE CONVERSION. |
| 0192 | C09A 18 E6 01 |  | LDAB | PWR10EXP, Y | YES. GET PREVIOUS DIGIT. |
| 0193 | CO9D 58 |  | LSLB |  | MULT. BY 2. |
| 0194 | CO9E 58 |  | LSLB |  | NOW BY 4. |
| 0195 | CO9F 18 EB 01 |  | ADDB | PUR10EXP, Y | BY 5. |
| 0196 | COA2 58 |  | L.SLB |  | BY 10. |
| 0197 | COA3 8030 |  | SUBA | \#\$30 | Make second digit binary. |
| 0198 | COAS 1B |  | ABA |  | ADD It TO FIRST DIGIT. |
| 0199 | COA6 18 A7 01 |  | StAA | PWR 10EXP, Y |  |
| 0200 | COA9 8126 |  | CMPA | \#38 | IS the exponent out of range? |
| 0201 | COAB 228 C |  | BHI | ASCFLTS | YES. REPORT ERROR. |
| 0202 | COAD 18 A6 01 | ASCFLT14 | LDAA | PWR 10EXP, Y | GET POWER 10 EXPONENT. |
| 0203 | COBO 186000 |  | TST | EXPSIGN,Y | WAS IT NEGATIVE? |
| 0204 | COB3 2A 01 |  | BPL | ASCFLT12 | NO. GO ADD It TO BUILT 10 PWR EXPONENT. |
| 0205 | COBS 40 |  | NEGA |  |  |
| 0206 | COB6 98 00 | ASCFLT12 | ADDA | fPaCCiex | final total pur 10 EXPONENT. |
| 0207 | COB8 9700 |  | STAA | fPACCIEX | Save result. |
| 0208 | COBA 20 5B |  | BRA | FINISH | GO FINISH UP CONVERSION. |
| 0209 |  | * |  |  |  |
| 0210 |  | * | PRE-DE | CIMAL POINT N | NON-DIGIT FOUND, IS IT A decimal point? |
| 0211 |  | * |  |  |  |
| 0212 | COBC 812 E | ASCFLT10 | CMPA | \#'. | IS It a decimal point? |
| 0213 | COBE 26 A9 |  | BNE | ASCFlit | NO. GO CHECK FOR THE EXPONENT. |
| 0214 | COCO 08 |  | INX |  | yes. point to next character. |
| 0215 |  | * |  |  |  |
| 0216 |  | * | POST | ECIMAL POINT | Processing |
| 0217 |  | * |  |  |  |
| 0218 | cocl ab 00 | ASCFLTI1 | ldaa | $0, x$ | get next character. |
| 0219 | COC3 BD C1 55 |  | JSR | NUMERIC | IS IT NUMERIC? |
| 0220 | COC6 24 A1 |  | BCC | ASCflti 7 | NO. GO CHECK FOR EXPONENT. |
| 0221 | COC8 80 08 |  | BSR | ADDNXTD | YES. ADD In the digit. |
| 0222 | COCA 08 |  | INX |  | POINT TO THE NEXT CHARACTER. |
| 0223 | COCB 2592 |  | BCS | ASCFLT8 | If OVER FLOW, flush remaining digits. |
| 0224 | COCD 7A 0000 |  | DEC | fPACCIEX | ADJUST THE 10 POWER EXPONENT. |
| 0225 | CODO 20 EF |  | BRA | ASCFLT11 | PROCESS ALL FRACTIONAL DIGITS. |
| 0226 |  | * |  |  |  |
| 0227 |  | * |  |  |  |
| 0228 |  | * |  |  |  |
| 0229 | C002 9601 | ADDNXTD | LDAA | FPACCIM | GET UPPER 8 BITS. |
| 0230 | COD4 9706 |  | StAA | FPACC2MN | COPY INTO FPAC2. |
| 0231 | C006 DC 02 |  | LDD | FPACC 1 MN +1 | GET LOWER 16 BITS OF MANTISSA. |
| 0232 | C008 D0 07 |  | STD | FPACC2MN+1 | COPY INTO FPACC2. |
| 0233 | CODA 05 |  | LSLD |  | MULT. BY 2. |
| 0234 | CODB 790001 |  | ROL | fPACCIMN | OVERFLOW? |
| 0235 | CODE 252 E |  | BCS | ADDNXTDI | YES. DON'T ADD the digit in. |
| 0236 | COEO 05 |  | LSLD |  | MULT $8 Y 4$. |
| 0237 | COE1 790001 |  | ROL | fPACCIMN | OVERFLOW? |
| 0238 | COE4 2528 |  | BCS | ADONXTD1 | yes. Don't ado the digit in. |
| 0239 | COE6 0307 |  | ADOD | FPACC2MN+1 | BY 5. |
| 0240 | COE8 36 |  | PSHA |  | SAVE A. |
| 0241 | COE9 9601 |  | LDAA | FPACCIMN | GET UPPER 8 BITS. |
| 0242 | Coeb 8900 |  | ADCA | \# | ADDIN POSSABLE CARRY FROM LOWER 16 BItS. |
| 0243 | COED 9B 06 |  | ADDA | FPACC2MN | ADD IN UPPER 8 BITS. |



| 0310 | C15F OC | NUMERIC1 | CLC |  | now-numeric character. clear the carry. |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 0311 | C160 39 |  | RTS |  | RETURN. |
| 0312 |  | * |  |  |  |
| 0313 | C161 | FPNORM | EQU | * |  |
| 0314 | C161 CE 0000 |  | LOX | *FPACCIEX | POINT TO FPACC1. |
| 0315 | C164 80 1A |  | BSR | CHCKO | CHECK TO SEE If It's 0. |
| 0316 | C166 2714 |  | BEQ | FPNORM3 | YES. JUST RETURN. |
| 0317 | C168 700001 |  | TST | FPACC 1 Mn | IS THE NUMBER ALREADY NORMALIZED? |
| 0318 | C168 2B OF |  | BMI | FPNORM3 | YES. JUST RETURN.. |
| 0319 | C160 DC 02 | FPNORM1 | LDD | FPACC1MN+1 | GET The lower 16 bits of the mantissa. |
| 0320 | C16F 7a 0000 | FPNORM2 | DEC | fPACCIEX | DECREMENT THE EXPONENT FOR EACH SHIFT. |
| 0321 | C172 27 OA |  | BEQ | FPNORM4 | EXPONENT WENT TO O. UNDERFLOW. |
| 0322 | C174 05 |  | LSLD |  | Shift the lower 16 Bits. |
| 0323 | C175 790001 |  | ROL | FPACCIMN | ROTATE THE UPPER 8 BITS. NUMBER NORMALIZED? |
| 0324 | C178 2A F5 |  | BPL | FPNORM2 | no. keep shifting to the left. |
| 0325 | C17A DD 02 |  | STD | FPACC1MN+1 | PUT ThE LOWER 16 BITS BACK INTO FPACC1. |
| 0326 | C17C OC | FPNORM3 | CLC |  | SHOW NO ERRORS. |
| 0327 | C170 39 |  | RTS |  | YES. RETURN. |
| 0328 | C17E 00 | FPNORM4 | SEC |  | flag error. |
| 0329 | C17F 39 |  | RTS |  | RETURN. |
| 0330 |  | * |  |  |  |
| 0331 | C180 | CHCKO | EQU | * | Checks for zero in fpacc pointed to by x. |
| 0332 | C180 37 |  | PSHB |  | Save 0. |
| 0333 | C181 36 |  | PSHA |  |  |
| 0334 | C182 EC 00 |  | LDD | 0, x | GET fPACC EXPONENT \& HIGH 8 bits. |
| 0335 | C184 2602 |  | BNE | CHCK01 | NOT ZERO. RETURN. |
| 0336 | C186 EC 02 |  | LDD | 2, X | CHECK LOWER 16 Bits. |
| 0337 | C188 32 | CHCKO1 | PULA |  | RESTORE $\mathbf{D}$. |
| 0338 | C189 33 |  | PULB |  |  |
| 0339 | C18A 39 |  | RTS |  | RETURN WITH CC SET. |
| 0340 |  | * |  |  |  |
| 0341 | C18B 70 4C CC CD | CONSTP1 | FCB | \$70, \$4C, \$CC, | SCD 0.1 DECIMAL |
| 0342 | C18F 84200000 | CONST10 | FCB | \$84, \$20, \$00, | 00010.0 DECIMAL |
| 0343 |  | * |  |  |  |
| 0344 |  |  |  |  |  |



| 0410 | C1F2 A | A7 01 |  | StAA | $1, \mathrm{x}$ | SAVE to partial proouct. |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0411 | C1F4 6 | 6601 | Umulte | ROR | 1, $x$ | rotate partial proouct to the right. |
| 0412 | C1F6 6 | 6602 |  | ROR | 2, x |  |
| 0413 | C1F8 6 | 6603 |  | ROR | 3, X |  |
| 0414 | C1FA 76 | 760006 |  | ROR | FPACC2MN | Shift the multiplier to the right 1 bit. |
| 0415 | C1FD 76 | 760007 |  | ROR | FPACC2MN+1 |  |
| 0416 | C200 76 | 760008 |  | ROR | FPACC2MN+2 |  |
| 0417 | C203 6 | 6A 00 |  | DEC | $0, \mathrm{X}$ | DONE YEI? |
| 0418 | C205 26 | 26 DC |  | bNE | UMULTI | NO. KEEP GOING. |
| 0419 | C207 6 | 6001 |  | TST | 1, x | does partial proouct need to be normalized? |
| 0420 | C209 2 | $280 C$ |  | BMI | UMULT3 | NO. GET ANSUER \& RETURN. |
| 0421 | C208 | 780006 |  | LSL | FPACC2MN | GEt bit that was shifted out of p.p register. |
| 0422 | C2OE 6 | 6903 |  | ROL | 3, X | PUT It back into the partial proouct. |
| 0423 | C210 | 6902 |  | ROL | 2, x |  |
| 0424 | C212 | 6901 |  | ROL | 1, x |  |
| 0425 | C214 | 74 0000 |  | DEC | fpacciex | FIX EXPONENT. |
| 0426 | C217 | 700006 | umults | TST | fPACC2MN | DO WE NEED TO ROUND the partial proouct? |
| 0427 | C21A | 2A 18 |  | BPL | UMULT4 | NO. JUST RETURN. |
| 0428 | C21. | EC 02 |  | LDD | 2, x | yes. get the least signifigant 16 bits. |
| 0429 | C21E | C3 0001 |  | ADDD | \#1 | ADD 1. |
| 0430 | C221 | ED 02 |  | STD | 2, x | save result. |
| 0431 | C223 | A6 01 |  | LDAA | 1,x | Propigate through. |
| 0432 | C225 | 8900 |  | ADCA | \#0 |  |
| 0433 | C227 | A7 01 |  | STAA | 1, x |  |
| 0434 | C229 | 2409 |  | BCC | UMULT4 | If CARry clear all is ok. |
| 0435 | C22B 6 | 6601 |  | ROR | 1, X | If NOT OVERFLOW. ROTATE CARry into p.p. |
| 0436 | C22D 66 | 6602 |  | ROR | $2, \mathrm{x}$ |  |
| 0437 | c22F 6 | 6603 |  | ROR | 3, x |  |
| 0438 | C231 | 7c 0000 |  | INC | fPACCIEX | UP The EXPONENT. |
| 0439 | C234 | 31 | UMULT 4 | INS |  | take counter off stack. |
| 0440 | C235 | 38 |  | PULX |  | GEt M.S. 16 bits of partial product. |
| 0441 | C236 | DF 01 |  | six | FPACC 1 M | PUT IT IN FPACC1. |
| 0442 | C238 | 32 |  | pula |  | GET L.S. 8 bItS Of PARTIAL PRODUCT. |
| 0443 | C239 | 9703 |  | STAA | FPACC 1 MN +2 | PUT It In fPacci. |
| 0444 | C238 | 39 |  | RTS |  | RETURN. |
| 0445 |  |  | * |  |  |  |
| 0446 |  |  | * |  |  |  |
| 0447 |  |  | * |  |  |  |



| 0513 | C2AO | DE 08 |  | LOX | FPACC2MN+2 | GET LOWER 8 BITS \& SIGN OF FPACC2. |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0514 | C2A2 | 3C |  | PSHX |  | save It. |
| 0515 | C2A3 | DE 03 |  | LOX | FPACCTMN +2 | GET LOWER 8 BITS \& SIGN OF FPACC1. |
| 0516 | C2A5 | DF 08 |  | STX | FPACC2MN+2 | PUT IT IN FPACC2. |
| 0517 | C2A7 | 38 |  | PULX |  | GEt SAVED PART OF fPaccl |
| 0518 | C2A8 | DF 03 |  | six | FPACC1Mn+2 | PUT IT IN FPACCI. |
| 0519 | c2aA | DC 02 | fltadd 8 | LDD | FPACC1MN+1 | GET LOWER 16 Bits of fPacci. |
| 0520 | c2ac | 9307 |  | SUBD | FPACC2MN+1 | SUBTRACT LOVER 16 BItS OF FPACC2. |
| 0521 | caae | D0 02 |  | STO | FPACC1MN+1 | SAVE RESULT. |
| 0522 | C280 | 9601 |  | LDAA | fPACC1Mn | get high 8 bits of fpacci mantissa. |
| 0523 | C2B2 | 9206 |  | SBCA | FPACCZMN | SUBTRACT HIGH 8 BITS OF fPACC2. |
| 0524 | C284 | 9701 |  | STAA | fPACCIMN | save the result. is the result negative? |
| 0525 | C286 | 2416 |  | BCC | fltados | no. go mormalize the result. |
| 0526 | C288 | 9601 |  | LDAA | FPACC1MN | yes. negate the mantissa. |
| 0527 | C2BA | 43 |  | COMA |  |  |
| 0528 | C2B8 | 36 |  | PSHA |  | save the result. |
| 0529 | C2BC | DC 02 |  | LDD | FPACC1MN+1 | GET LOWER 16 Bits. |
| 0530 | C2BE | 53 |  | COMB |  | FORM THE ONE'S COMPLEMENT. |
| 0531 | C2BF | 43 |  | COMA |  |  |
| 0532 | C2CO | C3 0001 |  | ADDD | \#1 | form the two's complement. |
| 0533 | C2C3 | DD 02 |  | STD | FPACC1MN+1 | save the result. |
| 0534 | C2C5 | 32 |  | PULA |  | GET UPPER 8 bITS BACK. |
| 0535 | C2C6 | 8900 |  | ADCA | \#0 | ADO IN POSSIBLE CARRY. |
| 0536 | C2C8 | 9701 |  | STAA | fPACCIMN | Save result. |
| 0537 | C2CA | 86 FF |  | LDAA | \#SFF | SHOW that ffacci is negative. |
| 0538 | C2CC | 9704 |  | StAA | MANTSGN 1 |  |
| 0539 | C2CE | BD C1 61 | fltadd 9 | JSR | FPNORM | go normalize the result. |
| 0540 | C201 | 2406 |  | BCC | FLTADD 12 | EVERYTHING'S OK SO RETURN. |
| 0541 | C203 | 8603 |  | LDAA | \#UNFERR | UNDERFLOW OCCURED DURING NORMALIZATION. |
| 0542 | C205 | OD |  | SEC |  | FLAG ERROR. |
| 0543 | C206 | 7E C2 48 |  | JMP | FLTADD 10 | RETURN. |
| 0544 | C209 | 7E C2 47 | FLTADD 12 | JMP | FLTADD6 | CAN't branch that far from here. |
| 0545 |  |  |  |  |  |  |
| 0546 | C2DC | DC 02 | FLTADO11 | LDD | FPACC1MN+1 | GET LOWER 16 Bits of fpacci. |
| 0547 | C2DE | 0307 |  | ADDD | FPACC2MN+1 | ADD it to the lower 16 bits of fPaccl. |
| 0548 | C2EO | D0 02 |  | STO | FPACC 1 M +1 | Save result in fracct. |
| 0549 | C2E2 | 9601 |  | LDAA | fPACCIMN | GET UPPER 8 BITS OF FPACCI. |
| 0550 | C2E4 | 9906 |  | ADCA | FPACC2MN | AOD IT (WITH CARRY) TO UPPER 8 8ITS OF FPACC2. |
| 0551 | C2E6 | 9701 |  | StAA | fPACCIMN | save the result. |
| 0552 | C2E8 | 24 EF |  | BCC | FLTADD 12 | NO OVERFLOW SO JUST RETURN. |
| 0553 | C2EA | 760001 |  | ROR | fPACCIMN | put the carry into the mantissa. |
| 0554 | C2ED 76 | 760002 |  | ROR | FPACC1MN+1 | PROPIGATE THROUGH MANTISSA. |
| 0555 | C2F0 | 760003 |  | ROR | FPACC1Mn+2 |  |
| 0556 | C2f3 | 7c 0000 |  | INC | fPACC1EX | Up the mantissa by 1. |
| 0557 | C2F6 | 26 E1 |  | BNE | FLTADD12 | EVERYTHING'S OK Just return. |
| 0558 | C2F8 8 | 8602 |  | LDAA | \#ovferr | RESULT WAS too large. overflow. |
| 0559 | C2FA | 00 |  | SEC |  | FLAG ERROR. |
| 0560 | C2FB | 7E C2 48 |  | JMP | FLTADO 10 | RETURN. |
| 0561 |  |  | * |  |  |  |
| 0562 |  |  | * |  |  |  |
| 0563 |  |  |  |  |  |  |




| 0655 | C35E 740006 | FLTOIV14 LSR | FPACC2MN | Shift the divisop to the right 1 git. |
| :---: | :---: | :---: | :---: | :---: |
| 0656 | C361 760007 | ROR | FPACC2MN+1 |  |
| 0657 | C364 760008 | ROR | FPACC2MN+2 |  |
| 0658 | C367 9600 | LDAA | fPACCIEX | GET FPACC1 EXPONENT. |
| 0659 | C369 0605 | LDAB | fPACC2EX | GET FPACC2 EXPONENT. |
| 0660 | C36B 50 | NEGB |  | add the two's complement to set flags properly. |
| 0661 | C36C 18 | ABA |  |  |
| 0662 | C360 28 06 | BMI | FLTDIV5 | L.F RESULT MINUS CHECK CARRY FOR POSS. OVERflow. |
| 0663 | C36F 2506 | BCS | FLTOIV7 | If PLUS \& CARRY SET ALL IS OK. |
| 0664 | C37186 03 | LDAA | HUNFERR | If NOT, UNDERFLOW ERROR. |
| 0665 | C373 2003 | BRA | FLTDIV6 | RETURN WITH ERROR. |
| 0666 | C375 25 CE | FLTOIVS BCS | FLTDIV8 | If MINUS \& CARRY SET OVERFLOW ERROR. |
| 0667 | C377 88 81 | fltoiv7 adoa | \#\$81 | ADD BACK BIAS + 1 (THE '11 COMPENSATES FOR ALGOR.) |
| 0668 | C379 9700 | STAA | FPACCIEX | SAVE RESULT. |
| 0669 | C37B DC 01 | fliolvg LOD | fPACCIMN | SAVE dividend in case subtraction doesn't go. |
| 0670 | C370 ED 04 | Sto | $4 . X$ |  |
| 0671 | C37f 9603 | LDAA | FPACCIMN +2 |  |
| 0672 | C381 A7 06 | STAA | 6, x |  |
| 0673 | C383 OC 02 | LOD | FPACCIMN +1 | GET LOWER 16 BITS FGR SUBTRACTION. |
| 0674 | C385 $93 \mathrm{C7}$ | SUBD | FPACC2MN+1 |  |
| 0675 | C387 00 02 | STO | FPACCIMN+1 | SAVE RESULT. |
| 0676 | c389 96 01 | LDAA | fPACCIMn | GET HIGH 8 bits. |
| 0677 | -388 9206 | SBCA | FPACC2MN |  |
| 0678 | C380 9701 | StAA | FPACCIMN |  |
| 0679 | C38F 2A 08 | BPL | FLTOIVIO | SUBTRACTION WENT OK. GO DO Shifts. |
| 0680 | C391 EC 04 | LOD | $4, \mathrm{x}$ | RESTORE OLD DIVIDENC. |
| 0681 | C393 DD 01 | STD | FPACCIMN |  |
| 0682 | C395 A6 06 | LDAA | 6, X |  |
| 0683 | C397 9703 | STAA | FPACC $1 \mathrm{MN}+2$ |  |
| 0684 | 63996903 | FLTOIVIO ROL | 3, x | rotate carry into quotient. |
| 0685 | C398 6902 | ROL | 2, $x$ |  |
| 0686 | C390 6901 | ROL | 1, X |  |
| 0687 | C39F 7800 c 3 | LSL | FPACC 1 M +2 | Shift dividend to left for next subtract. |
| 0688 | C3AL 7900 c 2 | ROL | FPACC 1 MN +1 |  |
| CE89 | C3A5 79 00 3 | 2 OL | FPACCIMN |  |
| C6C5 | çar ba oo | OEC | $0, \mathrm{x}$ | DONE YET? |
| 2671 | C3AA 26 CF | BNE | fltoivg | NO. KEEP GOING. |
| 0692 | c3aC 6301 | COM | 1, x | RESULT MUST BE COMPLEMENTED. |
| 0693 | c3aE 63 02 | COM | 2, $x$ |  |
| 0694 | こ380 6303 | COM | 3, x |  |
| 0695 | C382 DC 02 | LDD | FPACC1MN+1 | do 1 more subtract for rounding. |
| 0696 | C3B4 9307 | SUBD | FPACCZMN +1 | ( don't neeo to save the resúlt. ) |
| 0697 | C386 9601 | LDAA | fPACCIMn |  |
| 0698 | C3B8 92 Ot | SBCA | FPACC2Mn | ( NO NEED to save the resillt. ) |
| 0609 | c3ba ec 02 | LCD | 2, X | GET LOW 16 BITS. |
| 0700 | こ3BC 2403 | BCC | FLTDIVI ${ }^{1}$ | If it oidnt go result ok as is. |
| 0701 | C3BE OC | CLC |  | Clear the carry. |
| 0702 | C3bF 2003 | bRA | fltoivis | go save the number. |
| 0763 | C3C1 c3 00: | FLTO:V11 A000 | \#1 | ROUND UP BY 1. |
| 0704 | C3C4 20 Cl | FLTD:V13 STO | FPACC1MN +1 | put it in fpacci. |
| 0705 | C3C6 A6 01 | LDAA | 1, $x$ | GET HIGH 8 bIts. |
| 0706 | c3C8 89 do | AOCA | \# 0 |  |
| 6707 | C3CA 9701 | STAA | fPACCIMN | Save result. |
| 0758 | C3CC 2409 | BCC | fltolviz | If CARRY Clear answer ok. |
| 0709 | C3CE 7600 Cl | ROR | FPACC:MN | If NOT OVERFLOW. ROTATE CARry in. |
| 0710 | C301 760002 | ROR | FPACC $1 \mathrm{MN}+1$ |  |
| 0711 | C304 $7600 \quad 03$ | ROR | FPACC 1 M +2 |  |
| 0712 | C307 OC | fliolv12 CLC |  | NO ERRORS. |
| 0713 | C308 7E C3 48 | JMP | FLTDIVS | RETURN. |
| 0714 |  | * |  |  |
| 0715 |  | * |  |  |
| 0716 |  | * |  |  |




| 0848 C403 CD EF 00 | FLTASC16 Six | 0,Y | SAVE UPDATED POINTER. |
| :---: | :---: | :---: | :---: |
| 0849 C4D6 38 | PULX |  | RESTORE POINTER TO CONSTANTS. |
| 0850 C4D 08 | INX |  | POINT TO NEXT CONSTANT. |
| 0851 C4D8 08 | INX |  |  |
| 0852 C4D9 08 | INX |  |  |
| 0853 C4DA 18 6A 05 | DEC | 5, Y | DONE YET? |
| 0854 C4DD 26 BC | BNE | Fltascio | no. Continue conversion of "mantissa". |
| 0855 C4DF CD EE 00 | LDX | O, Y | YES. POINT TO BUFFER STRING BUFFER. |
| 0856 CLE2 09 | fltasc 13 dex |  | POINT TO LASt character put in the buffer. |
| 0857 C4E3 A6 00 | LDAA | 0,x | GET IT. |
| 0858 C4E5 8130 | CMPA | \#\$30 | WAS IT AN ASCII O? |
| 0859 C4E7 27 F9 | BEQ | Fltasc 13 | YES. REMOVE TRAILING ZEROS. |
| 0860 CLE9 08 | INX |  | point to next available location in buffer. |
| 0861 CLEA 18 E6 02 | LDAB | 2, Y | DO WE NEED TO PUT OUT AN EXPONENT? |
| 0862 C4ED 27 2A | BEQ | Fltascis | NO. WE'RE DONE. |
| 0863 C4EF 8645 | LDAA | \#'E | Yes. PUT AN 'E' in the buffer. |
| 0864 C4F1 A7 00 | STAA | $0 . \mathrm{x}$ |  |
| 0865 C4F3 08 | INX |  | POINT TO NEXT BUFFER LOCATION. |
| 0866 C4F4 86 2B | LDAA | \#'+ | ASSUME EXPONENT IS POSITIVE. |
| 0867 C4F6 A7 00 | StAA | 0, X | put plus sign in the buffer. |
| 0868 C4F8 50 | tStB |  | IS It really minus? |
| 0869 C4F9 2A 05 | BPL | FLTASC14 | NO. IS'S OK AS IS. |
| 0870 C4FB 50 | NEGB |  | yes. make it positive. |
| 0871 C4FC 86 2D | LDAA | \#'. | put the minus sign in the buffer. |
| 0872 C4FE A7 00 | STAA | 0, x |  |
| 0873 C500 08 | FLTASC14 InX |  | POINT TO NEXT BUFFER LOCATION. |
| 0874 C501 CD EF 00 | STX | 0, Y | SAVE POINTER TO STRING BUFFER. |
| 0875 C504 4F | CLRA |  | SET UP FOR DIVIDE. |
| 0876 C505 CE 00 OA | LDX | \#10 | DIVIDE DECIMAL EXPONENT BY 10. |
| 0877 C508 02 | IDIV |  |  |
| 0878 C509 37 | PSHB |  | SAVE REmAINDER. |
| 0879 C50A 8F | XGDX |  | PUT QUotient in o. |
| 0880 C50B CB 30 | ADDB | \#\$30 | make it ascil. |
| 0881 C500 CD EE 00 | LDX | O,Y | GET POINTER. |
| $0882 \mathrm{C510}$ E7 00 | STAB | 0, x | PUT NUMBER In buffer. |
| 0883 C512 08 | InX |  | POINT TO NEXT LOCATION. |
| 0884 C513 33 | PULB |  | GET SECOND DIGIT. |
| 0885 C514 CB 30 | ADDB | \#\$30 | make it ascil. |
| 0886 C516 E7 00 | Stab | $0, \mathrm{x}$ | put lit in the buffer. |
| 0887 C518 08 | InX |  | POINT TO NEXT LOCATION. |
| 0888 C519 6F 00 | FLTASC15 CLR | $0, \mathrm{x}$ | terminate string with a zero byte. |
| 0889 C51B 38 | PULX |  | Clear locals from stack. |
| 0890 C51C 38 | PULX |  |  |
| 0891 C510 38 | PULX |  |  |
| 0892 C51E BD C8 43 | JSR | PULFPAC2 | RESTORE FPACC2. |
| 0893 C521 32 | PULA |  |  |
| 0894 C522 9704 | STAA | MANTSGN1 |  |
| 0895 C524 38 | PULX |  | RESTORE FPACCT. |
| 0896 C525 DF 02 | Six | FPACC1MN+1 |  |
| 0897 C527 38 | PULX |  |  |
| 0898 C528 DF 00 | STX | fPACC1EX |  |
| 0899 C52A 38 | PULX |  | Point to the start of the ascil string. |
| 0900 C528 39 | RTS |  | RETURN. |
| 0901 | * |  |  |
| 0902 | * |  |  |
| 0903 C52C | DECDIG EQU | * |  |
| 0904 C52C OF 4240 | FCB | \$0F,\$42,\$40 | decimal 1,000,000 |
| 0905 C52F 0186 AO | FCB | \$01, \$86, \$A0 | DECIMAL 100,000 |
| 0906 C532 002710 | FCB | \$00,\$27,\$10 | DECIMAL 10,000 |
| 0907 C535 $0003 \mathrm{E8}$ | FCB | \$00,\$03, \$E8 | decimal 1,000 |
| 0908 C538 000064 | FCB | \$00,\$00,\$64 | DECIMAL 100 |
| 0909 C53B 00000 O | FCB | \$00, \$00,\$0A | DECIMAL 10 |
| 0910 CS3E 000001 | FCB | \$00, \$00, \$01 | DECIMAL 1 |
| 0911 | * |  |  |
| 0912 | * |  |  |
| 0913 C541 | P9999999 EQU | * | CONSTANT 999999.9 |


| 0914 | C5419474 23 FE | FCB | \$94, \$74,\$23,57E |
| :---: | :---: | :---: | :---: |
| 0915 |  | * |  |
| 0916 | C545 | N9999999 EQU | * CONSTANT 9999999. |
| 0917 | C545 $98 \quad 189678$ | FCB | \$98, \$18, \$96, \$7\% |
| 0918 |  | * |  |
| 0919 | C549 | CONSTPS EQU | CONSTANT . 5 |
| 0920 | c549 80000000 | FCB | \$80, \$00, \$00,\$00 |
| 0921 |  | * |  |
| 0922 |  | * |  |
| 0923 | C540 | fltcmp equ | * |
| 0924 | C540 700004 | TST | MANTSGN1 IS FPACCI NEGATIVE? |
| 0925 | C550 2A 12 | BPL | FLTCMP2 NO. CONTINUE WITH COMPARE. |
| 0926 | C552 700009 | TST | mantsgnz is fpaccz negative? |
| 0927 | C555 2A OD | BPL | FLTCMPZ NO. CONTINUE WITH COMPARE. |
| 0928 | C557 DC O5 | 100 | fpacczex yes. both are negative so compare must be done |
| 0929 | C559 1A 9300 | CPD | fpacciex backwards. are they equal so far? |
| 0930 | C5SC 2605 | BNE | FLICMP1 NO. RETURN WITH CONDITION COOES SET. |
| 0931 | CS5E DC 07 | LOO | fPACC2Mn+1 YES. COMPARE LOWER 16 BITS OF MANTISSAS. |
| 0932 | C560 1A 9302 | CPD | FPACC1MN+1 |
| 0933 | C563 39 | FLTCMP1 RTS | RETURN WITH CONDITION CODES SET. |
| 0934 | C564 9604 | FLICMPZ LDAA | mantsgni get fpacci mantissa sign. |
| 0935 | C566 9109 | CMPA | MANTSGN2 BOTH POSITIVE? |
| 0936 | C568 26 f9 | BNE | fltcmpl no. return with conoition cooes set. |
| 0937 | CS6A OC 00 | LDD | fPACCIEX GET FPACCI EXPONENT \& UPPER 8 bits of mantissa. |
| 0938 | C56C 1A 9305 | CPD | FPACC2EX SAME AS FPACC2? |
| 0939 | C56F 26 f2 | BNE | Flicmpi no. return with conoition codes set. |
| 0940 | C571 DC 02 | LDD | FPACCIMN+1 GET FPACC1 LOWER 16 BITS OF MANTISSA. |
| 0941 | C573 1A 9307 | CPD | fPACC2mn+1 COMPare with fpaccl lower 16 Bits of mantissa. |
| 0942 | C576 39 | RTS | return With condition cooes set. |
| 0943 |  | * |  |
| 0944 |  | * |  |
| 0945 |  | * |  |









| 1252 c | c702 A7 00 |  | STAA | $0, \mathrm{x}$ | , |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 1253 c | C704 08 |  | INX |  | POINT TO The nexi power. |
| 1254 c | C705 08 |  | INX |  |  |
| 1255 | c706 98 |  | INX |  |  |
| 1256 | C707 08 | * | INX |  |  |
| 1257 c | C708 08 |  | InX |  |  |
| 1258 | C709 18 6A 00 |  | DEC | 0, Y | DONE? |
| 1259 c | C70C 26 C5 |  | 8NE | SINCOS2 | NO. GO DO ANOTHER MULIIPLICATION. |
| 1260 c | C70e 8603 |  | LDAA | \#53 | GET LOOP COUNT. |
| 1261 c | C710 18 A7 00 |  | StaA | 0,Y | SAVE IT. |
| 1262 c | C713 CD EE 03 | Sincos3 | L0X | 3, Y | POINT TO RESULTS ON THE STACK. |
| 1263 c | C716 09 |  | DEX |  | point to previous result. |
| 1264 | C717 09 |  | DEX |  |  |
| 1265 | c718 09 |  | DEX |  |  |
| 1266 c | C719 09 |  | DEX |  |  |
| 1267 C | C71A 09 |  | DEX |  |  |
| 1268 C | C71B CD EF 03 |  | STX | 3,Y | SAVE the new pointer. |
| 1269 c | C71E A6 00 |  | LDAA | $0, \mathrm{X}$ | GET NUMBERS SIGN. |
| 1270 | C720 9709 |  | STAA | MANTSGN2 | PUT IT IN FPACC2. |
| 1271 | C722 EC 01 |  | LDD | 1, X | GET LOW 16 Bits of the Mantissa. |
| 1272 c | C724 DD OS |  | STD | fPaCC2EX | PUT IN FPACC2. |
| 1273 | C726 EC 03 |  | LDD | 3, x | GET HIGH 8 BIT \& EXPONENT. |
| 1274 | C728 DD 07 |  | STD | FPACC2MN+1 | PUT IN FPACC2. |
| 1275 | C72A BD C2 3C |  | JSR | FlTADD | GO ADD the two numbers. |
| 1276 | C720 18 6A 00 |  | DEC | $0, Y$ | DONE? |
| 1277 c | c730 26 E1 |  | BNE | SINCOS3 | NO. GO AdD the next term in. |
| 1278 c | C732 1860 OA |  | TST | 10, Y | ARE WE DOING THE SINE? |
| 1279 c | c735 2708 |  | BEQ | SINCOSS | YES. GO PUT THE ORIGINAL ANGLE INTO fPACC2. |
| 1280 c | C737 CE C7 E3 |  | LDX | \#ONE | no. for cosine put the constant 1 into fpaccl. |
| 1281 | C73A 8D C8 66 |  | JSR | GETfPAC2 |  |
| 1282 C | C730 20 OF |  | BRA | SINCOS6 | GO ado it to the sum of the terms. |
| 1283 | c73F 18 A6 05 | SINCOS5 | LDAA | S, Y | GEt the value of the original angle. |
| 1284 | C742 9709 |  | StaA | MANTSGN2 | PUT IT IN FPACC2. |
| 1285 | C744 18 EC 06 |  | LDD | 6,Y |  |
| 1286 c | C747 DD 05 |  | STD | fPaCc2ex |  |
| 1287 c | C749 18 EC 08 |  | LDD | 8, $Y$ |  |
| 1288 C | C74C DD 07 |  | STD | FPACC2MN+1 |  |
| 1289 C | C74E BD C2 3C | SINCOS6 | JSR | Fltado | go add it to the sum of the terms. |
| 1290 C | C751 30 |  | TSX |  | NOW CLEAN UP THE STACK. |
| 1291 C | C752 8F |  | XGDX |  | PUT STACK IND. |
| 1292 c | C753 C3 00 1F |  | ADDD | \#31 | Clear all the terms \& temps off the stack. |
| 1293 C | C756 8F |  | XGOX |  |  |
| 1294 C | C757 35 |  | TXS |  | UPDATE The stack pointer. |
| 1295 C | C758 39 |  | RTS |  | RETURN. |
| 1296 |  | * |  |  |  |
| 1297 |  | * |  |  |  |
| 1298 C | C759 | ANGRED | EQU | * |  |
| 1299 C | C759 4F |  | CLRA |  | initialize the 45's compliment flag. |
| 1300 C | C75A 36 |  | PSHA |  | put it on the stack. |
| 1301 c | c758 4C |  | INCA |  | initialize the quad count to 1. |
| 1302 C | C75C 36 |  | PSHA |  | Put it on the stack. |
| 1303 C | C75D 1830 |  | TSY |  | POINT TO IT. |
| 1304 C | C75F CE C7 EB |  | LDX | \#THREE60 | POINT TO THE CONSTANT 360. |
| 1305 C | C762 BD C8 66 |  | JSR | GETfPACZ | GET IT INTO FPACC. |
| 1306 C | C765 70 0004 |  | TST | MANTSGN1 | IS the input angle negative: |
| 1307 C | C768 2A 03 |  | BPL | ANGRED 1 | NO. SKIP THE ADD. |
| 1308 C | C76A BD C2 3C |  | JSR | FLTADD | yes. make the angle positive by adoing 360 deg. |
| 1309 C | C760 7A 0005 | ANGRED 1 | DEC | fPACC2EX | make the constant in fpacc2 90 degrees. |
| 1310 C | c770 7a 0005 |  | DEC | fpacceex |  |
| 1311 C | C773 BD C5 40 | ANGRED2 | JSR | FLTCMP | IS the angle less than 90 Degrees already? |
| 1312 C | C776 2308 |  | BLS | ANGRED3 | yes. RETURN WITH QUAD COUNT. |
| 1313 c | C778 BD C2 FE |  | JSR | fltsub | NO. REDUCE ANGLE BY 90 degrees. |
| 1314 C | C77B 18 6C 00 |  | INC | O, Y | InCREMENT THE QuAd Count. |
| 1315 c | C77E $20 \mathrm{f3}$ |  | BRA | ANGRED2 | GO SEE If It's less than 90 NOW. |
| 1316 C | C780 i8 A6 00 | ANGRED3 | LDAA | 0, ${ }^{\text {Y }}$ | GET THE QUAD COUNT. |
| 1317 C | c783 8101 |  | CMPA | \#1 | WAS the original angle in ouad 1? |


| 1318 | c785 27 OB |  | BEO | ANGRED4 YE | YES. COMPUTE TRIG FUNCTION AS IS. |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 1319 | C787 8103 |  | CMPA | \#3 NO | NO. WAS THE ORIGINAL ANGLE IN QUAD 3? |
| 1320 | C789 2707 |  | BEQ | ANGRED4 YE | yes. Compute the trig function as if in quad 1. |
| 1321 | C78B 86 FF |  | LDAA | \#SFF NO | NO. MUST COMPUTE the trig function of the 90's |
| 1322 | C780 9704 |  | STAA | MANTSGN1 CO | COMPLIMENT ANGLE. |
| 1323 | C78F BD C2 3C |  | JSR | FLTADD AD | add 90 degrees to the negated angle. |
| 1324 | C792 7A 0005 | ANGRED4 | DEC | fPACC2EX MAK | make the angle in fpaccl 45 degrees. |
| 1325 | C795 BD C5 4D |  | JSR | FLTCMP IS | IS the angle < 45 Degrees? |
| 1326 | C798 2300 |  | BLS | ANGRED5 YES | YES. IT'S OK AS IT IS. |
| 1327 | C79A 7C 0005 |  | INC | fPACCZEX NO | no. must get the 90's compliment. |
| 1328 | C790 86 FF |  | LDAA | \#SFF MAK | make fpacci negative. |
| 1329 | C79F 9704 |  | StaA | MANTSGN1 |  |
| 1330 | C7A1 BD C2 3C |  | JSR | FLTADD GE | GET THE 90's COMPLIMENT. |
| 1331 | C7A4 18 6C 01 |  | INC | 1,Y SE | SEt the flag. |
| 1332 | c7a7 33 | ANGRED5 | PULB |  | GEt the quad count. |
| 1333 | C7A8 32 |  | PULA |  | get the compliment flag. |
| 1334 | C7A9 39 |  | RTS |  | RETURN WITH THE QUAD COUNT \& COMPLIMENT FLAG. |
| 1335 |  | * |  |  |  |
| 1336 |  | * |  |  |  |
| 1337 | C7AA | EXGIAND2 | EQU | * |  |
| 1338 | C7AA DC 00 |  | LDD | fpacciex |  |
| 1339 | C7AC DE 05 |  | LOX | fPaCCZEX |  |
| 1340 | C7AE DD 05 |  | STD | fpacciex |  |
| 1341 | C7B0 DF 00 |  | STX | fPacciex |  |
| 1342 | C7B2 DC 02 |  | LDD | FPACC1MN+1 |  |
| 1343 | C7B4 DE 07 |  | LDX | FPACC2MN+1 |  |
| 1344 | C7B6 DD 07 |  | STO | FPACCZMN+1 |  |
| 1345 | C7B8 DF 02 |  | STX | FPACC1MN +1 |  |
| 1346 | C7BA 9604 |  | LDAA | MANTSGN1 |  |
| 1347 | C7BC 0609 |  | LDAB | mantsgn2 |  |
| 1348 | C7BE 9709 |  | StAA | MANTSGN2 |  |
| 1349 | C7C0 D7 04 |  | Stab | Mantsgn 1 |  |
| 1350 | C7C2 39 |  | RTS |  | RETURN. |
| 1351 |  | * |  |  |  |
| 1352 |  | * |  |  |  |
| 1353 | c7C3 | SINFACT | EQU | * |  |
| 1354 | C7C3 6E 38 EF 10 |  | FCB | \$6E,\$38,\$EF, \$1D | $10 \quad+(1 / 9!)$ |
| 1355 | C7C7 74 DO OD 01 |  | FCB | \$74, \$00, \$00, \$01 | $01-(1 / 7!)$ |
| 1356 | C7CB 7A 088888 |  | FCB | \$7A,\$08, \$88, \$89 | $89+(1 / 5!)$ |
| 1357 | C7CF 7E AA AA AB |  | FCB | \$7E, \$AA, \$AA, \$AB | AB $\quad$ (1/3!) |
| 1358 |  | * |  |  |  |
| 1359 |  | * |  |  |  |
| 1360 | c703 | COSFACT | Equ | * |  |
| 1361 | C703 71500001 |  | FCB | \$71,\$50, \$00, \$01 | $01+(1 / 8!)$ |
| 1362 | C707 77 B6 OB 61 |  | FCB | \$77, \$B6, \$0B, \$61 | $81-(1 / 6!)$ |
| 1363 | C7DB 7C 2A AA AB |  | FCB | \$7C, \$2A, \$AA, \$AB | AB $\quad+(1 / 4!)$ |
| 1364 | CTDF 80800000 |  | FCB | \$80,\$80,\$00,\$00 | $00 \cdot(1 / 2!)$ |
| 1365 |  | * |  |  |  |
| 1366 |  | * |  |  |  |
| 1367 | C7E3 81000000 | ONE | FCB | \$81,\$00,\$00,\$00 | 000 |
| 1368 | C7E7 8249 OF DB | PI | FCB | \$82,\$49,\$0F, \$DB | OB $\quad 3.1415927$ |
| 1369 | C7EB 89340000 | THREE60 | FCB | \$89,\$34,\$00,\$00 | 00360.0 |
| 1370 |  | * |  |  |  |
| 1371 |  | * |  |  |  |
| 1372 |  | * |  |  |  |




1479
1480
1481
1482



```
FLTASC12 C4B1 *0831 0828
FLTASC13 C4E2 *0856 0859
FLTASC16 C500 *0873 0869
FLTASC1S CS19 *0888 0862
FLTASC16 C403 *0848 0844
FLTASC17 C45C *0791 0786
FLTASC18 C490 *0817 0813
FLTASC2 C4OE *0760 0757
FLTASC3 C438*0776 0766
FLTASC4 C440 *0779 0770
FLTASC5 C414 *0763 0775
FLTASC6 C430 *0773 0778
FLTASC7 C452 *0787 0791
FLTASC8 C474 *0804 0797 0799
FLTASC9 C493 *0818 0807
FLTCMP C54D *0923 0765 0769 1311 1325
FLTCMP1 CS63 *0933 093009360939
FLTCMP2 C564 *0934 0925 0927
FLTCOS C66F *1168 1384
FLTCOS1 C68C *1183 1179 1181
FLTDIV C30A *0608 1101 1387
FLTDIV1 C316 *0615 0611
FLTDIV10 c399 *0684 0679
FLTDIV11 C3C1 *0703 0700
FLTDIV12 C3D7 *0712 0708
FLYDIV13 C3C4 *0704 0702
FLTDIV14 C35E *0655 0639
FLTDIV2 C32O *0620 0617
FLTDIVS C33E *0636 0633
FLTDIV4 C350 *0648 0636
FLTDIVS C375 *0666 0662
FLTDIV6 C348 *0642 0665 0713
FLTDIV7 C377 *0667 0663
FLTDIV8 C345 *0640 0666
FLTDIV9 C378 *0669 0691
FLTFMTER 0001 *0038 0136
FLTMUL C193 *0358 0293 0774 1210 1218 1245 1419
FLTSIN C653 *1142 1386
FLTSIN1 C65F *1149
FLTSIN2 C66A *1154 1152 1183
FLTSQR CSEB *1073
FLTSQR1 C5F4 *1078 1076
FLTSQR2 CSFD *1083 1079
FLTSQR3 C617 *1098 1095
FLTSQRG C61A *1100 1097
FLTSQRS C61C *1101 1110
FLTSUB C2FE *0580 1313
FLTSUB1 C303 *0583 0581
FLTTAN CTEF *1381
FLTTAN1 C80B *1392 1388
FPACC1EX 0000 *0030 0100 0101 0151 0206 0207 0224 0276 02790282
```

                                    03140320036003680374038603880425043804710475
                                    04810490049105560615065806680735074207820898
                                    09290937096009651020102310361053107410881103
                                    \(\begin{array}{lllllllllll}1106 & 1112 & 1124 & 1199 & 1221 & 1242 & 1249 & 1338 & 1341 & 1517 & 1553\end{array}\)
    FPACCIMN 0001 *0031 022902310234023702410244024802490254
02550256025902620264031703190323032503690405
04080441044304770492050905120515051805190521
05220524052605290533053605460548054905510553
05540555063106340648065006510653066906710673
06750676067806810683068706880689069506970704
07070709071007110744078707880789082208240825
08270831083308340836089609320940098509911031
10321033104210461054108611081114112611971219
$\begin{array}{llllll}1244 & 1247 & 1342 & 1345 & 1519 & 1558\end{array}$
FPACC2EX 0005 *0033 036303750465047404820484060906370659

09280938109211001111112512721286130913101324 13271339134015311564
FPACC2MN 0006 *0034 023002320239024302610263040204140415 04160421042604760496050705100513051605200523 05470550063206350649065206550656065706740677 06960698093109411113112712741288134313441533 1569
FPMULT1 C1C1 *0381 0376
FPMULT2 C1C8 *0385 03770381
FPMULTS C1CF *0388 03620370
FPMULT4 C1AE *0371 0365
FPMULTS C1BC *0378 0389
FPMULT6 C1D5 *0391 03800384
FPNORM C161 *0313 028305390966
FPNORM1 C160*0319
FPNORM2 C16F *0320 0324
FPNORMS C17C *0326 03160318
FPNORM4 C17E *0328 0321
GETFP11 C85D *1516 1514
GETFP12 C85F *1517 1511
GETFP21 C873 *1530 1528
GETFP22 C875 *1531 1525
GETFPAC1 C850 * 150913901433
GETFPAC2 C866 *1523 028802920764076807730780123212811305
14181469
GETPI C82B *1431
MANTSGN1 0004 *0032 010201130371037304790502050505380622 06230746075607580894092409340997102610471078 $\begin{array}{llllllllllllllllllllll}1128 & 1153 & 1182 & 1201 & 1223 & 1240 & 1251 & 1306 & 1322 & 1329 & 1346\end{array}$ 1349 :512 15151554
MANTSGN2 0009 *0035 $03720 ; 780503058305850621092609351129$ $\begin{array}{llllllllllll}1270 & 1 ; 84 & 1347 & 1348 & 1526 & 1529 & 1565\end{array}$
MAXNUM C80F *1396 1389
N9999999 C545*0916 0763
NSQRTERR 0006 *0043 1080
NUMERIC C155 *0303 010601160126014301540162017401840190 0219
NUMERIC1 C15F *0310 03050307
ONE C7E3 *1367 1280
OVFERR 0002 *0039 037805580640
P9999999 C541*0913 0767
PI C7E7 *1368 1432
PIOV180 C831 *1436 1417
PSHFPAC2 C839 *1454 009703590464062007481083114311691382 14161426
PULFPAC2 C843 *1465 013402980391046906460892111811551392 1420
PUTFP11 C885 *1557 1555
PUTFP21 C895 *1568 1566
PUTFPAC1 C87C *1552
PUTFPAC2 C88C *1563 1462
PUR10EXP 0001 *0090 018701920195019902020280028402890294
RAD2DEG C823*1425
SINCOS C68F *1195 11491176
SINCOS1 C6BC *1218 1226
SINCOS2 C6D3 *1230 1259
SINCOS3 C713 *1262 1277
SINCOS4 C6BF *1219 1216
SINCOS5 C73F *1283 1279
SINCOS6 C74E *1289 1282
SINCOS7 C6B9 * 12171212
SINFACT C7C3 *1353 1203
SINT2FLT C589 *0984
SINTFLT1 C595 *0992 0987
SINTFLT2 C59F *0998 0996
TAN90ERR 0007 *0044 1391


# Using the Serial Peripheral Interface to Communicate Between Multiple Microcomputers 

As the complexity of user applications increases, many designers find themselves needing multiple microprocessors to provide necessary functionality in a circuit. Communication between multiple processors can often be difficult, especially when differing processors are used. A possible solution to this problem is usage of the serial peripheral interface (SPI), an interface intended for communication between integrated circuits on the same printed wire board. The MC68HCO5C4 is one of the first single-chip microcomputers to incorporate SPI into hardware. One advantage of the SPI is that it can be provided in software, allowing communication between two microcomputers where one has SP1 hardware and one does not. Special interfacing is necessary when using the hardware SPI to communicate with a microcomputer that does not include SPI hardware. This interface can be illustrated with a circuit used to display either temperature or time, that incorporates both a MC68HC05C4 and a MC68705R3. The MC68HC05C4 monitors inputs from a keypad and controls the SPI data exchange, while the MC68705R3 determines temperature by performing an analog-to-digital conversion on inputs from a temperature sensor and controls the LED display. Communication between the microcomputers is handled via SPI, with the MC68HC05C4 handling exchanges in hardware, and the MC68705R3 handling them in software.
Usage of software SPI can be expanded to include circuits where the single-chip implementing the SPI in software controls the data exchange, and those in which neither singlechip has hardware SPI capability. Minor modifications to the SPI code are necessary when data exchanges are controlled by the software.

Debugging designs including multiple processors can often be confusing. Some of the confusion can be alleviated by careful planning of both the physical debugging environment and the order in which software is checked.

## SERIAL PERIPHERAL INTERFACE

Communication between the two processors is handled via the serial peripheral interface (SPI). Every SPI system consists of one master and one or more slaves, where a master is defined as the microcomputer that provides the SPI clock, and a slave is any integrated circuit that receives the SPI clock from the master. It is possible to have a system where more than one IC can be master, but there can only be one master at any given time. In this design, the MC68HC05C4 is the master and the MC68705R3 is the slave. Four basic signals, master-out/slave-in (MOSI), master-in/slave-out (MISO), serial clock (SCK), and slave select (SS), are needed for an SPI. These four signals are provided on the MC68HCO5C4 on port D, pins 2-5.

## SIGNALS

The MOSI pin is configured as a data output on the master and a data input on the slave. This pin is used to transfer data serially from the master to a slave, in this case the MC68HC05C4 to the MC68705R3. Data is transferred most significant bit first.

Data transfer from slave to master is carried out across the MISO, master-in/slave-out, line. The MISO pin is configured as an input on the master device and an output on the slave device. As with data transfers across the MOSI line, data is transmitted most significant bit first.

All data transfers are synchronized by the serial clock. One bit of data is transferred every clock pulse, and one byte can be exchanged in eight clock cycles. Since the serial clock is generated by the master, it is an input on the slave. The serial clock is derived from the master's internal processor clock, and clock rate is selected by setting bits 0 and 1 of the serial peripheral control register to choose one of four divide-by values. Values for the MCUs crystal oscillators and the SPI divide-by must be chosen so that the SPI clock is no faster than the internal processor clock on the slave.

The last of the four SPI signals is the slave select (SS). Slave select is an active low signal, and the SS pin is a fixed input which is used to enable a slave to receive data. A master will become a slave when it detects a low level on its SS line. In this design, the MC68HC05C4 is always the master, so its SS line is tied to VDD through a pull-up resistor.

## REGISTERS

Three registers unique to the serial peripheral interface provide control, status, and data storage.
The Serial Peripheral Control Register (SPCR), shown below, provides control for the SPI.

|  | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| \$0A | SPIE | SPE | - | MSTR | CPOL | CPHA | SPR1 | SPRO | SPCR |
| RESET | 0 | 0 | 0 | 0 | 0 | 1 | $u$ | $U$ |  |

SPIE-Serial Peripheral Interrupt Enable
$0=$ SPIF interrupts disabled
$1=$ SPI interrupt if SPIF = 1
SPE-Serial Peripheral System Enable
$0=$ SPI system off
$1=$ SPI system on
MSTR-Master Mode Select
0 = Slave mode
1 = Master mode
 ss

INTERNAL STROBE FOR DATA CAPTURE (ALL MODES)
Figure 1. Data Clock Timing Diagram

CPOL-Clock Polarity
When the clock polarity bit is cleared and data is not being transferred, a steady state low value is produced at the SCK pin of the master device. Conversely, if this bit is set, the SCK pin will idle high. This bit is also used in conjunction with the clock phase control bit to produce the desired clock-data relationship between master and slave. See Figure 1.

## CPHA - Clock Phase

The clock phase bit, in conjunction with the CPOL bit, controls the clock-data relationship between master and slave. The CPOL bit can be thought of as simply inserting an inverter in series with the SCK line. The CPHA bit selects one of two fundamentally different clocking protocols. When CPHA $=0$, the shift clock is the OR of SCK with $\overline{\mathbf{S S}}$. As soon as $\overline{\mathrm{SS}}$ goes low the transaction begins and the first edge on SCK involves the first data sample. When CPHA $=1$, the $\overline{\mathrm{SS}}$ pin may be thought of as a simple output enable control. Refer to Figure 1.
SPR1 and SPR0-SPI Clock Rate Selects
These two serial peripheral rate bits select one of four baud rates (Table 1) to be used as SCK if the device is a master; however, they have no effect in the slave mode.

Table 1. Serial Peripheral
Rate Selection

| SPR1 | SPR0 | Internal Processor <br> Clock Divide By |
| :---: | :---: | :---: |
| 0 | 0 | 2 |
| 0 | 1 | 4 |
| 1 | 0 | 16 |
| 1 | 1 | 32 |

Data for the SPI is transmitted and received via the Serial Peripheral Data Register (SPDR). A data transfer is initiated by the master writing to its SPDR. If the master is sending data to a slave, it first loads the data into the SPDR and then transfers it to the slave. When reading data, the data bits are gathered in the SPDR and then the complete byte can be accessed by reading the SPDR.

## DEMONSTRATION BOARD DESCRIPTION

A keypad input from the user is used to choose the output display function. The MC68HC05C4 monitors the keypad, decodes any valid inputs, and sends the data to the MC68705R3. If the user has requested a temperature display, the MC68705R3 sends a binary value of temperature in degrees farenheit to the MC68HC05C4, where the value is converted to a celcius binary coded decimal value and returned to the MC68705R3 to be displayed. The LEDs are common anode displays and are driven directly off of port B on the MC68705R3. If the user desires the circuit to function as a real-time clock, a starting time must be entered and transmitted from the MC68HC05C4 to the MC68705R3. Once the clock has been initialized, the MC68705R3 updates the clock every minute. Clock values are stored in memory, and when the circuit is functioning as a thermometer, the values in memory are updated as required to maintain clock accuracy.

## USING THE A/D CONVERTOR TO MONITOR TEMPERATURE

Temperature monitoring is performed by the Motorola MTS102 silicon temperature sensor and the LM358 Dual LowPower Operational Amplifier, as shown in the schematic in

Figure 2. Variations in the base-emitter voltage of the Motorola MTS102 silicon temperature sensor are monitored by the MC68705R3, which converts these analog inputs to equivalent digital values in degrees farenheit. The sensor voltage is buffered, inverted, and amplified by a dual differential amplifier before entering the A/D converter. An amplifier gain of 16 is used, resulting in $\mathbf{2 0 - m i l l i v o l t ~ s t e p s ~ p e r ~ d e g r e e ~ f a r e n h e i t . ~ U s i n g ~}$ a VCC of 5 volts, the maximum differential amplifier output is 3.8 volts, resulting in a temperature sensing range from - 40 degrees to +140 degrees farenheit.

The output from the differential amplifier is connected to the A/D converter on the MC68705R3. A block diagram of the successive approximation A/D converter is shown in Figure 3. Provision is made for four separate external inputs and four internal analog channels.

Two different registers associated with the converter control channel selection, initiate a conversion, and store the result of a completed conversion. Both the external and the internal input channels are chosen by setting the lower 3 bits of the A/D Control Register (ACR). The internal input channels are connected to the $\mathrm{V}_{\mathrm{RH}} / \mathrm{V}_{\mathrm{RL}}$ resistor chain and may be used for calibration purposes.

The converter operates continuously, requiring 30 machine cycles per conversion. Upon completion of a conversion, the digital value of the analog input is placed in the A/D result register (ARR) and the conversion complete flag, bit 7 of the ACR, is set. Another sample of the selected input is taken, and a new conversion is started.
Conversions are performed internally in hardware by a simple bisection algorithm. The D/A converter (DAC) is initially set to $\$ 80$, the midpoint of the available conversion range. This value is compared with the input value and, if the input value is larger, $\$ 80$ becomes the new minimum conversion value and the DAC is once again set to the midpoint of the conversion range, which is now $\$ C 0$. If the input value is less than $\$ 80$, $\$ 80$ becomes the maximum conversion value and the DAC is set to the midpoint of the new conversion range, in this case $\$ 40$. This process is repeated until all eight bits of the conversion are determined.
Quantizing errors are reduced to $+1 / 2$ LSB, rather than $+0,-1$ LSB, through usage of a built-in $1 / 2$ LSB offset. Ignoring errors, the transition between 00 and 01 will occur at $1 / 2$ LSB above the voitage reference low, and the transition between \$FE and \$FF will occur 1-1/2 LSBs below voltage reference high.
The A/D convertor returns a value of $\$ 30$ when given an input of zero degrees farenheit, so $\$ 30$ must be subtracted from the result before converting to celcius. This offset must also be considered when calibrating the sensor. Calibration of the temperature sensor can be performed by adjusting the variable resistor to produce a display of $\$ 00$ after a piece of ice has been placed on the temperature sensor for approximately one minute. A 00 display results from a value of $\$ 50$ in the ARR, so the variable resistor should be adjusted until this value is reached.

## COMMUNICATION CONSIDERATIONS

In this application, an SPI read or write is initiated via an interrupt from the MCU desiring to write data. When any of
the three function keys, display temperature, set time, or display time, are pressed, the MC6BHCO5C4, as master, sends the MC68705R3 an interrupt on the MC68705R3's INT pin. The MC68HCO5C4 writes the key value to its serial peripheral data register, thereby initiating the SPI. It then waits for the SPIF bit to go high and returns to scanning the keypad.

At the same time the MC68HCO5C4 is writing to its SPDR, the MC68705R3 sets a bit counter to eight and waits for the first SCK from the MC68HC05C4. After each clock pulse, the MC68705R3 checks the status of the data bit, sets the carry bit equal to the data bit, and rotates the carry bit left into a result register. The bit counter is decremented, compared to zero, and if not zero, the MC68705R3 waits for the next clock pulse and repeats the cycle.

To ensure proper data transfers, the internal processor clock of the MC68705R3 must be sufficiently faster than the SPI clock of the MC68HCOSC4 to allow the MC68705R3 time to complete this routine before the MC68HCO5C4 can send another bit. This requires the user to first write the code to handle the software SPI, count machine cycles, and then choose MCU oscillator values that allow the additional machine cycles required in a software SPI to be completed before the master can send another clock pulse to the slave.

For example, consider the following piece of code for the MC68705R3, a slave receiving data from the master.

| DATA IN SCK | PORTC pin 5 PORTC pin 4 |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| Cycles | Instruction |  |  |  |
| 2 |  | LDA | \#\$08 |  |
| 5 |  | STA | BITCT | Set bit counter |
| 10 | NXT | BRSET | 4,PORTC,* | Wait for clock transition |
| 10 |  | BRSET | 5,PORTC,STR | Check data status |
| 6 | STR | ROL | RESULT | Store in result |
| 6 |  | DEC | BITCT | Check for end of byte |
| 4 |  | BNE | NXT | Get next bit |
| 43 |  |  |  |  |

Execution of this code requires 43 machine cycles. The maximum oscillator speed for an MC68705R3 is 1 MHz , requiring an SPI clock no greater than $1 / 43 \mathrm{MHz}$. One way of obtaining this rate for the SPI clock is to run the MC68HC05C4 at 0.5 MHz and choose a divide-by 32 to generate the SPI clock.

If the user has selected a temperature display, it is necessary for the MC68705R3, as a slave, to send data to the MC68HC05C4 master. When the MC68705R3 is ready to send data, it interrupts the MC68HCO5C4 via the MC68HCO5C4's IRQ line. The MC68HC05C4 then writes to its serial peripheral data register to initiate the transfer and shifts in data bits sent from the MC68705R3 until the SPIF bit goes high. While the MC68HCO5C4 is writing to its SPDR, the MC68705R3 program is setting a bit counter to 8 . When it detects a clock pulse on the SCK pin, the data register is rotated left one bit, placing the MSB in the carry. The MOSI pin is then set equal to the carry bit, the bit counter is decremented and, if it is greater than zero, the process is repeated.


Figure 2. Serial Peripheral Interface Demonstration Schematic


Figure 3. A/D Block Diagram

## ADDITIONAL USES OF SPI

Many variations of this usage of the SPI are possible. The three possibilities are hardware SPI at both master and slave, software SPI at the master and hardware at the slave, and software SPI at both master and slave. Table 1 shows the various MCUs that have SPI implemented in hardware.

SPI is fairly straightforward in a circuit where both master and slave have hardware SPI capability. In this case, the MCUs are connected as shown in Figure 4. Figure 4a illustrates a single master system, and Figure 4b shows a system where either MCU can be system master. When both master and slave have SPI capability in hardware, data transfers can be handled full duplex. For a single master system, both master and slave write the data to be transferred to their respective serial peripheral data registers. A data transfer is initiated when the master writes to its serial peripheral data register. A slave device can shift data at a maximum rate equal to the CPU clock, so clock values must be chosen that allow the slave to transfer data at a rate equal to the master's transfer rate. In a multiple master system, the master must pull the slave's SS line low prior to writing to its serial peripheral data register and initiating the transfer.

## PROGRAMMING A MASTER FOR SOFTWARE SPI

When the master in an SPI system does not have hardware SPI capabilities, the resulting system is quite different. An SPI system with a master providing the SPI in software is shown in Figure 5. This system only requires two lines between the microcomputers; data and clock. A slave select line can be added for use with multiple slaves. If operated with one data line, the SPI will function half-duplex only. Data is stored in a register, rotated left one bit at a time, and a port pin is set equal to the data bit. The master then provides the serial clock by toggling a different port pin. A bit counter must also be used to count the eight bits in the byte. Bit manipulation instructions are very useful for implementing SPI in software.

One possible software implementation for a write from the master to the slave is shown below.

| DATA OUT SCK | PORTC pin 0 |  |  |
| :---: | :---: | :---: | :---: |
|  |  | LDX \#\$08 | Bit counter |
|  |  | LDA DATA | Put data in register A |
|  | RPT | ROLA | Shift a data bit into carry |
|  |  | BCS SET | Check for a 1 |
|  |  | BCLR O,PORTC | Set data out line to 0 |
|  | CLK | BSET 1,PORTC |  |
|  |  | BCLR 1,PORTC | Toggle clock pin |
|  |  | DECX | Check for end of byte |
|  |  | BNE RPT | If not, repeat |
|  | SET | BSET O,PORTC | Set data out line to 1 |
|  |  | BRA CLK | Go to clock |

Full duplex operation requires a second data line. One port pin is then devoted to data-out and one to date-in. Data transfer from slave to master is accomplished immediately before the SCK pin is toggled. The state of the data-in pin is tested, and the carry is then set equal to the data-in pin. This value is then rotated in to a result register. The modified code is shown below.



Figure 4a. Single Master SPI


Figure 4b. Multiple Master SPI


Figure 5. Software SPI

## PROGRAMMING A SLAVE FOR SOFTWARE SPI

If the slave in the system is a MCU with hardware SPI capability, the data transfer will happen automatically, one bit per clock pulse. If the slave is a MCU that does not have SPI implemented in hardware, a read requires the following actions. A bit counter is set to eight, the slave polls its SCK pin waiting for a clock transition, once it perceives a clock it checks its data-in pin, sets the carry equal to the data and rotates the carry into a results register. One possible code implementation is shown in the previous timing example.
Converting this to full duplex operation requires the addition of a write from slave to master. The slave rolls a data register to place the data bit to be sent into the carry, and the dataout pin is set equal to the carry. These actions occur prior to the read of data from the master. With these modifications, the code looks as shown below.

| DATA OUT | PORTC pin 6 |  |  |
| :---: | :---: | :---: | :---: |
| DATA IN | PORTC pin 5 |  |  |
| SCK | PORTC p |  |  |
|  | LDA | \# ${ }^{\text {0 }}$ |  |
|  | STA | BITCT | Set bit counter |
|  | BRSET | 4,PORTC,* | Wait for clock |
|  | ROL | RES1 | Shift data to send |
|  | BCS | SET1 | Check data status |
|  | BCLR | 6,PORTC | If 0 , clear data out |
|  | BRCLR | 4,PORTC,* | Wait for clock transition |
|  | BRSET | 5,PORTC,STR | Check input data status |
|  | ROL | RESULT | Store in result |
|  | DEC | BITCT | Check for end of byte |
|  | BNE | AGN |  |

## DEBUGGING TIPS

Debugging a circuit containing two microcomputers presents various problems not evident when working with a single microcomputer circuit. The first problem is simultaneously providing emulation for both microcomputers. Once emulation capability is arranged, the designer needs to keep track of the progress of each single-chip, and monitor how the actions of one affects the actions of the other.

One of the easiest methods to debug a circuit of this type is to use two emulator stations, complete with separate terminals. Any emulators can be used, but user confusion is reduced if the emulators have similar commands and syntax. Physical separation also helps reduce confusion. It is somewhat easier to keep track of the concurrent operations if one side of the prototype board is devoted to each single-chip and the majority of peripherals they each must interface with, and the emulator for that microcomputer is placed to that side of the printed circuit board.

Before starting simultaneous debugging, it is best to individually debug the code for each microcomputer wherever possible. Once it becomes necessary for the microcomputers to communicate with one another, halt one of the microcomputers anytime they are not actually talking and work with the remaining microcomputer. As the debugging progresses, keep in mind that an error in the function of one single-chip does not necessarily indicate an error in the corresponding code for that single-chip, but rather, the error may have been caused by an incorrect or unintended transmission from the other single-chip.

Although the aforementioned suggestions reduce debugging problems, some will remain. Long periods of debug can result in an obscuring of the separation of the functions of the two programs. It helps to take periodic breaks to get away from the system and clear the thought processes. Expect to occasionally be confused, be willing to retrace sections of code multiple numbers of times, and the debugging will proceed fairly smoothly.

## CONCLUSION

The Serial Peripheral Interface can be used as a tool to innerconnect to MCU with various other MCUs or peripherals, and can be used with any microcomputer. A special case occurs when one, or more, of the MCUs in a circuit do not have SPI capability in hardware. In this case, a simple software routine can be written to perform the SPI. Used in this manner, the SPI eliminates the need for costly, inconvenient parallel expansion buses and Universal Asynchronous Receiver/Transmitters (UARTs) and simplifies the design effort.



```
** check keypad **
key jsr keypad
    cmp #$Da check for disp. temp
    beq dtmp
    cmp #$De check for set time
    beq 5ttm
    cmp #$Df
    beq dtmp
    cmp #$0b
    beq dtmp
    bra key wait for next input
** display temp **
dtmp belr D,porte send interrupt for spi
    jsr spiwr send byte
    cmp #$0a check for disp. temp.
    beq cir
    bra key
cir cif
    bra key
** set time **
nudig jsr keypad
    cmp #$Da
    beq nudig
    cmp #$0b
    beq nudig look for valid digit
    cmp #$De
    beq nudig
    cmp #$D+
    beq nudig
sttm bcir 0,portc send int. for spi
    jsr spiwr send value
    cmp #$0c check for pm
    beq key yes, wait for next input
    cmp #क\d check for am
    beq key yes, wait for next input
    bra nudig get next time digit
** 5pi write subroutine **
spiwr equ *
    sta spdr put data in data reg.
    brelr 7,5psr,* wait for end of byte
    bset D,parte
5piflg rts done
** spi read subroutine **
spird equ *
    stx spdr initiate transfer
    brcir 7,spsr,* wait for end of byte
rdend rts
```



| 0183 |  |  |  |
| :---: | :---: | :---: | :---: |
| 0184 |  |  |  |
| 0185 |  |  |  |
| 0186 |  |  |  |
| 0187 |  |  |  |
| 0188 |  |  |  |
| 0189 |  |  |  |
| 0190 | 01B7 |  |  |
| 0191 | 01B7 | CD | 01 |
| 0192 | D1BA | B6 | OC |
| 0193 | D1BC | AD | 20 |
| 0194 | D1BE | 24 | 05 |
| 0195 | D1C0 | 40 |  |
| 0196 | D1C1 | AE | DA |
| 0197 | -1C3 | BF | B6 |
| 0198 . |  |  |  |
| 0199 |  |  |  |
| 0200 |  |  |  |
| 0201 |  |  |  |
| 0202 |  |  |  |
| 0203 |  |  |  |
| 0204 | 01C5 | 3 F | B9 |
| 0205 | 01C7 | 3F | B8 |
| 0206 | 01C9 | B7 | B8 |
| 0207 | -1CB | 48 |  |
| 0208 | D1CC | 39 | B9 |
| 0209 | D1CE | 48 |  |
| 0210 | -1CF | 39 | B9 |
| 0211 | 01D1 | BB | B8 |
| 0212 | 0103 | 24 | D2 |
| 0213 | -1D5 | 3C | B9 |
| 0214 | 0107 | 3F | B2 |
| 0215 | 0109 | B7 | B8 |
| 0216 | D1DB | 98 |  |
| 0217 | D1DC | 3C | B2 |
| 0218 | Q1DE | B7 | B8 |
| 0219 | 01E0 | B6 | B9 |
| 0220 | D1E2 | A2 | ロם |
| 0221 | 01E4 | B7 | B9 |
| 0222 | D1E6 | B6 | B8 |
| 0223 | D1E8 | AD | 09 |
| 0224 | D1EA | 24 | FO |
| 0225 | D1EC | 3D | B9 |
| 0226 | D1EE | 26 | EC |
| 0227 |  |  |  |
| 0228 |  |  |  |
| 0229 |  |  |  |
| 0230 |  |  |  |
| 0231 |  |  |  |
| 0232 | D1F0 | $A B$ | 09 |
| 0233 | D1F2 | A1 | 04 |
| 0234 | D1F4 | 22 | 02 |
| 0235 | D1F6 | 3A | B2 |
| 0236 | D1F8 | B6 | B2 |
| 0237 |  |  |  |
| 1238 | D1FA | AE | DB |
| 0239 | D1FC | BF | B7 |
| 0240 |  |  |  |
| 0241 |  |  |  |
| 0242 |  |  |  |
| 0243 |  |  |  |
| 0244 |  |  |  |

```
****** temperature conversion routine ********
*
* farenheit value is received tram 705r3 via
* spi and received in the a register. the value
* is converted to celcius and the leftmost
* led is blanked.
r3int equ *
    jsr spird read value
    Ida spar transter value to register
    sub #$20 subtract 32
    bhs conv if pos. convert
    nega negate
    ldx #$0a
    stx base+2 '-' pattern
*** temperature conversion ***
** a 16-bit multipiy by 5 is pertormed on the
** value received from the r3. this number
**,is then divided by 9.
\begin{tabular}{|c|c|c|}
\hline \multirow[t]{6}{*}{conv} & \[
\begin{aligned}
& c i r ~ m s b \\
& c i r ~ l s b
\end{aligned}
\] & clear counters \\
\hline & \[
\begin{aligned}
& \text { sta lsb } \\
& \text { lsla }
\end{aligned}
\] & multiply by 2 \\
\hline & rol msb & load overtiow into msi \\
\hline & ral msb & load overfiow into mso \\
\hline & add lsb & a contains value \(\times 5\) \\
\hline & bec div ine msb & if overfiow, inc msb \\
\hline div & cir detr & \\
\hline & sta lsb & \\
\hline & cic & \\
\hline \multirow[t]{9}{*}{\(n \times t 9\)} & \[
\begin{aligned}
& \text { ine detr } \\
& \text { sta lsb }
\end{aligned}
\] & \\
\hline & Ida msb & \\
\hline & sbc \#\$00 & subtract borrow from msb \\
\hline & sta msib & \\
\hline & 1da 1sb & count factors of 9 \\
\hline & sub \#\$09 & \\
\hline & bee \(n \times t 9\) & if no borrow, repeat \\
\hline & tst msb & if borrow, check for end \\
\hline & bne nxt9 & repeat if not end \\
\hline
\end{tabular}
*** end of divide, add last 9 back in and
*** check remainder for rounding
    add #$09 find remainder
    Cmp #$04 if greater
    bhi done than 4, round up
    dec detr
done lda detr
pas |dx #$Ob blank pattern
    stx base+3 blank most sig. digit
**** convert binary value to bcd value ****
*
* the x registers begins with the binary value
* and exits with zero. each digit, units, tens
```



0001
0002
0003

$$
0004
$$

0005
00060001
00070002
00080005
00090006
0010 800
00110009
DO12 DODE 0013 DODF 0014
0015
00160040
0017
0018
00190040 00200041 00210042 00220043 00230044 00240045 00250046 00260047 00270048 00280049 0029 004A 0030

## 00310080

0032
0033
0034
00350080
0036008001
003700814 F
0038008212
0039008306
00400084 4C
0041008524
0042008620
00430087 DF
0044008800
00450089 DC
0046 ODEA TE
0047 OOBB 7F
0048 DOBC $7 F$
0049 0080 18
0050
00510090
0052
0053
0054
00550090
00560090 A6 07
00570092 C7 OF 38
00580095 A6 FF
00590097 B7 05
00600099 B7 08
0061 009B B7 4A
$00620090874 B$

```
    nam r3disp
```

********** REGISTER DEFINITION *******

| portb | equ | 1 |
| :--- | :--- | ---: |
| portc | equ | 2 |
| ddrb | equ | 5 |
| ddrc | equ | 6 |
| tdr | equ | 8 |
| ter | equ | 9 |
| acr | equ | 14 |
| arr | equ | 15 |

wrdat rmb 1
timtmp rmb 1
ct $r m b 1$
ct 1 rmb 1
result rmb 1
resi rmb 1
bitet rmb 1
sec $r m b 1$
segmnt $r m b 1$
pm rmb 1
base $r m b 4$
org $\$ 80$

segtab equ *
fcb \% 000000010
fcb \%
feb \%00010010 2
feb \%00000110 3
tab \%ロ1001100 4
fcb \%00100100 5
fcb \% 001000006
feb \%o00011117 7
fcb \% \% ODODOQ 8
feb \% \% OOD1100 9
fab \%01111110 -
feb \%o1111111 blank
feb \% 1 1111111 pm
feb \% $\mathrm{c} 0 \mathrm{O}_{1100} \mathrm{p}$
org $\$ 90$ program start
*** initialize variables ***
start equ*
1da \#\$07
sta $\$+38$ set MOR
lda \#\$t+
sta ddrb set up port b as output
sta tdr set timer for prescale of 128
sta base
sta baset blank time display






0373

| 0374 | 0208 |  |  | tmehs | equ * |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0375 | 020B | 3C | 47 |  | inc sec | increase seconds |
| 0376 | 0200 | 3C | 52 |  | inc base+8 | inc. secs. units |
| 0377 | D20F | B6 | 52 |  | Ida base+8 |  |
| 0378 | D211 | A1 | DA |  | cmp \#\$0a | look for ten |
| 0379 | 0213 | 27 | 38 |  | beq tens | it yes, inc. tens |
| 0380 | 0215 | A6 | 3C | minck | lda \#\$3c | look for a minute |
| 0381 | 0217 | B1 | 47 |  | cmp sec |  |
| 0382 | 0219 | 26 | 54 |  | bne ret1 | wait for next second |
| 0383 | D21B | $3 F$ | 47 |  | clr spe |  |
| 0384 | 0210 | 3F | 53 |  | clr base+9 | zero display |
| 0385 | 021F | B6 | 4A |  | Ida base | check min. units |
| 0386 | 0221 | A1 | 09 |  | cmp \#\$09 | less than 9? |
| 0387 | 0223 | 26 | 20 |  | bne inml | increase |
| 0388 | 0225 | 3F | 4A |  | clr base | min. units $=0$ |
| 0389 | 0227 | B6 | 4B |  | Ida base+1 | check tens of min. |
| 0390 | 0229 | A1 | 05 |  | cmp \#\$05 | less than 5? |
| 0391 | D22B | 26 | 1 C |  | bne inm2 | increase |
| 0392 | 0220 | 3F | 4B |  | clr base+1 | tens of min $=0$ |
| 0393 | D22F | B6 | 4D |  | Ida base+3 | check tens of hrs. |
| 0394 | 0231 | A1 | DB |  | cmp \#\$0b | look for blank |
| 0395 | 0233 | 27 | 1E |  | beq hrek | less than 10:00 |
| 0396 | 0235 | B6 | 4C |  | Ida base+2 | check hrs. units |
| 0397 | 0237 | A1 | D2 |  | cmp \#\$02 | less than 2? |
| 0398 | 0239 | 26 | 2A |  | bne intria | increase |
| 0399 | 023B | A6 | DB |  | Ida \#\$0b |  |
| 0400 | D23D | B7 | 40 |  | sta base+3 | set time to 1:00 |
| 0401 | 023F | A6 | 01 |  | Ida \#\$01 |  |
| 0402 | 0241 | B7 | 4C |  | sta base+2 |  |
| 0403 | 0243 | 20 | 2A |  | bra ret1 | done |
| 0404 | 0245 | 3C | 4 A | inm1 | inc base | increase min. units |
| 0405 | 0247 | 20 | 26 |  | bra ret1 | done |
| 0406 | 0249 | 3C | 4B | inm2 | inc base+1 | increase tens of min. |
| 0407 | D24B | 20 | 22 |  | bra ret1 |  |
| 0408 |  |  |  |  |  |  |
| 0409 | D240 | 3F | 52 | tens | clr base+8 | zero sec. units |
| 0410 | D24F | 3C | 53 |  | inc base+9 | inc sec. tens |
| 0411 | 0251 | 20 | C2 |  | bra minck |  |
| 0412 |  |  |  |  |  |  |
| 0413 |  |  |  | * | increase hours | * |
| 0414 |  |  |  |  |  |  |
| 0415 | 0253 | B6 | 4 C | hrek | Ida base+2 | check hours units |
| 0416 | 0255 | A1 | 09 |  | cmp \#\$09 | less than 9? |
| 0417 | 0257 | 26 | D8 |  | bne inthri | increase |
| 0418 | 0259 | 3F | 4C |  | clr base+2 | hours units $=0$ |
| 0419 | D25B | 3F | 4D |  | clr base+3 |  |
| 0420 | 025D | 3C | 40 |  | inc base+3 | tens of hours $=1$ |
| 0421 | D25F | 20 | DE |  | bra ret1 | done |
| 0422 | 0261 | 3C | 4C | inhr 1 | inc base+2 | increase hours units |
| 0423 | 0263 | 20 | DA |  | bra ret1 | done |
| 0424 | 0265 | 3C | 4C | inhr1a | inc base+2 | increase hours units |
| 0425 | 0267 | B6 | 4C |  | Ida base+2 | check value |
| 0426 | 0269 | A1 | 02 |  | cmp \#\$02 | for 12:00 |
| 0427 | D26B | 26 | 90 |  | bne ret | no, done |
| 0428 | 0260 | 33 | 49 |  | com pm | switch pm indicator |
| 0429 | D26F | A6 | 3B | ret1 | Ida \#\$3b |  |
| 0430 | 0271 | B7 | 42 |  | stact | reset inner loop counter |
| 0431 | 0273 | A6 | 08 |  | Ida \#\$08 |  |
| 0432 | 0275 | B7 | 43 |  | stact1 | reset outer loop counter |
| 0433 | 0277 | 80 |  |  | rti |  |

0435
3436
0437
0438 DFFB
0439
0440 OFFB 01 CB
0441 OFFA 01 3A
0442 DFFC 0090
0443 DFFE 0090


## MC68HC11 EEPROM Programming from a Personal Computer

This application note describes a simple and reliable method of programming either the MC68HC11's internal EEPROM, or EEPROM connected to the MCU's external bus. The data to be programmed is downloaded from any standard personal computer (PC) fitted with a serial communications port. In addition to the programming procedure, the software incorporates the facility to verify the contents of the MCU's internal or external memory against code held on a PC disc. Both program and verify options use data supplied in S record format, which is downloaded from the PC to the MC68HC11 using the RS232 protocol supported by the MCU's SCI port.

The minimum MCU configuration required to program the MC68HC11's internal EEPROM is shown in Figure 1. This consists only of the MCU, an RS232 level shifting circuit, plus an 8 MHz crystal and a few passive components.
To initiate the download, the PC is connected to the MC 68 HC 11 SCl transmit and receive lines via a level shifter. The circuit of Figure 1 uses a Maxim MAX232 to
eliminate the need for additional $\pm 12 \mathrm{~V}$ supplies. The MCU's special bootstrap mode is invoked by applying a logic zero to the MODA and MODB pins, followed by a hardware RESET.
Removing the RESET condition causes the MCU to start execution of its bootloader program, located in internal ROM, between addresses \$BF40 and \$BFFF. In normal single-chip or expanded modes, the boot ROM is not accessible, and reads from these memory locations will result respectively in irrelevant data or external memory fetches.

An additional consequence of bootstrap operation is that all vectors are relocated to the boot ROM area. With the exception of the RESET vector, which points to the start of the boot ROM, the remaining interrupt vectors all point to an uninitialized jump table in RAM. Three bytes are reserved for each entry in the jump table, to allow for an extended jump instruction. Tables 1 and 2 detail the memory map of the bootstrap vectors and an example RAM jump table.


C1, C2, C3, C4 - $22 \mu \mathrm{~F} 25 \mathrm{~V}$ Aluminium or Tantalum
NOTE: To improve reliability of the MCU, all its unused inputs should be connected to $V_{S S}$ or $V_{D D}$

Figure 1. MC68HC11 Bootstrap Mode Connection to RS232 Line

Table 1. Bootstrap Vector Assignments

| Boot ROM |  |  |
| :---: | :---: | :---: |
| Address | Vector | Description |
| BFFE | BF40 | Bootstrap Reset |
| BFFC | OOFD | Clock Monitor |
| BFFA | 00FA | COP Fail |
| BFF8 | 00F7 | Illegal Opcode |
| BFF6 | 00F4 | SWI |
| BFF4 | 00F1 | XIRQ |
| BFF2 | OOEE | IRQ |
| BFFO | 00EB | Real Time Interrupt |
| BFEE | 00E8 | Timer Input Capture 1 |
| BFEC | 00E5 | Timer Input Capture 2 |
| BFEA | 00E2 | Timer Input Capture 3 |
| BFE8 | 00DF | Timer Output Compare 1 |
| BFE6 | 00DC | Timer Output Compare 2 |
| BFE4 | 0009 | Timer Output Compare 3 |
| BFE2 | 00D6 | Timer Output Compare 4 |
| BFEO | 00D3 | Timer Output Compare 5 |
| BFDE | 00D0 | Timer Overflow |
| BFDC | OOCD | Pulse Accumulator Overflow |
| BFDA | 00CA | Pulse Accumulator Input Edge |
| BFD8 | $00 \mathrm{C7}$ | SPI |
| BFD6 | 00 C 4 | SCl |

Table 2. RAM Jump Table

| Internal RAM |  |
| :---: | :--- |
| Address | Typical Instruction |
| OOFD | JMP CLKMON |
| OOFA | JMP COPFL |
| $\ldots$. etc |  |

Note that, before any interrupts are enabled in bootstrap mode, it is the software designer's responsibility to initialize all appropriate entries in the jump table.

As this application note does not make use of the MC68HC11's interrupt system, the jump table is not set up.

The bootstrap program continues by initializing the SCl transmitter and receiver to 7812 baud and proceeds to examine the state of the NOSEC bit in the CONFIG register. If this is at logic zero (security enabled) the bootloader will erase the entire contents of internal EEPROM and also the CONFIG register.

This feature is particularly useful for security conscious applications, where the internal EEPROM contains information of a proprietary or confidential nature. If the NOSEC bit is at logic one, then the erasing sequence is not carried out.

Note also that erasing the CONFIG register disables the security feature.
The bootstrap program then issues a break condition on the SCI transmit line, and waits for the reception of the first byte. In this application, no use is made of the break transmitted by the SCI.
At this point, it is necessary to initiate the PC S record downloader program, called EELOAD.BAS (written in BASIC). It will display a header message, and prompt the user for the number of the COM channel (either one or two) which is connected to the MC68HC11. A listing of EELOAD.BAS is given at the back of this application note.
The PC-resident program will now configure the appropriate COM channel to 1200 baud, one stop bit, no parity, and download the binary file EEPROGIX.BOO from the PC to the MC68HC11.
The MC68HC11's bootloader will automatically detect the fact that the first incoming character is received at a different baud rate, and change its SCI rate to 1200 baud.
It will then proceed to load the binary file into all 256 RAM locations and then jump to address $\$ 0000$ (i.e., the first RAM location).

EEPROGIX.BOO consists of the MC68HC11 executable code shown in the source listing at the back of this application note, with the addition of \$FF at the head of the file, and $\$ 00$ appended up to the 256th byte. This program is designed to receive $S$ records from the PC and program the data fields into the appropriate EEPROM memory locations.

A point to note is that the initial \$FF byte in EEPROGIX.BOO is only used to detect the baud rate of the PC, and is not echoed back, while the remaining 256 bytes are echoed by the MC68HC11's SCI transmitter. However, during download of EEPROGIX.BOO, the PC does not detect the echo, as this feature is unnecessary at this stage.
Once the newly downloaded $S$ record programmer starts execution in the MC68HC11, it configures the SCl to 9600 baud, then waits for a control character from the PC. This character will determine the operating mode of the S record programmer. The options available are shown in Table 3. Note that these programming utilities can be used to load and verify external RAM as well as external EEPROM.

Table 3. S Record Downloader Operating Mode Options

| Control Character | Operating Mode |
| :---: | :--- |
| $X$ | Program External EEPROM RAM |
| 1 | Program Internal EEPROM |
| $V$ | Verify Internal or External EEPROM/RAM |

If the S record programmer has been downloaded successfully, the PC resident program will now -

1. Request whether the downloaded data must be echoed to the screen.
2. Prompt the user for the required operating mode.
3. Request the name of the $S$ record file to be downloaded from the PC.

Once the download starts, every character in the S record file is immediately echoed back to the PC. This ensures synchronism between the PC and the MC68HC11, and at the same time, removes some of the overhead associated with the EEPROM programming delay time. It also removes the need for a hardware handshake.

## VERIFY OPTION

If a verify error occurs, the actual stored byte value is returned to the PC, where it is displayed with a preceding colon delimiter. In this way, EEPROM data and address faults can be quickly identified by inspection. At the end of the verify download, the total number of errors is displayed.

## INTERNAL OR EXTERNAL OPTION

If a programming error occurs in either internal or external programming mode, i.e., if the read back data after programming does not correspond to the expected data, the MC68HC11-resident software will hang up. This condition is detected by the PC-resident program, which will then abort the download and display an error message. This same error message is displayed if a fault or incorrect connection exists on the serial link between the PC and MC68HC11.

There is one exception to this operation. It stems from the fact that changes to the MC68HC11's CONFIG register can only be detected after a subsequent hardware RESET. If the CONFIG register address (\$103F) is detected, then the CONFIG register is not read directly after programming. This prevents premature termination of the download.

To allow programming of the CONFIG register in all mask set versions of the MC68HC11A series, and to permit expanded mode operation, the MCU resident program switches from bootstrap mode to special test mode, by setting the MDA bit (bit 5) in the HPRIO register (address \$103C).

If the user wishes to maintain operation in bootstrap mode, (to verify internal ROM code, for instance), then the 'BSET HPRIO,X,\#MDA' instruction on the 8th line of program code in EEPROGIX.ASC should be removed, and the program reassembled.

## PROGRAMMING INTERNAL EEPROM

The techniques for programming internal and external EEPROM are quite different.

With internal EEPROM, it is first generally necessary to erase the required byte (erased state is \$FF), and follow with a write of data to the same address.

The internal programming sequence involves accessing the PPROG register (address $\$ 103 \mathrm{~B}$ ) to latch the EEPROM address and data buses for the duration that the
programming voltage is applied. Also, the programming time delay must be implemented or initiated by software. In this application, a software timing loop is used, but one of the internal MC68HC11 timer functions could equally well be used to provide the time delay.
Figures 2 and 3 show the flowcharts of the internal EEPROM erase and write sequences.


Figure 2. Internal EEPROM Erase Sequence


Figure 3. Internal EEPROM Write Sequence

## PROGRAMMING EXTERNAL EEPROM

Figure 4 shows the hardware needed to interface the MC68HC11 to an external 2864 EEPROM, which provides a total of 8 K bytes of reprogrammable memory. The ad-
dition of the MC68HC24 gives a minimal component count implementation of a circuit which accurately emulates the MC68HC11A8 single-chip MCU. The added benefit of using the 2864 is that the software designer's program and/or data can be modified without removing the emulator from the target system. This can be particularly useful in applications where the emulator may be enclosed in a confined space or in an environmental chamber.
To program the 2864 from the PC, the external operating mode option ( X ) must be selected from the EELOAD menu.
Programming the 2864 involves fewer operations than are needed for internal EEPROM, as the former has no equivalent of the PPROG control register. In addition, the erase sequence and delay time are handled automatically by the 2864 on-chip logic.
A data polling technique is used to determine the end of the programming delay time. This involves examining the most significant bit of the data programmed, by reading from the address just written to, until the data becomes true. (During the programming delay time, the MS bit will read as the complement of the expected data).
This means that the same software algorithm can be used to download code or data to external RAM as well as external EEPROM.

## EMULATOR ADDRESS DECODING

The emulator circuit in Figure 4 shows the MC68HC11's address line A13 connected to pin 26 of the 2864. Though this pin is actually unused by the 2864, its inclusion permits the replacement of the 2864 with a 2712816 K byte EEPROM memory.
An important outcome of this is that, when a 2864 is used, the memory range \$C000-\$DFFF is mapped over the normally used 8 K byte range of $\$ E 000-\$ F F F F$. In practice, this should never pose a problem. When a 27128 memory is used, its full 16 K byte address range of $\$ C 000-\$ F F F F$ is available to the MCU.
Included in the $S$ record programmer, irrespective of the selected programming mode, is a feature to force program execution at the address specified in the S9, S record address field, provided the address is not $\$ 0000$.
Figure 5 shows the general format of $S$ record files.


Figure 4. MC68HC11A8 Emulator Using 2864 EEPROM


APART FROM THE LETTER S AT THE START, ALL CHARACTERS IN THE RECORDS ARE HEXADECIMAL DIGITS REPRESENTED IN ASCII FORMAT.

CHECKSUM ALGORITHM: LSB OF [Ler $\cdot$ Ldhi + Ldlo $\left.\cdot \sum_{k}^{n} \operatorname{lonte}_{k}\right]$

NOTE: The $S$-record programmer in this application ignores the checksum byte.
Figure 5. S-Record Format

```
10 ' ******* EELOAD.BAS 20/3/87 Version 1.0 *******'
20 'Written by R.Soja, Motorola East Kilbride'
30 ' Motorola Copyright 1987'
40 'This program downloads S record file to the MC68HC11 through special'
50 ' bootstrap program, designed to program either internal or external '
60 ' EEPROM in the 68HC11's memory map'
70 'The loader can also verify memory against an S record file.'
80'Downloaded data is optionally echoed on terminal.'
90 ' ===================================
100 CR$=CHR$(13)
110 MIN$=CHR$(32)
120 MAX$=CHR$(127)
130 ERMS="Can't find "
140 LOADER$="EEPROGIX.BOO"
150 CLRLN$=SPACE$(80)
160 VER$="1.0": 'Version number of EELOAD'
170 ERRTOT%=0: 'Number of errors found by verify operation'
1 8 0 \text { CLS}
190 PRINT " <<<<<<<<< EELOAD Version ";VERS;| >>>>>>>>>"
200 PRINT " <<<<<<<<< 68HC11 Internal/External EEPROM loader/verifier >>>>>>>>"
210 PRINT
220 PRINT "==> Before continuing, ensure 68HC11 is in bootstrap mode,"
230 PRINT " RESET is off, and COM1 or COM2 is connected to the SCI"
240 PRINT
250 ' First make sure loader program is available'
260 ON ERROR GOTO 880
270 OPEN LOADERS FOR INPUT AS #2
280 ClOSE #2
290 ON ERROR GOTO O
300 CHANS="0"
310 ROW=CSRLIN: 'Store current line number'
320 WHILE CHANS<>"1" AND CHAN$<>"2"
330 GOSUB 1070
340 LINE INPUT "Enter COM channel number (1/2):",CHANS
350 WEND
360 CMS="COM"+CHAN$
370 'Now set baud rate to 1200 and load EEPROG through boot loader'
380 ' by executing DOS MODE and COPY commands'
390 SHELL "MODE "+CM$+":1200,N,8,1"
400 SHELL "COPY "+LOADER$+" "+CMS
401 GOSUB }107
402 FOR 1%=1 TO 4:PRINT CLRLN$;:NEXT I%:PRINT: 'Clear DOS commands from screen'
410 ECHOS=" "
420 UHILE ECHO$<>"Y" AND ECHO$<>"N"
430 GOSUB 1070
440 LINE INPUT "DO you want echo to screen (Y/N):",ECHOS
450 WEND
470 ROW=CSRLIN: 'Store current'line number'
480 EEOPT$=" ": 'Initialise option char'
490 WHILE EEOPT$<>"X" AND EEOPT$<>"I" AND EEOPT$<>"V"
500 GOSUB }107
510 LINE INPUT "Select Internal,eXternal or Verify EEPROM option (I/X/V):",EEOPTS
520 WEND
530 OPT$="Verify"
540 IF EEOPT$="I" THEN OPT$="Internal"
550 IF EEOPT$="x" THEN OPT$="External"
560 ROW=CSRLIN: 'Store current line position in case of file error'
570 RXERR=0: 'Initialise number of RX errors allowed'
580 ON ERROR GOTO 910
590 GOSUB }107
```

```
600 IF OPT$="Verify" THEN INPUT "Enter filename to verify: ",F$ ELSE INPUT "Enter filename to download:",F$
6 1 0 \text { CLOSE}
620 OPEN FS FOR INPUT AS #2
630 ON ERROR GOTO O
640'COM1 or 2 connected to SCI on HC11'
650 OPEN CMS+":9600,N,8,1" AS #1
660 'Establish contact with HC11 by sending CR char & waiting for echo'
670 ON ERROR GOTO 860: 'Clear potential RX error'
680 PRINT #1,CR$;
690 GOSUB 990: 'Read char into B$'
700 'Transmit Internal,External or Verify EEPROM option char to 68HC11'
710 PRINT #1,EEOPT$;:GOSUB 990: 'No echo to screen'
720 ON ERROR GOTO 930
730 PRINT "Starting download of <";F$;"> to: ";OPT$;" Eeprom"
72 IF ECHO$="Y" YHEN E%=1 ELSE E%=0
734 IF EEOPT$="V" THEN V%=1 ELSE V%=0
740 WHILE NOT EOF(2)
750 INPUT #2,S$
751 L%=LEN(S$)
752 FOR 1%=1 TO L%
760 PRINT #1,MID$(S$,I%,1);:GOSUB 990:IF E% THEN PRINT B$;
770 IF V% THEN GOSUB 1030:IF C$<>"" THEN PRINT ":";HEX$(ASC(C$));
785 NEXT 1%
787 IF E% THEN PRINT
790 WEND
795 PRINT
800 PRINT "Download Complete"
810 IF V% THEN PRINT ERRTOT%;" error(s) found"
820 CLOSE #2
830 SYSTEM
840 END
```



```
860 IF RXERR>5 THEN 940 ELSE RXERR=RXERR+1:RESUME 610
870 , ....-.-................
880 PRINT:PRINT ERM$;LOADER$:PRINT "Program aborted"
890 GOTO }83
900 '
910 PRINT ERM$;F$;SPACE$(40)
920 RESUME 580
930
940 PRINT:PRINT "Communication breakdown: Download aborted"
950 GOTO }82
960 '.........................
970 '--SUB waits for received character, with time limit'
980 '.- returns with char in B$, or aborts if time limit exceeded'
990 T0%=0:WHILE LOC(1)=0:IF T0%>100 THEN 940 ELSE T0%=T0%+1:WEND
1000 B$=INPUT$(1,#1):RETURN
1010 '...........................
1020 '--SUB waits for received character, with time limit'
1025 %.. returns with char in C$, or null in C$ if time limit exceeded'
1030 T0%=0:C$="":WHILE LOC(1)=0 AND T0%<1:T0%=T0%+1:WEND
1040 IF LOC(1)>0 THEN C$=INPUT$(1,#1):ERRTOT%=ERRTOT%+1
1050 RETURN
1060 '.-.----.-....-.-.-.-.-.-.--'
1070 '--sUB Clear line '
1080 LOCATE ROW,1,1:PRINT CLRLNS
1090 LOCATE ROW,1,1:RETURN
1100 '--.-------------------'
```

| A | ****** |
| :---: | :---: |
| 2 A | EEPROGIX.ASC 19/3/87 Revision 1.0 |
| 3 A | * Uritter by Reja, Motorola, East Kilbride |
| 4 A | * Written by R.Soja, Motorola, East Kilbride |
| 5 A | * Motorola Copyright 1987. |
| 6 A |  |
| 7 A | * This program loads S records from the host to |
| 8 A | * either a 2864 external EEPROM on the $68 \mathrm{HC11}$ external bus, |
| 9 A | * or to the $68 \mathrm{HCl11}$ s internal EEPROM. It can also be used |
| 10 A | * verify memory contents against an S record file or just |
| 11 A | * load Ram located on the 68HC11's external bus. |
| 12 A | * Each byte loaded is echoed back to the host. |
| 13 A | * When programming a 2864, data polling is used to detect |
| 14 A | * completion of the programming cycle. |
| 15 A | * As the host software always waits for the echo before |
| 16 A | * downloading the next byte, host transmission is suspended |
| 17 A | * during the data polling period. |
| 18 A | * Because the serial communication rate ( $\sim 1 \mathrm{~ms} /$ byte) is |
| 19 A | * slower than the 2864 internal timer timeout rate (-300us) |
| 20 A | * page write mode cannot be used. This means that data |
| 21 A | * polling is active on each byte written to the EEPROM, |
| 22 A | * after an initial delay of approx 500us. |
| 23 A |  |
| 24 A | * When the internal EEPROM is programmed, instead of data |
| 25 A | * polling, each byte is verified after programming. |
| 26 A | * In this case, the 500us delay is not required and is |
| 27 A | * bypassed. |
| 28 A | * If a failure occurs, the program effectively hangs up. It |
| 29 A | * is the responsibility of the host downloader program to |
| 30 A | * detect this condition and take remedial action. |
| 31 A | * The BASIC program EELOAD just displays a 'Communication |
| 32 A | * breakdown' message, and terminates the program. |
| 33 A |  |
| 34 A | * When used in the verify mode, apart from the normal echo |
| 35 A | * back of each character, all differences between menory |
| 36 A | * and S record data are also sent back to the host. |
| 37 A | * The host software must be capable of detecting this, and |
| 38 A | * perform the action required. |
| 39 A | * The BASIC loader program EELOAD simply displays the |
| 40 A | * returned erroneous byte adjacent to the expected byte, |
| 41 A | * separated by a colon. |
| 42 A |  |
| 43 A | * Before receiving the S records, a code byte is received |
| 44 A | * from the host. i.e.: |
| 45 A | ASCII ' X ' for external EEPROM |
| 46 A | ASCII ' 1 ' for internal EEPROM |
| 47 A | ASCII 'V' for verify EEPROM |
| 48 A | * |
| 49 A | * This program is designed to be used with the BASIC EELOAD |
| 50 A | * program. |
| 51 A | * Data transfer is through the SCI, configured for 8 data |
| 52 A | * bits, 9600 baud. |
| 53 A |  |
|  | PAGE |



| 113 | A 003A | C139 |  | CMPB | \#'9 |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 114 | A 003C | 26F0 |  | BNE | LOAD |  |
| 115 | A 003E | 805F |  | BSR | RDBYTE | Complete reading 59 record before terminating |
| 116 | A 0040 | 17 |  | TBA |  |  |
| 117 | A 0041 | 8002 |  | SUBA | *2 | \# of bytes to read including checksum. |
| 118 | A 0043 | 8068 |  | BSR | GETADR | Get execution address in $Y$ |
| 119 | A 0045 | 8058 | LOAD9 | BSR | RDBYTE | Now discard remaining bytes, |
| 120 | A 0047 | 4 A |  | DECA |  | including checksum. |
| 121 | A 0048 | 26FB |  | BNE | LOAD9 |  |
| 122 | A 004A | 188 C 0000 |  | CPY | \# | If execution address $=0$ then |
| 123 | A 004E | 27fE |  | BEQ | * | hang up else |
| 124 | A 0050 | 186E00 |  | JMP | , $Y$ | jump to it! |
| 125 | A |  | * |  |  |  |
| 126 | A | 0053 | LOAD1 | EQU | * |  |
| 127 | A 0053 | 804A |  | BSR | RDBYTE | Read byte count of S1 record into ACCB |
| 128 | A 0055 | 17 |  | TBA |  | and store in ACCA |
| 129 | A 0056 | 8003 |  | SUBA | \#3 | Remove load address \& checksum bytes from count |
| 130 | A 0058 | 8056 |  | BSR | GETADR | Get load address into $X$ register. |
| 131 | A 005A | 1809 |  | DEY |  | Adjust it for first time thru' load2 loop. |
| 132 | A 005C | 2017 |  | BRA | LOAD1B |  |
| 133 | A |  | * |  |  |  |
| 134 | A 005E | D600 | LOAD 1A | LDAB | EEOPT | Update CC register |
| 135 | A 0060 | 2825 |  | BMI | VERIFY | If not verifying EEPROM then |
| 136 | A 0062 | 2705 |  | BEQ | DATAPOLL | If programming external EEPROM |
| 137 | A 0064 | C6A6 |  | LDAB | \#uS500 |  |
| 138 | A 0066 | 5A | WAIT 1 | DECB |  | then wait 500uS max. |
| 139 | A 0067 | 26FD |  | BNE | WAITI |  |
| 140 | A 0069 | 18 E 600 | DATAPOLL | LDAB | , Y | Now either wait for completion of programming |
| 141 | A 006C | D803 |  | EORB | <LASTBYTE | cycle by testing MS bit of last data written to |
| 142 | A 006E | D401 |  | ANDB | <MASK | memory or just verify internal programmed data. |
| 143 | A 0070 | 26F7 |  | BNE | DATAPOLL |  |
| 144 | A 0072 | 4A | LOAD1E | DECA |  | When all bytes done, |
| 145 | A 0073 | 2789 |  | BEQ | LOAD | get next $S$ record (discarding checksum) else |
| 146 | A 0075 | 8028 | LOAD1B | BSR | RDBYTE | read next data byte into ACCB. |
| 147 | A 0077 | 1808 |  | INY |  | Advance to next load address |
| 148 | A 0079 | 700000 |  | TST | EEOPT |  |
| 149 | A 007C | 2805 |  | BMI | LOAD 10 | If verifying, then don't program byte! |
| 150 | A 007E | 2743 |  | BEQ | PROG | If internal EEPROM option selected then program |
| 151 | A 0080 | 18 E 700 |  | STAB | ,Y | else just store byte at address. |
| 152 | A 0083 | D703 | LOAD1D | STAB | <LASTBYTE | Save it for DATA POLLING operation. |
| 153 | A 0085 | 2007 |  | BRA | LOADIA |  |
| 154 | A |  | * |  |  |  |
| 155 | A 0087 | 18 E 600 | VERIFY | LDAB | ,Y | If programmed byte |
| 156 | A 008A | D103 |  | CMPB | <LASTBYTE | is correct then |
| 157 | A 008C | $27 E 4$ |  | BEQ | LOADIE | read next byte |
| 158 | A 008E | 8008 |  | BSR | WRITEC | else send bad byte back to host |
| 159 | A 0090 | 20E0 |  | BRA | LOADIE | before reading next byte. |
| 160 | A |  | * |  |  |  |
| 161 | A | 0092 | READC | EQU | * | $A C C A, X, Y$ regs unchanged by this routine. |
| 162 | A 0092 | 1F2E20FC |  | BRCLR | SCSR, X, \#RDRF,* |  |
| 163 | A 0096 | E62F |  | LDAB | SCDR, $X$ | Read next char |
| 164 | A 0098 | 1F2E80FC | WRITEC | BRCLR | SCSR, $X$, \#TDRE,* |  |
| 165 | A 009C | E72F |  | STAB | SCDR, $X$ | and echo it back to host. |
| 166 | A 009E | 39 |  | RTS |  | Return with char in ACCB. |
| 167 | A |  | * |  |  |  |
| 168 | A 009F | 80 F 1 | RDBYTE | BSR | READC | 1st read MS nibble |
| 169 | A 00a 1 | 8017 |  | BSR | HEXBIN | Convert to binary |
| 170 | A 00a3 | 58 |  | LSLB |  | and move to upper nibble |


| 171 | A 0004 |  |  | LSLB |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 172 | a 00a5 | 58 |  | LSLB |  |  |
| 173 | a 00ab | 58 |  | LSLB |  |  |
| 174 | A 00a7 | D702 |  | STAB | <TEMP |  |
| 175 | a 00a9 | $80 E 7$ |  | BSR | READC | Get ASCII char in ACCB |
| 176 | A 00ab | 8000 |  | BSR | HEXBIN |  |
| 177 | a 00ad | DA02 |  | ORAB | <TEMP |  |
| 178 | a 00aF | 39 |  | RTS |  | Return with byte in ACCB |
| 179 | A |  | * |  |  |  |
| 180 | A | 0080 | GETADR | EOU | * |  |
| 181 | A 0080 | 36 |  | PSHA |  | Save byte counter |
| 182 | A 0081 | 80EC |  | BSR | RDByte | Read MS byte of address |
| 183 | A 0083 | 17 |  | TBA |  | and put it in MS byte of ACCD |
| 184 | A 0084 | 80E9 |  | BSR | RDBYTE | Now read LS byte of address into LS byte of ACCD |
| 185 | A 0086 | 188F |  | XGDY |  | Put load address in $Y$ |
| 186 | A 0088 | 32 |  | PULA |  | Restore byte counter |
| 187 | A 0089 | 39 |  | R.TS |  | and return. |
| 188 | A |  | * |  |  |  |
| 17 | A | 00BA | HEXBIN | EQU | * |  |
| 190 | a 00ba | C139 |  | CMPB | \#'9 | If ACCB>9 then assume its A-F |
| 191 | A OOBC | 2302 |  | BLS | HEXNUM |  |
| 192 | A OOBE | CB09 |  | ADDB | \# 9 |  |
| 193 | A OOCO | C40F | HEXNUM | ANDB | * ${ }^{\text {F }}$ F |  |
| 194 | A 00c2 | 39 |  | RTS |  |  |
| 195 | A |  | * |  |  |  |
| 196 | A | 0003 | PROG | EQU | * |  |
| 197 | A 00C3 | 36 |  | PSHA |  | Save ACCA. |
| 198 | A 00C4 | 8616 |  | LDAA | \#\$16 | Default to byte erase mode |
| 199 | A 00C6 | 188C103F |  | CPY | \#CONFIG | If byte's address is CONFIG then use |
| 200 | a 00ca | 2602 |  | BNE | PROGA |  |
| 201 | A OOCC | 8606 |  | LDAA | \# 506 | bulk erase, to allow for A1 \& A8 as well as A2. |
| 202 | A OOCE | 8010 | PROGA | BSR | PROGRAM | Now erase byte, or entire memory + CONFIG. |
| 203 | A 0000 | 8602 |  | LDAA | \#2 |  |
| 204 | A 0002 | 800C |  | 8SR | PROGRAM | Now program byte. |
| 205 | A 0004 | 188C103F |  | CPY | \#CONFIG | If byte was CONFIG register then |
| 206 | A 0008 | 2603 |  | BNE | PROGX |  |
| 207 | A 000 A | 18 E 600 |  | LDAB | , Y | load ACCB with old value, to prevent hangup later. |
| 208 | A 000d | 32 | PROGX | PULA |  | Restore ACCA |
| 209 | A OODE | 2043 |  | BRA | LOAD1D | and return to main bit. |
| 210 | A |  | * |  |  |  |
| 211 | A | OOEO | PROGRAM | EQU | * |  |
| 212 | A OOEO | A738 |  | STAA | PPROG, $X$ | Enable internal addr/data latches. |
| 213 | A 00E2 | 18 E 700 |  | STAB | , Y | Write to required address |
| 214 | A 00E5 | 6C3B |  | INC | PPRROG, X | Enable internal programming voltage |
| 215 | A 00E7 | 3 C |  | PSHX |  |  |
| 216 | A 00E8 | CE0D05 |  | LDX | \#mS 10 | and wait 10 mS |
| 217 | A OOEB | 09 | WAIT2 | DEX |  |  |
| 218 | A OOEC | 26FD |  | BNE | WAIT2 |  |
| 219 | a O0EE | 38 |  | PULX |  |  |
| 220 | A OOEF | 6A38 |  | DEC | PPROG, $X$ | Disable internal programming voltage |
| 221 | A 00F1 | 6F3B |  | CLR | PPROG, $X$ | Release internal addr/data latches |
| 222 | A 00F3 | 39 |  | RTS |  | and return |
| 223 | A |  | * |  |  |  |
| 224 | A |  |  | END |  |  |

SYMBOL TABLE: Total Entries $=41$

| BALD | 002B | PROGA | OOCE |
| :---: | :---: | :---: | :---: |
| CONFIG | 103F | PROGRAM | OOEO |
| DATAPOLL | 0069 | PROGX | 000D |
| EEOPT | 0000 | RDBYTE | 009F |
| GETADR | OOBO | RDRF | 0020 |
| HEXBIN | 008A | READC | 0092 |
| HEXNUM | 00CO | Readopt | 0012 |
| HPRIO | 003C | SCCR 1 | 002C |
| LASTBYTE | 0003 | SCCR2 | 0020 |
| LOAD | 002E | SCDR | 002F |
| LOADI | 0053 | SCSR | 002E |
| LOADIA | 005E | SMOD | 0040 |
| LOAD18 | 0075 | TDRE | 0080 |
| LOAD 10 | 0083 | TEMP | 0002 |
| LOADIE | 0072 | VERIFY | 0087 |
| LOAD9 | 0045 | WAIT1 | 0066 |
| MASK | 0001 | WAIT2 | O0EB |
| MDA | 0020 | WRITEC | 0098 |
| OptVerf | 0027 | mS 10 | 0005 |
| PPROG | 0038 | uS500 | 00A6 |
| PROG | $00 \mathrm{C3}$ |  |  |

# DESIGNING FOR ELECTROMAGNETIC COMPATIBILITY (EMC) WITH HCMOS MICROCONTROLLERS 

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## INTRODUCTION

The operating speed of present HCMOS devices is approaching that of the fastest bipolar logic families of only a few years ago. Associated with this increase in performance are some new design challenges for the MCU-based system designer. This application note addresses one of these issues, the electromagnetic compatibility (EMC) of the finished product. EMC may be considered from either an emission or a susceptibility point of view. Although the following discussion relates primarily to emission control (in particular, radiated emission), most techniques to limit emission also reduce susceptibility. Futhermore, minimizing electromagnetic interference (EMI) will reduce overall system noise, the benefits of which are higher digital noise immunity and accurate operation of local analog subsystems - i.e., better design margin and a more reliable end product.

EMC can only exist when the system functions correctly within the intended electromagnetic environment and does not exceed the EMI levels specified in the appropriate standards documents. EMI, which encompasses interference in a bandwidth of 'dc to daylight' is a generalization of a much older term, radio frequency interference (RFI), which is now defined to encompass 10 kHz to 3 GHz . Failure to consider EMC during early phases of the design process may result in expensive modifications (possibly with many additional components), printed circuit board (PCB) re-layout, product introduction delays, and EMC consultant fees to conform to the required standards.

## LEGAL REQUIREMENTS

The Federal Communications Commission (FCC) have a set of standards to regulate EMI in electronic equipment and systems for use in the United States. Compliance with the appropriate sections of these regulations is mandatory to market or sell a product except for certain subclasses of digital devices that are temporarily exempt. Engineering models (including field-trial prototypes which are not sold) are also exempt; however, the display of a product at an electronics show is considered a marketing function subject to regulations.

FCC rules and regulations (part 15, subpart J of Title 47 of The Federal Regulations) apply to almost all digital devices (see Reference 1), defining standards and operational requirements for all devices capable of emitting RF energy within the range 450 kHz to 1 GHz .

Equipment for use within West Germany must comply with a different set of standards defined and administered by the Verland Deutcher Electro-Techniker (VDE). Digital equipment is generally required to meet both VDE0871 standards. In other countries, compliance to a standard is not always mandatory, however, the European Economic Community (EEC) member states intend to introduce a mandatory RFI performance standard after 1st January 1992. The current proposal is based on International Special Committee on Radio Interference specification CISPR22 and is referred to as European norm EN55022. As the FCC is a member of the CISPR, and has voted in favor of the CISPR22 standard, it is likely that the FCC will utimately adopt the same standards. CISPR22 is somewhat more stringent than FCC part 15, subpart $J$ in the 88 to 230 MHz frequency range, though it is less stringent than some aspects of the VDE0871.

## RFI PROBLEM OVERVIEW

The frequency spectrum of a periodic waveform has been shown, through Fourier analysis, to be composed of discrete frequency components that include the fundamental ( $f 0$ ) and multiple harmonics ( $\mathrm{n} \times f 0$ ). For a typical trapezoidal waveform, the relative amplitude of each frequency component is related to the fundamental frequency, the rise time, and mark-to-space ratio (duty cycle) of the waveform (see Reference 2). Doubling the frequency, halving the rise time, or halving the mark-to-space ratio will double ( +6 dB ) the amplitude of a specific harmonic frequency.

It is possible to graphically predict the harmonic spectrum of a specific trapezoidal waveform by plotting the amplitude of two corner frequencies and a reference 10 dB ) point. This plot is referred to as a Fourier envelope, a Bode plot, or a nomogram. An example is shown in Figure 1 where:

$$
\begin{aligned}
0 \mathrm{~dB} \text { reference } & =20 \log (2 A \bar{\delta}) & & d B \\
f 1 & =1 \pi P & & H z \\
f 2 & =1 \pi t_{r} & & H z
\end{aligned}
$$

where:

$$
\begin{array}{ll}
V=\text { amplitude } & V \\
P=\text { pulse width } & s \\
t_{r}=\text { rise time } & s \\
T=\text { period } & s \\
\delta=\left(P-t_{r}\right) T &
\end{array}
$$

At frequencies beyond $\mathrm{f} 1(1 \pi \mathrm{P})$, the amplitude of the harmonics falls off at -20 $d B$ decade. Above $f 2\left(1 \pi t_{r}\right)$, the amplitude of the harmonics falls off at $-40 \mathrm{~dB} /$ decade. For many applications, these latter harmonics are considered small enough to be ignored; thus, the bandwidth of a system is generally defined to be $1 / \pi t_{r}$. For example, an HCMOS device which can produce an external periodic signal with edge times on the order of 2 ns can generate significant harmonics (i.e., have a bandwidth) of up to 160 MHz . Any PCB tracks, component leads, cables, or connectors attached directly or capacitively to signal sources, such as those previously described, can act as antennas and radiate the harmonics with varying degrees of efficiency. Radiated emission from a system may be either differential-mode or common-mode radiation; common-mode radiation is typically more difficult to reduce.

## DIFFERENTIAL-MODE RADIATION

Differential-mode radiation is caused by the flow of RF current loops around the system conductors. For a small loop area, the far-field electric term, when operating in an field above a ground plane (free space is not a typical environment), can be shown to be approximately (see Reference 3):

$$
\begin{equation*}
E=2.6\left(\mathrm{~A} \mid L f^{2}\right) / \mathrm{R} \quad \mu \mathrm{~V} / \mathrm{m} \tag{1}
\end{equation*}
$$

where:

$$
\begin{aligned}
\mathrm{A} & =\text { loop area } & & \mathrm{cm}^{2} \\
\mathrm{I} & =\text { loop current } & & \mathrm{A} \\
f & =\text { frequency } & & \mathrm{MHz} \\
\mathrm{R} & =\text { distance } & & \mathrm{m}
\end{aligned}
$$


(a) Nomogram

(b) Trapezoidal Waveform

Figure 1. Nomogram of a Trapezoidal Waveform

For a constant current and loop area, the electric field at a prescribed distance is proportional to the square of the frequency (i.e., it increases at $40 \mathrm{~dB} / \mathrm{decade}$ ). Adding this term to the Fourier envelope indicates that the differential-mode radiated emission increases at $20 \mathrm{~dB} /$ decade up to f 2 , after which it remains flat. R is fixed by both the FCC and VDE rules and regulations, and $f$ is usually not a system variable; however, A and IL can be reduced through thoughtful board layout and careful circuit design.

## COMMON-MODE RADIATION

Common-mode (CM) radiation is caused by unintentional voltage drops in a circuit, which cause some grounded parts of the circuit to rise above the real ground potential (see Figure 2). Cables connected to the affected ground act like antennas and radiate the components of the CM potential. The far-field electric term can be shown as follows (see Reference 3):

$$
\begin{equation*}
E \approx\left(f I_{C M} L\right) / R \quad V / m \tag{2}
\end{equation*}
$$

where:

$$
\begin{aligned}
\mathrm{L} & =\text { antenna length } & & \mathrm{m} \\
\mathrm{I} \mathrm{CM} & =\text { common-mode current } & & \mathrm{A} \\
f & =\text { frequency } & & \mathrm{Hz} \\
\mathrm{R} & =\text { distance } & & \mathrm{m}
\end{aligned}
$$

For a constant current and antenna length, the electric field at a prescribed distance is proportional to the frequency (i.e., it increases at $20 \mathrm{~dB} / \mathrm{decade}$ ). Adding this term to the Fourier envelope indicates that the CM radiated emission remains flat up to f 2 , then decreases at $-20 \mathrm{~dB} /$ decade for frequencies above f 2 . Unlike differentialmode radiation, which is relatively easy to reduce through careful product design, CM radiation is more difficult to control since the only variables available to the designer are typically the common path impedances and CM current. Obviously, to eliminate the radiation, the CM current must approach zero, which can be achieved through a sensible grounding scheme and the addition of inductors or capacitors to increase the cable (antenna) impedance.

## SUPPLY DECOUPLING

Inadequate decoupling decreases system noise margins and ultimately leads to incorrect, unreliable, or unstable operation. For example, the MC68HC11A8 can generate peak supply-current transients of approximately 100 mA , which is typical of an HCMOS microcontroller. Although the average supply current is only a few milliamps, the power supply must be able to source the peak supply-current levels

(a) Poor Supply Decoupling

(b) Equivalent Circuit of (a)

Figure 2. PCB Layout
to guarantee correct operation. Also, for fast digital logic, the peak supply-current transients are large enough to create an EMI problem if the decoupling layout is poor.

A decoupling network is used to reduce the supply impedance at the device. To calculate the value of a decoupling capacitor, the acceptable supply ripple must first be determined. An appropriate goal is to achieve a maximum ripple of $20 \%$ of the minimum noise immunity voltage - e.g., for the MC68HC11A8 with $V_{D D}=5 \mathrm{~V}$ and no loads:

$$
\left.\begin{array}{rl}
V_{I L}-V_{O L} & =\left(0.2 \times V_{D D}\right)-0.1
\end{array}=0.9 \mathrm{~V},-V_{\text {DD }}\right)=1.4 \mathrm{~V}
$$

Therefore,

$$
\begin{aligned}
\text { Minimum noise immunity } & =0.9 \mathrm{~V} \\
\text { Maximum ripple }=0.2 \times 0.9 & =180 \mathrm{mV} \\
\text { Transient period } & =10 \mathrm{~ns}
\end{aligned}
$$

Now,

$$
\begin{aligned}
\mathrm{C} & =1 \mathrm{DD} /(\mathrm{dv} / \mathrm{dt}) \\
& =100 \mathrm{~mA} /(180 \mathrm{mV} / 10 \mathrm{~ns}) \\
& =0.006 \mu \mathrm{~F}
\end{aligned}
$$

Rounding up to the nearest preferred value gives $0.01 \mu \mathrm{~F}$. When operating the device in expanded mode, the transient currents generated by bus switching can be significantly larger. Consequently, the recommended decoupling configuration is a $1 \mu \mathrm{~F}$ tantalum in parallel with a high-frequency $0.01 \mu \mathrm{~F}$ multilayer ceramic (or similar) capacitor. The parallel $0.01 \mu \mathrm{~F}$ capacitor extends the upper frequency response of the network which migh otherwise be reduced due to the internal inductance of the $1 \mu \mathrm{~F}$ capacitor. However, with the exception of VLSI devices, decoupling capacitors rarely need to exceed $0.01 \mu \mathrm{~F}$ per device. It is also recommended to bulk decouple the board at the supply-line entry point with a $10-100$ $\mu \mathrm{F}$ capacitor, depending upon the total board-supply requirements. Because it is desirable to prevent unwanted supply noise from going off-board and radiating from the connecting cables, a ferrite bead can be added between the decoupling capacitor and the connector. Care must be taken to ensure that the DC current will not saturate the ferrite, making it ineffective.

For a decoupling network to operate successfully, the impedance between the network and its load must be very low, and, to reduce EMI, its loop area must be as small as possible. Consider the PCB layout of Figure 2(a); the equivalent circuit is shown in Figure 2(b).

For DC current,

$$
\begin{aligned}
V_{\text {drop }} & =(77) \times 0.1 \mathrm{mV} \\
& =7.7 \mathrm{mV}
\end{aligned}
$$

For AC current, assuming 100 mA peak current with a minimum rise time of 10 ns , Total inductance $=89 \mathrm{nH}$

$$
\begin{aligned}
\mathrm{V}_{\text {drop }} & =\mathrm{L} \mathrm{di/dt} \\
& =89 \mathrm{nH}(100 \mathrm{~mA} / 10 \mathrm{~ns}) \\
& =890 \mathrm{mV}
\end{aligned}
$$

A drop of 0.9 V between the decoupling network and the MCU exceeds the maximum acceptable ripple, even if the recommended network is used. As shown in this example, for fast current transients containing many high-frequency components, the circuit inductance is by far the most critical factor when considering decoupling effectiveness.

Parasitic loop impedance can be effectively reduced through the use of thicker PCB tracks, ground/supply planes, and more direct routing. Decoupling networks should be located as close as possible to the device supply pins. Surface-mount capacitors, which have lower inductance than their leaded counterparts, may be used to the full advantage as decouplers if mounted on the noncomponent side of a PCB across a component, which is the closest possible location. Reducing loop impedance also tends to reduce loop area, which has been previously shown (see Equation (1)) to be directly proportional to radiated field strength.

## SELF-RESONANCE

The inductance and capacitance within the decoupling loop, essentially results in a series-resonant tuned circuit where:

$$
\begin{equation*}
\text { resonant frequency, } f=1 / 2 \pi \sqrt{ } \text { LC } \quad H z \tag{3}
\end{equation*}
$$

At frequencies above $\mathbf{f}$, the impedance of the circuit becomes inductive and results in a less effective decoupler. At resonance, $f$, the impedance is purely resistive and at a minimum, which can be used to advantage in solving narrow-band RFI problems by tuning suspect decoupling networks to resonate at the problem frequency. For example, to reduce harmonics in the area of 100 MHz (the FM radio band) for a total loop inductance of 10 nH , equate Equation (3) to 100 MHz and solve for C . In this example, C would equal approximately 250 pF.

## LINE TERMINATION

A signal will propagate down a PCB track at approximately 0.6 the speed of light ( 0.6 ft ns ) until it reaches a load. If the line is unterminated (e.g., a high-impedance input), then the degree of impedance mismatch between the load and the line will cause a proportional amount of the signal to be reflected back down the line toward the source. These reflections can induce ringing and overshoot, causing significant EMI problems. If the load equals the characteristic impedance of the line, $\mathrm{Z}_{0}$, then from viewpoint of the line, the load looks like an infinite line and nothing will be reflected.

In the case of a mismatched line, if the source-signal rise time is sufficiently slow with respect to the line propagation time, then the reflections will be absorbed by the source during the signal rise time. In all other cases, the line should be treated as a transmission line and terminated accordingly (see Reference 3). As a general guide, there should be no need to terminate a line if the one-way propagation delay of a line is less than one-fourth of the signal rise time. For example, for HCMOS with a rise time of 10 ns , the maximum unterminated line length can be estimated as follows:

$$
\begin{aligned}
& \mathrm{t} \text { delay }<0.25 \times 10 \mathrm{~ns} \\
& <2.5 \mathrm{~ns} \\
& \text { length }<\text { velocity } \times \text { t delay } \\
& <0.6 \times 2.5 \\
& <1.5 \mathrm{ft}
\end{aligned}
$$

Therefore, for the majority of cases, termination will not be necessary when using HCMOS devices. Applying the same criteria to Schottky TTL, which has rise times on the order of 3 ns , provides a maximum length of 5.5 in .

## FERRITE BEADS

Ferrite beads have excellent high-frequency characteristics and are especially effective in damping high-frequency switching transients or parasitic ringing due to line reflections. Their low impedance (usually below $100 \Omega$ ) makes them particularly suitable to filter out supply noise above approximately 1 MHz , preventing the noise from going off-board or into another circuit. However, care must be taken to ensure that the DC current does not saturate the ferrite if it is to be an effective filter. Ferrites having a variety of characteristics are available in many different packages, including surface mount.

## GROUNDING TECHNIQUES

A ground is supposed to be an equipotential point or plane used as a reference potential within a system. In reality, this is untrue due to inevitable parasitic inductance and high ground currents causing significant voltage drops, which can result in common-mode radiation problems. To design a successful grounding scheme, the designer must be aware of the paths that ground currents will take to identify possible common-mode impedance problems, reduce loop areas, and prevent noisy return currents from interfering with low-level circuits.

Signal grounds can be classified as single-point, multipoint, or hybrid grounds (see Figure 3). Single-point is acceptable for low frequencies but may have too much impedance at higher frequencies to operate correctly. The ground wire length should be kept as short as possible to reduce inductance and radiating ability. A multipoint ground is used in high-frequency systems, such as digital circuitry, in which each element is connected to the nearest low-impedance ground plane. A hybrid ground looks like a single-point ground at low frequencies and a multipoint ground at high frequencies. A typical system is often a mixture of grounding techniques.

Figure 4 shows a typical MCU application grounding scheme, categorized into lowlevel analog, digital, input/output (I/O) buffer, high-current switching, and hardware grounds. A single-point ground is located at the source of primary power, which is typically the power supply. The on-board digital logic has a multipoint ground, though it is grounded off-board through a single-point ground. To prevent radiation, no high-frequency components of digital return current should be allowed offboard; thus, the board power-supply lines should only carry DC current, which is suitable for single-point grounding. A block diagram, such as the one shown in Figure 4, is a useful starting point for the design of a good grounding scheme.

## ANALOG-DIGITAL MIX

Combining analog and digital circuitry onto a single board requires special attention to PCB layout. Figure 5(a) demonstrates how common-mode impedance ground coupling can superimpose noise on an analog input signal. For example, if the analog section were a 12 -bit A/D converter, the added digital noise would significantly reduce the achievable accuracy of the measurements, possibly by several bits. In Figure 5(a), the analog circuit shares its ground and supply with the noisy digital section and is therefore within the digital supply loop. The PCB tracks are also very thin, increasing the parasitic inductance and voltage drop. A better layout of the board is shown in Figure 5(b) in which the digital supply and ground tracks are substantially wider and the analog circuitry is provided with its own supply and ground reference. Any voltage drop occurring on the digital ground track no longer affects the analog input signal because the digital current no longer passes through the analog input loop.


Figure 3. Grounding Techniques


Figure 4. Typical MCU Application Grounding Example


Figure 5. Analog Circuit Grounding

Adequate supply decoupling is also a prerequisite to minimizing noise in an analog subsystem. With regard to the MC68HC11 on-chip A/D converter, the recommended decoupling network for the analog reference inputs is shown in Figure 6.


Figure 6. Recommended A/D Reference Voltage Decoupling for the MC68HC11

## I/O CABLES AND SHIELDING

Providing a low-noise ground for I/O enables I/O shunt filters to be used to remove common-mode voltages from I/O cables that extend beyond the enclosure (see Figure 4). In addition, externally shielding I/O cables is ineffective if the termination grounds are themselves noisy. Alternatively, an inductor (choke) may also be used to increase I/O cable impedance and reduce radiation.

Generally, the shield surrounding low-frequency signals should be grounded at one end, and that for high-frequency signals, at both ends. For example, in Figure 4 where the analog section is grounded, an input cable shield would only be grounded at the analog circuitry end. Shielded cables carrying digital signals (e.g., MC68HC11 SCl data) should be grounded at both ends to ensure that the shield be as close as possible to ground potential throughout its length. If this configuration is not practical, the next best configuration is to ground only the signal source end of the shield. Caution, grounding at both ends of a long cable can cause large powerfrequency ground-loop currents to flow due to potential differences between the shield grounding points. This problem can also be removed through filtering or the addition of a common-mode choke or balun (see Reference 3).

## PCB LAYOUT GUIDELINES

A successful EMI design starts with good board design. As discussed earlier, the two criteria of most concern are signal-path inductance and loop area. The inductance of a flat conductor (e.g., a PCB track) above a current-return path is as follows:

$$
\begin{equation*}
L=2 \ln (2 \pi h / w) \quad n H / c m \tag{4}
\end{equation*}
$$

```
where:
    h = height above current-return path
    w = track width
```

Evaluating Equation (4) for a height above a current-return path of 1 mm and a track width of $0.5 \mathrm{~mm}, \mathrm{~L}=5.1 \mathrm{nH} / \mathrm{cm}$. The relationship is logarithmic, so doubling the track width will not halve the inductance, however, it will make a significant difference and is always worth doing. For example, doubling the track width to 1 mm makes $\mathrm{L}=3.7 \mathrm{nH} / \mathrm{cm}$. A track width of 5 mm makes $\mathrm{L}=0.5 \mathrm{nH} / \mathrm{cm}$, which is of the order required for effective decoupling loops and reducing common-mode radiation problems.

Use of a multilayer PCB will provide low-inductance supplies, though at an additional cost. The recommended arrangement is to place the supply and ground planes on the outside, sandwiching the signal lines between them. This arrangement will also provide some shielding. To minimize crosstalk, signals on adjacent layers should be routed perpendicular to each other wherever possible. If a multilayer board is not used, fill all unused area with ground plane; avoid creating ground loops that can cause EMI problems. For example, a ground loop is discovered and subsequently broken with a small gap. This technique is acceptable at DC, but at high frequencies the gap capacitance may effectively close the loop and create a large loop antenna. Apart from the radiation problems, large ground loops can also make a system more susceptible to malfunction when subjected to an electrostatic discharge (e.g., through a membrane keypad) or other external EMI source.

Reducing loop area through decoupling and careful layout will reduce RFI. The smaller footprint of surface-mount components can be used advantageously in reducing loop area. For PCBs without a ground plane, signal lines should ideally have a ground-return path as close as possible to them to minimize loop area. In the case of address/data lines, this arrangement may be impractical; thus, routing at least one ground-return track adjacent to each of the eight lines and keeping the lines as short as possible is a good compromise. For the address lines, route the ground return next to A0 (in the case of a word-sized bus, A1), since this line is likely to be the most active. Ground and supply loops with long or thin tracks can
be easily identified by tracing them on a printed copy of the PCB artwork using colored marker pens. As previously mentioned, any unused area should be filled with ground plane.

The system clock is often a primary source of radiation. The clock components should be closely grouped, and all clock lines should be as short as possible and have adjacent ground tracks or ground plane. To avoid crosstalk contamination and subsequent radiation problems, the clock circuitry should be located away or shielded from any I/O signal lines or circuitry. For example, mixing clock and I/O buffers in one package is not good practice.

Another source of RFI is an abrupt change of direction of a PCB track which effectively look like impedance discontinuities and will radiate accordingly. For HCMOS designs, it is important to ensure that 90 -degree track-direction changes do not occur (see Figure 7).

(a) Incorrect


Figure 7. Incorrect (a) and Correct (b) PCB Track Layout for HCMOS Designs

Finally, all unused inputs to HCMOS devices should be terminated to prevent unintentional random switching and noise generation. Also, unterminated CMOS inputs tend to self-bias into the linear region of operation, which can significantly increase DC current drawn. They are also more susceptible to electrostratic discharge damage.

## SIMPLE RFI DIAGNOSTIC TOOL

An article (reprinted by permission of EMC Technology magazine, Reference 5) detailing the construction of a set of RFI diagnostic tweezers is included with this application note. After applying the previously discussed techniques to attain EMC, if a radiated EMI problem exists, this simple tool may be used to speed up the identification of potential problem areas on a PCB.

## CONCLUSION

EMI control has left the specialized realms of electronic design (e.g., military) and is rapidly becoming an industry-wide phenomenon. Although the application of good system design will alway be a prerequisite to achieving EMC, it is reasonable to suppose that similar design concepts could also be applied to the source of most of the radiation, the VLSI HCMOS device. To respond to these and other customer demands for higher performance machines, Motorola is investigating new system and circuit design, layout, and alternative packaging techniques. This research may help to reduce the likelihood of problematic RFI when using HCMOS MCU devices; however, the user's awareness and understanding of the problem will remain the most vital step towards product EMC.

## REVIEW OF KEY POINTS

Differential-mode radiation features are as follows:

1. The system clock is often the primary source of radiation. Avoid ground loops and long tracks (always take the most direct route). Wherever possible, clock tracks (or any other signal) should have adjacent ground-return tracks. Minimize the number of devices requiring the system clock. Ensure that clock circuitry and associated lines are located well away or shielded from PCB I/O tracks or circuitry. Never mix clock and bus or I/O drivers in the same package - use separate buffer drivers for clock and buses.
2. Ensure that decoupling capacitors are as close as possible to the device supply pins to reduce the loop area through the capacitor. Always parallel decouple large-value (DC ballast) capacitors with one or more smaller high-frequency capacitors (check their equivalent series inductance (ESL) and maximum frequency rating).
3. In addition to local device decoupling, decouple the power supply where it enters the PCB. A ferrite bead (e.g., $\mathrm{Z}>50 \Omega$ at 100 MHz ) will also help prevent switching transients from going off-board.
4. For PCBs without a ground plane, minimize address/data line loop areas by routing a minimum of one ground-return track adjacent to each of the eight lines and by keeping the lines as short as possible. For the address lines, route the ground return next to A0 because this line is likely to be the most active. Note also that long address lines will ring, which is another potential source of RFI. These lines may need to be individually terminated (see Reference 4). Operating an MCU in single-chip mode will almost eliminate radiation from address/data lines (still exists internally, of course).
5. Avoid ground loops. Remember that breaking a loop with a small gap may be fine at DC but gap capacitance may effectively close the loop at RF frequencies, creating a large loop antenna. Apart from the radiation problems, large ground loops can make a system more susceptible to malfunction when subjected to external EMI sources.
6. Using a printed copy of the PCB artwork and a marker pen, trace the ground and supply tracks. Long, thin, or looped tracks can then be easily identified and subsequently modified.
7. Terminate all unused inputs to prevent unintentional random switching and noise generation (in addition, unterminated CMOS inputs tend to self-bias into the linear region of operation, significantly increasing the DC current drawn).
8. The smaller footprint of surface-mount components may be used advantageously to reduce loop areas.

Common-mode radiation features are as follows:

1. Ensure a good ground plane and choose the external ground connection to minimize the overall common-mode voltage drop (see Reference 4). Increase both supply and return-supply track widths (as a general rule, cover as much as possible of the unused part of a PCB).
2. A grounding scheme that isolates digital and I/O (including any analog sections) reduces radiation from $1 / O$ cables. Shielding these cables is ineffective if the shield termination grounds are noisy. In digital systems, the shield should be connected to noise-free grounds at both ends. If this configuration is not possible, then ground only the source end.
3. A choke may be effective in reducing the radiation from an $1 / 0$ cable. Also available are a variety of other passive RFI filter elements which shunt the common-mode current to ground. The effectiveness of these devices will depend upon the condition of the shunt ground.

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# EMI/RFI Dicignostic Tweezer Probes: A Construction Article 

## by Frank Moriarty General DataComm, Inc. Middlebury, CT O6762

The RF bypassing tweezer probes described in this article will give their users the ability to quickly and conveniently locate EMI trouble spots at which a permanent suppression component would likely lower the overall EMI. Equally important, these probes will quickly eliminate those circuit points at which a permanent bypassing fix would not be effective. Though simple (isolated tweezer blades spanned with a capacitive element), their effectiveness greatly reduces EMI troubleshooting time.
This article includes three different models of the basic idea, i.e., a fixed, broadband, non-tuning probe; a tunable model; and a bandswitching (three bands) model. The practical performance of each probe was initially tested in both active square wave and coaxial sine wave test circuits. Also, these probes have been used for several years in "on the job" RF suppression work. The time saved has been priceless, and head scratching is held to a minimum. I am sure that the tweezer probe will also become an indispensable suppression tool in your bag of EMI tricks.

While the usefulness of these probes is perhaps priceless, the material count and cost will be extremely low-under $\$ 5.00$-as shown in Table 1. These probes are also available pre-built.
To help in choosing which probe would be best suited to your particular situation, see Table 2. It lists the frequency bandwidths and average attenuation for each of the three types of probes investigated. The Table 2 data was derived from comparing sine wave ( $50 \Omega$ coaxial) and active circuit probe frequency/attenuation signatures, and it reflects the most conservative data produced from these two test methods. The active circuit chosen, a 5.376 MHz ,

Table 1-Parts List

| Qty. | Item | Vendor | Part \# | Cost |
| :---: | :---: | :---: | :---: | :---: |
| 1 ea | Tweezers | ** | 7948 | \$1.97 |
| A/R | Epoxy, shrink tubing, ( $3 / 16$ \& $1 / 2^{\prime \prime}$ ). Insulator, Wire | * | N/A | \$0.10 |
|  | GENERAL, (all types) |  |  |  |
|  | Fixed Probes |  |  |  |
| A/R | Capacitors, (Fixed) 220, 47, 2010 pF | *** | $\begin{gathered} \text { C40 } \\ \text { series } \end{gathered}$ | \$0.43 |
|  | Tunable Probe |  |  |  |
| 1 | Tuning Capacitor ( 25 tp 150 pF ) | ARCO | Arco 424 | \$1.20 |
|  | Bandswitching Probe |  |  |  |
| 1 | Toggle Switch, SPDT, Center Off | * | Any | \$1.95 |
| 1 | Capacitor 220, 39, 20 pF | *** | $\begin{gathered} \text { C40 } \\ \text { series } \end{gathered}$ | \$0.43 |

TTL, square-wave hybrid oscillator, produced an output rich in harmonics. The controlled impedance data (sinewave, $50 \Omega$ coaxial) was, of course, much more predictable. Though different circuits will produce different data, it is felt that Table 2 can be considered a general guide in probe frequency selection and can also be used as an aid in bypass selection.

The base for either of these RF bypassing probes is a simple pair of special tweezers. Tweezers enable quick, one-hand, firm mechanical connection to circuit points. They can be spread to reach circuit points as much as 9 cm ( 3.5 in ) apart, which will cover most applications. Longer tweezers could be substituted for greater spans; however, the increased blade inductance would have to be taken into consideration as the bandwidth parameters would change. The tweezer blades' inherent low impedance over the frequency range tested ( 82 nH average) is low enough for them to be of practical use in this application, over the frequency range covered in this article. Figure 1 illustrates the tweezer assembly, and Fig. 2 is a photo of a completed assembly.

## General Construction Stops

1. The first problem is to split a pair of tweezer blades into two halves. High-quality, spot-welded tweezers are very difficult to split. The lower-quality type, listed in the Table 2 parts list, are very easy to split as they are the unwelded, single-piece, foldover type. These are quite adequate for this application. If you choose to split the high-quality variety, I recommend drilling

Table 2-Tweezer Performance Chart

| Probe Type | Bypass Element | Span in MHz | Bandwidth in MHz | Average Atten.,dB |
| :---: | :---: | :---: | :---: | :---: |
| Fixed | 220 pF | 31-85 | 54 | 17 |
| Fixed | 47 pF | 70-129 | 59 | 13 |
| Fixed | 20 pF | 108-150 | 42 | 11 |
| Fixed | 10 pF | $140 \cdot 220$ | 80 | 11 |
| Band-Switching (Low Band) | 220 pF | 27-71 | 44 | 12 |
| Bandswitching (Mid Band) | 39 pF | 68-120 | 52 | 12 |
| Bandswitching (High Band) | 20 pF | $105 \cdot 140$ | 35 | 11 |
| Tuning | 25/150 pF | 30-140 | 110 | 14 |
| SUMMARY |  |  |  |  |
| Probe <br> Fixed | $\begin{gathered} \text { Best BW } \\ \text { in } \mathrm{MHz}^{* *} \\ \mathrm{X} \\ \hline \end{gathered}$ | Best Atten. in dB | Highest Freq. X | Most * Convenient |
| Bandsw. |  |  |  | X |
| Tuning |  | X |  |  |

* Based on 30 to 140 MHz Span
** Evaluation based on a set of four fixed probes.
NOTE: Tweezer parameters derived from sine, and TTL square wave test circuits, (worst case listed), and ar subject to variations from circuit to circuit.
out the spot welds first. After splitting the blades, you may want to shape the tips on a grinding stone. For getting between narrow chip pins, these tips should be thin. Sharp points are also helpful for good probe contact.

2. The next task will be to electrically isolate each tweezer blade from the other and then to bond the two blades together. Sandwich a piece of thin insulator (a piece of wooden ice cream stick 25 mm [ 1 in ] long will suffice) at the upper portion of and between the tweezer halves as shown in Fig. 1. Secure the assembly with alligator clips or shrink tubing. Be sure to keep the tweezer tips parallel. Cover the top $3 \mathrm{~mm}(0.125 \mathrm{in})$ portion of the assembly with a small piece of shrink tubing so that you will have an epoxy-free area for soldering the capacitor later on.
3. Liberally coat all sides of the top 33 mm ( 1.3 in ) of your assembly with a generous amount of epoxy. Allow 24 hours hardening time to ensure a good set.
4. Choose the assembly you wish to build; i.e., fixed, tunable or band-switching probe per Table 2. Each probe type has its advantages and disadvantages in bandwidth covered, attenuation characteristics and convenience. The chief advantage of the band-switching and fixed probes are their non-tuning convenience. The chief disadvantage of the fixed probes is the need to have more than one probe to cover a wider frequency range. On the other hand, the tunable probe covers a wide range of frequencies but requires tuning. Overall, the band-switching probe offers the most convenience with a slight loss in attenuation capability. Personally, I have made good use of all three types. Your situation, bandwidth of interest, etc. will be major factors in this decision.

If you choose to build the single-element probe and, depending on the frequency range you wish to cover, you may want to build three or more with different capacitive elements to cover a wider frequency range. Please note that there is an upper frequency limit in the practicality of any of these probes, as covered later in this article.

## Fixed-Elomont Probe, Final Assombly

1. Referring to Fig. 1 as a general guideline, choose the capacitor element you wish to solder to the tweezer blades. Note that the upper frequency limit is roughly 300 MHz here, due to hand capacitance, the basic tweezer capacitance of 10 pF average and the tweezer blades' inductance of 82 nH average. The author limited testing and use to 220 MHz .


Figure 1-Tweezer Assembly (Typical)


Figure 2-(Bandswitching Probe Shown)


Figure 3-Electro-Flux


Figure 4-Probe Testing Setup
2. Solder the capacitor across the top of each of the tweezer halves as in Fig. 1. Keep capacitor lead lengths short and use heat sinks on them.

Note: Soldering to stainless steel tweezers requires a special flux. I tried several fluxes, including ammonia, with no success. If you do not have the proper flux available, then try a method I call "electro flux." Figure 3 shows a schematic for the electrical part of this method. With this hookup, alternately charge and then discharge the large electrolytic capacitor, through a length of solder, to the top left corners of each tweezer half. The arcing between the solder element and the tweezer will eventually cause a solder buildup at this point. This buildup will not be readily obvious, but it will be quite adequate when tinned. For tinning, use a good electronic grade of rosin core solder. A paste flux would also aid in this tinning.
3. Decide on the desired spread of the tweezer blades. For instance, if the largest spread you will require is for a 40 -pin chip, then spread your tweezer blades equally for a 50 mm ( 2 in ) gap. Caution: when bending the tweezer blades, avoid putting excessive stress on the epoxy bond.
4. Finish off the probe with shrink tubing on each blade and on the top portion of the tweezer assembly to help reduce hand capacitance effects and possible PC card shorts (should you happen to drop the probe into a circuit card). Note: this top covering could be of a removable type which would enable the removal and soldering of different capacitors for experimental purposes or to avoid building two or more probes to cover wider frequency ranges.

## Testing Your Probe

1. Make the $50 \Omega$ coaxial test setup shown in Fig. 4.
2. Connect your probe across the open end of the coaxial "Tee" connector.
3. Your readings, being in a controlled impedarce test circuit, will only approximate the data listed in Table 2, which was derived by comparing data from differing circuits and indicates the worst-case effects of that comparison.
4. Of course, if you are testing the tunable probe, you will have to tune for each frequency being tested to get maximum attenuation.

## Use of the Single-Element Probe

As a typical use of the probe would be in chasing down radiated EMI signals, the following will cover that aspect of its use. Adjustments can be made for other situations.

## Caution: Do not use these probes in circuits containing voltages in excess of $\mathbf{5 0} \mathbf{V d c}$.

1. Begin by tuning in the EMI signal in question. Determine its exact frequency. A schematic analysis of various EMI harmonic frequencies or circuit probing with a "sniffer probe" (see Table 1) will determine the location of suspected circuit points which might be generating the offending frequencies.
2. Assuming a typical radiated test setup using an antenna for a pickup device and a receiver/analyzer to observe the EMI, tune in the EMI signal to be investigated and use your tweezer probe to probe the suspected circuit "hot spots" as determined in step 1, above.

Note: As you are using a bypass device, one blade of the tweezer must be in firm contact with a circuit common point, and the other blade should be in contact with the circuit point under investigation. The best common point is generally the common pin on the chip being probed.

Sheuld probing show little or no decrease in the observed EMI at a particular circuit point, or be seen to increase the EMI at this point, is generally an indication that this circuit point would not yield to a successful, permanent EMI bypass fix. However, the points which indicate a small decrease ( 3 or 4 dB ) may be part of a dual EMI problem, i.e., a circuit which has two or more problem areas. Keep these points in mind if later probing is inconclusive. Such a condition may require two or more permanent fixes. In any event, with experience your probing analysis will keep time-consuming "cut and try" methods to a minimum.

Any circuit point which indicates a moderate or large decrease due to probing should be noted as a likely point for a permanent EMI bypass fix. As will all things, experience will bring more knowledge. As you use your probes more often, you will be able to quickly determine those areas at which a permanent fix would be successful. Also, you will be able to more accurately choose the type and size of fix to use, i.e., a series or bypassing fix. Other types of EMI fixes which might be required, such as shielding or grounding improvements, will also be determined by these methods.

## Tuning Probe

1. Refer to the previous "general construction" and applicable "fixed probe" paragraphs to create a completed tweezer assembly, minus the capacitive element. One exception here would be to apply the shrink tubing on the tweezer blades before joining them. Shrink tubing should stop approximately 25 mm ( 1 in ) from the top of each blade for bonding purposes.

Remove any unneeded mounting parts from the bottom of the variable capacitor so that it wili fit as closely as possible to the tweezer blade. You may also want to consider a clearance hole in the tweezer blades for the bottom of the capacitor's adjustment screw. Be sure the variable capacitor's active parts do not come in contact with either of the tweezer blades.

Solder the variable capacitor to the upper half of the tweezer blades. Solder one element of the variable capacitor directly to a tweezer blade. The other half of the capacitor element will have to be soldered through a short length of wire. Keep this wire as short as possible to hold your usable bandwidth as wide as possible.

It is good practice to have the movable portion of the variable capacitor (rotor) as the circuit ground connection. The rotor part of the tweezer assembly can easily be identified by stripping back a longer piece of the shrink tubing on the tip portion of the rotor's tweezer blade.
2. Carefully epoxy the variable capacitor to a tweezer blade. Be sure not to get epoxy on any of the capacitor's moving parts. Allow ample hardening time, then cover the assembly with shrink tubing. Be sure the shrink tubing allows for free movement of the capacitor's moving paris. The minimum movement of the assembly must allow for three full turns on the variable capacitor's adjustment screw.

## Using the Tuning Probe

1. With your radiated test setup intact, place a "Tee" coaxial adaptor at the input of the receiver/analyzer.
2. Tune in the EMI signal to be investigated.
3. Connect your tuning probe across the open end of the coaxial "Tee" and tune the variable capacitor for a minimum signal as observed on your receiver. For maximum attenuation due to circuit detuning, an optional, additional in-circuit tweak might be desirable.

Note: Resonant tuning begins at approximately 60 MHz and ends around 130 MHz . Frequencies below 50 MHz are probed with the adjusting screw fuily clockwise (tight). Likewise, fre-
quencies above 130 MHz are probed with minimum capacitance (three turns counterclockwise on the adjustment screw). The frequencies from 60 to 130 MHz should be tuned to resonance (minimum amplitude as seen on your receiver/analyzer). Of course, different assemblies will vary somewhat from these parameters.
Your tuning probe is now tuned for optimum attenuation at the EMI frequency under investigation.
4. Refer to the preceding section, "Using the Single-Element Probe", for a guide to probing.

## Bencl-Switching Probe

The band-switching probe was the next obvious step in the evolution of these probes. It performs quite well and is very convenient to use.

1. Proceed with the basic construction steps as outlined in the "general construction" paragraphs, with the exception of leaving an epoxy-free area for mounting the band switch and applying the shrink tubing on the tweezer blades before bonding.
2. Mount, secure and epoxy the band switch to one of the tweezer blades (see Fig. 1). Allow ample hardening time for the epoxy.
3. Referring to Fig. 5, mount the three capacitors as shown and wire the band switch. Use the capacitor leads for wiring, keep lead lengths short and apply heat sinks to the capacitors before soldering. Note that capacitor logic is single capacitor, series, hand series parallel (moving toggle from left to right). This method was chosen to obtain closer overlapping bands and to take advantage of the band switch's terminals for mounting the capacitors.
4. Cover the capacitors and exposed band switch terminals with heat shrink tubing.

## Using the Band-Switching Probe

Use this probe as with the fixed probes, with the exception of the band-switching feature. If wired as shown in Fig. 5 (pictorial view), and if you are using a typical toggle switch, the low band will be with the toggle left of center, the high band will be with the toggle in mid position (off), and the mid band will be with the toggle in the far-right position.

Note: If it is desired to know the actual capacitance involved in a particular fixedprobe effect, simply add 15 pF (residual capacitance of the tweezers when constructed as per Fig. 1) to the probe's capacitive element value. The capacitance of the tuning probe, however, would have to be measured. For the band-switching probe, being series and series parallel wired, add the 15 pF to the following:

Low band, 220 pF
Mid band, 47 pF
High band, 19 pF
This information is useful when looking for a minimum capacitance for a permanent bypass fix when working with a circuit which cannot drive a large capacitance without unacceptable distortion of the wave shape. $\Omega$


Figure 5-Bandswitching Wiring

[^0] ordering information, contact F\&M Electronics, 41 Chestnut St., Seymour, CT 06483, (203) 888-4847.

# AN1055 

## M6805 16-Bit Support Macros

If your microcontroller (MCU) application requires a small amount of program memory and not much raw computing power, the M6805 MCU Family is a most logical choice, given their low cost. But do not cross the M6805 Family off your selection list just because you need some 16-bit indexing and/or 16-bit operations, such as the higher cost M68HC11 Family provides. While the 8 -bit X index register of the M6805 Family cannot access the entire M6805 12/13-bit address space and its single 8 -bit accumulator cannot directly do 16-bit operations, advanced software techniques can be employed to work around the limitations of the M6805 Family. This application note gives specific details and examples of these techniques.
The code samples given here are available in source code form on the Motorola FREEWARE Bulletin Board Service (BBS), by telephoning 512/891-FREE (512/891-3733). The FREEWARE line operates continuously (except for maintenance) at 300-2400 baud, 8 data bits, 1 stop bit, and no parity. Sample test files are also included. Download the archive file, MACROS05.ARC, to get all the files. All files are suitable for use with the Motorola Development Systems M6805 Portable Assembler for MS-DOS, known as PASM05. Other assemblers may also be supported, but consult the BBS for details.

The techniques used here involve a combination of macros and RAM-based subroutines which use instruction modification. Macros allow programming on a higher level of thought with less chance for introducing errors.

Instruction modification is a technique of altering an instruction just prior to its execution. The modification requires that the instruction be in RAM and can involve the opcode and/or the operand portion of the instruction. By determining the exact instruction/operand needed in advance of execution, greater efficiency in execution speed and code size can be obtained. There is a significant risk in using the instruction modification technique because if used improperly, the program will either fail to work properly at best, or crash at worst. When the technique is used, great care must be exercised to ensure correct operation in all possible cases.

To illustrate the instruction modification technique, consider the following instruction at location $\$ 0050$ in RAM memory.
0050 C6 04FF LDA $\$ 4 \mathrm{FF}$

The LDA instruction consists of three bytes: an opcode byte (\$C6) and two bytes that hold the extended address (\$04FF) of the operand. When executed, the A accumulator will be loaded with the contents of location \$04FF. Now consider what happens when the following instructions at location $\$ 870$ are executed and ho the previous memory locations are changed.

| 0870 | A6 | 05 | LDA | \#\$05 |
| :--- | :--- | :--- | :--- | :--- |
| 0872 | B7 | 51 | STA | $\$ 51$ |
| 0874 | A6 | 2C | LDA | $\# \$ 2 C$ |
| 0872 | B7 | 52 | STA | $\$ 52$ |

These instructions store $\$ 05$ into location $\$ 0051$ and $\$ 2 \mathrm{C}$ into location $\$ 0052$, which is the operand address of the opcode byte at location $\$ 0050$. This has the effect of changing the instruction at location $\$ 0050$ to the following.

$$
0050 \text { C6 052C LDA } \$ 52 \mathrm{C}
$$

When location $\$ 0050$ is executed, the A accumulator will now be loaded with the contents of location \$052C, i.e., the instruction at location $\$ 0050$ has been modified! Note that the original source listing will only show "LDA \$4FF", as the instruction is only changed at execution time, not assembly time.

When instruction modification is used in a ROM-based sys tem, the RAM code must be initialized (from the ROM) before being used. This can be as simple as a few LOAD/STORE in:structions for a small routine, or a MOVE BLOCK routine may be required for larger routines.

As with all things of value, there is a price to be paid. The price for using these macros is rather small, namely, 23 bytes ( 16 for RAM subroutines and 7 for local storage) of direct addressing memory, i.e., in the range of $\$ 0-\$ 00 F F$. The macros have a small size/execution speed penalty associated with them that varies from zero to 50 percent, depending on the frequency and type of macros used. An estimated typical cosi for an entire program with moderate macro usage would be in the 5 to 20 percent range. But this is small cost to pay for error-free code generation in areas of the program where speed is not critical. By judicious usage/choice of macros, the cost can be held closer to the 5 percent range.

Part of this cost is associated with the structured code technique of preserving registers and another part is involved witt: setting up the proper condition codes. The rest of the cost is inherent in the fact that M6805 MCUs must do extra work in software to simulate the hardware capabilities built in M68HC11 MCUs. Because these macros have been fine-tuned for size and speed efficiencies. the overhead cost of register preservation is typically 4 bytes and the overhead cost of condition code setting is typically 2 to 4 bytes, per macro invocation. It can be as high as 200 percent, as is the case of the MOV.B macro for extended addressing operands ( 16 versus 8 bytes if no register preservation/condition code initialization is done) or as low as zero percent for direct addressing operands.

The DREG macros have almost no overhead associated with them since the DREG is implemented using the already existing $A$ and $X$ registers. The overhead price for DREG macros is only 2 bytes of local storage (TEMPA\$. TESTA\$). because the RAM subroutines are only needed for XREG and YREG support. The Add and Subtract DREG macros (ADDD. SUBD) have the most overhead because they must save and restore a working register $(A)$. but even this is rather minimal. If only DREG macros are used. it is estimated that the code size could expand from zero to 5 percent over straight assembly language. depending on how many and which type of DREG macros are used.

The XREG and YREG macros have the most overhead. since they are implemented using RAM memory locations. The Load and Store via XREG/YREG macros (LDAXY. STAXY) have the most overhead when nonzero offset values are used ( 26 bytes versus 2 bytes for zero offset. or 1300 percent). Thus. nonzero offset usages should be avoided unless absolutely necessary. There is also some inefficiency associated with internally maintaining two copies of each register. but it actually helps in the overall implementation.

The Increment. Decrement. and Move macros (INC.B. INC.W. DEC.B. DEC.W. MOV.B. MOVE.W. MOVE) have zero to high overhead. The DEC.B and INC.B macros have zero overhead when used with direct addressing operands, while the INC.W and DEC. W macros have high overhead due to setting the proper condition code based on the resultant 16-bit value.

To use these 16 -bit macros. here is a quick summary of the steps involved for use on an IBM-PC with the Development Systems PASM05 macro assembler, which should already have been installed per the instructions supplied with the product. The sample MS-DOS commands are shown in upper case for clarity only (except as noted). as MS-DOS accepts either upper or lower case.

1. Create a new directory for your project and change directory to it as shown below.

## C $>$ MKDIR PROJ C>CD PROJ

2. Download the archive file, MACROS05.ARC, from the Motorola FREEWARE Bulletin Board to your project directory and then de-archive it as shown below. See the FREEWARE bulletin file, archive.bul, for de-archiving information.

## C $\triangle$ PKARC MACROS05.ARC

3. Read the READ.ME file first, and then read the Notes header in the MACROS05.MAC and RAMSBR.INI files. In the MACROS05.MAC file, study the individual macro headers of the macros you intend to use, especially the examples shown.
4. Write your source code using the example shown in the Notes header of the MACROS05.MAC file, as illustrated in Listing 1, lines 1030-1460. If the two ORG statements, lines 1130 and 1180. are not valid for your application's memory map. change them to the appropriate values. Notice especially how the initialization of the RAM subroutines is accomplished by the MOVE macro in line 1200 using the ROM code generated by the INCLUDE statement in line 1400. Or you can expand the BBS EXAMPLE.S fite into your source file by first making a copy of it and then editing the copy as shown below (PE is the IBM Personal Editor command, but you can use any editor you feel comfortable with).

## C>COPY EXAMPLE.S MYFILE.S C $\triangle$ PE MYFILE.S

5. Invoke PASM05 to assemble your new source file as shown below. Because the options for PASM05 are case sensitive, be sure to enter them just as shown.

## C>PASM05 -eq -1 MYFILE.LST MYFILE.S

This produces listing file MYFILE.LST and a COFF relocatable object file MYFILE.O.
6. To produce an absolute S -record object file suitable for programming an EPROM, the COFF relocatable object file must first be linked to an absolute object file (MYFILE.OUT) and then converted to an S-record file (MYFILE.MX), which many commercial EPROM programmers, such as Data I/O, recognize. Enter the commands shown below to create the S-record file.

```
C>PLD -O MYFILE.OUT MYFILE.O
C>UBUILDS MYFILE.OUT
```

Steps 5 and 6 can be simplified by copying and editing the BBS batch file, MAKE1.BAT, in a manner similar to that shown in Step 4, except here we want the new batch file, MAKE.BAT, to process MYFILE instead of TEST1. The resultant MAKE.BAT file should be similar to the text shown below. The two DEL commands at the end are optional, as these files are no longer needed.

```
pasm05 -eq -1 myfile.lst myfile.s
pld -o myfile.out myfile.o
ubuilds myfile.out
del myfile.o
del myfile.out
```

To accomplish Steps 5 and 6, invoke the batch file MAKE.BAT by simply typing its name as shown below. MS-DOS will execute each line of the file as if you had typed it on the keyboard.

C $\triangle$ MAKE
7. Consult your EPROM programmer's user manual for how to load the resultant S-record object file (MYFILE.MX) and program your chosen device.

Because of the length of the source listings involved and because these listings are intended to be self-explanatory, the rest of this discussion will only deal with salient points which might need clarification for the reader. Line numbers have been added at the beginning of each line for identification purposes in this Application Note, i.e., they are not present in the actual source file.
These macros have been written so that any syntax error will result in falling to the end of the macro where the FAIL directive will force a "Macro syntax error detected!" message. Proper usage results in exiting the macro early via the MEXIT directive and thus avoids the FAIL directive at the end
The file header of Listing 1 (lines 20-1800) gives specific details of the macros supported and their general operation and restrictions. Line 1810 defines where a seven byte block of low memory will be allocated for support of these macros (see lines 20430-20490). Line 1830 disables the output listing to avoid repetitious output, while line 19630 re-enables the listing
A lot of conditionals (IFxx) involve testing to see if direct addressing can be used, as it is more efficient (one less byte and one less execution cycle per instruction) than extended addressing, as illustrated by lines 2090-2210. Also, conditionals check to see if shorter instruction forms can be used, like "CLRA" instead of "LDA \#0", as in these same lines. For this same reason, it is most efficient to place the RAM subroutines, and thus the XREG and YREG, into direct addressing space ( $\$ 0000-\$ 00 B F$ ). Remember that the M6805 uses a fixed stack area in direct addressing space of $\$ 00 \mathrm{C} 0-\$ 00 \mathrm{FF}$.
The COMPARE macros (CPD, CPXR, CPYR) use a shortened form when immediate addressing is specified and either
of the halves is zero, i.e., no "CMP \#0" instruction is generated. Lines 3480-3660 are typical of this technique. As always, testing for zero is most efficient in computer architecture.

The 16-BIT INDEXING macros (LDAXY, STAXY) are most efficient when used with a zero offset, as typified in lines 3980-4060, but will function with any sized offset (lines 4070-4210). Nonzero offsets must first be added to the indexing register (XREG or YREG), the operation performed via the appropriate RAM subroutine, and lastly, the indexing register must be restored to its original value.

Lines 19640-20410 comprise the RAM subroutines which are the keystone of the macros using the XREG and YREG pseudo 16 -bit index registers. It is here that the XREG and YREG pseudo-registers are defined and stored as the second and third bytes of extended addressing LDA and STA instructions using EQU directives (lines 19910-19920, 20060-20070. 20210-20220, and 20360-20370). Instructions that store values to XREG or YREG will thus modify the instruction's effective address, hence the name instruction modification. These RAM subroutines must be initialized before they can be used. and so a mirror image of this code with altered labels is provided in the RAMSBR.INI file (as seen in Listing 2). This file can then be simply $\operatorname{NNCLUDED}$ in the ROM section of the user's code and copied to RAM via the MOVE macro, as discussed in lines 19660-19760 of Listing 1.

Listing 2 is the RAM subroutine initialization file and is essentially a copy of the RAM subroutines defined in lines 19640-20410 of Listing 1, but the labels have all been prefixed with a period (.). This allows using the MOVE macro to copy this RAM initialization code from a ROM to RAM (see lines 370-410).
Lines 1070-1090 verify that the number of RAM subroutine initialization bytes is identical.

## Listing 1 - MACROS05.MAC File





```
0 1 8 3 0
01840
0 1 8 7 0
01880 * Examples:
01900
01910 *
01920 *
01930
01940 *
01980 *
01990 * Notes:
02020 LDD MACR
02030 IFEQ NARG-1
02040
02050
02060
02070
02080
02090
02100
02110
02120
02130
02140
02150
02160
02170
02180
02190
02200
02210
02220
02230
02240
02250
02260
02270
02280
0 2 2 9 0
02290 *
02300 *
02310 *
02320
02330 *
02350 *
02360 * Register Usage:
02390
02400 * Notes:
02420 *
02430 STD MACR
02440 STX (\0)+1
02450 STA (\0)
02460 ENDM
02470
```

```
01850 * LDD = load DREG
```

01850 * LDD = load DREG
01860 * LDD [\#,]<address>
01860 * LDD [\#,]<address>

* 1. "LDD \#,START" puts the value of symbol 'START' into
* 1. "LDD \#,START" puts the value of symbol 'START' into
01950 * A,X = loaded with new value (DREG).
01950 * A,X = loaded with new value (DREG).
01960 * CC = reflects MS half (=A).
01960 * CC = reflects MS half (=A).
01970 * All other registers preserved.
01970 * All other registers preserved.
02000 * 1. Byte access order is LS, then MS (reversed from 68HCl1).
02000 * 1. Byte access order is LS, then MS (reversed from 68HCl1).
    * 1."STD START" stores the DREG (=A,X) into locations
    * 1."STD START" stores the DREG (=A,X) into locations
02340 * 'START' and 'START' +1.
02340 * 'START' and 'START' +1.
02370 * CC = reflects MS half (=A).
02370 * CC = reflects MS half (=A).
02380 * All other registers preserved.
02380 * All other registers preserved.
02410 * 1. Byte access order is LS, then MS (reversed from 68HC11).
02410 * 1. Byte access order is LS, then MS (reversed from 68HC11).

```
                            OPT NOL
```

                            OPT NOL
    *****************************************************************************************
*****************************************************************************************

* the DREG (=A,X)
* the DREG (=A,X)
* 2. "LDD START" puts the contents of location 'START'
* 2. "LDD START" puts the contents of location 'START'
* and 'START'+1 into the DREG (=A,X).
* and 'START'+1 into the DREG (=A,X).
* Register Usage:
* Register Usage:
LDX (\0)+1
LDX (\0)+1
LDA (\0)
LDA (\0)
MEXIT
MEXIT
ENDC
ENDC
IFEQ NARG-2
IFEQ NARG-2
IFC '\0', '\#'
IFC '\0', '\#'
IFEQ (\1)!.$FF
              IFEQ (\1)!.$FF
CLRX
CLRX
ENDC
ENDC
IFNE (\1)!.$FF
              IFNE (\1)!.$FF
LDX \#(\1)!.$FF
                  LDX #(\1)!.$FF
ENDC
ENDC
IFEQ (\1)!>8
IFEQ (\1)!>8
CLRA
CLRA
ENDC
ENDC
IFNE (\1)!>8
IFNE (\1)!>8
LDA \#(\1)!>8
LDA \#(\1)!>8
ENDC
ENDC
MEXIT
MEXIT
ENDC
ENDC
ENDC
ENDC
FAIL Macro syntax error detected!
FAIL Macro syntax error detected!
ENDM
ENDM
*****************************************************************************************
*****************************************************************************************
    * STD = store DREG
    * STD = store DREG
    * STD <address>
    * STD <address>
    * 
    * 
    * Examples:
    * Examples:
STD MACR

```
        STD MACR
```


03350
0 3 3 6 0
0 3 3 7 0
0 3 3 8 0
03390
03400
03410
03420
03430
03440
03450
03460
03470
03480
03490
03500
03500
03520
03530
03540
03550
03560
03570
03580
0 3 5 9 0
0 3 6 0 0
03610
0 3 6 2 0
0 3 6 3 0
03640
03650
03660
0 3 6 7 0
0 3 6 8 0
0 3 6 9 0
03120
03130
03140
03150
03160
03170
03180
03190
03200
03210
03220
03230
03240
03250
03260
03270
0 3 2 8 0
03290
0 3 3 0 0
03310
03320
0 3 3 3 0
03340

```
```

```
IFEQ NARG-2
```

```
IFEQ NARG-2
        IFC '\0','#'
        IFC '\0','#'
            STA TEMPA$
            STA TEMPA$
            TXA 
            TXA 
            TAX TDA TEMPAS
            TAX TDA TEMPAS
            LDA TBM #(\1)!>8
            LDA TBM #(\1)!>8
            MEXIT
            MEXIT
        ENDC
        ENDC
    ENDC
    ENDC
            FAIL Macro syntax error detected!
            FAIL Macro syntax error detected!
    ENDM
    ENDM
*******************************************************************************************
*******************************************************************************************
* CPD = compare DREG
* CPD = compare DREG
* CPD [#,]<address>
* CPD [#,]<address>
* Examples:
* Examples:
* 1."CPD #,BLOCKSZ" compares the value of symbol 'BLOCKSZ'
* 1."CPD #,BLOCKSZ" compares the value of symbol 'BLOCKSZ'
* with the DREG (=A,X).
* with the DREG (=A,X).
* 2. "CPD START" compares the contents of location
* 2. "CPD START" compares the contents of location
* 'START' and 'START' +1 with the DREG.
* 'START' and 'START' +1 with the DREG.
```

            SBC #(\1)!>8
    ```
            SBC #(\1)!>8
* Register Usage:
* Register Usage:
* CC = reflects DREG comparison (z-bit only).
* CC = reflects DREG comparison (z-bit only).
* All other registers preserved.
* All other registers preserved.
CPD MACR
CPD MACR
    IFEQ NARG-1
    IFEQ NARG-1
        CPX (\0)+1
        CPX (\0)+1
            BNE \.0
            BNE \.0
            CMP (\0)
            CMP (\0)
\.0 EQU *
\.0 EQU *
            MEXIT
            MEXIT
    ENDC
    ENDC
    IFEQ NARG-2
    IFEQ NARG-2
        IFC '\0','#'
        IFC '\0','#'
            IFEQ (\1)!.$FF
            IFEQ (\1)!.$FF
                tSTX
                tSTX
            ENDC
            ENDC
            IFNE (\1)!.$FF
            IFNE (\1)!.$FF
                CPX #(\1)!.$FF
                CPX #(\1)!.$FF
            ENDC
            ENDC
                BNE \.0
                BNE \.0
            IFEQ (\1)!>8
            IFEQ (\1)!>8
                TSTA
                TSTA
            ENDC
            ENDC
            IFNE (\1)!>8
            IFNE (\1)!>8
                CMP #(\1)!>8
                CMP #(\1)!>8
            ENDC
            ENDC
                EQU *
                EQU *
                MEXIT
                MEXIT
        ENDC
        ENDC
    ENDC
    ENDC
            FAIL Macro syntax error detected!
            FAIL Macro syntax error detected!
            ENDM
```

            ENDM
    ```
```

    03700 ************************************************************************)
    03710 * LDAXY = load A via 16-bit p
03710 * LDAXY = load A via 16-bit ps
03740 *
03750 * Examples:
03760 * 1."LDAXY 0,XREG" loads the contents of the memory location

```


```

* *)
* *)
* *)

```

```

03820 * 4. Above examples can be repeated with substituting YREG for XREG.

# (. Above examples can be repeated

# (. Above examples can be repeated

# (. Above examples can be repeated

# (. Above examples can be repeated

# (. Above examples can be repeated

# (. Above examples can be repeated

# (above examples can be repeated

03910 LDAXY MACR
03920 IFNC '\1', 'XREG'
03930 IFNC '\1', 'YREG'
03940
FAIL Macro syntax error detected!
MEXIT
ENDC
ENDC
IFC '\0',',
JSR LDA\1 Default offset=0
MEXIT
ENDC
IFNC '\0',',
IFEQ \0
JSR LDA\1 Offset=0
MEXIT
ENDC
IFNE \O
LDA \11$+1 Set nREG= offset + nREG
            ADD #(\0)!.SFF
            STA \11$+1
LDA \11\$
ADC \#(\0)!>8
STA \11\$
JSR LDA\1 Offset=0
STA TEMPAS
LDA \12\$ Restore nREG
STA \11\$
LDA \12$+1
            STA \11$+1
LDA TEMPAS
MEXIT
ENDC
ENDC
FAIL Macro syntax error detected!
ENDM
04250
04260
0 3 9 5 0
0 3 9 6 0
03970
03980
03990
04000
04010
04020
04030
04040
04050
04060
04070
04080
04090
04100
04110
04120
04130
04140
04150
04160
04170
04180
04190
04200
04210
04220
04230
04240
*
*

```




```

03820 * ulator.

```

```

03700

```
04310
04320 * Examples:
04400
04410 * Register Usage:
04440 *
04450 STAXY MACR
04460 IFNC '\1', 'XREG'
04490
04500
04510
04520 IFC '\0',',
04530
04540
04550
04560
04570
04580
04590
04600
04610
04620
04630
04640
04650
04660
04670
04680
04690
04700
04710
04720
0 4 7 3 0
04740
04750
04760
04770
04780
0 4 7 9 0
04800
04810
```

```
```

04280 * STAXY = store A via 16-bit pseudo-register (XREG or YREG)

```
```

04280 * STAXY = store A via 16-bit pseudo-register (XREG or YREG)
04290 * STAXY <offset>,XREG
04290 * STAXY <offset>,XREG
04300 * STAXY <offset>, YREG
04300 * STAXY <offset>, YREG
04330 * 1. "STAXY 0,XREG" stores the accumulator (=A) into the memory
04330 * 1. "STAXY 0,XREG" stores the accumulator (=A) into the memory
04340 * location specified by XREG+0.
04340 * location specified by XREG+0.
04350 * 2. "STAXY ,XREG" stores the accumulator ( }=A\mathrm{ () into the memory
04350 * 2. "STAXY ,XREG" stores the accumulator ( }=A\mathrm{ () into the memory
04360 * location specified by XREG+0.
04360 * location specified by XREG+0.
04370 * 3."STAXY TBL,XREG" stores the accumulator (=A) into the memory
04370 * 3."STAXY TBL,XREG" stores the accumulator (=A) into the memory
04380 * specified by XREG+ 'TBL'
04380 * specified by XREG+ 'TBL'
04390 * 4.Above examples can be repeated with substituting YREG for XREG.
04390 * 4.Above examples can be repeated with substituting YREG for XREG.
04420 * CC = reflects value stored.
04420 * CC = reflects value stored.
04430 * All other registers preserved.
04430 * All other registers preserved.
04470 IFNC '\1', 'YREG'
04470 IFNC '\1', 'YREG'
04480 FAIL Macro syntax error detected!
04480 FAIL Macro syntax error detected!

```
*
```

*           MEXIT
          MEXIT
      ENDC
      ENDC
    ENDC
ENDC
JSR STA\1 Default offset=0
JSR STA\1 Default offset=0
MEXIT
MEXIT
ENDC
ENDC
IFNC '\0',',
IFNC '\0',',
IFEQ \0
IFEQ \0
JSR STA\1 Offset=0
JSR STA\1 Offset=0
MEXIT
MEXIT
ENDC
ENDC
IFNE \0
IFNE \0
STA TEMPA\$
STA TEMPA\$
LDA \12$+1 Set nREG= offset + nREG
          LDA \12$+1 Set nREG= offset + nREG
ADD \#(\0)!.SFF
ADD \#(\0)!.SFF
STA \12$+1
          STA \12$+1
LDA \12\$
LDA \12\$
ADC \#(\0)!>8
ADC \#(\0)!>8
STA \12\$
STA \12\$
LDA TEMPAS
LDA TEMPAS
JSR STA\I Offset= 0
JSR STA\I Offset= 0
LDA \11\$ Restore nREG
LDA \11\$ Restore nREG
STA \12\$
STA \12\$
LDA \11$+1
          LDA \11$+1
STA \12$+1
          STA \12$+1
LDA TEMPAS
LDA TEMPAS
MEXIT
MEXIT
ENDC
ENDC
ENDC
ENDC
FAIL Macro syntax error detected!
FAIL Macro syntax error detected!
ENDM

```
                ENDM
```

```
04820 *********************
04840 * LDXR [#,]<address>
04850 *
04860 * Examples:
04870 * 1."LDXR #,START" puts the value of symbol 'START' into the
04880 *
04890 * 2. "LDXR START" puts the contents of location 'START' and
04900 *
04910 *
04920 * Register Usage:
04930 * CC = reflects MS half (=A).
04940 * All other registers preserved.
04950 *
04960 * Notes:
04970 * 1. Byte access order is LS, then MS (reversed from 68HC11).
04980 *
04990 LDXR MACR
05000 IFEQ NARG-1
05010 STA TEMPAS
05020 LDA (\0)+1
05030 STA XREG1$+1
05040 STA XREG2$+1
05050 LDA (\0)
05060 STA XREG1$
05070 STA XREG2$
05080
05090
05100
05110
05120
05130
05140
05150
05160
05170
05180
05190
05200
05210
05220
05230
05240
05250
05260
05270
05280
05290
05300
05310
05320
05330
05340
05350
05360
05370
05380
05390
05400
05410
05420
05430
            STA XREG1$
            IFEQ XREG1$!.$FF00
            LDA TEMPA$
            TST XREG1$
        ENDC
        IFNE XREG1$!.$FF00
            STA TESTAS
            LDA TEMPAS
            TST TESTAS
        ENDC
            MEXIT
        ENDC
        IFEQ NARG-2
            IFC '\0',`#'
            IFEQ XREG1$!.$FF00 ! XREG in low memory?
            IFEQ \1 ! #0 value?
                    CLR XREG1$+1
                    CLR XREG2$+1
                    CLR XREGI$
                    CLR XREG2$
                        MEXIT
            ENDC
            IFNE \1 ! not #O value?
                STA TEMPAS
            IFEQ (\1)!.$FF
                CLR XREG1$+1
                CLR XREG2$+1
            ENDC
            IFNE (\1)!.$FF
                    LDA #(\1)!.$FF
                    STA XREG1$+1
                    STA XREG2$+1
            ENDC
            IFEQ (\1)!>8
                    CLR XREG1$
                    CLR XREG2$
            ENDC
```

```
05440
05450
05460
05470
05480
05490
0 5 5 0 0
05510
05520
05530
05540
05550
05560
05570
0 5 5 8 0
0 5 5 9 0
05600
05610
05620
05630
05640
05650
05660
05670
05680
05690
05700
05710
05720
05730
05740
05750
05760
05770
05780
05790
0 5 8 0 0
05810
05820
05830
05840
05850
05860
05870
05880
05890
05900
05910
05920 ENDC
05940
05950
```

```
05930 FAIL Macro syntax error detected!
```

05930 FAIL Macro syntax error detected!

```
            IFNE (\1)!>8
```

            IFNE (\1)!>8
                LDA #(\1)!>8
                LDA #(\1)!>8
                STA XREG1$
                STA XREG1$
                STA XREG2$
                STA XREG2$
            ENDC
            ENDC
                LDA TEMPA$
                LDA TEMPA$
                TST XREG1$
                TST XREG1$
                MEXIT
                MEXIT
            ENDC
            ENDC
        ENDC
        ENDC
        IFNE XREG1$!.$FF0 ! XREG in high memory?
        IFNE XREG1$!.$FF0 ! XREG in high memory?
            IFEQ \1 ! #O value?
            IFEQ \1 ! #O value?
                STA TEMPAS
                STA TEMPAS
                CLRA
                CLRA
                STA XREG1$+1
                STA XREG1$+1
                STA XREG2$+1
                STA XREG2$+1
                STA XREG1$
                STA XREG1$
                STA XREG2$
                STA XREG2$
                CLR TESTA$
                CLR TESTA$
                LDA TEMPAS
                LDA TEMPAS
                TST TESTA$
                TST TESTA$
                MEXIT
                MEXIT
            ENDC
            ENDC
            IFNE \1 ! not #O value?
            IFNE \1 ! not #O value?
                STA TEMPA$
                STA TEMPA$
            IFEQ (\1)!.$FF
            IFEQ (\1)!.$FF
                CLRA
                CLRA
            ENDC
            ENDC
            IFNE (\I)!.$FF
            IFNE (\I)!.$FF
                LDA #(\1)!.$FF
                LDA #(\1)!.$FF
            ENDC
            ENDC
                STA XREG1$+1
                STA XREG1$+1
                STA XREG2$+1
                STA XREG2$+1
            IFEQ (\1)!>8
            IFEQ (\1)!>8
                CLRA
                CLRA
            ENDC
            ENDC
            IFNE (\1)!>8
            IFNE (\1)!>8
                LDA #(\1)!>8
                LDA #(\1)!>8
            ENDC
            ENDC
                STA XREGI$
                STA XREGI$
                STA XREG2$
                STA XREG2$
                STA TESTAS
                STA TESTAS
                LDA TEMPAS
                LDA TEMPAS
                TST TESTAS
                TST TESTAS
                MEXIT
                MEXIT
            ENDC
            ENDC
        ENDC
        ENDC
    ENDC
    ENDC
    ENDM
    ```
    ENDM
```

```
05970 * STXR = store XREG
05980 * STXR <address>
05990 *
06000 * Examples:
06010 * 1."STXR START" stores the XREG into locations 'START' and
06020 *
06030 *
06040 * Register Usage:
06050 * CC = reflects MS half (=A).
06060 * All other registers preserved.
06070 *
06080 * Notes:
06090 * 1. Byte access order is LS, then MS (reversed from 68HC11).
06100 *
06110 STXR MACR
06120
06130
06140
06150
06160
06170
06180
06190
06200
06210
06220
06230
06240
06250
06260
06270
06280
06290
06300
06310
06320
06340
06360
0 6 3 7 0
06380
06390
06400
06410
06420 *
06430
06440 * Notes:
06450
06460
06470
06480
06490 *
06500 INCXR MACR
06510 IFEQ NARG
06520 IFEQ XREG1$!.$FF00
06530 INC XREG1$+1
06540 INC XREG2$+1
06550 BNE \.0
06560 INC XREG1$
06570 INC XREG2$
06580 \.0 EQU *
06590 MEXIT
06600 ENDC
```

```
06610
06620
06630
06640
06650
06660
06670
06680
06690
06700
06710
06720
0 6 7 3 0
06740
06750
06760
06770
06780
06790
06800
06810
06820
06830
06840
06850
06860
06870
06880
06890
0 6 9 0 0
06910
06920
06930
06940
06950
06960
06970
06980
06990
07000
07010
07020
07030
07040
07050
0 7 0 6 0
07070
0 7 0 8 0
0 7 0 9 0
0 7 1 0 0
0 7 1 1 0
07120
0 7 1 3 0
07140
```

```
    IFNE XREG1$!.$FF00
```

    IFNE XREG1$!.$FF00
        STA TEMPAS
        STA TEMPAS
        LDA XREG1$+1
        LDA XREG1$+1
        ADD #1
        ADD #1
        STA XREG1$+1
        STA XREG1$+1
        STA XREG2$+1
        STA XREG2$+1
        LDA XREG1$
        LDA XREG1$
        ADC #O
        ADC #O
        STA XREG1$
        STA XREG1$
        STA XREG2$
        STA XREG2$
        ORA xREG1$+1
        ORA xREG1$+1
        STA TESTAS
        STA TESTAS
        LDA TEMPAS
        LDA TEMPAS
        TST TESTAS
        TST TESTAS
        MEXIT
        MEXIT
        ENDC
        ENDC
    ENDC
ENDC
IFEQ NARG-1
IFEQ NARG-1
STA TEMPAS
STA TEMPAS
LDA XREG1$+1
        LDA XREG1$+1
ADD (\0)+1
ADD (\0)+1
STA XREG1$+1
        STA XREG1$+1
STA XREG2$+1
        STA XREG2$+1
LDA XREG1\$
LDA XREG1\$
ADC \0
ADC \0
STA XREG1\$
STA XREG1\$
STA XREG2\$
STA XREG2\$
ORA XREG1$+1
        ORA XREG1$+1
STA TESTA\$
STA TESTA\$
LDA TEMPAS
LDA TEMPAS
TST teSTAS
TST teSTAS
MEXIT
MEXIT
ENDC
ENDC
IFEQ NARG-2
IFEQ NARG-2
IFC '\0', '\#'
IFC '\0', '\#'
STA TEMPA\$
STA TEMPA\$
LDA XREG1$+1
            LDA XREG1$+1
ADD \#(\1)!.$FF
            ADD #(\1)!.$FF
STA XREG1$+1
            STA XREG1$+1
STA XREG2$+1
            STA XREG2$+1
LDA XREG1\$
LDA XREG1\$
ADC \#(\1)!>8
ADC \#(\1)!>8
STA XREG1\$
STA XREG1\$
STA xREG2\$
STA xREG2\$
ORA XREG1$+1
            ORA XREG1$+1
STA TESTAS
STA TESTAS
LDA TEMPAS
LDA TEMPAS
TST TESTA\$
TST TESTA\$
MEXIT
MEXIT
ENDC
ENDC
ENDC
ENDC
FAIL Macro syntax error detected!
FAIL Macro syntax error detected!
ENDM

```
        ENDM
```

```
07150
07160 * DECXR = decrement XREG
07170 * DECXR [[#,]<address>]
07180 *
07190 * Examples:
07200 * 1. "DECXR" subtracts one (1) from the XREG
07210 * 2. "DECXR #,START" subtracts the value of symbol 'START' from
07220 * the XREG,
07230 * 3. "DECXR START" subtracts the contents of location 'START'
07240 * and 'START'+1 from the XREG.
07250 * 4. "DECXR ! comment" subtract one from the XREG (comment present!).
07260
07270 * Register Usage:
07280 * CC = reflects value decremented (z-bit only).
07290 * All other registers preserved.
07300 *
07310 * Notes:
07320 * 1. Explicit comment character (!) MUST be used when comment field is
07330 * present!
07340 * 2.Assumes XREG1$ = XREG2$
07350 * 3. When parameters are present, this macro becomes "SUBTRACT from XREG".
07360 *
07370 DECXR MACR
07380 IFEQ NARG
07390 STA TEMPA$
07400 LDA XREG1$+
07410 SUB #1
07420 STA XREG1$+1
07430 STA XREG2$+1
07440 LDA XREG1$
07450 SBC #0
07460 STA XREG1S
07470 STA XREG2$
07480 ORA XREG1$+1
07490 STA TESTAS
07500 LDA TEMPA$
07510 TST TESTAS
07520 MEXIT
07530 ENDC
07540 IFEQ NARG-1
07550 STA TEMPAS
07560 LDA XREG1$+1
07570 SUB (\0)+1
07580 STA XREG1$+1
07590 STA XREG2$+1
07600 LDA XREG1$
07610 SBC \0
07620 STA XREG1$
07630 STA XREG2$
07640 ORA XREG1$+1
07650 STA TESTAS
07660 LDA TEMPA$
07670 TST TESTAS
07680 MEXIT
07690 ENDC
```

```
    IFEQ NARG-2
    IFC '\0', '#'
            STA TEMPAS
            LDA XREG1$+1
            SUB #(\1)!.$FF
            STA XREG1$+1
            STA XREG2$+1
            LDA XREG1$
            SBC #(\1)!>8
            STA XREG1$
            STA XREG2$
            ORA XREG1$+1
            STA TESTAS
            LDA TEMPAS
            TST TESTAS
            MEXIT
        ENDC
    ENDC
            FAIL Macro syntax error detected!
    ENDM
**************************************************************************************
* CPXR = compare XREG
* CPXR [#,]<address>
* Examples:
* 1."CPXR #,BLOCKSZ" compares the value of symbol 'BLOCKSZ'
* with the XREG.
* 2. "CPXR START" compares the contents of location
* 'START' and 'START'+1 with the XREG.
* Register Usage:
* CC = reflects XREG comparison (z-bit only).
* All other registers preserved.
*
CPXR MACR
    IFEQ NARG-1
            STA TEMPA$
            BSET 0,TESTAS Preset for .NE. condition!
            LDA XREG1$+1
            CMP (\0)+1
            BNE \.O Branch if LS half is .NE.
            LDA XREG1$
            CMP (\0)
            BNE \.0 Sranch if MS half is .NE.
            CLR TESTA
            set for .EQ. condition!
                    Set proper z-bit (.EQ. or .NE.)!
            MEXIT
    ENDC
```

```
08200
08210
08220
08230
08240
08250
08260
08270
08280
08290
08300
08310
08320
08330
08340
08350
08360
08370
08380
0 8 3 9 0
08400
08410
08420
08430
08440
08450
08460
08470
08480
08490
0 8 5 0 0
08510
08520
08530
08540
08550
08560
08570
08580
08590
08600
08620 ENDM
08630
```

```
```

0 8 6 1 0 ~ F A I L ~ M a c r o ~ s y n t a x ~ e r r o r ~ d e t e c t e d !

```
```

0 8 6 1 0 ~ F A I L ~ M a c r o ~ s y n t a x ~ e r r o r ~ d e t e c t e d !

```
```

0 8 6 1 0 ~ F A I L ~ M a c r o ~ s y n t a x ~ e r r o r ~ d e t e c t e d !

```
    IFEQ NARG-2
```

    IFEQ NARG-2
    ```
    IFEQ NARG-2
        IFC '\0', '#'
        IFC '\0', '#'
        IFC '\0', '#'
        IFEQ \1
        IFEQ \1
        IFEQ \1
            IFEQ XREG1$!.$FF00
            IFEQ XREG1$!.$FF00
            IFEQ XREG1$!.$FF00
                TST XREG1$+1
                TST XREG1$+1
                TST XREG1$+1
                    BNE \.0 Branch if LS half is .NE.
                    BNE \.0 Branch if LS half is .NE.
                    BNE \.0 Branch if LS half is .NE.
                TST XREG1$
                TST XREG1$
                TST XREG1$
                EQU *
                EQU *
                EQU *
                MEXIT
                MEXIT
                MEXIT
            ENDC
            ENDC
            ENDC
                IFNE XREG1$!.$FF00
                IFNE XREG1$!.$FF00
                IFNE XREG1$!.$FF00
                    STA TEMPAS
                    STA TEMPAS
                    STA TEMPAS
                    BSET 0,TESTAS Preset for .NE. condition!
                    BSET 0,TESTAS Preset for .NE. condition!
                    BSET 0,TESTAS Preset for .NE. condition!
                    LDA XREG1$+1
                    LDA XREG1$+1
                    LDA XREG1$+1
                        BNE \.0
                        BNE \.0
                        BNE \.0
                        LDA XREG1$
                        LDA XREG1$
                        LDA XREG1$
                        BNE \.0 Branch if MS half is .NE.
                        BNE \.0 Branch if MS half is .NE.
                        BNE \.0 Branch if MS half is .NE.
                        CLR TESTAS Set for .EQ. condition!
                        CLR TESTAS Set for .EQ. condition!
                        CLR TESTAS Set for .EQ. condition!
        LDA TEMPAS
        LDA TEMPAS
        LDA TEMPAS
                TST TESTAS
                TST TESTAS
                TST TESTAS
                MEXIT
                MEXIT
                MEXIT
        ENDC
        ENDC
        ENDC
    ENDC
    ENDC
    ENDC
        STA TEMPAS
        STA TEMPAS
        STA TEMPAS
        BSET 0,TESTAS
        BSET 0,TESTAS
        BSET 0,TESTAS
        LDA XREG1$+1
        LDA XREG1$+1
        LDA XREG1$+1
        IFNE (\1)!.$FF
        IFNE (\1)!.$FF
        IFNE (\1)!.$FF
        CMP #(\1)!.$FF
        CMP #(\1)!.$FF
        CMP #(\1)!.$FF
        ENDC
        ENDC
        ENDC
        BNE \.0 Branch if LS half is .NE.
        BNE \.0 Branch if LS half is .NE.
        BNE \.0 Branch if LS half is .NE.
        LDA XREG1$
        LDA XREG1$
        LDA XREG1$
        IFNE (\1)!>8
        IFNE (\1)!>8
        IFNE (\1)!>8
        CMP #(\1)!>8
        CMP #(\1)!>8
        CMP #(\1)!>8
    ENDC
    ENDC
    ENDC
        BNE \.0 Branch if MS half is .NE.
        BNE \.0 Branch if MS half is .NE.
        BNE \.0 Branch if MS half is .NE.
        CLR TESTAS Set for .EQ. condition!
        CLR TESTAS Set for .EQ. condition!
        CLR TESTAS Set for .EQ. condition!
I.0 LDA TEMPAS
I.0 LDA TEMPAS
I.0 LDA TEMPAS
        TEMPAS (
        TEMPAS (
        TEMPAS (
                                TESTAS Set proper z-bit (.EQ. or .NE.)!
                                TESTAS Set proper z-bit (.EQ. or .NE.)!
                                TESTAS Set proper z-bit (.EQ. or .NE.)!
        MEXIT
        MEXIT
        MEXIT
        ENDC
        ENDC
        ENDC
ENDC
ENDC
ENDC
                Q XREG1$!.$F%00
                Q XREG1$!.$F%00
                Q XREG1$!.$F%00
                        *
                        *
                        *
    Branch if MS half is .NE.
    Branch if MS half is .NE.
    Branch if MS half is .NE.
    Set proper Z-bit (.EQ. or .NE.)!
    Set proper Z-bit (.EQ. or .NE.)!
    Set proper Z-bit (.EQ. or .NE.)!
        XREG1$
        XREG1$
        XREG1$
        CRA 
```

        CRA 
    ```
        CRA 
```




```
09930
09940
09950
09960
09970
09980
09990
10000
10010
10020
10030
10040
10050
10060
10070
10080
10090
10100
10110
10120
10130
10140
10150
10160
10170
10180
10190
10200
10210
10220
10230
10240 * 3. When parameters are present, this macro becomes "ADD to YREG".
10250
10260
10270
10280
10290
10300
10310
10320
10330
10340
10350
10360
10370
10380
10390
10400
10410
10420
10430
10440
10450
10460
10470
10480
10490
10500
10510
10520
10530
* INCYR = increment YREG
* INCYR [[#,]<value>]
*
* Examples:
* 1. "INCYR" adds one (1) to the YREG.
* 2. "INCYR #,START" adds the value of symbol 'START' to the
* YREG.
* 3. "INCYR START" adds the contents of location 'START' and
* 'START'+1 to the YREG.
* 4. "INCYR! comment" adds one (1) to the YREG (comment present!).
*
* Register Usage:
* CC = reflects value incremented (z-bit only).
* All other registers preserved.
* Notes:
* 1. Explicit comment character (!) MUST be used when comment field is
* present!
* 2.Assumes YREG1$ = YREG2$.
*
INCYR MACR
    IFEQ NARG
        IFEQ YREG1$!.$FF00
            INC YREG1$+1
            INC YREG2$+1
            BNE \.0
            INC YREG1$
            INC YREG2$
1.0 EQU *
            MEXIT
        ENDC
        IFNE YREG1$!.$FF00
            STA TEMPA$
            LDA YREG1$+1
            ADD #1
            STA YREG1$+1
            STA YREG2$+1
            LDA YREG1$
                ADC #0
                STA YREG1$
                STA YREG2$
                ORA YREG1$+1
                STA TESTAS
                LDA TEMPAS
                TST TESTAS
                MEXIT
        ENDC
    ENDC
```

```
10920 * DECYR = decrement YREG
```

10920 * DECYR = decrement YREG
10930 * DECYR [[\#,]<value>]
10940
10950
10960 * Examples.
10960 * 1."DECYR"
10970 * 2. "DECYR \#,START" subtracts the value of symbol 'START' from
10980 *
1 0 9 9 0
11000
11010
11020 *

* CC = reflects value decremented (z-bit only).
11050 * All other registers preserved.
11060 *
11070 * Notes:
11080 * 1. Explicit comment character (!) MUST be used when comment field is
11090 * present!
11100 * 2.Assumes YREG1\$ = YREG2\$.
11110 * 3. When parameters are present, this macro becomes "SUBTRACT from YREG".
11120 *

```

```

11680 * CPYR = compare YREG
11690 * CPYR [\#,]<address>
11700 *
11710 * Examples:
11720 * 1."CPYR \#,BLOCKSZ" compares the value of symbol 'BLOCKSZ'
11730
11740
11750
11760 *
11770 * Register Usage:
11780 * CC = reflects YREG comparison (Z-bit only).
11790 * All other registers preserved.
11800 *
11810 CPYR MACR
11820
11830
11840
11850
11860
11870
11880
11890
11900
11910
1 1 9 2 0
11930
11940
11950
11960
11970
1 1 9 8 0
11990
12000
12010
12020
12030
12040
12050
12060
12070
12080
12090
12100
12110
12120
12130
12140
12150
12160
12170
12180
12190
12200
12210
12220
12230
12240
12250
12260
12270
12280
12290
11670
with the YREG.

* 2. "CPYR START"
compares the contents of location
IFEQ NARG-1
STA TEMPAS
BSET 0,TESTAS Preset for .NE. condition!
LDA YREG1$+1
       CMP (\0)+1
       BNE \.O Branch if LS half is .NE.
       LDA YREG1$
CMP (\0)
BNE \.0 Branch if MS half is .NE.
CLR TESTAS Set for .EQ. condition!
\ CLR TESTA\$
TST TESTAS Set proper Z-bit (.EQ. or .NE.)!
MEXIT
ENDC
IFEQ NARG-2
IFC '\0', '\#'
IFEQ \1
IFEQ YREG1$!.$FF00
TST YREG1$+1
               BNE \.0 Branch if LS half is .NE.
           BNE \.0
1.0 EQU *
           MEXIT
       ENDC
       IFNE YREG1$!.$FF00
       STA TEMPA$
BSET 0,TESTAS Preset for .NE. condition!
LDA YREG1$+1
               BNE \.0 Branch if MS half is .NE.
               LDA YREGI$
BNE \.O Branch if MS half is .NE.
CLR TESTAS Set for .EQ. condition!
1.0
Set proper z-bit (.EQ. or .NE.)!
'START' and 'START'+1 with the YREG.
LDA TESTAS
TST TESTAS
MST
ENDC
ENDC
STA TEMPAS
BSET 0,TESTAS Preset for .NE. condition!
LDA YREG1$+1
   IFNE (\1)!.$FF
CMP \#(\1)!.$FF
   ENDC
   BNE \.0 Branch if LS half is .NE.
   LDA YREG1$
IFNE (\1)!>8
CMP \#(\1)!>8
ENDC

```



```

13960 **************************************************************************************
13970 * INC.B = increment byte
13980 * INC.B [[\#,]<value>,]<address>
13990 *
14000 * where:
14010 * <value> = value to decrement the contents of the <address>
14020 * location by; immediate ("\#," present) or absolute
14030 * addressing ("\#," not present). If only <address> is
14040 * specified, a default immediate value of one is used.
14050 *
14060 * Examples:
14070 * 1."INC.B START" adds one to the contents of location
14080 *
'START'
adds five to the contents of location
'START'.
14100 *
14110 *
14120 *
14130 *
14140 * Register Usage:
14150 * CC= reflects value incremented (N and z-bits).
14160 * All other registers preserved.
14170 *
14180 * Notes:
14190 * 1. <address> may be direct or extended!
14200 * 2.This macro essentially performs an "ADD n" function.
14210 *
14220 INC.B MACR
14230 IFEQ NARG-1
14240
14250
14260
14270
14280
14290
14300
14310
14320
14330
14340
14350
14360
14370
14380
14390
14400
14410
14420
14430
14440
14450
14460
14470
14480
14490
14500
14530 ENDC

```
```

14540
14550
14560
14570
14580
14590
14600
14610
14620
14630
14640
14650
14660
14670
14680
14690
14700
14710
14720
14730
14740
14750
14760
14770
14790
14800 *
14810
14820
14830
14840 *
14850 *
14860 *
14870 *
14880
14890
14900
14910 *
14920 *
14930 *
14940 *
14950 * Register Usage:
14980 *
14990
15000
15010 *
15020 *
15030
15040
15050
15060
15070
15080
15090
15100
15110

```
```

14960 * CC = reflects value incremented (z-bit only).

```
14960 * CC = reflects value incremented (z-bit only).
14970 * All other registers preserved.
14970 * All other registers preserved.
```

    IFEQ NARG-3
    ```
    IFEQ NARG-3
        IFC '\0', '#'
        IFC '\0', '#'
            STA TEMPAS
            STA TEMPAS
            LDA \2
            LDA \2
            ADD #1
            ADD #1
            STA \2
            STA \2
            IFEQ (\2)!.$FF00
            IFEQ (\2)!.$FF00
                LDA TEMPAS
                LDA TEMPAS
                    TST \2
                    TST \2
                MEXIT
                MEXIT
            ENDC
            ENDC
            IFNE (\2)!.$FF00
            IFNE (\2)!.$FF00
                    STA TESTA$
                    STA TESTA$
                    LDA TEMPAS
                    LDA TEMPAS
                    TST TESTAS
                    TST TESTAS
                    MEXIT
                    MEXIT
            ENDC
            ENDC
        ENDC
        ENDC
    ENDC
    ENDC
            FAIL Macro syntax error detected!
            FAIL Macro syntax error detected!
            ENDM
            ENDM
******************************************************************************************
******************************************************************************************
* INC.W = increment word
* INC.W = increment word
* INC.W [[#,]<value>, ]<address>
* INC.W [[#,]<value>, ]<address>
* where:
* where:
    <value> = value to increment the contents of the <address> and
    <value> = value to increment the contents of the <address> and
                    <address>+1 locations by; immediate ("#," present)
                    <address>+1 locations by; immediate ("#," present)
                    or absolute addressing ("#," not present). If only
                    or absolute addressing ("#," not present). If only
                    <address> is specified, a default immediate value of
                    <address> is specified, a default immediate value of
                    one is used.
                    one is used.
*
*
Examples:
Examples:
        1. "INC.W START" adds one to the contents of locations
        1. "INC.W START" adds one to the contents of locations
* 'START' and 'START'+1.
* 'START' and 'START'+1.
    2. "INC.W CNT,START" adds the value of 'CNT' to the contents
    2. "INC.W CNT,START" adds the value of 'CNT' to the contents
                        of locations 'START' and 'START'+1.
                        of locations 'START' and 'START'+1.
        3. "INC.W #,5,START" adds five to the contents of locations
        3. "INC.W #,5,START" adds five to the contents of locations
                        'START' and 'START'+1.
                        'START' and 'START'+1.
*
*
*
*
* Notes:
* Notes:
        1. <address> may be direct or extended!
        1. <address> may be direct or extended!
        2. This macro essentially performs an "ADD n" function.
        2. This macro essentially performs an "ADD n" function.
*
*
INC.W MACR
INC.W MACR
    IFEQ NARG-1
    IFEQ NARG-1
        IFEQ (\0)!.$FF00
        IFEQ (\0)!.$FF00
            INC (\0)+1
            INC (\0)+1
            BNE }1.
            BNE }1.
            INC \0
            INC \0
1.0 EQU *
1.0 EQU *
        MEXIT
        MEXIT
        ENDC
```

        ENDC
    ```
\begin{tabular}{|c|c|c|}
\hline 15120 & IFNE & (\0) ! . \$FF00 \\
\hline 15130 & STA & TEMPAS \\
\hline 15140 & LDA & (\0) +1 \\
\hline 15150 & ADD & \#1 \\
\hline 15160 & STA & (\0) +1 \\
\hline 15170 & LDA & \(\backslash 0\) \\
\hline 15180 & ADC & \# 0 \\
\hline 15190 & STA & 10 \\
\hline 15200 & ORA & ( \(\backslash 0\) ) +1 \\
\hline 15210 & STA & TESTAS \\
\hline 15220 & LDA & TEMPAS \\
\hline 15230 & TST & TESTA\$ \\
\hline 15240 & \multicolumn{2}{|l|}{MEXIT} \\
\hline 15250 & \multicolumn{2}{|l|}{ENDC} \\
\hline 15260 & ENDC & \\
\hline 15270 & IFEQ NA & NARG-2 \\
\hline 15280 & STA & TEMPAS \\
\hline 15290 & LDA & \((\backslash 1)+1\) \\
\hline 15300 & ADD & \((\backslash 0)+1\) \\
\hline 15310 & STA & \((\backslash 1)+1\) \\
\hline 15320 & LDA & \(\backslash 1\) \\
\hline 15330 & ADC & \(\backslash 0\) \\
\hline 15340 & STA & \(\backslash 1\) \\
\hline 15350 & ORA & (\1) +1 \\
\hline 15360 & STA & TESTAS \\
\hline 15370 & LDA & TEMPAS \\
\hline 15380 & TST & TESTAS \\
\hline 15390 & & MEXIT \\
\hline 15400 & ENDC & \\
\hline 15410 & IFEQ NA & NARG-3 \\
\hline 15420 & \multicolumn{2}{|l|}{IFC ' 10 ', \#'} \\
\hline 15430 & STA & TEMPA\$ \\
\hline 15440 & LDA & (\2) +1 \\
\hline 15450 & ADD & \# ( 11\()\) ! . \$FF \\
\hline 15460 & STA & \((\backslash 2)+1\) \\
\hline 15470 & LDA & \(\backslash 2\) \\
\hline 15480 & ADC & \# (\1) ! > 8 \\
\hline 15490 & STA & \(\backslash 2\) \\
\hline 15500 & ORA & (\2) +1 \\
\hline 15510 & STA & TESTAS \\
\hline 15520 & LDA & TEMPA\$ \\
\hline 15530 & TST & TESTA\$ \\
\hline 15540 & \multicolumn{2}{|l|}{MEXIT} \\
\hline 15550 & \multicolumn{2}{|l|}{ENDC} \\
\hline 15560 & ENDC & \\
\hline 15570 & \multicolumn{2}{|r|}{FAIL Macro syntax error detected!} \\
\hline 15580 & \multicolumn{2}{|l|}{\multirow[t]{2}{*}{ENDM}} \\
\hline 15590 & & \\
\hline
\end{tabular}
```

15600 **********************
15620 * MOV.B [\#,]<byte>,<address>
15630 *
15640 * where:
15650 * <byte> = byte value to move to the <address> location, using
15660 * immediate ("\#," present) or absolute addressing ("\#,"
15670 * not present).
15680 *
15690 * Examples:
15700 * 1. "MOV.BCNT,TMP" puts the contents of location 'CNT'
15710 * into location 'TMP'.
15720 * 2. "MOV.B\#,5,START" puts 5 into location 'START'.
15730 *
15740 * Register Usage:
15750 * CC = reflects value moved.
15760 * All other registers preserved.
15770 *
15780 MOV.B MACR
15790 IFEQ NARG-2
15800 STA TEMPAS
15810 LDA \0
15820 STA \1
15830 IFEQ (\1)!.$FF00
15840 LDA TEMPAS
15850 TST \1
15860
15870
15880
15890
15900
15910
15920
15930
15940
1 5 9 5 0
15960
15970
1 5 9 8 0
15990
16000
16010
16020 IFEQ NARG-3
16030
16040
16050
16060
16070
16080
16090
16100
16110
16120
16130
16140
16150
16160
16170
16180
16190
16200
16210
16220
    ENDC
    IFNE (\1)!.$FF00
IFEQ (\0)!.$FFOO
                    LDA TEMPAS
                    TST \0
            MEXIT
        ENDC
            IFNE (\0)!.$FFOO
STA TESTAS
LDA TEMPA\$
TST TESTAS
MEXIT
ENDC
ENDC
ENDC
IFEQ NARG-3
IFC
IFEQ (\)!
CLR \
MEXIT
ENDC
ENDC
STA TEMPAS
IFEQ \I
CLRA
ENDC
IFNE \1
LDA \#1
ENDC
STA \2
IFEQ (\2)!.\$FFOO
LDA TEMPAS
TST\
MEXIT
ENDC

```
```

16230
16240
16250
16260
16270
16280
16290
16300
16310
16320
16330
16340
16350
16360
16370
16380
16390
16400
16410
16420
16430
16440
16450
16460
16470
16480
16490
1 6 5 0 0
16510
16520
16530
16540
16550
16560
16570
16580
16590
16600
16610
16620
16630
16640
16650
16660
16670
16680
16690
16700
16710
16720
16730
16740
16750
16760
16770
16780
16790
16800
16810

```
```

            IFNE (\2)!.$FFOO
    ```
            IFNE (\2)!.$FFOO
            STA TESTAS
            STA TESTAS
            LDA TEMPAS
            LDA TEMPAS
            TST TESTAS
            TST TESTAS
            MEXIT
            MEXIT
                ENDC
                ENDC
        ENDC
        ENDC
    ENDC
    ENDC
            FAIL Macro syntax error detected!
            FAIL Macro syntax error detected!
            ENDM
            ENDM
********************************************************************************
********************************************************************************
* MOV.W = move word
* MOV.W = move word
* MOV.W [#,] <word>, <address>
* MOV.W [#,] <word>, <address>
*
* where:
* where:
    <word> = word (16-bit) value to move to the <address> and
    <word> = word (16-bit) value to move to the <address> and
                <address>+1 locations, using immediate ("#," present)
                <address>+1 locations, using immediate ("#," present)
                or absolute addressing ("#," not present).
                or absolute addressing ("#," not present).
*
*
* Examples:
* Examples:
* 1."MOV.W #,5,START" puts $0005 into location 'START' and
* 1."MOV.W #,5,START" puts $0005 into location 'START' and
* 'START'+1.
* 'START'+1.
* 2. "MOV.W #,CNT,TMP" puts the value of symbol 'CNT' into
* 2. "MOV.W #,CNT,TMP" puts the value of symbol 'CNT' into
    locations 'TMP' and 'TMP'+1.
    locations 'TMP' and 'TMP'+1.
    3. "MOV.W CNT,TMP" copies the contents of location 'CNT'
    3. "MOV.W CNT,TMP" copies the contents of location 'CNT'
                                    and 'CNT'+1 into locations 'TMP' and
                                    and 'CNT'+1 into locations 'TMP' and
                                    'TMP'+1.
                                    'TMP'+1.
*
*
* Register Usage:
* Register Usage:
* CC = reflects MS half of value moved.
* CC = reflects MS half of value moved.
* All other registers preserved.
* All other registers preserved.
MOV.W MACR
MOV.W MACR
    IFEQ NARG-2
    IFEQ NARG-2
            STA TEMPAS
            STA TEMPAS
            LDA (\0)+1
            LDA (\0)+1
            STA (\1)+1
            STA (\1)+1
            LDA \0
            LDA \0
            STA \1
            STA \1
        IFEQ (\1)!.$FFOO
        IFEQ (\1)!.$FFOO
            LDA TEMPAS
            LDA TEMPAS
            TST \1
            TST \1
            MEXIT
            MEXIT
        ENDC
        ENDC
        IFNE (\1)!.$FFOO
        IFNE (\1)!.$FFOO
            IFEQ (\0)!.$FFOO
            IFEQ (\0)!.$FFOO
                    LDA TEMPAS
                    LDA TEMPAS
            TST \0
            TST \0
            MEXIT
            MEXIT
            ENDC
            ENDC
            IFNE (\0)!.$FFOO
            IFNE (\0)!.$FFOO
                    STA TESTAS
                    STA TESTAS
                    LDA TEMPAS
                    LDA TEMPAS
                    TST TESTAS
                    TST TESTAS
                    MEXIT
                    MEXIT
            ENDC
            ENDC
        ENDC
        ENDC
    ENDC
```

    ENDC
    ```
```

16820
16830
16840
16850
16860
16870
16880
16890
16900
16910
16920
16930
16940
16950
16960
16970
16980
16990
17000
17010
17020
17030
17040
17050
17060
17070
17080
17090
17100
17110
17120
17130
17140
17150
17160
17170
17180
17190
17200
17210
17220
17230

```
```

IFEQ NARG-3

```
IFEQ NARG-3
    IFC '\0', '#'
    IFC '\0', '#'
        IFEQ ((\2)+1)!.SFF00
        IFEQ ((\2)+1)!.SFF00
            IFEQ \1
            IFEQ \1
                    CLR \2
                    CLR \2
                    CLR \2+1
                    CLR \2+1
                    MEXIT
                    MEXIT
                ENDC
                ENDC
        ENDC
        ENDC
                    STA TEMPA$
                    STA TEMPA$
            IFEQ (\1)!.$00FF
            IFEQ (\1)!.$00FF
                    CLRA
                    CLRA
        ENDC
        ENDC
        IFNE (\1)!.$OOFF
        IFNE (\1)!.$OOFF
            LDA #(\1)!.$00FF
            LDA #(\1)!.$00FF
        ENDC
        ENDC
                            STA (\2)+1
                            STA (\2)+1
        IFEQ (\1)!>8
        IFEQ (\1)!>8
                IFNE (\1)!.$00FF
                IFNE (\1)!.$00FF
                CLRA
                CLRA
                ENDC
                ENDC
            ENDC
            ENDC
            IFNE (\1)!>8
            IFNE (\1)!>8
            LDA #(\1)!>8
            LDA #(\1)!>8
        ENDC
        ENDC
                            STA \2
                            STA \2
            IFEQ (\2)!.$FFOO
            IFEQ (\2)!.$FFOO
                LDA TEMPAS
                LDA TEMPAS
                TST \2
                TST \2
                MEXIT
                MEXIT
            ENDC
            ENDC
            IFNE (\2)!.$FFOO
            IFNE (\2)!.$FFOO
                STA TESTAS
                STA TESTAS
                LDA TEMPAS
                LDA TEMPAS
                TST TESTA$
                TST TESTA$
                MEXIT
                MEXIT
            ENDC
            ENDC
        ENDC
        ENDC
ENDC
ENDC
        FAIL Macro syntax error detected!
        FAIL Macro syntax error detected!
        ENDM
```

        ENDM
    ```
```

17240 **********************************************************************
17250 * MOVE = move block of memory
17260 * MOVE [\#],<source>,[\#],<destination>, [\#],<length>
17270 *
17280
17300 * <destination> is the address of the destination block.
17310 *
17320
17330
17340
17350
17360
17370
17380
17390
17400
17410
17420 *
17430 *
17440
17450
17460
17470 *
17480
17490
17500 *
17510
17520
17530
17540 *
17550
17560
17570
17580
17590
17600
17610
17620
17630
17640
1 7 6 5 0
17660
17670
17680
17690
17700
17710
17720
17730
17740
17750
17760
17770
17780
17790
17800
17810
17820
17830
17840
17850
17860
17870
17880
where:

<source> is the address of the source memory block.
    <length> is the length of the block to move, in bytes.
    Maximum of 65,536 bytes can be moved.
    * 
* 
* 
* Examples:
* 1. "MOVE \#,ROM,\#,RAM,\#,CNT moves the block of memory starting at
* location 'ROM' for 'CNT' bytes, to
* location 'RAM'.
* 2. "MOVE \#, ABC,\#,XYZ,,CNT m
* 
* 
* 

Register Usage:
CC = unknown.
All other registers preserved.
Subr. used:
LDAXREG, STAXREG
Macros used:
None, because this macro was written to be as efficient as
possible.
Notes:
1. If all immediate addressing operands (\#) and the move count is
<= 256, then a special 'short form' is generated which DOES NOT
contain any subroutine calls!
2. Depending on the exact parameters passed, not all registers,
subroutines and/or macros may be used.
3. This macro takes advantage of the fact that there are in fact
two XREGs, one for LOAD (XREG1$) and one for STORE (XREG2$).
4. The INCXR macro cannot be used here, because it assumes that
XREG1\$ = XREG2\$.

* --------------------------------------------------------------------------------------
MOVE MACR
IFNE NARG-6
FAIL ** 'move' macro requires six arguments!
ENDC
IFC '\4', '\#' ! If all immediate operands (\#) and move
IFC '\2', '\#' ! count <=256, use short form!
IFC '\0','\#'
IFLE 5-256 ! No subr. calls!
STA TEMPAS
STX TEMPX\$
LDX \#(\5)
\.0 LDA (\1)-1,x
STA (\3)-1,x
DEX
BNE \.0
LDA TEMPAS
LDX TEMPX\$
MEXIT
ENDC
ENDC
ENDC
ENDC

```

\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 18540 & & STA & XREG1 \$+1 & & & \\
\hline 18550 & & STA & XREG2 \$+1 & & & \\
\hline 18560 & & LDA & TEMPA\$ & & & \\
\hline 18570 & & LDX & TEMPX\$ & & & \\
\hline 18580 & & MEXI & & & & \\
\hline 18590 & & ENDC & & & & \\
\hline 18600 & * & & & & & \\
\hline 18610 & & IFGT \5 & -256 & ! & no: 16-bit size= use & 'length' \\
\hline 18620 & & LDA & \#(\5) ! . \$00FF & & & \\
\hline 18630 & & STA & LENGTHS+1 & & & \\
\hline 18640 & & LDA & \# ( \(\backslash 5\) ) ! > \(>8\) & & & \\
\hline 18650 & & STA & LENGTH\$ & & & \\
\hline 18660 & 1.0 & JSR & LDAXREG & & & \\
\hline 18670 & & JSR & STAXREG & & & \\
\hline 18680 & & IFEQ & XREG1 \$ . \$FF00 & & & \\
\hline 18690 & & INC & XREG1 \$ +1 & & & \\
\hline 18700 & & BNE & \(\backslash .1\) & & & \\
\hline 18710 & & INC & XREG1\$ & & & \\
\hline 18720 & \. 1 & INC & XREG2\$+1 & & & \\
\hline 18730 & & BNE & \(\backslash .2\) & & & \\
\hline 18740 & & INC & XREG2\$ & & & \\
\hline 18750 & 1.2 & EQU & * & & & \\
\hline 18760 & & ENDC & & & & \\
\hline 18770 & & IFNE & XREG1\$!. \$FF00 & & & \\
\hline 18780 & & LDA & XREG1 \$+1 & & & \\
\hline 18790 & & ADD & \#1 & & & \\
\hline 18800 & & STA & XREG1 \$ +1 & & & \\
\hline 18810 & & LDA & XREG1 \$ & & & \\
\hline 18820 & & ADC & \#0 & & & \\
\hline 18830 & & STA & XREG1\$ & & & \\
\hline 18840 & & LDA & XREG2\$+1 & & & \\
\hline 18850 & & ADD & \#1 & & & \\
\hline 18860 & & STA & XREG2 \({ }^{\text {+ }} 1\) & & & \\
\hline 18870 & & LDA & XREG2\$ & & & \\
\hline 18880 & & ADC & \# 0 & & & \\
\hline 18890 & & STA & XREG2 \$ & & & \\
\hline 18900 & & ENDC & & & & \\
\hline 18910 & & LDA & LENGTH\$+1 & & & \\
\hline 18920 & & SUB & \#1 & & & \\
\hline 18930 & & STA & LENGTH\$+1 & & & \\
\hline 18940 & & LDA & LENGTH\$ & & & \\
\hline 18950 & & SBC & \# 0 & & & \\
\hline 18960 & & STA & LENGTH\$ & & & \\
\hline 18970 & & ORA & LENGTH\$+1 & & & \\
\hline 18980 & & BNE & 1.0 & & & \\
\hline 18990 & & LDA & TEMPXR\$ & & & \\
\hline 19000 & & STA & XREG1\$ & & & \\
\hline 19010 & & STA & XREG2 \$ & & & \\
\hline 19020 & & LDA & TEMPXR\$+1 & & & \\
\hline 19030 & & STA & XREG1\$+1 & & & \\
\hline 19040 & & STA & XREG2 \$ +1 & & & \\
\hline 19050 & & LDA & TEMPAS & & & \\
\hline 19060 & & LDX & TEMPX\$ & & & \\
\hline 19070 & & MEXI & & & & \\
\hline 19080 & & ENDC & & & & \\
\hline 19090 & & DC & & & & \\
\hline 19100 & & & & & & \\
\hline
\end{tabular}


```

**************************************************************************************

* STAYREG = store A via YREG subr.
* 
* Register Usage:
* CC = reflects value stored.
* All other registers preserved.
* NOTE
* 1. Instruction modified code here must be located in RAM!
* 

STAYREG EQU *
YREG2\$ EQU 0-0+$FFFF
RTS
*-- end of RAM subroutines ------------------------------------------------------------
RAMSZ$ EQU *-RAMSBR\$ Size of ram subroutines (in bytes).
ORG LO\$MEM

* NOTE: TEMPAS and TESTAS must always be in low memory $0000-00FF.
TEMPAS RMB 1 Temporary storage for A accumulator.
TEMPX$ RMB 1 Temporary storage for X register.
TEMPXRS RMB 2 Temporary storage for XREG register.
TESTAS RMB 1 Temporary operand storage for setting CC bits.
LENGTH\$ RMB - 2 Temporary operand length.

```

\section*{Listing 2 - RAMSBR.INI File}

```

0 0 6 0 0
00620 *
00630 * Register Usage:
00660
00670 * NOTE:
00680
00690
00700
00710
00720
00730
00740
00750
00760
00770
00780
00790
0 0 8 0 0
00810
00820
00830
00840
00850
00860
00870
0 0 8 8 0
00890
0 0 9 0 0
00910
00920
00930
00940 * R
00960 *
00970 * NOTE:
00980 *
00990 *
01000
01010
01020
010.30
01040
01050
01060
01070
01080
01090

```
```

00610 * STA\$X = store A via XREG subr.

```
00610 * STA$X = store A via XREG subr.
00640 * CC = reflects value stored.
00640 * CC = reflects value stored.
00650 * All other registers preserved.
00650 * All other registers preserved.
* CC = reflects value stored.
* CC = reflects value stored.
00950 * All other registers preserved.
00950 * All other registers preserved.
```

**************************************************************************************

```
**************************************************************************************
*
*
* 1. Instruction modified code here must be located in RAM!
* 1. Instruction modified code here must be located in RAM!
*
*
.STA$X EQU *
.STA$X EQU *
    XREG2$ EQU *-2 Pseudo XREG #2
    XREG2$ EQU *-2 Pseudo XREG #2
        RTS
        RTS
**************************************************************************************
**************************************************************************************
* LDAYREG = load A via YREG subr.
* LDAYREG = load A via YREG subr.
*
*
* Register Usage:
* Register Usage:
* CC = reflects value loaded.
* CC = reflects value loaded.
* All other registers preserved.
* All other registers preserved.
* NOTE:
* NOTE:
* 1. Instruction modified code here must be located in RAM!
* 1. Instruction modified code here must be located in RAM!
*
*
.LDAYREG EQU *
.LDAYREG EQU *
    LDA 0-0+$FFFF
    LDA 0-0+$FFFF
.YREG1$ EQU *-2 Pseudo YREG #1
.YREG1$ EQU *-2 Pseudo YREG #1
**************************************************************************************
**************************************************************************************
* STASY = store A via YREG subr.
* STASY = store A via YREG subr.
*
*
* Register Usage:
* Register Usage:
* 1. Instruction modified code here must be located in RAM!
* 1. Instruction modified code here must be located in RAM!
*
*
.STASY EQU *
.STASY EQU *
            STA 0-0+$FEFF
            STA 0-0+$FEFF
    YREG2$ EQU *-2 Pseudo YREG #2
    YREG2$ EQU *-2 Pseudo YREG #2
            RTS
```

            RTS
    ```


```

.RAMSZ\$ EQU *-.RAMSBRS Size of ram subroutines (in bytes).

```
.RAMSZ$ EQU *-.RAMSBRS Size of ram subroutines (in bytes).
    FNE RAMSZ$-.RAMSZ$
    FNE RAMSZ$-.RAMSZ$
    FAIL Size mismatch between RAM/ROM subroutine areas!
    FAIL Size mismatch between RAM/ROM subroutine areas!
    ENDC
```

    ENDC
    ```

\section*{Selecting the Right Microcontroller Unit}

\section*{INTRODUCTION}

Selecting the proper microcontroller unit (MCU) for your application is one of the critical decisions which control the success or failure of your project. There are numerous criteria to consider when choosing an MCU and this Application Note will enumerate most of them and presents an outline of the thought process guiding this decision. The reader must attach their own grading scale to the selection criteria presented and then evaluate the total to make the correct decision.

\section*{PURPOSE}

The main goal is to select the least expensive MCU that minimizes the overall cost of the system while still fulfilling the system specification, i.e., performance, reliability, environmental, etc. The overall cost of the system includes everything, such as Engineering Research and Development (R\&D), manufacturing (parts and labor), warranty repairs, updates, field service, upward compatibility, ease of use, etc.

\section*{SELECTION PROCESS}

To start the selection process, the designer must first ask the question, "What does the MCU need to do in my system?" The answer to this one simple question dictates the required MCU features for the system and thus is the controlling agent in the selection process.

The second step is to conduct a search for MCUs which meet all of the system requirements. This usually involves searching the literature, primarily data books, data sheets, and technical trade journals, but also includes peer consultations. These days, recent trade journals seem to contain the most up to date information for the newer MCUs. If the fit is good enough, a single-chip MCU solution has been found, otherwise a second search must be conducted to find an MCU which best fits the requirements with a minimum of extra circuitry, including considerations of cost and board space. Obviously, a single-chip solution is preferred for cost as well as reliability reasons. Of course, if there is a company policy dictating which MCU manufacturer to use, this will narrow your search considerably.

The last step has several parts, all of which attempt to reduce the list of acceptable MCUs to a single choice. These parts include pricing, availability, development tools, manufacturer support, stability, and sole-sourcing. The whole process may need to be iterated several times to arrive at the optimum decision.

\section*{SELECTION CRITERIA}

The general outline of the main criteria in selecting a microcontroller is listed below, in the order of importance. Each criteria is explained in greater detail later on.
1. Suitability for the application system, i.e., can it be done with a single-chip MCU or at most a few additional chips?
A. Does it have the required number of \(1 / O\) pins/ports, i.e., too few = can't do the job and too many = excessive cost?
B. Does it have all the other required peripherals, such as serial I/O, RAM, ROM, A/D, D/A, etc.?
C. Does it have other peripherals that are not needed?
D. Does the CPU core have the correct throughput, i.e., computing power, to handle the system requirements over the life of the system for the chosen implementation language? Too much is wasteful and too little will never work.
\(E\). Is the MCU affordable, i.e., does the project budget allocate enough funds to permit using this MCU? A budgeting quotation from the manufacturer is usually required to answer this question. If the MCU is not affordable for the project, all the other questions become irrelevant and you must start looking for another MCU.
2. Availability?
A. Is the device available in sufficient quantities?
B. Is the device in production today?
C. What about the future?
3. Development support available?
A. Assemblers.
B. Compilers.
C. Debugging tools.
1. Evaluation Module (EVM).
2. In-circuit emulators.
3. Logic analyzer pods
4. Debug monitors
5. Source level debug monitors.
D. On-line bulletin board service (BBS).
1. Real time executives.
2. Application examples.
3. Bug reports.
4. Utility software, including "free" assemblers.
5. Sample source code.
E. Applications support.
1. Specific group who does nothing but applications support?
2. Application engineers, technicians, or marketers?
3. How knowledgeable are the support personnel? Are they truly interested in helping you with your problem?
4. Telephone and/or FAX support?
4. Manufacturer's history, i.e., "track record."
A. Demonstrated competence in design.
B. Reliability of silicon, i.e., manufacturing excellence.
C. On-time delivery performance.
D. Years in business.
E. Financial report.

\section*{SYSTEM REQUIREMENTS}

Applying system analysis to the current project will determine the MCU requirements for the system. What peripheral devices are required? Is the application to be bit manipulating or number crunching? Once data is received, how much manipulation is required? Is the system to be driven by interrupt, polled, or human-responses? How many devices/bits (I/O pins) need to be controlled? Among the many possible types of \(1 / O\) devices to be controlled/monitored are RS-232C terminals, switches, relays, keypads, sensors (temperature, pressure, light, voltage, etc.), audible alarms, visual indicators (LCD displays, LEDs), anaiog to digital (A/D), and digital to analog (D/A). Is a single or multiple voltage power supply required for the system? What is the power supply tolerance? Is the device characterized for operation at your system supply voltage? Are the voltages to be held to a small fixed percent variation or are they to operate over a wider range? What is the operating current? Is the product to be ac or battery operated? If battery operated, should rechargables be used, and if so, what is the operational time required before recharging and the required time for recharging?

Are there size and weight restrictions or aesthetic considerations such as shape and/or color? Is there anything special about the operating environment, such as military specification, temperature, humidity, atmosphere (explosive, corrosive, particulates, etc.), pressure/altitude? Is the application to be disk-based or ROM-based? Is it a real time application, and if so, are you going to build or purchase a real time kernel program or maybe a public domain version will suffice? Does your schedule contain enough time and personnel to develop your own? What about royalty payments and bug support? Much more investigation is required for real time applications in order to evaluate their special requirements.

\section*{GENERAL MCU ATTRIBUTES}

MCUs can generally be classified into 8 -bit, 16 -bit, and 32-bit groups based upon the size of their arithmetic and index register(s), although some designers argue that bus access size determines the \(8 / 16 / 32\)-bit architecture. Is a lower-cost 8 -bit MCU able to handle the requirements of the system, or is a higher-cost 16 -bit or 32 -bit MCU required? Can 8 -bit software simulation of features found on the 16-bit or 32-bit MCUs permit using the lower-cost 8 -bit MCU by sacrificing some code size and speed? For example, can an 8-bit MCU be used with software macros to implement 16 -bit accumulator
and indexing operations? The choice of implementation language (high level vs assembler) can greatly affect system throughput, which can then dictate the choice of \(8 / 16 / 32\)-bit architectures, but system cost restraints may override this.

Clock speed, or more accurately, bus speed, determines how much processing can be accomplished in a given amount of time by the MCU. Some MCUs have a narrow clock speed range, whereas others can operate down to zero. Sometimes a specific clock frequency is chosen in order to generate another clock required in the system, e.g., for serial baud rates. In general, computational power, power consumption and system cost increase with higher clock frequencies. System costs increase with frequency because not only does the MCU cost more, but so do all the support chips required, such as RAMs, ROMs, PLDs, and bus drivers.

Consider also the processing technology of the MPU; N channel metal-oxide semiconductor (NMOS) vs high-density complementary metal-oxide semiconductor (HCMOS). In HCMOS, signals drive from rail-to-rail, unlike earlier NMOS processors. Since these criteria can significantly affect noise issues in system design, HCMOS processors are usually preferred. Also, HCMOS uses less power and thus generates less heat. The design geometries in HCMOS are smaller which permit denser designs for a given size, and thus allow higher bus speeds. The denser designs also allow lower cost, for more units can be processed on the same sized silicon wafer. For these reasons, most MCUs today are produced using HCMOS technology.

\section*{MCU RESOURCES}

By definition, all MCUs have on-chip resources to achieve a higher level of integration and reliability at a lower cost. An on-chip resource is a block of circuitry built into the MCU which performs some useful function under control of the MCU. Built-in resources increase reliability because they do not require any external circuitry to be working for the resource to function. They are pre-tested by the manufacturer and conserve board space by integrating the circuitry into the MCU. Some of the more popular on-chip resources are memory devices, timers, system clock/oscillator, and I/O. Memory devices include read/write memory (RAM), read-only memory (ROM), erasable programmable ROM (EPROM), electrically erasable programmable ROM (EEPROM) and electrically erasable memory (EEM). The term EEM actually refers to an engineering development version of an MCU where EEPROM is substituted for the ROM in order to reduce development time. Timers include both real time clocks and periodic interrupt timers. Be sure to consider the range and resolution of the timer as well as any subfunctions, such as timer compare and/ or input capture lines. I/O includes serial communication ports, parallel ports (I/O lines), analog-to-digital (A/D) converters, digital-to-analog (D/A) converters, liquid crystal display drivers (LCD), and vacuum fluorescent display drivers (VFD).

Other less common built-in resources are internal/external bus capability, computer operating properly (COP) watchdog system, clock operating properly detection, selectable memory configurations, and system integration module (SIM). The SIM replaces the external "glue" logic usually required to interface to external devices via chip select pins.

On most MCUs with on-chip resources, a configuration register block is included to control these resources. Sometimes the configuration register block itself can be set up to appear at a different location in the memory map. Sometimes a user
and/or factory test register is present, which indicates concern for quality by the manufacturer. With configuration registers also comes the possibility of errant code altering the desired configuration, so check for "lock-out" mechanisms, i.e., before a register can be changed, a bit in another register must first be altered in a certain sequence. Although configuration registers can at first be very confusing and intimidating because of their complexity, they are extremely valuable because of the flexibility they offer at a low cost so that a single MCU can serve many applications.

\section*{MCU INSTRUCTION SET}

The instruction set and registers of each MCU should be carefully considered, as they play critical roles in the capability of the system. Have software engineers study the indexed addressing modes versus the anticipated needs of your system. Are there any specialty instructions available which could be used in your system, such as multiply, divide, and table lookup/ interpolate? Are there any low power modes for battery conservation, such as stop, low power stop, and/or wait? Are there any bit manipulation instructions (bit set, bit clear, bit test, bit change, branch on bit set, branch on bit clear) to allow easier implementation of controller applications? How about bit field instructions?

Be dubious of fancy instructions which seem to do a lot in one instruction. The real measure of performance is how many clock cycles it takes to accomplish the task at hand, not how many instructions were executed. A fair comparison is to code the same routine and compare the total number of clock cycles executed and bytes used. Are there any unimplemented instructions in the opcode map and what happens if they are accidently executed? Does the system handle this gracefully with an exception handler or does the system crash?

\section*{MCU INTERRUPTS}

Examining the interrupt structure is a necessity when constructing a real time system. How many interrupt lines or levels are there versus !ow many does your system require? Is there an interrupt level mask? Once an interrupt level is acknowledged, are there individual vectors to the interrupt handler routines or must each possible interrupt source be polled to determine the source of the interrupt? In speed critical applications, such as controlling a printer, the interrupt response time, i.e., the time from the start of the interrupt (worst case phasing relative to the MCU clock) until the first instruction in the appropriate interrupt handler is executed, can be the selection criterion in determining the right MCU.

\section*{COMPANY ATTRIBUTES}

Examine the assets of your own company with a little truthful introspection. Does your company have a significant investment in knowledge/training of existing personnel with a particular MCU manufacturer and in the development tools for those MCUs? Does your company own enough development tools or will you have to buy or rent more? If a new MCU is under consideration, are there development tools available, such as high level language compilers, assembler/linkers, evaluation modules, and debuggers/emulators? Are your present development tools easily expandable for new MCUs? Will additional personnel have to be hired and trained for this project? Can you hire an expert to train/lead the rest of your team? Does your budget permit hiring additional permanent staff and/or
contractors? Is your company satisfied with your current MCU manufacturer's product line and services?

\section*{SUPPLIER ATTRIBUTES}

The third step is pruning the list of technically acceptable MCUs by examining the MCU manufacturer and supplier, i.e., the companies with which you plan to enter into a long-term relationship for mutual benefit. A supplier can either be the MCU manufacturer itself, or it can be a full-service dealer who is the authorized representative for several manufacturers. A supplier with a broader range of products and a reputation for quality, reliability, service, and on-time deliverability at a fair price can best serve your needs. Additionally, the more products you purchase from one supplier, the more leverage you obtain for pricing, service, and support. Always keep in mind that although your dollar volume may seem high to you, it is always a relative amount to the total business of the supplier. Suppliers who can furnish not only MCUs, but memories (RAM and ROM), discrete devices (transistors, diodes, etc.), standard digital logic devices ( \(7400,74 \mathrm{HC} 00\), etc.), specialty chips, customer specific devices (CSIC), application specific devices (ASIC), and programmable logic devices (PLDs), will be better suited to serve your growing needs. Has the manufacturer and/ or supplier won any awards for quality, reliability, service, and/ or deliverability? Be suspicious of self-bestowed awards.

\section*{MANUFACTURER ATTRIBUTES}

Other criteria to consider in selecting the MCU manufacturer/supplier are stability, sole-supplier status, literature, and support. Stability can best be ascertained by considering the number of years in business and obtaining a Dunn \& Bradstreet rating plus copies of past Annual and Quarterly Financial Reports. Your company's Purchasing and Credit Departments can greatly assist you in these areas. Listing on a major stock exchange is another sign of stability. A local stock broker can assist you in obtaining up-to-date information for those manufacturers listed on stock exchanges, or you can visit your local library to check the Periodical Guide for pertinent information. The Wall Street Journal is another excellent source of up-to-date financial news. Sole-supplier status is unfortunately usually the norm, as most MCU manufacturers do not often cross license their products to other manufacturers. If the manufacturer has a good track record for supply, delivery, and pricing, sole-supplier status should not be a problem.

\section*{MANUFACTURER SUPPORT}

Direct manufacturer support includes Marketing/Sales, Field Application Engineers (FAEs), and Application Engineering. Are the FAEs near your site? When telephoning for support, can you reach the support person directly or do you play "telephone tag"? Are calls returned promptly? Is there a toll-free 800 number? Is there a FAX number? How many phone lines are available? Are the phone lines always busy? Do they have an individual Voice Mail answering system or does a secretary in another office take "While You Were Out" messages which must be physically relayed to the support person? Voice Mail is a state of the art computer controlled answering system whereby each user effectively has their own password protected answering machine with enhanced capabilities, such as message forwarding. What hours do the support personnel work? Do they have other duties and/or responsibilities besides support? How many support personnel are
there? Are factory personnel, such as Product Engineers, Manufacturing Engineers, Quality Engineers, Hardware Engineers, and Software Engineers, readily available to assist the support personnel? Are the factory people on-site with the support personnel? Are the support personnel knowledgeable, have a helpful attitude, and do they "follow through" in a timely manner when they promise to do something, such as research your problem or send you something? Does it come via regular mail, UPS, or Overnight Express? Were you charged for fast delivery?

Does the Manufacturer have an Electronic Bulletin Board Service (BBS) where information such as application programs, product news, software updates, source code, bug lists, electronic mail, and conferencing are available? What baud rates are supported? How many phone lines are available? What are the hours of operation? Do you need any special brand of computer and/or modem to access it? Is there a system operator (sysop) assigned to manage it?

\section*{LITERATURE SUPPORT}

Literature covers a wide selection of printed material which can assist you in the selection process. This includes items from the Manufacturer, such as Data Sheets, Data Books, and Application Notes, as well as items available at the local bookstore and/or library. Items from the local bookstore and/or library indicate not only the popularity of the manufacturers/ MCUs under consideration, but also offer unbiased opinions when written by non-manufacturer related authors.

\section*{FINALIZING THE SELECTION}

As a final step to help in the selection process, build a table listing each MCU under consideration on one axis and the important attributes on the other axis. Then fill in the blanks from the manufacturer's data sheets in order to obtain a fair side-by-side comparison. Some manufacturers have pre-made comparison sheets of their MCU product line which makes this task much easier, but as with all data sheets, be sure they are up to date with current production units. Among the possible attributes are price (for the anticipated production volume, including predictions of future pricing, i.e., will the price be decreasing as you move into production?), RAM, ROM, EPROM, EEPROM, timer(s), A/D, D/A, serial ports, parallel ports (1/O control lines), bus speed (minimum/maximum), special instructions (multiply, divide, etc.), number of available interrupts, interrupt response time (time from start of interrupt to execution of the first interrupt handler instruction), package size/type (ceramic DIP or LCC, plastic \(0.3^{\prime \prime}\) DIP or \(0.6^{\prime \prime}\) DIP, shrink DIP (.071" pin spacing), PLCC, PQFP, EIAJ QFP, SOIC; some involve surface mount technology), power supply requirements, and any other items important to your system design. The tables at the end of this application note detail the attributes of Motorola's MCU product line.

If after all this, you still have more than one MCU on your list, consider expandability and value. What expansions in the
system requirements can you predict that will be needed in possible future iterations of this product? And lastly, consider value, for if two MCUs cost the same but one offers a few more features which are not required today but would make future expansion easier for no additional cost, chose that MCU.

\section*{CUSTOM MCU SOLUTION}

If there is no commercially available single-chip MCU that meets your system requirements and your anticipated production volume is high enough, you should consider using a custom CSIC MCU. In a custom CSIC MCU, you choose the core processor type and the exact peripherals needed for your system from a list of standard cells available. This gives you the benefits of a single-chip solution for slightly more cost, so the production volume must be high enough to justify it. Additionally, some manufacturers will not even start production unless the order volume is around one million units. However, if your production volume can be combined with others to reach the one million level, production could be started. Or, if the desired unit is judged to be have a broad enough market appeal, the manufacturer may proceed with production anyway because they plan to offer it as a standard product. As the design initiator you may be able to obtain an exclusivity clause whereby you have sole rights to the CSIC MCU for a specific period of time. Then the manufacturer can start marketing it to everyone.

\section*{TEAMWORK}

Finally, as project leader you can do all this investigative work yourself, or you can start involving your team by assigning investigative tasks to them, such as having the software engineers evaluate the instruction sets of each MPU under consideration. By involving your team early in the decision process, you not only build team spirit, but gain individual commitment to the project via active participation. This approach undoubtedly generates some conflict, as everyone has their own opinion, but your job as project leader is to be a mediator. After listening to all opinions, it is still your choice as project leader. As in political elections, once the winner of the primary has emerged, all party members are expected to fully support the winner, and so should all project team members support the decisions of the project leader in order to ensure a successful project.

\section*{CONCLUSION}

In conclusion, selecting the right MCU for your project is not an easy decision, as MCUs have become more complex devices since on-chip resources were added. And since the trend is towards more on-chip integration of off-chip resources to reduce system costs, the decision will become increasingly complex with time. This application note is not intended to make the choice for the designer, but to serve as a thought provoking guideline as to all the possible selection criteria that should be considered in this important decision process.

\section*{MOTOROLA MICROCONTROLLER COMPARISON GUIDE}

Motorola maintains a comparison guide on our most popular M68HC05, M68HC11, and M68300 Families of microcontrollers (MCUs). For a copy, please contact the Motorola Literature Distribution Center nearest you and request the current MICROCONTROLLER (MCU) QUARTERLY UPDATE FOLDER, Motorola part number SG148/D.

MOTOROLA 8-BIT M68HC05 MICROCONTROLLER FAMILY

\section*{Programming Model}

The M68HC05 Family of MCUs has five central processing unit (CPU) registers available to the programmer as shown in Figure 1 below.

\section*{MOTOROLA 8-BIT M68HC11 MICROCONTROLLER FAMILY}

\section*{Programming Model}

The M68HC11 Family of MCUs has eight central processing unit (CPU) registers available to the programmer as shown in Figure 2 below.

\section*{MOTOROLA 16-/32-BIT M68300 MICROCONTROLLER FAMILY}

\section*{Programming Model}

The M68300 Family of MCUs has 23 central processing unit (CPU) registers available to the programmer as shown in Figures 3 and 4 below, organized into User and Supervisor models.


Figure 1. M68HC05 Programming Model


Figure 2. M68HC11 Programming Model


Figure 3. M68300 User Programming Model

1. The Status Register (SR) consists of two halves as shown below.


Figure 4. M68300 Supervisor Programming Model Supplement

\section*{DEVELOPMENT SUPPORT}

Development support for Motorola MCUs is available from Motorola in the form of low cost Educational Computer Boards (ECBs), Evaluation Boards (EVBs), and Evaluation Modules (EVMs), and higher priced emulator systems with bus analysis (CDS Jewelbox and HDS-300 systems). EVBs and EVMs are on the order of hundreds of dollars, whereas emulators are on the order of thousands of dollars. Simple assemblers are available for no charge on the Freeware BBS, whereas more powerful assemblers with such features as macros, structured assembly, conditional assembly, and relocatable modules (for linking) are available for a few hundred dollars for popular PCs. Additionally, the Freeware BBS contains the most up to date information on Motorola MCUs and has a wealth of free software. Also available are literature and Application Notes on many subjects, including a title index, from Motorola's Literature Distribution Centers.

\section*{MOTOROLA FREEWARE ELECTRONIC BULLETIN BOARD SYSTEM}
"Freeware" is the name of the electronic bulletin board system (BBS) dedicated to support Motorola Microprocessor Units (MPUs) and Microcontroller Units (MCUs). The Freeware BBS contains the most up to date information, including support software for EVMs, PCs, and MACs, development software for MCUs and MPUs, confidential electronic mail service, file downloads/uploads, distributor directory and sales offices by state, press news, development support, literature, mask set erratas, devices/packages being phased out, ECB/ EVB/EVM product literature, and contest/promotion/seminar information.

Freeware is on-line 24 hours a day, everyday except for maintenance. To use the BBS, you need a 300-2400 baud modem, and a terminal or personal computer (PC) with communications software (e.g., Kermit, ProComm, etc.). Set your character format to 8 -bit, no parity, 1 stop bit and dial the Freeware number (512) 891-FREE (891-3733). Press RETURN and then enter the requested information to log on. You are now a registered user. Follow the menus for the desired functions (e.g., download, upload, mail, conferences, etc.). On-line help is available.

For most up to date information, please contact the Motorola Literature Distribution Center nearest you and request the MCU FREEWARE brochure, Motorola part number BR568/D.

\section*{APPLICATIONS SUPPORT}

Application support for Motorola products is provided by the same local salesperson and Field Application Engineer (FAE) that made the sale. If a technical question can not be answered locally by the salesman or FAE, the FAE will contact the

Factory Applications Support Group which has a highly trained staff of engineers to relentlessly pursue the answers in both hardware and software. Additionally, the Aps Group has the backup support of the entire on-site Factory staff to ensure answers to your questions.

\section*{MOTOROLA LITERATURE DISTRIBUTION CENTERS}

Motorola has several Literature Distribution Centers (LDCs) worldwide with the main one located in Phoenix, Arizona, U.S.A. They carry all Motorola literature, including Data Books, Data Reference Manuals, User Manuals, Application Notes, brochures, books on Motorola products, etc. Contact your local Motorola representative or the LDC office nearest you and they will be most happy to serve you. The LDC addresses are listed on the back cover of this application note. The phone numbers are listed below or consult your local telephone directory book.

\author{
Motorola Literature Distribution Center Phone: (602) 994-6561
}

Motorola Semiconductors H.K. Ltd. Phone: 480-8333
Motorola Ltd.; European Literature Center Phone: (908) 614614
Nippon Motorola Ltd.
Phone: 03-440-3311

\begin{abstract}
ABOUT MOTOROLA
Motorola was founded in 1928 by Paul V. Galvin and has continuously been in the electronics business since then. Motorola moved up to number 48 on the 1989 Fortune 500 list of the largest U.S. industrial corporations with \(\$ 9.62\) billion in sales and is the \#3 in electronics in the U.S., behind General Electric and Westinghouse Electric. In terms of semiconductor market share, Motorola is \#1 in North America and \#4 in the world. Motorola's Microcontroller Division is the world's \#1 supplier of 8 -bit MCUs, with more than 500 million in use around the globe. Motorola was ranked \#3 by Fortune Magazine's poll of America's Most Admired Corporations.

Motorola has consistently demonstrated product and technology leadership along with the global capability and teamwork to get the job done for the lowest possible price. Motorola is driven by Total Customer Satisfaction, which means global design and manufacturing facilities, on-time delivery, and above all, a dedication to quality that is unsurpassed in the industry. Motorola's relentless pursuit of perfection is the key in achieving Six Sigma Quality by 1992. This translates to virtual perfection ( 3.4 defects per million parts). There is only one goal: zero defects in everything Motorola does.
\end{abstract}

\section*{RECENT AWARDS PRESENTED TO MOTOROLA}

1990 GM Mark of Excellence Award
This award was presented by Delco Electronics for outstanding performance as a supplier in all five areas covered by GM's supplier monitoring program - quality, cost, delivery, technology and management. Currently, less than 30 suppliers have earned the GM Mark of Excellence award.

1990 Computer Design's Vendor Preference Survey reported Motorola Microcontrollers as \#1 in the three measured categories of Response Time, Documentation, and Applications Support.

1989 Texas Instruments information Technology
Group Supplier Excellence Award
Presented to less than one percent of TI's suppliers worldwide for quality and on-time delivery performance.

1989 Chrysler Motor Company Pentastar Award Presented to select group of Chrysler's suppliers worldwide for quality, price, delivery, and technology.

1989 Ford Motor Company Q1 Preferred Quality Award A total quality supplier award; requires consistent high quality coupled with excellent pricing and delivery.

1988 Malcolm Baldrige National Quality Award
This award was created by Congress in 1987, named after the late Malcolm Baldrige, Secretary of Commerce during
the Reagan Administration. It is awarded to companies that demonstrate superior company-wide management of quality processes. A panel of judges examines the quality standards in eight critical business areas for each company applying for the award. Six prizes are offered each year - two each for manufacturing companies and service companies, and two for small businesses. In the two years the award has been offered, only five companies out of a potential 12 winners have met the rigid standards required to capture the prize. In 1988, Motorola was one of only three Baldrige winners out of 66 applicants. Winners of the Malcolm Baldrige National Quality Award must wait five years before they can apply again. Therefore, Motorola will be eligible to compete again in 1993.

\section*{1988 Dataquest Supplier of the Year}

1988 Texas Instruments Data Systems Group Supplier

\section*{Excellence Award}

Presented for demonstrated excellence in meeting Texas Instrument's requirements.

1987/1988 Bosch Group Recognition Award
Presented for quality and special performance as a supplier to the Bosch Group.

1987 Delco Electronics Award of Excellence
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Reducing A/D Errors in Microcontroller Applications
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Many significant benefits can be realized in an electronic product by converting analog signals into the digital domain. From drift-free signal filtering to extremely reliable signal detection. the digital domain offers a level of performance many times only approximated by its analog circuit-based counterpart. Once cost prohibitive. converting analog signals into the digital domain has become more cost effective. These decreasing costs, increasing digital semiconductor speeds, and the benefits of digital processing have contributed significantly to the increasing popularity of digital systems and to the rise of the digital system with built-in analog interfaces. One such popular system on silicon is the single-chip microcontroller unit (MCU). Now available from many manufacturers and in many forms. MCUs with resident analog interfaces like analog-to-digital converters (ADCs) and other on-chip peripherals can provide unsurpassed cost effectiveness to a product's design. The MCU with integral ADC may easily be used to convert analog signals in the digital domain with the convenience of an already defined on-chip ADC-to-CPU interface. In addition, the MCU offers the flexibility afforded to all software-based systems.
MCUs have liberated many board-level designers from selecting. designing. and debugging microprocessor peripherals in multichip assemblies. This type of highly integrated solution is becoming more popular than the multichip solution. Consequently. it is reasonable to expect that the practicing design engineer will eventually work with an MCU-based system. Yet, despite the advantages of the MCU system, some integrated peripherals such as the ADC offer new challenges to the designer. By incorporating a wide bandwidth linear system, such as an ADC, on the same die with a high-speed digital central processor unit (CPU), ADC performance can be adversely affected. Noisy ADC readings functionally manifest themselves in a range from merely annoying and relatively benign glitches to more catastrophic hard failures. In any case, an MCU-based system does not have to be at the mercy of poor MCU/ADC performance. Fortunately, by following some fairly rudimentary systems-level guidelines in the design phase of the MCU-based product, potential ADC performance problems can be avoided.

To resolve ADC performance issues, it is necessary to understand a little about the nature of the MCU and the various areas of susceptibility of several ADC types. Although much information presented in this application note assumes that the ADC is resident on-chip with the CPU, other converter types not typically found on-chip with MCUs are discussed for those instances in which a multichip combination is encountered. The following paragraphs also apply to these less frequent hardware combinations.

\author{
ADC TYPES
}

Even when the ADC is available on-chip with an MCU where the unpleasant task of interfacing and debugging the ADC-to-CPU interface is done, obtaining maximum performance from the ADC requires attention to application details of the given MCU/ADC combination. The type of design precautions and applications details needed to avoid problems varies as a function of the type of ADC used. Understanding the mechanics of the given ADC is crucial to improving performance.

ADCs may be categorized into five main categories: integrating, servo, flash, successive approximation, and hybrid. Although each type has unique capabilities and traits, each has surprisingly similar points of vulnerability.

The integrating converter has appeal for applications requiring high resolution ( 16 -bit or higher) and low cost. Because the basic converter is simply implemented (see Figure 1 (a)), hardware is minimized while high resolution is obtained. In addition, the integrating ADC may provide some noise immunity that is not feasible with higher speed designs. Although it is possible to build the integrating converter onto MCU chips (there is nothing technologically impeding such a construct), its lower speed has apparently been discouraged by MCU designers since it is currently not offered on an MCU by a major manufacturer.

Whereas the integrating converter tends to be the slowest of ADC types, the servo converter tends to have the highest resolution and fastest conversion times in its most recent advance-ment-the sigma-delta converter. The more traditional servo converter tries to balance the charge or voltage on an input comparator by using a feedback configuration (see Figure 1 (b)) to force slewing from a previous charge or voltage to the current input signal level applied to the other input of the same comparator. This process is followed by appropriately changing a digital counter up or down (in this form, the converter is often called a tracking converter). Before the sigma-delta variation, the servo converter was less popular than other converter types primarily due to its slew-rate limitation. Nothing about the servo converter would prevent its inclusion onto an MCU die; once BiCMOS processes improve, this converter type will probably become a popular feature of future MCUs (particularly the sigma-delta variation, most of which is linear circuitry).

Although the sigma-delta variation of the servo converter provides high-resolution conversions and maintains a relatively high throughput rate, the fastest type is the flash converter. By stringing together several voltage comparators (one per desired level to be detected), conversion bandwidths in excess of 100 MHz are now quite commonplace (see Figure 1 (c)), albeit at lower resolutions ( \(4-6\) bits are common). As the input voltage is applied to one input of all the comparators, a set of

(a) Integrating ADC

(b) Tracking/Servo ADC

(c) Flash ADC

(d) Successive Approximation ADC
reference voltages are applied to the other comparator inputs. After a period of time has elapsed, determined primarily by the propagation delays through the comparators, the discrete-level representation of the input voltage is available at the comparator outputs. Flash conversion, although incredibly fast, requires a tremendous number of devices to implement even modest-resolution converters. In addition to the number of transistors necessary to implement each comparator, the outputs of each comparator are typically input to a combinational logic array to form a desired output code. Consequently, this converter, which consumes much silicon area when compared to other converter types, has not been widely accepted by MCU designers and users.
The fourth ADC type is the successive-approximation converter (SAC). Of all current converter types, SAC is the most popular (see Figure 1(d)). This popularity is primarily due to its applicability to smaller circuit requirements, medium to fast conversion speeds, and medium- to high-resolution applications ( \(8-16\) bits). Like other converter types, the SAC uses a differential voltage comparator to compare the input signal with a reference voltage. By performing a binary search, conversion rates of one bit per clock are possible. Because only one comparator is typically required and the output code is inherent in the conversion process, circuitry and silicon surface area are reduced when compared with other conversion methods. Although the exact implementation varies from silicon-chromium-based to charge-redistribution, this ADC is currently the most prevalent type found on MCUs.

The fifth ADC category is the hybrid converter. In this case, the term "hybrid" is not used to reference a specific implementation approach, but rather implies combining one or more ADC types to form an ADC with different performance characteristics. For example, some of the faster and higher resolution ADCs now employ a hybridized technique which utilizes flash-conversion prescaling followed by an SAC. In this case, almost instantaneous prescaling is accomplished and easily interfaced to an existing SAC design. Hybrid converters are a very viable alternative as an MCU peripheral and may find eventual popularity in MCU designs when higher resolution converters are needed.

\section*{ADC NOISE SUSCEPTIBILITY}

The comparator is the cornerstone of the A/D conversion process. The ability of the comparator to announce the presence of small voltage/current differentials with large changes in its output voltage make the comparator invaluable to the \(A / D\) conversion process. Yet, this same feature also accounts for the largest potential source of ADC malfunction. Of course, degradation of the comparator's desired action, and hence the ADC, is most usually caused by unwanted noise. Two basic characteristics of the comparator affect noise susceptibility: bandwidth and power supply connections.

Wide bandwidth comparators easily respond to noise as well as to signals. Even in the low-speed integrating converter, the accuracy of measurement is heavily contingent upon the comparator's speed of operation. To illustrate, imagine that a

Figure 1. ADC Types
very slowly varying input signal has been applied to an input of such a comparator. For a single-slope integrating converter, the other comparator input will have a linearly increasing voltage (or other convenient shape) applied to it. As this voltage ramp increases, an independent digital counter (started at the same time the voltage ramp began) will count clock pulses provided by some timebase. When the voltage ramp finally exceeds the input voltage, the comparator will change state. If the comparator fails to respond to the voltage ramp in a timely fashion, the digital counter will register an incorrect count when compared to the results obtained by a perfectly fast comparator, implying that the response time (characterized by bandwidth) must be reasonably fast even in the slowest ADC types. Consequently, a wide bandwidth comparator will appropriately respond not only to input/reference signals but also to any other signal present at the comparator input terminals (including noise components superimposed upon the signals of interest).

The typical comparator uses some form of differential front end. The operation of the differential front end is dependent upon biasing networks that are ultimately connected to the supply terminals of the comparator. Therefore, the comparator should be considered as a five-terminal device - two differential inputs, one output, and two inputs to the biasing networks - for the purposes of designing with the ADC. The implication is that signals present at the supply terminals of an ADC, particularly the high-frequency signals typically superimposed on the power supply in digital systems, can affect comparator and ADC operation.

Due to the high bandwidth of the comparator found in ADCs, the designer of a given system should be extremely careful about the type and amount of signals allowed to reach the comparator stage of the ADC, particularly the power supply terminals. For this reason, some of the more mundane and overlooked aspects of electrical product design, such as printed circuit design and circuit interconnection, become increasingly critical to the success of the MCU/ADC system.

\section*{APPROPRIATE DESIGN TECHNIQUES}

Most of the MCU is digital. As seen in Figure 2, a major portion of the MC68HC11E9, a representative MCU, is digital circuitry. Thus, it is reasonable to assume that digital design practices will generally be employed when designing with the MCU. With an analog-based subsystem, such as the M68HC11 ADC, normally accepted digital design practices may not be sufficient to ensure satisfactory performance of the converter. As an illustration, consider noise levels normally found on the power supply of a typical high-speed HCMOS digital system. It is not unusual to find 100 mV PP broadband noise riding on top of the positive voltage rail. With a nominal 5 V HCMOS system, the resulting voltage drop, down to 4.9 V , is above the \(\mathrm{V}_{\mathrm{OH}}\) for HCMOS. Thus, the 100 mV signal will probably not upset circuit operation. When present in such a robust digital system (HCMOS), this 100 mV noise signal is a mere visual nuisance on the oscilloscope. Because of the theoretically infinite signal-to-noise ratio of digital gates, the presence of the 100 mV noise poses no practical threat.

However, when such a noise signal is inserted into an ADC system, the results can be much more dramatic. In an 8-bit ADC system with a nominal 5 V reference, this same 100 mV noise can result in a greater than 5-bit error in the ADC reading. Thus, an MCU system utilizing an ADC assumes a different electrical character that requires application of design practices not traditionally used in the design of digital systems.

What design practices should be used? To correct or avoid a noisy ADC/MCU design, separate the noisy signals from the sensitive ones. The challenge is to design a system in which this separation is practically realized. The closer to the ideal of completely separating the noisy signals from the sensitive ones, the better. For situations where the noisy and sensitive circuits cannot be completely separated, reduce the noise coupling as much as possible. Since it is difficult to axiomatically specify how to implement both concepts in all cases, a illustration will aid understanding and provide an analogy by which individual situations may be gauged.

Motorola tests \(100 \%\) of the ADCs found on their MCUs. Before any M68HC11 ADCs leave the factory, they have been tested and verified for specified ADC performance. Even so, it is possible to operate the M 68 HC 11 in an environment that causes the M68HC11 ADC to subsequently malfunction. These two scenarios in the life of such an MCU indicate not, strictly speaking, a parts-related anamoly, but rather a significant interaction of the part's characteristics with the electrical environment.

Typically, a large contributor to malfunction is the printed circuit board (PCB) layout. Since the PCB can influence many of the circuit parametrics (reactance, voltage, etc.), the PCB layout can help or hinder ADC performance. Yet, the PCB layout is not typically done by the circuit's designer. More importantly, laying out the PCB artwork, up to and including the width and placement of traces, is often performed by people without a detailed knowledge of correct electrical circuit design practices. Many PCB designers are only concerned with ensuring that they have connected all the points connected in the schematic. Although this has its economic advantages, this can be a dangerous proposition with regard to ADC performance. Figure 3 shows an example of such a PCB layout which, although it manages to distribute the power to all of the devices, provides several potential sources of ADC/MCU performance problems.

First, the MCU/ADC is placed farthest from the power terminal, meaning that the MCU return currents will be mixed with the digital circuit currents between the MCU and the power terminal. Although the MCU may not produce large return currents in the power return, high-speed digital circuits typically do. The inductance of PCB traces at high frequencies can be significant enough to produce large noise spikes when measured between the ground pin of the MCU and the ground terminal of the board.

Second, the opamp, which buffers the signals to the ADC inputs on the MCU, is physically located close to the MCU but is electrically located in a very poor place. As with the MCU, the opamp power supply return will be corrupted with high-frequency spikes. However, the voltage drops measured


Figure 2. MC68HC11E9 Block Diagram
between the opamp and the MCU will be even worse than those measured between the MCU and power terminal. When deciding which parts are to be jointly located on the PCB, the electrical impact of conductor distance and tolerance to any induced noise must be considered.
Third, the bypass capacitors, as shown, are ineffectual in reducing high-frequency noise on \(V_{D D}\). To perform the decoupling function properly, bypass capacitors should be attached
as close as possible to the IC power pins they are intended to bypass. In addition, PCB trace inductance should be minimized between the leads of the capacitor and the power pins.

Figure 3 illustrates a few of the PCB-related errors that can degrade ADC performance. Specific PCB designs involving MCU/ADCs should be carefully engineered. A better PCB layout is depicted in Figure 4, which corrects the defects shown in Figure 3.


Figure 3. Poor Layout Design


Figure 4. Improved Layout Design

\section*{A SPECIFIC MCU WITH ADC}

Other factors involving a more specific ADC system contribute to reduced ADC performance. Thus, this discussion will focus on the ADC system found on the Motorola M68HC11 Family of MCUs.
A unique implementation of an SAC, the standard M68HC11 ( 2 MHz bus) ADC provides a \(16 \mu \mathrm{~s} 8\)-bit A/D conversion with the convenience of an on-chip MCU peripheral. The ADC is a charge-redistribution SAC. The digital-to-analog converter (DAC) is implemented with capacitors rather than the usual R-2R silicon-chromium ( SiCr ) thin-film resistors. Although the SiCr resistor has the advantage over the commonly used diffused resistor in improved temperature stability and tracking, laser trimming is necessary to obtain ADC accuracies compatible with even medium-resolution converters. Processing this R-2R ladder presents a challenge since trimming one resistor in the network will change the current in the previously trimmed bit, requiring an iterative trimming process. Furthermore, the R-2R ladder requires careful control of the ON resistance in the MOS switches because the switches also determine the current flow through the R-2R network. The M68HC11 capacitive DAC avoids these shortcomings. The charge-redistribution method is easily fabricated using poly-poly capacitors. No trimming of the poly capacitors or MOS switches is required to obtain medium-resolution accuracies. As an added benefit, a sample-hold function, which extends the effective conversion bandwidth of the ADC, is an inherent byproduct of the redistribution technique.
The internal operatives of the M 68 HC 11 converter are relevant to preventing or reducing ADC errors. For converters using \(\mathrm{SiCr} \mathrm{R}-2 \mathrm{R}\) ladders, the impact of parametric phenomena may be different than for the \(\mathrm{M} 68 \mathrm{HC11}\). It is necessary to understand the nature and implementation of the ADC to realize the highest performance from it. To understand the M68HC11 conversion process, a 2 -bit example is presented (see Figure 5). A conversion is accomplished by a sequence of three operations. In the sample mode (see Figure 5(a)), the top plate is connected to \(\mathrm{V}_{\mathrm{L}}(0 \mathrm{~V})\), and the bottom plates are connected to the input voltage, \(\mathrm{V}_{\mathrm{X}}\), resulting in a stored charge on the top plate that is proportional to the input voltage. In the hold mode (see Figure 5(b)), the top switch is then opened, and the bottom plates are connected to \(\mathrm{V}_{\mathrm{L}}\). Since the charge on the top plate is conserved, its potential goes to \(-V_{X}\), which is the initial voltage at the input of the comparator. The approximation mode (see Figure 5(c)), begins by testing the value of the most significant bit by raising the bottom plate of the largest capacitor to the reference voltage, \(\mathrm{V}_{\mathrm{H}}\). The equivalent circuit is now actually a voltage divider between two equal capacitances. The output of the comparator, after each capacitor is switched, determines whether the bottom plate of that capacitor will remain at \(\mathrm{V}_{H}\) or be returned to \(\mathrm{V}_{\mathrm{L}}\) before the next capacitor is switched. Conversion proceeds in this manner until all bits have been deter-mined and the result is stored in the succes-sive-approximation register (SAR).
The following major sources of M68HC11 ADC errors controllable by external circuit parameters are discussed in the following paragraphs.

(a) Sample Mode

(b) Hold Mode

(c) Approximation Mode

Figure 5. ADC Conversion Modes

\section*{Leakage Current on ADC Input Pin}

The electrical model of an M68HC11 ADC input pin is shown in Figure 6. The problem is caused by \(n\)-channel device junction leakages at this node (there are no p-channel devices used here), which are worse at high temperatures. Consequently, the leakage current is (1) unidirectional and (2) bound by the maximum specification of 400 nA . This leakageinduced error would tend to only cause a static lowering of ADC results. To avoid leakage effects, the external circuit network feeding the ADC pin(s) should maintain impedances, which, in the presence of maximum leakage, would guarantee a maximum desired error. For example, if the maximum error (due to leakage) is desired to be \(\leq 1\) LSB with a 5 V reference voltage, then the maximum source impedance (resistance) feeding this pin should be \(50 \mathrm{k} \Omega=(\approx 19.5 \mathrm{mV} / 400 \mathrm{nA})\).

\section*{Charge Time on Sample Capacitor}

By lengthening the resistance-capacitance ( RC ) time constant, comprised of the source resistance feeding the ADC pin and the DAC capacitance evidenced at the pin during the sample mode, errors may result. However, given the size of the DAC input capacitance, the size of the source resistance necessary to induce these RC time-constant errors will probably be inundated by the effects of pin leakage described previously.

\section*{VDD/VSS and Input Terminal Noise}

The differential comparator used in the M68HC11 ADC derives its power from \(V_{D D}\) and \(V_{S S}\), the power pins that supply the rest of the M68HC11 (see Figure 7). The M68HC11,


NOTE: This analog switch is closed only during the 12 -cycle sample time.

Figure 6. Electrical Model of an M68HC11 ADC Input Pin


Figure 7. MC68HC11 ADC in Sample Mode
when considered with respect to ADC performance, is a source of noise, partially due to the waveshape and harmonics associated with square waves. In addition, the complex relationship between the primary M 68 HC 11 clock and related noise voltages are further complicated by dependance of the M68HC11 upon many software combinations, each sufficiently changing the noise characteristics eminating from the M 68 HC 11 . Therefore, ADC performance degradation, which is linked to noise generated on \(\mathrm{V}_{\mathrm{DD}} / \mathrm{V}_{\mathrm{SS}}\) by the M 68 HC 11 , can often appear related to execution of specific software combinations. As established earlier, this is due to the ADC wide bandwidth comparator.

\section*{NOTE}

Because the M68HC11 ADC uses a very wide bandwidth comparator capable of responding to noise components in excess of 20 MHz , it must be guarded against unwanted noise at its input terminals and \(V_{D D} / V_{S S}\) pins.

The reference to input terminal noise must be distinguished between noise externally superimposed on the input signal lines that is measured between a system reference and a given input signal (occurs from capacitive coupling between high-impedance ADC inputs and noisy signal sources or electro-magnetic interference) and voltage differentials experienced by different comparator inputs when referenced to each other. The importance of input terminal noise in this context is the presence of non-common-mode differential noise between the biasing networks in the comparator and the input lines. If, under noisy conditions, the same noise is presented to an input to the comparator and one of the supply (or other input) terminals, the common-mode rejection ratio (CMRR) capabilities of the comparator may prevent performance perturbations; whereas, noise presented to either terminal, with respect to system ground, may cause havoc (see Wide Bandwidth Input Signals). Efforts should be made to ensure that noise, if it cannot be reduced further, is also seen by the other comparator inputs to take advantage of the CMRR. Of the ADC error sources, this is one of the most challenging to control in a practical and effective manner.

\section*{Wide Bandwidth Input Signals}

A certain way to disrupt ADC function is to give the wide bandwidth comparator something to respond to other than the input signal of interest. By designing the electronics feeding the ADC inputs to pass input signals having frequencies that range from DC to purple, ADC problems are usually guaranteed. Thus, this fourth area is a common source of ADC malfunction.

\section*{Other Error Sources}

Although occurring less frequently and more subtlely, other error sources can also impact ADC performance: rate of conversion requests to a particular channel and interchannel charge-sharing. These sources and an estimate of the impact on a given M68HC11 system are presented in detail in M68HC11RM/AD, M68HC11 Reference Manual.

\section*{REAL-WORLD EXAMPLE}

When discussing the mechanics of noise phenomena in MCU/ADC systems, it is very difficult to understand how large the noise problem is, how well it is expected to respond to corrective action, and how closely the analysis matches the real world. To help resolve these problems, an actual troubleshooting session involving an M68HC11-based assembly is presented.

The subject assembly, an industrial controller, is a typical MCU/CPU installation utilizing the M68HC11 in expanded multiplexed (CPU) mode. The customer designed the program memory to expand to \(32 \mathrm{~K} \times 8\), RAM to \(2 \mathrm{~K} \times 8\), an external address decoder, some additional digital I/O lines, and analog buffers feeding the ADC inputs. Built on a six-layer PCB, the assembly had the benefit of separate ground and voltage planes, and was designed to be placed in a Faraday shield providing electromagnetic compatability. This assembly was designed without the aid of any of the concepts presented in this applcation note. Understandably, the customer was having difficulty with ADC performance.

\section*{The Problem}

Functionally, the ADC noise problem manifested itself as an extreme shutdown condition in the final product. Since this assembly provides control to industrial equipment, conditions sensed by this controller could indicate dangerous conditions, which must be dealt with by severe and swift action, including functional shutdown of the controlled equipment. To achieve the safest response times and largest safety margins to such stimuli, the software designers of this system required \(64 \mu \mathrm{~s}\) continuous conversions ( \(>15 \mathrm{kHz}\) sampling frequency). Once they were run through part of the designer's algorithmn, the conversion results could not deviate more than \(\pm 2\) counts from the actual system ADC measurements. The M68HC11 was selected for this application because of its high level of integration as well as the \(\pm 1\) LSB 8 -bit ADC performance. Errors many times this specification were encountered in the application. Unfortunately, evaluation of the extent of the ADC errors concerned only functional operation of the assembly and manual inspection of ADC values read with an in-circuit emulator, making the problem more serious. An attempt by the hardware engineers to reduce the noise by changing the bypassing scheme yielded no apparent change in the pattern of product shutdown. In this case, the lack of quantitative data convinced the engineers that they had no control over the problem, diverting attention from the actual cause. When dealing with these types of problems, always instrument the problem correctly that is, ensure measuring techniques used to observe the malfunction follow these guidelines:
1. Quantify the \(A / D\) conversion process with regard to frequency of occurrence and magnitude of error.
2. Ensure that the measurements are with sufficient resolution so that minute improvements or degradations in performance may be monitored and evaluated.
3. Ensure that the number of observed conversions are similar to product usage or are statistically significant to allow inference from the measured sample to actual product operation.

Had the assembly been properly monitored, an improvement in ADC performance with the different bypassing scheme would have been evident (see Figure 8). These two histograms display ranges of \(A / D\) conversion values on the vertical axis and the hit rate (percent of total readings landing within the boundaries of the selected ADC reading range) on the horizontal axis. As shown, there was approximately a 3\% improvement in the number of correct A/D conversions with new bypassing. To detect these changes, the EPROM on the controller PCB was probed with a fairly simple logic analyzer. The logic analyzer was then configured to trigger on accesses to a location in memory containing the results of \(A / D\) conversions. By utilizing the simple statistics options given by the analyzer, each quantitative improvement in ADC performance was observed.

\section*{The Perfect Circuit}

After sufficiently instrumenting the offending assembly, the next step is to attempt to duplicate ideal operating conditions for the MCU/ADC. Since every M68HC11 is \(100 \%\) tested for ADC performance before leaving the factory, in the absence of externally induced failure, the M 68 HC 11 should maintain factory performance given identical operating conditions. By operating the M 68 HC 11 in near perfect conditions, the engineer learns if the failure is or is not parts related. The motivating factor for this case, however, concerned 1 VPP noise (spaced in time at approximately the E-clock rate of the M68HC11) found when measuring VDD at the pins of the M68HC11. Given what is known about the ADC comparator, it was best for system performance to reduce this VDD noise as much as possible. The noise was reduced by isolating the power bussing to the M68HC11 only. The PCB foil was cut to \(\mathrm{V}_{\mathrm{DD}}, \mathrm{V}_{\text {SS }}\). \(V_{R L}\),
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|}
\hline \[
\begin{aligned}
& \text { ADC } \\
& \text { READING } \\
& \text { (HEX) }
\end{aligned}
\] & FREQ. & \multicolumn{4}{|l|}{CONDITIONS: NO BYPASSING TOTAL SAMPLES = 8192} & \multicolumn{5}{|c|}{M68HC11 INDUSTRIAL CONTROLLER} \\
\hline 0-90 & \(0 \%\) & \multicolumn{9}{|l|}{} \\
\hline 91-98 & 95\% & \multicolumn{8}{|l|}{} & \\
\hline 99-A0 & 1\% & \multicolumn{9}{|l|}{} \\
\hline A1-A8 & \(1 \%\) & \multicolumn{9}{|l|}{\(\square\)} \\
\hline A9-80 & 1\% & \multicolumn{9}{|l|}{} \\
\hline B1-B8 & 0\% & \multicolumn{9}{|l|}{} \\
\hline B9-C0 & 2\% & \multicolumn{9}{|l|}{} \\
\hline C1-FF & 0\% & \multicolumn{9}{|l|}{} \\
\hline & & \begin{tabular}{cc|c}
1 & 5 & 10 \\
(EXPANDED SCALE)
\end{tabular} & 1
30
PER & 40 & 1
50
CE & 60 & 70 & 1
80 & 90 & \[
100
\] \\
\hline
\end{tabular}
(a) No Bypassing
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|c|}
\hline \[
\begin{gathered}
\text { ADC } \\
\text { READING } \\
\text { (HEX) }
\end{gathered}
\] & FREQ. & \multicolumn{5}{|l|}{CONDITIONS: \(0.1 \mu \mathrm{~F}\) CERAMIC BYPASS TOTAL SAMPLES = 8192} & \multicolumn{5}{|c|}{M68HC11 INDUSTRIAL CONTROLLER} \\
\hline 0.90 & 0 \% & \multicolumn{10}{|l|}{} \\
\hline 91-98 & 98\% & \multicolumn{10}{|l|}{} \\
\hline 99-A0 & 1\% & \multicolumn{10}{|l|}{} \\
\hline A1-A8 & 0\% & \multicolumn{10}{|l|}{} \\
\hline A9-B0 & 0\% & \multicolumn{10}{|l|}{} \\
\hline B1-B8 & \(0 \%\) & \multicolumn{10}{|l|}{} \\
\hline B9-C0 & 0\% & \multicolumn{10}{|l|}{\multirow[t]{2}{*}{}} \\
\hline C1-FF & 0\% & & & & & & & & & & \\
\hline & 10 & \begin{tabular}{|c|c}
1 & 10 \\
5 & 10
\end{tabular} & 20 & 1
30
PER & 40 & 1
50
CE & 60 & 70 & 1 80 & 90 & 100 \\
\hline
\end{tabular}
(b) Improved Bypassing

NOTE: Readings are rounded to nearest \(1 \%\) value. Columns with \(0 \%\) and a grey bar imply \(>0 \%\) and \(<0.5 \%\).

Figure 8. Effect of Bypassing Only
and \(\mathrm{V}_{\mathrm{RH}}\) leading to the M 68 HC 11 . Discrete wires were then run directly to an external laboratory-grade power supply. With this configuration, measurements were taken as before. The results of these measurements are shown in Figure 9. As the graph shows, an improvement was made over the nonbypassed assembly. Instead of a \(5 \%\) error in the ADC readings, less than \(0.5 \%\) of the readings were outside of the expected range. Also evident in Figure 9 is the presence of full-scale errors as before. At this point, a bypass capacitor was soldered between the M68HC11 VDD and VSS pins. The resulting measurements, shown in Figure 10, are an apparent improvement over the previous non-bypassed assembly. However, due to the granularity of the measurement reported by the logic analyzer, it cannot be stated quantitatively how
much the bypassing improved the condition. Further manipulation of the bypassing network failed to improve the readings in a discernible manner.

At this point, only power distribution busses had been manipulated to reduce ADC errors. Another part of the ADC circuit manipulated to yield some improvement was the linear portion interfacing the MCU to the various input signals. Consisting of 324-type opamps operated at unity gain, this linear buffer provided a low-impedance source for the ADC input multiplexer. Although not usually considered a wideband opamp, it proved too wideband for this system. Most data coming from the devices feeding the 324 buffers were slowly varying DC or signals with frequencies below 500 Hz . Yet, the full bandwidth of signals allowed by the buffer passed unaltered to
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|c|}
\hline \[
\underset{\substack{\text { READC } \\ \text { RHEX) }}}{\substack{\text { READ }}}
\] & FREQ. & \multicolumn{5}{|l|}{CONDITIONS: SEPARATE MCU POWER SUPPLY TOTAL SAMPLES \(=16384\)} & \multicolumn{5}{|c|}{M68HC11 INDUSTRIAL CONTROLLER} \\
\hline 0.80 & \multicolumn{11}{|l|}{\(0 \%\)} \\
\hline 81-98 & \multicolumn{11}{|l|}{100\%} \\
\hline 99-A0 & \multicolumn{11}{|l|}{0\% []} \\
\hline A1-A8 & \multicolumn{11}{|l|}{0\%} \\
\hline A9-B0 & \multicolumn{11}{|l|}{0\%} \\
\hline B1-88 & \multicolumn{11}{|l|}{0\%} \\
\hline 89-C0 & \multicolumn{11}{|l|}{0\%} \\
\hline C1.FF & \multicolumn{11}{|l|}{0\%} \\
\hline & \multicolumn{3}{|c|}{(EXPANDED SCALE)} & \multicolumn{7}{|l|}{PERCENT OCCURRENCE} & 100 \\
\hline
\end{tabular}

NOTE: Readings are rounded to nearest \(1 \%\) value. Columns with \(0 \%\) and a grey bar imply \(>0 \%\) and \(<0.5 \%\).

Figure 9. Separate MCU Power Supply
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|c|}
\hline \[
\begin{aligned}
& \text { ADC } \\
& \text { READING } \\
& (H E X)
\end{aligned}
\] & FREQ. & \multicolumn{5}{|l|}{CONDITIONS: SEPARATE MCU POWER SUPPLY \& BYPASS TOTAL SAMPLES \(=16384\)} & \multicolumn{5}{|c|}{M68HC11 INDUSTRIAL CONTROLLER} \\
\hline 0-80 & \multicolumn{11}{|l|}{0\%} \\
\hline 81.98 & \multicolumn{11}{|l|}{100\%} \\
\hline 99-A0 & \multicolumn{11}{|l|}{0\%} \\
\hline A1-A8 & \multicolumn{11}{|l|}{0\%} \\
\hline A9-B0 & \multicolumn{11}{|l|}{0\%} \\
\hline B1-B8 & \multicolumn{11}{|l|}{0\%} \\
\hline B9-C0 & \multicolumn{11}{|l|}{0\%} \\
\hline C1-FF & \multicolumn{11}{|l|}{\(0 \%\)} \\
\hline & \multirow[t]{3}{*}{0} & & \multirow{3}{*}{20} & ! & ! & 1 & 1 & i & & & \\
\hline & & 510 & & 30 & 40 & 50 & 60 & 70 & 80 & 0 & 100 \\
\hline & & (EXPANDED SCALE) & & \multicolumn{3}{|l|}{PERCENT OCCURRENCE} & & & & & \\
\hline
\end{tabular}

NOTE: Readings are rounded to nearest \(1 \%\) value. Columns with \(0 \%\) and a grey bar imply \(>0 \%\) and \(<0.5 \%\).

Figure 10. Separate MCU Power Supply with \(0.1 \mu\) F Bypass
the ADC inputs. This manipulation violated a design guideline that urges the designer to tailor the bandwidth of each ADC channel to the bandwidth of the input signal. By properly filtering the input to the \(A D C\), frequencies that may prove troublesome if left unfiltered will not be allowed to pass to the ADC input. To test the affect of this guideline on this specific industrial controller, \(0.01 \mu \mathrm{~F}\) capacitors were soldered to the ADC input pins at the M68HC11. The measurements taken with this configuration (see Figure 11) showed significant improvement. As shown in Figure 11, there were still occasional occurrences of out-of-spec ADC readings.
In the absence of other guidelines, the only choice left to achieve specified ADC performance was to refine the implementation of the existing guidelines. The second guideline, duplicate ideal operating conditions, is usually the most likely candidate for improvement. One of the corollaries to duplicating ideal operating conditions is reducing unwanted interaction between adjacent circuit segments. In this case, VDD noise had not been completely eradicated. Rather than inserting a local IC regulator for just the \(\mathrm{M} 68 \mathrm{HC11}\), an alternative method
of \(V_{D D}\) isolation was attempted: a series diode with \(V_{D D}\) forming a peak detector with the bypass cap. Out-of-spec ADC errors were totally eliminated (see Figure 12(a)). To check the thoroughness of this last circuit fix, the range of sensitivity for the ADC result range of interest was changed on the logic analyzer. By changing the range to show values between (94) \({ }_{16}\) and (96) 16 , inclusively, the \(\pm 1\) LSB spec could be observed directly. The results of this measurement run are shown in Figure 12(b).

\section*{SUMMARY}

The highly integrated MCU can be a cost-effective design tool. With the breadth of MCU choices available to the circuit designer these days, analog circuit functions may now often be implemented by MCUs with integral ADCs. By following the practical guidelines presented in this application note during the design phase, the MCU-based product design using the on-chip ADC can achieve its full cost-effective potential.


NOTE: Readings are rounded to nearest \(1 \%\) value. Columns with \(0 \%\) and a grey bar imply \(>0 \%\) and \(<0.5 \%\).

Figure 11. Capacitor on ADC Pin
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|}
\hline \[
\begin{gathered}
\text { ADC } \\
\text { READING } \\
(H E X)
\end{gathered}
\] & FREQ. & \multicolumn{4}{|l|}{CONDITIONS: DIODE \(\mathbb{N}^{\text {V }}\) DD TOTAL SAMPLES \(=167.9 \mathrm{~K}\)} & \multicolumn{5}{|c|}{M68HC11 INDUSTRIAL CONTROLLER} \\
\hline 0-80 & \(0 \%\) & \multicolumn{9}{|l|}{} \\
\hline 81-98 & 100\% & \multicolumn{9}{|l|}{} \\
\hline 99-A0 & 0\% & & & & & & & & & \\
\hline A1-A8 & 0\% & \multicolumn{9}{|l|}{\multirow[t]{5}{*}{}} \\
\hline A9-B0 & 0\% & & & & & & & & & \\
\hline B1-88 & 0\% & & & & & & & & & \\
\hline B9-C0 & 0\% & & & & & & & & & \\
\hline C1-FF & 0\% & & & & & & & & & \\
\hline \multicolumn{11}{|r|}{\multirow[b]{3}{*}{}} \\
\hline & & & & & & & & & & \\
\hline & & & & & & & & & & \\
\hline
\end{tabular}
(a) Diode in \(\mathrm{V}_{\mathrm{DD}}\)
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|}
\hline ADC READING (HEX) & FREQ. & \multicolumn{4}{|l|}{CONDITIONS: FINAL CIRCUIT TOTAL SAMPLES \(=167.9 \mathrm{~K}\)} & \multicolumn{5}{|c|}{M68HC11 INDUSTRIAL CONTROLLER} \\
\hline \(0-93\) & 0 \% & \multicolumn{9}{|l|}{} \\
\hline 94-96 & 100\% & \multicolumn{9}{|l|}{} \\
\hline 97-A0 & 0\% & \multicolumn{9}{|l|}{\multirow[t]{6}{*}{}} \\
\hline A1-A8 & 0\% & & & & & & & & & \\
\hline A9-B0 & 0\% & & & & & & & & & \\
\hline B1-88 & \(0 \%\) & & & & & & & & & \\
\hline B9-C0 & 0\% & & & & & & & & & \\
\hline C1-FF & 0\% & & & & & & & & & \\
\hline \multicolumn{11}{|r|}{} \\
\hline
\end{tabular}
(b) Tightened ADC Range

NOTE: Readings are rounded to nearest \(1 \%\) value. Columns with \(0 \%\) and a grey bar imply \(>0 \%\) and \(<0.5 \%\).

Figure 12. \(\mathrm{V}_{\mathrm{DD}}\) Diode and Tightened ADC Range

\title{
AN1060
}

\title{
MC68HC11 Bootstrap Mode
}

\author{
Prepared by: Jim Sibigtroth \\ Mike Rhoades \\ John Langan
}

\section*{INTRODUCTION}

M68HC11 MCUs have a bootstrap mode that allows a user-defined program to be loaded into the internal random access memory (RAM) by way of the serial communications interface (SCI); the M68HC11 then executes this loaded program. The loaded program can do anything a normal user program can do as well as anything a factory test program can do because protected control bits are accessible in bootstrap mode. Although the bootstrap mode is a single-chip mode of operation, expanded mode resources are accessible because the mode control bits can be changed while operating in the bootstrap mode.

This application note explains the operation and application of the M68HC11 bootstrap mode. Although the basic concepts associated with this mode are quite simple, the more subtle implications of these functions require careful consideration. Useful applications of this mode are overlooked due to an incomplete understanding of the bootstrap mode. Also, common problems associated with the bootstrap mode could be avoided by a more complete understanding of its operation and implications.
Topics included in this application note are as follows:
- Basic operation of the M68HC11 bootstrap mode
- General discussion of bootstrap mode uses
- Detailed explanation of on-chip bootstrap logic
- Detailed explanation of bootstrap firmware
- Bootstrap firmware vs. EEPROM security
- Incorporating the bootstrap mode into a system
- Driving bootstrap mode from another M68HC11
- Driving bootstrap mode from a personal computer
- Common bootstrap mode problems
- Variations for specific versions of M68HC11
- Commented listings for selected M68HC11 bootstrap ROMs

\section*{BASIC BOOTSTRAP MODE}

This section describes only basic functions of the bootstrap mode. Other functions of the bootstrap mode are described in detail in the remainder of this application note.
When an M68HC11 is reset in bootstrap mode, the reset vector is fetched from a small internal read-only memory (ROM) called the bootstrap ROM or (boot ROM). The firmware program in this boot ROM then controls the bootloading pro-
cess. First, the on-chip SCI is initialized. The first character received (\$FF) determines which of two possible baud rates should be used for the remaining characters in the download operation. Next, a binary program is received by the SCl system and is stored in RAM. Finally, a jump instruction is executed to pass control from the bootloader firmware to the user's loaded program. Bootstrap mode is useful both at the component level and after the MCU has been embedded into a finished user system.

At the component level, Motorola uses the bootstrap mode to control a monitored burn-in program for the on-chip electrically erasable programmable read-only memory (EEPROM). Units to be tested are loaded into special circuit boards that each hold fifty MCUs. These boards are then placed in burn-in ovens. Driver boards outside the ovens download an EEPROM exercise and diagnostic program to all fifty MCUs in parallel. The MCUs under test independently exercise their internal EEPROM and monitor programming and erase operations. This technique could be utilized by an end user to load program information into the EPROM or EEPROM of an M68HC11 before it is installed into an end product. As in the burn-in setup, many M68HC11s can be gang programmed in parallel. This technique can also be used to program the EPROM of finished products after final assembly.

Motorola also uses bootstrap mode for programming target devices on the M68HC11EVM Evaluation Modules. Because bootstrap mode is a privileged mode like special test, the EEPROM-based configuration register (CONFIG) can be programmed using bootstrap mode on the EVM.

The greatest benefits from bootstrap mode are realized by designing the finished system so that bootstrap mode can be used after final assembly. The finished system need not be a single-chip mode application for the bootstrap mode to be useful because the expansion bus can be enabled after resetting the MCU in bootstrap mode. Allowing this capability requires almost no hardware or design cost and the addition of this capability is invisible in the end product until it is needed.

The ability to control the embedded processor through downloaded programs is achieved without the disassembly and chip-swapping usually associated with such control. This mode provides an easy way to load non-volatile memories such as EEPROM with calibration tables or to program the application firmware into a one-time programmable (OTP) MCU after final assembly.

Another powerful use of bootstrap mode in a finished assembly is for final test. Short programs can be downloaded to check parts of the system, including components and circuitry external to the embedded MCU. If any problems appear during product development, diagnostic programs can be downloaded to find the problems, and corrected routines can be downloaded and checked before incorporating them into the main application program.

Bootstrap mode can also be used to interactively calibrate critical analog sensors. Since this calibration is done in the final assembled system, it can compensate for any errors in discrete interface circuitry and cabling between the sensor and the analog inputs to the MCU. Note that this calibration routine is a downloaded program that does not take up space in the normal application program.

\section*{BOOTSTRAP MODE LOGIC}

In the MC68HC11 very little logic is dedicated to the bootstrap mode: Thus, this mode adds almost no extra cost to the MCU system. The biggest piece of circuitry for bootstrap mode is the small boot ROM. This ROM is 192 bytes in the original MC68HC11A8, but some of the newest members of the M68HC11 Family have as much as 448 bytes to accommodate added features. Normally, this boot ROM is present in the memory map only when the MCU is reset in the bootstrap mode to prevent interference with the user's normal memory space. The enable for this ROM is controlled by the read boot ROM (RBOOT) control bit in the highest priority interrupt (HPRIO) register. The RBOOT bit can be written by software whenever the MCU is in special test or special bootstrap modes; when the MCU is in normal modes, RBOOT reverts to zero and becomes a read-only bit. All other logic in the MCU would be present whether or not there was a bootstrap mode.

Figure 1 shows the composite memory map of the MC68HC711E9 in its four basic modes of operation, including bootstrap mode. The active mode is determined by the mode \(A\) (MDA) and special mode (SMOD) control bits in the HPRIO control register. These control bits are in turn controlled by the state of the mode \(A\) (MODA) and mode \(B\) (MODB) pins during reset. Table 1 shows the relationship between the state of these pins during reset, the selected mode, and the state of the MDA, SMOD, and RBOOT control bits. Refer to the composite memory map and Table 1 for the following discussion.

The MDA control bit is determined by the state of the MODA pin as the MCU leaves reset. MDA selects between single-chip and expanded operating modes. When MDA is zero, a single-chip mode is selected, either normal single chip or special bootstrap mode. When MDA is one, an expanded mode is selected, either normal expanded mode or special test mode.

The SMOD control bit is determined by the inverted state of the MODB pin as the MCU leaves reset. SMOD controls whether a normal mode or a special mode is selected. When SMOD is zero, one of the two normal modes is selected, either normal single-chip or normal expanded mode. When SMOD is one, one of the two special modes is selected, either special bootstrap mode or special test mode. When either special mode is in effect (SMOD = 1), certain privileges are in effect -

\section*{Table 1. Mode Selection Summary}
\begin{tabular}{|c|c|c|c|c|c|}
\hline \multicolumn{2}{|c|}{ Input Pins } & & \multicolumn{3}{c|}{ Control Bits in HPRIO } \\
\cline { 5 - 6 } \cline { 4 - 5 } & \multirow{3}{*}{ MODB } & MODA & Mode Seled & RBOOT & SMOD \\
MDA \\
\hline 1 & 0 & Normal Single Chip & 0 & 0 & 0 \\
\hline 1 & 1 & Normal Expanded & 0 & 0 & 1 \\
\hline 0 & 0 & Special Bootstrap & 1 & 1 & 0 \\
\hline 0 & 1 & Special Test & 0 & 1 & 1 \\
\hline
\end{tabular}
i.e., the ability to write to the mode control bits and fetching the reset and interrupt vectors from \$BFxx rather than \$FFxx.

The alternate vector locations are achieved by simply driving address bit A14 low during all vector fetches if \(\mathrm{SMOD}=1\). For special test mode, the alternate vector locations assure that the reset vector can be fetched from external memory space so the test system can control MCU operation. In special bootstrap mode, the small boot ROM is enabled in the memory map by RBOOT \(=1\) so the reset vector will be fetched from this ROM and the bootloader firmware will control MCU operation.

RBOOT is reset to one in bootstrap mode to enable the small boot ROM. In the other three modes, RBOOT is reset to zero to keep the boot ROM out of the memory map. While in special test mode, SMOD = 1; which allows the RBOOT control bit to be written to one by software to enable the boot ROM for testing purposes.

\section*{BOOT ROM FIRMWARE}

The main program in the boot ROM is the bootloader, which is automatically executed as a result of resetting the MCU in bootstrap mode. Some newer versiors of the M68HC11 Family have additional utility programs that can be called from a downloaded program. One utility is available to program EPROM or OTP versions of the M68HC11. A second utility allows the contents of memory locations to be uploaded to a host computer. In the MC68HC711K4 boot ROM, a section of code is used by Motorola for stress testing the on-chip EEPROM. These test and utility programs are similar to self-test ROM programs in other MCUs except that the boot ROM does not use valuable space in the normal memory map.

Bootstrap firmware is also involved in an optional EEPROM security function on some versions of the M68HC11. This EEPROM security feature prevents a software pirate from seeing what is in the on-chip EEPROM. The secured state is invoked by programming the no security (NOSEC) EEPROM bit in the CONFIG register. Once this NOSEC bit is programmed to zero, the MCU will ignore the mode A pin and always come out of reset in normal single-chip mode or special bootstrap mode, depending on the state of the mode B pin. Normal single-chip mode is the usual way a secured part would be used. Special bootstrap mode is used to disengage the security function (only after the contents of EEPROM and RAM have been erased). Refer to the M68HC11RM/AD, M68HC11 Reference Manualfor additional information on the security mode and complete listings of the boot ROMs that support the EEPROM security functions.

\section*{AUTOMATIC SELECTION OF BAUD RATE}

The bootloader program in the MC68HC711E9 accommodates either of two baud rates. The higher of these baud rates (7812 baud at a \(2-\mathrm{MHz}\) E-clock rate) is used in systems that operate from a binary frequency crystal such as \(2^{23} \mathrm{~Hz}(8.389\) MHz ). At this crystal frequency the baud rate is 8192 baud which was used extensively in automotive applications based on the MC6801 MCU. The second baud rate available to the M 68 HC 11 bootloader is 1200 baud at a \(2-\mathrm{MHz}\) E-clock rate. Some of the newest versions of the M68HC11 accommodate other baud rates using the same differentiation technique explained here. Refer to the reference numbers in square brackets in Figure 2 during the following explanation.


NOTE: Software can change some aspects of the memory map after reset.

Figure 1. MC68HC711E9 Composite Memory Map


Figure 2. Automatic Detection of Baud Rate

Figure 2 shows how the bootloader program differentiates between the default baud rate ( 7812 baud at a \(2-\mathrm{MHz}\) E-clock rate) and the alternate baud rate ( 1200 baud at a \(2-\mathrm{MHz}\) E-clock rate). The host computer sends an initial \$FF character, which is used by the bootloader to determine the baud rate that will be used for the downloading operation. The top half of Figure 2 shows normal reception of \$FF. Receive data samples at [1] detect the falling edge of the start bit and then verify the start bit by taking a sample at the center of the start bit time. Samples are then taken at the middle of each bit time [2] to reconstruct the value of the received character (all ones in this case). A sample is then taken at the middle of the stop bit time as a framing check (a one is expected) [3]. Unless another character immediately follows this \$FF character, the receive data line will idle in the high state as shown at [4]

The bottom half of Figure 2 shows how the receiver will incorrectly receive the \$FF character that is sent from the host at 1200 baud. Because the receiver is set to 7812 baud, the receive data samples are taken at the same times as in the upper half of Figure 2. The start bit at 1200 baud [5] is 6.5 times as long as the start bit at 7812 baud [6].

Samples taken at [7] detect the falling edge of the start bit and verify it is a logic zero. Samples taken at the middle of what the receiver thinks are the first five bit times [8] detect logic zeros. The sample taken at the middle of what the receiver thinks is bit 5 [ 9 ] may detect either a zero or a one because the receive data has a rising transition at about this time. The samples for bits 6 and 7 detect ones, causing the receiver to think the received character was \(\$ C 0\) or \(\$ E 0\) [10] at 7812 baud instead of the \$FF which was sent at 1200 baud. The stop bit sample detects a one as expected [11], but this detection is actually in the middle of bit 0 of the 1200 baud \(\$\) FF character. The SCl receiver is not confused by the rest of the 1200 baud \$FF character because the receive data line is high [12] just as it would be for the idle condition. If a character other than \$FF is sent as the first character, an SCI receive error could result.

\section*{MAIN BOOTLOADER PROGRAM}

Figure 3 is a flowchart of the main bootloader program in the MC68HC711E9. This bootloader demonstrates the most important features of the bootloaders used on all M68HC11 Family members. For complete listings of other M68HC11 versions refer to Listings 3-8 at the end of this application note, and
appendix B of the M68HC11RM/AD, M68HC11 Feference Manual.
The reset vector in the boot ROM points to the start [1] of this program. The initialization block [2] establishes starting conditions and sets up the SCl and port D . The stack pointer is set because there are push and pull instructions in the bootloader program. The X index register is pointed at the start of the register block ( \(\$ 1000\) ) so indexed addressing can be used. Indexed addressing takes one less byte of ROM space than extended instructions, and bit manipulation instructions are not available in extended addressing forms. The port \(D\) wire-OR mode (DWOM) bit in the serial peripheral interface control register (SPCR) is set to configure port D for wired-OR operation to minimize potential conflicts with external systems that use the PD1/TxD pin as an input. The baud rate for the SCI is initially set to 7812 baud at a \(2-\mathrm{MHz}\) E-clock rate but can automatically switch to 1200 baud based on the first character received. The SCI receiver and transmitter are enabled. The receiver is required by the bootloading process, and the transmitter is used to transmit data back to the host computer for optional verification. The last item in the initialization is to set an intercharacter delay constant used to terminate the download when the host computer stops sending data to the MC68HC711E9. This delay constant is stored in the timer output compare 1 (TOC1) register, but the on-chip timer is not used in the bootloader program. This example illustrates the extreme measures used in the bootloader firmware to minimize memory usage. However such measures are not usually considered good programming technique because they are misleading to someone trying to understand the program.
After initialization, a break character is transmitted [3] by the SCI . By connecting the TxD pin to the RxD pin (with a pullup because of port \(D\) wired-OR mode), this break will be receivedas a \(\$ 00\) character and cause an immediate jump [4] to the start of the on-chip EEPROM (\$B600 in the MC68HC711E9). This feature is useful to pass control to a program in EEPROM essentially from reset. Refer to COMMON BOOTSTRAP MODE PROBLEMS before using this feature.
If the first character is received as \(\$ F F\), the baud rate is assumed to be the default rate ( 7812 baud at a \(2-\mathrm{MHz}\) E-clock rate). If \$FF was sent at 1200 baud by the host, the SCl will receive the character as \(\$ E 0\) or \(\$ C 0\) because of the baud rate mismatch, and the bootloader will switch to 1200 baud [5] for the rest of the download operation. When the baud rate is switched to 1200 baud, the delay constant used to monitor the
intercharaiter delay must also be changed to reflect the new character time.

At [6], the Y index register is initialized to \(\$ 0000\) to point to the start of on-chip RAM. The index register \(Y\) is used to keep track of where the next received data byte will be stored in RAM. The main loop for loading begins at [7].

The number of data bytes in the downloaded program can be any number between zero and 512 bytes (the size of on-chip RAM). This procedure is called 'variable-length download' and is accomplished by ending the download sequence when an idle time of at least four character times occurs after the last character to be downloaded. In M68HC11 Family members which have 256 bytes of RAM, the download length is fixed at exactly 256 bytes plus the leading \$FF character.

The intercharacter delay counter is started [8] by loading the delay constant from TOC1 into the X index register. The 19-E-cycle wait loop is executed repeatedly until either a character is received [9] or the allowed intercharacter delay time expires [10]. For 7812 baud, the delay constant is \(10,241 \mathrm{E}\) cycles ( \(539 \times 19\) E cycles per loop). Four character times at 7812 baud is 10,240 E cycles (baud prescale of 4 X baud divider of 4 X 16 internal SCI clocks/bit time X 10 bit times/character \(X 4\) character times). The delay from reset to the initial \(\$ \mathrm{FF}\) character is not critical since the delay counter is not started until after the first character ( \(\$ \mathrm{FF}\) ) is received.

To terminate the bootloading sequence and jump to the start of RAM without downloading any data to the on-chip RAM, simply send \$FF and nothing else. This feature is similar to the jump to EEPROM at [4] except the \$FF causes a jump to the start of RAM. This procedure requires that the RAM has been loaded with a valid program since it would make no sense to jump to a location in uninitialized memory.

After receiving a character, the downloaded byte is stored in RAM [11]. The data is transmitted back to the host [12] as an indication that the download is progressing normally. At [13], the RAM pointer is incremented to the next RAM address. If the RAM pointer has not passed the end of RAM, the main download loop (from [7] to [14]) is repeated.

When all data has been downloaded, the bootloader goes to [16] because of an intercharacter delay timeout [10] or because the entire 512-byte RAM has been filled [15]. At [16], the \(X\) and \(Y\) index registers are set up for calling the PROGRAM utility routine, which saves the user from having to do this in a downloaded program. The PROGRAM utility is fully explained in EPROM PROGRAMMING UTILITY. The final step of the bootloader program is to jump to the start of RAM [17], which starts the user's downloaded program.


Figure 3. MC68HC711E9 Bootloader Flowchart

\section*{UPLOAD UTILITY}

The UPLOAD utility subroutine transfers data from the MCU to a host computer system over the SCI serial data link. Note that M68HC11 versions that support EEPROM security do not include this utility. Verification of EPROM contents is one example of how the UPLOAD utility could be used. Before calling this program, the \(Y\) index register is loaded (by user firmware) with the address of the first data byte to be uploaded. If a baud rate other than the current SCI baud rate is to be used for the upload process, the user's firmware must also write to the BAUD register. The UPLOAD program sends successive bytes of data out the SCI transmitter until a reset is issued (the upload loop is infinite). For a complete commented listing of the UPLOAD utility, refer to Listings at the back of this application note.

\section*{EPROM PROGRAMMING UTILITY}

The EPROM programming utility is one way of programming data into the internal EPROM of the MC68HC711E9 MCU. An external \(12-\mathrm{V}\) programming power supply is required to program on-chip EPROM. The simplest way to use this utility program is to bootload a three-byte program consisting of a single jump instruction to the start of the PROGRAM utility program (\$BF00). The bootloader program sets the \(X\) and \(Y\) index registers to default values before jumping to the downloaded program (see [16] at the bottom of Figure 3). When the host computer sees the \$FF character, data to be programmed into the EPROM is sent, starting with the character for location \(\$ \mathrm{DOOO}\). After the last byte to be programmed is sent to the MC68HC711E9 and the corresponding verification data is returned to the host, the programming operation is terminated by resetting the MCU.

The number of bytes to be programmed, the first address to be programmed, and the programming time can be controlled by the user if values other than the default values are desired.

To understand the detailed operation of the EPROM programming utility, refer to Figure 4 during the following discussion. Figure 4 is composed of three interrelated parts. The upper-left portion shows the flowchart of the PROGRAM utility running in the boot ROM of the MCU. The upper-right portion shows the flowchart for the user-supplied driver program running in the host computer. The lower portion of Figure 4 is a timing sequence showing the relationship of operations between the MCU and the host computer. Reference numbers in the flowcharts in the upper half of Figure 4 have matching numbers in the lower half to help the reader relate the three parts of the figure.

The shaded area [1] refers to the software and hardware latency in the MCU leading to the transmission of a character (in this case, the \$FF). The shaded area [2] refers to a similar latency in the host computer (in this case, leading to the transmission of the first data character to the MCU).

The overall operation begins when the MCU sends the first character (\$FF) to the host computer, indicating that it is ready for the first data character. The host computer sends the first data byte [3] and enters its main loop. The second data character is sent [4], and the host then waits [5] for the first verify byte to come back from the MCU.

After the MCU sends \$FF [8], it enters the WAIT1 loop [9] and waits for the first data character from the host. When this character is received [10] the MCU programs it into the address pointed to by the Y index register. When the programming time delay is over, the MCU reads the programmed data, transmits it to the host for verification [11], and returns to the top of the WAIT1 loop to wait for the next data character [12]. Because the host previously sent the second data character, it is already waiting in the SCI receiver of the MCU. Steps [13], [14], and [15] correspond to the second pass through the WAIT1 loop.
Back in the host, the first verify character is received, and the third data character is sent [6]. The host then waits for the second verify character [7] to come back from the MCU. The sequence continues as long as the host continues to send data to the MCU. Since the WAIT1 loop in the PROGRAM utility is an indefinite loop, reset is used to end the process in the MCU after the host has finished sending data to be programmed.

\section*{ALLOWING FOR BOOTSTRAP MODE}

Since bootstrap mode requires very few connections to the MCU, it is easy to design systems that accommodate the bootstrap mode. Bootstrap mode is useful for diagnosing or repairing systems that have failed due to changes in the CONFIG register or failures of the expansion address/data buses, (rendering programs in external memory useless). Bootstrap mode can also be used to load information into the EPROM or EEPROM of an M68HC11 after final assembly of a module. Bootstrap mode is also useful for performing system checks and calibration routines. The following paragraphs explain system requirements for use of bootstrap mode in a product.
MODE SELECT PINS: It must be possible to force the MODA and MODB pins to logic zero, which implies that these two pins should be pulled up to \(V_{D D}\) through resistors rather than being tied directly to VDD. If mode pins are connected directly to \(V_{D D}\) it is not possible to force a mode other than the one the MCU is hard wired for. It is also good practice to use pulldown resistors to \(V_{S S}\) rather than connecting mode pins directly to \(V_{S S}\) because it is sometimes a useful debug aid to attempt reset in modes other than the one the system was primarily designed for. Physically, this requirement sometimes calls for the addition of a test point or a wire connected to one or both mode pins. Mode selection only uses the mode pins while RESET is active.

RESET: It must be possible to initiate a reset while the mode select pins are held low. In systems where there is no provision for manual reset, it is usually possible to generate a reset by turning power off and back on.

RxD PIN: It must be possible to drive the PDO/RxD pin with serial data from a host computer (or another MCU). In many systems, this pin is already used for SCl communications; thus no changes are required.

In systems where the PDO/RxD pin is normally used as a general-purpose output, a serial signal from the host can be connected to the pin without resulting in output driver conflicts. It may be important to consider what the existing logic will do with the SCl serial data instead of the signals that would have been produced by the PDO pin. In systems where the PDO pin is normally used as a general-purpose input, the driver circuit


Figure 4. Host and MCU Activity during EPROM PROGRAM Utility
that drives the PDO pin must be designed so that the serial data can override this driver, or the driver must be disconnected during the bootstrap download. A simple series resistor between the driver and the PDO pin solves this problem as shown in Figure 5. The serial data from the host computer can then be connected to the PDO/RxD pin, and the series resistor will prevent direct conflict between the host driver and the normal PDO driver.


Figure 5. Preventing Driver Conflict
TxD PIN: The bootloader program uses the PD1/TxD pin to send verification data back to the host computer. To minimize the possibility of conflicts with circuitry connected to this pin, port \(D\) is configured for wire-OR mode by the bootloader program during initialization. Since the wire-OR configuration prevents the pin from driving active high levels, a pullup resistor to \(V_{D D}\) is needed if the TxD signal is used.
In systems where the PD1/TxD pin is normally used as a general-purpose output, there are no output driver conflicts. It may be important to consider what the existing logic will do with the SCI serial data instead of the signals that would have been produced by the PD1 pin.
In systems where the PD1 pin is normally used as a generalpurpose input, the driver circuit that drives the PD1 pin must be designed so that the PD1/TxD pin driver in the MCU can override this driver. A simple series resistor between the driver and the PD1 pin can solve this problem. The TxD pin can then be configured as an output, and the series resistor will prevent direct conflict between the internal TxD driver and the external driver connected to PD1 through the series resistor.

OTHER: The bootloader firmware sets the DWOM control bit, which configures all port D pins for wire-OR operation. During the bootloading process, all port D pins except the PD1 \(/ T \times D\) pin are configured as high-impedance inputs. Any port \(D\) pin that is normally used as an output should have a pullup resistor so it does not float during the bootloading process.

\section*{DRIVING BOOT MODE FROM ANOTHER M68HC11}

A second M68HC11 system can easily act as the host to drive bootstrap loading of an M68HC11 MCU. This method is used to examine and program nonvolatile memories in target M68HC11s in Motorola EVMs. The following hardware and software example will demonstrate this and other bootstrap mode features.
The schematic in Figure 6 shows the circuitry for a simple EPROM duplicator for the MC68HC711E9. The circuitry is built in the wire-wrap area of an M68HC11EVBU Evaluation

Board to simplify construction. The schematic shows only the important portions of the EVBU circuitry to avoid confusion. To see the complete EVBU schematic, refer to the M68HC11EVBU/D, M68HC11EVBU Universal Evaluation Board User's Manual.

The default configuration of the EVBU must be changed to make the appropriate connections to the circuitry in the wire-wrap area and to configure the master MCU for bootstrap mode. A fabricated jumper must be installed at J 6 to connect the XTAL output of the master MCU to the wire-wrap connector P5, which has been wired to the EXTAL input of the target MCU. Cut traces that short across J 8 and J 9 must be cut on the solder side of the printed circuit board to disconnect the normal SCI connections to the RS232 level translator (U4) of the EVBU. The J8 and J9 connections can easily be restored at a later time by installing fabricated jumpers on the component side of the board. A fabricated jumper must be installed across J 3 to configure the master MCU for bootstrap mode.

One MC68HC711E9 is first programmed by other means with a desired 12K-byte program in its EPROM and a small duplicator program in its EEPROM. Alternately, the ROM program in an MC68HC11E9 can be copied into the EPROM of a target MC68HC711E9 by programming only the duplicator program into the EEPROM of the master MC68HC11E9. The master MCU is installed in the EVBU at socket U3. A blank MC68HC711E9 to be programmed is placed in the socket in the wire-wrap area of the EVBU (U6).

With the VPP power switch off, power is applied to the EVBU system. As power is applied to the EVBU, the master MCU (U3) comes out of reset in bootstrap mode. Target MCU (U6) is held in reset by the PB7 output of master MCU (U3). The PB7 output of U3 is forced to zero when U3 is reset. The master MCU will later release the reset signal to the target MCU under software control. The R×D and T×D pins of the target MCU (U6) are high-impedance inputs while U6 is in reset so they will not affect the TxD and RxD signals of the master MCU (U3) while U3 is coming out of reset. Since the target MCU is being held in reset with MODA and MODB at zero, it is configured for the EPROM emulation mode, and PB7 is the output enable signal for the EPROM data I/O pins. Pullup resistor R7 causes the port \(D\) pins including RxD and TxD, to remain in the high-impedance state so they do not interfere with the RxD and TXD pins of the master MCU as it comes out of reset.

As U3 leaves reset, its mode pins select bootstrap mode so the bootloader firmware begins executing. A break is sent out the TxD pin of U3. Pullup resistor R10 and resistor R9 cause the break character to be seen at the RxD pin of U3. The bootloader performs a jump to the start of EEPROM in the master MCU (U3) and starts executing the duplicator program. This sequence demonstrates how to use bootstrap mode to pass control to the start of EEPROM after reset.

The complete listing for the duplicator program in the EEPROM of the master MCU is provided in Listing 1.

The duplicator program in EEPROM clears the DWOM control bit to change port D (thus, TxD) of U3 to normal driven outputs. This configuration will prevent interference due to R9 when TxD from the target MCU (U6) becomes active. Series resistor R9 demonstrates how TxD of U3 can drive RxD of U3 and later TxD of U6 can drive RxD of U3 without a destructive conflict between the TxD output buffers.


Figure 6. MCU to MCU EPROM Duplicator Schematic

As the target MCU (U6) leaves reset, its mode pins select bootstrap mode so the bootloader firmware begins executing. A break is sent out the TxD pin of U6. At this time, the TxD pin of U3 is at a driven high so R9 acts as a pullup resistor for TXD of the target MCU (U6). The break character sent from U6 is received by U3 so the duplicator program that is running in the EEPROM of the master MCU knows that the target MCU is ready to accept a bootloaded program.

The master MCU sends a leading \$FF character to set the baud rate in the target MCU. Next, the master MCU passes a three-instruction program to the target MCU and pauses so the bootstrap program in the target MCU will stop the loading process and jump to the start of the downloaded program. This sequence demonstrates the variable-length download feature of the MC68HC711E9 bootloader.

The short program downloaded to the target MCU clears the DWOM bit to change its TxD pin to a normal driven CMOS output and jumps to the EPROM programming utility in the bootstrap ROM of the target MCU.
Note that the small downloaded program did not have to set up the SCl or initialize any parameters for the EPROM programming process. The bootstrap software that ran prior to the loaded program left the SCl turned on and configured in a way that was compatible with the SCI in the master MCU (the duplicator program in the master MCU also did not have to set up the SCl for the same reason). The programming time and starting address for EPROM programming in the target MCU were also set to default values by the bootloader software before jumping to the start of the downloaded program.

Before the EPROM in the target MCU can be programmed, the VPP power supply must be available at the XIRQ/VPPE pin of the target MCU. The duplicator program rurining in the master MCU monitors this voltage (for presence or absence - not level) at PE7 through resistor divider R14-R15. The PE7 input was chosen because the internal circuitry for port \(E\) pins can tolerate voltages slightly higher than \(V_{D D}\); therefore resistors R14 and R15 are less critical. No data to be programmed is passed to the target MCU until the master MCU senses that VPP has been stable for about 200 ms .

When VPP is ready, the master MCU turns on the red LED and begins passing data to the target MCU. EPROM PROGRAMMING UTILITY explains the activity as data is sent from the master MCU to the target MCU and programmed into the EPROM of the target. The master MCU in the EVBU corresponds to the HOST in the programming utility description, and the "PROGRAM utility in MCU" is running in the bootstrap ROM of the target MCU.

Each byte of data sent to the target is programmed and then the programmed location is read and sent back to the master for verification. If any byte fails, the red and green LEDs are turned off, and the programming operation is aborted. If the entire 12 K bytes are programmed and verified successfully, the red LED is turned off, and the green LED is turned on to indicate success. The programming of all 12K bytes takes about 30 sec .

After a programming operation, the VPP switch (S2) should be turned off before the EVBU power is turned off.

Listing 1. MCU to MCU Duplicator Program


\section*{Listing 1. MCU to MCU Duplicator Program}



Figure 7. Isolating EVBU XIRQ Pin

\section*{DRIVING BOOT MODE FROM A PERSONAL COMPUTER}

In this example, a personal computer is used as the host to drive the bootloader of an MC68HC711E9. An M68HC11EVBU is used for the target MC68HC711E9. A large program is transferred from the personal computer into the EPROM of the target MC68HC711E9.
HARDWARE: Figure 7 shows a small modification to the EVBU to accommodate the \(12-\mathrm{V}\) (nominal) EPROM programming voltage. The \(\overline{\mathrm{XIRQ}}\) pin is connected to a pullup resistor, two jumpers, and the 60 -pin connectors, P 4 and P5. The object of the modification is to isolate the XIRQ pin and then connect it to the programming power supply. Carefully cut the trace on the solder side of the EVBU as indicated in Figure 7. This disconnects the pullup resistor RN1D from XIRQ but leaves P4-18, P5-18, and jumpers J7 and J14 connected so the EVBU can still be used for other purposes after programming is done. Remove any fabricated jumpers from J 7 and J 14 . The EVBU normally has a jumper at J 7 to support the trace function

Figure 8 shows a small circuit that is added to the wire-wrap area of the EVBU. The three-terminal jumper allows the XIRQ line to be connected to either the programming power supply or to a substitute pullup resistor for XIRQ. The \(100-\mathrm{hm}\) resistor is a current limiter to protect the \(12-\mathrm{V}\) input of the MCU . The resistor and LED connected to P 5 pin 9 (port C bit 0 ) is an optional indicator that lights when programming is complete.

SOFTWARE: BASIC was chosen as the programming language due to its readability and availability in parallel versions on both the IBM \({ }^{\text {M1 }}\) PC and the Macintosh \({ }^{\text {M2 }}\). The program demonstrates several programming techniques for use with an M68HC11 and is not necessarily intended to be a finished, commercial program. For example, there is very little error checking, and the user interface is very elementary. A complete listing of the BASIC program is included in Listing 2 with moderate comments. The following paragraphs include a more detailed discussion of the program as it pertains to communicating with and programming the target

MC68HC711E9. Lines \(25-45\) initialize and define the variables and array used in the program. Changes to this section would allow for other programs to be downloaded.
1. IBM is a trademark of International Business Machines.
2. Macintosh is a trademark of Apple Computers, Inc.


Figure 8. PC to MCU Programming Circuit

Lines 50-95 read in the small bootloader from DATA statements at the end of the listing. The source code for this bootloader is presented in the DATA statements. The bootloaded code makes port \(C\) bit 0 low, initializes the \(X\) and \(Y\) registers for use by the EPROM programming utility routine contained in the boot ROM, and then jumps to that routine. The hexadecimal values read in from the DATA statements are converted to binary values by a subroutine. The binary values are then saved as one string (BOOTCODE\$).

The next long section of code (lines 97-1250) reads in the S-records from an external disk file (in this case, BUF34.S19), converts them to integer, and saves them in an array. The techniques used in this section show how to convert ASCII S-records to binary form that can be sent (bootloaded) to an M68HC11.

This S-record translator only looks for the S1 records that contain the actual object code. All other S-record types are ignored.

When an S1 record is found (line 1000-1024), the next two characters form the hex byte giving the number of hex bytes to follow. This byte is converted to integer by the same subroutine that converted the bootloaded code from the DATA statements. This BYTECOUNT is adjusted by subtracting 3, which accounts for the address and checksum bytes and leaves just the number of object-code bytes in the record.

Starting at line 1100, the two-byte (four-character) starting address is converted to decimal. This address is the starting address for the object-code bytes to follow. An index into the CODE\% array is formed by subtracting the base address initialized at the start of the program from the starting address for this S -record.

A FOR-NEXT loop starting at line 1130 converts the object-code bytes to decimal and saves them in the CODE\% array. When all the object-code bytes have been converted from the current S-record, the program loops back to find the next S1 record.
A problem arose with the BASIC programming technique used. The draft versions of this program tried saving the object-code bytes directly as binary in a string array. This caused "Out of Memory" or "Out of String Space" errors on both a 2 M Macintosh and a640K PC. The solution was to make the array an integer array and perform the integer-to-binary conversion on each byte as it is sent to the target part.

The one compromise made to accommodate both Macintosh and PC versions of BASIC is in lines 1500 and 1505. Use line 1500 and comment out line 1505 if the program is to be run on a Macintosh and, conversely, use line 1505 and comment out line 1500 if a PC is used.

After the COM port is opened, the code to be bootloaded is modified by adding the \$FF to the start of the string. \$FF synchronizes the bootloader in the MC68HC711E9 to 1200 baud. The entire string is simply sent to the COM port by PRINTing the string. This is possible since the string is actually queued in BASIC's COM buffer, and the operating system takes care of sending the bytes out one at a time. The M68HC11 echoes the data received for verification. No automatic verification is provided, though the data is printed to the screen for manual verification.

Once the MCU has received this bootloaded code, the bootloader automatically jumps to it. The small bootloaded program in turn includes a jump to the EPROM programming routine in the boot ROM.

Refer to the previous explanation of the EPROM PROGRAMMING UTILITY for the following discussion. The host system sends the first byte to be programmed through the COM port to the SCI of the MCU. The SCI port on the MCU buffers one byte while receiving another byte, increasing the throughput of the EPROM programming operation by sending the second byte while the first is being programmed.

When the first byte has been programmed, the MCU reads the EPROM location and sends the result back to the host system. The host then compares what was actually programmed to what was originally sent. A message indicating which byte is being verified is displayed in the lower half of the screen. If there is an error, it is displayed at the top of the screen.

As soon as the first byte is verified, the third byte is sent. In the meantime, the MCU has already started programming the second byte. This process of verifying and queueing a byte continues until the host finishes sending data. If the programming is completely successful, no error messages will have been displayed at the top of the screen. Subroutines follow the end of the program to handle some of the repetitive tasks. These routines are short, and the commenting in the source code should be sufficient explanation.

MODIFICATIONS: This example programmed version 3.4 of the BUFFALO monitor into the EPROM of an MC68HC711E9; the changes to the BASIC program to download some other program are minor. The necessary changes are as follows:
1. In line 30, the length of the program to be downloaded must be assigned to the variable "CODESIZE\%".
2. Also in line 30 , the starting address of the program is assigned to the variable "ADRSTART".
3. In line 9570, the start address of the program is stored in the third and fourth items in that DATA statement in hexadecimal.
4. If any changes are made to the number of bytes in the boot code in the DATA statements in lines 9500-9580, then the new count must be set in the variable "BOOTCOUNT" in line 25.
OPERATION: Configure the EVBU for boot mode operation by putting a jumper at J 3 . Ensure that the trace command jumper at J 7 is not installed because this would connect the \(12-\mathrm{V}\) programming voltage to the OC5 output of the MCU.

Connect the EVBU to its DC power supply. When it is time to program the MCU EPROM, turn on the \(12-\mathrm{V}\) programming power supply to the new circuitry in the wire-wrap area.

Connect the EVBU serial port to the appropriate serial port on the host system. For the Macintosh, this is the modem port with a modem cable. For the MS-DOS computer, it is connected to COM1 with a "straight through" or modem cable. Power up the host system and start the BASIC program. If the program has not been compiled, this is accomplished from within the appropriate BASIC compiler or interpreter. Power up the EVBU.

Answer the prompt for filename with either a [RETURN] to accept the default shown or by typing in a new filename and pressing [RETURN].

The program will inform the user that it is working on converting the file from S-records to binary. This process will take from 30 sec to a few minutes, depending on the computer.

A prompt reading, "Comm port open?" will appear at the end of the file conversion. This is the last chance to ensure that everything is properly configured on the EVBU. Pressing [RETURN] will send the bootcode to the target MC68HC711E9. The program then informs the user that the bootload code is being sent to the target, and the results of the echoing of this code are displayed on the screen.

Another prompt reading "Programming is ready to begin. Are you?" will appear. Turn on the \(12-\mathrm{V}\) programming power supply and press [RETURN] to start the actual programming of the target EPROM.

A count of the byte being verified will be continually updated on the screen as the programming progresses. Any failures will be flagged as they occur.
When programming is complete, a message will be displayed as well as a prompt requesting you to press [RETURN] to quit.

Turn off the \(12-\mathrm{V}\) programming power supply before turning off 5 V to the EVBU.

\section*{Listing 2. BASIC Program for Personal Computer}
```

|***********************************************************************
`* `* E9BUF.BAS - A PROGRAM TO DEMONSTRATE THE USE OF THE BOOT MODE
ON THE HC11 BY PROGRAMMING AN MC68HC711E9 WITH
BUFEALO 3.4
REQUIRES THAT THE S-RECORDS FOR BUFFALO (BUF34.S19)
BE AVAILABLE IN THE SAME DIRECTORY OR FOLDER
THIS PROGRAM HAS BEEN RUN BOTH ON A MS-DOS COMPUTER
USING QUICKBASIC 4.5 AND ON A MACINTOSH USING
** QUICKBASIC 1.0.
v************************************************************************
H\$ = "0123456789ABCDEF" 'STRING TO USE FOR HEX CONVERSIONS
DEFINT B, I: CODESIZE% = 8192: ADRSTART= 57344!
BOOTCOUNT = 25 'NUMBER OF BYTES IN BOOT CODE
DIM CODE%(CODESIZE%) 'BUFFALO 3.4 IS 8K BYTES LONG
BOOTCODE\$ = "" 'INITIALIZE BOOTCODES TO NULL
REM ***** READ IN AND SAVE THE CODE TO BE BOOT LOADED ******
FOR I = 1 TO BOOTCOUNT \# OF BYTES IN BOOT CODE
READ QS
A\$ = MIDS(Q$, 1, 1)
GOSUB 7000 'CONVERTS HEX DIGIT TO DECIMAL
TEMP = 16* X 'HANG ON TO UPPER DIGIT
AS = MIDS(QS, 2, 1)
GOSUB 7000
TEMP = TEMP + X
BOOTCODE$ = BOOTCODE\$ + CHR$(TEMP) 'BUILD BOOT CODE
NEXT I
REM ***** S-RECORD CONVERSION STARTS HERE *****
FILNAMS="BUF34.S19"
    `DEFAULT FILE NAME FOR S-RECORDS
CLS
105 PRINT "Filename.ext of S-record file to be downloaded (";FILNAM$;") ";
107 INPUT Q\$
110 IF Q$<>"" THEN FILNAMS=Q$
120 OPEN FILNAMS FOR INPUT AS \#1
130 PRINT : PRINT "Converting "; FILNAMS; " to binary..."
999 REM ***** SCANS FOR 'SI' RECORDS ****
1 0 0 0 GOSUB 5000 'GET 1 CHARACTER FROM INPUT FILE
1010 IF FLAG THEN 1250 'FLAG IS EOF FLAG FROM SUBROUTINE
1020 IF AS <> "S" THEN 1000
1022 GOSUB 6000
1024 IF A\$ <> " 1" THEN 1000
1 0 2 9 REM ***** SI RECORD FOUND, NEXT 2 HEX DIGITS ARE THE BYTE COUNT *****
1030 GOSUB 6000
1 0 4 0 ~ G O S U B ~ 7 0 0 0 ~ ' R E T U R N S ~ D E C I M A L ~ I N ~ X ~
1050 BYTECOUNT = 16* X 'ADJUST FOR HIGH NIBBLE
1060 GOSUB 6000
1070 GOSUB 7000
1080 BYTECOUNT = BYTECOUNT + X 'ADD LOW NIBBLE
1090 BYTECOUNT = BYTECOUNT - 3 'ADJUST FOR ADDRESS + CHECKSUM
1099 REM ***** NEXT 4 HEX DIGITS BECOME THE STARTING ADDRESS FOR THE DATA *****
1100 GOSUB 6000 'GET FIRST NIBBLE OF ADDRESS
1102 GOSUB 7000 'CONVERT TO DECIMAL

```
```

1104 ADDRESS= 4096 * X
106 GOSUB 6000 'GET NEXT NIBBLE
1108 GOSUB 7000
1110 ADDRESS= ADDRESS + 256 * X
1112 GOSUB 6000
1114 GOSUB 7000
1116 ADDRESS= ADDRESS+ 16 * X
1118 GOSUB 6000
1120 GOSUB 7000
1122 ADDRESS = ADDRESS + X
1124 ARRAYCNT = ADDRESS-ADRSTART 'INDEX INTO ARRAY
1129 REM ***** CONVERT THE DATA DIGITS TO BINARY AND SAVE IN THE ARRAY *****
1130 FOR I = 1 TO BYTECOUNT
1140 GOSUB 6000
1150 GOSUB 7000
1160 Y = 16 * X 'SAVE UPPER NIBBLE OF BYTE
1170 GOSUB 6000
1180 GOSUB 7000
1190 Y = Y + X 'ADD LOWER NIBBLE
1200 CODE% (ARRAYCNT) = Y 'SAVE BYTE IN ARRAY
1210 ARRAYCNT = ARRAYCNT + 1 'INCREMENT ARRAY INDEX
1220 NEXT I
1230 GOTO 1000
1250 CLOSE 1
1499 REM ***** DUMP BOOTLOAD CODE TO PART ******
1500 'OPEN "R",\#2,"COM1:1200,N,8,1" 'Macintosh COM statement
1505 OPEN "COM1:1200,N,8,1,CDO,CSO,DSO,RS" FOR RANDOM AS \#2 'DOS COM statement
1510 INPUT "Comm port open"; Q\$
1512 WHILE LOC(2) >0 'FLUSH INPUT BUFFER
1513 GOSUB 8020
1514 WEND
1515 PRINT : PRINT "Sending bootload code to target part..."
1520 AS = CHRS(255) + BOOTCODES `ADD HEX FF TO SET BAUD RATE ON TARGET HC11
1530 GOSUB 6500
1540 PRINT
1550 FOR I = 1 TO BOOTCOUNT \# OF BYTES IN BOOT CODE BEING ECHOED
1560 GOSUB 8000
1564 K=ASC(B$):GOSUB 8500
1565 PRINT "Character #"; I; " received = "; HX$
1570 NEXT I
1590 PRINT "Programming is ready to begin.": INPUT "Are you ready"; QS
1595 CLS
1597 WHILE LOC(2) > 0 'FLUSH INPUT BUFFER
1598 GOSUB 8020
1599 WEND
1600 XMT = 0: RCV = 0 'POINTERS TO XMIT AND RECEIVE BYTES
1610 AS = CHRS (CODE% (XMT))
1620 GOSUB 6500 'SEND FIRST BYTE
1625 FOR I = 1 TO CODESIZE% - 1 'ZERO BASED ARRAY 0 -> CODESIZE-1
1630 AS = CHRS(CODE%(I)) 'SEND SECOND BYTE TO GET ONE IN QUEUE
1635 GOSUB 6500
1640 GOSUB 8000
1650 RCV = I - 1
1660 LOCATE 10,1:PRINT "Verifying byte \#"; I; " "
1664 IF CHRS (CODE% (RCV)") = B\$ THEN 1670
1665 K=CODE% (RCV) :GOSUB 8500
1666 LOCATE 1,1:PRINT "Byte \#"; I; " ", " - Sent "; HX$;
1668 K=ASC(B$):GOSUB 8500
1669 PRINT " Received "; HX$;
1670 NEXT I
1680 GOSUB 8000 'GET BYTE FOR VERIFICATION
1690 RCV = CODESIZE% - 1
1700 LOCATE 10,1:PRINT "Verifying byte #"; CODESIZE%; " "
1710 IF CHR$(CODE告(RCV)) = B\$ THEN 1720
1713 K=CODE (RCV):GOSUB 8500
1714 LOCATE 1,1:PRINT "Byte \#"; CODESIZE%; " ", " - Sent "; HX$;
1715 K=ASC(B$):GOSUB 8500
1716 PRINT " Received "; HX$;
1720 LOCATE 8, 1: PRINT : PRINT "Done!!!!"
4900 CLOSE
4910 INPUT "Press [RETURN] to quit...", Q$
5000 END

```
```

5900 `******************************************************************************* 5910 `* SUBROUTINE TO READ IN ONE BYTE FROM A DISK FILE
5 9 3 0 ~ ' * ~ R E T U R N S ~ B Y T E ~ I N ~ A S ~
5940 `\star\star\star***************************************** 6000 FLAG = 0 6010 IF EOF(1) THEN FLAG = 1: RETURN 6020 A$ = INPUT$ (1, #1) 6 0 3 0 \text { RETURN} 6490 `*****************************************************************************
6 4 9 2 ~ ' * ~ S U B R O U T I N E ~ T O ~ S E N D ~ T H E ~ S T R I N G ~ I N ~ A \$ ~ O U T ~ T O ~ T H E ~ D E V I C E ~
6494 `* OPENED AS FILE #2. 6496 `*****************************************************************************
6500 PRINT \#2, AS;
6 5 1 0 RETURN
6590 \******************************************************************************
6 5 9 4 ~ `* ~ S U B R O U T I N E ~ T H A T ~ C O N V E R T S ~ T H E ~ H E X ~ D I G I T ~ I N ~ A S ~ T O ~ A N ~ I N T E G E R 6596`******************************************************************************
7 0 0 0 ~ X ~ = ~ I N S T R ( H \$ , ~ A \$ ) ~
7 0 1 0 ~ I F ~ X ~ = ~ 0 ~ T H E N ~ F L A G ~ = ~ 1 ~
7020 x = X - 1
7 0 3 0 ~ R E T U R N
7990 `****************************************************************************** 7 9 9 2 ~ ` * ~ S U B R O U T I N E ~ T O ~ R E A D ~ I N ~ O N E ~ B Y T E ~ T H R O U G H ~ T H E ~ C O M M ~ P O R T ~ O P E N E D
7994 ** AS FILE \#2. WAITS INDEFINITELY FOR THE BYTE TO BE
7 9 9 6 ~ `* ~ R E C E I V E D . ~ S U B R O U T I N E ~ W I L L ~ B E ~ A B O R T E D ~ B Y ~ A N Y ~ 998`* KEYBOARD INPUT. RETURNS BYTE IN BS. USES QS.
7999 `******************************************************************************* 8 0 0 0 ~ W H I L E ~ L O C ( 2 ) ~ = ~ 0 ~ ' W A I T ~ F O R ~ C O M M ~ P O R T ~ I N P U T ~ 8005 Q$ = INKEY$: IF QS <> "" THEN 4900 'IF ANY KEY PRESSED, THEN ABORT 8 0 1 0 ~ W E N D 8 0 2 0 ~ B \$ ~ = ~ I N P U T \$ ( 1 , ~ \# 2 ) 8030 RETURN 8490 , ********************************************************************************* 8491 '* DECIMAL TO HEX CONVERSION 8492 `* INPUT: K - INTEGER TO BE CONVERTED
893 '* OUTPUT: HX\$ - TWO CHARACTER STRING WITH HEX CONVERSION
8494 \*******************************************************************************
8500 IF K > 255 THEN HX$="TOO big":GOTO 8530
8510 HXS=MID$(H$,K16+1,1) 'UPPER NIBBLE
8520 HX$=HX$+MID$(H\$, (K MOD 16) +1,1) 'LOWER NIBBLE
8 5 3 0 ~ R E T U R N ~
9499 1********************** BOOT CODE *********************************************
9500 DATA 86, 23 'LDAA \#$23
9510 DATA B7, 10, 02 'STAA OPT2 make port C wire or
9520 DATA 86, FE 'LDAA #SFE
9530 DATA B7, 10, 03 'STAA PORTC light 1 LED on port C bit 0
STAA PORIC
9550 DATA F7, 10, 07 \STAB #SFF make port C outputs
9560 DATA CE, OF, AO 'LDX #4000 2msec at 2MHz
9570 DATA 18, CE, E0, 00 'LDY #$E000 Start of BUFFALO 3.4
9580 DATA 7E, BF, 00 'JMP \$BF00 EPROM routine start address
9590 \*********************************************************************************

```

\section*{COMMON BOOTSTRAP MODE PROBLEMS}

It is not unusual for a user to encounter problems with bootstrap mode because it is new to many users. By knowing some of the common difficulties, the user can avoid them or at least recognize and quickly correct them.

\section*{Reset conditions vs. conditions as bootloaded program} starts.
It is common to confuse the reset state of systems and control bits with the state of these systems and control bits when a bootloaded program in RAM starts. Between these times, the bootloader program is executed, which changes the states of some systems and control bits.
- The SCl system is initialized and turned on (Rx and Tx).
- The SCI system has control of the PDO and PD1 pins.
- Port D outputs are configured for wire-OR operation.
- The stack pointer is initialized to the top of RAM
- Time has passed (two or more SCl character times).
- Timer has advanced from its reset count value.

Users also forget that bootstrap mode is a special mode; thus privileged control bits are accessible, and write protection for some registers is not in effect. The bootstrap ROM is in the memory map. The DISR bit in the TEST1 control register is set, which disables resets from the COP and clock monitor systems.

Since bootstrap is a special mode, these conditions can be changed by software. The bus can even be switched from single-chip mode to expanded mode to gain access to external memories and peripherals.
Connecting \(\mathbf{R x D}\) to \(\mathbf{V}_{\mathbf{s s}}\) does not cause the \(\mathbf{S C I}\) to receive a break - To force an immediate jump to the start of EEPROM, the bootstrap firmware looks for the first received

Table 2. Summary of Boot-ROM-Related Features
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|c|c|}
\hline MCU Part \# & BOOT ROM Revision (@\$BFD1) & \[
\begin{gathered}
\text { Mask Set } \\
\text { I.D. } \\
\text { (@\$BFD2,3) }
\end{gathered}
\] & \[
\begin{aligned}
& \text { MCU Type } \\
& \text { I.D. } \\
& \text { (@\$BFD4,5) }
\end{aligned}
\] & Security & Download Length & JMP on BRK or \(\$ 0{ }^{1}\) & \[
\begin{gathered}
\text { JMP } \\
\text { to RAM }{ }^{2}
\end{gathered}
\] & Default RAM Location & EPROM \({ }^{3}\) PROGRAM Utility & UPLOAD \({ }^{4}\) Utility & Notes \\
\hline MC68HC11A0 & - & - & Mask Set \# & - & 256 & \$B600 & \$0000 & \$0000-FF & - & - & 5 \\
\hline MC68HC11A1 & - & - & Mask Set \# & - & 256 & \$B600 & \$0000 & \$0000-FF & - & - & 5 \\
\hline MC68HC11A8 & - & - & Mask Set \# & - & 256 & \$B600 & \$0000 & \$0000-FF & - & - & 5 \\
\hline MC68SEC11A8 & - & - & Mask Set \# & Yes & 256 & \$B600 & \$0000 & \$0000-FF & - & - & 5 \\
\hline MC68HC11D3 & \$00 & Mask Set \# & \$11D3 & - & 0-192 & \$F000-ROM & - & \$0040-FF & - & - & 6 \\
\hline MC68HC711D3 & \$42 (B) & \$0000 & \$71D3 & - & 0-192 & \$F000-EPROM & - & \$0040-FF & Yes & Yes & 6 \\
\hline MC68HC811E2 & - & \$0000 & \$E2E2 & - & 256 & \$B600 & \$0000 & \$0000-FF & - & - & 5 \\
\hline MC68SEC811E2 & - & - & \$E25] & Yes & 256 & \$B600 & \$0000 & \$0000-FF & - & - & 5 \\
\hline MC68HC11E0 & - & Mask Set \# & \$E9E9 & - & 0-512 & \$B600 & - & \$0000-1FF & - & - & 5 \\
\hline MC68HC11E1 & - & Mask Set \# & \$E9E9 & - & 0-512 & \$B600 & - & \$0000-1FF & - & - & 5 \\
\hline MC68HC11E9 & - & Mask Set \# & \$E9E9 & - & 0-512 & \$B600 & - & \$0000-1FF & - & - & 5 \\
\hline MC68SEC11E9 & - & Mask Set \# & \$E95C & Yes & 0-512 & \$B600 & - & \$0000-1FF & - & - & 5 \\
\hline MC68HC711E9 & \$41 (A) & \$0000 & \$71E9 & - & 0-512 & \$B600 & - & \$0000-1FF & Yes & Yes & 6 \\
\hline MC68HC11F1 & \$42 (B) & \$0000 & \$F1F1 & - & 0-1024 & \$FE00 & - & \$0000-3FF & - & - & 6,8 \\
\hline MC68HC11K4 & \$30 (0) & Mask Set \# & \$044B & - & 0-768 & \$0D80 & - & \$0080-37F & - & - & 6, 8 \\
\hline MC68HC711K4 & \$42 (B) & \$0000 & \$744B & - & 0-768 & \$0D80 & - & \$0080-37F & Yes & Yes & 6, 8 \\
\hline
\end{tabular}

NOTES:
1. By sending \(\$ 00\) or a break as the first SCl character after reset in bootstrap mode, a jump (JMP) is executed to the address in this table rather than doing a download. Unless otherwise noted, this address is the start of EEPROM. Tying RXD to TxD and using a pullup resistor from TxD to VDD will cause the SCI to see a break as the first received character.
2. If \(\$ 55\) is received as the first character after reset in bootstrap mode, a jump (JMP) is executed to the stat of on-chip RAM rather than doing a download. This \(\$ 55\) character must be sent at the default baud rate ( 7812 baud @ \(\mathrm{E}=2 \mathrm{MHz}\) ).
For devices with variable-length download, the same effect can be achieved by sending \$FF and no other SCl characters. After four SCl character times, the download terminates, and a jump (JMP) to the start of RAM is executed.
The jump to RAM feature is only useful if the RAM was previously loaded with a meaningful program.
3. A callable utility subroutine is included in the bootstrap ROM of the indicated versions to program bytes of on-chip EPROM with data received via the SCI.
4. A callable utility subroutine is included in the bootstrap ROM of the indicated versions to upload contents of on-chip memory to a host computer via the SCI.
5. The complete listing for this bootstrap ROM may be found in the M68HC11RM/AD, M68HC11 Reference Manual.
6. The complete listing for this bootstrap ROM is included in this application note.
7. Due to the extra program space needed for EEPROM security on this device, there are no pseudo-vectors for SCI, SPI, PAIF, PAOVF, TOF, OC5F, or OC4F interrupts.
8. This bootloader extends the automatic software detection of baud rates to include 9600 baud at \(2-\mathrm{MHz}\) E-clock rate.
character to be \(\$ 00\) (or break). The data reception logic in the SCl looks for a one-to-zero transition on the RxD pin to synchronize to the beginning of a receive character. If the RxD pin is tied to ground, no one-to-zero transition occurs. The SCI transmitter sends a break character when the bootloader firmware starts, and this break character can be fed back to the RXD pin to cause the jump to EEPROM. Since TxD is configured as an open-drain output, a pullup resistor is required.
An \$FF character is required before data is loaded into RAM - The initial character (usually \$FF) that sets the download baud rate is often forgotten.
Original M68HC11 versions required exactly 256 bytes to be downloaded to RAM - Even users that know about the 256 bytes of download data sometimes forget the initial \$FF that makes the total number of bytes required for the entire download operation equal to \(256+1\) or 257 bytes.
Variable-length download - When on-chip RAM surpassed 256 bytes, the time required to serially load this many characters became more significant. The variable-length download feature allows shorter programs to be loaded without sacrificing compatibility with earlier fixed-length download versions of the bootloader. The end of a download is indicated by an idle RxD line for at least four character times. If a personal computer is being used to send the download data to the MCU, there can be problems keeping characters close enough together to avoid tripping the end-of-download detect mechanism. Using 1200 as the baud rate rather than the faster default rate may help this problem.

Assemblers often produce S-record encoded programs which must be converted to binary before bootloading them to the MCU. The process of reading S-record data from a file and translating it to binary can be slow, depending on the personal computer and the programming language used for the translation. One strategy that can be used to overcome this problem is to translate the file into binary and store it into a RAM array before starting the download process. Data can then be read and downloaded without the translation or file-read delays.

The end-of-download mechanism goes into effect when the initial \$FF is received to set the baud rate. Any amount of time may pass between reset and when the \$FF is sent to start the download process.
EPROM/OTP versions of M68HC11 have an EPROM emulation mode - The conditions that configure the MCU for EPROM emulation mode are essentially the same as those for resetting the MCU in bootstrap mode. While RESET is low and mode select pins are configured for bootstrap mode (low), the MCU is configured for EPROM emulation mode.
The port pins that are used for EPROM datal/O lines may be inputs or outputs, depending on the pin that is emulating the

EPROM output enable pin ( \(\overline{\mathrm{OE}})\). To make these data pins appear as high-impedance inputs as they would on a non-EPROM part in reset, connect the \(\mathrm{PB} 7 /(\overline{\mathrm{OE}})\) pin to a pullup resistor.
Bootloading a program to perform a ROM checksum The bootloader ROM must be turned off before performing the checksum program. To remove the boot ROM from the memory map, clear the RBOOT bit in the HPRIO register. This is normally a write-protected bit that is zero, but in bootstrap mode it is reset to one and can be written. If the boot ROM is not disabled, the checksum routine will read the contents of the boot ROM rather than the user's mask ROM or EPROM at the same addresses.
Inherent delays caused by double buffering of SCl dataThis problem is troublesome in cases where one MCU is bootloading to another MCU.
Because of transmitter double buffering, there may be one character in the serial shifter as a new character is written into the transmit data register. In cases such as downloading in which this two-character pipeline is kept full, a two-character time delay occurs between when a character is written to the transmit data register and when that character finishes transmitting. A little more than one more character time delay occurs between the target MCU receiving the character and echoing it back. If the master MCU waits for the echo of each downloaded character before sending the next one, the download process takes about twice as long as it would if transmission is treated as a separate process or if verify data is ignored.

\section*{BOOT ROM VARIATIONS}

Different versions of the M 68 HC 11 have different versions of the bootstrap ROM program. Table 2 summarizes the features of the boot ROMs in 16 members of the M68HC11 Family.
The boot ROMs for the MC68HC11F1, the MC68HC711K4, and the MC68HC11K4 allow additional choices of baud rates for bootloader communications. For the three new baud rates, the first character used to determine the baud rate is not \$FF as it was in earlier M68HC11s. The intercharacter delay that terminates the variable-length downioad is also different for these new baud rates. Table 3 shows the synchronization characters, delay times, and baud rates as they relate to E -clock frequency.

\section*{COMMENTED BOOT ROM LISTINGS}

Listings 3-8 contain complete commented listings of the boot ROM programs in six specific versions of the M68HC11. Other versions can be found in appendix \(B\) of the M68HC11RM/AD, M68HC11 Reference Manual.

Table 3. Bootloader Baud Rates
\begin{tabular}{|c|c|c|c|c|c|c|c|}
\hline & & \multicolumn{6}{|c|}{Baud Rates at E-clock =} \\
\hline Character & Delay & 2 MHz & 2.1 MHz & 3 MHz & 3.15 MHz & 4 MHz & 4.2 MHz \\
\hline \$FF & 4 Characters & 7812 & 8192 & 11,718 & 12,288 & 15,624 & 16,838 \\
\hline \$FF & 4 Characters & 1200 & 1260 & 1800 & 1890 & 2400 & 2520 \\
\hline \$F0 & 4.9 Characters & 9600 & 10,080 & 14,400 & 15,120 & 19,200 & 20,160 \\
\hline \$FD & 17.3 Characters & 5208 & 5461 & 7812 & 8192 & 10,416 & 10,922 \\
\hline \$FD & 13 Characters & 3906 & 4096 & 5859 & 6144 & 7812 & 8192 \\
\hline
\end{tabular}

Listing 3. MC68HC711E9 Bootloader ROM




\section*{Listing 3. MC68HC711E9 Bootloader ROM}


Symbol Table:
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|}
\hline Symbol Name & Value & Def. \({ }^{\text {\% }}\) & ine Nu & mber Cr & Ss Re & erence & & & \\
\hline BAUD & 002B & *00037 & 00160 & 00180 & & & & & \\
\hline BAUDOK & BF8A & *00183 & 00178 & & & & & & \\
\hline BEGIN & BF54 & *00155 & 00250 & & & & & & \\
\hline delayf & 021B & *00061 & 00163 & & & & & & \\
\hline DELAYS & ODB0 & *00060 & 00181 & & & & & & \\
\hline DONEIT & BF47 & *00142 & 00124 & & & & & & \\
\hline EEPMEND & B7FF & *00050 & & & & & & & \\
\hline EEPMSTR & B600 & *00049 & 00175 & & & & & & \\
\hline Elat & 0020 & *00043 & 00125 & 00128 & & & & & \\
\hline EPGM & 0001 & *00044 & 00128 & & & & & & \\
\hline EPRMEND & FFFF & *00053 & & & & & & & \\
\hline EPRMSTR & D000 & *00052 & 00206 & & & & & & \\
\hline NEWONE & BF9B & *00196 & 00189 & & & & & & \\
\hline NOTzERO & BF7E & *00176 & 00174 & & & & & & \\
\hline OC1F & 0080 & *00034 & 00136 & 00139 & & & & & \\
\hline PORTD & 0008 & *00029 & 00168 & & & & & & \\
\hline PPROG & 003B & *00041 & 00126 & 00129 & 00140 & & & & \\
\hline PRGROUT & BF13 & *00110 & 00074 & & & & & & \\
\hline PROGDEL & 1068 & *00063 & 00205 & & & & & & \\
\hline PROGRAM & BFOO & *00074 & & & & & & & \\
\hline RAMEND & 01FF & *00056 & 00156 & 00201 & & & & & \\
\hline RAMSTR & 0000 & *00055 & 0.0184 & 00207 & & & & & \\
\hline SCCR2 & 002D & *00038 & 00162 & 00167 & 00169 & & & & \\
\hline SCDAT & 002F & *00040 & 00091 & 00118 & 00122 & 00145 & 00172 & 00197 & 00199 \\
\hline SCSR & 002E & *00039 & 00090 & 00116 & 00121 & 00143 & 00171 & 00189 & \\
\hline SPCR & 0028 & *00036 & 00158 & & & & & & \\
\hline STAR & BFAA & *00204 & 00194 & & & & & & \\
\hline TCNT & 000E & *00030 & 00134 & & & & & \(\cdots\) & \\
\hline TFLG1 & 0023 & *00032 & 00137 & 00139 & & & & & \\
\hline TOCI & 0016 & *00031 & 00135 & 00164 & 00182 & 00187 & & & \\
\hline UPLOAD & BF03 & *00075 & & & & & & & \\
\hline UPLOOP & BF06 & *00089 & 00093 & & & & & & \\
\hline WAIT & BF8E & *00186 & 00202 & & & & & & \\
\hline WAIT1 & BF1F & *00120 & 00147 & & & & & & \\
\hline WTLOOP & BF90 & *00188 & 00193 & & & & & & \\
\hline
\end{tabular}

Errors: None
Labels: 35
Last Program Address: \$BFFF
Last Storage Address: \(\$ 0000\)
Program Bytes: \(\$ 0100256\)
Storage Bytes: \(\$ 00000\)

\section*{Listing 4. MC68HC11D3 Bootloader ROM}

\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 81 & BF64 & 7EF000 & & JMP & ROMSTR & Jump to ROM if it was \$00 \\
\hline 82 & BF67 & & NOTZERO & EQU & * & \\
\hline 83 & BF67 & 81FF & & CMPA & \# \({ }^{\text {SFF }}\) & SFF will be seen as \$FF. \\
\hline 84 & BF69 & 2708 & & BEQ & BAUDOK & if baud was correct \\
\hline 85 & & & * Or else change & to /104 & (/13 \& /8) 1200 ¢ & 2 MHz \\
\hline 86 & BF6B & 142B33 & & BSET & BAUD \$33 & Works because \$22 -> \$33 \\
\hline 87 & BF6E & CCODBO & & LDD & \#DELAYS & And switch to slower... \\
\hline 88 & BF71 & DD16 & & STD & TOC1 & delay constant \\
\hline 89 & BF73 & & BAUDOK & EQU & * & \\
\hline 90 & BF73 & 18 CE 0040 & & LDY & \#RAMSTR & Point to start of RAM \\
\hline 91 & & & & & & \\
\hline 92 & BF77 & & WAIT & EQU & * & \\
\hline 93 & BF77 & DE16 & & LDX & TOC1 & Move delay constant to X \\
\hline 94 & BF79 & & WTLOOP & EQU & * & \\
\hline 95 & BF79 & 122E2009 & & BRSET & SCSR \$20 NEWONE & Exit loop if RDRF set \\
\hline 96 & BF7D & 09 & & DEX & & Decrement count \\
\hline 97 & BE7E & 01 & & NOP & & Kill... \\
\hline 98 & BF7F & 01 & & NOP & & ...seven cycles. \\
\hline 99 & BF80 & 2100 & & BRN & * +2 & ..to match original program \\
\hline 100 & BF82 & 26 F 5 & & BNE & WTLOOP & Loop if not timed out \\
\hline 101 & BF84 & 200F & & BRA & STAR & Quit download on timeout \\
\hline 102 & & & & & & \\
\hline 103 & BF86 & & NEWONE & EQU & * & \\
\hline 104 & BF86 & 962F & & LDAA & SCDAT & Get received data \\
\hline 105 & BF88 & 18A700 & & STAA & \$00, Y & Store to next RAM location \\
\hline 106 & BF8B & 972F & & STAA & SCDAT & Transmit it for handshake \\
\hline 107 & BF8D & 1808 & & INY & & Point to next RAM location \\
\hline 108 & BF8F & 188C0100 & & CPY & \#RAMEND +1 & See if past end \\
\hline 109 & BF93 & 26E2 & & BNE & WAIT & If not, get another \\
\hline 110 & & & & & & \\
\hline 111 & BF95 & & STAR & EQU & \(\star\) & \\
\hline 112 & BF95 & 7E0040 & & JMP & RAMSTR & ** Exit to start of RAM \\
\hline 113 & & & ***************** & ***** & ********** & \\
\hline 114 & & & * Block fill unus & sed byte & s with zero & \\
\hline 115 & & & & & & \\
\hline 116 & BF98 & 000000000000 & & BSZ & \$BFD1-* & \\
\hline & & 000000000000 & & & & \\
\hline & & 000000000000 & & & & \\
\hline & & 000000000000 & & & & \\
\hline & & 000000000000 & & & & \\
\hline & & 000000000000 & & & & \\
\hline & & 000000000000 & & & & \\
\hline & & 000000000000 & & & & \\
\hline & & 000000000000 & & & & \\
\hline & & 000000 & & & & \\
\hline 117 & & & & & & \\
\hline 118 & & & ** & ******* & ***************** & *** \\
\hline 119 & & & * Boot ROM revisi & on leve & 1 in ASCII & \\
\hline 120 & & & * (ORG & \$BFD1) & & \\
\hline 121 & BFD1 & 00 & & FCB & 0 & \\
\hline 122 & & & ***************** & ******* & ******************** & ***** \\
\hline 123 & & & * Mask set I.D. - & & & \\
\hline 124 & & & * (ORG & \$BFD2) & & \\
\hline 125 & BFD2 & 0000 & & FDB & \$0000 & \\
\hline 126 & & & \(\star \star * * * * * * * * * * * * * * ~\) & ******* & ******************* & ***** \\
\hline 127 & & & * 11D3 I.D. - can & be used & d to determine MCU & type \\
\hline 128 & & & * (ORG & \$BFD4) & & \\
\hline 129 & BFD 4 & 11D3 & & FDB & \$11D3 & \\
\hline 130 & & & \(\star * * * * * * * * * * * * * * * * *\) & ** & **************** & **** \\
\hline 131 & & & * VECTORS - point & to RAM & for pseudo-vector & JUMPs \\
\hline 132 & & & & & & \\
\hline 133 & BFD6 & 00C4 & & FDB & \$100-60 & SCI \\
\hline 134 & BFD8 & 00C7 & & FDB & \$100-57 & SPI \\
\hline 135 & BEDA & 00CA & & FDB & \$100-54 & PULSE ACCUM INPUT EDGE \\
\hline 136 & BFDC & OOCD & & FDB & \$100-51 & PULSE ACCUM OVERFLOW \\
\hline 137 & BFDE & OODO & & FDB & \$100-48 & TIMER OVERFLOW \\
\hline 138 & BFEO & 00D3 & & FDB & \$100-45 & TIMER OUTPUT COMPARE 5 \\
\hline 139 & BFE2 & 00D6 & & FDB & \$100-42 & TIMER OUTPUT COMPARE 4 \\
\hline 140 & BFE4 & 00D9 & & FDB & \$100-39 & TIMER OUTPUT COMPARE 3 \\
\hline 141 & BFE6 & OODC & & FDB & \$100-36 & TIMER OUTPUT COMPARE 2 \\
\hline 142 & BFE8 & 00DF & & FDB & \$100-33 & TIMER OUTPUT COMPARE 1 \\
\hline 143 & BFEA & OOE2 & & FDB & \$100-30 & TIMER INPUT CAPTURE 3 \\
\hline 144 & BFEC & 00E5 & & FDB & \$100-27 & TIMER INPUT CAPTURE 2 \\
\hline 145 & BFEE & O0E8 & & FDB & \$100-24 & TIMER INPUT CAPTURE 1 \\
\hline 146 & BFFO & OOEB & & FDB & \$100-21 & REAL TIME INT \\
\hline 147 & BFF2 & OOEE & & FDB & \$100-18 & IRQ \\
\hline 148 & BFF4 & 00F1 & & FDB & \$100-15 & XIRQ \\
\hline 149 & BFF6 & 00F4 & & FDB & \$100-12 & SWI \\
\hline 150 & BFF8 & 00F7 & & FDB & \$100-9 & ILLEGAL OP-CODE \\
\hline 151 & BFFA & 00FA & & FDB & \$100-6 & COP FAIL \\
\hline
\end{tabular}
\begin{tabular}{|c|c|c|c|c|c|c|c|}
\hline 152 BFFC 00FD & & & FDB & & 100-3 & CLOCK & MONITOR \\
\hline 153 BFFE BF40 & & & FDB & & EGIN & RESET & \\
\hline 154 C000 & & & END & & & & \\
\hline \multicolumn{8}{|l|}{Symbol Table:} \\
\hline Symbol Name & Value Def.\# & Line & Number & Cross & Reference & & \\
\hline BAUD & 002B*00027 & 00066 & 00086 & & & & \\
\hline BAUDOK & BF73 *00089 & 00084 & & & & & \\
\hline BEGIN & BF40 *00062 & 00153 & & & & & \\
\hline CONFIG & 003 F *0.0038 & & & & & & \\
\hline DDRD & 0009 *00019 & & & & & & \\
\hline delayf & 021B *00052 & 00069 & & & & & \\
\hline DELAYS & ODB0 *00051 & 00087 & & & & & \\
\hline EPGM & 0001 *00035 & & & & & & \\
\hline LAT & 0020 *00034 & & & & & & \\
\hline NEWONE & BF86 *00103 & 00095 & & & & & \\
\hline NOTZERO & BF67*00082 & 00080 & & , & & & \\
\hline OC1F & \(0080 * 00024\) & & & & & & \\
\hline PORTD & \(0008 * 00018\) & 00074 & & & & & \\
\hline PPROG & 003B *00032 & & & & & & \\
\hline RAMEND & OOFF *00047 & 00063 & 00108 & & & & \\
\hline RAMSTR & 0040 *00046 & 00090 & 00112 & & & & \\
\hline ROMEND & FFFF *00044 & & & & & & \\
\hline ROMSTR & F000 *00043 & 00081 & & & & & \\
\hline SCCR1 & 002C *00028 & & & & & & \\
\hline SCCR2 & 002D *00029 & 00068 & 00073 & 00075 & & & \\
\hline SCDAT & 002F *00031 & 00078 & 00104 & 00106 & & & \\
\hline SCSR & 002E *00030 & 00077 & 00095 & & & & \\
\hline SPCR & 0028 *00026 & 00064 & & & & & \\
\hline STAR & BF95 *00111 & 00101 & & & & & \\
\hline TCNT & O00E *00020 & & & & & & \\
\hline TEST1 & 003E *00037 & & & & & & \\
\hline TELG1 & 0023 *00022 & & & & & & \\
\hline TOC1 & 0016 *00021 & 00070 & 00088 & 00093 & & & \\
\hline WAIT & BF77 *00092 & 00109 & & & & & \\
\hline \multirow[t]{2}{*}{WTLOOP} & BF79 *00094 & 00100 & & & & & \\
\hline & \begin{tabular}{l}
Errors: None \\
Labels: 30
\end{tabular} & & & & & & \\
\hline Last Program & Address: \$BFFF & & & & & & \\
\hline Last Storage & Address: \(\$ 0000\) & & & & & & \\
\hline Progra & m Bytes: \(\$ 0000\) & \[
{ }_{0}^{192}
\] & & & & & \\
\hline
\end{tabular}
```

* BOOTLOADER FIRMWARE FOR MC68HC711D3 - 28 Aug 90
**********************************************************
* Features of this bootloader are...
* Auto baud select between 7812 and 1200 (E = 2 MHz).
* 0 - 192 byte variable length downioad:
* reception of characters quits when an idle of at
* least four character times occurs.
* Jump to EPROM at \$F000 if first download byte = \$00.
* PROGRAM - Utility subroutine to program EPROM.
* UPLOAD - Utility subroutine to dump memory to host.
* Part I.D, at \$BFD4 is \$71D3.
* Revision B -
* 
* Changed program delay to 2 mSec at E = 2 MHz
**********************************************************
* Revision A -
* 
* Fixed bug in PROGRAM routine where the first byte
* programmed into the EPROM was not transmitted for
* verify.
* Also added to PROGRAM routine a skip of bytes
* which were already programmed to the value desired.
* Equates (registers in direct space)
0008
0009
000E
0016
0023
0080
0028
002B
002C
002D
002E
002F
003B
0020
0001
003E
003F
50
51
53
55 F000
FFFF
0040
00FF
ODB0
021B
1068
7
BF00
* toxt two instructions provid
* change PROGRAM and UPLOAD even
BF00 7EBF10
BF03
7 9

```
\begin{tabular}{|c|c|c|}
\hline 80 & & *************************************************** \\
\hline 81 & & * UPLOAD - Utility subroutine to send data from \\
\hline 82 & & * inside the MCU to the host via the SCI interface. \\
\hline 83 & & * Prior to calling UPLOAD set baud rate, turn on SCI \\
\hline 84 & & * and set \(Y=\) first address to upload. \\
\hline 85 & & * Boot loader leaves baud set. SCI enabled, and \\
\hline 86 & & * Y pointing at EPROM start (\$FOOO) so these default \\
\hline 87 & & * values do not have to be changed typically. \\
\hline 88 & & * Consecutive locations are sent via SCI in an \\
\hline 89 & & \multirow[t]{2}{*}{* infinite loop. Reset stops the upload process.} \\
\hline 90 & & \\
\hline 91 & BF03 & UPLOOP EQU \\
\hline 92 & BF03 18A6,00 & LDAA \(0, Y\) Read byte \\
\hline 93 & BF06 132E80FC & BRCLR SCSR \(\$ 80\) * Wait for TDRE \\
\hline 94 & BEOA 972F & STAA SCDAT Send it \\
\hline 95 & BFOC 1808 & INY \\
\hline 96 & BFOE 20F3 & BRA UPLOOP Next... \\
\hline 97 & & \multirow[t]{2}{*}{*****************************************************} \\
\hline 98 & & \\
\hline 99 & & * PROGRAM - Utility subroutine to program EPROM. \\
\hline 100 & & * Prior to caliing PROGRAM set baud rate, turn on SCI \\
\hline 101 & & * set \(X=2 \mathrm{~ms}\) prog delay constant, and set \(Y=f\) irst \\
\hline 202 & & * address to program. SP must point to RaM. \\
\hline 103 & & * Bootloader leaves baud set, SCI enabled, \(X=4200\) \\
\hline 104 & & * and Y pointing at EPROM start (\$F000) so these default \\
\hline 105 & & * values do not have to be changed typically. \\
\hline 106 & & * Delay constant in \(X\) should be equivalent to 2 ms \\
\hline 107 & & * at \(2.1 \mathrm{MHz} \mathrm{X=4200;} \mathrm{at} 1 \mathrm{MHz} \mathrm{X}=2000\). \\
\hline 108 & & * An external voltage source is required for EPROM \\
\hline 109 & & * programming. \\
\hline 110 & & * This routine uses 2 bytes of stack space. \\
\hline 1:1 & & * Routine does not return. Reset to exit. \\
\hline \(\because 12\) & & **************************************************** \\
\hline 113 & 3 F 10 & \multirow[t]{2}{*}{\(\stackrel{\text { PRGROUT }}{\star}\) Send \(\$\) EF to indicate ready for program data} \\
\hline 114 & & \\
\hline : 5 & BF10 132E80FC & BRCLR SCSR \(\$ 80\) * Wait for TDRE \\
\hline 126 & BFi4 86FF & LDAA \#\$FF \\
\hline 117 & BF16 972F & STAA SCDAT \\
\hline 118 & & \\
\hline 119 & BF18 & WAIT 1 EQU \\
\hline 120 & BFi8 i32E20FC & BRCLR SCSR \$20 * Wait for RDRF \\
\hline :21 & BF1C D62F & LDAB SCDAT Get received byte \\
\hline -22 & BFIE 18E100 & CMPB \(\$ 0, Y\) See if already programmed \\
\hline :23 & BF21 2710 & BEQ DONEIT If so, skip prog cycle \\
\hline :24 & BF23 8620 & LDAA \#LAT Put EPROM in prog mode \\
\hline i25 & BF25 ¢.73B & STAA PPROG \\
\hline :26 & SF27 18E700 & STAB 0,Y Write data \\
\hline -27 & BF2A 8621 & \# LAT+EPGM \\
\hline -25 & BE2C 973B & STAA PPROG Turn on prog voltage \\
\hline -29 & EF2E 3C & PSHX Save delay on stack \\
\hline :30 & EF2F 8F & XGDX \\
\hline 137 & BF30 38 & \multirow[t]{2}{*}{PULX \(\quad\) TCNT} \\
\hline - 32 & BF 31 D30E & \\
\hline :33 & BF33 DD16 & STD TOC1 Schedule OCl (prog delay) \\
\hline -34 & BF35 8680 & LDAA \#OC1F \\
\hline :35 & BE37 9723 & STAA TFLG1 Clear any previous flag \\
\hline :36 & & \\
\hline 137 & BF39 132380FC & BRCLR TFLG1 OCIF * Wait for delay to expire \\
\hline 138 & BF3D 7F003B & CLR PPROG Turn off prog voltage \\
\hline \(\pm 39\) & BF40 & DONEIT EQU \\
\hline 140 & BF40 132E80FC & BRCLR SCSR \$80 * Wait for TDRE \\
\hline 141 & BF44 18A600 & LDAA \(\$ 0, Y\) Read from EPROM and... \\
\hline : 42 & BF47 972F & STAA SCDAT Xmit for verify \\
\hline 143 & BF49 1808 & INY Point to next location \\
\hline 144 & BF4B 20CB & BRA WAITl Back to top for next \\
\hline 145 & & \multirow[t]{2}{*}{} \\
\hline 146 & & \\
\hline 147 & & \multirow[t]{2}{*}{* Main bootloader starts here} \\
\hline 148 & & \\
\hline 149 & & \begin{tabular}{l}
* Main bootloader starts here \\
***************************************************
\end{tabular} \\
\hline 150 & & * RESET vector points to here \\
\hline 151 & & \\
\hline 152 & BF4D & \multirow[b]{2}{*}{\#RAMEND Initialize stack pntr} \\
\hline 153 & BF4D 8E00FF & \\
\hline 154 & BF50 142820 & BSET SPCR \$20 Select port D wire-OR mode \\
\hline 155 & BF53 CCA20C & LDD \#\$A20C Baud in A, SCCR2 in B \\
\hline 156 & BF56 972B & STAA BAUD \(\quad\) SCPx \(=/ 4, \mathrm{SCRx}=14\) \\
\hline 157 & & * Writing 1 to MSB of BAUD resets count chain \\
\hline 158 & BF58 D72D & STAB SCCR2 Rx and Tx enabled \\
\hline 159 & BF5A CC021B & LDD \#DELAYF Delay for fast baud rate \\
\hline
\end{tabular}

\begin{tabular}{|c|c|c|}
\hline 234 & BFE8 & 00DF \\
\hline 235 & BEEA & 00E2 \\
\hline 236 & BFEC & OOES \\
\hline 237 & BFEE & OOE8 \\
\hline 238 & BFFO & OOEB \\
\hline 239 & BFF2 & OOEE \\
\hline 240 & BFF4 & OOF1 \\
\hline 241 & BFF6 & 00F4 \\
\hline 242 & BFF8 & 00F7 \\
\hline 243 & BFFA & OOFA \\
\hline 244 & BFFC & OOFD \\
\hline 245 & BFFE & BF 4D \\
\hline 246 & C000 & \\
\hline Symb & 1 T & ble: \\
\hline
\end{tabular}
\begin{tabular}{ll} 
FDB & \(\$ 100-33\) \\
FDB & \(\$ 100-30\) \\
FDB & \(\$ 100-27\) \\
FDB & \(\$ 100-24\) \\
FDB & \(\$ 100-21\) \\
FDB & \(\$ 100-18\) \\
FDB & \(\$ 100-15\) \\
FDB & \(\$ 100-12\) \\
FDB & \(\$ 100-9\) \\
FDB & \(\$ 100-6\) \\
FDB & \(\$ 100-3\) \\
FDB & BEGIN \\
END &
\end{tabular}

TIMER OUTPUT COMPARE 1
TIMER INPUT CAPTURE 3
BFE
236 BEEC OOES
237 BFEE OOE8
239 BFF2 OOEB
240 BFF4 00F1
241 BFF6 OOF4
\(\begin{array}{lll}242 & \text { BFF8 OOF7 } \\ 243 & \text { BFFA OOFA }\end{array}\)
244 BFFC OOFD

Symbol Table:
\begin{tabular}{|c|c|c|c|c|c|c|c|c|c|}
\hline Symbol Name & Value & Def. \# & Line & Number & Cross & Refer & nce & & \\
\hline BAUD & 002B & *00039 & 00156 & 00176 & & & & & \\
\hline BAUDOK & BF80 & *00179 & 00174 & & & & & & \\
\hline BEGIN & BF4D & *00152 & 00245 & & & & & & \\
\hline CONFIG & 003F & *00050 & & & & & & & \\
\hline DDRD & 0009 & *00031 & & & & & & & \\
\hline DELAYF & 021B & *00064 & 00159 & & & & & & \\
\hline DELAYS & ODB0 & *00063 & 00177 & & & & & & \\
\hline DONEIT & BF40 & *00139 & 00123 & & & & & & \\
\hline EPGM & 0001 & *00047 & 00127 & & & & & & \\
\hline EPRMEND & FFFF & *00056 & & & & & & & \\
\hline EPRMSTR & F000 & *00055 & 00171 & 00203 & & & & & \\
\hline LAT & 0020 & *00046 & 00124 & 00127 & & & & & \\
\hline NEWONE & BF93 & *00193 & 00185 & & & & & & \\
\hline NOTZERO & BF74 & *00172 & 00170 & & & & & & \\
\hline OC1F & 0080 & *00036 & 00134 & 00137 & & & & & \\
\hline PORTD & 0008 & *00030 & 00164 & & & & & & \\
\hline PPROG & 003B & *00044 & 00125 & 00128 & 00138 & & & & \\
\hline PRGROUT & BF10 & *00113 & 00077 & & & & & & \\
\hline PROGDEL & 1068 & *00066 & 00202 & & & & & & \\
\hline PROGRAM & BFOO & *00077 & & & & & & & \\
\hline RAMEND & OOFF & *00059 & 00153 & 00198 & & & & & \\
\hline RAMSTR & 0040 & *00058 & 00180 & 00204 & & & & & \\
\hline SCCR1 & 002C & *00040 & & & & & & & \\
\hline SCCR2 & 002D & *00041 & 00158 & 00163 & 00165 & & & & \\
\hline SCDAT & 002F & *00043 & 00094 & 00117 & 00121 & 00142 & 00168 & 00194 & 00196 \\
\hline SCSR & 002E & *00042 & 00093 & 00115 & 00120 & 00140 & 00167 & 00185 & \\
\hline SPCR & 0028 & *0.0038 & 00154 & & & & & & \\
\hline STAR & BFA2 & *00201 & 00191 & & & & & & \\
\hline TCNT & OOOE & *00032 & 00132 & & & & & & \\
\hline TEST1 & 003E & *00049 & & & & & & & \\
\hline TFLG1 & 0023 & *00034 & 00135 & 00137 & & & & & \\
\hline TOC1 & 0016 & *00033 & 00133 & 00160 & 00178 & 00183 & & & \\
\hline UP LOAD & BF03 & *00078 & & & & & & & \\
\hline UPLOOP & BF03 & *00091 & 00096 & & & & & & \\
\hline WAIT & BF84 & *00182 & 00199 & & & & & & \\
\hline WAIT1 & BF18 & *00119 & 00144 & & & & & & \\
\hline WTLOOP & BF86 & *00184 & 00190 & & & & & & \\
\hline
\end{tabular}

\footnotetext{
Errors: None
Labels: 37
Last Program Address: \$BFFF Last Storage Address: \(\$ 0000\) Program Bytes: \(\$ 0100256\) Storage Bytes: \(\$ 00000\)
}
\begin{tabular}{|c|c|c|c|c|c|c|c|c|}
\hline  & \[
\underset{\sim}{\infty}
\]
ค & 界思界 いった & 罚罚罚罚界罚 ㅇㅇㅇㅇㅇ ก6のに00 & \[
\begin{aligned}
& \text { 罚 } \\
& 0
\end{aligned}
\] & \[
\begin{aligned}
& \text { OO } \\
& \text { No } \\
& \text { Ho m }
\end{aligned}
\] &  &  & \begin{tabular}{l}
 WWINNNNNNHOO \\

\end{tabular} \\
\hline \[
\begin{aligned}
& \text { DH } \\
& \text { Non } \\
& \text { No } \\
& \text { N } \\
& \text { On }
\end{aligned}
\] &  &  & \begin{tabular}{l}
ッดッ？ \\
 \(\infty 0 \infty\) 으우
\end{tabular} & & & & & \\
\hline
\end{tabular}



Symbol Table:
\begin{tabular}{|c|c|c|c|c|c|c|}
\hline Symbol Name & Value & Def. & Line & Number & Cross & Reference \\
\hline BAUD & 002B & *00031 & 00064 & 00096 & 0010 & \\
\hline BAUDOK & BF4B & *00107 & 00083 & 00098 & & \\
\hline BEGIN & BF00 & *00059 & 00170 & & & \\
\hline CONFIG & 003F & *00038 & & & & \\
\hline DDRD & 0009 & *00028 & & & & \\
\hline DELAYF & 021B & *00051 & 00067 & & & \\
\hline DELAYS & ODBO & *00050 & 00105 & & & \\
\hline EEPEND & FFFF & *00043 & & & & \\
\hline EEPSTR & FE00 & *00042 & 00079 & & & \\
\hline NEWONE & BF5C & *00120 & 00113 & & & \\
\hline NOTZERO & BF2A & *00080 & 00078 & & & \\
\hline PORTD & 0008 & *00027 & 00072 & & & \\
\hline PPROG & 003B & *00036 & & & & \\
\hline RAMEND & 03 FF & *00046 & 00060 & 00125 & & \\
\hline RAMSTR & 0000 & *00045 & 00108 & 00129 & & \\
\hline SCCR1 & 002C & *00032 & & & & \\
\hline SCCR2 & 002D & *00033 & 00066 & 00071 & 00073 & \\
\hline SCDAT & 002F & *00035 & 00076 & 00121 & 00123 & \\
\hline SCSR & 002E & *00034 & 00075 & 00113 & & \\
\hline Slobaud & BF44 & *00103 & 00087 & 00092 & & \\
\hline SPCR & 0028 & * 00030 & 00062 & & & \\
\hline STAR & BF6B & *00128 & 00118 & & & \\
\hline TEST1 & 003E & *00037 & & & & \\
\hline TOC1 & 0016 & *00029 & 00068 & 00106 & 00111 & \\
\hline WAIT & BF4F & *00110 & 00126 & & & \\
\hline WTLOOP & BF51 & *00112 & 00117 & & & \\
\hline
\end{tabular}

Errors: None
Labels: 26
Last Program Address: SBFFF Last Storage Address: \(\$ 0000\) Program Bytes: \(\$ 0100256\) Storage Bytes: \(\$ 00000\)
*****************************************************
* BOOTLOADER FIRMWARE FOR MC68HC11K4 - 18 Jul 90

* Features of this bootloader are...
* Auto baud select between \(7812,1200,9600,5208\)
    and \(3906(E=2 \mathrm{MHz})\)
* 0 - 768 byte variable length download
* reception of characters quits when an idle of at
* least four character times occurs. (Note: at 9600
* baud rate this is almost five bit times and at
* 5208 and 3906 rates the timeout is even longer).
* Jump to EEPROM at \(\$ 0 D 80\) if first download byte \(=\$ 00\)
* PROGRAM - Utility subroutine to program EPROM.
* UPLOAD - Utility subroutine to dump memory to host.
* Part I.D. at SBFD4 is \$044B.
* Equates (registers in direct space)
0004
0005
0008
0009
OOOE
OOOE
0016
0016
0023
002
0080
002B
0020
0001
003B
003 E
003F
0070
0072
0073
0074
0075
0076
0077
00
0D80
OFFF
2000
7FFE

0080
037 F
580
59
60
61
6215 AB
0356
1068

BE40
BF 00
72
72
73
74
76 BF 00
BF00 8E037F
\begin{tabular}{|c|c|c|}
\hline PORTB & EQU & \$04 \\
\hline PORTF & EQU & \$05 \\
\hline PORTD & EQU & \$08 \\
\hline DDRE & EQU & \$09 \\
\hline * & & \\
\hline TCNT & EQU & \$0E \\
\hline TOC1 & EQU & \$16 \\
\hline TFLG1 & EQU & \$23 \\
\hline * Bit equates & for TFLG1 & \\
\hline OC1F & EQU & \$80 \\
\hline EPROG & EQU & \$2B \\
\hline * Bit equates & for EPROG & \\
\hline ELAT & EQU & \$20 \\
\hline EPGM & EQU & \$01 \\
\hline * & & \\
\hline PPROG & EQU & \$3B \\
\hline TEST1 & EQU & \$3E \\
\hline CONEIG & EQU & \$3F \\
\hline * & & \\
\hline SCBD & EQU & \$70 \\
\hline SCCR1 & EQU & \$72 \\
\hline SCCR2 & EQU & \$73 \\
\hline SCSR1 & EQU & \$74 \\
\hline SCSR2 & EQU & \$75 \\
\hline SCDRH & EQU & \$76 \\
\hline SCDRL & EQU & \$77 \\
\hline
\end{tabular}
* Memory configuration equates
\begin{tabular}{|c|c|c|c|}
\hline EEPMSTR & EQU & \$0D80 & Start of EEPROM \\
\hline \(\underset{*}{\text { EEPMEND }}\) & EQU & \$0FFF & End of EEPROM \\
\hline ROMSTR & EQU & \$2000 & Start of ROM \\
\hline \(\underset{*}{\text { ROMEND }}\) & EQU & \$7FFF & End of ROM \\
\hline RAMSTR & EQU & \$0080 & Start of RAM \\
\hline RAMEND & EQU & \$037F & End of RAM \\
\hline \multicolumn{4}{|l|}{* Delay constants} \\
\hline DELAYS & EQU & 5547 & Delay at slow baud rate \\
\hline \({ }_{*}^{\text {DELAYF }}\) & EQU & 854 & Delay at fast baud rates \\
\hline PROGDEL & EQU & at 2.1 MHz & 2 mSec programming delay \\
\hline CYCLCOD & EQU & \$BE40 & EPROM cycling code (TEST) \\
\hline \multicolumn{4}{|l|}{***************************************************} \\
\hline \multicolumn{2}{|r|}{ORG} & \multicolumn{2}{|l|}{\$BF00} \\
\hline \multicolumn{4}{|l|}{* Main bootloader starts here} \\
\hline \multicolumn{4}{|l|}{* Main bootloader starts here} \\
\hline \multicolumn{4}{|l|}{* RESET vector points to here} \\
\hline \multirow[t]{2}{*}{\[
\begin{aligned}
& \text { * RESET } \\
& \text { BEGIN }
\end{aligned}
\]} & EQU & & \multirow[b]{2}{*}{Initialize stack pntr} \\
\hline & LDS & \#RAMEND & \\
\hline
\end{tabular}

\section*{Listing 7. MC68HC11K4 Bootloader ROM}



Listing 7. MC68HC11K4 Bootloader ROM




\begin{tabular}{|c|c|c|c|c|c|c|}
\hline 242 & BFBE & & NEWONE & EQU & * & \\
\hline 243 & BFBE & 9677 & & LDAA & SCDRL & \multirow[t]{2}{*}{Get received data Store to next RAM location} \\
\hline 244 & BFC0 & 18A700 & & STAA & \$00, Y & \\
\hline 245 & BFC3 & 9777 & & STAA & SCDRL & Transmit it for handshake \\
\hline 246 & BFC5 & 1808 & & INY & & Point to next RAM location \\
\hline 247 & BFC 7 & 188 C 0380 & & CPY & \#RAMEND+1 & \multirow[t]{2}{*}{See if past end If not, get another} \\
\hline 248 & BFCB & 26E6 & & BNE & WAIT & \\
\hline 249 & & & & & & \\
\hline 250 & BFCD & & STAR & EQU & * & \multirow[b]{2}{*}{** Exit to start of RAM **} \\
\hline 251 & BFCD & 7E0080 & & JMP & RAMSTR & \\
\hline 252 & & & \multicolumn{4}{|l|}{} \\
\hline 253 & & & \multicolumn{4}{|l|}{\multirow[t]{2}{*}{* Block fill unused bytes with zero}} \\
\hline 254 & & & & & & \\
\hline 255 & BFD0 & 00 & & BS2 & \$BFD1-* & \\
\hline 256 & & & \multicolumn{4}{|l|}{\multirow[t]{2}{*}{}} \\
\hline 257 & & & & & & \\
\hline 258 & & & \multicolumn{3}{|l|}{\multirow[t]{2}{*}{\begin{tabular}{l}
* Boot ROM revision level in ASCII \\
* (ORG SBFD1)
\end{tabular}}} & \\
\hline 259 & & & & & & \\
\hline 260 & BFD1 & 42 & \multicolumn{3}{|c|}{FCC "B"} & \\
\hline 261 & & & \multicolumn{4}{|l|}{} \\
\hline 262 & & & \multicolumn{4}{|l|}{\multirow[t]{2}{*}{}} \\
\hline 263 & & & & & & \\
\hline 264 & BFD2 & 0000 & \multicolumn{3}{|r|}{FDB \$0000} & \\
\hline 265 & & & \multicolumn{4}{|l|}{***********************************************} \\
\hline 266 & & & \multicolumn{4}{|l|}{\multirow[t]{2}{*}{\begin{tabular}{l}
* 711K4 I.D. - can be used to determine MCU type \\
* (note: \(\$ 4 \mathrm{~B}=\mathrm{K}\) in ASCII)
\end{tabular}}} \\
\hline 267 & & & & & & \\
\hline 268 & & & * (ORG \({ }^{*}\) SBED4) & \multicolumn{2}{|l|}{\$BFD4)} & \\
\hline 269 & BFD 4 & 744B & \multicolumn{3}{|l|}{*********************************} & \\
\hline 270 & & & \multicolumn{4}{|l|}{} \\
\hline 271 & & & \multicolumn{4}{|l|}{\multirow[t]{2}{*}{* VECTORS - point to RAM for pseudo-vector JUMPs}} \\
\hline 272 & & & & & & \\
\hline 273 & BFD6 & 00C4 & & FDB & \$100-60 & SCI \\
\hline 274 & BFD8 & 00C7 & & FDB & \$100-57 & SPI \\
\hline 275 & BFDA & 00CA & & FDB & \$100-54 & PULSE ACCUM INPUT EDGE \\
\hline 276 & BFDC & OOCD & & FDB & \$100-51 & PULSE ACCUM OVERFLOW \\
\hline 277 & BFDE & 00D0 & & FDB & \$100-48 & TIMER OVERFLOW \\
\hline 278 & BFEO & 00D3 & & FDB & \$100-45 & \multirow[t]{2}{*}{TIMER OUTPUT COMPARE 5
TIMER OUTPUT COMPARE 4} \\
\hline 279 & BFE2 & 00D6 & & FDB & \$100-42 & \\
\hline 280 & BFE4 & 00D9 & & FDB & \$100-39 & TIMER OUTPUT COMPARE 4
TIMER OUTPUT COMPARE 3 \\
\hline 281 & BFE6 & OODC & & FDB & \$100-36 & TIMER OUTPUT COMPARE 2 \\
\hline 282 & BFE8 & 00DF & & FDB & \$100-33 & TIMER OUTPUT COMPARE 1 \\
\hline 283 & BFEA & OOE2 & & FDB & \$100-30 & TIMER INPUT CAPTURE 3 \\
\hline 284 & BFEC & O0E5 & & FDB & \$100-27 & TIMER INPUT CAPTURE 2 \\
\hline 285 & BFEE & 00E8 & & FDB & \$100-24 & TIMER INPUT CAPTURE 1 \\
\hline 286 & BFFO & 00EB & & FDB & \$100-21 & REAL TIME INT \\
\hline 287 & BFF2 & O0EE & & FDB & \$100-18 & IRQ \\
\hline 288 & BFF4 & 00F1 & & FDB & \$100-15 & XIRQ \\
\hline 289 & BFF6 & 00F4 & & FDB & \$100-12 & SWI \\
\hline 290 & BFF8 & 00F7 & & FDB & \$100-9 & Illegal OP-CODE \\
\hline 291 & BFFA & 00FA & & FDB & \$100-6 & COP FAIL \\
\hline 292 & BFFC & 00FD & & FDB & \$100-3 & CLOCK MONITOR \\
\hline 293 & BFFE & BF5C & & FDB & BEGIN & \multirow[t]{2}{*}{RESET} \\
\hline 294 & C 000 & & & END & & \\
\hline
\end{tabular}


\section*{AN1064}

\title{
Use of Stack Simplifies M68HC11 Programming
}

\section*{By Gordon Doughman}

\section*{INTRODUCTION}

The architectural extensions of the M6800 incorporated into the M68HC11 allow easy manipulation of data residing on the stack of the microcontroller unit (MCU). The M68HC11 central processing unit (CPU) automatically uses the stack for two purposes. Each time the CPU executes a branch to subroutine (BSR) or jump to subroutine (JSR) instruction, it pushes a return address onto the stack. This procedure allows the CPU to resume execution with the instruction following the BSR or JSR when the program returns from the subroutine. Second, just before the MCU executes an interrupt service routine, the CPU saves its register contents on the stack, allowing the registers to be restored when the CPU executes a return from interrupt (RTI) instruction at the end of the interrupt service routine. Two additional uses of the M68HC11 stack discussed in this application note are the storage of local or temporary variable values and subroutine parameter passing.

Using the stack for local variables and parameter passing provides the assembly language programmer with the following benefits. First, since a routine allocates storage space for local variables and parameters upon entry and releases the storage upon exit, the same temporary memory space can be reused by program routines that run in succession. This reuse can result in a substantial savings in the total amount of RAM required by a program.
Second, allocating a new set of local variables and parameters when entering a routine makes it both reentrant and recursive. Routines that possess these two properties can make a programmer's job much easier when debugging a program in a real-time, interrupt-driven environment.

Third, placing local variables and parameters on the stack helps to promote modular programming. Because all temporary storage required by a routine is allocated and deallocated by the program module itself, it can be easily detached from the main program for reuse or replacement.

The final major benefit of using the stack for local variables and parameters becomes apparent during the debugging process. Because a routine's local variables and parameters exist only while it is executing, it is very unlikely that one routine will accidentally modify the local variables and parameters of another routine. Once the programmer has written and debugged a routine, time can be spent finding logical errors and/or problems associated with the interaction of the different routines in a program.
The goal of this application note is to help the assembly language programmer understand the following topics: 1) the basic operation of the M68HC11 stack, 2) the concept of local and global variables, 3) subroutine parameter passing, and 4) use of the M68HC11 instruction set to support local variables and parameter passing.

The source code for the examples and the macros described in this application note can be obtained by calling the Motorola FREEWARE Bulletin Board Service (BBS) at (512) 891-3733. The FREEWARE BBS operates 24 hours a day, 7 days a week, except for maintenance. The BBS's format is 300-2400 BAUD, 8 data bits, 1 stop bit, and no parity.

\section*{M68HC11 STACK OPERATION}

The M68HC11 supports a stack through the use of the CPU stack pointer (SP) register. The SP is a 16 -bit register that points to an area of RAM used for stack storage. Because the SP is 16 bits wide, the stack can be located anywhere in the M68HC11 64 K byte address space. The SP contents are undefined at power-up and are normally initialized in the first few instructions of a program. Each time a byte is pushed onto the stack, the SP is automatically decremented. Therefore, the initial value loaded into the SP is usually the address of the last RAM location in a system. Thus, as more information is pushed onto the stack, the stack area grows downward (the SP points to lower addresses) in the memory map. The SP always contains the address of the next available location on the stack.

As previously mentioned, the stack on the M68HC11 is used automatically by the CPU hardware during subroutine calls/returns and during the servicing of interrupts. When a subroutine is called by a JSR or BSR instruction, the address of the instruction following the JSR or BSR is automatically pushed onto the stack. Since the M68HC11 only has an 8-bit data bus, two separate push operations are performed by the CPU hardware. During the first push operation, the low-order eight bits ( \(b 7-b 0\) ) of the return address are placed on the stack. The second push operation places the high-order eight bits (b15-b8) of the return address on the stack at the next lower address in memory. Performing the operation in this order leaves the 16-bit return address on the stack in the order that all 16-bit numbers are stored in memory, with the high-order eight bits at the lower address. After a JSR or BSR instruction, the stack appears as shown in Figure 1.


Figure 1. Stack Contents after Executing a JSR or BSR Instruction

Whenever an unmasked interrupt occurs, the contents of all CPU registers (with the exception of the SP itself) are pushed onto the stack as shown in Figure 2. After the registers are stacked, CPU execution continues at an address specified by the vector for the pending interrupt source. Upon completion of the interrupt service routine, the execution of an RTI instruction restores the previously saved CPU registers by pulling them off the stack in the reverse order in which they were pushed onto the stack. Since the entire state of the CPU is restored, execution resumes as if the interrupt had not occurred.


Figure 2. Stack Contents after an Interrupt

The M68HC11 instruction set contains instructions that allow the individual CPU registers to be pushed onto and pulled off the stack. For example, if the value contained in one of the CPU registers needs to be saved before a particular subroutine call, a push instruction places the register value on the stack. When the subroutine returns, a pull instruction restores the contents of the CPU register. These instructions not only allow the stack to be used as temporary data storage but also allow the construction of recursive and reentrant subroutines. M68HC11 instructions that involve the direct manipulation of the SP are listed in Table 1.

Table 1. Instructions Involving Direct Manipulation of the SP
\begin{tabular}{|c|l|}
\hline Instruction Mnemonic & \multicolumn{1}{|c|}{ Description } \\
\hline PSHA & Push Accumulator A onto the Stack. \\
\hline PSHB & Push Accumulator B onto the Stack. \\
\hline PULA & Pull Accumulator A off the Stack. \\
\hline PULB & Pull Accumulator B off the Stack. \\
\hline PSHX & Push Index Register X onto the Stack. \\
\hline PSHY & Push Index Register Y onto the Stack. \\
\hline PULX & Pull Index Register \(X\) off the Stack. \\
\hline PULY & Pull Index Register \(Y\) off the Stack. \\
\hline INS & Increment the Stack Pointer by 1. \\
\hline DES & Decrement the Stack Pointer by 1. \\
\hline TXS & Place the Contents of Index Register \(X-1\) in the Stack Pointer. \\
\hline TYS & Place the Contents of Index Register \(Y-1\) in the Stack Pointer. \\
\hline TSX & Place the Contents of the Stack Pointer +1 in Index Register X. \\
\hline TSY & Place the Contents of the Stack Pointer +1 in Index Register Y. \\
\hline
\end{tabular}

\section*{STACK USAGE}

Although most assembly language programmers use the M68HC11 stack for subroutine return addresses, register contents during interrupt processing, and temporary CPU register storage, more powerful programming techniques can make additional use of the stack.

Most high-level language compilers for modern, block-structured, high-level languages make use of the stack for two additional functions: passing parameters and local or temporary variable storage. By borrowing some of these techniques, programmers can write assembly language programs that are much more reliable, easier to maintain, and easier to debug.

\section*{VARIABLES IN ASSEMBLY LANGUAGE}

Computer programs rarely operate on data directly; instead, the program refers to variables. A variable is a physical location in computer memory that can be used to hold different values while the program runs. Variables usually have an identifier or name associated with them. Using names to refer to data contained in memory is much easier than trying to remember a long string of binary or hexadecimal numbers.

Besides a name and an address, variables may have several other attributes. Depending on the programming language, variable declarations may assign attributes to the variables restricting both the scope and extent of the variable. The scope of a variable is the range of program text in which a particular variable is known and can be used. The extent of a variable is the time during which a computer associates physical storage with a variable name.
In assembly language, the scope of variables is usually giobal - i.e., variables may be referenced throughout the text of a program. Though some assemblers may provide mechanisms to restrict the scope of declared variables, many assembly language programmers do not use these features. A programmer using assembly language usually declares variables by employing an assembler directive as shown in Listing 1. This method assigns fixed storage locations to the variables. The extent of variables declared this way is for the entire program execution - i.e., the storage locations assigned to the variables at assembly time remain allocated during the entire time the program is executing.
```

* ram locations
* 

OEG S10
J:TBLP PMB 1 DATE. TABLE POINTER REGISTER.
S\#ENS% RMB 1 STATION BIT MASK REGISTER.
ECT:UU: PMB 1 FUNCTION NUMBER REGISTER FOR MODE SET.
Z:EMP RMB 2 Z-REG. TEMPORARY STORAGE.
ZZEMP: RMB 2 X-REGISTER TEMPORARY STORAGE.
AEME: PMB 1 A-REGISTER TEMPORARY STORAGE.
COM:L: RMB I COUNT USED DURING STATION POLLING LOOP.
YPCNT PMB 1 'NUMBER OF YEYS PRESSED' COUNT.
LSTFC: PMB 1 LAST T/L FUNCTION THAT WAS PROCESSED.
CEIST PME 1 PEMOTE CALL STATUS BYTE.
OTEMP2 PMB 1 A-REG. TEMPORARY STORAGE FOR THE DELAY SUBROUTINE.
ZTEMP3 F:A3 2 Y-REG. STOPAGE BEFORE CALL TO DELAY SUBROUTINE.
COUNT2 PIKB 1 COUNT USED IN DELAY SUBROUTINE.
IONESL PMS 1 'NONE SELECTED' REGISTER USED BY SSCHK.

```

\section*{Listing 1. Declaring Global Variables in Assembly Language}

Further examination of the variable declarations in Listing 1 shows that several variables are used for intermediate calculation results or for temporary CPU register storage. This example is typical of the way many assembly language programmers allocate temporary storage. Each time they write a routine requiring temporary variable storage, they allocate an additional set of global variables. The
use of this technique can lead to the inefficient use of RAM if there are many routines within a program requiring temporary storage.

In an effort to make more efficient use of the limited amount of RAM on single-chip MCUs, some programmers use a technique known as "variable sharing." Listing 2 shows a portion of a listing using this technique. In this program, more than one routine shares the use of a single temporary variable. To keep track of which routines use which variables, each line, in addition to the variable declaration, contains a list of the routines using that particular variable. In small programs, it may not be too difficult to manage temporary variables this way; however, in large programs having hundreds or thousands of routines using temporary variables, it becomes impossible to keep track of which routines use which temporary variables at any given time.
```

* 
* RAM LOCATIONS
* 
* 

ORG \$0
*** variables - used by: ***
PTR0 RMB 2 main, readbuff,incbuff,AS
PTR1 RMB 2 main,BR,DU,MO,AS,EX
PTR2 RMB 2 EX,DU,MO,AS
PTR3 RMB 2 EX,HO,MO,AS
PTR4 RMB 2 EX,AS
PTR5 RMB 2 EX,AS,BOOT
PTR6 RMB 2 EX,AS,BOOT
PTR7 RMB 2 EX,AS
PTR8 RMB 2 AS
TMP1 RMB 1 main,hexbin,buffarg,termarg
TMP2 RMB 1 GO,HO,AS,LOAD
TMP3 RMB 1 AS,LOAD
TMP4 RMB 1 TR,HO,ME,AS,LOAD

```

Listing 2. Declaring Global Variables in Assembly Language

The sharing of temporary variable storage shown in Listing 2 can produce debugging problems that are extremely hard to find. The chances of having one routine unintentionally modify the temporary storage of another can become quite high in large programs. In interrupt-driven, real-time systems, the sharing of temporary variables by various routines can become disastrous. Consider the situation illustrated in Figure 3. Subroutine \(A\) and subroutine \(B\) both share the temporary variable Temp1. Initial\(l y\), there seems to be no problem since subroutine \(A\) and subroutine \(B\) do not call one another. Yet, consider what happens if an interrupt occurs during the execution of subroutine A. Because of the interrupt, subroutine \(B\) is called indirectly through subroutine \(C\). The execution of subroutine \(B\) causes any value placed in Temp1 by subroutine \(A\) before the interrupt to be overwritten! Because interrupts usually occur asynchronously to main program execution, the program may appear to operate properly most of the time and crash randomly, depending on when an interrupt occurs. This type of apparently random program failure can be almost impossible to find:


Figure 3. Two Subroutines Sharing a Single Temporary Variable

Though this example may seem overly simplistic, a program that contains hundreds or thousands of routines makes it nearly impossible to keep track of which subroutines are using what variables at any specific time, particularly if the main program and interrupt service routines share subroutines. The solution to this type of problem may seem simple - do not allow any subroutines to share globally declared temporary variables. This solution is acceptable provided enough RAM is available for all required temporary variables. A better solution to this problem can be found by examining the way modern, block-structured, high-level languages use temporary variables.

\section*{VARIABLES IN BLOCK-STRUCTURED HIGH-LEVEL LANGUAGES}

Most block-structured, high-level languages, notably C and Pascal, provide the ability to limit both the scope and the extent of variables as part of the language definition. In both C and Pascal, the scope of a variable is local to the block in which it is declared. The scope of variables declared outside of a block (function or procedure) is usually global. These global variables are similar to the ones declared in the assembly language shown in Listing 1. They can be accessed by all routines within a program, and they remain in existence throughout the entire time the program executes. Listing 3 shows an example of how global variables are declared in C and Pascal.
```

        Pascal
    var
x,y:integer; int x,y;
j:char;
z:boolean;
num:array[1..10] of integer;
Date:record
Month:integer;
Day:integer;
Year:integer;
end; };
program(input,output);
end.
main()
{
j
}

```

C
```

char j;

```
char j;
char j;
char j;
int z;
int z;
int num[9];
int num[9];
struct Date {
struct Date {
    int x,y;
    int x,y;
    int Day;
    int Day;
    int Year;
```

    int Year;
    ```

\section*{Listing 3. Declaring Global Variables in High-Level Languages}

Variables declared within a function or procedure have their scope limited to that function or procedure. The extent of these variables is also limited. These variables, known as local or automatic variables, come into existence when the functions or procedures that contain them are called. When a function or procedure finishes execution, the local variables disappear, and the memory locations occupied by them can be used again. Listing 4 shows an example of how local variables are declared in C and Pascal. In both examples, the variables \(i\) and \(j\) are local to procedure/function A and do not exist outside them.
```

        Pascal
    var
x,y:integer; int x,y;
z:boolean; int z;
proceaure A; A()
var
i,j:integer;
begin
.
end;
c
A()
.
i

```

C
int \(z\);

A()
int i.j;

Listing 4. Declaring Local Variables in High-Level Languages

There are several benefits of using local variables. First, the restricted life of local variables can result in memory savings. Since storage for local variables is allocated upon entry to a routine and released upon exit from a routine, the same temporary memory space can be used by many different program routines. If two routines are run in succession, each can use the same storage locations.

Second, since a new set of local variables is allocated each time the procedure or function is entered, it makes the routine both reentrant and recursive. A reentrant routine is one that allocates a new set of local variables upon entry. When complex programs are run in a real-time, interrupt-driven environment, the interrupt handlers may call the routine that was interrupted. Making routines reentrant can greatly simplify a programmer's job during the debugging process in a real-time environment. The same properties that make a routine reentrant also makes a routine recursive. A recursive routine is one that can call itself.

Third, the use of local variables helps to promote modular programming. A program module is a selfcontained program element that can be easily detached from the main program either for reuse in another program or for replacement. Since any storage space for local variables is allocated and deallocated by the program module itself, the module code can easily be copied from a single place within one program and reused in another program.

A fourth benefit of using local variables is evidenced during the debugging process. In complex programs, there may be hundreds or thousands of routines that have to interact with each other. Since local variables help isolate any changes made within a routine, debugging becomes a much simpler process. Once routines are written and debugged, the programmer does not have to worry about one routine accidentally modifying the local variables of another. Instead, time can be spent finding any logical errors and/or problems associated with the interaction of routines in the program.

Even with all the benefits provided by the use of local variables, there are some costs associated with their use. On the M68HC11, programs using local variables tend to be slightly larger and slower than programs using only global variables because the addressing modes required to access the local variables can make the instruction somewhat longer and may cause longer execution time. Given the benefits of using local variables, a slightly larger and slower program is usually well worth the cost.

The reusable memory storage for local variables is usually taken from the same memory space used for the MCU's hardware stack. Placing local variables on the hardware stack leaves them intact even if the routine using them is interrupted. The specifics of allocating, deallocating, and accessing local variables residing on the M68HC11 stack is discussed in USING THE M68HC11 STACK.

\section*{PASSING PARAMETERS}

To make routines more flexible and to vary their actions each time they are called, different information must be passed to the routines. Generally, most assembly language programmers use the CPU registers to pass information to a subroutine. Using this technique is acceptable as long as the amount of information to be passed to the subroutine fits within the available CPU registers.

When the amount of information to be passed to a routine exceeds the space available in the CPU registers, the information can be passed in a set of global variables. This technique may be acceptable for some situations, but it can also cause problems that make debugging difficult. One problem with passing parameters in this manner is that it makes a routine non-reentrant. Referring to Figure 4, assume that subroutine A's parameters are passed in a set of global variables. If subroutine A is called either by the main program or by subroutine \(C\) as a result of an interrupt, the program will work correctly. If an interrupt occurs during the execution of subroutine A, the original parameters passed by the main program will be overwritten when subroutine \(C\) calls subroutine \(A\). When the processor returns from the interrupt and resumes execution of subroutine \(A\), it will be using incorrect parameter data, and the results passed back to the main program will most likely be incorrect.


Figure 4. Subroutine Calling Chain

Because interrupts usually occur asynchronously to main program execution, the program may appear to operate properly most of the time and crash randomly. This type of problem can be extremely difficult to locate and can make debugging of real-time, interrupt-driven systems very difficult. Passing the parameters on the stack completely solves this problem. When subroutine \(C\) calls subroutine \(A\) as a result of the interrupt, a new set of parameters is placed on the stack while the original parameters remain undisturbed. Figure 5 shows the state of the stack after an interrupt.


Figure 5. Stack State as a Result of an Interrupt

In addition to where parameters are passed, there is also an issue of how parameters are passed. Subroutine parameters can be passed either by value or by reference. When a parameter is passed by value, the parameter acts as a local variable whose initial value is provided by the calling routine. Any modification of the supplied value has no effect on the original data that was passed to the subroutine. Thus, a subroutine can import values but not export values by means of value parameters.
Passing a parameter by reference is one method used to pass results back to a calling subroutine. These types of parameters are known as variable parameters. When using variable parameters, the address of the actual parameter is passed to the subroutine rather than a value. The passed address can be a local variable of the calling routine or even the address of a global variable. Whenever a subroutine has to effect a permanent change in the values passed to it, the parameters must be passed by reference rather than by value.
Consider the following example in both C and Pascal that exchanges the value of two integers:
Pascal Call By Value
procedure SwapInt (x,y:integer);
        var
        Temp:integer;
        begin
            Temp: =x;
            \(x:=y\)
            \(y:=\) Temp
        end;
            Call By Reference
    procedure SwapInt (var \(x, y:\) integer);
    var
        Temp:integer;
        begin
            Temp:=x;
            \(x:=y\)
        \(y:=\) Temp
        end;
    Call Of "SwapInt" Using Either Method
            program(output);
                var
                \(z, w:\) integer;
                beg in
                \(z:=2\);
                        w: \(=4\);
                        SwapInt ( \(z, w)\);
                end;

\section*{Listing 5. Passing Parameters by Reference and by Value}

If the call-by-value routine were to be used in this example, the routine would not work as the programmer might expect. It would exchange the local values of \(x\) and \(y\) within the Swapint routine, but it would have no effect on the actual variables in the routine's call statement. For the SwapInt routine to work properly, the routine must be declared so that the parameters are passed by reference rather than by value. As mentioned previously, passing a parameter by reference passes the address of the actual parameter. In the example in Listing 5, using the call-by-reference routine, the addresses of the variables \(z\) and \(w\) are passed to the Swaplnt routine when it is called from the main program. This procedure allows the Swapint routine to exchange the actual values of the variables passed to the routine.

\section*{FUNCTION/SUBROUTINE RETURN VALUES}

Most subroutines or functions, if they are to perform a useful action in a program, will return one or more values to the calling routine. Any value or status can be returned using one of the three methods previously described. When a subroutine only needs to return a single value, one of the CPU registers is commonly used to pass the value back to the calling routine. This simple, safe technique allows the routine to remain reentrant. This method is used most often by C compilers to return a value from a function.

Similar to the situation that exists when passing parameters in the CPU registers, there may be times when a routine must return more information than will fit in the CPU registers. The information can be returned in a set of global variables; however, as previously described, this method poses the same problems as passing parameters in this manner. Returning results in global variables makes the routine non-reentrant and can cause the same debugging problems previously described.

A better way to return large amounts of data from a subroutine is to allocate the required amount of space on the stack either just before or just after pushing a routine's parameters onto the stack. This method possesses the same benefits of passing parameters on the stack - it makes the routine completely reentrant and self-contained. Most Pascal compilers return function values in this manner.

\section*{USING THE M68HC11 STACK}

This section specifically discusses how to allocate, deallocate, and access both local variables and parameters residing on the M68HC11 stack. The programmer's model of the M68HC11 is shown in Figure 6. The following paragraphs briefly describe the CPU registers and their usage.


Figure 6. M68HC11 Programmer's Model

The \(A\) and \(B\) accumulators are used to hold operands and the results of arithmetic and logic operations. These two 8 -bit registers can be concatenated to form a single 16 -bit \(D\) accumulator to support the M68HC11 16-bit arithmetic instructions. The \(A\) and \(B\) accumulators can easily be used to push data onto or pull data off the stack.

The \(X\) and \(Y\) index registers are used in conjunction with the CPU indexed addressing mode. The indexed addressing mode uses the contents of the 16 -bit index register in addition to a fixed 8 -bit unsigned offset that is part of the instruction to form the effective address of the operand to be used by the instruction. The index registers play a very important role in accessing data residing on the stack.

The CPU SP is a 16 -bit register that points to an area of RAM used for stack storage. The stack is used automatically during subroutine calls to save the address of the instruction that follows the call. When an interrupt occurs, the stack is used automatically by the CPU to save the entire CPU register contents on the stack (except for the SP itself). The SP always contains the address of the next available location on the stack.

The program counter ( PC ) is a 16 -bit register used to hold the address of the next instruction to be executed.

The condition code register (CCR) contains five status indicators and two interrupt mask bits. The status bits reflect the results of arithmetic and other operations of the CPU as it performs instructions.

Before considering the specifics of parameter passing and the utilization of local variables that reside on the M 68 HC 11 stack, the method used to access the information placed on the stack will be discussed. One M68HC11 index register and the CPU indexed addressing mode are used to access parameters or local variables residing on the stack. With respect to the indexed addressing mode, the contents of one of the 16 -bit index registers plus a fixed unsigned offset is used in calculating the effective address of an instruction's operand. The unsigned offset, contained in a single byte following the instruction opcode, can only accommodate positive offsets in the range 0-255. Thus, the indexed addressing mode can only access information at addresses that are between 0 and 255 bytes greater than the base address contained in one of the index registers. Figure 7 illustrates how to calculate the effective address of an instruction using the indexed addressing mode.


Figure 7. Effective Address Calculation for the Indexed Addressing Mode

As information is pushed onto the M68HC11 stack, the SP is decremented, signifying that the information placed on the stack resides at addresses greater than the address contained in the SP. The use of indexed addressing is ideal for accessing information residing on the M 68 HC 11 stack. The example shown in Figure 8 illustrates how information on the stack is manipulated.


Figure 8. Stack Data Access Example

As Figure 8 shows, the SP is pointing to the next available address, and the Y index register is pointing to the last data placed on the stack. The instruction LDD 1, Y will load the value of the local variable ' \(x\) ' into the D accumulator. To access the parameter 'Num,' the instruction LDD 7, Y can be used. Any instructions that support the indexed addressing mode can be used to manipulate stack data.

\section*{PASSING PARAMETERS}

Parameters are easily placed on the M68HC11 stack by CPU push instructions. Table 2 lists the push instructions available on the M68HC11. Note that there is not a single instruction for pushing the D accumulator onto the stack. A PSHD instruction can easily be simulated by executing the two instructions PSHB, PSHA. These two instructions must be executed in this order to keep the value pushed onto the stack consistent with the way 16 -bit values are stored in memory - i.e., 16 -bit values are placed in memory with the most significant eight bits at a lower address than the least significant eight bits. By following this convention, a 16-bit parameter pushed onto the stack in this manner is easily retrieved using one of the 16 -bit load instructions.

Table 2. Push Instructions in the M68HC11 Instruction Set
\begin{tabular}{|c|l|}
\hline Instruction Mnemonic & \multicolumn{1}{|c|}{ Description } \\
\hline PSHA & Push Accumulator A onto the Stack. \\
\hline PSHB & Push Accumulator B onto the Stack. \\
\hline PSHX & Push Index Register \(X\) onto the Stack. \\
\hline PSHY & Push Index Register \(Y\) onto the Stack. \\
\hline
\end{tabular}

As previously mentioned, parameters can be passed either by value or by reference. Consider a function, Int2Asc, that converts a signed 16-bit integer to ASCII text and places the ASCII characters in a text buffer. The function requires two parameters: the number to be converted into ASCII text and
ád pointer to a buffer where the ASCII text is to be stored. The first parameter is passed to the subroutine by value because the actual number to be converted is passed to the function. The second parameter is passed by reference because a pointer to the buffer is passed to the routine and not the buffer itself. A function declaration written in C is shown in Listing 6.
```

void Int2Asc(int. Num; char *Buff)
{
jnt Pwrl0 = 10000;
char zs = 0;
.
i

```

\section*{Listing 6. Function Declaration of Int2Asc}

Before calling an equivalent routine written in M 68 HC 11 assembly language, the two parameters will be pushed onto the stack as shown in Listing 7.
\begin{tabular}{lll} 
LDK & ErrorNum & ; Get the value of the current error. \\
PSH\% & & ; Place it on the stack. \\
iD\% & \#OUt Buff & ; Get the address of the Output buffer. \\
HSH\% & Int2ASC & ; Place it on the stack. \\
JSH & ; Go convert the number.
\end{tabular}

\section*{Listing 7. Placing Parameters on the M68HC11 Stack}

Using the immediate addressing mode with the second load index register X (LDX) instruction loads the address of OutBuff into the \(X\) index register rather than the 16 -bit value contained in the memory locations OutBuff and OutBuff+1. After both parameters have been pushed onto the stack, the function is called with a JSR instruction. Upon entry to the subroutine Int2Asc, the parameters reside just above the return address as shown in Figure 9.


Figure 9. Location of Parameters Passed on the Stack

\section*{ALLOCATING LOCAL VARIABLES}

Four basic techniques can be used to allocate local variables that reside on the stack. Choosing which one to use depends upon the total amount of storage required for the local variables and whether or
not the variables need to have an initial value assigned to them. Of course, a combination of all four techniques can be used.
One technique used to allocate space on the stack for local storage involves the use of the decrement stack pointer (DES) instruction. The DES instruction subtracts one from the value of the SP each time the instruction is executed, allocating one byte of local variable storage for each DES instruction. This technique is a simple and direct way of allocating local storage but becomes impractical when large amounts of local storage are required. For instance, if 100 bytes of local storage are required for a subroutine, 100 DES instructions are needed to allocate the required amount of storage. This required amount is clearly unacceptable since each DES instruction requires one byte of program memory. Even if a small program loop is set up to execute 100 DES instructions, the subroutine will suffer a severe execution speed penalty each time the routine is entered.

Using the previously described technique requires one byte of program storage for each byte of local storage that is allocated. Since allocating local storage simply involves decrementing the SP, the PSHX instruction can be used to allocate two bytes of local storage space for each executed PSHX instruction. The actual contents of the X index register are irrelevant because the only concern is decrementing the SP. The use of this technique can be confusing if not properly documented since it is not directly obvious what is being accomplished with five or six sequentially executed PSHX instructions.

Many times it is necessary to initialize local variables with a particular value before they are used. The same technique used to push parameters onto the stack before a subroutine call can also be used to allocate space for local variables and simultaneously assign initial values to them. This procedure is accomplished by loading one of the CPU registers with a variable's initial value and executing a PSH instruction. The program fragment in Listing 8 shows the use of this technique to allocate and initialize both an 8 - and 16 -bit local variable.


Listing 8. Allocating and Initializing Local Variables

If more than 13 bytes of local storage are required by a subroutine, a fourth technique allocates storage more efficiently than using multiple DES or PSHX instructions. Since there are not any instructions that allow arithmetic to be performed directly on the SP, the fourth technique involves using several M 68 HC 11 instructions. These instructions adjust the value of the SP downward in memory, allocating the required amount of local storage. Listing 9 shows the instruction sequence required to allocate an arbitrary number of bytes of local storage.


Listing 9. Allocation of More Than 13 Bytes for Local Storage

Since no single instruction allows the contents of the SP to be transferred to the \(D\) accumulator, the two-instruction sequence transfer from SP to index register \(X\) or \(Y\); exchange double accumulator and index register \(X\) or \(Y\) (TSX; XGDX or TSY; XGDY) must be used. Placing the SP value in the D accumulator allows the use of the 16-bit subtract instruction to adjust the value of the SP. The subtract double accumulator (SUBD) instruction will subtract the 16 -bit value xxxx from the contents of the D accumulator. To place this new value in the SP, the two-instruction sequence XGDX; TXS or XGDY; TYS is used.

\section*{NOTE}

Actually the TSX or TSY instruction causes the SP value plus one to be transferred to either the \(X\) or \(Y\) index register (SP +1 \(\rightarrow X\) or \(S P+1 \rightarrow Y\) ). This transfer does not pose a problem because when the SP is updated with the TXS or TYS instruction, one is subtracted from the value of the index register \((X-1 \rightarrow\) SP or \(\mathrm{Y}-1 \rightarrow \mathrm{SP}\) ) before the SP is updated. Remember that since the SP points to the next available location on the stack, adding one to its value before the execution of the TSX or TSY instruction makes the X or Y index register point to the last data placed on the stack.

\section*{CREATING A COMPLETE STACK FRAME}

In addition to providing storage space for local variables and parameters, a complete stack frame (sometimes called an activation record) must contain two additional pieces of information: a return address and a pointer to the base of the stack frame of any previous routines. The return address is placed on the stack automatically by the M68HC11 when it executes either a JSR or BSR instruction. As shown in Figure 9, the return address is placed on the stack just below a subroutine's parameters.

Before using either the \(X\) or \(Y\) index register to access a routine's parameters or local variables, the contents of the register must first be saved. The index register contents, known as the stack frame pointer, may contain the base address of a stack frame for a routine from which control was transferred. This pointer must be maintained so that when control is returned to the calling routine, the calling routine's environment can be restored to its previous state. Even if a routine has no local variables or parameters, the contents of the index register being used as the stack frame pointer must be saved before the register is used for any other purpose.

The best time to save the value of the previous stack frame pointer is immediately upon entry to a subroutine, which places the previous stack frame pointer immediately below the return address as shown in Figure 10.


Figure 10. Location of the Stack Frame Pointer

After space for local variables has been allocated, the stack frame pointer for the new subroutine needs to be initialized. By transferring the contents of the SP to either the X or Y index register using the TSX or TSY instruction, a new stack frame is created.

In summary, creating a complete stack frame involves the following three steps after entering a subroutine:
1. Immediately upon entry to a subroutine, the contents of the index register being used as the stack frame pointer must be saved by using either the PSHX or PSHY instruction.
2. Storage space for the routine's local variables should be allocated using one of the three methods described earlier.
3. The new stack frame pointer must be initialized using either the TSX or TSY instruction.

The last issue to discuss is which index register to use as the stack frame pointer. In terms of code size and speed, the X index register would be the most logical choice since ALL instructions involving the Y index register require one additional opcode byte and one additional clock cycle to execute. However, if a program is not making extensive use of the stack for local variables and parameters but is performing extensive array or table manipulations, the Y index register may be a better choice. No matter which index register is used as the stack frame pointer, it should be, if at all possible, dedicated to that use throughout a program. Program debugging is much easier if the contents of a single index register can always be expected to point to the current stack frame.

\section*{ACCESSING PARAMETERS AND LOCAL VARIABLES}

As mentioned in USING THE M68HC11 STACK, local variables and parameters are accessed by using instructions that support the indexed addressing mode. The following list identifies the load and store instructions as well as all arithmetic and logic instructions that support indexed addressing. Because most M68HC11 instructions support indexed addressing, it is just as code efficient to manipulate local variables that reside on the stack as it is to manipulate global variables using direct or extended addressing. Figure 11(a) illustrates a complete allocation frame as used by a subroutine.
\begin{tabular}{lllll} 
ADC & ADCB & ADDA & ADDB & ADDD \\
ANDA & ANDB & ASL & ASR & BCLR \\
BITA & BITB & BRCLR & BRSET & BSET \\
CLR & CMPA & CMPB & COM & CPD \\
CPX & CPY & DEC & EORA & EORB \\
INC & JMP & JSR & LDAA & LDAB \\
LDD & LDS & LDX & LDY & LSL \\
LSR & NEG & ORA & ORB & ROL \\
POR & SBCA & SBCB & STAA & STAB \\
STD & STS & STX & STY & SUBA \\
SUBB & SUBD & TST & &
\end{tabular}

Using the indexed addressing mode to access data contained in a stack frame places a restriction on the combined size of local variables and parameters. Since the indexed addressing mode functions by adding an unsigned 8 -bit offset to the contents of the 16 -bit index register, the indexed addressing mode can only access information at addresses that are between 0 and 255 bytes greater than the base address contained in one of the index registers. Consequently, the maximum size of a single stack frame is restricted to 256 bytes. If no parameters are passed to a routine on the stack, then the entire 256 bytes are available for local variables. However, when parameters are passed on the stack, not only is the space occupied by the parameters unavailable for use as local variables, but the subroutine return address and previous stack frame pointer reduce the amount of available space by an additional four bytes.

In most embedded control applications that use the M68HC11 in the single-chip mode, this limit on the combined size of parameters and local variables for a single stack frame is rarely a concern since the amount of on-chip RAM is limited. Several techniques can be used to work around the limit imposed by the indexed addressing mode; however, they are extremely wasteful in terms of code space and execution speed.

\section*{NOTE}

In reality, the amount of memory available for local storage in a single stack frame is 257 bytes. Because the M68HC11 is capable of loading and storing 16 bits of data with a single instruction, it is possible to access one byte beyond the contents of the index register plus the fixed offset of 255 with the 16 -bit load and store instructions.

\section*{DEALLOCATING THE STACK FRAME}

When a subroutine has completed execution, the stack space allocated for the stack frame must be released so the memory can be reused by subsequent subroutine calls. The deallocation of the stack frame includes not only the removal of the space occupied by the local storage, but also the restoration of the previous stack frame pointer and the removal of space occupied by any parameters that were passed to the subroutine.
The process of freeing the memory occupied by the stack frame is simply a matter of adjusting the value of the SP upward in memory. The SP must be adjusted upward by the same amount that it was adjusted downward when the space for the stack frame was allocated. Either of the following methods can be used to perform this task.

The most obvious way to perform the deallocation is to reverse the process used to allocate the storage. Removing the stack frame in this manner involves three basic steps. First, the storage occupied by any local variables must be removed from the stack area by using the reverse of one of the techniques described in ALLOCATING LOCAL VARIABLES. Alternately, the technique shown in Listing 10 can be used. This technique involves adjusting the value of the SP upward in memory by the same amount it was adjusted downward when the space was allocated.
```

SDAB \#LOCLEN Get size of local storage into the B register.
ABX Add it to the current stack frame pointer.
TYS Deallocate the iocal storage.

```

\section*{Listing 10. Alternate Method for Deallocating Local Storage}

Second, the previous stack frame pointer must be restored. Because the previous stack frame pointer is now on the top of the stack, the use of a pull index register X or Y from the stack (PULX or PULY) instruction is all that is needed to perform this operation. At this point, the return address is on the top of the stack. Simply executing a return from subroutine (RTS) instruction returns program execution to the instruction following the subroutine call.

After returning to the calling routine, any parameters that were pushed onto the stack before the subroutine call must now be removed. This places the burden of removing subroutine parameters on the calling routine rather than on the called routine. This method of removing subroutine parameters is perfectly acceptable and is the one most often used by C language compilers.
Removing the parameters can be as simple as a one-instruction operation. If the \(X\) or \(Y\) index register contains the address of the current stack frame pointer, simply executing a TXS or TYS instruction places the SP just below the stack frame pointer. If the \(X\) or \(Y\) index register does not contain the
address of the current stack frame pointer, an alternate method must be used to remove the parameters. Figure 11 illustrates the state of the stack at each stage of the deallocation process.

An alternate method requires the called routine to remove the entire stack frame, including any parameters passed to it. This method may not be as code efficient as the first method since it requires a fixed number of instructions to release the storage space occupied by the entire stack frame. Listing 11 shows the instruction sequence necessary to deallocate the stack frame when the \(X\) index register is being used as the stack frame pointer. This four-instruction sequence requires nine bytes of program storage space and 18 cycles to execute but removes the entire stack frame, regardless of the size. This method of stack frame deallocation has one drawback - the \(X\) or \(Y\) index register must always contain a valid stack frame pointer. Thus, all subroutines, even if they do not require parameters or local variables, must "mark" the current state of the stack upon entry by executing a PSHX; TSX or PSHY; TSY instruction sequence.


Figure 11. Deallocation of the Stack Frame

\section*{NOTE}

In Listing 11, RA is the offset value to the <Return Address> and PSFP is the offset value to the <Previous Stack Frame Pointer>.
\begin{tabular}{lll} 
LDY & RA, X & Load the return address into the \(Y\) register. \\
LDX & PSFP, X & Restore the previous stack frame pointer. \\
TXS & & Remove the entire stack frame. \\
JMP & \(0, Y\) & Return to the calling routine.
\end{tabular}

Listing 11. Alternate Method for Deallocating the Entire Stack Frame

In summary, choosing a method to deallocate the stack frame involves a tradeoff between code size and execution speed. Using the first method results in the smallest amount of code being generated but may take longer to execute than the method shown in Listing 11.

\section*{SUPPORT MACROS}

The following macros may be used to help in managing stack frames in M68HC11 programs. Using these macros may not provide the smallest or fastest code in all situations but should make the program easier to write and debug. Although the macros were written for the Micro Dialects \(\mu \mathrm{ASM}-\mathrm{HC} 11^{\text {TM }}\) assembler that runs on the Macintosh \({ }^{T M}\), they can be used with other assemblers with some modification. The following paragraph explains the way parameters are passed and referenced in the Micro Dialects assembler and should help in the conversion process.

When a macro is defined, parameters are not declared. When a macro is invoked, the parameters appear in the operand field following the macro name. Within a macro definition, parameters are referenced by using a colon (:) followed by a single decimal digit (0-9). Therefore, within the body of the macro, the first parameter is referenced by using ' \(: 0\) ', the second parameter is referenced by using ' \(: 1\) ', and so forth. Parameter substitution is performed strictly on a textual substitution basis.
The link macro shown in Listing 12 can be used to allocate a complete stack frame after entry into a subroutine. The link macro performs the following functions: 1) saves the previous stack frame pointer, 2) allocates the required number of bytes of local storage, and 3) initializes a new stack frame pointer. The calling convention for the link macro is as follows:
```

link <s.f. reg>.<storage bytes>

```

The first parameter passed to the macro is the name of the index register being used as the stack frame pointer (either X or Y ). Although no check is made to ensure that a legal index register name is passed to the macro, the assembler will produce an "Unrecognized Mnemonic" error message when the macro is expanded. The second parameter is the number of bytes of local storage required by the subroutine.
```

_i-k macro
psh:0 ; Save the previous stack frame pointer.
₹s:0 ; Transfer the stack pointer into :0.
xgă:0 ; Transfer :0 into D.
subci \#:: ; subtract the required amount of local storage.
xgá:0 ; Initialize the new stack frame pointer
=:0s ; Update the stack pointer with new value.
enam

```

Listing 12. The Link Macro
The return and deallocate (rtd) macro shown in Listing 13 can be used to partially deallocate a subroutine stack frame. The rtd macro performs the following functions: 1) deallocates local storage, 2) restores the previous stack frame pointer, and 3) returns to the calling routine. The rtd macro DOES NOT remove any parameters from the stack that may have been passed to the subroutine. Removal of any parameters must be performed by the calling routine. This macro is useful when no parameters are passed to a subroutine or when parameters are passed in registers. The calling convention for the rtd macro is as follows:

Like the link macro, the first parameter passed to the rtd macro is the name of the index register.being used as the stack frame pointer (either X or Y ). Again, although no check is made to ensure that a legal index register name is passed to the macro, the assembler will produce an "Unrecognized Mnemonic" error message when the macro is expanded. The second parameter is the number of bytes of local storage allocated when the subroutine was entered.


\section*{Listing 13. The Return and Deallocate Macro}

The only drawback in using this macro is that it uses the \(\mathbf{B}\) accumulator when deallocating a subroutine's local storage, preventing a subroutine from returning a 16 -bit result in the \(D\) accumulator. A simple solution to the problem is to surround the load accumulator \(B\) (LDAB) and add accumulator \(B\) to index register X or Y (ABX/ABY) instructions with the PSHB/PULB instruction pair as shown in Listing 14. This macro, renamed frtd for function return and deallocate, allows the \(D\) accumulator to be loaded with a return value immediately before the macro is called. A second solution to this problem is to place all return values on the stack as described in FUNCTION/SUBROUTINE RETURN VALUES, allowing the calling routine to retrieve the returned value and then remove it along with the parameters.
\begin{tabular}{|c|c|c|c|}
\hline frtd & macro & & \\
\hline & pshb & & ; save the lower byte of the return value. \\
\hline & ldab & \# : 1 & ; number of bytes to deallocate. \\
\hline & \(a b: 0\) & & ; add it to the current stack frame pointer. \\
\hline & pulb & & ; restore the lower byte of the return value. \\
\hline & \(t: 0 \mathrm{~s}\) & & ; dealiocate storage by updating the stack pointer. \\
\hline & pul:0 & & ; restore the previous stack frame pointer. \\
\hline & rts & & ; return to the calling routine. \\
\hline
\end{tabular}

Listing 14. The Function Return and Deallocate Macro

The return and deallocate using \(x\) (rtdx) and return and deallocate using y (rtdy) macros shown in Listing 15 can be used to completely deallocate a subroutine stack frame, including any parameters that were passed on the stack. The rtdx and rtdy macros perform the following functions: 1) deallocates the entire stack frame, including local storage and passed parameters, 2) restores the previous stack frame pointer, and 3) returns to the calling routine. The calling convention for the rtdx and itdy macros is as follows:

> rtdx <storage bytes> or rtdy <storage bytes>

The only parameter passed to the macros is the number of local storage bytes allocated upon entry to the subroutine. These macros have an advantage over the rtd macro in that the \(A\) and \(B\) accumulators are not used during deallocation, which allows a return value to be loaded into the \(A, B\), or \(D\) registers before execution of the rtdx or rtdy macro.
```

rtdx macro ldy : 0+2,x ; Load the return address into the }Y\mathrm{ index register.
ldx :0,x ; restore the previous stack frame pointer.
txs ; Update the stack pointer, removing the storage space.
jmp 0,y ; Return to the calling routine.
endm
*
*
rtdy macro
ldx : 0 +2,y ; Load the return address into the }x\mathrm{ index register.
ldy :0,y ; restore the previous stack frame pointer.
tys ; Update the stack pointer, removing the storage space.
jmp 0,x ; Return to the calling routine.
endm

```

Listing 15. The rtdx and rtdy Macro

The only restriction to using the rtdx and ridy macros is that a valid stack frame pointer for the previous subroutine must be present in either the \(X\) or \(Y\) index register when the register is pushed onto the stack at the beginning of the subroutine. Even if a subroutine has no local variables in it or no parameters passed to it, a PSHX and TSX instruction must be executed immediately upon entry to a subroutine to save the previous stack frame pointer and "mark" the current state of the stack. Before returning, a PULX instruction must be executed to restore the previous stack frame pointer.
This restriction implies that, somewhere in the program, the index register to be used as the stack frame pointer must be initialized with a valid value. If either the \(X\) or \(Y\) index register is to be dedicated for use as a stack frame pointer, the index register must be initialized at the beginning of the program. The initial value loaded into the index register should be one more than the value loaded into the stack pointer, which is easily accomplished by executing the TSX instruction immediately after initializing the stack pointer.

In summary, the use of the rtdx and rtdy macros are convenient in that they remove both parameters and local variables passed to subroutines. However, their use will cost three extra instructions in subroutines that do not have local variables or parameters but call subroutines that use local variables or have parameters passed to them.

\section*{EXAMPLES}

Appendix A contains several examples that use the techniques described to manage local storage, parameter passing, and allocation/deallocation of stack frames.

\title{
APPENDIX A EXAMPLE LISTINGS
}
```

1





| 285 | 0007 |  | [ 3] |  | psha |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 286 | 0008 | 1830 | [4] |  | tsy |  | ; initialize the new stack frame pointer. |
| 287 | 000A | 18 EC 07 | [ 6] |  | ldd | num, y | ; get the number to convert. Is it zero? |
| 288 | 000D | 260B | [ 3] |  | bne | Int 2Asc1 | ; no go do the conversion. |
| 289 | 000F | CC3000 | [ 3] |  | ldd | \#\$3000 | ; yes. |
| 290 | 0012 | CDEE09 | [ 6] |  | 1 dx | Buff $\mathrm{P}, \mathrm{y}$ | ; point to the buffer. |
| 291 | 0015 | 18ED00 | [ 6] |  | std | 0, y | ; just put an ASCII 0 in the buffer. |
| 292 | 0018 | 2050 | [ 3] |  | bra | Int 2 Asc 5 | ; then return. |
| 293 | 001A | 186D0B | [ 71] | Int 2 Asc 1 | tst | Signed, y | ; do the conversion as a signed number? |
| 294 | 001D | 2716 | [ 3] |  | beq | Int 2 Asc 2 | ; no. |
| 295 | 001F | 4D | ( 2) |  | tsta |  | ; yes. Is the number negative? |
| 296 | 0020 | 2A13 | [ 3] |  | bpl | Int 2 Asc 2 | ; no. just go do the conversion. |
| 297 | 0022 | 43 | [ 2] |  | coma |  | ; yes. make it a positive number by negation. |
| 298 | 0023 | 53 | [ 2] |  | comb |  |  |
| 299 | 0024 | C30001 | \| 41 |  | addd | \# \$1 |  |
| 300 | 0027 | 18 ED 07 | [ 6] |  | std | Num, y | ; save the result. |
| 301 | 002A | 862D | 121 |  | Idaa | \#' - ' | ; get an ASCII minus sign. |
| 302 | 002C | CDEE09 | [ 6] |  | 1 dx | Buffp,y | ; point to the buffer. |
| 303 | 002F | A700 | [4] |  | staa | $0, \mathrm{x}$ | ; put it in the buffer. |
| 304 | 0031 | 08 | [ 3] |  | inx |  | ; point to the next location in the buffer. |
| 305 | 0032 | CDEF09 | [ 6] |  | stx | Buffp,y | ; save the new pointer value. |
| 306 | 0035 | 18 EC 07 | [ 6] | Int2Asc2 | 1 dd | Num, Y | ; get the remainder to convert. |
| 307 | 0038 | CDEE01 | [ 61 |  | 1 dx | Divisor,y |  |
| 308 | 003B | 02 | [41] |  | idiv |  |  |
| 309 | 003C | 18 ED 07 | [ 6] |  | std | Num, y | ; save the remainder. |
| 310 | 003F | 8 F | [ 3] |  | xgdx |  | ; put the dividend into d. |
| 311 | 0040 | 5D | [ 2] |  | tstb |  | ; was the dividend 0? |
| 312 | 0041 | 2605 | [ 3] |  | bne | Int 2 Asc 3 | ; no. go store the number in the buffer. |
| 313 | 0043 | 186D00 | [7] |  | tst | zs,y | ; are we still supressing leading zeros? |
| 314 | 0046 | 2710 | [3] |  | beq | Int2Asc4 | ; yes. go setup for the next divide. |
| 315 | 0048 | CB30 | [ 2] | Int 2 Asc 3 | addb | \#'0' | ; make the dividend ASCII. |
| 316 | 004A | 8601 | [2] |  | ldaa | \#1 |  |
| 317 | 004C | 18 A700 | ( 5) |  | staa | zs,y | ; don't supress leading zeros anymore. |
| 318 | 004F | CDEE09 | ( 6] |  | 1 dx | Buffery | ; get a pointer to the buffer. |
| 319 | 0052 | E700 | [ 4] |  | stab | $0, \mathrm{x}$ | ; save the digit. |
| 320 | 0054 | 08 | [ 3] |  | inx |  | ; point to the next location. |
| 321 | 0055 | CDEF09 | [ 6] |  | stx | Buffeg | ; save the new pointer value. |
| 322 | 0058 | 18 EC 01 | 1 61 | Int 2 Asc 4 | 1 dd | Divisor, y | ; get the previous divisor. |
| 323 | 005B | CE000A | [ 31] |  | $1 d x$ | \# 10 |  |
| 324 | 005E | 02 | [41] |  | idiv |  | ; divide it by 10. |
| 325 | 005F | CDEF 01 | [6] |  | stx | Divisor, y | ; save the dividend. Is it zero? |
| 326 | 0062 | 26D1 | [ 3] |  | bne | Int2Asc2 | ; no. continue with the conversion. |
| 327 | 0064 | CDEE09 | [ 6] |  | 1 dx | Buffe,y | ; get a pointer to the buffer. |
| 328 | 0067 | 6F00 | [ 6] |  | clr | $0, \mathrm{x}$ | ; null terminate the string. |
| 329 | 0069 | 30 | ( 3) |  | tsx |  | ; this is only needed because we are using $y$ as our sf pointer. |
| 330 | 006A |  |  | Int 2 Asc 5 | rtdx | LocSize | ; return \& deallocate locals \& parameters. |
| 331 | 006A | 1AEE05 | [6] |  | $1 d y$ | LocSize $+2, x$ | ; Load the return address into the y-index register. |
| 332 | 006D | EE03 | [ 5] |  | 1 dx | LocSize, x | ; restore the previous stack frame pointer. |
| 3.33 | 006F | 35 | [ 3] |  | txs |  | ; Update the stack pointer, removing the storage space. |
| 334 | 0070 | 186E00 | [4] |  | jmp | 0,y | ; Return to the calling routine. |
| 335 |  |  | * |  |  |  |  |
| 336 |  |  | * |  |  |  |  |
| 337 |  |  | * |  |  |  |  |
| 338 |  |  |  | 杜 | *** | *********** |  |
| 339 |  |  | * |  |  |  |  |
| 340 |  |  |  |  |  |  |  |
| 341 |  |  |  |  |  |  |  |
| 342 |  |  | * result. Two 16 -bit numbers are passed to the subroutine on the stack. <br> * The 32 -bit result is returned on the stack in place of the two 16 -bit <br> * parameters. This allows the calling routine to easily pull the product |  |  |  |  |
| 343 |  |  |  |  |  |  |  |
| 344 |  |  | * | from the stack and store the result. Because multiplication is a |  |  |  |
| 345 |  |  |  | commutative operation, the order in which the parameters are pushed |  |  |  |
| 346 |  |  |  | onto the stack is unimportant. A typical calling sequence would be: |  |  |  |
| 347 |  |  | ( ${ }^{\text {a }}$ |  |  |  |  |
| 348 |  |  | * | 1 dd | Num1 |  |  |
| 349 |  |  |  | pshd |  |  |  |
| 350 |  |  | * | ldd | Num2 |  |  |
| 351 |  |  | * | pshd |  |  |  |
| 352 |  |  | * |  | Mul $16 \times 16$ |  |  |
| 353 |  |  | * | puld |  |  |  |
| 354 |  |  | * std | std | Result 32 |  |  |
| 355 |  |  | * | puld | Result $32+2$ |  |  |
| 356 |  |  | , | std |  |  |  |




| 506 | 00BE | CDEE0E | [ 6] |  | 1 dx | Denm, y | load the divisor into $x$. |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 507 | 00C1 | 02 | [41] |  | idiv |  | ; divide the upper 16 bits by the divisor. |
| 508 | 00C2 | CDEF00 | [ 6] |  | stx | Quo0,y | ; save the partial quotient. |
| 509 | 00C5 | CDEE0E | [ 6] | Div $32 \times 16 \mathrm{a}$ | ldx | Denm, $y$ | ; load the divisor into $x$. |
| 510 | 00C8 | 03 | [41] |  | fdiv |  | ; resolve the remainder into a 16 -bit fractional part. |
| 511 | 00C9 | CDEF02 | [ 6] |  | stx | Quo2,y | ; save the partial result. |
| 512 | 00CC | 18 ED 04 | [ 6] |  | std | Rem, y | ; save the remainder of the fractional divide (partial remainder). |
| 513 | 00CF | 18ECOC | [ 6] |  | 1dd | Num2, y | ; get the lower 16-bits of the dividend. |
| 514 | 00D2 | cdeeom | [ 6] |  | 1 dx | Denm, $y$ | ; get the denominator again. |
| 515 | 00D5 | 02 | [41] |  | idiv |  | ; resolve the remaining quotient. |
| 516 | 00D6 | 18 E 304 | [ 7] |  | addd | Rem, y | ; add the previous remainder to this remainder. |
| 517 | 00D9 | 18 ED 04 | [ 6] |  | std | Rem, y | ; save the total remainder. |
| 518 | OODC | 8 F | [ 3] |  | xgdx |  | ; put the last partial quotient into the d-accumulator... |
| 519 |  |  |  |  |  |  | ; \& save the total remainder in x . |
| 520 | OODD | 18 E 302 | [ 7] |  | addd | Quo2,y | ; add partial quoient to the lower 16 -bits of the quotient. |
| 521 | OOEO | 18EDOC | [ 6] |  | std | Num2, y | ; save the result. |
| 522 | 00E3 | 18 EC 00 | [ 6] |  | ldd | Quo0, y | ; get the upper 16 -bits of the quotient. |
| 523 | 00E6 | C900 | [ 2] |  | adcb | \# 0 | ; add the possible carry to the lower 8-bits. |
| 524 | 00E8 | 8900 | [ 2] |  | adca | \# 0 | ; add the possible carry to the upper 8-bits. |
| 525 | 00EA | 18ED0A | [ 6] |  | std | Num0, y | ; save the result. |
| 526 | OOED | 8 F | [ 3] |  | xgdx |  | ; get the total remainder back into d. |
| 527 | 00EE | CDA30E | [ 7] |  | cmpd | Denm, y | ; is the total fractional remainder > the divisor? |
| 528 | 00F1 | 2519 | [ 3] |  | blo | Div $32 \times 16 \mathrm{~b}$ | ; no. we're finished. |
| 529 | 00F3 | 18A30E | [ 7] |  | subd | Denm, y | ; yes. It will be < than $2 *$ Divisor. |
| 530 | 00F6 | 18ED04 | [ 6] |  | std | Rem, y | ; save the final remainder. |
| 531 | 00F9 | 18EC0C | [ 6] |  | 1dd | Num2, y | ; now we must add 1 to the 32-bit quotient. |
| 532 | 00FC | C30001 | [ 4] |  | addd | \#1 | ; add 1 to the lower 16-bits. |
| 533 | 00FF | 18EDOC | [ 6] |  | std | Num2, y | ; save the result. |
| 534 | 0102 | 18EC0A | [ 6] |  | 1 dd | Num0, y | ; get the upper 16 -bits. |
| 535 | 0105 | C900 | [ 2] |  | adcb | \# 0 | ; add the possible carry to the lower 8-bits. |
| 53.6 | 0107 | 8900 | [ 2] |  | adca | \# 0 | ; add the possible carry to the upper 8-bits. |
| 537 | 0109 | 18ED0A | [ 6] |  | std | Num0, y | ; save the result. |
| 538 | 010C | 18 EC 04 | [ 6] | Div $32 \times 16 \mathrm{~b}$ | ldd | Rem, y | ; get the final remainder. |
| 539 | 010F | 18ED0E | [ 6] |  | std | Denm, y | ; overwrite the divisor. |
| 540 | 0112 | 30 | [ 31 |  | tsx |  | ; need to do this for rtd to work correctly. See NOTE. |
| 541 | 0113 |  |  |  | rtd | x,LocSize | ; deallocate locals \& return. |
| 542 | 0113 | C606 | [ 2] |  | 1 dab | \#LocSize | ; number of bytes to deallocate. |
| 543 | 0115 | 3A | [ 3] |  | $a b x$ |  | ; add it to the current stack frame pointer. |
| 544 | 0116 | 35 | [ 3] |  | txs |  | ; deallocate storage by updating the stack pointer. |
| 545 | 0117 | 38 | [5] |  | pulx |  | ; restore the previous stack frame pointer. |
| 546 | 0118 | 39 | [ 5] |  | rts |  | ; return to the calling routine. |
| 547 | cycles total $=347$ |  |  |  |  |  |  |
| 548 |  |  |  |  |  |  | ; Total number of E cycles for a $32 \times 16$ divide. |
| 549 |  |  | * |  |  |  |  |

$$
\begin{array}{rl}
\qquad \begin{array}{l}
\text { Errors: } \\
\text { Labels: }
\end{array} & 30 \\
\text { Last Program Address: } & \text { S0118 } \\
\text { Last Storage Address: } & \text { \$FFFF } \\
\text { Program Bytes: } \$ 0119 & 281 \\
\text { Storage Bytes: } \$ 000 \mathrm{D} 13
\end{array}
$$

# AN1065 

# Use of the MC68HC68T1 Real-Time Clock with Multiple Time Bases 

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## INTRODUCTION

The MC68HC68T1 is an HCMOS peripheral chip containing a real-time clock/calendar and a 32 byte static RAM array. A synchronous, serial, three-wire interface (synchronous peripheral interface) is provided for communication with a microcomputer. The MC68HC68T1 can use a crystal or the 50/60 hertz line frequency as its timebase.

Often applications are line powered during normal operation but must continue to maintain the correct time-of-day when powered down. During normal operation the timebase is provided by the power mains ( 50 or 60 hertz). When the main power is lost, the 50/60 hertz timebase is lost. At this point, the clock must switch to crystal operation to provide correct time keeping. The MC68HC68T1 is not directly capable of this; additional support must be provided by the host microcomputer. This application note makes use of the Motorola MC68HC11A8P1 as the host MCU, as it provides the necessary Serial Peripheral Interface. MCUs that do not provide this functionality may emulate it in software by manipulating parallel I/O.

The power line is chosen as the preferred timebase because of the accuracy provided by the electric utility companies. A 32.768 kHz crystal, on the other hand, is quite sensitive to temperature variations, and to the voltage on which the oscillator runs. Temperature sensitivity often exceeds $0.035 \mathrm{ppm} /{ }^{\circ} \mathrm{C}$ and aging can exceed $5 \mathrm{ppm} /$ year. This may cause errors exceeding twenty seconds per month, if the crystal is subjected to wide temperature variations, such as encountered in remote, outdoor sites.

Contrast this error with that achieved with the power line as a timebase, which may be under one second per month.

This application note discusses the transition from line to crystal timebase operation during line power failure, and back to line power timebase when line power is reestablished.

## CIRCUIT OPERATION

The purpose of this circuit is to demonstrate the use of the MC68HC68T1 in a application using both the power line and a crystal as the timebase, depending on the availability of line power. As such, it is just a skeleton of an actual system. No method to set the clock is provided; just a subroutine called "SET_CLCK" which always sets the clock to 00:00:00, Friday, January 1, 1990 ( 24 hour time). An actual application would, of course, prompt the operator for the correct time and date.

The demonstration software puts the MCU into a continuous loop, where the time (hours, minutes, and seconds), maintained in the MC68HC68T1 is read, converted into an ASCII representa-
tion, then transmitted through the asynchronous serial port (SCl) to a display device, such as a CRT terminal. No linefeed character is sent, so the time display remains on one line, and appears to simply increment. Power can be removed from the system, and the clock continues to operate on power supplied by the 3.6 volt NiCad battery. When power is reapplied, the displayed time reflects correct operation.

Please refer to Figure 1 for a schematic diagram of this demonstration system. The MCU is operated with an 8 MHz crystal, for an internal bus frequency of 2 MHz . This allows the standard data rate of 9600 baud to be generated. An MC145407 line driver/receiver is used to level shift the asynchronous serial port to RS-232C levels. This device requires only a single 5 volt supply, as on-chip charge pumps generate the $\pm 10$ volt levels required by RS-232C.

The MC68HC68T1 is configured by the host MCU to operate with the line frequency providing the timebase. This is done by serially writing the value \%11110100 to the Clock Control Register in the MC68HC68T1.

| CLOCKCONTROL REGISTER | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | START | LINE | XTAL | XTAL | 50 Hz | CLK | CLK | CLK |
|  | STOP | XTAL | SEL 1 | SEL 0 | 60 Hz | OUT 2 | OUT 1 | OUT 0 |

Bit D7 = 1 enables the clock counter chain
Bit $D 6=1$ selects the line frequency as the timebase Bits D5:D4 $=1: 1$ select the 32.768 kHz crystal option Bit D3 $=1$ selects 60 Hz as the timebase frequency Bits $\mathrm{D} 2: \mathrm{D} 1: \mathrm{DO}=1: 0: 0$ disables the CLK OUT pin
Please note that when the line frequency is selected as the timebase, the MC68HC68T1's power fail detect circuit can not be used, as it is disconnected from the LINE pin. This requires that the POWER SENSE bit (bit D5) in the Interrupt Control Register be set to 0 . This is the default value at reset time, and does not need to be initialized by the user.

The battery connected to the MC68HC68T1 supplies power to the oscillator at all times, including when the 5 volt system power is available. In a system which uses only the crystal as the timebase, this minimizes frequency variation, as the oscillator supply voltage is relatively constant. In this system, however, this is not important because of the line frequency timebase. The important item here is that current always flows from the battery to the MC68HC68T1. During line powered operation, this current must be supplied to the battery (by $\mathrm{R}_{\text {charge }}$ in Figure 1), to prevent its discharge, and to provide a trickle charging current. This requires that only rechargeable batteries be used, such as NiCad types, or one of the new, rechargeable lithium cells.

Since the internal power fail detect circuitry is disabled in the MC68HC68T1, the power supply must provide this information to the system. A Motorola MC34160 Power Supply Supervisory Circuit was chosen for this function. This device provides the voltage regulator function required for the 5 volt power supply. The two
outputs of interest here are the Power Warning and the Reset outputs. The Reset output generates a reset to the MCU when power is applied to the system. The Power Warning output generates an interrupt to the MCU when the unregulated voltage drops below a value considered to be dangerously low, but not yet below the minimum operating voltage of the regulator. Please refer to Figure 2.

An uncommitted voltage comparator is also provided by the MC34160; and is used to convert the 60 Hz sine wave from the power transformer into a logic signal to drive LINE on the MC68HC68T1. Since this comparator provides hysteresis, noise immunity is improved.

When the Power Warning output generates an interrupt to the MCU, the MCU completes the current instruction, or series of instructions in the critical code section, and then enters the interrupt handier code. This code simply reconfigures the MC68HC68T1 to crystal timebase operation by writing the value \%10110100 to the Clock Control Register. Please note that only bit D6 was changed, as compared to the value previously written. The interrupt handler routine would then save whatever other information was required by the application into the MC68HC68T1's internal RAM. In this example, however, nothing needs to by saved, so the MCU just enters the STOP state

The code section that reads the time information from the MC68HC68T1 is considered a critical code section, because it accesses MCU resources which are also accessed from within the interrupt handler. If the interrupt were to be accepted while serial transmissions were in progress, errors would occur, because the interrupt handler would not allow the completion of the transmission, but would simply start its own transmission. This could cause a "Write Collision" in the S.P.I., or erroneous data to be sent to the MC68HC68T1. This is prevented by simply bracketing this critical code with instructions that disable interrupts at the beginning, and enable interrupts at the end.

The value of the power supply filter capacitor (Cfilter in Figure 1) must be chosen so that T save (Figure 2) is long enough to allow the MCU to completely execute the interrupt handler code before the unregulated voltage drops to a point below which the regulator will not operate. The value of $\mathrm{C}_{\text {filter }}$ (Figure 1) provides approximately 150 ms of operation after the interrupt is generated.

The MC34164P Low Voltage Detect Circuit guarantees that the MCU is held in the reset state when the supply voltage drops below the level that allows the MC34160 to function correctly. This prevents possible program run away, which may modify registers in the MC68HC68T1.

The program source code listing is included. This software was written for Motorola's MC68HC11 cross macro assembler.

## REFERENCES

M68HC11 Reference Manual, M68HC11RM/AD Revision 1, Motorola, 1990.

Linear and Interface Integrated Circuits, DL128 Revision 3, Motorola, 1990.

M68HC11EVB Evaluation Board User's Manual, M68HC11EVB/D1, Motorola, 1986.

M6800 Family Macro Assemblers Reference Manual, M68XRASM/D2, Motorola, 1985.
"CX-1V Crystal Data Sheet," Statek Corporation, 12/87.
"MC68HC68T1 Advance Information Data Sheet," MC68HC68T1/D, Motorola, 1988.
"Linear/Switchmode Voltage Regulator Handbook," HB206 Revision 3, Motorola, 1989.

NOTE: After November, 1990 please refer to the updated MC68HC68T1 data sheet in Application-Specific Standard ICs data book, DL130 Revision 1, Motorola, 1990.

This scftware demonstrates the use of the MC68HC68T1 Real Time Clock in a system that normally derives its timebase from the ac line, but during a power failure, switches to a 32.768 kHz crystal.

This software runs on an MC68HC11A8P1 microcomputer. This MCU contains a debug monitor called "BUFFALO".

This software is stored in the MCU's on-chip EEPROM.

| MC68HC68T1 |  |  |
| :--- | :--- | :--- |
| Register | Addresses: |  |
| Seconds | EQU | $\$ 20$ |
| Minutes | EQU | $\$ 21$ |
| Hours | EQU | $\$ 22$ |
| Day | EQU | $\$ 23$ |
| Date | EQU | $\$ 24$ |
| Month | EQU | $\$ 25$ |
| Year | EQU | $\$ 26$ |
| Sec_Alarm | EQU | $\$ 28$ |
| Min_Alarm | EQU | $\$ 29$ |
| Hrs_Alarm | EQU | $\$ 2 A$ |
| Status | EQU | $\$ 30$ |
| First_Up | EQU | $\% 00010000$ |
| Control | EQU | $\$ 31$ |
| Start | EQU | $\% 10000000$ |
| Line | EQU | $\% 01000000$ |
| XTL_SEL1 | EQU | $\% 00100000$ |
| XTL_SELO | EQU | $\% 0001000$ |
| Line_50 | EQU | $\% 00001000$ |
| Interrupt | EQU | $\$ 32$ |
| Write | EQU | $\% 10000000$ |


| MC68HC11A8P1 Equates: |  |  |  |
| :--- | :--- | :--- | :---: |
| REGBASE | EQU | $\$ 1000$ |  |
| IRQ_VEC | EQU | $\$ E E$ |  |
| SPSR | EQU | $\$ 29$ |  |
| SPIF | EQU | $\% 10000000$ |  |
| SPCR | EQU | $\$ 28$ |  |
| SPDR | EQU | $\$ 2 A$ |  |
| BAUD | EQU | $\$ 2 B$ |  |
| SCCR1 | EQU | $\$ 2 C$ |  |
| SCCR2 | EQU | $\$ 2 D$ |  |
| TE | EQU | $\% 00001000$ |  |
| SCSR | EQU | $\$ 2 E$ |  |
| TDRE | EQU | $\% 10000000$ |  |
| SCDR | EQU | $\$ 2 F$ |  |
| PORTD | EQU | $\$ 8$ |  |
| SS | EQU | $\% 00100000$ |  |
| DDRD | EQU | $\$ 9$ |  |

MIsc. Equates:

| CR | EQU | 13 |
| :--- | :--- | :--- |
| JMP | EQU | $\$ 7 E$ |
| TOS | EQU | $\$ 35$ |
|  | BSCT |  |


| Scratch Pad |  |  |
| :---: | :---: | :--- |
| Torage | Locations: |  |
| Time | RMB | 3 |
| String | RMB | 8 |
|  | ORG | \$B600 |
| Reset | EQU | ${ }^{*}$ |
|  | LDS | \#TOS |
|  | LDX | \#REGBASE |

Initialize the SCI Port

| LDAA | $\# \% 00110000$ |
| :--- | :--- |
| STAA | BAUD, X |
| BSET | SCCR2,X,\#TE |

The purpose of this program is to output the time-of-day to a CRT terminal connected to the MCUs SCI (UART) port. When a power failure occurs, the MCU is interrupted with an IRQ, then it switches the real time clock to crystal control. When power is reapplied, the MCU switches the real time clock back to line power timebase.

Seconds Register
Minutes Register
Hours Register
Day of Week Register
Date of Month Register
Month Register
Year Register
Seconds Alarm
Minutes Alarm
Hours Alarm
Status Register
First-Time-Up Status Bit
Clock Control Register
Start = 1 Enables the Divider Chain
Line $=1$ Crystal $=0$
XTL_SEL1:XTL_SELO $=\% 11$ for 32.768 kHz
Clear for 60 Hz Timebase
Interrupt Control Register
Write Enable Bit In Address Word

Base Address of I/O Register Set
Indirect Vector for IRQ (3 Bytes)
SPI Status Register (Offset from "REGBASE")
Transfer Complete Flag
SPI Control Register
SPI Data Register
SCI Baud Rate Control
SCI Control Register \#1
SCI Control Register \#2
Transmitter Enable
SCI Status Register
Transmit Data Register Empty
SCI Data Register
Port D Data Register
Slave Select Output to MC68HC68T1
Port D Data Direction Register

ASCII Carriage Return
"JMP \$HHHH" OPcode
Top of Available RAM (BUFFALO Compatible)

Store Time in B.C.D. Here
Build Time String Here in ASCII
Beginning of EEPROM
Init Stack Pointer to Top of RAM
Point to Base of I/O Registers

9600 Baud $($ Crystal $=8.0 \mathrm{MHz})$
Enable SCl's Transmitter

Initialize the SPI Port

| BSET | DDRD, $\mathrm{X}, \# \%$ 000111000 | Configure SS, SCK, and MOSI into Outputs |
| :--- | :--- | :--- |
| LDAA | $\# \% 01010100$ | Enable, SPI, Bit Rate $=1$ MHZ, $\ldots$ |
| STAA | SPCR, $X$ | $\ldots . C P O L=0, C P H A=1$ |

Initialize the Indirect Vector Table. The MC68HC11A8P1's interrupt vectors are in ROM, and can't be modified. They point to an indirect vector table placed in RAM, so users can set vector addresses at will.

| LDAA | \#JMP |
| :--- | :--- |
| STAA | IRQ_VEC |
| LDD | SIRQ |
| STD | IRQ_VEC+1 |

"JMP \$HHHH" Opcode
Store a "JMP IRQ" in the Table
Address of IRQ Interrupt Handier

The MC68HC68T1 is always reinitialized, because it needs to be set to line timebase. If the first-time-up bit is set in its status register, it must also have its time and date set.

| BSET | PORTD,X,\#SS | Enable the MC68HC68T1 |
| :--- | :--- | :--- |
| LDAA | \#STATUS | Read the Status Register |
| JSR | SQUIRT | Send Address to MC68HC68T1 |
| JSR | SQUIRT | Dummy Access to get Returned Value |
| BCLR | PORTD,X,\#SS | Disable the MC68HC68T1 |
| TAB |  | Save the Status to Check for First-Time-Up |
| BSET | PORTD,X,\#SS | Enable the MC68HC68T1 |
| LDAA | \#CONTROL!+WRITE | Write the Control Register |
| JSR | SQUIRT | Send Address |

The MC68HC68T1 is set up for line timebase, but the crystal oscillator is set for 32.768 kHz operation, so it will properly run.

| LDAA | \#START!+LINE!+XTL_SEL1!+XTL_SELO | Select Line Operation |
| :--- | :--- | :--- |
| JSR | SQUIRT | Control Register Value |
| BCLR | PORTD,X.\#SS | Disable the MC68HC68T1 |

If this was the first time up for the MC68HC68T1, then set the time.

| BITB | \#FIRST_UP | Check First-Time-Up Bit |
| :--- | :--- | :--- |
| BEQ | SKIP_SET | Do Not Set the Time in the MC68HC68T1, if Clear |
| BSR | SET_CLCK | Set the Clock's Time Here |

Enable the stop instruction.

| Skip_Set | TPA ANDA TAP | \#\%01111111 | Get Condition Code Register Value Clear the Stop Mask |
| :---: | :---: | :---: | :---: |
| Main | EQU |  |  |
|  | SEI |  | Enter Critical Code Section |
|  | BSET | PORTD, X,\#SS | Enable the MC68HC68T1 |
|  | LDAA | \#SECONDS | Read the Seconds Register First |
|  | JSR | SQUIRT |  |
|  | JSR | SQUIRT | Dummy Character to Shift in Seconds |
|  | STAA | TIME+2 | Save Seconds |
|  | JSR | SQUIRT | Read the Minutes Register |
|  | STAA | TIME+1 | Save Minutes |
|  | BSR | SQUIRT | Read the Hours Register |
|  | STAA | TIME | Save Hours |
|  | BCLR | PORTD,X,\#SS | Disable the MC68HC68T1 |
|  | CLI |  | End of Critical Code Section |

Convert B.C.D. time to ASCII.

| LDAA | TIME | Get Hours |
| :--- | :--- | :--- |
| BSR | BCD_ASCI | Convert to ASCII |
| STD | STRING | Build String |
| LDAA | TIME+1 | Get Minutes |
| BSR | BCD_ASCI | Convert to ASCII |
| STD | STRING +3 | Save Room for Colon |
| LDAA | TIME +2 | Get Seconds |
| BSR | BCD_ASCI | Convert to ASCII |
| STD | STRING +6 | Save Room for Colon |
| LDAA | \#': | Now Store the Colons |
| STAA | STRING+2 |  |
| STAA | STRING +5 |  |

Now send the time strong to the SCI port.

| SEND_CHR | LDAB | \#8 | 8 Bytes to Send |
| :---: | :---: | :---: | :---: |
|  | LDY | \#STRING | Point to the String |
|  | LDAA | O,Y | Get the Character |
|  | BSR | OUTCH | Output the Character |
|  | INY |  | Bump the Pointer |
|  | DECB |  | Decrement Loop Counter |
|  | BNE | SEND_CHR | Continue Until Loop Counter Exhausted |
|  | LDAA | \#CR | Now Send a Carriage Return |
|  | BSR | OUTCH |  |
|  | BRA | MAIN | Continue in Main Loop |

A power failure causes an IRQ to be generated by the MC34160 power supply chip. Enter here for power failure.

| EQU | * | Interrupt Handler |
| :--- | :--- | :--- |
| LDX | \#REGBASE | Point to I/O Space |
| BSET | PORTD,X,\#SS | Enable the MC68HC68T1 |
| LDAA | \#CONTROL!+WRITE | Write the Control Register |
| BSR | SQUIRT |  |
|  |  |  |
|  | Select Crystal Operation |  |
| BSR | \#START!+XTL_SEL1!+XTL__SELO |  |
|  | SQUIRT | Disable the MC68HC68T1 |
| BCLR | PORTD,X,\#SS |  |
|  |  |  |

Utility Subroutines:
This subroutine converts the packed BCD number in A into to ASCII numbers in Register D .

| BCD_ASCI | EQU * |  |
| :--- | :--- | :--- |
|  | PSHA | Save Argument |
|  | ANDA | \#\%00001111 |
| ORAA | M'O | Convert to ASCII |
| TAB | Place in Low Half of Reg D |  |
| PULA | Restore Argument |  |
| LSRA | Align M.S.D. |  |
| LSRA |  |  |
| LSRA |  |  |
| LSRA |  |  |
| ORAA |  |  |
| RTS |  | Convert to ASCII |
|  |  | Return with 2 ASCII Chars in Reg D |

This is only a dummy time setting routine. The clock is set to 00:00:00 January 1, 1990, Friday (24 hour time). A real application would substitute an actual time setting routine here.

| SET_CLCK | EQU | * |  |
| :---: | :---: | :---: | :---: |
|  | BSET | PORTD, X,\#SS | Enable the MC68HC68T1 |
|  | LDAA | \#SECONDS!+WRITE | Write to the Seconds Register First |
|  | BSR | SQUIRT |  |
|  | CLRA |  | Seconds $=0$ |
|  | BSR | SQUIRT |  |
|  | CLRA |  | Minutes $=0$ |
|  | BSR | SQUIRT |  |
|  | CLRA |  | Hours $=0$ |
|  | BSR | SQUIRT |  |
|  | LDAA | \#6 | Day $=$ Friday |
|  | BSR | SQUIRT |  |
|  | LDAA | \#1 | Date $=1$ |
|  | BSR | SQUIRT |  |
|  | LDAA | \#1 | Month = January |
|  | BSR | SQUIRT |  |
|  | LDAA | \#\$90 | Year $=1990$ |
|  | BSR | SQUIRT |  |
|  | LDAA | PORTD,X,\#SS | Disable the MC68HC68T1 |
|  | RTS |  | Return to Caller |

Output the contents of Register A to the SPI Port. Return with A containing the character received from the MC68HC68T1. No other registers modified upon return. The slave select must be handled by the calling program.

| SQUIRT | EQU |  |  |
| :--- | :--- | :--- | :--- |
|  | PSHX |  | Save Working Register |
|  | LDX | \#REGBASE | Point to I/O Registers |
| WAITSPIF | STAA | SPDR,X | Send Byte |
|  | LDAA | SPDR,X,\#SPIF,WAITSPIF | SPDR,X |
|  | PULX |  | Loop Until Transmission Complete |
|  | RTS |  | Read Returned Data to Clear SPIF |
|  |  | Restore Working Register |  |
|  |  | Return to Calling Program |  |

This subroutine transmits the contents of Register A to the SCI Port. All registers preserved upon return.
OUTCH EQU

| PSHX |  | Save Working Register |
| :--- | :--- | :--- |
| LDX | \#REGBASE | Point to I/O Space |
| BRCLR | SCSR,X,\#TDRE,WAITTDRE | Wait for Empty Transmit Buffer |
| STAA | SCDR,X | Transmit Character |
| PULX |  | Restore Working Register |
| RTS |  | Return to Calling Program |

END


Figure 1. Schematic Diagram


Figure 2. Power Fail Timing

## AN1066

## Interfacing the MC68HC05C5 SIOP to an $I^{2} C$ Peripheral

By Naji Naufel

## INTRODUCTION

When designing a system based on a standard, non-custom-designed, microcontroller unit (MCU), the user is faced with the problem of not having all the desired peripheral functions on-chip. This problem can be solved by interfacing the MCU to an off-chip set of peripherals. An ideal interface is a synchronous serial communication port. Unfortunately, these peripherals may not have a serial interface that is compatible with the Motorola simple synchronous serial I/O port (SIOP).

This document demonstrates how the SIOP on the MC68HC05C5 can be interfaced to an $1^{2} \mathrm{C}$ peripheral, the PCF8573 clock/timer. The MC68HC05C5 was chosen because its SIOP has a programmable clock polarity.

The serial peripheral interface (SPI) on the MC68HC05C4 cannot be used in the interface because the SPI pins cannot be used as output pins when the SPI is off.

## SIOP DEFINITION

The SIOP (see Figure 1) is a three-wire master/slave system including serial clock (SCK), serial data input (SDI), and serial data output (SDO). A programmable option determines whether the SIOP handles data most significant bit (MSB) or least significant bit (LSB) first.


Figure 1. SIOP Block Diagram

## SIOP SIGNAL FORMAT

The SCK, SDO, and SDI signals are discussed in the following paragraphs.

## SCK

The state of SCK between transmissions can be either a logic one or a logic zero. The first falling edge of SCK signals the beginning of a transmission. At this time, the first bit of received data is presented to the SDI pin, and the first bit of transmitted data is presented at the SDO pin (see Figure 2). When CPOL $=0$, the first falling edge occurs internal to the SIOP. Data is captured at the SDI pin on the rising edge of SCK. Subsequent falling edges shift the data and accept or present the next bit. When CPOL =1, transmission ends at the eighth rising edge of SCK. When CPOL $=0$, transmission ends at the eighth falling edge of SCK.

Format is the same for master mode and slave mode except that SCK is an internally generated output in master mode and an input in slave mode. The master mode transmission frequency is fixed at E/4.


Figure 2. SIOP Timing

## SDO

The SDO pin becomes an output when the SIOP is enabled. The state of SDO always reflects the value of the first bit received on the previous transmission, if a transmission occurred. Prior to enabling the SIOP, PB5 can be initialized to determine the beginning state, if necessary. While the SIOP is enabled, PB5 cannot be used as a standard output since that pin is coupled to the last stage of the serial shift register. On the first falling edge of SCK, the first data bit to be shifted out is presented to the output pin.

## SDI

The SDI pin becomes an input when the SIOP is enabled. New data may be presented to the SDI pin on the falling edge of SCK. Valid data must be present at least 100 ns before the rising edge of the clock and remain valid 100 ns after that edge.

## SIOP REGISTERS

The SIOP contains the following registers: SCR, SSR, and SDR.

## SIOP Control Register (SCR)

This register, located at address $\$ 000 \mathrm{~A}$, contains three bits (see Figure 3).


Figure 3. SIOP Control Register

## SPE - Serial Peripheral Enable

When set, this bit enables the SIOP and initializes the port B data direction register (DDR) such that PB5 (SDO) is output, PB6 (SDI) is input, and PB7 (SCK) is an input in slave mode and an output in master mode. The port B DDR can be subsequently altered as the application requires, and the port B data register (except for PB5) can be manipulated as usual; however, these actions could affect the transmitted or received data. When SPE is cleared, port B reverts to standard parallel I/O without affecting the port B data register or DDR. SPE is readable and writable any time, but clearing SPE while a transmission is in progress will abort the transmission, reset the bit counter, and return port B to its normal I/O function. Reset clears this bit.

MSTR - Master Mode
When set, this bit configures the SIOP for master mode, which means that the transmission is initiated by a write to the data register and SCK becomes an output, providing a synchronous data clock at a fixed rate of the bus clock divided by 4 . While the device is in master mode, SDO and SDI do not change function; these pins behave exactly as they would in slave mode. Reset clears this bit and configures the SIOP for slave operation. MSTR may be set at any time regardless of the state of SPE. Clearing MSTR will abort any transmission in progress.
CPOL - Clock Polarity
When CPOL is set, SCK idles high, and the first data bit is seen after the first falling edge. When CPOL is cleared, the SCK idles low, and the first data bit is seen after the first falling edge, which occurs internally (see Figure 2).

## SIOP Status Register (SSR)

Located at address \$000B, the SSR contains only two bits (see Figure 4).

|  | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| ---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SOB | SPIF <br> RESET: | DCOL | 0 | 0 | 0 | 0 | 0 | 0 |

Figure 4. SIOP Status Register

SPIF - Serial Peripheral Interface Flag
This bit is set on the last rising clock edge, indicating that a data transfer has occurred. SPIF has no effect on further transmissions and can be ignored without problem. SPIE is cleared by reading the SSR with SPIF set, followed by a read or write of the SDR. If it is cleared before the last edge of the next byte, it will be set again. Reset also clears this bit.
DCOL - Data Collision
DCOL is a read-only status bit that indicates an invalid access to the data register has been made. A read or write of SDR during a transmission results in invalid data being transmitted or received. DCOL is cleared by reading the SSR with SPIF set, followed by a read or write of the SDR. If the last part of the clearing sequence is done after another transmission has been started, DCOL will be set again. If DCOL is set and SPIF is not set, clearing DCOL requires turning the SIOP off, then turning it back on using the SPE bit in the SCR. Reset also clears this bit.

## SIOP Data Register (SDR)

Located at address $\$ 000 \mathrm{C}$, SDR is both the transmit and receive data register (see Figure 5). This system is not double buffered; thus, any write to this register destroys the previous contents. The SDR can be read at any time, but if a transmission is in progress, the results may be ambiguous. Writes to the SDR while a transmission is in progress can cause invalid data to be transmitted and/or received. This register can be read and written only when the SIOP is enabled ( $\mathrm{SPE}=1$ ).


Figure 5. SIOP Data Register

## $1^{2} \mathrm{C}$ definition

The inter IC $\left(I^{2} \mathrm{C}\right)$ is a two-wire half-duplex serial interface with data transmitted/received MSB first. The two wires are a serial data line (SDA) and a serial clock line (SCL).
The protocol consists of a start condition, slave address, $n$ bytes of data, and a stop condition (see Figure 6). Each byte is followed by an acknowledge bit. A start condition is defined as a high-to-low transition on SDA while SCL is high; a stop condition is defined as a low-to-high transition on SDA while SCL is high (see Figure 9). An acknowledge is a low logic level sent by the addressed receiving device during the ninth clock period. A master receiver signals the end of data by not generating an acknowledge after the last byte has left the slave device.


Figure 6. PCF8573 Serial Data Format

## INTERFACING THE SIOP TO THE PCF8573

The PCF8573 has an address of 11010 A1 A0, where A1 and A0 give the device a one-of-four address assigned by two hardware pins. Bit 0 of the address byte is the read/write indicator (see Figure 7).

| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 1 | 1 | 0 | 1 | 0 | A 1 | AO | $\mathrm{R} \bar{W}$ |
| MSB |  |  |  |  |  |  |  |

Figure 7. Address Byte

The byte following the address byte is the mode pointer used to control register access inside the PCF8573. Subsequent bytes following the mode pointer contain data read from or written to the clock/timer. Clock data is in binary-coded decimal format with two digits per byte.

## HARDWARE DESCRIPTION

The SIOP is used as master by setting the MSTR bit in the SPCR. PB7/SCK is connected to SCL. Since the PCF 8573 has a bidirectional data line (SDA) and the SIOP has separate input and output pins, the SDO and the SDI pins need to be connected. A resistor must be used for this connection because port B is not open-drain (see Figure 8). The SEC pin, which goes high every second, is connected to PA7, which is polled by software to keep a seconds count.

When receiving data from the clock timer, an \$FF is transmitted by the SIOP, which makes the resistor (R3), in series with the SDO pin, look like a pullup to $V_{D D}$; therefore, SDO will not interfere with data coming from the SDA pin.


Figure 8. MC68HC05C5 Connection to PCF8573

## SOFTWARE DESCRIPTION

To generate the timing required by the $I^{2} \mathrm{C}$, the user has to manipulate the port B pins as I/O and SIOP pins (see Figure 9). Before any data transactions, PB5 and PB7 are initialized high. While the SIOP is off (SPE = 0), PB5 is cleared to zero while PB7 is still high, creating a start condition. The SIOP is then enabled with CPOL $=0$ and MSTR $=1$ and a byte is transmitted. After transmission is complete, the SIOP is turned off ( $\mathrm{SPE}=0$ ), and PB7 is toggled high, then low, to generate the acknowledge clock. If the MCU is sending data, PB5 is forced high during the acknowledge pulse; otherwise, it is forced low to let the slave know that the byte has been received. If needed, the stop condition is accomplished by clearing PB5, setting PB7, then setting PB5.

To satisfy the $100-\mathrm{kHz}$ serial clock maximum rating of the PCF8573, the MC68HC05C5 must be slowed to run at a bus speed of 250 kHz , which gives a serial clock rate of 62.5 kHz .


Figure 9. SIOP-Generated Timing

## SOFTWARE APPLICATION

In demonstrating how the SIOP is interfaced to an $1^{2} \mathrm{C}$ peripheral, the author developed a complex application having time and calendar functions.

This application interfaces serially with a terminal to allow the user to initialize the PCF8573 with the time and date (see Figure 8). After the software prompts the user to enter the date (month, day, hour, and minutes), it starts displaying the information every second (see Figure 10). Every second the SEC pin goes high, telling the software to read the PCF8573 data and display it along with the software-kept seconds.

To initialize clock data, use the following sequence:
Send \$D0 with start bit (ADDRESS)
Send $\$ 00$ without start bit (CONTROL)
Send hours data without start bit
Send minutes data without start bit
Send day data without start bit
Send month data without start bit
Generate stop bit
To read clock data, use the following sequence:
Send \$D0 with start bit (ADDRESS)
Send $\$ 00$ without start bit (CONTROL)
Set up for low acknowledge bit transmit
Send \$D1 with start bit (ADDRESS)
Send \$FF without start bit to receive hours
Send \$FF without start bit to receive minutes
Send \$FF without start bit to receive day
Send \$FF without start bit to receive month
Generate stop bit
Since the MC68HC05C5 does not have a universal asynchronous receiver transmitter (UART), the interface to the terminal was implemented in software. See subroutines INCHAR and OUTCHAR in APPENDIX A PROGRAM LISTING.


Figure 10. Program Flowchart

## APPENDIX A. PROGRAM LISTING

| 0001 | $* * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * * ~$ |
| :--- | :--- | :--- |


| iicc5 |  | page 2 |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 0050 |  |  |  |  |  |
| 0051 |  |  |  |  |  |
| 0052 **************************************************************** |  |  |  |  |  |
| 0053 * start of program |  |  |  |  |  |
| $0054$ |  |  |  |  |  |
| 0055 | 0200 |  | org | \$0200 |  |
| 0056 |  | * all ti | ing is | ased on a 50 | Khz crystal |
| 0057 * |  |  |  |  |  |
| 0058 |  |  |  |  |  |
| 0059 | 0200 | begin | equ | * |  |
| 0060 | 0200 a6 02 |  | lda | \#\%00000010 |  |
| 0061 | 0202 b7 00 |  | sta | porta | ; TX pin high |
| 0062 | 0204 b7 04 |  | sta | ddra | ; PA1=TX pin, PAO=RX pin |
| 0063 | 0206 a6 a0 |  | 1da | \#\%10100000 | ;pb7=pb5=output, pb6=input |
| 0064 | 0208 b7 01 |  | sta | portb |  |
| 0065 | 020a b7 05 |  | sta | ddrb |  |
| 0066 | 020c ae 03 |  | $1 d x$ | \#3 |  |
| 0067 | 020e d6 0407 |  | lda | delays, $x$ |  |
| 0068 | 0211 b7 8e |  | sta | cdelay | ; 2400 baud |
| 0069 | 0213 a6 10 |  | lda | \#\%00010000 | ;mstr=1, cpol=0, siop still off |
| 0070 | 0215 b7 0a |  | sta | sper |  |
| 0071 | 0217 b7 82 |  | sta | ack | ; ack flag non-zero, high acknowledge |
| 0072 le |  |  |  |  |  |
| 0073 | 0219 cd 0385 |  | jsx | crlf |  |
| 0074 | 021c cd 0376 |  | jsr | outmsg | ; print "ENTER MM/DD HH:MM" |
| 0075 | $021 f$ cd 0285 |  | jsr | getdate | ; get month |
| 0076 | 0222 b7 85 |  | sta | month |  |
| 0077 | 0224 cd 0390 |  | jsx | inchar | ; dummy char '/' |
| 0078 | 0227 cd 0285 |  | jsr | getdate | ; get day |
| 0079 | 022a b7 86 |  | sta | day |  |
| 0080 | 022c cd 0390 |  | jsx | inchar | ; dummy space |
| 0081 | 022 fcd 0285 |  | jsr | getdate | ; get hours |
| 0082 | 0232 b7 83 |  | sta | hour |  |
| 0083 | 0234 cd 0390 |  | jsr | inchar | ; dumment ':' |
| 0084 | 0237 cd 0285 |  | jsr | getdate | ; get minutes |
| 0085 | 023a b7 84 |  | sta | min |  |
| 0086 | 023c cd 0390 | again | jsr | inchar | ; wait for <CR> |
| 0087 | 023f al Od |  | cmp | \#\$0d |  |
| 0088 | $024126 \mathrm{f9}$ |  | bne | again |  |
| 0089 | 0243 cd 0385 |  | jsr | crlf |  |
| 0090 |  | * |  |  |  |
| 0091 |  | * issue | reset | rescaler com | and |
| 0092 * 0 |  |  |  |  |  |
| 0093 | 0246 a6 20 |  | 1da | \#\$20 |  |
| 0094 | 0248 b7 81 |  | sta | control |  |
| 0095 | 024a cd 02 d 2 |  | jsr | addrentl |  |
| 0096 | 024d cd 02 cb |  | jsr | stop |  |
| 0097 |  |  |  |  |  |
| 0098 * initialize the clock |  |  |  |  |  |
| 0099 |  |  |  |  |  |
| 0100 | 0250 a6 00 |  | Ida | \#\$00 |  |
| 0101 | 0252 b7 81 |  | sta | control |  |
| 0102 | 0254 cd 02 d 2 |  | jsr | addrentl | ; send address/control bytes |
| 0103 | 0257 cd 02 db |  | jsr | senddta | ; send 4 data bytes |
| 0104 |  | * |  |  |  |
| 0105 |  | * issue | reset | rescaler com | and |
| 0106 * 010 |  |  |  |  |  |
| 0107 | 025a a6 20 |  | 1 da | \#\$20 |  |
| 0108 | 025c b7 81 |  | sta | control |  |
| 0109 | 025e cd 02 d 2 |  | jsr | addrentl |  |
| 0110 | 0261 cd 02 cb |  | jsr | stop |  |
| 0111 l 011 er |  |  |  |  |  |
| 0112 | $02643 f 80$ |  | clr | sec | ; clear seconds counter |
| 0113 | 0266 Of 00 fd | sec_pin | brclr | 7,porta,* | ; wait for SEC pin to go high |
| 0114 | 0269 cd 0331 |  | jsr | dispdata | ; display clock data |
| 0115 | 026c 0e 00 fd |  | brset | 7,porta,* | ; wait until pin goes low |
| 0116 | $026 \pm 20$ f5 |  | bra | sec_pin |  |
| 0117 |  | * |  |  |  |
| 0118 | $0271454 e 5445$ | msg | fcc | "ENTER MM/D | HH: MM" |
|  | $52204 d$ 4d |  |  |  |  |
|  | $2 \mathrm{f44420}$ |  |  |  |  |
|  | 4848 3a 4d |  |  |  |  |
|  | 4d |  |  |  |  |
| 0119 | 0282 Od Oa 04 |  | fcb | \$0d, \$0a, \$04 |  |



| iicc5 |  |  |  | page 4 |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 0162 Page |  |  |  |  |  |
| 0163 ******************************************************************** |  |  |  |  |  |
| 0164 |  |  |  |  |  |
| 0165 * this subroutine transfers a byte from the he05's spi to the iic |  |  |  |  |  |
| 0166 * peripheral. data is in reg $x$ upon en |  |  |  |  |  |
| 0167 * w_start is the entry point for sending a start |  |  |  |  |  |
| 0168 * start is the entry point for transfering data without a start condition. |  |  |  |  |  |
| 0169 |  |  |  |  |  |
| 0170 |  | ******** | ***** | ************ | ************************************* |
| 0171 |  |  |  |  |  |
| 0172 | 02ad | w_start | equ | * |  |
| 0173 | 02ad le 01 |  | bset | 7, portb | ; take SCL line high |
| 0174 | 02af lb 01 |  | bclr | 5, portb | ; start condition |
| 0175 | 02b1 | nostart | equ | , |  |
| 0176 | 02b1 1c 0a |  | bset | 6, sper | ; enable spi, SPE=1 |
| 0177 | 02b3 bf Oc |  | stx | spdr | ; send data |
| 0178 | 02b5 Of Ob fd | wait | brcle | 7, spsx, wait | ; wait for and of transmition |
| 0179 * |  |  |  |  |  |
| 0180 | 02b8 1d 0a |  | bclr | 6, sper | ; clear SPE, disable spi |
| 0181 |  |  |  |  |  |
| 0182 | 02ba 3d 82 |  | tst | ack | ; test acknowledge flag |
| 0183 | 02bc 2604 |  | bne | hi_ack | ; keep ack high |
| 0184 | 02be 1b 01 | 10_ack | belr | 5, portb | ;else, clear ack bit |
| 0185 | 02c0 2002 |  | bra | hi_ackl | ; generate ack clock |
| 0186 * - |  |  |  |  |  |
| 0187 | 02c2 la 01 | hi_ack | bset | 5, portb | ; send high ACK bit |
| 0188 | 02 ct 1e 01 | hi_ackl | bset | 7, portb | ;take pb7 (SCL) high |
| 0189 | 02c6 1f 01 |  | belr | 7, portb |  |
| 0190 | 02c8 la 01 |  | bset | 5, portb | ; return data pin high |
| 0191 | 02ca 81 |  | rts |  |  |


| iice5 |  | page 5 |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $0193$ |  |  |  |  |  |
| 0194 |  |  |  |  |  |
| 0195 |  |  |  |  |  |
| 0196 |  |  |  |  |  |
| 0197 |  |  |  |  |  |
| 0198 |  | * the following routine (stop) creates a stop condition |  |  |  |
| 0199 |  |  |  |  |  |
| 0200 |  | ******************************************************************* |  |  |  |
| 0201 |  | * |  |  |  |
| 0202 | 02cb | stop | equ | * |  |
| 0203 | 02cb 1b 01 |  | bclr | 5, portb | ;bring sda low |
| 0204 | 02cd 1e 01 |  | bset | 7, portb | ;bring scl high |
| 0205 | 02cf 1a 01 |  | bset | 5, portb | ;bring sda high |
| 0206 | 02d1 81 |  | rts |  |  |
| 0207 |  |  |  |  |  |
| 0208 |  |  |  |  |  |
| 0209 |  |  |  |  |  |
| 0210 |  |  |  |  |  |
| 0211 |  |  |  |  |  |
| 0212 |  |  |  |  |  |
| 0213 |  |  |  |  |  |
| 0214 |  | * the following routine sends 2 bytes. an address byte followed |  |  |  |
| 0215 |  | * by a control byte in control. |  |  |  |
| 0216 |  |  |  |  |  |
| 0217 |  |  |  |  |  |
| 0218 |  | * |  |  |  |
| 0219 | 02d2 | addrentl | equ | * |  |
| 0220 | 02d2 ae do |  | $1 d x$ | \#waddr | ; ( $x / w=0$ ) |
| 0221 | 02d4 ad d7 |  | bsx | w_start | ; send address with start condition |
| 0222 | 02d6 be 81 |  | $1 d x$ | control |  |
| 0223 | 02d8 ad d7 |  | bst | nostart | ; send control byte without start |
| 0224 | 02da 81 |  | rts |  |  |
| 0225 |  |  |  |  |  |
| 0226 |  |  |  |  |  |
| 0227 |  |  |  |  |  |
| 0228 |  |  |  |  |  |
| 0229 |  | * |  |  |  |
| 0230 |  | * the following routine sends 4 bytes. |  |  |  |
| 0231 |  |  |  |  |  |
| 0232 |  | *************************************************************** |  |  |  |
| 0233 |  | * |  |  |  |
| 0234 | 02db | senddta | equ | * |  |
| 0235 | 02db be 83 |  | 1 dx | hour |  |
| 0236 | 02dd ad d2 |  | bsx | nostart | ; send hours |
| 0237 | 02df be 84 |  | $1 d x$ | min |  |
| 0238 | 02 el ad ce |  | bsr | nostart | ; send minutes |
| 0239 | $02 e 3$ be 86 |  | 1 dx | day |  |
| 0240 | 02 e 5 ad ca |  | bsr | nostart | ; send days |
| 0241 | 02 e 7 be 85 |  | $1 d x$ | month |  |
| 0242 | 02e9 ad c6 |  | bst | nostart | ; send months |
| 0243 | 02eb ad de |  | bst | stop | ; stop condition |
| 0244 | 02ed 81 |  | rts |  |  |



| iice5 |  |  |  |  | page |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0294 |  |  |  |  |  |  |
| 0295 ******************************************************************* |  |  |  |  |  |  |
| 0296 * This service routine increments the seconds counter |  |  |  |  |  |  |
| 0297 * and displays the clock data on the screen every second. |  |  |  |  |  |  |
| 0298 ****************************************************************** |  |  |  |  |  |  |
| 0299 |  |  |  |  |  |  |
| 0300 | 0331 |  | dispdata | equ | * |  |
| 0301 | 0331 a6 | 0d |  | 1da | \#\$0d |  |
| 0302 | 0333 cd | 03 ca |  | jex | outchar | ; send <CR> |
| 0303 | 0336 cd | 02 f9 |  | jsx | read | ; read 4 bytes from clock |
| 0304 |  |  |  |  |  |  |
| 0305 | 0339 b6 | 85 |  | 1da | month | ; display month |
| 0306 | 033b a4 | $1 f$ |  | and | \#\$1f |  |
| 0307 | 033d ad | af |  | bst | bcd | ; output 2 BCD digit |
| 0308 | 033f a6 | $2 f$ |  | 1da | \#'/ |  |
| 0309 | 0341 cd | 03 ca |  | jsr | outchar | ; outout '/' |
| 0310 |  |  |  |  |  |  |
| 0311 | 0344 b6 | 86 |  | 1da | day | ; display day |
| 0312 | 0346 a4 | $3 f$ |  | and | \#\$3f |  |
| 0313 | 0348 ad | a 4 |  | bst | bcd |  |
| 0314 | 034a a6 | 20 |  | 1da | \#\$20 |  |
| 0315 | 034c cd | 03 ca |  | jsr | outchar | ;output space |
| 0316 |  |  |  |  |  |  |
| 0317 | $034 f$ b6 | 83 |  | 1da | hour | ; display hours |
| 0318 | 0351 a4 | 3 f |  | and | \#\$3f |  |
| 0319 | 0353 ad | 99 |  | bsr | bcd |  |
| 0320 | 0355 a6 | 3a |  | 1da | \#' : |  |
| 0321 | 0357 cd | 03 ca |  | jsr | outchar | ; output ':' |
| 0322 |  |  |  |  |  |  |
| 0323 | 035a b6 | 84 |  | 1da | min | ; display minutes |
| 0324 | 035c a4 | 7 f |  | and | \#\$7f |  |
| 0325 | 035e cd | 02 ee |  | jsr | bcd |  |
| 0326 | 0361 a6 | 3 a |  | 1 da | \#': |  |
| 0327 | 0363 cd | 03 ca |  | jsr | outchar | ;output ':' |
| 0328 |  |  |  |  |  |  |
| 0329 | 0366 b6 | 80 |  | 1da | sec | ; display seconds |
| 0330 | 0368 cd | 0298 |  | jsr | bin_dec | ; convert seconds to BCD and display |
| 0331 - jor |  |  |  |  |  |  |
| 0332 | 036b b6 | 80 |  | 1da | sec | ; read seconds byte |
| 0333 | 036d 4c |  |  | inca |  | ;increment it |
| 0334 | 036e al | 3 c |  | cmp | \#60 |  |
| 0335 | 037026 | 01 |  | bne | not_sixty | ; not 60 yet |
| 0336 | 0372 4f |  |  | clra |  |  |
| 0337 | 0373 b7 | 80 | not_sixty | sta | sec | ; update seconds counter |
| 0338 | 037581 |  |  | rts |  |  |




| iicc50476 |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  |  |  |
| 0477 |  | ************************************************************ |  |  |  |
| 0478 |  | * Output the left nibble of Acc $\boldsymbol{A}$ as ASCII character. <br> *********************************************************** |  |  |  |
| $0479$ |  |  |  |  |  |
| 0480 |  |  |  |  |  |
| 0481 | 040b | outlhf | equ | * |  |
| 0482 | 040b 44 |  | lsra |  |  |
| 0483 | 040c 44 |  | lsra |  |  |
| 0484 | 040d 44 |  | lsra |  |  |
| 0485 | 040. 44 |  | lsra |  |  |
| 0486 | 040f at of | outrhf | and | \# ${ }^{\text {Of }}$ |  |
| 0487 | 0411 ab 30 |  | add | *\$30 outchar |  |
| 0488 | 0413 cd 03 ca |  | jar |  | ; send character to terminal |
| 0489 | 041681 |  | rts |  |  |
| 0490 ( |  |  |  |  |  |
| 0491 |  |  |  |  |  |
| 0492 |  | ************************************************************** |  |  |  |
| $0493$ |  |  |  |  |  |
| $0494$ |  |  |  |  |  |
| 0495 | 1 ffa |  | org | \$1ffa |  |
| 0496 | 1ffa 0200 | ixqv | fdb | begin |  |
| 0497 | 1ffc 0200 | swiv | fdb | begin |  |
| 0498 | 1ffe 0200 | resetv | fdb | begin |  |


| iicc5 |  |  |  |  |  |  | page 11 |  | 11 |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| InChar | 008b | *0045 | 0394 | 0405 | 0408 |  |  |  |  |  |  |
| OutChar | 008c | *0046 | 0417 | 0428 |  |  |  |  |  |  |  |
| ack | 0082 | *0036 | 0071 | 0182 | 0269 | 0273 | 0286 |  |  |  |  |
| addrentl | 02d2 | *0219 | 0095 | 0102 | 0109 | 0270 |  |  |  |  |  |
| again | 023c | *0086 | 0088 |  |  |  |  |  |  |  |  |
| atemp | 008d | *0047 | 0418 | 0448 |  |  |  |  |  |  |  |
| bcd | 02ee | *0251 | 0159 | 0307 | 0313 | 0319 | 0325 |  |  |  |  |
| begin | 0200 | *0059 | 0496 | 0497 | 0498 |  |  |  |  |  |  |
| bin_dec | 0298 | *0146 | 0330 |  |  |  |  |  |  |  |  |
| cdelay | 008e | *0048 | 0068 |  |  |  |  |  |  |  |  |
| control | 0081 | *0035 | 0094 | 0101 | 0108 | 0222 | 0267 |  |  |  |  |
| count | 008a | *0044 | 0379 | 0395 | 0397 | 0420 | 0438 |  |  |  |  |
| crlf | 0385 | *0358 | 0073 | 0089 |  |  |  |  |  |  |  |
| day | 0086 | *0040 | 0079 | 0239 | 0285 | 0311 |  |  |  |  |  |
| ddra | 0004 | *0021 | 0062 |  |  |  |  |  |  |  |  |
| ddrb | 0005 | *0022 | 0065 |  |  |  |  |  |  |  |  |
| ddrc | 0006 | *0023 |  |  |  |  |  |  |  |  |  |
| delay | 0402 | *0459 | 0384 | 0389 | 0391 | 0402 | 0404 | 0435 | 0437 | 0444 | 0446 |
|  |  |  | 0461 |  |  |  |  |  |  |  |  |
| delays | 0407 | *0471 | 0067 |  |  |  |  |  |  |  |  |
| dispdata | 0331 | *0300 | 0114 |  |  |  |  |  |  |  |  |
| finish | 0384 | *0354 | 0350 |  |  |  |  |  |  |  |  |
| getc4 | 0396 | *0380 | 0385 |  |  |  |  |  |  |  |  |
| getc6 | 03ad | *0394 | 0392 |  |  |  |  |  |  |  |  |
| getc 7 | 03a2 | *0388 | 0398 |  |  |  |  |  |  |  |  |
| getdate | 0285 | *0128 | 0075 | 0078 | 0081 | 0084 |  |  |  |  |  |
| hi_ack | 02c2 | *0187 | 0183 |  |  |  |  |  |  |  |  |
| hi_ackl | $02 \mathrm{c4}$ | *0188 | 0185 |  |  |  |  |  |  |  |  |
| hour | 0083 | *0037 | 0082 | 0235 | 0277 | 0317 |  |  |  |  |  |
| inchar | 0390 | *0376 | 0077 | 0080 | 0083 | 0086 | 0129 | 0136 |  |  |  |
| irqu | 1 ffa | *0496 |  |  |  |  |  |  |  |  |  |
| lo_ack | 02be | *0184 |  |  |  |  |  |  |  |  |  |
| min | 0084 | *0038 | 0085 | 0237 | 0281 | 0323 |  |  |  |  |  |
| month | 0085 | *0039 | 0076 | 0241 | 0291 | 0305 |  |  |  |  |  |
| msg | 0271 | *0118 | 0348 |  |  |  |  |  |  |  |  |
| no_tens | 02a0 | *0152 | 0149 |  |  |  |  |  |  |  |  |
| nostart | 02b1 | *0175 | 0223 | 0236 | 0238 | 0240 | 0242 | 0275 | 0279 | 0283 | 0288 |
| not_sixty | 0373 | *0337 | 0335 |  |  |  |  |  |  |  |  |
| outchar | 03ca | *0414 | 0302 | 0309 | 0315 | 0321 | 0327 | 0351 | 0360 | 0362 | 0488 |
| outlhf | 040b | *0481 | 0253 |  |  |  |  |  |  |  |  |
| outmsg | 0376 | *0346 | 0074 |  |  |  |  |  |  |  |  |
| outrhf | 0405 | *0486 | 0255 |  |  |  |  |  |  |  |  |
| porta | 0000 | *0018 | 0061 | 0113 | 0115 | 0382 | 0385 | 0392 | 0430 | 0432 | 0440 |
| portb | 0001 | *0019 | 0064 | 0173 | 0174 | 0184 | 0187 | 0188 | 0189 | 0190 | 0203 |
|  |  |  | 0204 | 0205 |  |  |  |  |  |  |  |
| portc | 0002 | *0020 |  |  |  |  |  |  |  |  |  |
| prtmsg | 0377 | *0348 | 0353 |  |  |  |  |  |  |  |  |
| putcl | 03cc | *0416 | 0407 |  |  |  |  |  |  |  |  |
| putc2 | 03 db | *0429 | 0424 |  |  |  |  |  |  |  |  |
| putc3 | 03 el | *0432 | 0429 |  |  |  |  |  |  |  |  |
| putc4 | 03e5 | *0434 | 0431 | 0433 |  |  |  |  |  |  |  |
| putc5 | 03d9 | *0428 | 0439 |  |  |  |  |  |  |  |  |
| raddr | 00d1 | *0028 | 0271 |  |  |  |  |  |  |  |  |
| ram | 0080 | *0031 | 0033 |  |  |  |  |  |  |  |  |
| read | 02 f9 | *0265 | 0303 |  |  |  |  |  |  |  |  |
| resetv | 1 ffe | *0498 |  |  |  |  |  |  |  |  |  |
| sava | 0088 | *0042 | 0135 | 0138 | 0157 | 0158 | 0252 | 0254 |  |  |  |
| savx | 0087 | *0041 |  |  |  |  |  |  |  |  |  |
| sec | 0080 | *0034 | 0112 | 0329 | 0332 | 0337 |  |  |  |  |  |
| sec_pin | 0266 | *0113 | 0116 |  |  |  |  |  |  |  |  |
| senddta | 02 db | *0234 | 0103 |  |  |  |  |  |  |  |  |
| sper | 000a | *0024 | 0070 | 0176 | 0180 |  |  |  |  |  |  |
| spdr | 000c | *0026 | 0177 | 0276 | 0280 | 0284 | 0290 |  |  |  |  |
| spsr | 000b | *0025 | 0178 |  |  |  |  |  |  |  |  |
| stop | 02 cb | *0202 | 0096 | 0110 | 0243 | 0289 |  |  |  |  |  |
| sub_more | 0299 | *0148 | 0151 |  |  |  |  |  |  |  |  |
| swiv | 1ffc | *0497 |  |  |  |  |  |  |  |  |  |
| w_start | 02ad | *0172 | 0221 | 0272 |  |  |  |  |  |  |  |
| waddr | 00d0 | *0029 | 0220 |  |  |  |  |  |  |  |  |
| wait | 02b5 | *0178 | 0178 |  |  |  |  |  |  |  |  |
| xtemp | 0089 | *0043 | 0377 | 0415 | 0447 |  |  |  |  |  |  |

# AN1067 

## Pulse Generation and Detection with Microcontroller Units

By Mike Pauwels


#### Abstract

INTRODUCTION

This application note examines two common interfaces between microcontroller units (MCUs) and external circuitry - pulse generation and pulse detection. Several families of Motorola MCUs and a variety of pulse applications are considered. Code segments and listings are also included.


## PULSE GENERATION

MCUs are often required to generate timed output pulses - i.e., signals asserted for a specified period of time. The application can be strobing a display latch, transmitting a code, or metering a reagent in a process control system; however, each application has specific requirements for pulse duration and accuracy. This application note examines methods of generating these pulses in relationship to timing accuracy, coding efficiency, and other controller requirements.

The following paragraphs describe the timing of the signals - the start time and duration of the pulse. All pulses can be divided into three basic classifications: short pulses, long pulses, and easy pulses. Each class of pulses is considered using three MCUs with different timer structures.

On the low end of the scale is the MC68HC05J1. The simple timer in this device limits the accuracy of short pulses and requires a larger amount of software investment to produce a given pulse. The second MCU, the MC68HC705C8 and similar devices, has a 16-bit timer that is somewhat more powerful and flexible than the MC68HC05J1 timer. Finally, the MC68HC1iA8 offers additional features in the 16 -bit timer system, as well as the possibility of producing multiple pulses simultaneously.

Because time measurements are being considered, the clock frequency for the MCU is significant. For this discussion, each MCU is assumed to be operating at a $2.0-\mathrm{MHz}$ internal, implying a $4.0-\mathrm{MHz}$ crystal for the MC68HC05 and an $8.0-\mathrm{MHz}$ crystal for the MC68HC11A8. The maximum speeds of these devices is somewhat higher, but these are commonly used values. Of course, these MCUs can all be operated at much slower clock speeds also. All times should be scaled to the actual clock frequency.

## Short Pulses

The classification of short pulses may vary according to the accuracy of the required pulse and the available MCU resources. In general, pulses of a few tens of microseconds and longer are relatively easy to produce. Below this broad limit, the methods used to generate short pulses may vary greatly according to the specific requirements. To produce a strobe pulse whose minimum required duration is in the order of magnitude of the clock period only requires writing a port bit high, then low in consecutive operations:

| PULSE | BSET | BITO, PORTA |
| :--- | :--- | :--- |
|  | BCLR | BITO, PORTA |

This produces a pulse duration of $2.5 \mu$ s duration in the MC 68 HC 05 , and $3.0 \mu \mathrm{~s}$ in the MC68HC11A8. The longer time in the MC68HC11A8 is a consequence of a longer BSET/BCLR instruction formation - three bytes versus two bytes in the MC68HC05. This is compensated for by the ability to set and clear multiple bits in one instruction. The MC68HC11A8, however, provides for a $0.5 \mu \mathrm{~s}$ minimum pulse by using the resources of two timer compare registers.

If the requirement for the pulse is longer than $2 \mu \mathrm{~s}$, the above pair of instructions can be separated by no operation (NOP) instructions or even by useful instructions to stretch to the desired pulse width. There are two problems with this option. First, padding the instructions with NOPs consumes MCU resources. If there is some task that the MCU can accomplish between the set and clear, this is not too serious. More difficult is the possible requirement that the pulse duration be run-time variable. The flexibility of the busy-wire pulse timing can be extended by adding a loop:

| SETUP | LDA | DURATION |
| :--- | :--- | :--- |
| PULSE | BSET | BITO, PORTA |
| LOOP | DECA |  |
|  | BNE | LOOP |
|  | BCLR | BITO, PORTA |

The duration of the pulse is:
$2.5+3.0^{*}$ DURATION $\mu$ s for the MC68HC05, and
$3.0+2.5^{*}$ DURATION $\mu \mathrm{s}$ for the MC68HC11A8
Of course the previous code could be padded with any number of NOPs at $1.0 \mu \mathrm{~s}$ or with branch nevers (BRNs) at $1.5 \mu \mathrm{~s}$ either inside or outside the timing loop for more precise values. However, the variable resolution is 2.5 or $3.0 \mu \mathrm{~s}$.

Note that in these cases the on-board timers were not used. In the case of these short pulses, the overhead of setting-up and reading the timers would be about as long as the pulse being driven. When the required pulse width is long enough to use the timer, easy pulses are produced.

## Easy Pulses

To produce a 10 ms pulse with the MC68HC11A8 controiler, force an output compare pin high and read the timer (in an uninterrupted sequence). Add the 10 ms to the timer value and store the result in the corresponding output compare register. Next write the corresponding output level (OLVL) bit to zero and enable the interrupt (if desired). The pulse completes automatically. Three questions arise: 1) What is the shortest pulse that can be produced in this manner? 2) What considerations must be made in the MC68HC705C8 timer which does not have a force register? 3) What is the equivalent procedure for the MC 68 HC 05 J 1 timer?

In the MC68HC11A8, two output compare registers can be combined to drive a single output. The elapsed time between the two events can be as little as one clock time; $0.5 \mu \mathrm{~s}$ if the prescaler is one. The code is as follows:

| PULSE | LDD <br> ADDD | $\begin{aligned} & \text { TIMER } \\ & \text { \#50 } \end{aligned}$ | Delay start of pulse |
| :---: | :---: | :---: | :---: |
| * The delay is selected according to <br> * timer prescaler, interrupts, etc. <br> * (min 33) |  |  |  |
|  | STD | TOC1 |  |
|  | ADDD | \#1 | Pulse Width |
|  | STD | TOC2 |  |
|  | LDAA | \#\$40 | Drive A6 High |
|  | STAA | OC1M |  |
|  | STAA | OC1D |  |
|  | LDAA | \#\$80 |  |
|  | STAA | TCTL1 | Drive A6 Low |

With the MC68HC705C8 timer system, there is no force bit for compare. The only way to drive the timer compare (TCMP) line high is to set the OLVL bit in the timer control register (TCR) and wait for a match. The exact start time of the pulse is easily obtained from the output compare register (OCR), so pulse accuracy is unaffected for moderate pulses. Often the pulse is started as soon as possible, if for no other reason than to complete the pulse setup routine. The following code segment provides a pulse start in $12 \mu \mathrm{~s}$, assuming no interrupts.
*

* Start the pulse
* 

BSET OLVL, TCR

* OUTPUT_COMPARE: = TIMER + DELAY
LDX ACHR MUST BE READ FIRST

| LDA | ACLR |
| :--- | :--- |
| ADD | \$DELAY |

BCC
INCX
STA OCLR
TIMER $=\mathbf{X : A}$

MARK TIME

INHIBITS TOC
ENABLES TOC
*

* IF DELAY IS CORRECT, PULSE WILL
* TURN ON IMMEDIATELY

Using a value for DELAY of about 21 (cycles) results in an average latency of $12 \mu \mathrm{~s}$ after the beginning of this routine. Note that loads and stores to the 16-bit registers are always performed high-byte first to take advantage of special hardware that maintains coherency in 16-bit data transfers. The pulse will turn on $1 \mu$ s later when there is a carry out of the low-byte add, which should occur about 1 in 12 times.

The programming of a moderate length pulse is now quite trivial. Simply add the desired pulse width (at $2 \mu \mathrm{~s}$ per bit) to the value stored in the output compare. Write the new value to the OCR and set the OLVL bit to zero. To finish code segment:


The interrupt structure is not required to generate pulses. The 16 -bit timers on the MC68HC11A8 and the MC68HC705C8 will automatically drive the falling edge of these pulses without software intervention. On the MC68HC05J1, there is no hardware timer interface. To drive moderate length pulses with this device, employ the interrupts so that useful work can be performed while the pulse is being timed. Consider a 10 ms pulse using the MC68HC05J1.

The simple timer of the MC68HC05J1 provides only the capability of being interrupted periodically. The source of interrupt can be a timer overflow or a real-time interrupt (RTI). The choice of interrupt times is given in Table 1:

Table 1. RTI and COP Rates ( $\mathrm{f}_{\mathrm{Op}}=\mathbf{2 M H z}$ )

| RT1/RTO | RTI | COP |
| :---: | :---: | :---: |
| $0 \quad 0$ | 8.2 ms | 57.3 ms |
| $0 \quad 1$ | 16.4 ms | 114.7 ms |
| 10 | 32.8 ms | 229.4 ms |
| $1 \quad 1$ | 65.5 ms | 458.8 ms |

Consider the algorithm for the timing of a pulse as counting "ticks" on a clock. Initially, it seems the ticks of the timer must be counted - 5,000 ticks ( $2 \mu \mathrm{~s}$ per tick) for the desired period of 10 ms . However, the timer overflow and real-time interrupts of the MC68HC05J1 provide long ticks that sound their completion with interrupts. Instead of 5,000 short ticks, count as follows:

| 1 RTI tick of $8192 \mu \mathrm{~s}$ | $=$ | 8,192 |
| :--- | :--- | ---: |
| 3 TOF ticks of $512 \mu \mathrm{~s}$ | $=$ | 1,536 |
| 544 cycles of $0.5 \mu \mathrm{~s}$ | $=$ | 272 |
| TOTAL |  | $\overline{10,000}$ |
|  | $=10.000 \mathrm{~ms}$ |  |

For most of this time background tasks can continue processing. The 544 cycles of busy-wait time include necessary work to set up the pulse. The key problem is the required timing of the start of the pulse. If the start time is flexible the design of the pulse could follow the pattern of Figure 1.


Figure 1. Time Line for a $\mathbf{1 0} \mathbf{~ m s}$ Pulse with Flexible Start Time

Start the pulse on the next RTI service routine, then count timer overflow flags (TOFs) after the next RTI until the final sequence, which is timed by a busy-wait counter. Careful calculation of the latencies and instruction cycles produces a pulse with a high degree of accuracy.

When the start time is not as flexible, a different approach is necessary. Since it is now impossible to align the RTI boundaries with the pulse, use only the TOF ticks to time the pulse. To turn the pulse on as soon as possible, read the value of the timer at turn-on. Calculate the time until the next overflow, add the predicted turn-off execution time, and then determine how many full TOF periods are in the remainder. After subtracting these long ticks, the remaining value is the busy-wait. A time line for this approach is given in Figure 2.


Figure 2. Time Line for a $\mathbf{1 0} \mathbf{~ m s ~ P u l s e ~ w i t h ~ I m m e d i a t e ~ S t a r t ~ T i m e ~}$

Since an interrupt occurs every $512 \mu \mathrm{~s}$, the performance of the MCU degrades slightly - about 10\% versus $1 \%$ for the first approach. The following code yields a 10.0 ms pulse on port $A 1$, with a latency of $2.5 \mu$ s after the code is entered:

```
* ASSUME THE DESIRED PULSE WIDTH,
* RESOLVED TO 2 \mus PER BIT,
* IS STORED IN A TWO-BYTE LOCATION
* LABELED: PW_H:PW_L. FOR A
* PULSE WIDTH OF }10\textrm{ms}\mathrm{ THIS
* VALUE WOULD BE $1388
* TURN ON TEE PULSE
\begin{tabular}{lll} 
START & BCLR & TOF,TCSR \\
& LDA & TIMER \\
& BSET & BITO, PORTA
\end{tabular}
    BSET BITO,PORTA
    COMA = TINE REMAINING
    SBA PW_L LOW BYTE OF PULSE
    BCC PWI
    DEC PW_H BORROW 1
    LDX *SA
        MOL (
        RE-SCALE LOW BYTE TO
        STX PW_L ...3 \mus PER BIT
        BSET TOFE,TCSR
        CLI
*
* the tmmer INTERRUPT DOES the rest
* OF THE WORK:
*
TOFI DEC PW H
    BNE END T
    LDA PW_L
    BEQ PLS_工
LOOP DECA BNE LOOP
PLS_L BCLR BITO,PORTA
END_T RTI
```

There will be some small inaccuracies due to latency of the interrupt and border conditions for the pulse width. The pulse can be refined, but if one-clock precision is required, choose another processor.

## Long Pulses

The idea of using the interrupt structure to count long "ticks" can be expanded beyond one byte. If a two-byte decrement is performed in the previous MC68HC05J1 example, pulses up to 30 seconds in length can be generated. The inaccuracies are the same in absolute terms as for the shorter pulses; therefore the percent of error is much smailer.

The same approach is used to expand the pulse width that can be generated by the 16-bit timers in the MC68HC705C8 and the MC68HC11A8 processors. With the help of the output compare function, one-tick accuracy with very long pulses is possible. The accuracy of the output is determined only by the accuracy of the crystal. The code listed in Appendix A has been tested in an MC68HC05C4 and produced pulses in the order of one minute with an accuracy of one part per million. Code to generate
long pulses with an MC68HC11A8 is similar. Since the timer interrupts are used to count the ticks, most of the MCU resources are available to do background tasks. For example, the timer interrupt routine consumes less than $25 \mu \mathrm{~s}$ every 131 ms . This represents about $0.2 \%$ of the processing power of the MCU. The actual code takes about 200 bytes of memory. The pulse will be precise if the interrupts are not masked for more than about 130 ms at a time. Beyond that limit, whole ticks of 131 ms will be added.

Finally, the MC68HC11A8 timer system provides for two timer output functions to drive a single pin. With this MCU, the start time and end time of the pulse can be driven independently with differences of as little as one count between the two pulse edges.

## Summary - Pulse Generation

Many MCU systems interface to hardware systems by means of timed pulses. Modern MCUs handle these pulses in three different ways depending on the hardware timing structure available and the length of the pulse.

Short pulses, ranging in length from as short as a microsecond to a few tens of microseconds, are usually timed with "busy-wait" loops. There is simply not enough time to set up a peripheral to control a pulse of short duration. The accuracy and resolution of these pulses is determined in part by the discrete execution time of branch instructions in the controller. The MC68HC11 can drive a pulse as short as a microsecond, resolved to a microsecond, by using the resources of two timer compare registers.

Moderate length pulses are simple to drive automatically using the 16 -bit timer available in the MC68HC11A8 and many of the MC68HC05 MCUs. These are set-and-forget systems that run to completion typically in 131 ms . In the simpler MC68HC05 MCUs, there is no 16-bit timer, and the moderate length pulses must use the timer overflow interrupt to count out large chunks of the pulse time while some background task is being performed.

The approach is similar in the MCUs with the 16 -bit timer when the desired pulse is greater than 131 ms . Multiple timer overflows can be counted in a few memory locations to produce very long pulses.

For more complex timing functions, a system may require a separate timing processor. In some complex control applications, an MC68HC11A8 or an MC68HC05 is employed as a peripheral timer to a larger computational engine. A variation on this theme is the time processing unit (TPU) in the MC68332. This complex timing system can perform several different functions on 16 different channels simultaneously, independent of the main processor. Information on the MC68332 is available from your Motorola Sales Office.

## PULSE DETECTION

Another system problem encountered when applying an MCU to a physical system is the detection and measurement of pulses. These can range from the actuation of a pushbutton to pulse codes detection, detection of the period of rotation of an engine, and accumulation of the 'on' time of a process control valve. The periods can range from microseconds to minutes, hours, or more.

There are several parameters that characterize a pulse, as Figure 3 illustrates. As far as a digital system is concerned, most of these parameters cannot be measured directly by a digital device such as an MCU. Indeed, some parameters such as the voltage level must be modified before the pulse
is applied to the MCU. If the values of these parameters are interesting to the system, then an external device such as an analog-to-digital converter is required. Other parameters may not be measurable by the MCU, including the signal rise and fall times and the presence of noise on the signal.


Figure 3. Characteristics of a Pulse
Digital pulses convey information only in the timing of their signals, assuming that all voltage signals vary between $\mathrm{V}_{\text {SS }}$ and $\mathrm{V}_{\text {DD }}$, and that rise and fall times are sufficiently fast to be unambiguous to the processor. The parameters of interest are the start-time and duration of the pulse. Noise, if it exists, is interesting only to the extent that it can be seen by the controller, and in that case, provision must be made to reduce its effects.

There remains one significant question to address before software design can commence. What is the expected duration range of the pulse? There are no effective maximum limits on the duration which can be measured; but very short pulses may require the support of on-chip or off-chip hardware. A related characteristic is the start-time of the pulse, measured from some reference. This can be thought of as the measurement of a pulse off-time, and hence is not significantly different from the duration measurement. Also important is the required accuracy of the measurement, specified in absolute or relative terms.

One important choice the designer makes in addressing system problems is the type of MCU that will be used. Most MCUs have some sort of timing device on-chip. Within the five basic families of Motorola processors are several timer variations. These range from the simple counter in the MC68HC05J1 to the sophisticated TPU of the MC68332. The former is useful only for the simplest requirements, while the latter can measure pulses accurately without intervention of the CPU. The choice for most applications is usually between an MC68HC11 and one of the large family of MC68HC05 devices.

The timer on the MC68HC11A8 provides as many as four hardware input signals with several hardware registers to measure input events. By combining two input capture functions, or by using the clock gate input of the MC68HC11A8, many pulse measurement problems are easily solved. It is more difficult to address the problems with the 16 -bit timer system found on the most popular MCU family, the MC68HC05.

Consider the accuracy limitations of the MC68HC(7)05Cx 16-bit timer. The timer counter itself is incremented once for every eight cycles of the MCU crystal frequency. A $4.0-\mathrm{MHz}$ crystal provides a count resolution of $2 \mu \mathrm{~s}$. With short pulses, this resolution may be a contributor to accuracy limitations. For example, measuring a $50 \mu \mathrm{~s}$ pulse, this resolution will produce a count of 25 with a 1 -bit quantizing error, an uncertainty of $4 \%$. However, in measuring a one minute pulse, the quantizing error is $0.0000033 \%$.

In the case of the longer pulses, the accuracy of the crystal can contribute far more to the loss of precision. A limited sampling of clock frequencies on MC68HC05 Evaluation Modules indicates that typical crystals may produce errors of $0.001 \%$. While crystals can be selected or trimmed to much higher accuracy, it is important not to specify accuracies from the software that cannot be supported by the hardware.

Consider four general classes of pulses to detect: 1) very fast pulse, say $20 \mu$ s or less; 2 ) longer pulses up to $130 \mathrm{~ms} ; 3$ ) long pulses; and 4) noisy pulses. The second class is almost trivial with the TCAP feature of the MC68HC05. Indeed, these are the most common class of pulses, and the hardware does almost all of the work. These are considered a special case of the third class of pulses. The other three classes require a bit more study.

## Short Pulses

To measure very fast pulses with the MC68HC05, it is necessary to deal with interrupt latency which can be as much as $10 \mu \mathrm{~s}$. If an IRQ is triggered on the start of the pulse, the pulse may have ended by the time code is executed in the interrupt routine. Accuracy is limited by the latency of the system. An example of the code necessary to measure these pulses is given below:

```
INTRUPT:
\begin{tabular}{llll} 
& CLRA & \\
BIL & END_PULS & \\
T_LOOP: & INCA & & \\
A: & BIH & T_LOOP &
\end{tabular}
END PULS:
*
*
```

After the pulse is driven low on the IRQ line, the timed wait is executed for the rising edge which enables detection of a very short pulse. At END_PULS, the Accumulator has a measurement of the length of the pulse resolved to $3 \mu \mathrm{~s}$ per bit. Assuming the interrupts are not masked the worst case time to get to point $\mathbf{A}$ the first time is $13.4 \mu \mathrm{~s}$ ( $11.5 \mu \mathrm{~s}$ if MUL is not used in the background). The fastest time is $9 \mu \mathrm{~s}$. Any pulse shorter than this will result in a zero time value. If the pulse value is greater than zero, the pulse width is $3 \mu$ s times the accumulator value plus a latency time of $9-13.5 \mu \mathrm{~s}$. Finally, the longest pulse time that this routine can reasonably measure before the accumulator will overflow is about $770 \mu \mathrm{~s}$. The interpretation of the result is left to the user.

If a short pulse is brought in on the TCAP line, there is additional latency to consider. If there is sufficient time to reverse the IEDG bit and clear the ICF (minimum about $20 \mu \mathrm{~s}$ ), this is a class 2 pulse. If the pulse is shorter than this, the input capture function may miss the second edge. Unlike the MC68HC11A8 input capture functions, the MC68HC05 timer pin (TCAP) is not directly detectable. Precautions must be taken in the hardware design if very short pulses are possible. For example, a port line could be wired to the TCAP pin and the state of the pin could be tested with a BRSET/BRCLR. The minimum resolvable pulse length is still no better than the IRQ driven case. However, using the

TCAP input offers capability to measure pulses of either polarity up to 131 ms in length and with a resolution of $2 \mu \mathrm{~s}$.

Of course, if the pulse is expected to be short and the start time can be predicted, a busy-wait can be executed for both ends of the pulse. In this case it is necessary to continually test the state of the input pin and branch accordingly. For example, if the expected pulse length is between 5 and $100 \mu \mathrm{~s}$, execute a string of tests as shown below:

```
PULSE:
CLRA
PO BRCL
    BRCLR SIN, PORT,P0 NAIT FOR THE FIRST EDGE 
    BRSET PIN, PORT, P2
    .
    BRSET PIN,PORT,PN
        INCA
PN INCA
    .
        INCA
P1 INCA
*
* ACC CONTAINS RULSE WIDTH OF 2.5 \mus
* PER BIT
```

This code yields a resolution of $2.5 \mu \mathrm{~s}$ for any pulse down to $2.5 \mu \mathrm{~s}$. Below that, the pulse may be missed. As the expected pulse length gets larger, this code becomes unwieldy and finally impossible.

The addition of an instruction loop shortens the code at the expense of resolution:

```
PULSE:
CLRA
P0 BRCLR PIN,PORT,PO
P1 INCA
    BRSET PIN,PORT,R1
*
* ACC CONTAINS PULSE AT 4 \mus PER BIT
*
```

For longer (class 2 ) pulses, use the input capture register of the timer to do all the work. Where the pulse is more than a few tens of microseconds long, the interrupt structure works well to measure the pulse within the accuracy of the crystal. The rising edge of the pulse triggers a first interrupt, and the service routine enables the interrupt on the falling edge. By reading the input capture register on each edge, the exact pulse length can be measured. This class of pulses is included in a special case of the long pulses below.

## Longer Pulses

What if the pulse length exceeds the rollover time of the timer? By counting the rollovers, a pulse of arbitrary length can be measured. Consider the possibility of a 60 second pulse that must be detected
and measured accurately. If the timer counts $2 \mu$ s per bit, 30 million counts must be accumulated. To store this information, $\log _{2}(30,000,000,000)=25$ bits, or 4 bytes are needed. To be precise, a value of \$1 C9 C3 80 is expected.

The 16-bit timer will automatically record the edges of the pulse. Ignoring the overflow, if the start time is subtracted from the end time the result will yield the two least significant bytes of the pulse width. In the 60 second example, if the pulse is exactly correct, the difference between the output compare value at the start of the pulse and the value at the end of the pulse will be $\$ \mathrm{C} 380$. Between those two pulse events, the timer will roll over $\$ 1 \mathrm{C} 9$ times ( $=457$ ). Counting those rollovers exactly will determine the pulse length. The timer overflow facility will allow a count of the rollovers under interrupt control. Some problems remain in arbitrating the interrupts and protecting for boundary conditions, which will be discussed below.

The general approach taken for the MC68HC05Cx TCAP works as well for the MC68HC11 family when a single input capture function is used for measurement.

Appendix B is a listing of an MC68HC05 program which can measure very long pulses with single tick accuracy. The program was tested with the pulse generation problem listed above and appears to work within the accuracy of the crystal. Some adjustment may be necessary when this software is integrated into the user's program, particularly insofar as the interrupt latency is affected, but the basic structure of the routines will perform the measurement function. Note that class 2 pulses can be measured with this routine as it stands, although some code savings can be realized if the pulse to be measured is known to be contained in less than 4 bytes.

Three particular areas should be attended to when incorporating this software in a larger project. The measurement routine uses mutually exclusive interrupts and no subroutines, therefore its contribution to stack push is seven bytes. Add this to any other subroutine and interrupt stack usage to determine the maximum stack depth and therefore the available RAM.

If other interrupts are used, remember that the interrupt mask is automatically set when the interrupt routine is entered. If the mask cannot be cleared, the execution time of the other interrupt, plus its latency, must be kept somewhat less than $500 \mu \mathrm{~s}$ (or the pulse width, whichever is smaller) to preserve the accuracy of the measurement routine. The same is true if critical code sections must be preserved with SEI...CLI instructions.

Within these limitations, the automatic timing features of the TCAP will provide accurate measurement of the pulse. The $500 \mu \mathrm{~s}$ limitation is necessary to assure the correct handling of the boundary conditions when an overflow coincides with a pulse edge. If the interrupts must be masked for longer periods, the boundary conditions handling can be modified.

The third area to consider is the effect of the interrupts on execution speed of the processor. The pulse measurement routines take less than $0.02 \%$ of the clock cycles when measuring long pulses, so the routine will not significantly affect the throughput of most programs, however, each timer overflow interrupt takes about $24 \mu \mathrm{~s}$, so software timing loops and critical sections can be affected.

## Noisy Pulses

The important thing to remember about noisy pulses is that a noise edge often cannot be distinguished from a pulse edge. This is particularly true when the input capture register is used to detect the edge. But even when the edge is polled, a momentary change in the signal level can be erroneously interpreted.

In general, it is difficult to measure any true pulse that contains noise pulse durations in order of magnitude of the measurement resolution. This means that signals must be free of $1 \mu \mathrm{~s}$ noise pulses for most MCU detection and measurement algorithms. The MC68HC11A8 pulse accumulator function in gated mode can be used to measure the total asserted time of a very noisy pulse.

Often, the easiest way to eliminate the ambiguity of minor noise is with some low pass hardware filtering. Remember that low pass filtering will also round and delay the edges of the pulse. The delay will contribute more or less to the accuracy of the measurement. In addition, sampled edges can be double-checked in our busy-wait algorithms with the addition of a single instruction per edge:

```
PULSE:
```

| PO | CLRA |  |
| :---: | :---: | :---: |
|  | BRCIR | PIN, PORT, PO |
|  | BRCLR | PIN, PORT, PO |
| P1 | INCA |  |
|  | BRSET | PIN, PORT, P1 |
|  | BRSET | PIN, PORT, P1 |
| * |  |  |
|  | LSE AT | Us PER BIT |

Sophisticated digital filter algorithms can be used to extract a pulse from very noisy conditions, but these are beyond the scope of this application note. Consider a simple method of determining the approximate pulse-width of an input signal corrupted by a lot of noise.

Consider the signal of Figure 4. Is this one noisy 5 ms pulse or a number of smaller pulses? Taken at face value, this would translate into a number of various length disjoint pulses. However, if this were part of a pulse-width modulated code that had been transmitted on an r.f. carrier, the range of reception of the pulse could be significantly improved if the intelligence could be unambiguously extracted from this waveform. Much of the success of decoding algorithms depends on the knowledge of the expected signal. If, for example, the above waveform is expected to be either a 6 ms pulse or a 2 ms pulse, it is expected that this algorithm would more often choose the former. If there were some independent cross check on the validity of the code detection, such as a cyclic redundancy check, the detection could be made with a fair degree of certainty.


Figure 4. Noisy Pulse

It is beyond the scope of this note to present a detailed discussion of pulse train encoding and decoding, but the following paragraphs offer a few ideas about developing an effective method for capturing noisy pulses with an MCU.

The detection of the above signal with any of the earlier methods is unlikely to yield the correct data. With the MC68HC11A8 pulse accumulator, the pulse can be determined to be more likely 6 ms than 2 ms , but without the pulse accumulator, the MC68HC05 MCUs require more software intensive methods.

The basic strategy used to measure the pulse is to take periodic samples of the signal and employ some heuristic process to discover the signal in the noise. Most commonly, the selected algorithm is simple voting. Additionally, some cross check of the data such as a check-sum may be employed. If, for example, a $100 \mu \mathrm{~s}$ sample of the above pulse is taken, marked by the tick marks on the drawing, the findings show that the signal is high for 37 to 50 samples. This is more consistent with a 'wide' pulse than a 'narrow' one. If a cross check agrees with this conclusion, there is some confidence in the conclusion. If the cross check disagrees, the error could be guessed based on the lowest probability detection; or a re-transmission might be required. If no cross check is possible, a decision can be made on a minimum probability required to accept the data.

Below is a sampling routine that uses the output compare interrupt to time the samples. Fifty samples are accumulated before testing the vote.

| TOCI | BRCLR | TOF, TSR, NO_TOC | CLEAR FLAG |
| :---: | :---: | :---: | :---: |
|  | LDX | OCHR |  |
|  | LDA | OCLR |  |
|  | ADD | \#50 | INT IN 100 |
|  | BCC | SMP1 | . $\mu$ Ms |
|  | INCX |  |  |
| SMP 1 | STX | OCHR |  |
|  | STA | OCLR |  |
| * |  |  |  |
| * | NEXT SAMPLE IN $100 \mu \mathrm{~s}$ |  |  |
|  |  |  |  |
|  | BRCLR | PIN, PORT, SMP 2 |  |
|  | INC | VOTE |  |
|  | BRA | SMP 3 |  |
| SMP 2 | DEC | VOTE |  |
|  | DEC | COUNT |  |
|  | BNE | SMP 9 |  |
| * |  |  |  |
| * HERE AFTER 50 SAMPLES |  |  |  |
| * PUT VOTING ROUTINE HERE |  |  |  |
| NO_TOC: |  |  |  |
| * DO OTHER INTERRUPT HERE |  |  |  |
|  | RTI |  |  |

Note that this interrupt routine consumes only about $25-30 \%$ of the processor cycles. This number is directly related to the sample rate - sampling of $1 / 2$ the rate reduces usage to less than $15 \%$ of the processor.

The choice of voting algorithm is application dependent. However, synchronization of the signal must also be considered. Depending on the type of coding used, a signal can be assumed to be self-synced. That is, the measurement of any pulse after a quiet period causes the receiving processor to try to wake up to a wide pulse or a narrow pulse. This causes the voting algorithm to reject pulses that vary widely from one of the expected widths.

With crystal-controlled oscillators in both the transmitting processor and the receiving one, this does not present a problem. If one or both of the controller clocks is not tightly regulated, however, the receiver will require time base as well as start time synchronization. In general, the more information that must be transmitted, the greater potential for error due to noise. The information transmitted is the code, the start time, and the time base.

## Summary of Pulse Detection

MCU systems often read information from a hardware device by means of timed pulses. When these pulses fall in the range of a few tens of milliseconds, most MCUs can measure the pulse width easily with a high degree of accuracy. When the pulses are very short, very long, or noisy, the accurate detection and measurement of them is more difficult.

The most important decision to be made in system design for pulse measurement is the choice of MCU, specifically the timer subsystem. The least sophisticated timers such as found on the MC68HC05J1 lose some resolution and accuracy, particularly for short pulses, but these simple timers are often found on the low-cost chips. As the complexity and cost of the timer is increased, so is the performance of the MCU in this task. The very complex timer system in the MC68332 provides the greatest resolution and performance of any MCU available. For information, call your local Motorola sales office.

# APPENDIX A <br> TTL LONG PULSE GENERATION 

```
*
*
*
*
*
*
* PULSE GENERATION
*
* THIS ROUTINE GENERATES PULSES FROM A MC68HC05CX MICROCONTROLLER USING
THE TIMER OUTPUT COMPARE FUNCTION. THE LENGTH OF PULSES GENERATED
RANGE FROM A FEW MICROSECONDS TO MORE THAN TWO HOURS.
*
THIS SOFTWARE IS INTENDED AS A SUBSYSTEM TO BE INCLUDED IN A INARGER
* PROGRAM. ETC.
*
* CONSTANTS:
* SYSTEM CONSTANTS:
* ADDRESSES:
\begin{tabular}{llll} 
& OPT & nol \\
PORTA & EQU & 0 & PORT A \\
DDRA & EQU & 4 & DATA DIRECTION REGISTER FOR PORT A \\
TCR & EQU & \(\$ 12\) & TIMER CONTROL REGISTER \\
ICIE & EQU & 7 & INPUT CAPTURE INTERRUPT ENABLE \\
OCIE & EQU & 6 & OUTPUT COMPARE INTERRUPT ENABLE \\
TOIE & EQU & 5 & TIMER OVERFLOW INTERRUPT ENABLE \\
IEDG & EQU & 1 & INPUT EDGE \\
OLVL & EQU & 0 & OUTPUT LEVEL \\
TSR & EQU & \(\$ 13\) & TIMER STATUS REGISTER \\
ICF & EQU & 7 & INPUT CAPTURE FLAG \\
OCF & EQU & 6 & OUTPUT COMPARE FLAG \\
TOF & EQU & 5 & TIMER OVERFLOW FLAG \\
ICHR & \(E Q U\) & \(\$ 14\) & INPUT CAPTURE REGISTER HIGH BYTE \\
ICLR & EQU & \(\$ 15\) & INPUT CAPTURE REGISTER LOW BYTE \\
OCHR & EQU & \(\$ 16\) & OUTPUT COMPARE REGISTER HIGH BYTE \\
OCLR & EQU & \(\$ 17\) & OUTPUT COMPARE REGISTER LOW BYTE \\
CHR & EQU & \(\$ 18\) & TIMER/COUNTER HIGH BYTE \\
CLR & \(E Q U\) & \(\$ 19\) & TIMER/COUNTER LOW BYTE \\
ACHR & \(E Q U\) & \(\$ 1 A\) & ALTERNATE TIMER/COUNTER HIGH BYTE \\
ACLR & \(E Q U\) & \(\$ 1 B\) & ALTERNATE TIMER/COUNTER LOW BYTE
\end{tabular}
* PROGRAM CONSTANTS
    ORG $20
DELAY FCB 6 DELAY FOR START OF PULSE
MIN_PLS FCB 5 MINIMUM PULSE WIDTH IN CLOCK COUNTS
DO_PLS FCB $01,$C9,$C3,$80
* VARIABLES
    ORG SBA OR CONCATENATE WITH USER MEMORY
    RMB 4
                4
PULSE RMB
MAX TIME = 143.1655765 MINUTES!
```

```
* ASSUMING A 4 MHz CRYSTAL, FOUR BYTES WILL AUTOMATICALLY tIME
* 2^33 MICROSECONDS (ABOUT 2.4 HOURS) WITHIN THE ACCURACY OF THE
* CRYSTAL. EACH BIT IS 2 MICROSECONDS. FOR LONG TIME PERIODS,
* CONSIDER THAT A SLOWER CLOCK WILL SAVE POWER AND A 32kHz WATCH
* CRYSTAL IS INEXPENSIVE, buT REMEMBER THAT THE PROCESSOR EXECUTION
* WILL SLOW BY 122 tIMES! IF YOU HAVE A LOT OF PROCESSING TO DO
* BETWEEN UPDATES, YOU MAY FIND THE PROCESSOR TOO SLOW!
* SOME OTHER TIME OPTIONS:
    5 BYTES WILL TIME UP TO 25.45 DAYS
    6 \text { BYTES WILL TIME UP TO 17.83 YEARS}
    7 BYTES WILL TIME 4,566 YEARS!
NO RESET INITIALIZATION IS REQUIRED. THE TIMED PULSE WILL BE
DRIVEN ON THE TCMP PIN WHICH IS AUTOMATICALLY INITIALIZED AS
AN OUTPUT. THE TIMER OUTPUT COMPARE AND THE TIMER OVERFLOW
INTERRUPTS ARE INITIALIZED BY THE START PULSE SUBROUTINE (STRT_PLS).
*
FLAGS RMB STORE A FLAG
FIRE EQU 7 7 INICATES PULSE HAS STARTED
LAST EQU 6 INDICATES LAST INTERRUPT HAS OCCURED
*
* MAIN PROGRAM GOES hERE. THE LENGTH OF the DESIRED PULSE IS
* DETERMINED AND STORED IN 'PULSE' AT 2 MICROSECONDS PER BIT.
* THE PULSE WILL START AFTER 'STRT_pLS' IS CALLED WITH THE
* latency and accuracy nOTEd below.
```



```
*********************************************************************
```

*********************************************************************

* MAIN PROGRAM
* MAIN PROGRAM
****************************************************************)
****************************************************************)
* 
* 
* HERE IS THE MAIN LOOP. IF WE HAVEN'T FIRED, CALL STRT PLS
* HERE IS THE MAIN LOOP. IF WE HAVEN'T FIRED, CALL STRT PLS
* 
* 

MAIN:
MAIN:
BRSET FIRE,FLAGS,FIRED
BRSET FIRE,FLAGS,FIRED
*
*

* HERE ONCE AFTER RESET WHILE FIRE FLAGG IS CLEARED
* HERE ONCE AFTER RESET WHILE FIRE FLAGG IS CLEARED
* 
* LDX \#3 LOAD FOUR BYTES
LDX \#3 LOAD FOUR BYTES
LOAD LDA DO PLS,X
LOAD LDA DO PLS,X
STA PULSSE,X

```
    STA PULSSE,X
```

```
        DECX
        BPL LOAD
        JSR STRT_PLS
* DURING THE INTERRUPTS, THE 'LAST' FLAG IS CLEAR, JUMP TO MAIN
*
FIRED BRCLR LAST,FLAGS,MAIN
*
* HERE AFTER THE INTERRUPTS
*
    NOP REPRESENTS OTHER INSTRUCTIONS
    BRA MAIN
*********************************************************************
* START PULSE SUBROUTINE
*
* CALL THIS ROUTINE WITH THE DESIRED PULSE LENGTH IN 'PULSE'.
* THE MOST SIGNIFICANT BYTE IS STORED FIRST. FOR LONG PULSES,
* THE 'FRACTIONAL' PART, THAT STORED IN THE TWO LEAST SIGNIFICANT
* BYTES, ARE TIMED FIRST. THEN THE EXTENSIONS ARE TIMED OUT ONE
* AT A TIME UNTIL, ON THE LAST PERIOD THE OUTPUT LEVEL BIT IS
* CLEARED AND THE PULSE STOPS AUTOMATICALLY.
* NOTE THAT THE VARIABLE PULSE IS MODIFIED BY THE PULSE GENERATION
* FUNCTION, AND THAT THAT VARIABLE REFLECTS (ROUGHLY) THE AMOUNT
* OF PULSE REMAINING. OVERWRITING THE PULSE WIDTH CAN HAVE
* UNDESIREABLE RESULTS, BUT SHOULD USUALLY RESULT IN CHANGING THE
* TERMINATION TIME.
* PROCEDURE START_PULSE (PULSE_WIDTH: LONG_INT);
STRT_PLS:
    SEI DON'T INTERRUPT
* IF PULSE_WIDTH > $FFFF THEN INTERRUPT:=ENABLE ELSE INTERRUPT:=DISABLE
    BSET 7,PORTA TURNS ON INDICATOR LED, NOT TRUE PULSE
    BSET OCIE,TCR ENABLE TOC INTERRUPT
    LDA PULSE+1
    SUB #1
    STA PULSE+1
    LDA PULSE
    SBC #O
    STA PULSE
    BCC SP1
*
* HERE IF PULSE WAS LESS THAN $FFFE--FIX THE DAMAGE
*
\begin{tabular}{ll} 
CLR & PULSE+1 \\
CLR & PULSE \\
BCLR & OCIE,TCR
\end{tabular}
*
* IF 0 < PULSE_WIDTH < MINIMUM THEN PULSE_WIDTH := MINIMUM;
SP1 TST PULSE+2
```

```
        BNE LONG_PLS
        LDA #PULSE+3
        BEQ LONG_PLS
        CMP MIN_PLS
        BHI LONG_PLS
        LDA MIN_PLS
        STA PULSE+3
LONG_PLS:
* HERE WHEN THE PULSE WIDTH FRACTIONAL PART IS ZERO OR >= MIN_PLS
*
* FIRST START THE PULSE
*
* NEXT LEVEL := TRUE;
    BSET OLVL,TCR
*
* ONE OF the trickIEST OPERATIONS IS TURNING ON THE PULSE. SINCE
* THE 'HCO5 DOES NOT HAVE THE FACILITY TO SWITCH THE TCMP LINE
* DIRECTLY, WE SETUP A TURN ON TO OCCUR IMMEDIATELY. WE HAVE TO
* adJUST TO the tIME NEEDED FOR the SEtUP. this IS the value 'delay'.
*
* OUTPUT_COMPARE := TIMER + DELAY
    LDX ACHR MUST BE READ FIRST
    LDA ACLR TIMER = X:A
    ADD DELAY
    BCC MARK_1 MARK TIME
    INCX
    BRA OC1
MARK_1 NOP TO BALANCE EXECUTION TIMES
        BRA OC1
        STX OCHR INHIBITS TOC
        STA OCLR ENABLES TOC
*
* IF DELAY IS CORRECT, PULSE WILL TURN ON IMMEDIATELY
*
*
* TOC := TURN_ON + PULSE_WIDTH MOD $10000
*
    ADD PULSE+3
        STA PULSE+3
        TXA
        ADC PULSE+2
        TAX
        LDA PULSE+3
        CLR PULSE+3
        CLR PULSE+2
*
*
* IF INTERRUPT=ENABLED THEN OLVL := 1 ELSE OLVL := 0 ;...AND PULSE
* wILL TERMINATE
*
OC2
\begin{tabular}{llr} 
BRSET & OCIE,TCR, OC2 & \\
BCLR & OLVL, TCR IF INTERRUPT = DISABLED \\
STX & OCHR & \\
TST & TSR & \\
STA & OCLR & WILL CLEAR OCF. .
\end{tabular}
```

```
    BSET FIRE,FLAGS INDICATE PULSE HAS FIRED
*
* AT THIS TIME, THE MINIMUM PULSE CAN EXPIRE. IN THAT CASE
* WHEN WE ENABLE THE INTERRUPT, WE WILL IMMEDIATELY BEGIN
* SERVICING.
*
    CLI
    RTS
```



```
* TIMER INTERRUPT ROUTINE
#********************************************************************
```

TCMP_INT:
*

* WE WILL INTERRUPT WITH A TOC ONLY IF THERE ARE A WHOLE NUMBER OF
* $\$ 10000$ PERIODS TO COMPLETE. WE NEED ONLY DECREMENT THE 'INTEGER'
* PART OF THE PULSE WIDTH AND IF THIS IS THE LAST TIME, WE CLEAR
* THE INTERRUPTS AND SET THE OUTPUT LEVEL TO ' 0 '. THE TOC REGISTER
* IS NOT CHANGED.
* 
* IF THERE ARE OTHER POSSIBLE TIMER INTERRUPT SOURCES (INPUT CAPTURE
* AND/OR TIMER OVERFLOW) THEN WE SHOULD ARBITRATE THE SOURCE AT THIS
* TIME. NOTE THAT THERE WILL ALWAYS BE PLENTY OF TIME TO SERVICE THIS
* ROUTINE, SO THE PRIORITY COULD BE SET TO THE LOWEST LEVEL.
* 
* 
* ARBITRATION...
* 
* IF PULSE_WIDTH $>\$ 10000$ THEN
* PULSE_WIDTH := PULSE_WIDTH - \$10000
* LDA PORTA
EOR \#\$03
STA PORTA TOGGLE 2 PORT LINES (DIAGNOSTICS)
*       LDA PULSE+1
      SUB \#1
      STA PULSE+1
      LDA PULSE
      SBC \#0
      STA PULSE
      BCC NOT LAST
    * ....ELSE INTERRUPT := DISABLE; OLVL $:=0$;
* 
* HERE IF PULSE WAS ON LAST COUNT, CLEAR INTERRUPT AND OLVL
* CLR PULSE+1
CLR PULSE
BCLR 7,PORTA
BCLR OCIE,TCR
BCLR OLVL,TCR
BSET LHAST, FLAGS

```
*
* here IE NOT ON IAST PULSE
*
* CLmar (OCF);
*
NOT_LAST:
    LDA TSR NECESSARY ACCESS
    LDA OCLR ... NEXT INTERRUPT WILL HAPPEN IN $10000
    RTI
*********************************************************************
* DUMMY INTERRUPT ROUTINES
*********************************************************************
SPI INT RTI
SCI_INT RTI
IRQ_INT RTI
SWI_INT RTI
```


SPI_VEC FDB SPI_INT
SCI_VEC FDB SCI_INT
TIM VEC FDB TCMP INT
IRQ_VEC FDB IRQ_INT
SWI_VEC FDB SWI_INT
RST_VEC FDB RST_INT

# APPENDIX B <br> LONG PULSE DETECTION 

```
*
*
*
* WRITTEN 11/18/89 BY MIKE PAUWELS
*
*
* PULSE DETECTION
*
* THIS ROUTINE DETECTS PULSES WITH A MC68HC05CX MICROCONTROLLER USING
* THE TIMER INPUT CAPTURE FUNCTION. THE LENGTH OF PULSES DETECTED
* CAN RANGE EROM A FEW MICROSECONDS TO MORE THAN TWO HOURS.
*
* THIS SOFTHARE IS INTENDED AS A SUBSYSTEM TO BE INCLUDED IN A LARGER
* PROGRAM. ETC.
*
* CONSTANTS:
    OPT nol
* SYSTEM CONSTANTS:
* ADDRESSES :
DDRA EQU \$04
PORTA EQU \$00
TCR EQU '\$12
ICIE EQU 7
OCIE EQU 6
TOIE EQU 5
IEDG EQU 
TSR EQU $13
ICF EQU 7
OCF EQU 6
TOF EQUU 5
ICHR EQU $14
ICLR EQU $15
OCHR EQU $16
OCLR EQU $1
CHR EQU $18
CLR EQU $19
ACHR EQU $1A ALTERNATE TIMER/COUNTER HIGH BYTE
ACLR EQU SIB ALTERNATE TIMER/COUNTER LOW BYTE
* PROGRAM CONSTANTS
* VARIABLES
    ORG SBA OR CONCATENATE WITH USER MEMORY
AC_OVFL RMB 2 MAX TIME = 143.1655765 MINUTES!
PULSE_W RMB 2 HOLDS STOP TIME AND TOTAL PULSE
START_T RMB 2 HOLDS PULSE START TIME
```





```
* ARM CAPTURE SUBROUTINE *
```



```
*
* CALL THIS ROUTINE TO ARM THE PULSE MEASURENMISNT. NOTE THAT THE
* LENGTH OF PULSE THAT CAN BE MEASURED IS LIMITED BY SIZE OF THE
* OVERFLOW ACCUNULATOR. POSITIVE GOING PULSE IS ASSUMED; THE
* MODIFICATIONS EOR NEGATIVE GOING PULSE ARE SIMPLY THE INVERSION
* OF THE IEDG. SYSTEM IS ARMED 22 MICROCYCLES AFTER THE ROUTINE
* IS CAILED.
*
GET_PLS:
    BSET IEDG,TCR
    IDA TSR TWO STEPS REQUIRED...
    LDA ICLR ...TO CLEAR OLD FLAGS
    BSET ICIE,TCR
    BSET TOIE,TCR START COUNTING OVERFLOWS
    BCLR 7,PORTA
    BSET ARM,FLAGS
    CLI
    RTS
********************************************************************
* TIME DELAY SUBROUTINE *
********************************************************************
*
* CALLED FOR A BUSY DELAY. IF NOT INTERRUPTED, WILL RETURN AFTER
* A DELAY OF 5 MILLISECONDS TIMES THE CONTENTS OF 'A' ACCUMULATOR.
*
DELAY:
    LDX #249
DLA1 DECX
    NOP
    NOP
    NOP
    NOP
    NOP
    NOP
    NOP
    BNE DLA1
    DECA
    BNE DELAY
    RTS
```



```
* TIMER INTERRUPT ROUTINE *
**t*****************************************************************
*
* HERE ON TIMER INTERRUPT. WE ASSUME THAT TIMER OUTPUT ROUTINES
* DO NOT HAVE TO BE ARBITRATED. IF TOC IS NEEDED, THE ARBITRATION
* MUST BE CALCULATED. SINCE THE ONLY STICKY PROBLEM OCCURS ON
* SIMULTANEOUS OR NEAR-SIMULTANEOUS INTERRUPTS, THE TIMING OF THIS
```

```
* ROUTINE IS CAREEULLY CALCULATED.
*
TIM_INT:
* THE FOLLOWING INSTRUCTION IS NEEDED IF ANY OTHER TIMER
* INTERRUPTS ARE ENABLED:
*BRCLR ICF,TSR,NO_TIC BR IF NO INPUT CAPTURE
*
* HERE ON INPUT CAPTURE. IS THIS FIRST EDGE OR LAST EDGE?
*
    BRCLR IEDG,TCR,INAST_EDG
    BCLR IEDG,TCR PREPARE FOR TRAILING EDGE
*
* HERE ON THE FIRST (RISING) EDGE
```



```
    LDA ICHR
    LDX ICLR <<<< point A
    STA START_T START TIME HIGH BYTE
    STX START_T+1 " " LOW "
*
* WE NOW HAVE THE CAPTURED START TIME IN MEMORY.
*
    CLI
    RTI
*
* HERE ON THE TRAILING EDGE OF THE MEASURED PULSE. THE TIC REGISTER
* HAS THE TWO LEAST SIGNIFICANT BYTES OF THE STOP TIME. SUBTRACT
* THE START TIME; IF NECESSARY BORROW FROM THE AC_OVFL. NO CHECK IS
* MADE FOR OVERFLOW OF THE MAXIMUM PULSE.
*
IAST_EDG:
BSET GOT,FLAGS
BSET 7,PORTA
BCLR ICIE,TCR
LDX ICHR
LDA ICLR
STX PULSE_W
STA PULSE_W+1
*
* HERE THE PROBLEM IS TOO MANY OVERFLOWS. IF ICHR = $FF AND ACHR = 0
* AND THE OVERFLOW FLAG HAS BEEN CLEARED, WE ACCUMULATED ONE TOO
* MANY OVERFLOW.
*
    INCA TEST FOR = $FF
    BNE CALC_PW
    TST ACHR
    BNE CLEAR_A1
    BRSET TOF,TSR,CLEAR_A1
    LDA ACOOVFL+1
    SUB #1
    STA AC_OVFL+1
    BCC CLEAR_A1
    DEC AC_OVFL
CLEAR A1:
    LDA ACLR TO CLEAR LATCH
CAIC_PW:
    LDA PULSE_W+1
```

```
SUB START_T+1
STA PULSE_W+1
LDA PULSE_W
SBC START_T
STA PULSE_W
LDA AC_OVFL+1
SBC #0
STA AC_OVFL+1
BCC TIM_EXIT
DEC AC_OVFL
NO_TIC:
* COULD be A tOC. OTHER tIC OR TOC OR OVERFLOW STUFF CAN BE DONE hERE
*
*
TIM_EXIT:
RTI
```


*******************************************************************

* INTERRUPT VECTORS *

|  | ORG | \$1FF4 |
| :--- | :--- | :--- |
| * Interrupt Vectors |  |  |
| SRI_VEC | FDB | SPI_INT |
| SCI_VEC | FDB | SCI_INT |
| TIM_VEC | FDB | TIM_INT |
| IRQ_VEC | FDB | IRQ_INT |
| SWI_VEC | FDB | SWI_INT |
| RST_VEC | FDB | RST_INT |

## AN1091

# Low Skew Clock Drivers and their System Design Considerations 

Prepared by Chris Hanke, CMOS Design Engineer Gary Tharalson, CMOS/TTL Product Planning Manager


#### Abstract

Several varieties of clock drivers with 1 ns or less skew from output-to-output are available from Motorola. Micropro-cessor-based systems are now running at 33 MHz and beyond, and system clock distribution at these frequencies mandate the use of low skew clock drivers. Unfortunately, just plugging a high performance clock driver into a system does not guarantee trouble free operation. Only careful board layout and consideration of system noise issues can guarantee reliable clock distribution. This application note addresses these system design issues to help ensure that Motorola's low skew clock drivers are used effectively in a system environment.


## INTRODUCTION

With frequencies regularly reaching 33 MHz and approaching $40-50 \mathrm{MHz}$ in today's CISC and RISC microprocessor systems, well controlled and precise clock signals are required to maintain a synchronous system. Many microprocessors also require input clock duty cycles very close to $50 \%$. These stringent timing requirements mandate the use of specially designed, low skew clock distribution circuits or 'clock drivers.' However, just plugging one of these parts into your board does not ensure a trouble free system. Careful system and board design techniques must be used in conjunction with a low skew clock driver to meet system timing requirements and provide clean clock signals.

## Why are Low Skew Clock Drivers Necessary

An MPU system designer wants to utilize as much of a clock cycle as possible without adding unnecessary timing guardbands. Propagation delays of peripheral logic do not scale with frequency. Therefore, as the clock period decreases, the system designer has less time but the same logic delays to accomplish the function. How can he get more time? A viable option is to use a special clock source that minimizes clock 'uncertainty.'
A simple example illustrates this concept. At 33 MHz , $T_{\text {cycle }}=30 \mathrm{~ns}$. An FCT240A, for example, has a High-Low uncertainty of the $\mathrm{min} / \mathrm{max}$ spread of tPLH to $\mathrm{tPHL}^{2}$ of approximately 3.3 ns . If 1.7 ns of pin-to-pin skew due to the actual part and PCB trace delays is also considered, then only 25 ns of the clock period is still available. The worst case tp of clock-to-data valid on the 88200 M -Bus is 12 ns , which leaves only 13 ns to accomplish additional functions. In this case
$17 \%$ of a cycle is required for clock distribution or clock 'uncertainty,' which is an unacceptable penalty from a system designer's point of view. At 50 MHz this penalty becomes $25 \%$. A maximum of $10 \%$ of the period allotted for clock distribution is an acceptable standard.

If multiple levels of clock distribution (one clock driver's output feeding the inputs of several other clock drivers) are necessary due to large clock fan-outs, the additional part-topart skew variations add even more to the clock uncertainty. Standard logic has always been specified with a large (and conservative) delta between the minimum and maximum propagation delays. This delta creates the excessive amount of clock 'uncertainty' which the system designer has been forced to design into his system, even though it is not realistic. When system frequencies were below 16 MHz thís large clock penalty could be tolerated, but as the above example points out, not anymore. A clock driver's specs guarantee this min/ max delta to be a specific, small value. To reduce the clock overhead to managable levels, a clock driver with minimal variation ( $<5 \%$ ) from a $50 \%$ duty cycle and guaranteed low output-to-output and part-to-part skew must be used.

## DEFINITIONS

A typical clock driver has a single input which is usually driven by a crystal oscillator. The clock driver can have any number of outputs which have a certain frequency relationship to the clock input. Clock driver skew is typically defined by three different specs. These specs are graphically illustrated in Figure 1.
The first spec, tos, measures the difference between the fastest and slowest propagation delays (any transition) between the outputs of a single part. This number must be 1 ns or less for high-end systems.
The second, tpS, measures the difference between the high-to-low and low-to-high transition for a single output (pin). This spec defines how close to a $50 \%$ duty cycle the outputs of the clock driver will be. For example, if this spec is 1 ns ( $\pm 0.5 \mathrm{~ns}$ ), at 33 MHz the output duty cycle is $50 \% \pm 3.5 \%$. A clock driver which only buffers the crystal input, creating a 1:1 input to output frequency relationship, can be a problem if a very tight tolerance to a $50 \%$ duty cycle is required. In this situation the output duty cycle is directly dependent on the input duty cycle, which is not well controlled in most crystal oscillators. The clock driver's outputs switching at half the input frequency ( $\div 2$ ) is a common relationship, which means


Notes: 1) tPS measures tPLH-tPHL for any single output on a part.
2) tOS measures the maximum difference between any tPHL or tplH between any output on a single part.
3) tPV measures the maximum difference between any tPHL or tplH between any output on any part.

Figure 1. Timing Diagram Depicting Clock Skew Specs Within One Part and Between any Two Parts
that the outputs switch on only one edge of the oscillator, eliminating the output's dependence on the duty cycle of the input (crystal oscillator frequency is very stable).

The third spec, tPV. measures the maximum propagation delay delta between any given pin on any part. This spec defines the part to part variation between any clock driver (of the same device type) which is ever shipped. This number reflects the process variation inherent in any technology. For CMOS, this spec is usually 3 ns or less. High performance ECL technologies can bring this number down into the 1-2 ns range. Another way to minimize the part-to-part variation is to use a phase-locked loop clock driver, which are just now becoming available.

An important consideration when designing a clock driver into a system is that the skew specs described above are usually specified at a fixed, lumped capacitive load. In a real system environment the clock lines usually have various loads distributed over several inches of PCB trace which can contribute additional delay and sometimes act like transmission lines, so the system designer must use careful board layout techniques to minimize the total system skew. In other words. just plugging a low skew clock driver into a board will not solve all your timing problems.

## DESIGN CONSIDERATIONS

Figure 2 is a scale replication of a section of an actual 88000 RISC system board layout. The section shown in the figure includes the MC88100 MPU and the MC88200 CMMU devices and the MC88914 CMOS clock driver. The only PCB traces shown are the clock output traces from the MC88914 to the various loads. For this clock driver the output-to-output skew (tOS) is guaranteed to be less than 1 ns at any given temperature, supply voltage, and fixed load up to 50 pF .

In calculating the total system skew, the difference in clock PCB trace length and loading must be taken into account. For an unloaded PCB trace, the signal delay per unit length.
$t_{\text {pd }}$, is dependent only on the dielectric constant, $e_{r}$, of the board material. The characteristic impedance, $Z_{0}$, of the line is dependent upon $e_{r}$ and the geometry of the trace. These relationships are depicted in Figure 3 for a microstrip line. 1 The formulas for $t_{p d}$ and $Z_{0}$ are slightly different for other types of strip lines, but for simplicity's sake all calculations in this article will assume a microstrip line.

The equations in Figure 3 are valid only for an unloaded trace; loading down a line will increase its delay and lower its impedance. The signal propagation delay ( $t_{p d}$ ') and characteristic impedance ( $Z_{0}$ ) due to a loaded trace are calculated by the following formulas:

$$
\begin{gathered}
t_{p d}=t_{p d} \sqrt{1+\frac{C_{d}}{C_{0}}} \\
Z_{o^{\prime}}^{\prime}=\frac{Z_{0}}{\sqrt{1+\frac{C_{d}}{\mathrm{C}_{0}}}}
\end{gathered}
$$

$C_{d}$ is the distributed load capacitance per unit length, which is the total input capacitance of the receiving devices divided by the length of the trace. $\mathrm{C}_{\mathrm{O}}$ is the intrinsic capacitance of the trace, which is defined as:

$$
C_{0}=\frac{t p d}{Z_{0}}
$$

Assuming typical microstrip dimensions and characteristics as $w=0.01$ in., $t=0.002$ in., $h=0.012$ in., and $e_{r}=4.7$, the equations of Figure 3 yield $Z_{0}=69.4 \Omega$ and $t_{p d}=$ $0.144 \mathrm{~ns} / \mathrm{in} . \mathrm{C}_{\mathrm{O}}$ is then calculated as 2.075 pF in. If it is assumed that an MC88100 or 88200 clock input load is 15 pF , and that two of these loads, in addition to a 7 pF FAST TTL load, are distributed along a 9.6 in. clock trace, $\mathrm{C}_{\mathrm{d}}=$ $(2 \times 15+7) \mathrm{pF} / 9.6 \mathrm{in} .=3.85 \mathrm{pF} / \mathrm{in}$. The loaded trace propagation delay and characteristic impedance are then calculated as $\mathrm{t}_{\text {pd }}{ }^{\prime}=0.243 \mathrm{~ns} / \mathrm{in}$. and $\mathrm{Z}_{\mathrm{O}}{ }^{\prime}=41 \mathrm{\Omega}$.

Looking at trace c in Figure 2, the two MC88200's are approximately 3 inches apart. Using the calculated value of


Figure 2. Scale Representation of an Actual $\mathbf{8 8 0 0 0}$ System PCB Layout (only sections of the board related to the clock driver outputs are shown).
tpd'. the clock signal skew due to the trace is about 0.7 ns . Since these two devices are on the same trace, this is the total clock skew between these devices. Upon careful inspection of all the clock traces. it can be seen that clock signal skew was accounted for and minimized on this board layout. The longest distance between any 88 K devices on a single clock trace is about 4.5 inches. which translates to approximately 1.1 ns of skew. The two 88K devices farthest away from the clock driver (traces a and c). are located at almost


$$
\begin{aligned}
& Z_{0} \quad \frac{87}{\sqrt{e_{r} \cdot 1.41}} \ln \left(\frac{5.98 \mathrm{~h}}{0.8 w-t}\right) \\
& \mathrm{t}_{\mathrm{pd}} \quad 1.017 \backslash \overline{0.475 \mathrm{e}_{\mathrm{r}} \cdot 0.67 \mathrm{~ns} \mathrm{ft}}
\end{aligned}
$$

WHERE

$$
\begin{aligned}
e_{r} & \text { RELATIVE DIELECTRIC CONSTANT OF THE BOARD MATERIAL. } \\
w, h, i & =\text { DIMENSIONS INDICATED INA MICROSTRIP DIAGRAM. }
\end{aligned}
$$

Figure 3. Formulas for the Characteristic Impedance and Propagation Delay of a Microstrip Line. (Ref. 1)
exactly the same distance along their respective traces, making the clock skew between them the 1 ns guaranteed from output to output of the clock driver. This means that the worst case clock skew between any two devices on this board is approximately 2.1 ns , which at 33 MHz is $7 \%$ of the period. Without careful attention to matching the clock traces on the board, this number could easily exceed 3 ns and the $10 \%$ cut-off point, even if a low skew clock driver is used.

## CLOCK SIGNAL TERMINATIONS

Transmission line effects occur when a large mismatch is present between the characteristic impedance of the line and the input or output impedances of the receiving or driving device. The basic guidelines used to determine if a PCB trace needs to be examined for transmission line effects is that if the smaller of the driving device's rise or fall time is less than three times the propagation delay of a switching wave through a trace, the transmission line effects will be present. ${ }^{2}$ This relationship can be stated in equation form as: 3

$$
3 \times t_{p d} \times \text { trace length } \leqslant t_{\text {RISE }} \text { or } t_{\text {FALL }}
$$

For the MC88914 CMOS clock driver described in this article, rise and fall times are typically 1.5 ns or less (from $20 \%$ to $80 \%$ of $\mathrm{V}_{\mathrm{C}}$ ). Analyzing the clock trace characteristics presented earlier for transmission line effects, $3 \times 0.243 \mathrm{~ns} / \mathrm{in}$. $x$ trace length $\leqslant 1 \mathrm{~ns}$ ( 1 ns is used as 'fastest' rise or fall time). Therefore the trace length must be less than 1.5 inches for the transmission line effects to be masked by the rise and fall times.

Figure 4 shows the clock signal waveform seen at the receiver end of an unterminated 0.5 inch trace and an unterminated 9 inch trace. These results were obtained using SPICE simulations, which may not be exact, but are adequate to predict trends and for comparison purposes. The 9 inch trace, which is well beyond the 1.5 inch limit where transmission line effects come into play, exhibits unacceptable switching characteristics caused by reflections going back and forth on the trace. Even the 0.5 inch line exhibits substantial overshoot and undershoot. Any unterminated line will exhibit some overshoot and undershoot at these edge rates.

Clock lines shorter than 1-1.5 inches are unrealistic on a practical board layout, therefore it is recommended that CMOS clock lines be terminated if the driver has 1-2 ns edge rates. Termination, which is used to more closely match the line to the load or source impedances, has been a fact of life in the ECL world for many years (reference 1 is an excellent source for transmission line theory and practice in ECL systems), but CMOS and TTL devices have only recently reached the speeds and edge rates which require termination. CMOS outputs further complicate the issue by driving
a. Unterminated 0.5 Inch, 41 § $\mathbf{\Omega}$ Transmission Line

b. Unterminated 9 Inch, $41 \Omega$ Transmission Line


Figure 4. SPICE Simulation Results of 'Short' and 'Long' Transmission Lines. Simulations were Run with Typical Parameters (a $25^{\circ} \mathrm{C}$ and $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}$.
from rail to rail ( 5 V ), with slew rates exceeding those of high performance ECL devices.

Since clock lines are only driven from a single location, they lend themselves to termination more easily than bus lines which are commonly driven from multiple locations. Termination of bus lines with multiple drivers is a complicated matter which will not be addressed in this article. The most common types of termination in digital systems are shown in Figure 5. Since no single termination scheme is optimal in all cases, the tradeoffs involving the use of each will be discussed, and recommendations specific to clock drivers will be made. Reference 2 is a comprehensive and practical treatment of transmission line theory and analysis of CMOS signals, and is recommended reading for those who want to gain a better understanding of transmission lines. Figure 6 shows SPICE simulated waveforms of the different termination schemes to be discussed. The driving device in the simulations was the MC88914 output buffer; in all simulations it drove a 9 inch $41 \Omega 2$ transmission line. The simulations were run using typical model parameters at $25^{\circ} \mathrm{C}$ and $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}$.

Series termination, depicted in Figure 5b, is recommended if the load is lumped at the end of the trace and the output impedance of the driving device is less than the loaded characteristic impedance of the trace, or when a minimum number of components is required. The main problem with series termination occurs when the driving device has different output impedance values in the low and high states, which is a problem in TTL and some CMOS devices. A well designed CMOS clock driver should have nearly equal output impedances in the high and low states, avoiding this problem. An additional advantage is that series termination does not create a DC current path, thus the $\mathrm{V}_{\mathrm{OL}}$ and $\mathrm{V}_{\mathrm{OH}}$ levels are not degraded. The SPICE generated waveforms of series termination in Figure 6a show that series termination effectively masks the transmission line effects exhibited in Figure 4. If each clock output is driving only one device, series termination would be recommended, but this is not a realistic case in most systems, so series termination is not generally recommended for termination of clock lines.

Parallel termination utilizes a single resistor tied to ground or $\mathrm{V}_{\mathrm{CC}}$ whose value is equal to the characteristic impedance of the line. Its major disadvantage is the DC current path it creates when the driver is in the high state (if the resistor is tied to ground). This causes excessive power dissipation and $\mathrm{V}_{\mathrm{OH}}$ level degradation. Since a clock driver output is always switching, the DC current draw argument loses some credibility at higher frequencies because the $A C$ switching current becomes a major component of the overall current. Therefore the main consideration in parallel termination is how much $\mathrm{V}_{\mathrm{OH}}$ degradation can be tolerated by the receiving devices. Figure 6 b demonstrates that this termination technique is effective in minimizing the switching noise, but Thevenin termination has some advantages over parallel termination.

Thevenin termination utilizes one resistor tied to ground and a second tied to $\mathrm{V}_{\mathrm{CC}}$. An important consideration when using this type of termination is choosing the resistor values to avoid settling of the voltage between the high and low logic levels of the receiving device. ${ }^{2}$ TTL designers commonly use a $220 / 330$ resistor value ratio, but CMOS is a little tricky because the switch point is at $\mathrm{V}_{\mathrm{CC}} / 2$. With a $1: 1$ resistor ratio a failure at the driver output would cause the line to settle at
2.5 V, causing system debug problems and also potential damage to the receiving devices.
In Thevenin termination, the parallel equivalent value of the two resistors should be equal to the characteristic impedance of the line. A DC path does exist in both the high and low states, but it is not as bad as parallel termination because the resistance in the Thevenin DC path is at least 2 times greater. Figure 6 c shows the termination waveforms, which exhibit characteristics similar to parallel termination, but with less VOH degradation. The only real advantage of parallel over Thevenin is less resistors ( $1 / 2$ as many) and less space taken up on the board by the resistors. If this is not a factor, Thevenin termination is recommended over parallel.

AC termination, shown in Figure 5e, normally utilizes a resistor and capacitor in series to ground. The capacitor blocks DC current flow, but allows the AC signal to flow to ground during switching. The RC time constant of the resistor and capacitor must be greater than twice the loaded line delay. AC termination is recommended because of its low power dissipation and also because of the availability of the resistor and capacitor in single-in-line packages (SIP). A pullup resistor to $\mathrm{V}_{\mathrm{CC}}$ is sometimes added to set the DC level at a certain point because of the failure condition described in regards to Thevenin termination. As discussed earlier, the argument of lower DC current is less convincing at high frequencies. The AC terminated waveform walks out slightly toward the end of a high-to-low or low-to-high transition as seen in Figure 6d, making it slightly less desirable than Thevenin termination.


## a. Transmission Line with No Termination


c. Transmission Line with Parallel Termination

e. Transmission Line with AC Termination

Thevenin and AC termination are the two recommended termination schemes for clock lines, but it depends on what frequency the clock is running at when making a decision between these types of termination. Although hard data is not provided to back this statement up, it is a safe assumption that at frequencies of 25 MHz and below $A C$ is the best choice. If the system frequency could reach 40 MHz and beyond, Thevenin becomes the better choice.

## Additional Considerations when Terminating Clock Lines

The results presented might imply that terminating the clock lines will completely solve noise problems, but termination can cause secondary problems with some logic devices. Termination acts to reduce the noise seen at the receiver, but that noise actually is seen as additional current and noise at the output of the driving device. If the internal and input logic on the source device is not sufficiently decoupled on chip from the high current outputs, internal threshold problems can occur. This phenomenon is commonly known as dynamic threshold.' It is usually evidenced by glitches appearing on the outputs of a fast, high current drive logic device as it switches high or low. This is most severe on 'ACT' devices which have high current and high slew rate CMOS outputs along with TTL inputs which have low noise immunity. This problem can be minimized by decoupling the internal ground and VCC supplies on-chip and in the package. This decoupling is accomplished by having separate 'quiet' ground and $V_{C C}$ pads on chip which supply the input circuitry's ground


WHERE, $Z_{d}=$ DRIVING DEVICE OUTPUT IMPEDANCE
b. Transmission Line with Series Termination

d. Transmission Line with Thevenin Termination

Figure 5. Schematic Representations of Common
Termination Techniques
and $\mathrm{V}_{\mathrm{CC}}$ references. These pads are then tied to extra 'quiet' ground and 'quiet' VCC pins on the package, or to special 'split leads' which resemble a tuning fork and utilize the leadframe inductance to accomplish the decoupling. When choosing a clock source, make sure that the part has one of these decoupling schemes.

## References

1. Blood, William R., MECL System Design Handbook, Motorola Inc., 1983.
2. Appl. Note AN1051, Transmission Line Effects in PCB Applications, Motorola Inc., 1990.
3. Motorola FACT Data Book DL138, Motorola Inc., 1990


Figure 6. SPICE Simulation Results for Various Terminations of a 9 Inch, $41 \Omega$ Transmission Line.
Simulations were Run With Typical Model Parameters a $25^{\circ} \mathrm{C}$ and $\mathrm{V}_{\mathrm{CC}}=5.0 \mathrm{~V}$.

# Calibration-Free Pressure Sensor System 

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## INTRODUCTION

The MPX2000 Series of pressure transducers are semiconductor devices which give an electrical output signal proportional to the applied pressure. The sensors are a single monolithic silicon diaphragm with strain gage and thin-film resistor networks on the chip. Each chip is laser trimmed for full scale output, offset and temperature compensation.
The purpose of this document is to describe another method of measurement which should facilitate the life of the designer. The MPX2000 Series sensors are available as unported elements and as ported assemblies suitable for pressure, vaccum and differential pressure measurements in the range of 10 kPa through 200 kPa .
The use of the on-chip A/D converter of Motorola's MC68HC05B6 HCMOS MCU makes possible the design of an accurate and reliable pressure measurement system.

## SYSTEM ANALYSIS

The measurement system is made up of the pressure sensor, the amplifiers and the MCU. Each element in the chain has their own device-to-device variations and temperature effects which should be analyzed separately. For instance, the 8 -bit A/D converter has a quantization error of about $\pm 0.2 \%$. This error should be subtracted from the maximum error specified for the system to find the available error for the rest of elements in the chain. The MPX2000 Series pressure sensors are designed to provide an output sensitivity of $4.0 \mathrm{mV} / \mathrm{V}$ excitation voltage with full-scale pressure applied or 20 mV at the excitation voltage of 5.0 Vdc .
An interesting property must be considered to define the configuration of the system, the ratiometric function of both the A/D converter and the pressure sensor device. The ratiometric function of these elements make all voltage variations from the power supply rejected by the system. With this advantage, it is possible to design a chain of amplification where the signal is conditioned in a different way.


Figure 1. Seven Laser-Trimmed Resistors and Two Thermistors Calibrate the Sensor for Offset, Span, Symmetry and Temperature Compensation.

The OP-AMP configuration should have a good common-mode rejection ratio to cancel the DC component voltage of the pressure sensor element which is about half the excitation voltage value $\mathrm{V}_{\mathrm{S}}$. Also, the OPAMP configuration is important when the designer's objective is to minimize the calibration procedures which cost time and money and often don't allow the unit-tounit replacement of devices or modules.
One other aspect is that most of the applications are not affected by inaccuracy in the region 0 kPa thru 40 kPa . Therefore, the goal is to obtain an acceptable tolerance of the system from 40 kPa thru 100 kPa thus minimizing the inherent offset voltage of the pressure sensor.

## PRESSURE SENSOR CHARACTERISTIC

Figure 2 shows the differential output voltage of the MPX2100 series at $+25^{\prime \prime}$ C. The dispersion of the output voltage determines the best tolerance that the system may achieve without undertaking a calibration procedure, if any other elements or parameters in the chain do not introduce additional errors.


Figure 2. Spread of the Output Voltage versus the Applied Pressure at $25^{\circ} \mathrm{C}$

The effects of temperature on the full scale output and offset are shown in Figure 3. It is interesting to notice that the offset variation is greater than the full scale output and both have a positive temperature coefficient respectively of $+8.0 \mu \mathrm{~V}$ degree and $+5.0 \mu \mathrm{~V}$ degree at 5.0 V excitation voltage. That means that the full scale variation may be compensated by modifying the gain somewhere in the chain amplifier by components arranged to produce a negative $\mathrm{T}_{\mathrm{C}}$ of 250 PPM C . The dark area of Figure 3 shows the trend of the compensation which improves the full scale value over the temperature range. In the area of 40 kPa , the compensation acts in the ratio of 40100 of the value of the offset temperature coefficient.


Figure 3. Output Voltage versus Temperature. The Dark Area Shows the Trend of the Compensation.

## OP-AMP CHARACTERISTICS

For systems with only one power supply, the instrument amplifier configuration shown in Figure 4 is a good solution to monitor the output of a resistive transducer bridge.
The instrument amplifier does provide an excellent CMRR and a symmetrical buffered high input impedance at both non-inverting and inverting terminals. It minimizes the number of the external passive components used to set the gain of the amplifier. Also, it is easy to compensate the temperature variation of the Full Scale Output of the Pressure Sensor by implementing resistors " $\mathrm{Rf}_{\mathrm{f}}$ " having a negative coefficient temperature of -250 PPM ${ }^{\circ}$ C.
The differential-mode voltage gain of the instrument amplifier is:

$$
\begin{equation*}
A v d=\frac{V 1-V 2}{V s 2-V_{s} 4}=\left(1+\frac{2 R_{f}}{R_{g}}\right) \tag{1}
\end{equation*}
$$



Figure 4. One Power Supply to Excite the Bridge and to Develop a Differential Output Voltage

The major source of errors introduced by the OP-AMP are offset voltages which may be positive or negative and the input bias current which develops a drop voltage $\Delta V$ through the feedback resistance $R_{f}$. When the OP-AMP input is composed of PNP transistors, the whole characteristic of the transfer function is shifted below the DC component voltage value set by the Pressure Sensor as shown in Figure 5.
The gain of the instrument amplifier is calculated carefully to avoid a saturation of the output voltage and to provide the maximum of differential output voltage available for the A.D Converter. The maximum output swing voltage of the amplifiers is also dependent on the bias current which creates a $\Delta V$ voltage on the feedback resistance $R_{f}$ and on the Full Scale output voltage of the pressure sensor.


Figure 5. Instrument Amplifier Transfer Function with Spread of the Device to Device Offset Variation

Figure 5 also shows the transfer function of different instrument amplifiers used in the same application. The same sort of random errors are generated by crossing the inputs of the instrument amplifier. The spread of the differential output voltage ( $\mathrm{V} 1-\mathrm{V} 2$ ) and ( $\mathrm{V} 2 \mathrm{x}-\mathrm{V} 1 \mathrm{x}$ ) is due to the unsigned voltage offset and its absolute value. Figures 6 and 7 show the unit-to-unit variations of both the offset and the bias current of the dual OP-AMP MC33078.


Figure 6. Input Offset Voltage versus Temperature

To realize such a system, the designer must provide a calibration procedure which is very time consuming. Some extra potentiometers must be implemented for setting both the offset and the Full Scale Output with a complex temperature compensation network circuit.
The new proposed solution will reduce or eliminate any calibration procedure.


Figure 7. Input Bias Current versus Temperature

## MCU CONTRIBUTION

As shown in Figure 5, crossing the instrument amplifier inputs generated their mutual differences which can be computed by the MCU.


Figure 8. Crossing of the Instrument Amplifier Inputs Using a Port of the MCU

Figure 8 shows the analog switches on the front of the instrument amplifier and the total symmetry of the chain. The residual resistance RDS(on) of the switches does not introduce errors due to the high input impedance of the instrument amplifier.
With the aid of two analog switches, the MCU successively converts the output signals $\mathrm{V} 1, \mathrm{~V} 2$.

Four conversioris are necessary to compute the final result. First, two conversions of V1 and V2 are executed and stored in the registers R1, R2. Then, the analog switches are commuted in the opposite position and the two last conversions of V 2 x and V 1 x are executed and stored in the registers R2x and R1x. Then, the MCU computes the following equation:

$$
\begin{equation*}
\text { RESULT }=(\mathbf{R} 1-R 2)+(R 2 x-R 1 x) \tag{2}
\end{equation*}
$$

The result is twice a differential conversion. As demonstrated below, all errors from the instrument amplifier are cancelled. Other averaging techniques may be used
to improve the result, but the appropriated algorithm is always determined by the maximum bandwidth of the input signal and the required accuracy of the system.


Figure 9. Two Channel Inputs and One Output Port are Used by the MCU

## SYSTEM CALCULATION

Sensor out 2
$\mathrm{Vs} 2=a(P)+o f 2$
Amplifier out 1
$\mathrm{V} 1=\operatorname{Avd}(\mathrm{Vs} 2+\mathrm{OF} 1)$
Inverting of the amplifier input
$\mathrm{V} 1 \mathrm{x}=\mathrm{Avd}(\mathrm{Vs} 4+\mathrm{OF} 1) \quad \mathrm{V} 2 \mathrm{x}=\mathrm{Avd}(\mathrm{Vs} 2+\mathrm{OF} 2)$
Delta $=\mathrm{V} 1-\mathrm{V} 2 \quad$ 1st differential result
$=A v d *(V s 2$ of OF1) - Avd $*(V s 4+O F 2)$
Deltax $=\mathrm{V} 2 \mathrm{x}-\mathrm{V} 1 \mathrm{x} \quad$ 2nd differential result
$=$ Avd $*(V s 2+O F 2)-$ Avd $*(V s 4+O F 1)$
Adding of the two differential results
VoutV = Delta + Deltax
$=A v d * V s 2+A v d * V s 2-A v d * V s 4-A v d * V s 4$

+ Avd*OF1 - Avd*OF2 + Avd*OF2 - Avd*OF1
$=2 * \operatorname{Avd} *(\mathrm{Vs} 2-\mathrm{Vs} 4)$
$=2 * \operatorname{Avd} *[(a(P)+o f 2)-(b(P)+o f 4)]$
$=2 *$ Avd $*[V(P)+$ Voffset $]$
There is a full cancellation of the amplifier offset OF1 and OF2. The addition of the two differential results V1-V2 and V 2 x - V 1 X produce a virtual output voltage VoutV which becomes the applied input voltage to the $A / D$ converter. The result of the conversion is expressed in the number of counts or bits by the ratiometric formula shows below:

$$
\text { count }=\text { VoutV } * \frac{255}{\text { VRH-VRL }}
$$

255 is the maximum number of counts provided by the A/D converter and VRH-VRL is the reference voltage of the ratiometric ADD converter which is commonly tied to the 5.0 V supply voltage of the MCU.

When the tolerance of the full scale pressure has to be in the range of $\pm 2.5 \%$, the offset of the pressure sensor may be neglected. That means the system does not require any calibration procedure.

The equation of the system transfer is then:
count $=2 *$ Avd $* V(P) * 51 \mathrm{~V}$ where:
Avd is the differential-mode gain of the instrument amplifier which is calculated using the equation (1). Then with $R_{f}=510 \mathrm{k} \Omega$ and $R_{g}=9.1 \mathrm{k} \Omega \mathrm{Avd}=113$.
The maximum counts available in the MCU register at the Full Scale Pressure is:
count (Full Scale) $=2 * 113 * 0.02 \mathrm{~V} * 51 \mathrm{~V}=\underline{230}$
knowing that the MPX2100AP pressure sensor provides 20 mV at 5.0 V excitation voltage and 100 kPa full scale pressure.

The system resolution is 100 kPa 230 that give 0.43 kPa per count.


Figure 10. Full Scale Output Calibration Using the Reference Voltage VRH-VRL

When the tolerance of the system has to be in the range of $\pm 1 \%$, the designer should provide only one calibration procedure which sets the Full Scale Output (counts) at
$25^{\circ} \mathrm{C} 100 \mathrm{kPa}$ or under the local atmospheric pressure conditions.


Figure 11. One Channel Input and Two Output Ports are used by the MCU

Due to the high impedance input of the A D converter of the MC68HC05B6 MCU, another configuration may be implemented which uses only one channel input as shown in Figure 11. It is interesting to notice that practically any dual OP-AMP may be used to do the job but a global consideration must be made to optimize the total cost of the system according to the requested specification.
When the Full Scale Pressure has to be set with accuracy, the calibration procedure may be executed in different ways.
For instance, the module may be calibrated directly using Up Down push buttons.
The gain of the chain is set by changing the VRH voltage of the ratiometric A D converter with the $R 2 R$ ladder network circuit which is directly drived by the ports of the MCU. (See Figure 12.)

Using a communication bus, the calibration procedure may be executed from a host computer. In both cases, the setting value is stored in the EEROM of the MCU.

The gain may be also set using a potentiometer in place of the resistor $R_{\mathrm{f}}$. But, this component is expensive, taking into account that it must be stable over the temperature range at long term.

PRESSURE CONVERSION TABLE

| Unity | Pa | mbar | Torr | atm | at $=\mathbf{k p / c m}{ }^{2}$ | mWs | psi |
| :--- | :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $1 \mathrm{~N} \mathrm{~m}^{2}=1$ Pascal | 1 | 0.01 | $7.5100^{3}$ | - | - | - | - |
| 1 mbar | 100 | 1 | 0.75 | - | - | 0.0102 | 0.014 |
| $1 \mathrm{Torr}=1 \mathrm{mmHg}$ | 133.32 | 1.333 | .1 | - | - | - | 0.019 |
| $1 \mathrm{~atm}(1)$ | 101325 | 1013.2 | 760 | 1 | 1.033 | 10.33 | 14.69 |
| 1 at $=1 \mathrm{kp} \mathrm{cm}$ |  |  |  |  |  |  |  |
| 1 m of water | 98066.5 | 981 | 735.6 | 0.97 | 1 | 10 | 14.22 |
| 1 lb sqin $=1 \mathrm{psi}$ | 9806.65 | 98.1 | 73.56 | 0.097 | 0.1 | 1 | 1.422 |

(1) Normal atmosphere (2) Technical atmosphere
(1) Normal atmosphere (2) Technical atmosphere


Figure 12.

# AN1102 

# Interfacing Power MOSFETs to Logic Devices 

Prepared by Ken Berringer Motorola Discrete Applications

## POWER MOSFET DRIVE CHARACTERISTICS

Power MOSFETs are commonly used in switching applications due to their fast switching speeds and low static losses. When driven with sufficient gate voltage, a power MOSFET will turn on and have a very low on-resistance. If the gate voltage is insufficient to bias the Power MOSFET fully on, or excessive drain currents are applied, the power MOSFET will operate in the saturation (pinch-off) region. In other words, a certain gate voltage will support only a limited amount of drain current.

Most of the current crop of fourth generation power MOSFETs require 10 volts of gate drive to support their maximum continuous drain current. This means that 5 volt logic will not provide enough voltage to drive a standard power MOSFET. A new family of Logic Level power MOSFETs are now available that can support their rated drain current with a gate voltage of 5 volts. With the proper considerations, these power MOSFETs may be easily interfaced to most logic families.

Design of the MOSFET's gate drive is dependent on the MOSFET's input capacitance, which is strongly affected by die size. Therefore, selecting the correct device for the application not only minimizes component cost, but it also optimizes switching performance. Static, or DC, losses are determined by the power MOSFET's on-resistance RDS(on), which is a function of junction temperature ( $T_{J}$ ), gate voltage ( $\mathrm{V}_{\mathrm{GS}}$ ), and drain current (ID). RDS(on) is typically specified at ID equal to half the rated drain current, a $V_{G S}$ of 10 volts, and junction temperatures of 25 and $100^{\circ} \mathrm{C}$.

The power MOSFET's static losses can be easily calculated in DC or pulsed applications. First, correct the rated RDS(on) for your drain current and estimated operating temperature with the help of the manufacturers' data sheet curves. Then multiply this value times the RMS load current squared [ $P_{\text {static }}$ $=1$ rms ${ }^{2}$ RDS(on)]. You should choose a power MOSFET with a current rating (ID) and voltage rating (VDSS) well above your worst case load conditions. A good rule of thumb is to select a device with twice your worst case RMS drain current and a voltage rating $25 \%$ above your worst case drain voltage.

In high frequency applications switching losses are often more significant than static losses. To minimize switching losses you must decrease the switching times. When a power MOSFET is used in switching applications, the gate cannot be modeled as a simple capacitor due to sizable displacement currents in $\mathrm{C}_{\text {rss }}$, the drain-to-gate capacitor, brought on by large swings in drain-to-gate voltage. As a result, the total input capacitance, $\mathrm{C}_{\text {iss }}$, varies greatly over the power MOSFET's operating range. $\mathrm{C}_{\text {iss }}$ can be piecewise modeled as a linear
capacitor in order to find first order approximations of switching times.

A better method of calculating switching times is to use gate charge data from the manufacturers' data sheet. Although a power MOSFET is usually thought of as a voltage controlled device, it can be accurately modeled as a charge controlled device. The charge required for a power MOSFET to handle a given current is relatively constant even though its drain-to-gate capacitance ( $\mathrm{C}_{\mathrm{rss}}$ ) varies drastically with drain-to-gate voltage. The value of $\mathrm{C}_{\text {rss }}$ may increase $1000 \%$ or more over the operating range.


Figure 1. Driving a Power MOSFET with a Constant Current Source

When a power MOSFET is driven by a current source as in Figure 1, its gate voltage will be nearly piecewise linear as shown in Figure 2. The three distinct regions are turn on delay ( $t_{0}$ to $t_{1}$ ), rise time ( $t_{1}$ to $t_{2}$ ), and excess charge time ( $t_{2}$ to $t_{3}$ ). At the end of the turn on delay ( $\mathrm{t}_{1}$ ) the power MOSFET begins to conduct but the drain current is still very small. During the rise time the power MOSFET actually turns on and the drain voltage drops to almost zero. The resistive switching rise time trise is actually measured as the time it takes for the drain voltage to drop from $90 \%$ to $10 \%$ of its highest value. It is called rise time referring to the drain current rise time although the voltage is what's usually measured. This time corresponds to the time that $\mathrm{V}_{\mathrm{GS}}$ remains in the plateau region of Figure 2.


Figure 2. Gate-to-Source Voltage versus Time for a Current Source Turning On a Power MOSFET

During the excess charge time ( $\mathrm{t}_{2}$ to $\mathrm{t}_{3}$ ) $\mathrm{RDS}_{\mathrm{D}}(\mathrm{on})$ continues to decrease. This excess charge must be removed during the turn off delay, so driving the gate to an unnecessarily high voltage will increase the total turn off time.

Unlike bipolar transistors, power MOSFETs are majority carrier devices. Without minority injection, power MOSFETs can be turned off just as easily as they are turned on. For identical gate drive currents, rise time will equal fall time. The turn off waveform for a constant gate current will be a mirror image of Figure 2. Note that the turn off delay does not equal turn on delay, it instead corresponds to the turn on excess charge time.

Since the gate current in Figure 2 is constant and equal to the charge per unit time, the horizontal axis can be labeled time or charge. Gate charge data is usually measured using a 1 mA current source which means it will provide 1 nC (nanoColoumb) of charge in $1 \mu \mathrm{~s}$. Manufacturers' dafa sheets usually include a gate charge chart of $V_{G S}$ vs $Q_{g}$ with $Q_{g}$ labeled in nC as in Figure 3. It is important to note that the value of $\mathrm{V}_{\mathrm{GS}}$ during rise time, also called the plateau voltage, increases with ID and therefore so does the turn on delay. Also, the amount of charge needed for rise time will vary with the drain supply voltage. This is usually indicated on the gate charge chart by multiple lines for the excess charge region labeled with the corresponding $\mathrm{V}_{\mathrm{DS}}$.

To determine the switching times using a current source to drive a Power MOSFET, find the charge required for each region using the gate charge chart, Figure 3, and then use the simple equation:

$$
\begin{equation*}
\mathrm{t}=\mathrm{Q}_{\mathrm{g}} / \mathrm{I} \mathrm{G} \tag{1}
\end{equation*}
$$

First find the charge required during the turn on delay region, $Q_{d(o n)}$, by drawing a line down from the first inflection point to the horizontal axis of Figure 3. This is the gate charge for the rated or tested $\mathrm{I}_{\mathrm{D}}$. If your actual drain current is different than the rated current you may improve accuracy by linearly scaling $Q_{d(o n)}$. Now calculate the turn on delay using Equation 1. Next find the gate charge required for rise time ( $Q_{\text {rise }}$ ) from the gate charge chart as the distance between the first inflection point and the intersection of the plateau with the line for your expected VDS. A typical value is sometimes listed as $Q_{g d}$. This value may be used to calculate both rise and fall times. Next find the intersection point of your maximum $\mathrm{V}_{\mathrm{GS}}$ and the line corresponding to your $V_{D S}$. This is the total gate charge $\mathrm{Q}_{\mathrm{g} \text { (total). To find the charge required for turn off delay }} \mathrm{Q}_{\mathrm{d} \text { (off) }}$ (and turn on excess charge), subtract $Q_{d}(o n)$ and $Q_{\text {rise }}$ from $\mathrm{Q}_{\mathrm{g} \text { (total) }}$. A maximum total gate charge $\mathrm{Q}_{\mathrm{g}(\max )}$ is often specified to facilitate worst case design, however this figure sometimes includes a substantial guard-band.

When driving a power MOSFET with a voltage source with a series resistance (Thevenin source), the calculations are a little more complex. During the rise and fall times $\mathrm{V}_{\mathrm{GS}}$ is relatively constant since all the gate current is used to charge the gate-to-drain capacitor. By Ohm's law, IG is therefore also constant and the gate charge chart can be used with Equation 1 to find rise and fall times. During turn on the voltage across the series resistance is the effective source voltage (usually the supply voltage) minus the gate-to-source plateau voltage, $V_{G S P}$. During turn off the voltage across the resistor is the plateau voltage minus the effective sink voltage (usually ground). Rise and fall times will therefore typically be different.

Using this information with Equation 1, we can obtain equations for rise and fall time.
and fall time:

$$
\begin{equation*}
t_{\text {rise }}=\frac{Q_{g}}{l_{G}}=\frac{Q_{g d} R_{\text {eff }}(O N)}{V_{S O U R C E}-V_{G S P}} \tag{2}
\end{equation*}
$$

$$
\begin{equation*}
t_{\text {fall }}=\frac{Q_{\mathrm{g}}}{I_{G}}=\frac{Q_{\mathrm{gd}} R_{\text {eff( }}(\mathrm{OFF})}{V_{\mathrm{GSP}}-V_{\text {SINK }}} \tag{3}
\end{equation*}
$$

$V_{G S P}$ is the Power MOSFET's gate-to-source plateau voltage, $V_{\text {source }}$ is the gate driver's effective source voltage, $V_{\text {sink }}$ is the gate driver's effective sink voltage, and $R_{\text {eff }}$ is the gate driver's effective resistance (output resistance). During turn off $\mathrm{V}_{\text {sink }}$ may be near zero volts or even a negative voltage.


Figure 3. Gate Charge Chart for the MTP3055E
During the turn on and turn off delays gate current is not constant and gate charge data cannot be used to determine switching speeds. The series resistance and the gate capacitance form a simple RC network; however, the capacitance varies greatly over the operating range. To find the switching times you must determine the capacitance for each region from a capacitance chart like Figure 4. During the turn on delay $\mathrm{V}_{\mathrm{DS}}$ is near its maximum value, $\mathrm{V}_{\mathrm{GS}}$ is near zero, and the input capacitance is low. Find the value of $C_{\text {iss }}$ in the capacitance curve for your maximum value of $V_{D S}$ and use this capacitance, Point A in Figure 4, to calculate the turn on delay. You can use Equation 4 to approximate the turn on delay time.
$t_{d}(O N)=R_{\text {eff }}(O N) C_{\text {iss }}$ (MIN) $\ln \left[\frac{V_{\text {SOURCE }}}{V_{\text {SOURCE }}-V_{G S P}}\right]$
During the turn off delay $\mathrm{V}_{D S}$ will be low and $\mathrm{C}_{\text {iss }}$ will have a larger value. Find the value of $\mathrm{C}_{\text {iss }}$ corresponding to minimum $\mathrm{V}_{\mathrm{DS}}$ and maximum $\mathrm{V}_{\mathrm{GS}}$, Point B on the capacitance chart. Then use Equation 5 to approximate turn off delay time.
$t_{d}(O F F)=R_{\text {eff }}(O F F) C_{\text {iss }}(M A X) \ln \left[\frac{V_{G(M A X)}-V_{\text {SINK }}}{V_{G S P}-V_{S I N K}}\right]$
$\mathrm{V}_{\mathrm{G}(\max )}$ is the initial gate voltage prior to turn off (usually the supply voltage), $\mathrm{Reff}^{\text {(off) }}$ is the effective series resistance during turn off, and $V_{\text {sink }}$ is the effective sink voltage. If $\mathrm{V}_{\text {sink }}$ is at ground, then the $\mathrm{V}_{\text {sink }}$ terms will drop out of Equation 5.


Figure 4. Capacitance Chart for the MTP3055E
Note that the gate charge chart and capacitance curves are related. The slope of the line in the gate charge chart is in volts per nano-Coloumb. A Farad of capacitance is equal to a Coloumb per volt.

I(coulomb/sec) = C dV/dt(Farad-volts/sec).
From this equation, you find that

## Farad = coulomb/volt.

Therefore, the reciprocal of the slope is the input capacitance in nano-Farads ( 1000 pF ). However, you should use both charts. The gate charge chart is most useful when the input capacitance varies and the gate current is constant (rise and fall times). The capacitance curve is most useful when the input capacitance is constant and the gate current varies (delay times).

## DIRECT INTERFACE TO STANDARD POWER MOSFETS

Standard power MOSFETs can be interfaced directly with standard CMOS devices, such as the MC14000 family. This family uses complementary N and P channel FETs for the output stage. Although standard outputs are rated at $\pm 10 \mathrm{~mA}$ and buffer outputs are rated at $\pm 45 \mathrm{~mA}$, saturation currents for short circuit conditions are much higher. While a CMOS gate should not be short circuited for long periods of time, it may be safely operated in the saturation region when switching large capacitive loads. A 14049 UB inverter buffer can typically source 30 mA and sink 120 mA using a 12 volt supply. If the


Figure 5. Standard CMOS Interface Circuit
output current is not limited, the CMOS gate's output will act like a current source. If the output current is limited to less then the saturation currents, the CMOS gate's output will act like a voltage source with a finite output resistance. The MC14000 series family will operate from 3 to 18 volts. The common 12 or 15 volt VDD supply will drive Power MOSFETs nicely.
The 14049UB can be connected directly to a standard power MOSFET such as the MTP3055E as in Figure 5. The MTP3055E is a rugged $12 \mathrm{amp}, 60$ volt power MOSFET that is very popular in the industry. The gate drive current is not limited by a series resistor and therefore the gate drive current will be equal to the 14049's output saturation currents of $+30 /-120$ mA . Using the gate charge data with Equation 1, we can predict the following switching times.

$$
\begin{gathered}
\mathrm{t}_{\mathrm{d}(\mathrm{ON})}=2 \mathrm{nC} / 30 \mathrm{~mA}=67 \mathrm{nsec} \\
\mathrm{t}_{\text {rise }}=4 \mathrm{nC} / 30 \mathrm{~mA}=133 \mathrm{nsec} \\
\mathrm{t}_{\mathrm{d}(\mathrm{OFF})}=6 \mathrm{nC} / 120 \mathrm{~mA}=50 \mathrm{nsec} \\
\mathrm{t}_{\text {fall }}=4 \mathrm{nC} / 120 \mathrm{~mA}=33 \mathrm{nsec}
\end{gathered}
$$

The switching times were measured using the circuit in Figure 5. The actual scope waveforms are shown in Figure 6, and the measured switching times are shown in Table 1.

## Table 1. Switching Times for Standard CMOS Devices Driving an MTP3055E <br> ID = 6 Amps One gate used unless noted

| Driver | $\begin{gathered} \text { Vcc } \\ \text { (Volts) } \end{gathered}$ | $\mathbf{R}_{\mathbf{G}}$ <br> ( $\Omega$ ) | $t_{d}$ (on) ( ns ) | trise ( ns ) | $t_{d}$ (off) (ns) | $t_{\text {fall }}$ (ns) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 4049UB | 12 | 0 | 50 | 150 | 60 | 50 |
| 4049UB | 12 | 220 | 60 | 300 | 200 | 150 |
| 4049UB | 12 | 470 | 100 | 400 | 400 | 300 |
| 4049UB | 15 | 0 | 40 | 100 | 70 | 40 |
| 4049UB | 15 | 220 | 50 | 200 | 280 | 120 |
| 4049UB | 15 | 470 | 75 | 330 | 500 | 420 |
| 4050B | 12 | 0 | 50 | 150 | 60 | 50 |
| 4050B | 12 | 220 | 60 | 300 | 200 | 150 |
| 4050B | 12 | 470 | 100 | 400 | 400 | 300 |
| 4069UB | 12 | 0 | 100 | 350 | 340 | 250 |
| 4069UB | 12 | 220 | 115 | 500 | 380 | 370 |
| 4069UB | 12 | 470 | 150 | 680 | 530 | 580 |
| 4069UB $\times 2$ | 12 | 0 | 70 | 260 | 170 | 130 |

The calculated values were fairly accurate for first order approximations considering that the speeds are high enough that circuit parasitics can affect performance. The saturation currents of the ' 4049 vary from device to device and with the supply voltage $\mathrm{V}_{\mathrm{DD}}$ and junction temperature. Driving directly from the logic IC will provide the quickest rise and fall times, but these times will vary greatly.

By adding a resistor between the CMOS buffer's output and the gate of the power MOSFET in Figure 5 we can control switching times by limiting gate drive current. However, increasing the gate resistor also increases the power MOSFET's susceptibility to noise and accidental dv/dt turn on. A rapid change in the power MOSFET's drain voltage will cause a voltage to appear on the gate, which may be sufficient to turn


Figure 6. Scope Waveforms for an MC14049 Driving an MTP3055E
it on. Keeping the driver impedance low will minimize or eliminate this phenomenon.

To find the switching times using a gate resistor, use Equations 2 and 3 to find rise and fall times. Then use Equations 4 and 5 to find the delay times. Here $R_{\text {eff }}(\mathrm{on} / \mathrm{off})$ equals the gate resistor, $\mathrm{R}_{\mathrm{g}}$, plus the CMOS buffer's output resistance, $\mathrm{R}_{\mathrm{o}}$. The approximate output resistance of the ' 4049 is $200 \Omega$ for turn on and $50 \Omega$ for turn off. Let $\mathrm{V}_{\text {source }}$ equal $\mathrm{V}_{\mathrm{DD}}$ and $\mathrm{V}_{\text {sink }}$ equal zero. Switching times for several gate resistors are summarized in Table 1.

The UB in the MC14049UB stands for "un-buffered". This means that it consists of a single complementary inverter. The additional gate in Figure 5 is used to ensure the power MOSFET driver is itself driven to $V_{D D}$. The input voltage will greatly affect saturation currents and therefore switching times. The MC14050B is a "buffered" non-inverting buffer and consists of two cascaded inverters. It therefore does not invert the signal, and is less susceptible to soft drive conditions. The diodes on the input in Figure 5 clamp the input voltage to ground and VDD. Excessive voltage applied to a CMOS input may damage it's internal static protection diodes. Voltage in excess of the supply voltage, VDD, applied to the output of a CMOS device may cause it to latch-up and destroy itself. Remember
to decouple the logic device, as it is drawing substantial currents.

Open collector TTL gates can also be used to drive standard power MOSFETs. However, most open collector output stages were designed for 5 volt operation. Low power Schottky (LS) gates such as the 74LS05 typically have a collector-emitter breakdown voltage of 10 to 15 volts. This makes them unsuitable for operation using a 12 or 15 volt supply. They can be operated from an 8 to 10 volt supply or with an 8 to 10 volt zener clamp on the output; however, long-term reliability of the logic device will suffer.

The 74LS26 was designed to interface to 15 volt logic and has a tested CE breakdown greater than 15 volts. This Quad NAND gate can be used to drive a power MOSFET with a single pull-up resistor, as in Figure 7. Using a $1.5 \mathrm{~K} \Omega$ pull-up with a 12 volt supply will limit the steady state sink current to 8 mA . This is necessary to guarantee the 'LS26's rated output low voltage $\mathrm{V}_{\mathrm{OL}}$ of 0.5 volts. Using a smaller pull-up resistor would increase the VOL of the 'LS26, and consequently increase the drain-to-source leakage current of the power MOSFET in the off state.

During turn on, current is supplied by the pull-up resistor. During turn off the 'LS26 must sink both the gate current and the pull-up resistor current. The pull-down transistor of an LS output will typically sink about 30 mA . Turn on times can be calculated using Equations 2 and 4 with $R_{\text {eff }}(o n)=R_{p}$ and $V_{\text {source }}=V_{p}$, where $R_{p}$ is the pull-up resistor and $V_{p}$ is the pull-up's supply voltage. Turn off times can be calculated using Equations 3 and 5 with $R_{\text {eff }}(\mathrm{off})=R_{p}$ and $V_{\text {sink }}=V_{p-1} l_{\text {sink }} R_{p}$ ( $V_{\text {sink }}$ may be negative). The equations for $R_{\text {eff (off) }}$ and $V_{\text {sink }}$ are the Thevenin equivalent of an ideal constant current source working against a pull-up resistor. The $\mathrm{V}_{\text {sink }}$ equation is only valid when the pull-down transistor may be approximated as a current source. During the turn off delay and fall times, the pull-down transistor provides a nearly constant sink current, since the pull-down transistor's collector-emitter voltage exceeds it's $V_{C E}$ (sat) and the base drive current is relatively constant.
The 'LS26 with a $1.5 \mathrm{~K} \Omega$ pull-up was used to drive a MTP3055E as in Figure 7. Oscilloscope waveforms are shown in Figure 8, and the switching times are summarized in Table 2.

This configuration provides minimum rise and fall times; however, fall times will vary greatly, since the 'LS26's sink current will vary with temperature and from device to device. A series gate resistor can be used to slow and control turn off. Switching times can again be calculated using Equations 2 through 5 . For large gate resistors you may use the following approximations: $R_{\text {eff(on) }}=R_{p}+R_{g}, V_{\text {source }}=V_{p}, R_{\text {eff(off) }}=R_{g}$, and $\mathrm{V}_{\text {sink }}=0.5$ volts. Switching times for several gate resistors are summarized in Table 2.

Table 2. Switching Times for the 74LS26 Driving an MTP3055E
$l_{D}=6$ Amps Only one gate used

| $V_{\mathbf{C C}}$ <br> (Volts) | $\mathbf{R}_{\mathbf{G}}$ <br> $(\Omega)$ | $\mathbf{R p}_{\mathbf{p}}$ <br> $(\Omega)$ | $\mathbf{t}_{\mathbf{d}(\mathbf{o n})}$ <br> (ns) | $\mathbf{t}_{\text {rise }}$ <br> (ns) | $\mathbf{t}_{\mathbf{d} \text { (off) }}$ <br> (ns) | $\mathbf{t}_{\text {fall }}$ <br> (ns) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 12 | 0 | 1500 | 200 | 850 | 240 | 175 |
| 15 | 0 | 1800 | 200 | 750 | 300 | 175 |
| 12 | 1500 | 1500 | 450 | 2000 | 1300 | 1450 |
| 12 | 3000 | 3000 | 930 | 3900 | 2500 | 2900 |



Figure 7. Low Power Schottky Interface Circuit

Figure 8. Scope Waveforms for a 74LS26 Driving an MTP3055E
$V_{C C}=5$ Volts, $V_{P}=12$ Volts, $R_{P}=1.5 \mathrm{~K} \Omega$


## DIRECT INTERFACE TO LOGIC LEVEL POWER MOSFETs

Logic level Power MOSFETs are designed to be easily interfaced to 5 volt logic devices. They have a larger transconductance and a lower threshold voltage than their conventional counterparts. More importantly, RDS(on) is specified at $V_{G S}=5$ volts. Unfortunately most 5 volt logic families do not have 5 volt high output ( V OH ) capability. Fast Schottky (FAST) and Low power Schottky (LS) logic have a minimum rated $\mathrm{V}_{\mathrm{OH}}$ of 2.7 volts. This means that a pull-up resistor to 5 volts is required to drive Logic Level Power MOSFETs. High speed CMOS $(\mathrm{HC})$ has a $\mathrm{V}_{\mathrm{OH}}$ rating of 4.95 volts, and therefore does not need a pull-up resistor.

Figure 9 shows the output stages of HC and LS logic devices. The HC output stage in Figure 9a is identical to the standard CMOS output stage, except that the complementary MOSFETs have been optimized for 5 volt operation. Most HC devices are buffered by additional complementary stages. The LS output stage in Figure 9b uses a totem pole output. The pull-down transistor is biased on by about $500 \mu \mathrm{~A}$ and has a current gain of about 60 . This means it can sink a maximum of 30 mA . The $110 \Omega$ resistor limits the pull-up transistor's sink current to about 30 mA when the output is shorted.

Figure 10 shows how to interface HC, LS, and FAST logic to Logic Level Power MOSFETs. Note the input termination and protection circuitry. This is necessary to drive the logic devices with a pulse generator. It is best to drive the Logic Level Power MOSFET driver with a device from the same logic family. When connecting an HC (or any CMOS) device to a off board connector, the diodes should be used for ESD protection.

Figure 11 shows the switching waveforms for the three logic families driving a Logic Level Power MOSFET using the circuits in Figure 10. The measured switching times are in Table 3.

Table 3. Switching Times for Logic Devices Driving a Logic Level MTP3055EL
ID = 6 Amps unless noted. One gate used unless noted.

| Driver | $\mathbf{R}_{\mathbf{p}}$ <br> $(\Omega)$ | $\mathbf{t}_{\mathbf{d}(\mathbf{o n )}}(\mathbf{n s})$ | $\mathbf{t}_{\text {rise }}$ <br> (ns) | $\mathbf{t}_{\mathbf{d}(\text { off })}$ <br> (ns) | $\mathbf{t}_{\text {fall }}$ <br> (ns) | Comment |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| 74 HC 04 |  | 25 | 120 | 85 | 75 |  |
| 74 LS 04 | 560 | 45 | 450 | 120 | 130 |  |
| $74 \mathrm{FO4}$ | 220 | 15 | 170 | 18 | 21 |  |
| 74 HC 04 |  | 10 | 65 | 30 | 30 | 2 gates |
| 74 HC 04 |  | 10 | 125 | 35 | 45 | $12 \mathrm{~A} 50^{\circ} \mathrm{C}$ |


(a) CMOS Output Stage

(b) LS TTL Output Stage

Figure 9. Logic Output Stages
A 74HC04 hex inverter can be connected directly to a Logic Level Power MOSFET. The switching times can be calculated the same way as the CMOS inverter buffer. The 'HC04 will source and sink about 50 mA with a 5 volt supply.

The HC family has an operating supply range of 2 to 6 volts. An HC device will drive the Logic Level Power MOSFETs gate to within 50 mV of $\mathrm{V}_{\mathrm{DD}}$. However, if the $\mathrm{V}_{\mathrm{DD}}$ supply falls below 5 volts the switching times and RDS(on) will increase dramatically. A $10 \%$ reduction in VDD (to 4.5 volts) will increase the rise timè by about $50 \%$ and fall time roughly $15 \%$. RDS(on) will increase from 10 to $100 \%$ or more depending on the drain
current and junction temperature. If low voltage operation is a real possibility you should choose the Logic Level Power MOSFET and heatsink to handle this worst case condition. Examine the curves for "On-region Characteristics", "RDS(on) versus ID", and "RDS(on) versus Temperature" in the manufacturers' data sheet. You may need to use a device with a current rating much larger than your expected load current to attain the desired RDS(on) under low supply conditions. Manufactures are now developing 4 volt logic level power MOSFETs with RDS(on) rated at 4 volts. These devices may be easily interfaced to HC logic devices and operated down to 4 volts. However, the lower threshold voltage makes them more susceptible to noise and increases leakage currents.

The 74LS04 in Figure 10 must have a pull-up resistor to 5 volts. A minimum pull-up resistor of $560 \Omega$ will guarantee the logic device's output low voltage, $\mathrm{V}_{\mathrm{OL}}$, of 0.5 volts. During turn on, gate drive current is supplied by the pull-up resistor and the 'LS04's internal pull-up transistor. During turn off the 'LS04 must sink both the gate drive current and the pull-up resistor current. A larger $R_{p}$ will increase turn on time and decrease turn off time. A smaller $R_{p}$ would increase the VOL of the 'LS04, increasing the power MOSFET's leakage current. The lower threshold voltage of logic level power MOSFETs makes the $\mathrm{V}_{\mathrm{OL}}$ rating critical. The threshold voltage of a power MOSFET decreases as temperature increases. Therefore, the VOL of the logic device must be less than the logic level power MOSFET's threshold voltage $\mathrm{V}_{\mathrm{GS}}(\mathrm{th})$ at its maximum expected junction temperature. For this reason 4 volt logic level power MOSFETs may be incompatible with TTL logic devices.

Switching times can again be estimated by using the Thevenin equivalents of the drive circuit with Equations 2 through 5. During turn on delay, current is supplied by the Darlington pull-up transistor of the 74LS04, and the external pull-up resistor. The Darlington is in saturation with a VCE(sat) of about 1.5 Volts. The 74LS04's output current is then limited by the internal $110 \Omega$ resistor. To calculate turn on delay time, you may use Equation 4 with $V_{\text {source }}=V_{C C}\left[1.5 R_{p} /\left(R_{p}+\right.\right.$ $110 \Omega$ )] and $R_{\text {eff( }}(0 n)=R_{\text {p }} \| 110 \Omega$. During rise time nearly all the current is supplied by the pull-up resistor, since $V_{G S P}$ is usually above the $\mathrm{V}_{\mathrm{OH}}$ of the 'LSO4. You may therefore use Equation 2 with $\mathrm{V}_{\text {source }}=\mathrm{V}_{\mathrm{CC}}$ and $\mathrm{R}_{\text {eff(on) }}=\mathrm{R}_{\mathrm{p}}$ to estimate rise time.

During turn off the pull-down transistor must sink both the gate current and the pull-up resistor current, just like the open collector 74LS26 in Figure 7. To calculate turn off times, use $V_{\text {sink }}=V_{C C}-I_{\text {sink }} R_{p}$ and $R_{\text {eff }}$ (off) $=R_{p}$ with Equations 3 and 5. The pull-down transistor's maximum sink current, Isink, is typically about 30 mA .
The 74LS family's specified supply voltage (VCC) range is from 4.75 to 5.25 volts. The rise time will vary greatly with supply voltage while the fall time only varies by about $5 \%$. The rise time will vary from about $+80 \%$ to $-40 \%$ for VCC equals 4.75 and 5.25 volts respectively. This is due to supply voltage affecting both the pull-up resistor current and the pull-up transistor current. Since the operating supply range of LS is less than that of HC logic, RDS(on) will not vary as much, but must be considered.

The FAST logic family can source and sink much more current than the LS family. The 74F04 can source about 50 mA and sink about 200 mA . A minimum pull-up resistor of $220 \Omega$ will guarantee the logic device's output low voltage $\mathrm{V}_{\mathrm{OL}}$ of


Figure 10. Logic Level Power MOSFET Interface Circuits
0.5 volts. A larger $R_{p}$ will increase turn on time and decrease turn off time. The switching times can be calculated as in the LS family. The 74F04 uses an internal $35 \Omega$ resistor to limit the pull-up Darlington's output current, instead of the $110 \Omega$ resistor. The same supply voltage considerations for LS family also apply to the FAST family.
A series gate resistor may be used with any of the circuits in Figure 10 to slow and control switching times. The switching times for large gate resistors (greater than $200 \Omega$ for $\mathrm{HC}, 5 \mathrm{~K} \Omega$ for LS, and $2 \mathrm{~K} \Omega$ for FAST) can be estimated using Reff(on/off) $=R_{g}$ with the Equations 2 through 5: When switching loads even slightly inductive, the inductive kick-back during turn off may cause the drain voltage to rise above the load supply. Slowing down the turn off with a gate resistor will reduce this voltage. If this voltage is large enough and sufficient energy is present it may destroy the Power MOSFET. A new family of rugged Power MOSFETs can handle considerable energy under these conditions. You may also want to choose a large $\mathrm{R}_{\mathrm{g}}$ value in order to reduce Electromagnetic Interference (EMI). When driving a lamp, you may want to use a very large resistor to limit in-rush current. Long-term reliability of the logic devic̣e will also be improved by using a gate resistor and/or a larger pull-up resistor. The gate resistor dissipates most the gate drive power losses, instead of the logic device, reducing stress on the logic output devices. A larger pull-up resistor limits the steady state on current in the pull-down transistors, thereby decreasing their power dissipation. However, using a large gate resistor will also increase the power MOSFET's susceptibility to noise and dv/dt turn on.

Logic gates on the same chip may be paralleled to increase switching speeds. The output current capability will increase in proportion to the number of gates used. If no gate resistor is used, the switching times will decrease in proportion to the number of gates used. If a gate resistor is used it may be safely decreased, in proportion to the number of gates, to decrease switching times. Paralleling logic gates will not change the total logic package power dissipation, since the output current increases and switching times decrease. When many gates are used, switching times may decrease to the point where they are limited by the stray inductance in the load and in the lay-out. Logic gates on different chips or from different families should not be paralleled because the different propagation delays may cause excessive shoot-through currents which might damage the logic devices.

Spare gates left over from a digital circuit may be used to drive a Logic Level power MOSFET. However, the large currents being used by the driver may cause large amounts of noise on the supply rail. This noise may cause data errors in the other gates on the same IC. Limiting the current with a large gate resistor and carefully decoupling the logic device will reduce the power supply noise. Also the driving logic device must be grounded at same point as the source of the power MOSFET to avoid ground shift problems caused by the large drain currents. If separate logic and analog grounds are used they should be connected only at the source of the power MOSFET.

Pay close attention to the power supply scheme. Thegate of a power MOSFET should never be left floating with voltage


Figure 11. Logic Devices Driving an MTP3055EL
applied to the drain. When this happens the power MOSFET may turn on and destroy itself if the current is not limited. If separate supplies are used for the load and the logic IC, the logic supply should be powered up first and powered down last. If this is not possible, consider what happens to the logic device output when power is removed. The pull-up resistors in the LS and FAST circuits of Figure 10 will pull the power MOSFET's gate down to $\mathrm{V}_{\mathrm{CC}}$ when it is low, turning the power MOSFET off. The HC inverter's output, however, will be in a high impedance state when the logic supply voltage is low, allowing the power MOSFET's gate to float. A large resistor to the logic supply voltage or ground, or using a small signal diode to clamp the output to below the logic supply voltage, will solve this problem. Low logic supply voltage may also cause power MOSFET failure due to insufficient gate drive. When a power MOSFET fails the drain voltage will usually appear at it's gate, which may take out the entire logic circuit. A gate resistor will also limit the current under this power MOSFET failure condition.

## INTERFACING TO A MICROPROCESSOR

Microprocessors can be easily interfaced to a Power MOSFET. Any of the circuits in Figure 10 can be used as a buffer between a microprocessor port and a Logic Level power MOSFET. If you want to use a standard power MOSFET, you will have to use the 'LS26 circuit in Figure 7 or a level shifter. The MC14504B hex level shifter can be used to interface HC, LS, or FAST to standard CMOS. This level shifter can be used to drive the Power MOSFET directly or with a buffer like the MC14049UB in Figure 5 to decrease switching times. The MC14504B has selectable TTLCMOS level inputs and standard CMOS outputs. It can source and sink a maximum of about 20 mA using a 12 volt supply.

Be very careful when using bus drivers and latches which have tri-state outputs, like the 74LS240-74HC240 and 74LS373-74HC373, to drive a power MOSFET. The LS tri-state devices require a pull-up resistor to drive the power MOSFET to 5 volts, and will therefore leave the power MOSFET on when the outputs are disabled. The HC devices with tri-state outputs will let the gate float when the outputs are disabled, possibly damaging the power MOSFET. Tri-state devices can be used provided the output enable pin is tied true, low for negative logic enable inputs. HC tri-state devices do not require a pull-up resistor to drive a logic level power MOSFET, and may therefore be used with a pull-down resistor to ground. Note that tri-state outputs should never be pulled above the supply rail or below ground.

When simplicity is important, a single chip microcomputer like the 68 HC 11 can be used to drive a power MOSFET directly. This microcomputer may be used to perform functions like Pulse Width Modulation, complex motor speed control, and controlling multiple power MOSFETs for bridge applications. When the microcomputer is used in the single chip mode, any one of the 8 pins of parallel output port B can be used to drive a Logic Level power MOSFET. A large gate series resistor should be used to minimize power dissipation and noise on the chip. This means that switching times will be fairly slow. This arrangement also exposes the microprocessor to possible harm from power MOSFET failure. Although all the outputs of port $B$ will be reset to zero on a Power-On Reset (POR), a pull down to ground should be used to ensure the power MOSFET will be off during power down. In some appli-
cations it may be necessary to initialize the power MOSFET gate drive via software before power is supplied to the power MOSFET.
Port B may also be used in a strobed mode by using the STRB signal from the control port D. The STRB signal will go high after the data on port $B$ is valid and may be used to latch or enable a logic device driving a power MOSFET. This mode may be useful when exact synchronization is desired between the microprocessor controlled devices.
When used in the extended memory mode, ports B and C are used for address and data busses. The 68 HC 24 port replacement unit will replace port $B$ in a software transparent fashion. Thus, a system can be developed using the 68 HC 11 with a 68 HC 24 and external memory, while the final product will use only the 68 HC 11 .

## CONCLUSION

We have seen that standard Power MOSFETs can be interfaced directly to standard CMOS logic with very good performance, about 50 ns rise and fall times for the MC14049UB driving a 12 Amp power MOSFET. Standard Power MOSFETs may also be interfaced to 5 volt logic using a special interface device such as the 74LS26 open collector NAND gate or the MC14504B hex level shifter. The 74LS26 driving a 12 Amp standard Power MOSFET gives turn on times of about $1 \mu \mathrm{~s}$ and fast turn off times of less than 200 ns . Switching times may be easily estimated using four simple equations and a series resistor may be selected to give the desired rise and fall times.
Logic Level Power MOSFETs can be driven directly with HC logic, and by LS logic with the addition of a pull-up resistor. Switching speeds using an HC device are very fast, less than 150 ns per gate when driving a 12 Amp power MOSFET. Using an LS device, turn on speed is good, about $0.5 \mu \mathrm{~s}$, and turn off speed is excellent, less than 150 ns . Again, switching speeds may be easily estimated and a series resistor may be selected to give the desired performance.

Logic power supply variations are the most important aspect affecting Logic Level Power MOSFET performance. Power supply sequencing and under-voltage protection is necessary to ensure system integrity. Circuit lay-out and power supply decoupling are alsQ important at high speeds.
Finally a Logic Level Power MOSFET may be interfaced directly to a dedicated microprocessor output port when microprocessor control is desired.

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## Basic Servo Loop Motor Control Using the MC68HC05B6 MCU

By Jim Gray

This application note describes a basic circuit and software implementing proportional derivative (PD) closed-loop speed control for a brush motor using four integrated circuits (ICs), two opto discretes, and less than 200 bytes of code.
Feedback control systems using digital algorithms implemented on microcontroller units (MCUs) are becoming increasingly commonplace. The use of an MCU in this type of control application is justified when system flexibility is needed, such as varying drive motors or storing wear parameters in electrically erasable programmable read-only memory (EEPROM). Typically, the system would be modeled mathematically in the discrete time domain due to the use of sampled rather than continuous data. The linear difference equations describing the transfer function of the system are solved using z-transforms, allowing, in the case of proportional-integral-derivative (PID) control, the determination of constants for proper system performance and stability. However, this level of analysis is not necessary to illustrate how straightforward the implementation is using the MC68HCO5B6 and the MPM3004 TMOS ${ }^{\text {TM }} \mathrm{H}$-bridge. The generalized flow of a PD loop is shown in Figure 1. The transfer function of $\mathrm{G}_{\mathrm{C}}(\mathbf{s})$ consists of the PD control, and $\mathrm{Gp}_{\mathrm{p}}(\mathrm{s})$ represents the power amplifier, motor, and load. Here $s$ is a complex variable having both real and imaginary parts. The proportional term $\mathrm{K}_{\mathrm{p}}$ can be accomplished with shifting operations, at least to the resolution of powers of 2 . The derivative term, KDs, of $f(\mathrm{t})$ is approximately

$$
\left.\frac{d f(t)}{d t}\right|_{t=k T} \cong \frac{1}{T}[f(k T)-f(k-1) T]
$$

where $f(\mathrm{kT})$ is the current value of the controlled parameter, and $f(\mathrm{k}-1) \mathrm{T}$ is the value of the same parameter at the previous sampling time. In this example, kDs is realized as the rate of change of the difference between the measured and the desired period of motor-shaft rotation.


Figure 1. PD Loop Flow

The MC68HC05B6 is an M68HC05 MCU Family member with two channels of programmable pulselength modulation on-chip. When used with an H -bridge device such as the MPM3004, these channels can control bidirectional currents of up to 10-A continuous (25-A peak) at 60 V (see Figure 2). Two I/O pins and both pulse-length modulation (PLM) channels are used to control the MPM3004. Proper gate drive and level conversion is provided by the MC34151 dual inverting gate drivers. Input to the control loop consists of the MLED71 infrared emitter and MRD750 photo Schmitt trigger detector coupled through a slotted disc on the motor shaft. The TCAP2 pin and associated input capture registers are used to convert the optical index marks into a time measurement. Great care must be taken to ensure an adequate current source for the MPM3004 and to isolate the supply for the MC34151s. Separate circuit runs and $0.1-\mu \mathrm{F}$ bypass capacitors on the MC34151 ICs were used in this case.

The justification for adding a derivative term to a proportional controller can be easily understood by examining the reasons for the overshoot and ringing typical of an underdamped proportional-only controller. When proportional control applies additional power to correct an underspeed condition, it does so continuously until the error term is zero, resulting in a power setting that ensures an overspeed condition. The converse occurs when reducing motor speed. The rate of change of the error signal as excessive power is being applied to correct underspeed will be a relatively large negative value (the error term is being rapidly reduced). Thus, the derivative of the error term is of the correct sign to compensate the proportional gain term. One effect of this compensation is to retard the loop's response time, but the proportional gain can be increased to offset this.

The listing (see Figure 3) shows the assembly source code for speed measurement and the PD control of PLMA, which drives the power H -bridge in one direction. The opposite direction of rotation is obtained by complementing bits 0 and 1 of port A and driving the opposite lower leg of the H -bridge with PLMB. Eight-bit arithmetic was used exclusively in this example for space and clarity. Although this approach is functional, 16 -bit routines for multiply and divide, given in Reference 2, are better for finer control. Routines to set initial values, control direction of rotation, and check for motor stall are also necessary, although they are not shown in this application note.

Figure 4 shows the response of the system to various changes in load. The data was captured in an emulator trace buffer (Motorola CDS8 Jewelbox) and plotted using a data base program. Beginning from a no-load condition at 4 s , loading (an uncalibrated friction brake) was ramped to cause approximately a 50 -percent duty cycle. Starting at 10 s , the load was then increased again until the system was at the limit of compliance - i.e., at full power and still maintaining the desired speed. Next, at 14 s , approximately half the load was rapidly ( 0.1 s ) removed. The gain of the proportional term was 2 , and the derivative constant was 1 . In systems where a low-pass filter would be beneficial or the steady state error is potentially large, an integral term could be added for full PID control.

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Figure 2. Block Diagram of Servo Loop Motor Control


Figure 3. MC68HC05B6 Servo Loop Motor Control Example




Figure 4. Step Response of PLM Motor Control

# A Software Method for Decoding the Output from the MC14497/MC3373 Combination 

Prepared by: Steve Reinhardt

The electronics industry has used infrared media as a simple, easy, and effective method of wireless communications over short distances. It is not without its problems since simple on/off modulation is affected by the many infrared sources in our environment today. To provide immunity from the noise created by lamps, lighters, electronics, and even humans, the IR carrier is modulated at a rate that would not occur in nature. The industry has settled on around 40 kHz as the modulation frequency.

The data that is transmitted usually takes the form of AM (or CW - continuous wave); that is the carrier is turned on and off for variable periods of time. Some have used a FM scheme, where the modulation frequency is changed to represent 1 or 0 . The output of detectors is generally the same: that is a logic 0 represents a presence of carrier in AM, or one of the frequencies in FM. A logic 1 then represents no carrier in AM, or the second frequency in FM .

The encoding of the data varies widely, from schemes that encode the data as variable pulse widths, constant length coding schemes, or simple ASCII, to the biphase scheme used in the MC14497. Any of these schemes can be decoded by the use of a microcomputer that has a timer, such as the MC68HC05 family or the MC68HC11 family of parts.

## THE MC14497

The MC14497 is a complete building block for IR data transmission, lacking only a high current driver to power the IR LED (or LEDs, depending on the range required) such as the MLED81. The chip limits the duty cycle of the LED to about $10 \%$. The use of an inexpensive ceramic resonator generates the 31.25 kHz carrier. A simple SPST matrix keyboard completes the transmitter.

## THE MC3373

The MC3373 is a companion chip to the MC14497. It provides all of the front-end signal processing to interface an IR photo detector, such as the MRD821, to a TTL level. It includes the gain stages, with automatic background level control (AGC), a simple frequency discriminator to eliminate interference from other sources, and a wave shaper that generates a TTL or CMOS output level. The MC3373 does not decode the data, it merely reconstructs it in logic level form (the way it was trans-
mitted) to facilitate decoding. It too requires few outside components, such as a tuned circuit and a few capacitors for wave shaping. Care must be taken in circuit layout, as this device operates at very high gain to accommodate the low level input signal from the photodetector. Since there are frequency sensitive components in the circuit, it is best to minimize lead lengths, work on a ground plane, and perhaps even put a shield around the components that make up the receiver. ${ }^{1}$

## THE ENCODED BIT STREAM

To understand how to decode the data from the MC14497, it is important to understand what is transmitted. Each word transmitted consists of an AGC burst, a start bit, and 6 data bits. The 6 data bits represent 64 individual channels (0-63). However, channel 63 (111111) is never sent.

The carrier frequency is determined by dividing the oscillator frequency by 16 . For a 500 kHz resonator, the carrier is 31.25 kHz . The baud rate (signalling rate) is equal to the carrier divided by 32, or the oscillator divided by 512 . Again, for a 500 kHz resonator, the baud rate is approximately 976 bps. Each command word takes approximately 8 ms to send.

Refer to Figure 1. Data is the representation of the channel code (001010, channel 10). Carrier represents the output of the MC14497. Recovered is the signal that is output from the MC3373. Notice that the data is inverted, or normally high. When a key is pressed, the chip sends a signal to setup the AGC in the receiver. In the AM mode, which is most common, each transmitted word is preceded by a $512 \mu \mathrm{~s}$ burst (oscillator divided by 256). One bit time later, the start bit is sent. The biphase modulation scheme then uses the position of a carrier within the bit time to represent the data value. Refer to Figure 2. The presence of carrier immediately after the bit time boundary represents a 1 . The lack of the carrier represents a 0 . The phase then changes so that there is a constant modulation, with clock edges on each bit time boundary. This feature is important in some communications schemes, but is not important here.

If a key is held down, the code is repeated at 90 ms intervals. See Figure 3. This results in a duty cycle of about $10 \%$ so that the IR LED can be pulsed at high peak power. At this duty cycle, the MLED81 can tolerate peak currents well in excess of 100 mA . Once a key is released, the MC14497 automatically sends the code for channel 62 (111110), which indicates end of transmission (EOT).


Figure 1


Figure 2


Figure 3


Figure 4

## THE DECODING METHOD

Refer to Figure 4. The letters refer to time slices shown on Fig. 4. The pseudocode to decode the data looks like this: Main:

Set up an interrupt to look for the start bit transition. Interrupt:

Capture the timer value and save it.(a)
Look for the next transition(b), capture the timer value and subtract the saved value. This is the bit time value. Save it.
Add one quarter bit time value to the timer, and set an interrupt for when it times out.(c)
At that interrupt(c-i), look for the value, and set the carry bit accordingly.
Add the bit time to the timer, and set the interrupt.
Shift the carry into the data storage location.
Have we got the six bits plus start? If not, repeat, otherwise we're done with this word.
Is the word EOT (channel 62)? if not, the key is probably repeating. If it is, the message is complete

## THE MC68HC11 PROGRAM

This chip is easy to use because of the 16 -bit add (ADDD) and subtract (SUBD) features which can used to service the timer. The MC68HC05 devices lack this, but do provide an add with carry (ADC) to implement 16 -bit adds.

Port A pin 3 (PA3) is used as the input from the MC3373. This is an input capture pin (IC1). The output compare feature is required to generate the bit clock, though an output pin is not necessary.

## THE MC68HC05 PROGRAM

The code for the MC68HC05 is a little different. First, since the state of the input capture pin cannot be read, the data must be routed to another pin. Therefore, PA7 is used to sample the data. The internal output compare interrupt is utilized to set the baud clock.

## MC68HC11 PROGRAM LISTING

| start | lds | \# ${ }^{\text {S }} \mathrm{FF}$ | *load the stack pointer |
| :---: | :---: | :---: | :---: |
|  | Idaa | \#2 | *set prescaler to /4 |
|  | staa | TMSK2 | *by writing to TMSK2 register |
|  | Idaa | \#1 | *enable input capture 3 functions |
|  | staa | TMSK1 | *TMSK1 enables the interrupt |
|  | staa | TFLG1 | *TFLG1 clears the flag |
|  | Idaa | \#2 | *look at falling edges |
|  | staa | TCTL2 | *by writing to TCTL2 |
|  | Idaa | \# 6 |  |
|  | staa | count | *number of bits to assemble |
|  | . |  |  |
|  | - |  |  |
|  | - |  |  |
| main |  |  | *main program |
|  | - |  |  |
|  | - |  |  |
|  | - |  |  |
| *Input | re inte | upt service r | st time through, the |
| *value | timer | s saved, the | ough, the difference |
| *is calc | d, det | mining the bi | the time slice is |
| *shifted | ne qua | er bit interval | the data. |
| timeint | brset | flags, 0 , next | *input capture 3 interrupt routine |
|  | 1 dd | \#\$1014 | *save the timer value from the first edge(a) |
|  | std | saveit | *to time the baud rate |
|  | bset | flags, 0 | *bit 0 in flags indicates first edge |
|  | bra | endint | *exit interrupt cleanly |
| next | ldd | \#\$1014 | *get the timer value (b) |
|  | subd | saveit | *subtract the first value(b-a) |
|  | std | baud | *save that in baud |
|  | 1srd |  | *divide by 2 |
|  | 1srd |  | *divide by 4 |
|  | addd | \#\$1014 | *add 1/4 bit time to the timer |
|  | std | OUTC1 | *store to output compare 1 |
|  | 1 daa | \# $\$$ FE | *clear the mask |
|  | anda | TMSK1 | *without disturbing other bits |
|  | staa | TMSK1 | *disable further input compare interrupts |
|  | bclr | flags, 0 | *clear first edge flag bitendint |
| endint | Idaa | \#1 | *setup to clear flag for next edge |
|  | staa | TFLG2 | *and writing to TFLG2 |
|  | rti |  | *wait for next edge |



## MC68HC05 PROGRAM LISTING

| start | 1da | \# \$ 0 | *set up timer control register |
| :---: | :---: | :---: | :---: |
|  | sta | TCR | *interrupts enabled, negative edge |
|  | lda | \# \$0 | * make sure port a is an input |
|  | sta | PADDR | * write to data direction |
|  | lda | \#6 |  |
|  | sta | count | * number of bits to assemble |
|  | - |  |  |
|  | - |  |  |
|  | $\cdot$ |  |  |
| main | equ | * | *main program |
|  | - |  |  |
|  | . |  |  |
|  | - |  |  |
| *input capture service routine. The first time through, the value of |  |  |  |
| *the timer is saved. The second time through, the difference is |  |  |  |
| *calculated, determining the bit interval. The time slice is shifted |  |  |  |
| *by one quarter time for sampling the data. |  |  |  |
| *timeint | brset | flags, 0 , next |  |
|  | lda | ICH | *grab the high byte |
|  | sta | saveit | *store it |
|  | lda | ICL | *then the low byte |
|  | sta | saveit+1 | * and save that. |
|  | bset | flags,0 | *got first edge flag |
|  | bra | endint |  |
| next | lda | ICL | *get the new low byte |
|  | sub | saveit+1 | *subtract the old low byte |
|  | sta | byte+1 | *and save the result |
|  | 1da | ICH | *get the new high byte |
|  | sbc | saveit | *subtract the old, with carry |
|  | sta | byte | *save the byte interval |
|  | lsr |  | *divide by two |
|  | sta | OCH | *to output compare |
|  | lda | byte +1 | *get low byte |
|  | ror |  | *use ror to get carry in |
|  | sta | OCL | to output compare |
|  | lda | OCH |  |
|  | 1 sr |  |  |
|  | sta | OCH |  |
|  | 1da | OCL |  |
|  | ror |  |  |
|  | sta | OCL | *finish divide by four |
|  | lda | \#\$7F | *mask off input capture |
|  | sta | TSR | *by writing to timer status |
|  | belr | flags, 0 | *clear first edge flag bit |

endint rti
*output compare service routine. For each interrupt that occurs,
*sample the input line and shift the appropriate data bit into the *data register. Do so for all six bits, then word is complete.
*

| bitint | 1da | PADR | *get the data bit value |
| :---: | :---: | :---: | :---: |
|  | 1sl |  | *get the data to carry |
|  | 1da | data | *get the data byte |
|  | rol |  | *and assemble the byte |
|  | sta | data | * to data |
|  | dec | count | *check to see if all done |
|  | beq | endbit | *exit if done |
|  | lda | OCL |  |
|  | add | byte +1 | *set up the next interrupt |
|  | sta | OCL | *write to OCL resets flag |
|  | lda | OCH |  |
|  | adc | byte | *use add with carry to do 16 bit |
|  | sta | OCH |  |
|  | rti |  |  |
| endbit | lda coma | data | *get the word <br> *remember the data was inverted |
|  | and | \#\$5F | *and there were only 6 bits |
|  | sta | data |  |
|  | bset | flags. 1 | *word ready flag bit |
|  | rti |  |  |

# Bi-directional Data Transfer between MC68HC11 and MC6805L3 using SPI 

by<br>Richard Soja, Motorola, EKB

## INTRODUCTION

One of the most powerful features shared by a wide range of Motorola MCUs is the Serial Peripheral Interface (SPI). It is primarily designed to operate as a synchronous, 8 -bit communication system and is implemented entirely with on-chip hardware. This frees the CPU for other tasks and ensures a minimum of software overhead associated with the SPI system.

The SPI is available in two basic forms:

1. Level 1 SPI - implemented on the MC68HC11, HC05C4 MCUS,
2. Level 2 SPI - implemented on the MC6805S2/S3/L3/L8 MCUs.
Note that the HCMOS family of MCUs only support level 1 , while level 2 is implemented only on HMOS MCUs.

Though both levels of SPI can communicate easily with each other, level 2 has a number of additional capabilities, including asynchronous communication. This application note is aimed at describing a method of achieving synchronous communication between a level 1 and level 2 SPI, and details the subtle relevant differences in the on-chip implementation of each.

## DESCRIPTION

The two MCUs used in this application are the high performance MC68HC11 and the low cost MC6805L3.

Data is transferred between the MCUs on a single
bi-directional line, with the clock supplied on an additional line. Also, to ensure initial synchronisation between each MCU, a software handshake sequence is implemented on the same lines which provide the clock and data. This has the considerable advantage of minimising the number of lines between each MCU as additional control lines are not needed.

The handshake sequence is also necessary for two other reasons; the 6805L3 receive data register is unbuffered, and it is not possible for the 6805L3 to stop transmission of data from the 68 HC 11 by inhibiting the clock signal. The fact that the 6805L3 data register is unbuffered means that, if a handshake sequence was not implemented, new data could begin to get clocked in before the previous data were read. Also, the on-chip configuration of the 68HC11's SPI means that, if an attempt were made to slow down or stop its clock during transfer of a byte, there would be a resultant loss of synchronism between the transmitting and receiving MCUs.

The 68 HC 11 software is implemented as the clock master (i.e. it provides the clock output), while the 6805 L 3 is the clock slave. As there are no other clock masters or slaves in the system, software is kept to an absolute minimum. In fact the main transfer routine (XFER) for the 68HC11 is only 27 bytes long, while the 6805L3 uses only 30 bytes.

The other significant advantage of this implementation is that none of the 6805L3 timers are required for SPI operation, thus ensuring a minimal impact on any other application dependent tasks the MCU may be executing.


Figure 1. Hardware Implementation

## Figure 2. 68HC11-6805L3 SPI Timing



앙

## Master releases clock line by disabling SPI.

Slave clears data line by forcing o/p clamp on PD3.Master clears clock line by enabling SPI.
Once clock line goes low, slave stores data in SPI data register, sets its data DDR to correct state, and enables SPI.

## Slave releases data clamp.

Master starts SPI clock by storing data in SPI register.
Both master and slave detect end of transmission and read data from SPI register.
Slave disables SPI to ensure data line is released

## Configuring the MCUs

The method of configuring each MCU for bidirectional data transfer is slightly different, due to the differences in their SPI silicon implementation. Figure 1 shows the hardware implementation. On the 68 HC 11 , the input and output pins must be connected together externally. On the 6805L3, this can be done internally by software, thus requiring only 1 external data I/O pin. The other 6805L3 SPI data pin is now free to be used in any other way.

As the slave select (SS) pins are unused by either MCU, they must be configured as outputs to prevent SPI fault conditions occurring.

The spare 6805L3 data pin (PD3) is used to control the bi-directional data line, thus providing a handshake signal to the 68 HC 11 . The 68 HC 11 's handshake is on the clock line, and is controlled by disabling and enabling its SPI.

## Data transfer and timing

Figure 2 shows details of the handshake sequence. The significant point to note from Figure 2 is that the handshake sequence is implemented purely in software, while the 8 -bit data and clocks are generated by the SPI hardware.

To prevent data contention, both during data transfer and during the handshake sequence, both SPIs must operate in wired-or (open drain) mode. On the 6805L3, this is done by setting bit 3 in the miscellaneous register, while on the 68 HC 11 , bit 5 of the SPI control register must be set. The SPI utilised on the 68HCO5 family of MCUs does not support this open-drain option and cannot, therefore, be used in this application.

The clock format is: idle low, data output on positive edge and sampled on negative edge. Both SPls must be configured to operate with the same clock format (see Figure 2). Eight data bits are transferred, at a maximum clock rate of 125 kHz ,
which is limited by the 6805L3 SPI. Data transfer is preceded by the handshake sequence, which ensures that both MCUs are in the correct state, and ready to transfer a new byte of data.

The most significant bit of data appears first, on the rising edge of the first clock. Data is latched into both SPI shift registers on the falling edge of the clock. Once the last data bit is latched, the data line is released high. This is necessary to ensure correct operation of the handshake sequence. When the 68 HC1 11 is acting as a transmitter, this state occurs automatically - as a by product of its SPI hardware implementation. However, on completion of data transmission from the 6805L3, the LSB is permanently maintained on the data line, so its driver routine has been designed to ensure that the data line is always restored to the high state.

## Software routines

A glance at the software listing (see Appendix 1) reveals that the transmit and receive routines for each MCU are essentially the same! The entry and exit conditions of each are as shown in table 1.

On the 6805L3, the $X$ register dictates the operating mode of the transfer routine. This is necessary because the same I/O pin is used for transmitting and receiving data, so its data direction register must be changed appropriately (by the contents of $X$ ).

On the 68 HC 11 , separate pins are used for transmitting and receiving data, so their DDR pins are set up once only in the initialisation routine.

There are other important subtle differences. Prior to reception of data, the 6805L3 SPI data register content is irrelevant, while the 68HC11 SPI data register must be loaded with $\$ F F$, to prevent data bus contention. This could occur with the 68 HC 11 , in this application, because data is simultaneously output to and read back on the same external line

Table 1
68HC11:

|  | $\frac{\text { Transmit }}{\text { ACCA }}$ | $\frac{\text { Receive }}{\text { ACCA }}$ |  |
| :--- | :---: | :---: | :--- |
| Entry | Data to send | \$FF | $\times$ Reg $=$base address of I/O Register <br> block (normally $\$ 1000$ ). |
| Exit | Data sent | Data received | $\times$ Reg $=$ unchanged |

All other registers are unused by the 68HC11 transfer routine.
6805L3:

|  | Transmit |  | Receive |  |
| :--- | :---: | :---: | :---: | :---: |
|  | ACC | $\times$ Reg | ACC | Reg |
| Entry | Data to send | $\$ 5$ | Don't care | $\$ 1$ |
| Exit | Data sent | \$D | Data received | $\$ D$ |

during data transfer. Loading \$FF into the 68HC11 data register ensures that this data is replaced by that transmitted from the 6805L3.

Note that, as the 68HC11 is the clock master, it must provide the clock signal, not only when transmitting data, but also when receiving data from the 6805L3. It does this by writing to its SPI data register.

Completion of data transfer is indicated by a single flag bit (SPIF). On the 6805L3, this is bit 7 of the SPI control register, while on the 68 HC 11 , it is bit 7 of the SPI status register. This flag bit is used to indicate completion of either transmission or reception of data.

Flag clearing techniques are quite different for the 68 HC 11 and 6805L3. On the latter, the SPIF flag is cleared simply by writing ' 0 ' to the flag bit. On the 68 HC 11 , a two stage operation is required to clear the SPIF flag; the SPI status register must first be read, with the flag set, followed by an access of the SPI data register.

An examination of the SPI software drivers shows that on completion of a data transmission, the SPI data register is read again. This data should be the same as that transmitted, and provides information on whether data contention or corruption occurred during transfer. This facility could be incorporated in a data validation routine to improve reliability of data transfer.

The key features in this implementation are:

1. An orderly start-up sequence to ensure the correct initial synchronisation. As the 6805L3 is the slave, its initialisation routine is not exited until it detects a low on the clock line - this will occur only when the 68 HC 11 gains control of the SPI. Before this happens, all I/O pins are set to inputs, so the clock line will be pulled high by the external resistor.
2. A well defined transfer protocol is used. The master device (i.e. 68HC11) must always dictate the data transfer direction and the data stream size must be specified by the currently selected transmitter, so that the receiver knows when the last byte has been sent.

The transfer protocol operates such that after initialisation, the master MCU (68HC11) transmits a control byte to the slave (6805L3). This control byte selects the subsequent data transfer direction and is either a slave listen address or a slave talk address. If it is a slave listen address, then the 6805L3 stays in receive mode. The next byte indicates the total number of bytes to be received, followed by the data stream (see Figure 3).

Once the last byte is transferred, the 6805L3 can await a new control byte, or alternatively it can return to some other task, such as processing the previously received data. Similarly, at this point, the


Master sends 'slave listen address' $=1$

Master sends 2 bytes of data
(4) SPI goes idle

Figure 3. Master Transmitter - Slave Receiver
master transmitter (68HC11) can return to another task, or send a new control byte.

If the control byte now sent is a slave talk address, then the 6805L3 will switch to transmit mode, and the master will switch to receive mode. The 6805L3 will send a byte count, followed by the data stream to the master (see Figure 4).

Note that, once the last byte is transferred in either direction, both processors are free to continue other tasks or attempt a new data transfer. The handshake sequence always ensures synchronisation of data transfer, independent of the response time of either MCU.

## CONCLUSION

Potential uses for this type of data transfer are in applications which require remote interrogation of an

MCU based system via a minimal number of lines, such as:

- Development and diagnosis of engine management systems
- Smart card and key card security applications - Instrumentation and data logging equipment.


## APPENDIX

The demonstration programs listed in the following pages simply transfer a string of characters from the 68HC1 1 to the 6805L3, which converts them to upper case and sends them back again.
The HC11SPI program is listed on pages 6 to 7; the L3SPI program on pages 8 to 10.


Master sends 'slave talk address' $=2$
(4) SPI goes idle

Figure 4. Master Receiver - Slave Transmitter


29 A C003 8D3C
30 A C005 18CE0001
31 A COO9 8008
32 A COOB 18CEOOO1
33 A COOF 8017
34 A CO11 $20 F 2$
35 A
37 A C013 8601
38 A C015 $803 A$
38 A C015 $803 A$
39 A C017 $18 A 600$
40 A C01A 16
41 A CO1B 8034
42 A CO1D 1808
43 A CO1F 18A600
44 A COR2 8020
45 A COR 54
47 A COR7 39
47 A
48
49 A COR8
50 A CO28 8602
51 A COR 8602
52 A CORC $86 F F$
53 A CORE 802
54 A CO3O 16
54 A CO30 16
55 A CO31 184700
56 A CO34 1808
57 A CO36 $86 F F$
58 A C038 8017

0008
0009
0028
0029
0024
0024
0025
0004
0008
0010
0080
0040

| PORTD | EQU | 8 |
| :--- | :--- | :--- |
| DORD | EQU | 9 |
| SPCR | EQU | $\$ 28$ |
| SPSR | EQU | $\$ 29$ |
| SPDR | EQU | $\$ 2 A$ |
| TMSK2 | EQU | $\$ 24$ |
| TFLG2 | EQU | $\$ 25$ |
| MISO | EQU | 4 |
| MOSI | EQU | 8 |
| SCK | EQU | $\$ 10$ |
| SPIF | EQU | $\$ 80$ |
| SPE | EQU | $\$ 40$ |


|  | ORG | $\$ 0$ |
| :--- | :--- | :--- |
| TIMCONT RMB | 1 |  |
| MSG1 | FCB | 28 |

## $\$ 0$ 1 28

Number of bytes in data block /BI-DIRECTIONAL DATA TRANSFER/

|  | ORG | \$COOO |
| :---: | :---: | :---: |
| START | LDS | \#\$35 |
|  | BSR | INIT |
| START1 | LDY | \#MSG1 |
|  | BSR | SEND |
|  | LDY | \#MSG1 |
|  | BSR | READ |
|  | BRA | START |
| SEND | EQU | * |
|  | LDAA | \#1 |
|  | BSR | XFER |
|  | LDAA | . $Y$ |
|  | TAB |  |
|  | BSR | XFER |
| SEND1 | INY |  |
|  | LDAA | X Y ${ }^{\text {Y }}$ |
|  | BSR | XFER |
|  | DECB |  |
|  | RNE | SEND1 |
| * |  |  |
| READ | EQU | * |
|  | LDAA | \#2 |
|  | BSR | XFER |
|  | LDAA | \#SFF |
|  | BSR | XFER |
|  | TAB |  |
|  | STAA | . Y |
| READ1 | INY |  |
|  | LDAA | \#SFF |
|  | BSR | XFER |

8
9
$\$ 28$
$\$ 29$
$\$ 2 A$
$\$ 24$
$\$ 25$
4
8
$\$ 10$
$\$ 80$
$\$ 40$

| SCOOO | LOAD INTO EVB RAM |
| :--- | :--- |
| \#\#S5 |  |
| INIT | BUFFALO USES RAM ABOVE This |

Y POINTS TO BEGINNING OF DATA BLOCK TO TRANSFER Transmit block to slave, starting with byte count RE-INITIALISE POINTER TO DATA BLOCK and read the bytes back.
ENTER WITH Y POINTING AT BYTE COUNT OF DATA BLOCK.
Command slave to receive
Now send slave the byte count. BUT IST STORE IT IN BYTE COUNTER.
point at next byte
AND SEND IT
UNTIL ALL DONE
ENTER WITH Y POINTING AT BYTE COUNT OF DATA BLOCK.
COMMAND SLAVE TO TRANSMIT
NOW READ BYTES BACK FROM SLAVE.
1ST BYTE IS BYTE COUNT SO
STORE IT IN BYTE COUNTER
THEN STORE IT AT BEGINNING OF DATA BLOCK.
BUMP POINTER
THEN CONTINUE TO READ

| 59 A CO3A 18A700 60 A CO3D 5A <br> 61 A COSE $26 f 4$ 62 A COHO 39 |  | $\begin{aligned} & \text { STAA } \\ & \text { DECCB } \\ & \text { BNE } \\ & \text { RTS } \end{aligned}$ | READ1 | and store bytes until all done |
| :---: | :---: | :---: | :---: | :---: |
| 64 A COH1 | INIT | ECl | * |  |
| 65 A COH1 CE1000 |  | LOX | \#S1000 |  |
| 66 A COH4 8638 |  | $\triangle$ LDAA | \#538 | ENABLE OUTPUT MODE ON SS, SCK, MOSI, INPUT ON MISO |
| 68 A COH8 8676 |  | LDAA |  | ENABLE SPI AS L2SKHZ CLOCK MASTER, WIRED-OR MOOE |
| 69 A COHA A728 |  | STAA | SPCR. $x$ | Enable spi as leskzz Clock master, wired-or mooe |
| 70 A COHC 8618 |  | LDAA | \#518 | SEt data \& clock output buffers to logic ' 1 ' |
| 71 A COHE A708 |  | STAA | PORTD, X | to generate ackeol edge clock. |
| 72 A CO5O 39 |  | RIS |  |  |
| 74 A |  |  |  |  |
| 75 A | Bidirectional data transfer. hith handshake on clock \& data lines. Entered with data in Acca. SPI enabled, | BIDIRECTIONAL DATA TRANSFER, WITH HANDSHAKE ON CLOCK \& DATA LINES. Entered with data in ACCA. SPI enabled, CLOCK LOW, DATA LINE DETERMINED BY SLAVE DATA PIN.* |  |  |
| 76 A |  |  |  |  |
| 77 A |  |  |  |  |
| 78 A |  |  |  |  |
| 79 A | * ${ }^{\text {P }}$ ER |  |  |  |
| 80 A Cosi |  | EQU |  |  |
| 81 A $\cos 1$ 1F0804FC |  | BRCLR | PORTD.X.MMISO.* | 1ST HAIT FOR SLAVE TO RELEASE data line. |
| 88 a Cos5 102840 |  | BCLR | SPCR, X .\#SPE | SEND ACK ON CLOCK LINE, bY disabling SPI |
|  |  | brset | PORTD | WAIT FOR SLAVE TO ACKNOMLEDGE. |
| 85 A CO5F 1F0804FC |  | BSECLR |  | Wait for silave to release daita iine, then |
| 86 A C063 A72A |  | STAA | SPOR. $X$. | Start SPI transaction by writing data. |
| 87 A CO65 1F2980FC |  | BRCLR | SPSR , X. \#SPIF.* | NOW WAIT FOR TRANSMISSION COMPL ETE FLAG. |
| 88 A COG9 A62A 89 A COSB 39 |  | LDAA | SPDR. X | Clear SPIF, and read data |
| 90 A | * |  |  |  |
| 91 A | : | $\begin{aligned} & \text { ORG SFFFE } \\ & \text { FDB START } \end{aligned}$ |  |  |
| 92 A |  |  |  |  |
| 94 A | * | END |  |  |
| TOTAL ERRORS ** TOTAL WAPNTNGS | $0-$ |  |  |  |

SMBOL TABLE LISTING
smbol name sect valle smbol name sect value

| DORD |  | 009 | SPCR | A | 0028 |
| :---: | :---: | :---: | :---: | :---: | :---: |
| INIT | A | COH | SPDR | A | 002 A |
| MISO | A | 0004 | SPE | A | 0040 |
| MOSI | A | 0008 | SPIF | A | 0080 |
| MSG1 | A | 0001 | SPSR | A | 0029 |
| PORTD | A | 0008 | START | A | C000 |
| READ | A | CO88 | START1 | A | COO5 |
| READ1 | A | ${ }^{0} 034$ | IFLG2 | A | 0025 |
| SCK | A | 0010 | TIMCONT | A | 0000 |
| SEND | A | C013 |  | A | 0024 |
| SEND1 | A | C01D | XFER | A | C051 |



＊

| PORTA | EQU | 0 |
| :--- | :--- | :--- |
| PORDD | EQU | 3 |
| DORA | EQU | 4 |
| DORD | EQU | 7 |
| TADAT | EQU | 8 |
| TACR | EQU | 9 |
| MISC | EQU | $\$ A$ |
| IBDAT | EQU | $\$ C$ |
| TBCR | EQU | $\$ D$ |
| SPIDAT | EQU | $\$ E$ |
| SPICR | EQU | $\$ F$ |
| PRESCL | EQU | $\$ 10$ |

## 0 3 4 7 8 9 SA SC SD SE SE $\$ 10$ <br> 0 1 2 3 4 4 7 <br> DATA LINE CLAMP ON D3


\＄80
INIT \＃1
XFER
\＃1
READ
\＃2
SEND
STAR StARTI
\＃
XFER
BYTCNT
DATLEN
$\# 1$
XFER BYTCNT \＃sizo DATA，X BYTCN READ1

1st receive command byte
If slave requested to Listen，then
read more data．
If slave requested to talk．then sEND DATA TO MASTER．
also store value as data length． NOW READ ALL REMAINING BYTES
（CONVERT LOWER CASE TO UPPER CASE） AND STORE IN BUFFER

UNTIL ALL DONE，
AND RETURN．
Reserve enough space for received data．
Initialise SPI，and wait for hCil to become ready
Get next byte，which is byte counter．


SMBOL TABLE LISTING

| SMBOL NAME | SECT VALLE | STMBO NAME | SECT VALIE |
| :---: | :---: | :---: | :---: |
| BYTCNT | A 0020 | SEND | A $\quad$ OAP |
| CLAMP | A 0003 | SEND1 | A 0081 |
| DATA | A 00022 | SPE | A 0004 |
| DATLEN | A 0021 | SPICR | A 000 F |
| DORA | A 0004 | SPIDAT | A 000 E |
| DORD | A 0007 | SPIF | A 0007 |
| INIT | 008 F | SS | A 0000 |
| MISC | A 000A | START | A 0080 |
| PORTA | A 0000 | START1 | A 0083 |
| PORTD | A 0003 | TACR | A 0009 |
| PRESCL | 0010 | TADAT | A 0008 |
| READ | A 0091 | IBCR | A 0000 |
| READ1 | A 0099 | TBDAT | A 000C |
| SCK | A 0001 | XFER | A 0003 |
| SOA | A 0002 |  |  |

# MC68HC805B6 LOW-COST EEPROM MICROCOMPUTER PROGRAMMING MODULE 

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## INTRODUCTION

The EEPROM feature of the MC68HC805B6 microcomputer unit (MCU) enables the user to emulate the MC68HC05B6 and MC68HC05B4 MCU devices. This application notes describes one programming technique which may be used to program the MC68HC805B6 internal EEPROM, and provides a description of the programming module used in conjunction with this application note. All that is required to program the MC68HC805B6 is the programming module (which can be implemented on a single PCB), and a twin $+5 \mathrm{~V} /+19 \mathrm{~V}$ dc power supply.

## PROGRAMMING TECHNIQUE

A multi-byte EEPROM programming technique is used to load a user program into the MC68HC805B6 EEPROM in order to emulate the MC68HC05B6 and MC68HC05B4 devices. This type of operation is accomplished via a bootstrap mode of operation. The user program contained in an external EPROM is copied into the internal EEPROM of the MC68HC805B6 device, then verified against the contents of the EPROM.
The bootstrap program follows the following sequence following reset:

1. EEPROM6 Erase.

The 6K EEPROM (which emulates the ROM on the MC68HC05B4 and MC68HC05B6 mask devices) is erased for a nominal 100 ms (with a 4 MHz crystal). This memory area is then tested for complete erasure by verifying that all bytes in the EEPROM6 map read \$FF. If any bytes have failed to erase, then the red LED will be illuminated and the bootstrap routine will cycle back and continue to erase EEPROM6 until all bytes are erased.
2. EEPROM1 Erase.

The 256 bytes EEPROM (which emulates the 256 bytes of byte-eraseable EEPROM on the MC68HC05B6 mask device) is erased in a similar fashion to the EEPROM6, with illumination of the red LED indicating a failure to erase. Completion of this program step ensures that the security bit (which is implemented in EEPROM1) is also erased.
3.EEPROM Program.

EEPROM1 and EEPROM6 are then programmed in turn from the data contained in the EPROM, in increasing address order. Areas in the MC68HC805B6 memory map which do not include EEPROM will be skipped by the programming routine, as will \$FF bytes, thus speeding the programming operation. During programming the green LED should flash at approximately 3 Hz , though this frequency will increase for data equal to \$FF.
4. EEPROM Program Verify

EEPROM1 and EEPROM6 are verified against the contents of the EPROM, with any error causing illumination of the red LED. A successful programming operation will result in green LED on, red LED off. Note that the red LED may glow very dimly, this is normal.

## PROGRAMMING OPERATION

To program the MC68HC805B6 MCU EEPROM, perform the following steps.:

1. With power to the module removed install MCU and EEPROM devices into the programming module.
2. Place switch S 1 to RESET position.
3. Apply +5 V power supply to the programming module.
4. Apply +19 V power supply to the programming module.
5. Place switch S1 in the RUN position.
6.Once the green LED is illuminated, place switch S1 to RESET position.
6. Remove +19 V power supply from the programming module.
7. Remove +5 V power supply from the programming module.

Note: To avoid possible damage to the MC68HC805B6 it is essential that power to the programming module is applied and removed in the sequence specified above.

## PROGRAMMING MODULE CONSTRUCTION

Table 1 provides the parts list for construction of the module, with component tolerances generally not critical. A schematic of the circuit is included as Figure 1.

## HARDWARE CONSIDERATIONS/DEBUG

Functionality of the module may be adversely affected by faults in the following areas:

1. IRQ and RESET

The circuitry on these pins ensures that the IRQ pin sees a voltage level equal to approximately +10 V dc during the RESET period. This is necessary for bootstrap mode capture. Correct operation of D1 and D2 should be verified. 2.VPP6

The input to this pin is controlled via a switch driven by port pin PC7. This method ensures that a minimum +5 V dc level is always present at the VPP6 pin, and that +19 V dc is available during programming and erase operations on EEPROM6. Correct operation of D5, 6 and 7 should be verified. Zener diode ZD1 protects the EEPROM from
possible damage caused by excursions greater than +20 V dc. 3. VPP1

It is important that this pin (at which the output of the internal EEPROM1 charge pump is visible) is allowed to float. Clamping this pin to +5 V dc will prevent successful programming and erase operations from taking place on EEPROM1, whilst clamping this pin to OV could damage the device.

## 4. Port D

For correct bootstrap mode capture it is necessary to connect these inputs to 0 V .

## 5. PC5/PC6

These pins provide a handshake which is not used in this application, therefore for correct operation of the module PC5 should be connected to PC6.



# Monitor Program for the MC68HC05B6 Microcomputer Unit 

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## INTRODUCTION

The MC68HC05B6 HCMOS microcomputer is a member of Motorola'sMC68HC05 family of low-cost single-chip microprocessors. This 8 -bit microcomputer (MCU) contains an on-chip oscillator, CPU, RAM, ROM, EEPROM, A/D, PULSE LENGTH Modulated outputs, $1 / O$, a serial Communications Interface, Timer system and Watchdog timer.
A monitor program is available in the mask ROM of a 68HC05B6, (XC68HC05B6FN MONITOR), which when used with a monitor circuit module, a power supply, and a video terminal will allow the user to write and debug small portions of $68 \mathrm{HC05B6}$ code. This application note contains a description of the facilities available via the monitor software, a diagram of the monitor circuit, and a listing of the monitor code.

## HARDWARE

The monitor module requires a single( +5 V ) power supply, and all communications between the device and terminal take place via an RS-232 link. All 68HC05B6 I/O pins are available to the user to be configured as required.

Terminal setup is as follows:
9600 Baud, Half Duplex,
and either 7 bit data and parity ' 0 ' or 8 bit data and no parity.
A circuit diagram of the monitor is given in Figure 1.

## MONITOR OPERATION

The following sequence of operations should be followed:

1. Remove power supply from module
2. Insert XC68HC05B6FN MONITOR device
3. Place S1 in 'RESET' position
4. Apply +5 V dc power supply
5. Connect video terminal
6. Place S1 in 'RUN' position

The 68HC05B6 will then begin to execute the monitor program, and the following message should appear on the monitor:
"Hi! I'm the MC 68HC805 B6 from MOTOROLA

European Design Centre, Geneva."
A prompt "." will be displayed to indicate that the device is ready to receive commands from the terminal. If no message appears, then the setup of the terminal should be verified.

## MONITOR COMMANDS

The following commands are available:

## Command Description

R Display the content of the registers in format.
HINZC AA XX PPPP ZZ = DD where

| HINZC | $=$ | Condition code register |
| :--- | :--- | :--- |
| AA | $=$ | Contents of Accumulator |
| XX | $=$ | Contents of Index Register |
| PPPP | $=$ | Program Counter |
| ZZ,DD | $=$ | User specified byte (which <br> addresses f00 to fFF) and |
|  |  | contents. Set up using the |
|  | V ' command. Reset <br> initialises ZZ to f08 (AD <br> data register). |  |
|  |  |  |

Note that this command assumes that the stack pointer is at address \$FA.

A Display/Change the Accumulator
The contents of the Accumulator are displayed, then the monitor waits for input of two hex digits (new accumulator contents). Typing a carriage return will return the program to the command mode with the contents of the Accumulator unchanged.

Note that this command assumes that the Stack Pointer is at address \$FA.

Display/Change the Index Register
The contents of the Index Register are displayed, then the monitor waits for the input of two hex digits (new Accumulator contents). Typing a carriage return will return
the program to the command mode with the contents of the Index Register unchanged.

Note that this command assumes that the Stack Pointer is at address \$FA.

Mnnnn Examine/Change Memory
The contents of any address in the range $\$ 000$ to \$1FF (Register, RAM and EEPROM1) are displayed, and the program will await further input, namely:

Redisplay the contents of the current address
$\wedge$ Display the contents of the previous address (nnnn-1)
<CR> Open the next address (nnnn+1)
$+\quad$ Increase the contents of the open location by 1

- Decrease the contents of the open location by 1
/D Replace the contents of the open location with the Ascii code for alphanumeric character D, and go to the next address. nn Replace the contents of the currently open address with two hex digits $n n$ and go to the next address

Typing any other character will return the monitor to the command mode.

L nnnn List a block of memory starting at address nnnn. The default address (if nnnn is not specified) is $\$ 100$. The data is displayed on screen as four blocks of eight by eight bytes, with the address printed at every sixteenth byte.

Vnn Change the address of the page zero byte displayed with the R command with the hex byte specified by $n n$.

K nn Set Program and Erase times for operations on EEPROM1 where $n n$ is milliseconds entered in decimal. The default values are 10 ms . Typing 'enter' will skip the command.

Pnn Program the entire EEPROM1 array (except
address $\$ 100$ ) with nn . This command may take some time to execute as firstly the entire array is erased, then each byte is programmed in turn.

If non-hex data is entered, then the following commands are available:

| Z | Program the entire array (except address |
| :---: | :---: |
|  | \$100) with Data = Address, i.e. |
|  | Address \$100 = not programmed |
|  | Address \$101 = \$01 |
|  | Address \$102 = \$02 |
|  | Address \$103 = \$03 ...etc. |
| P | Program a chequer-board pattern |
| Q | Program an inverse chequer-board pattern |
|  | Any other character will exit this command. |
| Ennnn | Start execution at address nnnn |
| C | Continue program execution according to the current program counter, accumulator, index register and condition code register stored on the stack. |
|  | BREAKPOINTS AND INTERRUPTS |

The SWI instruction may be used as a breakpoint. To continue following a breakpoint first replace the SWI with another command (such as NOP) then type ' $C$ ' to continue.

The interrupt vectors point to the RAM as shown below, and are spaced three bytes apart allowing the use of a JMP or BRA instruction to a service routine located in either RAM or EEPROM1.

| Vector | Address |
| :--- | :--- |
| SCI | \$00DF |
| Timer Overflow | \$00E2 |
| Timer O/P CMP | \$00E5 |
| Timer I/P CAP | \$00E8 |
| IRQ | \$00EB |
| SWI | \$08A6 |
|  |  |
| RESET | $\$ 0 C 22$ |

Pointing to monitor for breakpoint Start of monitor code


Figure 1-68HCO5B6 Monitor Circuit Diagram



* $===========================$



PAGE


```
            ORG ROMO
            FCC /Rev /
            FCB REV
            FCC /./
            FCB REL
            FCC / /
ONE ROUTINE IN PAGE O - JUST FOR THE (C) HECK OF IT
PCC --- PRINT CONDITION CODE REGISTER
*
PCC LDA STACK+1 GET CCR
    ASLA MOVE H BIT TO BIT 7
    ASLA
                        ASLA
                        STA GET SAVE IT
        CLRX
PCC2
LDA CCSTR,X PICKUP APPROPRIATE CHAR
PCC3 JSR PUTC PRINT '.' OR CHAR
            INCX POINT TO NEXT IN STRING
            CPX #5 5 BITS ARE GOOD ENOUGH
            BLO PCC2
            RTS
*
* Fill page 0 ROM
*
    FCC /O123456789AB/
*
```

```
            PAGE
                    ORG ROM2
*
* NOW, OTHER ROUTINES IN MAIN EEPROM
*
* TABLES
*
BBTBL FCB $A,$14,$28,$50
```




```
* MEMDIS - MEMORY ADDRESS CHANGE (FOR REGISTER DISPLAY)
*
MEMDIS JSR DISADD PRINT PRESENT ADDRESS
    JSR GETBYT GET NEW VALUE
    BCS BLEEP RETURN FOR NON VALID INPUT
    STA MEMADD
    BRA MAIN
    RETURN
*
* MEMORY - MEMORY EXAMINE / CHANGE
*
MEMORY JSR MEM8 GET ADDRESS
MEM2 BCS 
        JSR PRADD PRINT CURRENT ADDRESS
        JSR PRDAT AND ASSOCIATED DATA
        JSR GETBYT TRY TO GET A BYTE
        BCS MEM3 MIGHT BE A SPECIAL CHAR
MEMA JSR DROP OTHERWISE, PUT IT AND CONTINUE
MEM4 JSR BUMP GOTO NEXT ADDRESS
        BRA MEM2 AND REPEAT
MEM3 CMP #SAME RE-EXAMINE SAME ?
        BEQ MEM2 YES, RETURN WITHOUT BUMPING
        CMP #FWD GO TO NEXT ?
        BEQ MEM4 YES, BUMP THEN LOOP
        CMP #BACK GO BACK ONE BYTE ?
        BEQ MEM5 YES, GO DECREMENT ADDRESS
        CMP #ASCII NEXT VALUE ASCII ?
        BEQ MEM9 GO READ VALUE
        CMP #PLUS INCREMENT DATA ?
        BEQ MEM6 YES, GO READ DATA
        CMP #MINUS DECREMENT DATA ?
        BNE BLEEP NO, EXIT MEMORY COMMAND
*
        JSR PICK GET THE DATA BYTE
        DECA
        BRA MEM7 AND GO PUT IT BACK
MEM6 JSR PICK GET THE DATA BYTE
MEM7 JSR DROP PUT IT BACK
        BRA MEM2 READY
*
MEM5 DEC GET+1+LO DECREMENT LOW BYTE
        LDA GET+1+LO CHECK FOR UNDERFLOW
        CMP #$FF
        BNE MEM2 NO UNDERFLOW
        DEC GET+1+HI
        LDA GET+1+HI SAME FOR HIGH BYTE
        CMP #$FF
        BNE MEM2 OK
        LDA #$1F HIGHEST ADDRESS IS $1FFF
        STA GET+1+HI
        BRA MEM2
    MEM9 JSR GETC READ 1 BYTE
```

```
BRA MEMA
*
MEM8 JSR
```

```
BCS
STA
JSR
BCS
STA RTS MEND
*
* BULKW 
*
*
*
*
BULKW LDX #01
    STX GET+1+LO
    STX GET+1+HI SET UP ADDRESS $101
NXTBTR BSR BYTEW BYTE WRITE
    JSR BUMP
    BRCLR 1,GET+1+HI,NXTBTR LOOP
    RTS
*
* BULKE -- BULK ERASE OF EEPROM1 - A IS UNCHANGED
* SEE ABOVE ABOUT BULK OPS
*
BULKE CLR GET+1+LO
    LDX #O1 SET UP ADDRESS
    STX GET+1+HI
NXTBTE BSR BYTER BYTE ERASE
    JSR BUMP
    BRCLR 1,GET+1+HI,NXTBTE LOOP
    RTS
*
* PRESET - EEPROM SET OR ERASE
*
PRESET JSR GETBYT GET DATA BYTE
    BCS BLEEPZ MAY BE SPECIAL COMMAND
    BSR BULKE ERASE E2PROM
    BSR BULKW WRITE E2PROM
MAINT JMP MAIN RETURN
*
BLEEPZ CMP #'Z DATA = ADDRESS ?
    BEQ DADD
    CMP #'P CHCKBOARD 5'S ?
    BEQ PS5 S
    CMP #'Q CHCKBOARD A'S ?
    BEQ PSA ELSE FALL INTO BLEEP
*
*
BLEEPK LDA SCDAT CLEAR RX STATUS
BLEEPR JMP BLEEP
*
*
* DADD --- PRESET EEPROM WITH DATA = ADDRESS
```

```
*
DADD LDA #$01 BOTTOM OF EEPROM
STA GET+1+HI
DADLP STA GET+1+LO ADDRESS LSB
    BSR BYTEW WRITE DATA IN A
    INCA NEXT ADDRESS, NEXT DATA
        BNE DADLP NO OVERFLOW YET
DADND BRA MAINT JOB DONE
*
* CHECKBOARD PATTERNS
*
PS5 LDA #$55 START VALUE
    BRA PSC
PSA LDA #$AA
* PSC LDX #01
    STX GET+1+LO
    STX GET+1+HI
STA ATEMP
AX25 LDA #$OF
    AND GET+1+LO
    BNE TNC
    COM ATEMP
* TNC LDA ATEMP
    JSR BYTEW
    JSR BUMP
    BRCLR 1,GET+1+HI, AX25
    BRA DADND
*
* BYTEW -- BYTE WRITE TO EEPROM1 - DATA IS IN A
* ADDRESS IN GET+1&2 - A IS UNCHANGED
*
BYTEW STA FLAG SAVE A
    BSET .E1LAT,EECONT PROG LATCH ENABLE
    JSR DROP1 PUT ADDRESS + DATA
    BSET .E1PGM,EECONT
    LDA WRITEK GET WRITE TIMING CONSTANT
    JSR ADJDEL
    BCLR .EILAT,EECONT END OP
    LDA FLAG RESTORE A
    RTS
*
* BYTER -- BYTE ERASE - A IS UNCHANGED AND ADDRESS
* IS IN GET+1 HI & LO
*
BYTER STA FLAG SAVE DATA
    BSET .EILAT,EECONT PROG LATCH ENABLE
    BSET .EIERA,EECONT
    JSR DROP1 PUT ADDRESS
```






```
    A HAS BYTE TO STORE AND GET+1 HI & LO POINTS
        TO LOCATION TO STORE, A AND X ARE
        UNCHANGED AT EXIT
        THE FLOW IS DIFFERENT WHETHER FOR RAM OR EEPROM
DROP BSR TSTEE WITHIN EEPROM ?
    BCC DROP1 NOT EEPROM
    JSR BYTER ERASE BYTE
    JSR BYTEW WRITE BYTE
    RTS
DROP1 STX
    INX XTEMP SAVE X
    LDX #$D7 $D7 = STA 2-BYTE INDEXED
*
*
COMMON STX GET PUT OPCODE IN PLACE
    LDX #$81 $81 = RTS
    STX GET+3 NOW THE RETURN
    CLRX WE WANT ZERO OFFSET
    JSR GET EXECUTE THIS MESS
    LDX XTEMP RESTORE X
    RTS AND EXIT
*
* TSTEE -- TEST THE ADDRESS IN GET+1 HI & LO AND RETURN
* WITH CARRY SET IF IT IS A VALID EEPROMI
* ADDRESS, AND CLEARED OTHERWISE.
*
TSTEE LDX GET+1+HI 
    BNE NOEE NOT EEPROM1
    SEC
    RTS
NOEE CLC
    RTS
*
*
* BUMP --- ADD ONE TO CURRENT MEMORY POINTER
* A AND X UNCHANGED
*
BUMP INC GET+1+LO INCREMENT LOW BYTE
    BNE BUMP2 NON-ZERO MEANS NO CARRY
    INC GET+1+HI INCREMENT HIGH NYBBLE
BUMP2 RTS
*
* OUT4HS - PRINT BYTE POINTED TO AS AN ADDRESS AND
* BUMP POINTER - X IS UNCHANGED AT EXIT
```

```
OUT4HS BSR PICK GET HIGH BYTE
    BSR PUTBYT AND PRINT IT
    BSR BUMP GO TO NEXT ADDRESS
* FALL INTO OUT2HS
* OUT2HS - PRINT BYTE POINTED TO, THEN A SPACE,
*
*
OUT2HS BSR PICK GET THE BYTE
    BSR PUTBYT
    BSR BUMP GO TO NEXT
    BSR PUTS FINISH UP WITH A SPACE
    RTS
*
* DISADD - PRINT ONE BYTE ADDRESS IN MEMADD
*
DISADD LDA MEMADD GET ADDRESS
    STA GET+1+LO SET UP TO PRINT
    BSR PRADD1 PRINT ADDRESS (PAGE 0)
    RTS
*
* PRADD -- PRINT CURRENT ADDRESS FROM GET+1 HI & LO
*
PRADD LDA GET+1+HI PRINT CURRENT LOCATION
    AND #$1F max $1FFF
    STA GET+1+HI CONVENIENTLY RESTORE 1X
    BSR PUTBYT
PRADD1 LDA GET+1+LO
    BSR PUTBYT
    BSR PUTS THEN A SPACE
    RTS
*
* PRDAT -- PRINT DATA POINTED TO BY GET+1 HI & LO
*
PRDAT BSR PICK GET THAT BYTE
    BSR PUTBYT PRINT IT
    BSR PUTS ANOTHER SPACE
    RTS
*
* PUTBYT - PRINT £A| IN HEX - A AND X UNCHANGED
*
PUTBYT STA GET SAVE A
    LSRA
    LSRA
    LSRA
    LSRA SHIFT HIGH NYBBLE DOWN
    BSR PUTNYB PRINT IT
PTSN LDA GET
    BSR PUTNYB PRINT LOW NYBBLE
    RTS
*
* PUTNYB - PRINT LOWER NYBBLE OF A IN HEX
* A AND X UNCHANGED
* HIGH NYBBLE OF A IGNORED
*
```

```
PUTNYB STA
        AND
        ADD
        CMP
        BLS
        ADD
PUTNY2 JSR
    LDA
        RTS
*
* CRLF --- PRINT CARRIAGE RETURN - LINE FEED
A AND X UNCHANGED
CRLF STA
    LDA
    JSR
    LDA
    JSR
        LDA
        RTS
*
* PUTS --- PRINT A SPACE - A AND X UNCHANGED
*
PUTS STA GET SAVE A
    LDA #SPACE
        JSR PUTC
        LDA GET RESTORE A
        RTS
*
* GETBYT - GET A HEX BYTE FROM TERMINAL
*
* A GETS THE BYTE TYPED IF IT WAS A VALID HEX
* NUMBER, OTHERWISE A GETS THE LAST CHAR TYPED.
* THE C-BIT IS SET ON NON HEX CHARS, CLEARED
* OTHERWISE. X IS UNCHANGED IN ANY CASE.
*
GETBYT BSR GETNYB BUILD BYTE FROM 2 NYBBLES
    BCS NOBYT NON HEX CHAR
        ASLA
        ASLA
        ASLA
        ASLA
        STA
        BSR
        BCS
        ADD
NOBYT RTS
*
* GETNYB - GET HEX NYBBLE FROM TERMINAL
*
* A GETS THE NYBBLE TYPED IF IT WAS IN THE RANGE 0-F,
* OTHERWISE A GETS THE CHARACTER TYPED. THE C-BIT IS
* SET ON NON HEX CHARACTERS, CLEARED OTHERWISE.
* X IS UNCHANGED
```

```
GETNYB BSR GETC GET THE CHARACTER
    STA GET+3 SAVE IT JUST IN CASE
    SUB #'O SUBTRACT ASCII ZERO
    BMI NOTHEX WAS LESS THAN 'O'
    CMP
    BLS
    SUB #'A-'9-1 FUNNY ADJUSTMENT
    CMP #$F TOO BIG ?
    BHI
    CMP
    BLS
GOTIT CLC
    RTS
NOTHEX LDA
    SEC
    RTS
*
* ADJDEL - DELAY FOR EEPROM ROUTINES = TO £A| ms
ADJ10 LDA #10
ADJDEL LDX #83 CONSTANT
AL1 BRCLR 4,ADSTCT,*+3 DUMMY
    BRCLR 4,ADSTCT,*+3 DUMMY
    BRCLR 4,ADSTCT,*+3 DUMMY
    BRN * DITTO
    DECX
    BNE ALI
    DECA
    BNE ADJDEL LOOP A TIMES
    RTS
*
*
* PUTMSG - PRINT THE MESSAGE POINTED TO BY X
*
PUTMSG LDA CMA,X GET NEXT CHARACTER
    CMP #EOT
    BEQ NDMSG
    BSR PUTC SEND CHAR
    INX
    BRA PUTMSG
NDMSG RTS
*
*
*
* SERIALII/O ROUTINES
*
* Initialise the SCI
SCINIT BCLR MBIT,SCCR1 8 data bits
LDA #%11000000 baud rate 9600
STA BAUD
LDA #%00001100 TE / RE
STA SCCR2
STA SCSR
```

```
end of init
```

end of init
clear TDRE \& TC bits

```
clear TDRE & TC bits
```

```
RTS
*
* GETC : Routine GETC services the SCI, it does that by polling
* the RDRF (received data ready flag). It returns with
* the byte of data in ACCA.
*
GETC BRCLR .RDRF,SCSR,* Possibly wait for char
GDATA LDA SCDAT get data & clear RDRF
    CMP #'/ NEXT CHAR ASCII ?
    BNE CHARS
    DEC ASC
        RTS
CHARS BRSET 7,ASC,SCHAR
    CMP #$40
    BLS NOCHAR
    AND #%1011111 UPPER CASE
SCHAR CLR ASC
NOCHAR RTS
*
*
* PUTC : Routine PUTC services the SCI. It polls the TDRE
* (Tramsmit Data Register Empty), and puts the char
* when true.
*
PUTC BRCLR TDRE,SCSR,* WAIT
    STA SCDAT
    RTS
*
```



```
*
* MONIT - ENTRY POINT FROM RESET
*
MONIT LDA #10 10 ms BY DEFAULT
    STA ERASEK SET ERASE DEFAULT TIME
    STA WRITEK SET WRITE DEFAULT TIME
    JSR SCINIT INIT SCI
    LDA #ADDATA
    STA MEMADD DISPLAY ADR BY DEFAULT
    JSR CRLF START A BRAND NEW LINE
    CLRX POINT TO START OF MESSAGE
BABBLE LDA MSG,X GET NEXT CHARACTER
    BRCLR 4,PORTD,BAB1 ROM MESSAGE
    LDA EEPROM+1,X GET NEXT CHAR (EEPROM1 MESSAGE)
BAB1 CMP #EOT
    BEQ BABND IF END OF MESSAGE
    BSR PUTC PRINT IT
    INCX POINT TO NEXT CHAR
    BNE BABBLE MORE !
BABND JSR CRLF SEPARATE MESSAGE FROM COMMANDS
    SWI GO TO MONITOR ROUTINES
    BRA MONIT LOOP AROUND
```

```
*
* EEPROM1 BURN IN TEST ROUTINE.
* SET UP REQUIRED NB OF ITERATION IN $70:$71
* AND DATA TO BE PROGRAMMED IN $72.
* NOTE : MAXIMUM NB OF ITERATION IS $7FFF.
*
*
ABCNT EQU $70
ABDAT EQU $72
*
ABCD JSR CRLF
ABL LDA ABDAT
    JSR BULKE
    JSR BULKW
    LDA ABCNT+LO
    DECA
        STA ABCNT+LO
        CMP #$FF
        BNE NOBURO
        DEC ABCNT+HI
        BMI NDAB
NOBURO LDA ABCNT+HI
        JSR PUTBYT
        LDA ABCNT+LO
        JSR PUTBYT
        JSR CRLF
        BRA ABL
NDAB SWI
*
```



```
*
* VECTORS
*
* The unused vectors point to RAM, so as to be available
* for test purposes (RAM Bootloader, SCI loader). Their
* positionning allows }10\mathrm{ bytes for the stack, that is 2
* interrupt levels, or 1 interrupt and 2 subroutine levels.
*
FDB STACK-9-18 SCI
FDB STACK-9-15 TIM OVF
FDB STACK-9-12 TIM OUT COMP
FDB STACK-9-9 TIM IN CAP
FDB STACK-9-6 IRQ
FDB MAIN SWI
FDB MONIT RESET
*
```



```
*
* E N D
*
```

END

# EB400 

# An introduction to SECURE SINGLE CHIP MICROCOMPUTER MANUFACTURE 

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## INTRODUCTION

Motorola is one of the world leaders in the design and manufacture of advanced semiconductor devices. We have a major manufacturing capability at East Kilbride, in Scotland's "Silicon Glen", where we manufacture many of our latest microprocessor products-primarily for the European market, though we ship product world-wide, including to Japan and the U.S.A. Our business is in selling silicon; within this overall goal however we have, for more than a decade, worked on developing the necessary technology, design and manufacturing techniques required to produce a range of secure microcomputer products specifically for the SmartCard marketplace.

One of the most important and fundamental issues for SmartCards is security. There are many financial, commercial, industrial and even military applications for SmartCards which are viable only if they can provide the appropriate levels of security demanded by such applications. This brings us to the title of this Engineering Bulletin, does it mean "manufacture of secure microcomputers" or "secure manufacture of microcomputers"? Motorola is perhaps unique among today's silicon suppliers in that it can provide microcomputers both designed from the outset to be secure and from a secure manufacturing line. We recognise that the overall security of any application is dependent not only on the intrinsic security of the device itself and its ability to prevent unauthorised access, but also on the measures taken by the semiconductor supplier to prevent fraudulent tampering with the device during and after manufacture. The customer's application software is also a critical link in
the security chain. If the semiconductor manufacturer wants to play an active part in the SmartCard marketplace, he must recognise security as a key parameter in everything from the conceptual design of a new microcomputer, through his manufacturing process, even to his delivery of the product to his customer.

Security in relation to microcomputers used for SmartCards can be grouped into three main categories:

## 1. Designed-in ("intrinsic") security

2. Manufacturing security
3. Application security

Clearly Design and Manufacturing Security are the responsibility of the semiconductor manufacturer, and are the main subjects of this Engineering Bulletin. Application Security on the other hand is ultimately the responsibility of the SmartCard systems designer. His task is to design the (secure) application software required to meet the system specification of, for example, a financial transaction or an industrial security application. Application security takes into consideration the design of the chip and the on-chip security features which can be utilised by the user's application software. But even here the semiconductor manufacturer has a role to play; the manufacturer needs to be able to provide Applications Engineers well versed in the hardware and software features of his microcomputers and of their development support tools, to act as consultants in helping customers develop their own hardware and software.

This Engineering Bulletin will start by defining what we mean by a single chip microcomputer and what is fundamentally different about a secure one; then it will look briefly at the history of Motorola's involvement in this business, and how it has developed its SmartCard product line capability over the last decade to where it is today. Some of the techniques available to the design engineer which allow him to include security features in the device itself will be explored, along with the constraints placed on him by the demands of the SmartCard market and the need to test these devices. It will look very briefly at the wafer fabrication process and what security measures can and must be taken. Finally, it will consider the device testing process, and the particular problems associated with the testing of secure microcomputers.

## SINGLE CHIP MICROCOMPUTERS

What do we mean by a single chip microcomputer, and what is special about a secure one? A single chip microcomputer (commonly referred to as an MCU) is a full microprocessor system integrated on to a single piece of silicon. It is a complete computer system in miniature, containing almost all the resources required to implement a particular application, or range of applications. In addition to the Central Processing Unit (CPU) and its control circuitry, it typically contains blocks of different types of memory, and a selection of hardware functions, optimised for general or sometimes very specific application areas. The only com-puter-like resources it lacks are the external human or machine interface devices such as keyboards, displays, disk drives, transducers and sensors. Most MCUs contain, at the very least, areas of random access memory (RAM) and read only memory (ROM). The RAM is used by the CPU for temporary data storage during calculations and transactions. Data can be read from or written to the RAM by the CPU in the

Fig. 1: General Purpose Microcomputer
space of a few microseconds, however any data in the RAM is lost when the electrical power supply is removed. The ROM area is used to store information which will not change throughout the working life of the MCU. Primarily it is used to store the customer's application software (known as the user software or "ROM code"). This controls the sequence of logical operation and decision making of the CPU. It can also contain any fixed data, in the form of look-up tables for example, which may be required by the application. All this information is built into the ROM during the silicon manufacturing process and can never be altered after the manufacturing process is complete. MCUs incorporating arrays of non-volatile memory, such as EPROM (erased by UV light) and EEPROM (electrically erasable) are available for applications where variable data has to be kept for long periods of time, even when power is removed from the MCU. This is particularly important in SmartCard applications where transaction data and other records must be updated every time the card is used (possibly several times a day depending on the type of application) and which must be retained for weeks, months, or even years in some cases. Typical on-chip hardware functions for general applications are simple counter/timers, byte-wide I/O ports and serial communications interfaces.

An important thing to realise is that most typical single chip microcomputers are designed to function in a number of different operating modes which can be selected by the user. In the single chip user-mode, which is the normal mode of operation in most applications, the CPU runs under the control of the user software built into the on-board ROM. Some MCUs support expanded-mode operation where internal data and address buses are connected to the I/O pins to allow the CPU to access additional memory and I/O outside the MCU. Other operating modes are provided for testability.


Fig. 2: Secure Single-Chip Microcomputer

A secure single chip microcomputer can include any or all of the features just described, but it also has the built-in capability to prevent, by various means, unauthorised access to the CPU, the memory arrays, the user/application software, and any data being processed or stored within the device, at any time. After it has been tested and passed as fully functional by the semiconductor manufacturer, the only possible mode of operation for a secure microcomputer must be the user-mode, i.e. under the complete control of the user software in the on-board ROM.

## HISTORY

In 1977 Motorola (working with one of its European customers) began a feasibility study concerned with putting a microcomputer and a non-volatile memory within an ISO7810 credit card. This solution was fully functional by 1979. As a result of evaluation and feasibility studies it soon became apparent that "multi-chip computer" solutions have a number of inherent disadvantages which can detract significantly from their suitability for secure, reliable, high-volume SmartCard applications. In multi-chip solutions, the interconnections forming the control and data buses between the chips are easily accessible from the outside world and the data being transmitted across them may be intercepted and monitored. This can seriously limit the inherent security of such a multichip solution. In single chip solutions however the interconnections are buried deep within the structure of the silicon die and, in devices intended for SmartCard applications, the silicon designer can use a variety of techniques to ensure that these interconnections cannot be accessed from the outside world. Multi-chip solutions are also inherently less reliable and usually more expensive than single chip solutions because physical stresses can damage the external interconnections and fabrication, test and assembly


Fig. 3: Development History
costs have to be incurred for each chip. We believe therefore that the concept of a single chip microcomputer solution is important to the successful realisation of secure, reliable, high-volume SmartCard applications.

Work began in Motorola's European Design Office in Geneva in 1980 on the design of a SmartCard chip to a general specification agreed with a potential customer. The design was based upon the CPU of the highly successful M6805 single chip MCU, with 8 K bits of UV erasable memory (EPROM), as well as RAM and ROM. This was all integrated on a single NMOS technology silicon chip of less than $20 \mathrm{~mm}^{2}$. The merging of EPROM and NMOS MCU technologies on one piece of silicon was a new area for Motorola and our Advanced Products Research and Development Laboratory (APRDL) was given the task of designing and developing a completely new wafer fabrication process to support this combined technology. First silicon was successfully produced in APRDL in 1981, and in 1982 the new production process was transferred from APRDL to the volume wafer fabrication facility in East Kilbride, Scotland where the world's first single chip SmartCard MCU then went into full production.

Since then the advent of HCMOS technology and the ability to integrate electrically erasable memory arrays on the same chip have resulted in the extension of the family of SmartCard microcomputer chips based on the M6805 CPU. This family offers various combinations and sizes of RAM, ROM, EPROM and EEPROM areas. Other families of high-performance, highfunctionality MCUs which have been developed in parallel with the SmartCard family, notably the $68 \mathrm{HC} 05 \mathrm{~B}-, 68 \mathrm{HC} 05 \mathrm{C}$ - and $68 \mathrm{HC11}$ - families, are ideal for controlling SmartCard readers, keyboards, communications channels and interface devices.

Now, in 1990, East Kilbride is Motorola's world-wide centre of excellence for SmartCard product and manufacturing technology and, as a result of its ongoing commitment to this emerging market, has so far shipped more than 20000000 SmartCard devices.

## DESIGN SECURITY

The silicon designer's task is never an easy one, but it is particularly difficult when the end product is intended for SmartCard applications. There is a continual trade off between what the market demands and what it is willing to pay for in terms of functionality. One of the main reasons why general purpose single chip MCUs are not a cost effective solution for SmartCard applications, forgetting for the moment the lack of in-built security, is that a considerable area of silicon is wasted supporting functions which are not really
necessary for this type of application. All they serve to do is to increase the die size which increases the cost of production, and hence the price of the end product. The relative quantities of different types of on-chip memory is another key issue. The SmartCard market has a voracious appetite for non-volatile memory. However an EPROM cell uses roughly twice the silicon area of a ROM cell, and an EEPROM cell is about twice the size of an EPROM cell. In other words, if the target die size can accommodate 8 K bytes of ROM, the customer can have approximately 4 K bytes of EPROM or $2-3 \mathrm{~K}$ bytes of EEPROM instead. This is very much an oversimplification as for example each type of memory has a different requirement for decoding and programming circuitry, which also add to the silicon area. Also, the combination of non-volatile memory technologies and NMOS and HCMOS semiconductor technologies makes the manufacturing and testing processes much more complex and expensive. Although technological advances have helped reduce the dimensions of non-volatile memory cells, EPROM will always be more expensive than ROM, and EEPROM will be more expensive still. RAM is the most expensive type of memory in terms of silicon area. Fortunately, very large arrays of RAM are not usually required for SmartCard applications, though this does put pressure on cryptologist-programmers to use the available RAM very efficiently.

The result of the silicon designers' efforts may well be a masterpiece of design ingenuity with a functional specification second to none, but it also has to be manufacturable, in very high volumes, at the right price for the end customer - hence it has to be testable, quickly and thoroughly. Testing of a microprocessor device is usually achieved by accessing the data, address and control buses via the pins which electrically connect the internal circuitry of the device to the outside world. This is fairly easy to achieve with standard microprocessor devices which are intended
for multi-chip applications, as their data, address and control buses appear on the pins of the device, and are designed to allow easy interface to external memory and interface chips. It is considerably more difficult to achieve in most single chip microcomputers. However the design engineer usually incorporates a test mode which makes the internal bus connections externally accessible, by switching them onto the various I/O pins leading to the outside world.

Single chip MCUs intended for SmartCard applications present the silicon designer with a number of special problems. The device circuitry must be designed in such a way that, after testing, the test mode can be permanently disabled to prevent this mode from being reactivated. The device must then operate only under the control of the user application software.

Single chip MCUs for SmartCards do not need a large number of connections to interface to the outside world. (The current ISO standard, which specifies a serial half duplex system, defines six connections, plus two reserved for future use.) Although this presents the designer with the opportunity to save on valuable silicon area, it introduces the additional problem of how to provide access to the internal circuitry, when there are insufficient I/O lines available to connect the internal buses to the outside world. This problem can be overcome by adding special test connections to the device, which are not connected when the device is packaged in a SmartCard, or by utilising serial communication techniques during testing. However, extra test pads add to the total silicon area of the die, and serial communication adds to the testing time, both of which ultimately add to the cost. Motorola's designers have developed a number of techniques and features which ease the testing burden and reduce the test time of the device. These features are disabled by blowing fusible links upon completion of the test.


Fig. 4: Outline of MCC68HC05SC11/SC21 die showing the effect of cell complexity on the respective memory areas


Fig. 5: General Purpose Microcomputer


Fig. 6: Secure Microcomputer

Fusible links can be incorporated in the circuit design to connect the I/O lines to the internal data bus and other parts of the internal circuitry. These fusible links form part of the normal interconnecting layers embedded in the device during the wafer fabrication process. After testing is complete, these fuses are blown. In non-volatile memory arrays (EPROM and EEPROM) special bits or bytes can be provided within the array which allow the CPU to detect attempts to illegally erase the memory. These bits can be programmed only during testing, before the fuses are blown. Any attempt to erase the memory array will irrevocably alter the state of these bits. In some designs, it is left to the application software to decide on an appropriate course of action if such a condition is detected. In other designs, the CPU stops processing - permanently.

The layout of the circuitry of a semiconductor device on the silicon die is usually done in a fairly logical manner. However, the SmartCard chip designer can use a number of techniques to confuse anyone who may try to analyse the design. Communication buses and control lines can be routed through different masking layers rather than being routed by the most direct path. Memory topology can be made very complex with logically adjacent bits and bytes being physically distributed over the memory space. Also, dummy structures resembling transistors can be distributed within the integrated circuitry on the die.

## WAFER FABRICATION

Over the last 10 years or so Motorola has progressed from $5 \mu \mathrm{~m}$ NMOS technology on 75 mm wafers to $1.5 \mu \mathrm{~m}$ low-power HCMOS technology on 150 mm wafers. The significant reduction in line widths has allowed larger memory arrays, new memory technologies, and more functional circuitry to be incorporated


Fig. 7: Wafer Fabrication
in today's state of the art devices without increasing the die area. Unfortunately, this wonderful new technology does not come cheap. The capital investment in state-of-the-art wafer processing and test equipment is extremely high. A modern wafer fabrication facility such as the one Motorola has built in Scotland costs about $£ 200$ million to build and equip. This in itself may be viewed as an additional security feature against fraudulent manufacture!

The production process which turns raw silicon into finished wafers involves a very large number of process steps. In simple terms it is a multi-layer technology using techniques similar to photographic printing. The electronic circuit is converted into a number of layers which contain different elements of the circuit components: the interconnections; the bus lines; the bonding pads; the memory cells; and so on. Each layer is then converted into a photographic mask. (One of these masks contains the application software and customised data supplied by the end customer.) Each mask, and there can be as many as 15 in some complex device technologies, is then used in a series of exposure, print and development cycles as the electrical circuit is built up on the silicon wafer. In addition, a number of diffusion, oxidation and implant processes are used at different stages of the process to create the correct electrical and functional characteristics of the semiconductor device. The wafer fabrication process for producing secure microcomputers is essentially no different from any other type of microprocessor or microcomputer. However the inclusion of EPROM or EEPROM arrays makes the process much more complicated due to the extremely critical nature of such parameters as gate and interlevel oxide thicknesses and silicon defectivity.

## MANUFACTURING SECURITY

I have just reviewed the standard wafer fabrication process. What does the semiconductor manufacturer have to do differently when the product can end up in a SmartCard application, possibly representing a considerable sum of money or controlling access to bank accounts, personal information or to high security areas?

Security must be the watchword at every stage of the process. In Motorola, for any single chip MCU, the customer's application software (the ROM code) is converted into a set of geometric coordinates and dimensions, which are stored on a pattern generation tape. This tape is then used to produce one of the masks used in the wafer fabrication process.

For SmartCard MCUs the customer's software is processed, and the pattern generation tape produced, via a special restricted-access account on Motorola's internal computer system. Transfer of the tape to mask shop and of the ROM code mask and tape back to the factory is done by special courier. The mask is then safely stored within the wafer fabrication area which is itself a highly restricted area.

During the wafer fabrication process the wafers are strictly controlled on a batch basis up to the start of the metallisation process. From then on, each wafer is tracked and traceable individually, as the devices are essentially functionally complete after metallisation. As well as having various access controls to the manufacturing areas every wafer entering the metallisation stage is fully accounted for (even to the number of good dice on each wafer, once that is determined) from then on until it is either shipped to the customer or destroyed in a secure manner.

## TESTING OF NON-SMARTCARD DEVICES

The finished wafers move from the wafer fabrication line to the probe area for testing. Testing is done using a "stored response" technique. A comprehensive sequence of test signals (or vectors) is applied by the testing computer to the probe and bonding pads of each die and the resulting response signals are compared with a stored sequence of the expected responses. Any discrepancy between the actual and the expected response sequences indicates a defective device. (The device must pass every single vector in the test pattern, possibly tens of thousands of lines, to pass the test.) Parametric type tests, such as supply and leakage current measurements, are also performed.

Every die is tested for total functionality and performance to the device specification, including verification of the customer's application software in ROM. During the probe test any defective die can be physically marked or located on a wafer map to eliminate any further work on such non-functional devices. The wafers are then fixed to an adhesive plastic film before being sawn to separate the individual dice. If the devices are being supplied to the customer in packaged form, the wafers are then sent for assembly where the dice are assembled into the appropriate packages. They are then final tested and shipped to the customer via standard commercial carriers.

## TESTING OF SMARTCARD DEVICES

In the factory in East Kilbride the SmartCard probe test area and all its test equipment is completely dedicated to SmartCard products and access is restricted to authorised personnel only. Each device is functionally and electrically tested as with non SmartCard product. The non-volatile memory is then erased and retested to ensure complete erasure of every cell. At this point traceability information (such as batch number, manufacturing location, test date etc.) can be written into each device together with any customer specific data, in accordance with the customer's instructions or algorithms; some of this data may be unique to each individual die. This part of the procedure is carried out via a dedicated computer system which has no communication links with the world outside the SmartCard probe area. Finally the security fuses on each die are blown.

After being sawn, the dice are ready to be shipped to the customer as complete wafers on their adhesive plastic film backing. The wafers are transported from the factory in East Kilbride to the airport bonded warehouse - and from the destination airport to the customer's premises - by armoured car. These wafers include not only good dice which have passed the test programme, but also any dice which have been identified and marked as defective. This allows the customer to account for each individual die, good or bad, on every wafer.

## IN CONCLUSION

I hope that this Engineering Bulletin has given you some insight into the design and manufacture of single chip microcomputers in general. I have tried to illustrate, through the experience gained by Motorola over the past twelve years, how the additional problems set by the need for total security of design and manufacture of single chip microcomputers for the

SmartCard market have been tackled and solved. The level of expertise and overall capability required by the semiconductor manufacturer to enable him to supply the right products to the SmartCard market cannot be achieved overnight. It is not sufficient to be a world leader in microprocessor technology, with a worldbeating product portfolio. The semiconductor supplier has to provide a product portfolio which includes devices designed with intrinsic security features specifically for embedding in SmartCards (or indeed in any other "security package"), and other devices with the on-chip features required for SmartCard reader and peripheral applications. Almost any general purpose MCU can be used in a SmartCard application. Some of the penalties of doing so, such as increased
die size and increased cost due to unnecessary on chip hardware and inefficient bonding pad layout, are immediately apparent; others will become obvious only when the security of such an application is put to the test, and fails to meet the necessary standards. The constraints imposed by the need for high levels of security at every stage of design and manufacture are considerable. Motorola has more than a decade of experience in volume SmartCard MCU production, and has the product portfolio required to meet all the needs of the SmartCardmarket in the world today. We are not standing still; we already have devices at advanced stages of planning and design to meet the emerging and future needs of this diverse market; we intend to remain ahead of the field.

## GLOSSARY

Byte (Kbyte) 8-bits of binary data (1024 bytes)
CPU Central Processor Unit - the "number cruncher" in an MCU
DIE, pl. DICE individual microcomputer (or other) device on silicon
$\begin{array}{ll}\text { EEPROM } & \text { NVM - may be erased by applying } \\ \text { special voltage }\end{array}$
EPROM NVM - may be erased by exposure to UV light

HCMOS High-density low-power MOS technology
I/O Input/Output communication lines
ISO (7816) International Standards Organisation (standard concerned with specifications for IC cards)
Mask Medium used to convert customers' application software (ROM Code) to a pattern on silicon
MCU (Single-chip) microcomputer unit
MiCROCOMPUTER A silicon chip containing a microprocessor - plus memory and other peripheral devices

NVM Non-Volatile Memory (for "permanent" storage)

RAM Random Access Memory - for temporary storage
ROM Read Only Memory - contents fixed during manufacture of the silicon and unalterable "ROM Code" is customer supplied application programme
"Silicon Glen" An area stretching across the central belt of Scotland containing the factories of many international electronics companies
Smartcard ISO credit card sized package containing a microcomputer
Test Mode Special operating mode for an MCU to allow comprehensive testing by the manufacturer prior to shipping to customer

USER MODE Normal operating mode for MCUs (cf TEST MODE)

Wafer Slice of silicon which, after processing, contains typically hundreds of individual dice; $100-150 \mathrm{~mm}$ in diameter

## EB401

## SCAM modules for Smart Cards

Motorola is launching its SCAM range of assembly modules by introducing its Smart Card product family packaged in modules suitable for insertion into ISO standard plastic cards).

8 -contact and 6 -contact modules will be available. These modules can be inserted in IS7810 plastic cards, in either the ISO standard location or the transitional location as defined in IS7816/2.

Both modules conform completely to the contact dimensions, locations and electrical connections defined in IS7816/2 (Dimensions and locations of the contacts).


TRANSITIONAL LOCATION - 8 CONTACTS

During the assembly process, all pins are shorted together to minimise the risk of damage due to static electrical discharge.

|  | MEMORY (BYTES) |  |  |  |
| :--- | :---: | :---: | :---: | :---: |
|  | RAM | ROM | EPROM | EEPROM |
| 6805 SC01 | 36 | 1600 | 1024 | - |
| $6805 S C 03$ | 52 | 2048 | 2048 | - |
| $68 H C 05 S C 11$ | 128 | 6144 | 8192 | - |
| $68 H C 05 S C 21$ | 128 | 6144 | - | 3008 |

Packaged in these modules, Motorola's secure microcomputer devices conform completely to the electrical characteristics defined in IS7816/3 (Electronic signals and transmission protocols).


ISO LOCATION - 6 CONTACTS

Motorola is the leading supplier of secure microcomputers for smart card applications, with over 20 million units supplied to date from our manufacturing facilities in Scotland and the U.S.

# EB404 

# "MEMORIES ARE MADE OF THIS..." ... a look at memory considerations for Smart Card applications 

By Mike Paterson Motorola Ltd. East Kilbride

## OVERVIEW

This paper discusses some of the issues concerning memory size and type and how they affect the specification of Secure Microcomputers for today's Smart Card marketplace. The principal premise is that: in the kind of mass market, multi-million unit per annum, application which is the main target of the Smart Card systems in use and under developmentat present, the cost is crucial to the success of a particular application.

From the silicon manufacturer's point of view cost is directly proportional to the area of silicon required (as a good first approximation at least). This paper therefore discusses the features and advantages of the different types of semiconductor memory, with particular attention to their cost in terms of silicon area, as they affect the typical uses required for Smart Card
applications. After discussing some of the possible trade-offs in the specification for a secuite miciónũiiputer there is a brief look at likely future developments in technology available for these devices. Europe leads the world in the design and implementation of Smart Card based systems, from bank payment cards to access control to medical records. Motorola echoes this trend through its unparalleled expertise gained from 13 years involvement in the specification, design and manufacture of secure microcomputer devices in Europe.

This paper presents an overview of the issues concerned with memory provision and utilisation for secure microcomputers used in Smart Card applications. It does not attempt an in-depth treatment of the technical nor the applications specific issues involved.


Figure 1: The evolution of Motorola's Secure Microcomputer family

## INTRODUCTION

The drive towards more and more data storage, and hence bigger and bigger memory sizes, seems to be an essential part of all modern-day electronic systems. Only a few years ago desktop "personal computers" were confidently marketed, and thankfully purchased, with only 8 kilobytes (kb) of memory. Even today the ubiquitous IBM PC ${ }^{\text {ns }}$ has a direct memory addressing capability of only 640 kb , whilst other desktop machines are now designed to have anything from 1 Megabyte ( $1 \mathrm{Mb}=1000 \mathrm{~kb}$ ) to several Gigabytes $(1 \mathrm{~Gb}=1000 \mathrm{Mb})$ of storage. This increase in the amount of readily accessible memory has been made possible by enormous advances in system architectures and in the way data is stored. The semiconductor memory has come a long way from the invention of the transistor fewer than 40 years ago. Today single pieces of silicon no larger than a fingernail can store more than four million bits of data, and at a cost per bit so small as to be undreamt of when the transistor was born.

The earliest "computers" used mechanical storage means (gears and cogs); this swiftly advanced to the use of the vacuum tube in the first electronic computers. The next step was the ferrite core memory - until recently still a firm favourite with military systems designers the world over. However the development of the transistor saw the realisation of physically small memory cells each capable of storing a single bit of information, a ' 1 ' or a ' 0 '. As the integration level (the number of transistors on a single piece of silicon) increased so then did the physical size of a given memory array fall. The decreasing physical size of memory has led inevitably in the market driven economy to a real fall in its price. Electronic goods are among the very few categories of consumer goods that have fallen in price in real terms over the last two decades and semiconductor memories have fallen (in price-per-bit terms) faster than any other commodity product.

The very success of memory design improvements and the ability to make the individual constituents of a memory cell ever smaller has in part fuelled the rush towards greater memory capacity. As more and more memory becomes available on a personal computer for example, so more and more sophisticated applications software becomes possible, which generates the need for large amounts of storage for the output of these very complex programs. The colour VDU is perhaps a good example, requiring as it does so much more memory than a simple black and white one: how often is 'colour' specified when black-and-white would be perfectly adequate, simply because it is readily available and has a perceived added value.

So memory is readily available, and cheap to buy, but does this necessarily mean that "more is better" is the right strategy to adopt? The danger is that the ready availability and low cost of memory may tend to obscure the benefits of making the optimum use of it. After all, no matter how small and cheap a memory cell becomes one cell will always be cheaper than two! The problem is that "more memory" is always the easy option when specifying a system and, as with colour VDU's, you then pay for it - whether you really need it or not.

These arguments are just as valid in the context of Smart Cards as they are in the example of the desktop computers quoted above. In addition, there is a further restriction when the silicon is destined for a credit card application: size. Size can become an issue not only of cost but of reliability, as plastic bends and silicon does not! Before we look in some detail at the particular needs of the Smart Card marketplace (and by Smart Card I mean by extension all application areas where a Secure Microcomputer is desired) we first need to understand a little about the different types of memory that are available.

## TYPES OF MEMORY

There are basically two categories of semiconductor memory: volatile and non-volatile. In this context the terms volatile and non-volatile simply differentiate between a memory cell's ability to retain data in the absence of electrical power (non-volatile), or not (volatile). However both of these categories break down into sub-categories, each with different features and disadvantages.

We will look at the volatile memory first, as it is the simpler of the two, there being only two subcategories. This type of memory is usually known as RAM (Random Access Memory) and can be divided into two main sorts, Static (SRAM) and Dynamic (DRAM). Both types of RAM are very versatile: they can be written to and read from with no special preparations; the writing/reading is very rapid; there is no practical limit to the number of read-write cycles that may be performed. These features make this type of memory useful for storage of any kind of data, from fixed program data to rapidly changing data (such as time of day for a clock function). However there are disadvantages. RAM loses its information when the power is turned off, thus it is not useful for program and fixed data. RAM cells are also comparatively large (requiring as they do up to six transistors to store just one bit of information) and consume significant amounts of power. The former means that a given amount of RAM takes up much more silicon area than the same amount of any other type of memory. The
latter varies from being a nuisance in some circumstances to a very real drawback when considering, for example, battery powered equipment.

The two types of RAM vary in the way that they store data. Dynamic RAM is smaller in area than Static RAM but needs to be continually reminded of whether it is storing a ' 1 ' or a ' 0 ' by means of a regular refresh (or clock) signal. Since Static RAM does not need this signal to be provided there is less system overhead, but a larger area of silicon is necessary because of the increased cell complexity. In an application therefore the system designer needs to understand whether he will always have a clock signal available when he needs to maintain RAM data. If there is any doubt about this (for example battery powered equipment frequently shuts off system clocks, whenever possible, to reduce power consumption) then he needs to specify Static RAM, and pay the penalty of increased size, and therefore price. [Static RAM has itself two variants (using either four or six transistors per cell) which allow a trade-off between power consumption and cell size.]

Non-volatile memory (NVM) is a more complicated subject. There are three main types of NVM currently available in volume production quantities with other types just coming on-stream, or currently existing in low volumes. For now we will look only at these three main types, and towards the end of this paper discuss briefly the opportunities and challenges offered by the new technologies.

The basic feature of NVM is the fact that it retains its stored data even in the absence of electrical power. This makes it ideal for permanent and semi-permanent data storage, though as we shall see its versatility is extending its use towards the RAM's domain of frequently changing data. Again there are two basic categories of NVM: alterable and non-aiterabie.

ROM (for Read Only Memory), or mask-ROM as it is also known, is the simplest form of NVM. Its contents are defined during manufacture of the silicon and this data is then unchangeable over the life of the device. This type of memory has the smallest cell size (only one transistor ) and is ideally suited to storing the fixed application software (operating system, program, fixed data tables etc.). However, there its usefulness ends. Since it cannot be changed after manufacture it follows that the only actions that it can perform and the only situations that the program stored in it can respond to are those thought of in advance and allowed for in the coding of the ROM contents. Because it is small and can be fully tested during silicon manufacture it is the best kind of memory to use if its features are sufficient. Even where an application demands the ability to change fundamentally during the life of the Smart Card there will be functions (such as input/ output routines) which can be fixed, and hence coded in the ROM, leaving the more expensive alterableNVM for data subject to change. There is one further advantage of ROM in the Smart Card context; because the contents are defined during manufacture, and cannot thereafter be altered, a level of security is


Figure 2: Some typical uses for the different types of memory in a Smart Card application
inherent in this memory. For example if an application program runs in ROM, and if this program is written such that it never allows the device to output a "secret code" stored on the card then there is no way to change this program to get the device to output the restricted data.

EPROM (Eraseable Programmable Read Only Memory) provides the next level of versatility over that of ROM. This behaves exactly like ROM when being read. However in certain circumstances the data stored in the EPROM cells may be changed. EPROM cells read as ' 1 ' or ' 0 ' dependent on the level of stored charge within each cell. Because of the construction of the EPROM cells it is possible, by using a comparatively high voltage, to change the state of the cell from, say, ' 0 ' to ' 1 '. This is a one way process. In order to return the cell to its original, or virgin state it is necessary to erase the entire memory array by exposing it to ultra-violet (UV) light. The UV light causes a shift in the threshold voltages of the transistors in the EPROM array so as to allow the stored charge to leak away and the cells to return to their original (zero) state. Obviously by its nature an EPROM array will all be erased at once, it is not possible to selectively erase particular data. Again in the case of Smart Cards this limitation can be used to advantage. The (fixed) ROM code can be made to check that some particular part of the EPROM array is programmed (i.e. is non-virgin). On failing to detect this situation the applications program knows that the EPROM array has been erased at some point and hence the integrity of any data now in the EPROM is suspect. Further operation can then be suspended, or any other predetermined action taken. Clearly also in a Smart Card it is normally not possible to erase EPROM anyway as the die is permanently covered by opaque plastic. This means that for these applications EPROM is a 'write-once' or one-time-programmable' type of memory.

To get round the final restriction of non-selective erasure we have to move towards the most complex, largest, and most versatile type of NVM, the EEPROM array. Electrically Eraseable Programmable Read Only Memory can behave exactly like EPROM but in addition offers the advantage of being able to selectively erase, and re-write specific bytes of data. Again the EEPROM cell, like that of the EPROM, uses stored charge to differentiate between a ' 1 ' and a ' 0 '. Again like the EPROM, by use of a higher than normal voltage it is possible to change the state of the cell from, say, ' 0 ' to ' 1 '. However this time the process is reversible and hence the cell state can be returned to ' 0 ' in this example by simply applying the correct voltages to the cell. A further advantage of EEPROM over EPROM is
the fact that because the programming/erasure currents involved are so small it is possible to generate the high voltage required for this on the silicon chip itself by using a 'charge pump', thereby removing the need for a separate high voltage power supply external to the chip. This is a significant design simplification and provides significant cost reduction in the Smart Card arena, where the number of external contacts is thus reduced from six to five. Additionally the Smart Card reader designer does not have to provide expensive, high tolerance programming circuitry like that necessary to support EPROM based cards.

However all this versatility has a price. As stated the EEPROM cell is more complex than any other type of non-volatile memory cell. It therefore takes up more space and hence costs more. Because EEPROM can be written to very easily it puts an additional burden on the system software designer in order that the integrity of the data can be guaranteed. For example: to return to our 'application running in ROM' quoted above. If this same application software is now run in EEPROM then it is possible to change the actions of the program (by simply rewriting some of the bytes containing that program) to provide an option that was previously non-existent. The software designer therefore has to ensure that his software guards against any possibility of an unauthorised user being able to gain control of the application program in order to make changes to its operation. Additionally further precautions, both in hardware and software, must be taken to minimise the chance of spurious data being written into the EEPROM, due to a power failure for example.

Because the EEPROM memory is so much more versatile it is consequently more open to abuse. This throws more dependence back on the inherent design of the hardware itself, as well as on the software. Security implemented as part of the hardware design of the device protects against a variety of ways that the memory contents could be compromised - for example by ensuring that there are checks after the device is reset to determine the contents of particular areas of EEPROM.

Alterable-NVM such as EPROM and EEPROM, by its physical nature, has a finite life in terms of data storage and therefore its integrity can be regarded as lower than that for the unchanging ROM cells. The "life" of EPROM or EEPROM is usually given in terms of data retention and write-erase endurance. Data retention is simply a measure of how long any particular information is guaranteed to be retained in memory after being written there with a given set of conditions (voltage, programming time, temperature etc.). Write-
erase endurance is quoted as the number of times that any individual cell may be written to and erased and still be guaranteed to correctly store data. Typical values are: 10 years for data retention; 10000 writeerase cycles for EEPROM endurance. EPROM is a more mature technology than EEPROM, and needs comparatively high currents to perform the programming (electrical erase being impossible). Therefore the data integrity of EPROM is generally regarded as being better than that of EEPROM, there being a lower probability of incorrect data being stored (or good data being erased) through the action of "electrical interference" (power surge/failure, etc.). There are of course ways to improve statistically the effective reliability of data stored in EPROM or EEPROM, for example by using intelligent programming algorithms, or by using error detection and correction techniques. Each of these methods can be implemented so as to achieve the most demanding of data integrity requirements. Hence the recommendation should be that: use the flexibility of EEPROM if it is needed; but if "write-once" EPROM is sufficient for the nature of the data being stored then use it in preference; and if the data is fixed then use ROM.

We can summarise the memory types as follows:

| RAM | The fastest and most versatile type of <br> memory; volatile |
| :--- | :--- |
| EEPROM | Slower than RAM, but retains data in the <br> absence of power |
| EPROM | For Smart Cards this is really a write-once <br> kind of memory |
| ROM | Data defined during silicon manufacture <br> and then unchangeable |



Figure 3: Outline of an actual $68 \mathrm{HCO5SC} 21$ die showing the effect of cell complexity on the respective memory areas

## MEMORY USE IN SMART CARD APPLICATIONS

Before we can look even briefly at the type of uses that memory is put to in a Smart Card application we first need to define "Smart Card". In this context I shall take a fairly narrow and literal definition. Thus the Smart Card is a device in ISO 7816 credit-card form containing a single-chip microcomputer. There are many other possible implementations which could give the same functionality, for example multiple-chip solutions, or key-fob shaped packages, etc.; the adoption of the above definition is merely to make the discussion simpler.

Whilst the possible applications for Smart Cards are limited only by the imagination of the systems designers in their ability to demonstrate added value, a number of common basic features are required. A Smart Card is by definition and intention an identification and authentication medium. No matter what actual use the card is being put to its fundamental purpose is to authenticate the card and its owner and to establish their level of entitlement; secondary functions such as payment, personal details, or data transfer are then used dependent on the nature of the application. This leads us to the basic common requirements of the secure MCU in the card: it should have the ability to store the identity of itself and its owner in such a way as to prevent the unauthorised use of this information. The method commonly, if not universally adopted at present for positive identification is through the use of a Personal Identification Number (PIN) together with a scrambling (or coding) function of some kind. Hence the individual card needs to have the ability to manipulate numbers according to some encryption system and to store in a secure manner unique data pertaining to that card and its owner.

In order to perform any data manipulation "scratchpad" memory is required. This is memory that may be written to and rewritten countless times during the progress of a single calculation or transaction. Since there is also a need for this-memory to be accessed as fast as possible, to minimise calculation times, then the only choice is RAM. However, as I described earlier RAM is the most expensive kind of memory, due to its large physical size. This means that the system designer needs to pay a lot of attention to minimising the use of the "scratchpad" at any one time, to keep the percentage of the silicon area dedicated to temporary results (often of no consequence in themselves) as small as possible. The biggest use of RAM by far in a Smart Card device is for storing the intermediate results generated by the encryption or decryption algorithms and it is here that there is the biggest potential payback in terms of cost savings from efforts to optimise the use of RAM.

Alterable-NVM has the next biggest cell size after RAM, whether we are talking about EPROM or EEPROM. A fundamental requirement of a Smart Card, for whatever application, is that it can be "personalised" or customised for each individual user. This requires NVM since the individual data will have to be written immediately prior to the card being issued to a particular individual; and it will of course have to retain that data when the card is not in use and not powered up. The arguments between EPROM and EEPROM are complex ones. The significant functional difference between these two types of memory is that (at least in credit-card packaging) EPROM is a "writeonce" medium, whereas EEPROM can be written and erased many times.

If write-once versus repeated write-erase was the only issue then obviously EEPROM would win every time. The flexibility of EEPROM is unchallenged. Where the exact future usage of the memory is not known and cannot be predicted then it offers the best choice. However if the use of the memory is known and it can in fact be used in a write-once mode then EPROM has a number of advantages, not the least of which is cost. Bit for bit EPROM is less than half the size of EEPROM, offers a higher level of intrinsic security (more resistant to unauthorised alteration
since erasure is not possible in a Smart Card application), and is a more mature technology with the associated benefits of reliability and predictability. By making use of individual EPROM bits the number of transactions that can be sequentially recorded before the memory fills up can be quite large, however then the card has to be thrown away whereas the EEPROM card can simply have obsolescent data erased as necessary, and the memory re-used.

There are two main uses for the NVM: frequently updated data (such as information on every transaction); and only occasionally updated data (such as a new PIN code, credit limit, personal details, etc.). For the latter category the availability of more than twice as much EPROM memory in the same area may well make it equally or even more attractive than EEPROM. In the former situation however the ability to continually "refresh" the EEPROM card's capacity is an advantage, avoiding as it does the "throw away card" concept. However it should also be remembered that the lifetime of a credit card is finite and controlled by such considerations as plastic wear, customer expectations, and even security. A mixture of EPROM and EEPROM functionality would appear to be desirable, and this development is discussed later.


Figure 4: A comparison in schematic form of the circuitry involved in implementing ROM, EPROM, EEPROM, DRAM and SRAM cells in MOS technology suitable for microcomputers

The final memory type is the fixed ROM which can contain the applications program and general routines for input/output, PIN change etc. There is at least the temptation (and not only in Smart Card applications) for system designers to use the versatility of EPROM \& EEPROM almost as a crutch, enabling last minute changes to software to be made "painlessly". Whilst this does mean that the need for fully functional final software is postponed as long as possible, this delay does carry a price as we have seen, in terms of silicon area. It makes economic sense to ensure that as much of the software as possible is fully defined before the manufacturing of the die starts. In this way the fixed data can be most efficiently stored on the silicon while enabling the available amounts of alterable-NVM, be they EPROM or EEPROM, to be reserved for functions that really require its additional features. In a typical Smart Card type of application we might reasonably expect to see the following apportionment of the software in non-volatile memory: ROM - fixed or "core" software (e.g. I/O routines, read/write subroutines, basic encryption algorithm, planned use software (e.g. bank debit card); EPROM/EEPROM -
sections of the code which it may be desired to update on a 'regular' basis (e.g. algorithm seeds, precise flow of the algorithm, tracking credit balances \& expenditure profile) or which are unique to each individual card (e.g. serial number, personalisation data). EPROM or EEPROM can also be used to allow new functions to be loaded into the card after it has been issued to individual users (e.g. medical data, use as a credit card, telephone prepayment card, access control). By ensuring that the basic routines and functions are stored in ROM it is then possible to change the exact way in which they operate by simply writing different linking software to be stored in the E/ EEPROM. For example it would be possible to operate the data transfer to and from the card at different rates based on a single number stored in E/EEPROM used in conjunction with the basic routine in ROM.

Figures 4 and 5 show in some detail the circuitry involved in typical memory cells as they are constructed on microcomputer devices together with a comparison of the actual layout areas on silicon for some of these memory types.


Figure 5: A comparison in terms of the physical layout on the silicon chip of the circuitry involved in implementing different types of memory array

## VERSATILITY versus COST: THE MEMORY TRADE-OFF

If we take the size of a given ROM array to be 1 then the relative sizes for the other types of memory array are approximately: EPROM-3;EEPROM-7; dynamic RAM - 15; static RAM - 30 . The reasons for this increasing size are simply the increasing complexity of the cells needed to provide the features of each type of memory, plus all the associated driving and decoding logic.


Figure 6: Relative memory cell sizes

## THE FUTURE ?

Clearly the Smart Card market, and indeed the market for secure microcomputers as a whole is still in its infancy. There are a number of very large projects already well underway - in France, Germany, Norway, Switzerland and the U.K. for example, but there are countless more at the stage of advanced planning or preliminary trials. The future for the actual microcomputer chips themselves will be largely determined by the way this marketplace develops. Criteria such as die size, memory size, level of designed-in security, hardware features and so on will all be dependent on which of the many proposed applications actually stay the course and become volume users of this technology.

Without the ability to predict the future and say which will be the most significant uses of Smart Card technology in the 1990's and beyond all we can do is look at current trends in both technology and applications and assess their likely development in the next few years.

It is probable that we will see a reduction in the (apparent) homogeneity of the market; there will be requirements for very large memory array devices, which will be comparatively expensive (multi-function financial cards for example); there will also be a need for very cheap "stripped down" devices, aimed at providing a single, well-defined service very economically (perhaps a tracking token used for manufacturing control, or a simple access control card). Whilst it would appear at present that the latter category has the greater potential for generating very high volume business it is already clear that one of the major strengths of the "Smart Card" is its ability to be a truly multi-purpose card - where further new functions (and even distinct applications) can be added even after the cards have been issued to the individual end-users.

However, to return to the topic of this paper, the shortterm silicon technology developments which we can expect to see in support of the above market forces are basically to do with putting more and more functionality in a given area of silicon. Thus memory cell sizes will continue to shrink, and a significant reduction in this size could be in the use of "flash memory technology".

Flash-EEPROM is a modification of the existing EEPROM technology which reduces the effective individual memory cell size by abandoning the ability to individually erase specific bytes of data. In order to reduce the connection overheads for each cell the flash-EEPROM can normally only be erased in bulk (i.e. the entire array) or as a relatively small number of fairly large data blocks within the array. By making this seemingly simple change it is now possible to get almost as many bytes of flash-EEPROM memory as EPROM memory in a given area of silicon. It must be borne in mind though, that flash-EEPROM is a compromise technology: it will not be as small (hence not as cheap) as EPROM; it will not have the high write-erase cycling endurance of true EEPROM (perhaps only 10 - 100 changes of data, rather than the typical guaranteed figure of 10000 for the EEPROM): nor will it have the selectivity to be able to erase/rewrite single bytes of data, with all the speed advantages that implies; finally it will require an external high voltage source to perform the erase as the bulk nature of this erase precludes the use of an internal charge pump, since the required current is too high. As far as the Smart Card type of applications are concerned then flashEEPROM will give the system designer some of the benefits of EEPROM eraseability, with a cell size (and therefore cost) approaching that of EPROM.

Just becoming available on the market now is a new generation of microcomputer devices which combine both EPROM and true EEPROM on the same die. This mixing of manufacturing technologies has not been trivial but it offers unparalleled versatility to the system designer: he has the write-once kind of changeable memory to add, for example, a new application or a correction to an unforeseen limitation of the software; he also has the full write-erase cycling capability of the EEPROM to cope with frequently changing data, such as credit balances, entry logging etc. Because both types of memory are on the one piece of silicon it is possible to specify the minimum of the more complex and expensive EEPROM as it will only be used for data that changes many times and will not have to cope with the change-once data also, as the current EEPROM only devices have to.

Other developments for the near future which will affect the memory requirements of the secure microcomputer are likely to be in the field of algorithm handling. As we move to more and more sophisticated algorithms so the amount of processing power required increases and also the amount of working storage (RAM) necessary. It is presently a challenge to the cryptographers to cram the interim results of their encryption or decryption into the available RAM. Since RAM is expensive on silicon the pressure is unlikely to ease. Further advances in RAM technology and further shrinking of the cell size will increase the amount of available RAM; however by then the algorithms will require more working storage to cope with their ever increasing sophistication.

Finally we can expect to see the "contactless Smart Card" becoming more common as the complexity and cost problems of this technology are overcome to enable it to compete in the volume marketplace. Presently the potential disadvantage of contactless solutions is that the card has to contain at least two chips, with the associated issues of manufacturability, cost, reliability and security. One development that is firmly in the silicon manufacturer's court is to devise the means to combine the standard HCMOS process technology used for microcomputers with the RF technology needed for the transceiver function of the contactless card. Once this can be achieved then a single-chip contactless Smart Card will be a reality for the high volume low cost general marketplace, and at a stroke many of the interfacing and mechanical contact issues will be circumvented. This is not likely to happen in the immediate future, but if the demand is real then it will happen.

So in summary we can see that there is enormous scope for development of the secure microcomputer. As more flexibility becomes readily available this will of course make more and more potential Smart Card applications viable. The credit card format is a very acceptable one to the end-user, and it may well be that this is the shape of things to come. However one of the reasons that the Smart Card is so acceptable to users is because of the enormous numbers of "credit cards" for a wide range of services already being carried around in people's wallets. When the only kind of "credit cards" are those containing a secure microcomputer perhaps we will see a new, more compact and more durable form of personal identification medium.

| MEMORY <br> FEATURE | ROM | EPROM | EEPROM | RAM | FLASH <br> EEPROM |
| :--- | :--- | :--- | :--- | :--- | :--- |
| Relative array size <br> On silicon | 1 | 3 | 7 | $20-30$ | $3-6$ |
| Number of <br> write-erase cycles | 1 | $10-20$ | $>10000$ | $\infty$ | 100 |
| Data retention time | $\infty$ | 10 yrs | 10 yrs | as long as <br> power on | 10 yrs |
| Program voltage | N/A | external | internal | (internal) | external |
| Erase voltage | N/A | UV | internal | (internal) | external |
| Write time | N/A | 5 ms | 10 ms | bus speed | $2-10 \mathrm{~ms}$ |
| Erase time | N/A | minutes | 10 ms | bus speed | seconds |

Figure 7: A comparison of the principal features of each memory type

## GLOSSARY

| BIT | a single item of information; either "0" or "1" |
| :--- | :--- |
| BYTE | eight bits of data |
| DRAM | Dynamic RAM - requires a refresh, or clock, signal |
| EEPROM | Electrically Eraseable Programmable Read Only Memory |
| EPROM | Eraseable Programmable Read Only Memory |
| kb, Mb, Gb | kilo- (1 024 bytes), Mega- (1 048 576), Giga-byte (1 073 741 824) |
| FLASH | "Flash EEPROM" - a limited form of EEPROM |
| HCMOS | High density Complementary Metal Oxide Semiconductor; |
|  | a manufacturing process for MCU's |
| ISO | International Standards Organisation |
| MCU | Micro Computer Unit |
| NVM | Non-Volatile ("permanent") Memory |
| PIN | Personal Identification Number |
| RAM | Random Access Memory: temporary storage |
| RF | Radio Frequency |

## EB405

# SMART CARDS: how to deal yourself a winning hand 

By Mike Paterson<br>Engineering Manager for Secure Microcontrollers<br>MOTOROLA LTD., East Kilbride, Scotland

Motorola East Kilbride has been the company's worldwide "Centre of Excellence" for Smart Card products for more than ten years. Together with their Geneva Design Centre they have developed and supported a range of secure single chip microcontrollers for Smart Card and other security applications. To date more than 20 million secure MCUs have been sold and
Motorola now has customers throughout Europe, than 20 million secure MCUs have been sold and
Motorola now has customers throughout Europe, Japan and the Americas using its Secure MCU product range. The author has worked in Product Engineering for several years on supporting this range of device types.


## INTRODUCTION

What is a "Smart Card"? There are many definitions for this term, probably one for every article ever to appear in the popular press! However, before I define just what I consider to be a "Smart Card", I would like briefly to explain my choice of title and summarise what I hope to cover in this Engineering Bulletin.

For a number of years it has been fashionable to consider Smart Cards as a "solution looking for a problem", or as an "invention searching for a market". These are now becoming less fashionable expressions as the market for Smart Cards grows and diversifies. However, it is this historical basis and the very diversity of potential applications that are now beginning to come to fruition, which are in some ways hampering the growth of the marketplace.

This Engineering Bulletin sets out to explain, from a silicon manufacturer's perspective, the background to the current market and the variety of products that are on offer. It defines the "Smart Card" and looks at the ways to determine what a particular application needs, in terms of features, if a Smart Card solution is going to succeed for it. By its nature this Bulletin provides only an overview of the many, and complex, arguments that accompany any decision to introduce a Smart Card application, but it is hoped that this will give some basic guidelines to help the prospective end-user to ask his supplier the right kind of questions about the product types available. By choosing the optimum product for the particular market the likelihood of commercial success in that market is enhanced. So, by asking the right questions you end up with the right product. Remembering that (like Poker) you do not see your competitor's hand until it is actually played, it is clearly advantageous to be holding all the Aces before you place your bets on success.

## WHAT IS A SMART CARD?

The simplest definition might be that it is capable of "thinking" for itself - in other words, it has built-in computational ability within the credit card itself which can modify, and even create, data in response to external stimuli. This, then, distinguishes the microcontroller (MCU) based card from all other types. This definition, and its isolation of the MCU based card, is the one l am going to use throughout. All other cards are therefore "dumb" as opposed to "smart". However, it is only fair to say that there are varying degrees of "smartness" and "dumbness". The optical cards for example, with their vast memory capacity, are capable of deploying great amounts of data in order to enhance their operation. However their operational responses are rigidly defined and they cannot create any data: that requires an external "computer" to be connected on-line.

## TYPES OF "CREDIT CARD"

The magnetic stripe card has been around for many years now and it is typically against this bench-mark that all new card technologies are measured. Before we look at how the Smart Card compares with the magnetic stripe card, it may be useful to list what types of card are available and look briefly at their advantages and limitations.

The types of card available are:

1. Embossed plastic (with or without hologram or other visual security feature)
2. Card with magnetic stripe containing personalised/ security data
3. Card with optical storage medium
4. Card with physical/mechanical storage medium
5. Card with silicon chip
a) memory only
i) EPROM (write once)
ii) EEPROM (multiple write)
iii) Battery-backed RAM
b) MCU (with various memory types)
c) multi-chip ("contactless cards" etc.)

Of course not all of the above categories are exclusive, indeed many cards currently are a combination of (1), (2) and (5).

As Table 1 shows, the main differentiators between the various types of card are: cost; storage capacity; versatility; and security.

| Type of Card | Cost | Capacity | Versatility | Security |
| :--- | :---: | :---: | :---: | :---: |
| - embossed plastic | low | nil | nil | nil |
| - with hologram | low | nil | nil | low |
| - with magnetic stripe | low | low | low | low |
| - with non-volatile memory | medium | medium | low | low |
| - with battery-backed RAM | high | medium | medium | low |
| - with MCU | high | medium | high | high |
| - with multi-chip solution | high | medium | high | high |
| - with optical storage | medium | high | medium | medium |
| - with mechanical storage | low | low | nil | nil |

Table 1: A comparison of Card types and their features

## SMART CARD VERSUS MAGNETIC STRIPE

The Smart CardIS NOT a replacement for the magnetic stripe cards that are commonly to be found in all our pockets, at least not directly. The magnetic stripe card has two overwhelming advantages: it is cheap; and it is established - there are hundreds of thousands, if not millions, of standardised magnetic stripe card readers all over the world. This second advantage is, of course, held over all possible competition, and is a temporary hurdle, which will ensure that the new standard (whatever it is) really does offer some distinct advantages! However, on the issue of card cost alone, it is quite safe to say that the MCU based Smart Card will never be as cheap as a magnetic stripe card.

Given the above facts it is essential to look for value added from a proposed Smart Card implementation. This may either be direct, such as enabling a previously impossible application, or indirect, for example in reducing losses due to fraud or misuse.

So, the Smart Card is more expensive than a magnetic stripe card. On the other hand, it surpasses the magnetic stripe card when any other feature is considered. It has many times the data storage capacity, it offers a much higher degree of transaction security and data integrity, and it is flexible - it can support more than one type of transaction, and can be reconfigured after it has been issued to the end-user. If your application needs only the features of the magnetic stripe card then it is unlikely that a Smart Card system will succeed for you. If, however, the application would benefit from the increased flexibility for example, and this can be quantified, then it is much more likely that the system will be commercially viable.

## FEATURES OF A SMART CARD

As I have already said, the benefits of the Smart Card are only relevant if the proposed application gains something from them; it is not necessary to play an "ACE" to beat your opponent's "TWO", a "THREE" WILL do. Nevertheless, let us look at the strengths of the Smart Card, then later we can determine what a specific application actually needs.

I would list the principal features of Smart Cards as follows (in alphabetical order, rather than by merit!):

- Anti-fraud Capability
- Continuous Application and Transaction Validation
- Cost
- Flexibility
- Multi-purpose
- Off-line Capability / "Stand-alone"
- Positive User Authentication
- Reconfigurable In Use
- Security
- Speed
- User Friendly

As you can see, I feel that even overall cost can be considered a feature, when looked at in terms of initial costs, operating costs and cost effectiveness!

Many of the features are, of course, inter-dependent and so I will try to discuss the overall impact of all of them as well as looking at them individually.

Because of the Smart Card's ability to perform its own validation checks, and to store details of transactions internally, it is at once secure and capable of operating in a "stand-alone" mode, that is, with no need to communicate with a central computer/database for every transaction. It is this ability to store data securely, and to operate on that data and on external data within the card, that distinguishes the Smart Card from all other "data cards".

Security in the application is on many levels. There may be the normal software controls, such as passwords or PINs. There are hardware monitoring functions on the silicon itself (to protect against bulk erasure of data for example). There are also the specific hardware features of a Secure Microcontroller which effectively prevent access to data stored on the chip, except in the very limited way permitted by the application software, to ensure that data cannot be selectively modified. By making sure that all the links in the security "chain" are strong ones it is possible to rely on the integrity of the data stored in the die - and hence to perform authentication and validation tests within the card. The benefit of this feature is that the card can perform its own validation of any system it is connected to. This places requirements in terms of security and traceability considerations from the initial design of the chip itself, through silicon manufacture, to system software, and ultimately features of the application.

Given that the data storage is accepted as being secure, the card can then retain information about, for example, a person's credit balance (and balance remaining at a given time) as well as storing PIN data
or passwords, to avoid the need for a central computer link-up. It can also store usage patterns, voluntary limitations of use, and any number of specific details -so that it becomes possible, for example, for the card itself to initiate a fraudulent use check if the usage changes suddenly. The internal computing capability may also be used to detect fraudulent terminals, by continuously exchanging information cryptographically and so validating the terminal to which the card is connected.

## ANTI-FRAUD CAPABILITY

Because there is intelligence in the card, if it is used in a Credit Card application it can prevent overspending by its authorised users, unlike the conventional magnetic stripe card. This is simply because the credit limit and the current balance can be stored on the card, making the response time to overspending immediate and independent of human interaction.

Biometric data is perhaps the most visible of the new techniques being employed to avoid fraudulent use. Though by no means restricted to Smart Cards, the ability of the card itself to allow for changes in response (for example voice change due to a cold) make it a powerful tool. The basic advantage here for the Smart Card is that it can compare stored data with actual data in complex ways, and relate many different pieces of information. For example, there are always tolerances allowed for in biometric data. The card can monitor and update tolerance levels asit."sees" your signature change over a period of time. It can also ask for reconfirmation of identification in cases where a large amount of money, or entry into a high security area, is at stake, especially if the biometric data is on the extreme limit of acceptability.

In addition to all the security features on the silicon and in the software, it is possible for the card to store "typical usage" data. This then allows for the possibility of triggering a "fraudulent use check" if the usage suddenly changes.

## CONTINUOUS APPLICATION AND TRANSACTION VALIDATION

The card can re-verify at any time that it is connected to a legitimate system and application by requesting security data from either the user (eg: biometric or PIN data) or the system (eg: en/decryption keys).

## COST

Clearly the unit cost of a Smart Card is much higher than, for example, a magnetic stripe card. However, the initial cost can be offset by such factors as: the ability to reconfigure the card after issue; the capacity to store data for several distinct applications (eg: parking meter, access control, prepaid ticketing...); reduced loss of issuer income due to fraudulent use or fraudulent duplication; and the ability to function in stand-alone mode, thereby reducing system dependence on expensive, permanent and rapid access to central computing facilities for authorisation and validation etc.

## FLEXIBILITY

The card can have several distinct applications stored on it at once, with safeguards to ensure that there is no unwanted "sharing" of data. It can be reprogrammed (for example with a new credit balance, or even an entirely new application and entitlement) after issue to the end user - without recalling the card.

The exact way in which the card and the system interact is controlled by the software stored in the system and in the card. Obviously the system softwarè can be changed in any card-based system. An advantage of a system based on a Smart Card is that the card software, and hence the form of its responses too, can be changed at any time, by simply reprogramming part of the non-volatile (i.e. the changeable) memory in the card. This means that any operating deficiencies can be corrected, or any newly conceived and valuable features can be added.

## MULTI-PURPOSE

The number of applications installed on a card at one time is limited only by memory space. The card can respond "intelligently" to question-and-answer sessions enabling it to deal with an indefinite number of different application protocols.

> OFF-LINE CAPABILITY / "STAND-ALONE"

The card can validate both the user and the system. It can store credit balances, area access authorisations and records of recent transactions. Standard transactions (perhaps defined as fitting the usage pattern and lying within predefined limits) may be authorised, completed and recorded, for later
communication to a central computer. "Unusual" transactions can still require the card to seek external authorisation in certain circumstances if required.

This capability both reduces cost and increases transaction speed.

## POSITIVE USER AUTHENTICATION

Biometrics are beginning to be used, the limitations at present being principally memory size and response time. Even without this feature, however, there is the simple benefit of the user being able to define his own PIN number, including the length of it and its exact format, and being able to redefine it when and where he wants. There are, of course, varying degrees inbetween these extremes of PIN and biometrics.

## RECONFIGURABLE IN USE

If an application is compromised, or just upgraded (an extra subscription TV channel for example), then this facility can be uploaded on to the card the next time it is used with access to a host computer. This means that it is transparent to the end user, as well as being easy and cheap to accomplish - and fast.

## SECURITY

This technology can increase security in many ways. These include designed-in chip security features (such as fusible links and illegal frequency detection circuitry): reliable tracking and safeguarding, through a controlled manufacturing process; and features written into the user software (such as a check on Reset to ensure that a particular byte of data is present). All this is possible, andmoreover, because the hardware security is there it is possible to build up to very high degrees of additional software security.

## SPEED

Waiting for a telephone link to a central computer is bothexpensive andslow. Local transaction processing is cheaper and faster. It is also possible to respond rapidly to a new business opportunity (such as being able to use your telephone card in another country. now that there is an agreement on national standards) by simply updating the cards already issued, rather than having to offer new ones, with all the related cost and time delay implications.

## USER FRIENDLY

The user can: change PIN data; update personal data; customise operation; define voluntary limits; find out remaining credit/outstanding debit balances... In other words he can feel much more in control of the way the card works, which adds to its perceived convenience.

## What do you need?

As I have already implied, all these features are only worth paying for if they pay for themselves.

As in every area of commerce we have now to look at Cost versus Features. In this particular area past experience has shown that one of the critical parameters to consider is the cost of failure. This means, for example, how much of your revenue will you lose if the security of your product is compromised; or, how much bigger is your potential market if you offer this additional feature (or conversely, how much bigger will your market be if you forego this feature and reduce the price)? The inherent security of the Smart Card solution is advantageous here as it allows you to plan your revenue with much greater confidence.

From the silicon manufacturer's viewpoint the cost issue is quite straightforward; cost is roughly proportional to area of silicon. To minimise the cost of the chip, therefore, you have to trade off features which take up significant amounts of silicon against their expected payback in use.

The biggest single element of any microcontroller die is the memory. The memory area can typically take up to $80 \%$ of the total die area. This is the first region where you need to look for cost effectiveness. Amount of memory, and type of memory are crucial. By considering the cost of memory from the outset it is possible to structure at least some of a system's memory requirements to make use of the most compact types of memory. For example, the more of the system software that can be fixed land therefore stored in ROM as opposed to EPROM or EEPROM), the bigger the potential savings. Of course this does reduce flexibility from the point of view of being able to completely rewrite the system software in the card after it has been issued.

The frequency of change of the data determines the type of memory required. Small amounts of rapidly changing data will be stored in the relatively large RAM cells; EEPROM can cope with large amounts of data being updated several thousand times; the smaller EPROM cells can only cope with one change of data; and the data in the (physically smallest) ROM cells are fixed during manufacture.

Reliability and data integrity is also an issue. All changeable media, be they semiconductor, magnetic or otherwise are subject to loss of data. This again leads to the use of "permanent" (i.e. fixed, ROM) memory where possible. Once the data in ROM has been verified during manufacture, its contents are known and cannot change. For RAM, EEPROM and EPROM the functioning of the cells can, of course, be checked during manufacture but it is impossible to predict the behaviour of an individual cell under the widely varying conditions and long time periods typically to be found in a Smart Card system. It is, therefore, wise to incorporate into the system software (and perhaps the hardware too) a variety of error detection and correction techniques, exactly as is always done with magnetic recording on disk or tape. In this way the reliability and data integrity perceived by the system user is much higher.

Having considered the pros and cons of the various memory types, and also looked at the benefits of offering particular features in a specific system the next step is to optimise the card specification, and hence the silicon specification. Much of the operating code can be fixed from the outset. Where it is necessary to retain flexibility, control of how the fixed routines are linked together, and the exact parameters used, can be stored in alterable memory; this lets cards be changeable up to the point of issue, and beyond. The security of the overall application is controlled by features of the silicon and of the software. Having looked at the costs of the system being compromised is it easier to assess what degree of security is necessary. By writing the software to include a unique identity for every card it is possible to minimise the potential loss if one card is stolen; in other words, the fact that one card is compromised does not necessarily compromise the system. This effectively makes your system immune from illegal card duplication.

Communication between the card and the external system is well defined for ISO type systems. Nevertheless, it is possible to optimise the operation of your card for the desired application, so that for example, the most efficient data transfer rate and format is used for the kind and quantity of data that you are typically dealing with.

Another feature which may prove valuable in certain applications is the ability of the silicon manufacturer to identify each die uniquely during manufacture. This provides traceability information, which can have many uses: serial number; manufacturing date (plus manufacturer, test conditions, ...); a unique encryption key; etc. Because this data can only be written during manufacture, and thereafter is fixed, it enables a reliable user identification and authentication arrangement, whereby individual users can be traced back to individual cards with no possibility of error. Such data can also prove useful in analysing failure patterns, as it allows the contribution of the silicon to be evaluated very quickly, by showing for example that it is all from one manufacturer.

Finally, I return to the cost of failure. What is the "unit worth" of one of your proposed cards? If it is a card which may be used as an "electronic purse" and be preloaded with up to $£ 1000$ then the unit worth is apparent. Here it is obviously of paramount importance to ensure that the current balance cannot be tampered with, or recorded erroneously. There is considerable need to ensure that the reloading of a new balance is protected by very high security procedures. The capability of the Smart Card to perform system validation, and respond to authentication requests from the system, is crucial. If however the card is used as a "subscriber authorisation" for something such as Pay TV then the "unit worth" of a card is fairly low a few pounds a month for the validity period of the card. Even in this circumstance it is very important that the overall integrity of the system cannot be challenged. If, for example, it is possible, by "breaking in" to one card, to compromise the whole system (by, for example, being able to issue many fraudulent cards) then the unit worth of the individual card is very high. By putting in place appropriate security and traceability features on the card it is possible to ensure that defrauding one card, if it were possible, will be limited to that one card. Hence, for security and revenue reasons, it is generally desirable to limit and minimise the unit worth of an individual card.

## THE RIGHT QUESTIONS - to ask about the silicon and the system

If we assume that you have asked yourself the right questions about what your application really needs to succeed, then we can turn to the questions you should ask your card or system supplier - to make sure that the features you have decided are important to you are encompassed by the system you finally get.

SECURITY - is my revenue safe? Is my reputation safe? What features of the silicon/card/system guarantee the particular security needs of my application?

MEMORY SIZE - options and costs?
VERSATILITY - Ease of use and expandability of the system?

DELIVERY - when can I have samples? ...in volume?
QUALITY - can I depend on the product specification?
DEPENDABILITY - supplier's track record and guarantees?

UPGRADE PATH - supplier's history and plans?
COST - is it competitive? What am I paying for? Do I need it all?

As with buying anything, if you know what you want and why, there is a much better chance that you will get it!

## THE FUTURE

From the point of view of silicon for Smart Cards there seems no reason to doubt that progress will continue. The silicon chip will continue to get smaller, cheaper, more versatile and with a wider range of features. Likely enhancements in the not-too-distant future include:

- wider supply voltage range ( $<3 \mathrm{~V}$ to $>6 \mathrm{~V}$ ?)
- lower power consumption
- faster clock speeds
- more memory
- mixed memory (EPROM \& EEPROM)
- flash EEPROM
- greater system integration le.g. RF transceiver elements on same silicon as the MOS microprocessor and memory)

There will also be a drive towards more and more complex cards, to support many applications, or to support a very sophisticated real-time data processing application, perhaps for example involving complex biometric data. This means that, in addition to the above mentioned "smaller, cheaper" trend there is a simultaneous trend to "bigger, faster, more powerful" (and therefore unfortunately, more expensive). This may give rise to a slightly different set of advances in silicon for Smart Cards:

- real-time processing capability (> Digital Signal Processors?)
- dedicated hardware encryption engines on silicon
- parallel data I/O
- much more memory

Of course there is no reason why all future developments need conform to the "credit card" format. Indeed, we are already seeing applications for "secure microcontrollers" which are built in to systems and may therefore be more conventionally packaged. However, it is fair to say that, for consumer applications, the CARD has much in its favour, whether it is with or without contacts. The package problems encountered with the "credit card" are likely to become less and less significant as power consumption continues to fall and as chip architecture continues to shrink.

## IN SUMMARY

Know what YOU need - specify it, and insist on it.

As a service provider, only you understand all the needs and limitations of your business. It is easy to ask for "some of everything", but this will not necessarily make your system succeed. If you have quantified the benefits and shown that you do indeed need a Smart Card system, then make sure that it is optimised and specified for its intended use. You can then ask the vendors what they can offer to meet your specifications -and you can ask them the right questions to determine whether what they are proposing is indeed suited to your application. Extra features mean extra costs, and so need extra revenue.

If you quantify the benefits and optimise the product specification to bring about these benefits then you have done the best with the cards dealt to you. If in addition you ask the right questions of your suppliers then you may even draw an ACE.

# EB408/D 

# MC68HC705T3 Bootloader 

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## INTRODUCTION

Figure 1 shows the circuit required to program the EPROM of an MC68HC705T3 from an external EPROM. There is a direct correspondence between the addresses in the external EPROM and the memory map of the MC68HC705T3. The OSD characters should be in the area \$0400-\$0AFF, the program between $\$ 2000$ and $\$ 7$ EFF and the vectors between \$7FF0 and \$7FFF. It should be noted that these addresses must be used even if the MC68HC705T3 is being used to emulate the MC68HC05T1 or MC68HC05T2. The addresses of the vectors (and the program start address for the MC68HC05T2) must thus be changed from their normal position when emulating these devices. It should also be remembered that MC68HC05T1 and MC68HC05T2 emulation should not employ any resources not present on the target devices. The MC68HC705T3 has more OSD buffers (2 rows) and characters (112), more RAM and more ROM.

The bootloader code in the MC68HC705T3 has 4 modes of operation, selected by switches S1 and S2. In addition to EPROM programming and verifying it is also possible to load and execute a program in RAM locations \$0100-\$01FF. Like the EPROM programmer, the RAM loader transfers data from the corresponding addresses in an external EPROM; there is no serial load facility.

The progress of the loader can be observed in more detail if LEDs are connected to all the pins on port $D$, in a manner similar to that shown in figure 1 for bits 0 and 7 . If this is done, bit 7 is still used for verification and should be a different colour. During EPROM programming the high order address byte is displayed. For RAM loading the 7 lowest addresses are shown. Address 7 is not displayed in order to avoid a false impression of a successful verify.

## OPERATING PROCEDURE

1. The Vdd supply should be off, S3 closed (reset) and S4 in position I (internal).
2. Insert MC68HC705T3.
3. Switch on Vdd. If this is not done before step 4, the MC68HC705T3 may be damaged.
4. If EPROM programming is required, switch on Vpp by changing $S 4$ to position E (external); it is assumed that an external $\mathrm{Vpp}(18.5 \mathrm{~V})$ is present. Vpp is not necessary for verification or for the RAM load and execute modes. These other modes do, however, require at least 9 Volts on pin 2 immediately after reset. The charge pump will supply this voltage when S3 is opened if S4 has been left in position 1 .
5. Select required mode using switches S1 and S2.
6. Open S 3 ; this starts the selected mode. The red LED flashes to indicate that the bootloader is running. At the end of the programming modes a verification is carried out and the green LED switched on if this verification passes. If the green LED is not on at the end of the proceedure the verification has failed. The red LED may be on or off.
7. Close S 3 , at this stage the bootloader can be run again by returning to step 5 .
8. If $S 4$ is in position $E$, return it to position I. This disconnects an externally supplied Vpp. If this is not done before step 9, the MC68HC705T3 may be damaged.
9. Switch off Vdd.
10. Remove MC68HC705T3.


## ADDITIONAL FEATURES

A handshake facility has been included to allow the external EPROM to be replaced by an intelligent data source and to provide a limited debug capability. An alternative source of data could, for example, be a microprocessor controlling a gang programmer. When the direct connection shown in figure 1 between bits 0 and 1 on port $C$ is made, the handshake is performedautomatically. When this connection is not made the bootloader stops immediately before reading data from port $B$ and outputs a high on bit 1 . In order to proceed bit 0 should be pulsed high and low again. The high on bit 1 can be used to indicate that the MC68HC705T3 is ready to receive data.

If bit 0 is held low with a 10 kohm resitor and a push-button switch connected between bit 0 and Vdd the bootloader can be single-stepped. This feature is intended for use with the RAM loader.

To effectively use single-stepping an LED should be connected to every port $D$ pin. If the bootloader is started in the RAM loading mode with no link between bits 0 and 1 on port C , it will stop at the first address $(\$ 0100)$. Pressing the button will cause the bootloader to increment one address at a time (a debouncing circuit may be required to prevent it skipping addresses). The LEDs display addresses A0-A6. If switch S2 is closed once the bootloader has started, the LEDs display the MC68HC05T3's RAM data instead of the address. With S2 closed the contents of the external EPROM are ignored. Although the loader does not permit the inspection of any locations other than \$0100-\$01FF, it is possible to read other locations using a program loaded into RAM. The data can be saved in unused locations between $\$ 0100$ and $\$ 01 \mathrm{FF}$ and then read using the above procedure.

## SOFTWARE

The bootloader resides in the area occupied by the selftest program in the ROMed MC68HC05T3. This area extends from $\$ 7$ F00 to $\$ 7 F E F$ with the last 16 bytes (\$7FE0-\$7FEF) intended for vectors. In this bootloader only the reset vector is actually used.

The program starts at address \$7F00 and immediately checks the state of bits 2 and 3 on port $C$. If they are both high a jump to $\$ 0100$ is executed. This is to allow the running of a program previously loaded into RAM. If either I/O line is low, the software switches the OSD character EPROM into the memory map and initialises the ports. As the port B pins are always inputs, its data direction register does not need to be written to. The subroutine STXHIS is then used to initialise the address bus to the first EPROM location to be
used (\$0400). As the MC68HC705T3, in common with all M6805 microprocessors, has only an 8-bit index register, it is necessary to execute a program in RAM to allow the required flexibility in selecting the address for writing to, and reading from, the on-chip EPROM. For writing to EPROM this program consists simply of an extended STA instruction followed by a 2-byte address and an RTS instruction. This program is built by transferring the contents of the 6 bytes at TABLE into RAM. The 5 th and 6 th bytes are constants used for controlling EPROM write timing (actually 8 bytes are transferred but only the first six are relevant). This transfer is accomplished by the loop at MOVE. After this, a conditional branch depending on the level of bit 2 in port $C$ is taken. If the line is high, the RAM loader is entered, but if it is low the EPROM bootloader modes (program or verify according to the level of bit 3) are started.

The RAM loader transfer the contents of \$0100-\$01FF of the external EPROM into the same addresses in the MC68HC705T3 and then verifies them, switching on the LED (bit 7 of port D) and entering the STOP mode if the verify succeeds. If the verify fails, the program will hang at the first address to fail. If during this process bit 3 of port C becomes high, then the external data is ignored and the contents of internal RAM appear, inverted, on port $D$. The decision to display data rather than write it is made by two conditional branches, one in the main loop of the RAM loader and one in the subroutine HAND1. This subroutine also performs handshaking and reads the external EPROM. If bit 3 of port $C$ is high at the end of a successful verify, a jump to address $\$ 0100$ is performed instead of a STOP.

The EPROM loader similarly loops round its required addresses (\$0400-\$0AFF, \$2000-\$7EFF and \$7FF0-\$7FFF), transferring data from external EPROM. For the EPROM, however, several milliseconds are required to write data. The bootloader performs two loops, each incorporating a 2 mS write time per byte. After this is completed (it takes 110 seconds) a verify loop is performed and the green LED on bit 7 of port $D$ is switched on if the verify succeeds. Alternatively, if an error is detected, the verify loop will hang up at the address of the first byte which did not verify. An inspection of the address bus (port A) will determine the loworder address of this location. The high-order addresses can be seen between the output of the latch and the external EPROM. If all eight LEDs are fitted the high-order address will be displayed.

The last page of the listing consists of the subroutines STXHI which has two entry points, the subroutine NXTADR, TABLE and the bootloader's vectors. NXTADR is responsible for incrementing the EPROM address and skipping the areas. not required for EPROM programming.

MC68HC705T3 BOOTLOADER LISTING

| 0001 |  |  |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0002 ************************************************************************ |  | ************************************************************************ |  |  |  |  |  |  |
| 0003 |  |  |  |  |  |  |  |  |
| 0004 * MC68HC705T3 Bootloader. |  |  |  |  |  |  |  |  |
| 0005 |  |  |  |  |  |  |  |  |
| 0006 |  |  |  |  |  |  |  |  |
| 0007 * This software was developed by Motorola Ltd. for demonstration purp |  |  |  |  |  |  |  |  |
| 0008 * No liability can be accepted for its use in any specific applicat |  |  |  |  |  |  |  |  |
| 0009 * Original software copyright Motorola - all rights reserved. |  |  |  |  |  |  |  |  |
| 0010 |  |  |  |  |  |  |  |  |
| 0011 |  |  |  |  |  |  |  |  |
| 0012 * P. Topping 14-Feb-91 |  |  |  |  |  |  |  |  |
| 0013 |  |  |  |  |  |  |  |  |
|  |  |  |  |  |  |  |  |  |
| 0015 |  |  |  |  |  |  |  |  |
| 0016 | 0000 | PORTA | EQU | \$00 | Port A address |  |  |  |
| 0017 | 0001 | PORTB | EQU | \$01 | Port $B$ |  |  |  |
| 0018 | 0002 | PORTC | EQU | \$02 | Port C |  |  |  |
| 0019 | 0003 | PORTD | EQU | \$03 | Port D |  |  |  |
| 0020 | 0004 | DDRA | EQU | \$04 | Port A data direct | reg. |  |  |
| 0021 | 0006 | DDRC | EQU | \$06 | Port C |  |  |  |
| 0022 | 0007 | DDRD | EQU | \$07 | Port D | * |  |  |
| 0023 |  |  |  |  |  |  |  |  |
| 0024 | 001c | PROG | EQU | \$1C | EPROM program regi |  |  |  |
| 0025 |  |  |  |  |  |  |  |  |
| 0026 | 003e | TR1 | EQU | \$3E | Test register 1 |  |  |  |
| 0027 |  |  |  |  |  |  |  |  |
| 0028 **************************************************** |  |  |  |  |  |  |  |  |
| 0029 |  |  |  |  |  |  |  |  |
| 0030 * Switch options. |  |  |  |  |  |  |  |  |
| 0031 |  |  |  |  |  |  |  |  |
| 0032 * 2, C 3,C |  |  |  |  |  |  |  |  |
| 0033 |  |  |  |  |  |  |  |  |
| 0034 * 0 - 0 Program and verify EPROM. |  |  |  |  |  |  |  |  |
| 0035 * 0 , 1 Verify EPROM. |  |  |  |  |  |  |  |  |
| 0036 * 1 P Parallel RAM load/verify. |  |  |  |  |  |  |  |  |
| 0037 * 1 Execute prog. in RAM. |  |  |  |  |  |  |  |  |
| 0038 |  |  |  |  |  |  |  |  |
| 0039 * Note: Rom always starts at \$2000, Vectors |  |  |  |  |  |  |  |  |
| 0040 * are always at \$7FFF. These are not |  |  |  |  |  |  |  |  |
| 0041 * the normal addresses for T1 or T2. |  |  |  |  |  |  |  |  |
| 0042 |  |  |  |  |  |  |  |  |
| 0043 ***************************************************** |  |  |  |  |  |  |  |  |
| 0044 |  |  |  |  |  |  |  |  |
| 0045 | 0040 |  | ORG | \$40 |  |  |  |  |
| 0046 |  |  |  |  |  |  |  |  |
| 0047 | 0040 | RAM | RMB | 1 |  |  |  |  |
| 0048 | 0041 | ADDR | RMB | 2 |  |  |  |  |
| 0049 | 0043 | RET | RMB | 1 |  |  |  |  |
| 0050 | 0044 | LOOP | RMB | 1 |  |  |  |  |
| 0051 | 0045 | TIME | RMB | 1 |  |  |  |  |
| 0052 ( |  |  |  |  |  |  |  |  |
| 0053 | 7 f 00 |  | ORG | \$7F0 |  |  |  |  |
| 0054 |  |  |  |  |  |  |  |  |




| 0176 |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 0177 |  |  |  |  |  |  |
| 0178 |  | * | Subrout ines. |  |  |  |
| 0179 |  | subroutines. |  |  | * |  |
| 0180 |  | ***************************************************** |  |  |  |  |
| 0181 |  |  |  |  |  |  |
| 0182 | $7 \mathrm{fa5}$ b6 00 | STXHI STXHIS | LDA | PORTA | ADDRLO, LOAD ORIG. CONTENTS |  |
| 0183 | $7 \mathrm{fa7}$ la 02 |  | BSET | 5, PORTC | UPDATE LATCH |  |
| 0184 | $7 \mathrm{fa9}$ bf 00 |  | STX | PORTA | ADDRHI |  |
| 0185 | 7 fab 1b 02 |  | BCLR | 5, PORTC | LATCH CONTENTS OF ADDRHI |  |
| 0186 | 7 fad b7 00 |  | STA | PORTA | RESTORE CONTENTS OF ADDRLO |  |
| 0187 | 7 faf 81 |  | RTS |  |  |  |
| 0188 |  |  |  |  |  |  |
| 0189 | $7 \mathrm{fb} 03 \mathrm{3c} 42$ | NXTADR | INC | ADDR +1 | INC. ADDRLO |  |
| 0190 | 7 fb 23 c 00 |  | INC | PORTA |  |  |
| 0191 | $7 \mathrm{fb4} 2613$ |  | BNE | GOBACK | RETURN IF NOT PAGE BOUNDARY |  |
| 0192 | $7 \mathrm{fb6}$ be 41 |  | LDX | ADDR | GET ADDRHI |  |
| 0193 | 7 fb 85 c |  | INCX |  | INC. ADDRHI |  |
| 0194 | $7 \mathrm{fb} 9 \mathrm{a3} 80$ |  | CPX | \# 580 |  |  |
| 0195 | 7 fbb 27 0c |  | BEQ | GOBACK | END OF VECTORS ? IF SO, EXIT WITH | $Z=1$ |
| 0196 | $7 \mathrm{fbda3} 7 \mathrm{f}$ |  | CPX | \# ${ }^{\text {\% }} 7 \mathrm{~F}$ |  |  |
| 0197 | 7 fbf 2609 |  | BNE | NOTEND | END OF MAIN BLOCK ? |  |
| 0198 | $7 \mathrm{fc} 1 \mathrm{a6}$ f0 |  | LDA | \#FF0 | MOVE TO USER VECTORS |  |
| 0199 | 7 fc 3 b 742 |  | STA | ADDR+1 | UPDATE ADDRLO |  |
| 0200 | $7 \mathrm{fc5}$ bf 41 |  | STX | ADDR | UPDATE ADDRHI |  |
| 0201 | 7 fc 7 ad de |  | BSR | STXHIS | UPDATE LATCH (ADDRHI) |  |
| 0202 | $7 \mathrm{fc9} 81$ | GOBACK | RTS |  | $\mathrm{Z}=1$ IF FINISHED |  |
| 0203 |  |  |  |  |  |  |
| 0204 | 7 fca a3 0b | NOTEND | CPX | \# 50 B | WAS THAT END OSD EPROM ? |  |
| 0205 | 7 fcc 2602 |  | BNE | GO |  |  |
| 0206 | 7 fce ae 20 |  | LDX | * 520 | MOVE TO USER EPROM BEGINNING |  |
| 0207 | $7 \mathrm{fd0}$ bf 41 | GO | STX | ADDR | UPDATE ADDRHI |  |
| 0208 | $7 \mathrm{fd2}$ ad d1 |  | BSR | STXHI | UPDATE EXTERNAL LATCH OF ADDRHI |  |
| 0209 | $7 \mathrm{fd} 4{ }^{43}$ |  | COMA |  | CLEAR 2 FLAG |  |
| 0210 | $7 \mathrm{fd5} 81$ |  | RTS |  |  |  |
| 0211 |  |  |  |  |  |  |
| 0212 | 7 fd 6 c 7 | TABLE | FCB | \$C7 | STA EXTENDED INSTRUCTION |  |
| 0213 | $7 \mathrm{fd7} 0400$ |  | FDB | \$0400 | START ADDRESS |  |
| 0214 | $7 \mathrm{fd9} 81$ |  | FCB | \$81 | RTS INSTRUCTION |  |
| 0215 | 7 fda 02 |  | FCB | 2 | 2 PROGRAMMING LOOPS |  |
| 0216 | 7 fdb 02 |  | FCB | 2 | $2 \mathrm{~ms} \mathrm{PROGRAMMING} \mathrm{TIME} \mathrm{(PER} \mathrm{LOOP)}$ |  |
| 0217 |  |  |  |  |  |  |
| 0218 |  | ** | ** | *********** | *********************** |  |
| 0219 |  | * |  |  | * |  |
| 0220 |  | * | Boot 1 | der Vectors. | * |  |
| 0221 |  | * |  |  | * |  |
| 0222 |  | ******* | *** | ************ | ************************ |  |
| 0223 |  |  |  |  |  |  |
| 0224 | 7 fee |  | ORG | \$7FEE |  |  |
| 0225 |  |  |  |  |  |  |
| 0226 | 7 fee 7 f 00 | RESET | FDB | START | RESET VECTOR |  |
| 0227 |  |  |  |  |  |  |
| 0228 |  |  | END |  |  |  |

## Additional Information

## Additional Information

Additional information relevant to 8-bit MCU applications may be found in the following Motorola documents, available through your Franchised Distributor by quoting the appropriate reference.

| BR266/D | M68HC11EVM Evaluation Module (Rev. 3) |
| :---: | :---: |
| BR278/D | M68HC11EVB Evaluation Board (Rev. 2) |
| BR285/D | M68701EVM Evaluation Module |
| BR291/D | M68705EVM Evaluation Module |
| BR295/D | M68HC05EVM Evaluation Module (Rev. 2) |
| BR411/D | The M68HC11 Microcontroller Family |
| BR433/D | M68HC05 8-bit Microcontrollers. The Home of the Industry Standard Microcontrolter (Rev. 2) |
| BR459/D | MC68HC05SC24 Secure 8-bit Microcomputer with EEPROM: Product Preview |
| BR468/D | Secure MCU Product Packaging |
| BR568/D | MCU Freeware (Rev. 1) |
| BR706/D | M68HC11F1EVM Evaluation Module |
| BR730/D | M68HC05PGMR Programmer Board |
| BR735/D | M68HC05P8EVS CSIC Evaluation System |
| BR736/D | M68HC11EVBU Universal Evaluation Board |
| BR748/D | M68HC711D3PGMR Programmer Board |
| BR764/D | M68HC05 CSIC Portfolio |
| BR909/D | The Military Microprocessor Fleet is Arriving |
| BR911/D | Military Microprocessor Fact Sheet (Rev. 4, 1992) |
| BR913/D | The Military 68HC11A0 and 68HC11A1 are Available Now |
| BR922/D | Military MCU -68HC811E2 |
| BR1111/D | M68HC705J2/P9PGMR Programmer Board |
| BR1113/D | M68HC705B5PGMR Programmer Board |
| BR1116/D | Advanced Microcontroller Unit (AMCU) Literature |
| BR1310/D | Our Low-Cost 68HC05 CSICs Can Take Your Designs to New Heights |
| BRE435/D | M1468705EVM Evaluation Module (replaces BRE294/D) |
| BRE447/D | M6805SC13 Product Preview |
| BRE448/D | M68HC05SC1121 Product Preview |
| BR452/D | Motorola Development Support Guide (Rev. 2, 1991) |
| DL411/D | Communications Applications Manual |
| DLE404/D | M6804 MCU Manual (1984) |
| HC711D3EVB/AD1 | M68HC711D3EVB Evaluation Board User's Manual |
| HC711D3PGMR/AD1 | M68HC11711D3PGMR Programmer Board User's Manual |
| M68HC05AG/AD | M68HC05 Applications Guide |
| M68HC05PGMR/AD1 | M68HC05PGMR Programmer Board User's Manual |
| M68HC11RM/AD | M68HC11 Reference Manual (Rev. 3, 1991) |
| M68PCBUG11/D1/D | M68HC11 PCbug 11 User's Manual |
| M6805UM/AD3 | M6805 HMOS / M146805 CMOS Family User's Manual (1991) |
| M6809PM/AD | MC6809-MC6809E Microprocessor Programming Manual (1981) |
| MC68HC05CxRG/AD | MC68HC05Cx HCMOS Single-Chip Microcontrollers Programming Reference Guide (Rev. 1) |
| MC68HC11A8RG/AD | MC68HC11A8 Programming Reference Guide (Rev. 1) |

## Additional Information (continued)

| MC68HC11D3RG/AD | MC68HC11D3/MC68HC711D3 Programming Reference Guide |
| :--- | :--- |
| MC68HC11E9RG/AD | MC68HC11E9 Programming Reference Guide |
| MC68HC11F1RG/AD | MC68HC11F1 Programming Reference Guide |
| MC68HC11L6RG/AD | MC68HCL6/MC68HC711L6 Programming Reference Guide |
| MC68HC811E2RG/D | MC68HC811E2 Programming Reference Guide |
| MC6801RM/AD2 | MC6801 8-bit Single-Chip Microcomputer Reference Manual |
| MC6840UM/AD1 | MC6840 Programmable Timer Fundamentals and Applications |
| SG96/D | Linear/Interface Integrated Circuits Selector Guide \& Cross Reference <br>  <br> (Rev. 5, 1992) |
| SG138/D | Military IC \& Discrete Selector Guide (Rev. 2, 1992) |
| SG165/D | CSIC Microcontrollers Update - Quarter 2, 1992 |
| SG166/D | Advanced Microcontroller Division Update - Quarter 4, 1991 |
| TB301/D | Basic Microprocessors and the 6800 (Bishop, 1979) |
| TB302/D | What Every Engineer Should Know About Microcomputers <br> (Bennett, Evert and Lander, Rev.1, 1991) |
| TB303/D | Using Microprocessors and Microcomputers: The Motorola Family <br> (Greenfield and Wray, Rev. 1, 1988) |
| TB309/D | Programming the 6809 (Zaks \& Labiak, 1982) |
| TB316/D | Single- \& Multi-Chip MCU Interfacing (Lipovski, 1988) |
| TOOLWARE/D | Software Development Tools for MS-DOS |

Literature Distribution Centers:
USA: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036.
EUROPE: Motorola Lid.; European Literature Centre; 88 Tanners Drive, Blakelands, Milton Keynes, MK14 5BP, England. JAPAN: Nippon Motorola Ltd.; 4-32-1, Nishi-Gotanda, Shinagawa-ku, Tokyo 141, Japan.
ASIA PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Center, No. 2 Dai King Street, Tai Po Industrial Estate, Tai Po, N.T., Hong Kong.


[^0]:    Note: the probes discussed in this article are also available in pre-built form. For a price list and

